IPC-T-50H CN
电子电路互连与封装术语及定义

Terms and Definitions for Interconnecting and Packaging Electronic Circuits

2008年7月

取代IPC-T-50G
2003年12月

本标准由IPC开发

Association Connecting Electronics Industries

IPC®

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电子电路互连与封装术语及定义

Terms and Definitions for Interconnecting and Packaging Electronic Circuits

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感谢您的继续支持。

Acknowledgment

Any document involving a complex technology draws material from a vast number of sources. While the principal members of the Terms and Definitions Committee (2-30) are shown below, it is not possible to include all of those who assisted in the evolution of this standard. To each of them, the members of the IPC extend their gratitude. A special note of thanks goes to the 2-30CN Committee within IPC Task Group Asia (TGAsia) who reviewed and commented on the document for clarity with the Chinese translation of terms and definitions.

鸣 谢

IPC术语和定义委员会（2-30）的全体成员共同努力开发出了此项标准。任何包含复杂技术的标准都要有大量的资料来源，感谢他们为此做出的无私奉献。我们不可能罗列所有参与和支持本标准开发的个人和单位，以下仅列出IPC术语和定义委员会的主要成员。然而，我们还不得不提到IPC TGAsia 2-30CN技术组的部分成员，他们在此标准中文版的翻译、审核中为力求译文的信达雅付出了艰苦的劳动。我们在此一并对上述各有关组织与个人表示衷心的感谢。

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电子电路互连与封装术语及定义

SCOPE

This document is designed to provide definitions for terms commonly used in the electronics industry which have meanings specific to electronics. The definitions are intended to provide sufficient clarity of detail such that a reader utilizing English as a second language could understand the subtleties of the meaning. Terms listed here are those which have a generic usage across multiple disciplines. Terms which have a specialized meaning or usage within a single IPC document should be defined within that document. Commonly used English language terms which do not change meaning when applied to electronics are not defined here.

Acronyms commonly used in electronics are defined in Appendix A. Classification Codes, the numbers following the terms, are listed in Appendix C and discussed in Appendix B.

Note: Changes made to this revision of the IPC-T-50 are indicated throughout by gray-shading of the term and definition.

范围

本文件提供了电子工业常用术语及其定义，这类术语对于电子而言具有其特定的含义。本文件所规定的定义充分详细地阐明了术语，以便以英语为第二语言的读者能够理解含义的细微之处。本文件所列出的术语是在多学科内都通用的术语。在IPC某一标准内具有专门含义或用法的术语应该在相应的标准内做出规定。本文件未列出当其应用于电子学时未改变含义的常用术语。

附录A中给出了电子学中常用的缩写词。附录C按分类编码即每一术语后的编号对术语进行了排序，附录B详述了分类编码规则。

IPC-T-50修订版即H版通过灰色阴影标示出了所有新增及修订的术语和定义。

A

AABUS (As Agreed Upon Between User and Supplier) **26.2084**

Indicates additional or alternate requirements to be decided between the user and the supplier in the procurement documentation. Examples include contractual requirements, modifications to purchase documentation and information on the drawing. Agreements can be used to define test methods, conditions, frequencies, categories or acceptance criteria within a test, if not already established.

AABUS（由供需双方协商确定） **26.2084**

在采购文件中由供方和需方确定的附加或补充要求，例如包括合同要求、对采购文件的更改及图纸的信息，这些要求可以用来详细说明在测试中尚未建立的测试方法、测试条件、频率、类型或验收标准。

Abrasion Resistance **54.1821**

The ability of a material to withstand surface wear.

耐磨性 **54.1821**

材料耐表面磨损的能力。

Abrasive Trimming **54.1318**

Adjusting the value of a film component by notching it with a finely-adjusted stream of an abrasive material against the resistor surface.

磨削修整 **54.1318**

用精密调节的磨削材料射流对膜状元器件表面进行刻槽，以调整其参数值。

Absorption Coefficients **40.1727**

The degree to which various materials absorb heat or radiant energy when compared to each other.

吸收系数 **40.1727**

比较不同材料吸收热能或辐射能的程度。

Absorptivity, Infra-red **40.0087**

The ratio (or percentage) of the amount of energy absorbed by a substrate as compared with the total amount of incident energy.

红外吸光率 **40.0087**

基板所吸收光能量与总入射光能量的比率（或百分比）。

Accelerated Aging **93.0001**

A test in which the parameters such as voltage and temperature are increased above normal operating values to obtain observable or measurable deterioration in a relatively short period of time.

加速老化 **93.0001**

将诸如电压或温度等参数增加到正常工作值之上，以在较短时期内获得可见或可测变质情况的测试。

Accelerated Life Test **93.0119**

See “Accelerated Aging.”

加速寿命测试 **93.0119**

见“加速老化，Accelerated Aging”。

Accelerated Test **93.0216**

A test to check the life expectancy of an electronic component or electronic assembly in a short period of time by applying physically severe condition(s) to the unit under test.

加速测试 **93.0216**

将受测单元置于严酷物理条件下，在短时期内检查电子元器件或电子组件预期寿命的测试。

Accelerator **53.0002**

See “Catalyst.”

加速剂 **53.0002**

见“催化剂，Catalyst”。

Acceleration Factor (AF) **93.0260**

The ratio of stress in reliability testing to the normal operating condition.

加速因子（AF） **93.0260**

可靠性测试与正常工作条件下的应力之比。

Acceptance Quality Level (AQL) **90.0003**

The maximum number of defectives likely to exist within a population (lot) that can be considered to be contractually tolerable; normally associated with statistically derived sampling plans.

验收质量水平（AQL） **90.0003**

一个总体（批）中可能存在且合同所允许的最多缺陷数，通常与统计抽样方案有关。

Acceptance Tests **92.0004**

Those tests deemed necessary to determine the acceptability of a product and as agreed to by both purchaser and vendor.

验收测试 **92.0004**

经采购方和供方同意，为确定产品可接受性所必需的测试。

Acceptance Inspection (Criteria) **92.0288**

An inspection that determines conformance of a product to design specifications as the basis for acceptance.

验收检验（准则） **92.0288**

确定产品与验收依据的设计规范一致性的检验。

Access Hole **60.1319**

A series of holes in successive layers of a multilayer board, each set having their centers on the same axis. These holes provide access to the surface of the land on one of the layers of the board. (See Figure A-1.)

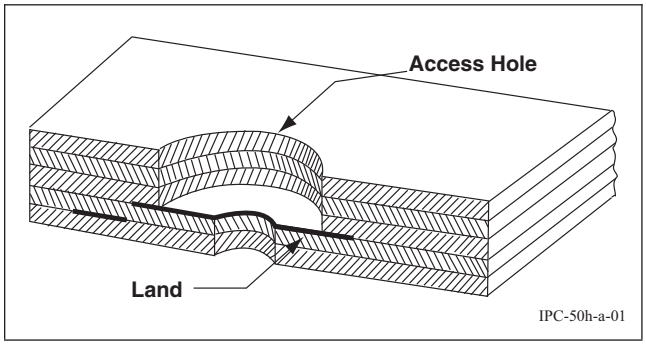
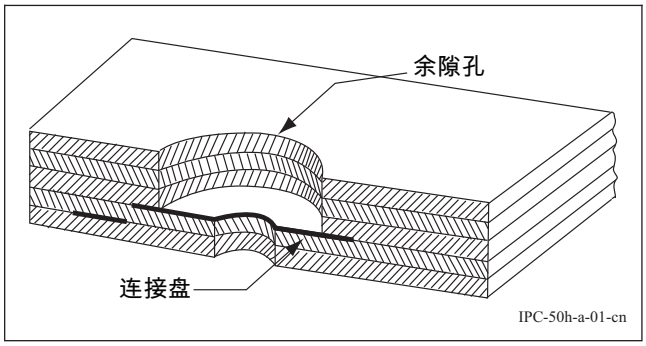


Figure A-1 Access Hole

余隙孔 **60.1319**

多层板逐连层中一系列孔，孔的中心在同一轴线上，这些孔为进入印制板某一层连接盘的表面提供了通道。（见图A-1。）



图A-1 余隙孔

Access Protocol **21.0005**

An agreed principle for establishing how nodes in a network communicate electronically.

访问协议 **21.0005**

建立网络结点如何实现电子通讯的约定规则。

Accordion Contact **36.0006**

A type of connector contact that consists of a flat spring formed into a “Z” shape in order to permit high deflection without overstress.

折叠式接触件 **36.0006**

为允许高挠曲而无过度应力，由扁平弹簧折成Z字形所构成的连接器接触件。

Accuracy **90.0007**

The deviation of the measured or observed value from the true value.

精度 **90.0007**
测量值或观察值与真值间的偏差。

Acid Flux **46.0009**
A solution of an acid and an inorganic, organic, or water soluble organic flux. (See also “Inorganic Flux,” “Organic Flux,” and “Water Soluble Organic Flux.”)

酸性助焊剂 **46.0009**
一种酸和无机、有机或水溶性有机助焊剂的溶液。（又见“无机助焊剂，Inorganic Flux”、“有机助焊剂，Organic Flux”和“水溶性有机助焊剂，Water Soluble Organic Flux”。）

Acid Number **54.0010**
The amount of potassium hydroxide in milligrams that is required to neutralize one gram of an acid medium.

酸值 **54.0010**
中和1克酸液所需以毫克计的氢氧化钾的量。

Acid Value **54.1217**
See “Acid Number.”

酸价 **54.1217**
见“酸值，Acid Number”。

Acid-Core Solder **46.0008**
Wire solder with a self-contained acid flux.

酸性芯焊料 **46.0008**
自身含有酸性助焊剂的焊料丝。

Actinic Radiation **52.0011**
Light energy that reacts with a photosensitive material in order to produce an image.

有效光 **52.0011**
与感光材料相互作用使生成影像的光能。

Active Desiccant **30.0397**
Desiccant that is either fresh (new) or has been baked according to the manufacturer’s recommendations to renew desiccant to original specifications.

活性干燥剂 **30.0397**
未用过的（新的）或者根据制造商的建议烘烤再生到原有规格的干燥剂。

Activated Rosin Flux **46.0012**
A mixture of rosin and small amounts of organic-halide or organic-acid activators. (See also “Synthetic Activated Flux.”)

活性松香助焊剂 **46.0012**
松香和少量的有机卤化物或有机酸活化剂的混合物。（又见“合成活性助焊剂，Synthetic Activated Flux”。）

Activating **53.0013**
A treatment that renders nonconductive material receptive to electroless deposition.

活化 **53.0013**
使非导电材料易于接受化学沉积的处理方法。

Activating Layer **53.0014**
A layer of material that renders a nonconductive material receptive to electroless deposition.

活化层 **53.0014**
使非导电材料易于接受化学沉积的材料层。

Activator **46.0015**
A substance that improves the ability of a flux to remove surface oxides from the surfaces being joined.

活化剂 **46.0015**
提高焊剂从待焊接表面去除表面氧化物能力的物质。

Active Device **30.0016**
An electronic component that can change a signal or respond to the signal in a way that is dependent upon the nature of the signal and/or other controlling factors. (This includes diodes, transistors, amplifiers, thyristors, gates, ASIC’s and other integrated circuits that are used for the rectification, amplification, switching, etc., of analog or digital circuits in either monolithic or hybrid form.)

主动（有源）器件 **30.0016**
能够根据信号和/或其它控制因素的特性改变信号或对信号作出响应的电子元器件。（这类器件包括二极管、晶体管、放大器、半导体闸流管、门电路、ASIC和其他集成电路，用于整流、放大、开关等以单片电路或混合电路形式组成的模拟或数字电路。）

Active Metal **36.0017**
A metal that has a very high electromotive force.

活泼金属 **36.0017**
具有很高电动势的金属。

Active Trimming **54.1321**
Adjusting the value of a film circuit element in order to obtain a specified functional output from the circuit while it is electrically activated.

带电修整 **54.1321**

在通电状态下，调整一个膜电路要素的值，使电路获得规定的输出功能。

Actual Size **90.0018**

The measured size.

实际尺寸 **90.0018**

测量得到的尺寸。

Additive Process **53.1322**

A process for obtaining conductive patterns by the selective deposition of conductive material on clad or unclad base material. (See also “Semi-Additive Process” and “Fully-Additive Process.”)

加成法工艺 **53.1322**

在覆箔或未覆箔基材上，通过选择性沉积导电材料而获得导电图形的工艺。（又见“半加成法工艺，Semi-Additive Process”及“全加成法工艺，Fully-Additive Process”。）

Add-On Component **30.0019**

Discrete or integrated packaged or chip components that are attached to a film circuit in order to complete the circuit’s function.

外加元器件 **30.0019**

为了实现电路功能而附加在膜电路上的分立的或集成封装或片式元器件。

Adhesion (Pressure Sensitive Tape) **46.2038**

The bond produced by contact between pressure-sensitive adhesive and a surface.

附着力（压敏胶带） **46.2038**

压敏胶带与表面接触所产生的粘合。

Adhesive **46.1728**

A substance such as glue or cement used to fasten objects together. In surface mounting, an epoxy adhesive is used to adhere SMDs to the substrate.

粘合剂 **46.1728**

用于将物体互相牢固连接的胶或接合剂等物质。在表面贴装中，环氧粘合剂用于将表面贴装元器件粘附到基板上。

Adhesion Failure **96.0020**

The rupture of an adhesive bond such that the separation appears to be at the adhesive-adherend interface.

粘接失效 **96.0020**

粘结连接的断裂，以至在粘接剂附着界面处呈现分离。

Adhesion Layer **74.0021**

The metal layer that adheres a barrier metal to a metal land on the surface of an integrated circuit.

粘接层 **74.0021**

将隔离金属粘附至集成电路表面上的金属连接盘的金属层。

Adhesion Promotion **53.0022**

The chemical process of preparing a surface to enhance its ability to be bonded to another surface or to accept an over-plate.

附着力增强 **53.0022**

为增强与其他表面的接合能力或接受外镀层能力的表面化学处理过程。

Adhesive Coated Substrate **41.0438**

A base material upon which an adhesive coating is applied, for the purpose of retaining the conductive material (either additively applied or attached as foil for subtractive processing), that becomes part of a metal-clad dielectric.

涂胶基板 **41.0438**

一种表面涂有粘胶层的基材，其粘胶层用于粘接导电材料（可用于加成法或覆以金属箔用于减成法），并成为覆金属箔绝缘层的一部分。

Adhesive-Coated Catalyzed Laminate **41.1320**

A base material with a thin polymer coating, that contains a plating catalyst, that is subsequently treated in order to obtain a microporous surface.

涂胶催化层压板 **41.1320**

涂覆了含有电镀催化剂薄聚合物涂层的基材，在其后续处理中可获得微孔结构的表面。

Adhesive-Coated Uncatalyzed Laminate **41.1323**

A base material with a thin polymer coating, that does not contain a plating catalyst, that is subsequently treated in order to obtain a microporous surface.

涂胶非催化层压板 **41.1323**

一种涂覆了不含电镀催化剂薄聚合物涂层的基材，在其后续处理中可获得微孔结构的表面。

Adhesive Transfer (Pressure Sensitive Tape) **75.0558**

The transfer of adhesive from its normal position on the pressure sensitive tape to the surface to which the tape was attached, either during unwind or removal.

粘接剂转移（压敏胶带） **75.0558**

当压敏胶带展开或从贴附表面移除时，粘接剂从正常位置转移到胶带粘附过的表面。

Adsorbed Contaminant **96.0023**

A contaminant attracted to the surface of a material that is held captive in the form of a gas, vapor or condensate.

吸附污染物 **96.0023**

以气体、蒸汽或冷凝液的形式粘附在材料表面的污染物。

Advanced Statistical Method **91.0024**

A statistical process analysis and control technique that is more sophisticated and less widely applicable than basic statistical methods.

高级统计方法 **91.0024**

较基本统计方法更为复杂及应用范围较小的统计过程分析及控制技术。

Aging **90.0025**

The change of a property, e.g., solderability, with time. (See also “Accelerated Aging.”)

老化 **90.0025**

随着时间的推移，而引起特性（例如可焊性）的变化。（又见“加速老化，Accelerated Aging”。）

Air Contamination **14.0026**

See “Air Pollution.”

空气污染 **14.0026**

见“空气污染，Air Pollution”。

Air Pollution **14.0027**

Contamination of the atmosphere with substances that are toxic or otherwise harmful.

空气污染 **14.0027**

大气被有毒或其它有害物质污染。

Algorithm **11.0849**

A set of procedures for the solution of a problem in a series of steps.

算法 **11.0849**

用一系列步骤解决问题的一组程序。

Alignment Mark **22.0030**

A stylized pattern that is selectively positioned on a substrate material to assist in alignment. (See Figure A-2.)

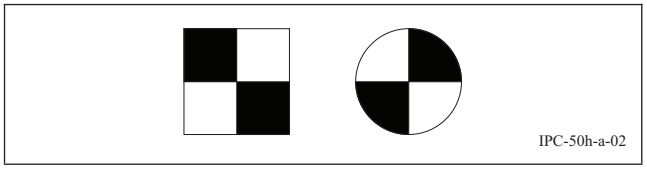
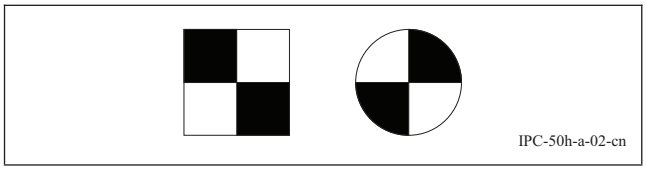


Figure A-2 Alignment Mark

对准标记 **22.0030**

为帮助对准定位，有选择地设置在基材上的特定图形。（见图A-2。）



图A-2 对准标记

Aliphatic Solvents **76.0031**

“Straight chain” solvents, derived from petroleum, of low solvent power.

脂肪族溶剂 **76.0031**

从石油中提取的“直链”溶剂，溶解能力较低。

Alkaline Cleaner **76.0032**

A material blended from alkali hydroxides and alkaline salts.

碱性清洗剂 **76.0032**

由碱性氢氧化物和碱性盐组成的混合物。

All Metal Package **33.0579**

A hybrid circuit package made solely of metal, without glass or ceramic.

全金属封装 **33.0579**

不用玻璃及陶瓷，只用金属制成的混合电路封装。

Allowable Temperature **75.0609**

The temperature range that an electronic circuit or component can perform its intended functions.

允许温度 **75.0609**

电子电路或元器件能实现其预期功能的温度范围。

Alloy, Tin Bismuth (Sn-Bi) **45.1947**

An alloy that is used as a lead free solder and consisting of tin and bismuth as the main constituents. Sn-Bi58 has a low melting point of 138 °C [280 °F], but is not widely used because of its brittle properties.

锡铋合金（Sn-Bi） **45.1947**

以锡及铋为主要成分的无铅焊料的合金，锡铋58具有138 °C[280 °F]的低熔点，但由于其脆性而未被广泛应用。

Alloy, Tin Copper (Sn-Cu) **45.1948**

An alloy that is used as a lead free solder consisting of tin and copper considered to be applicable for wave or reflow soldering.

锡铜合金（Sn-Cu） **45.1948**

由锡及铜组成的无铅焊料合金，主要可应用于波峰焊或再流焊。

Alloy, Tin Silver (Sn-Ag) **45.1949**

An alloy that is used as a lead free solder and consisting of tin and silver as the main constituents used as a high temperature solder.

锡银合金（Sn-Ag） **45.1949**

由锡及银组成的无铅焊料合金，主要用作高温焊料。

Alloy, Tin Silver Bismuth (Sn-Ag-Bi) **45.1950**

An alloy that is used as a lead free solder and consisting of tin, silver and bismuth as the main constituents. The Bi in Sn-Ag-Bi alloy reduces the melting temperature. The higher the Bi content, the higher the mechanical strength, but with poorer elongation capability. There is a limit to Bi content.

锡银铋合金（Sn-Ag-Bi） **45.1950**

以锡、银、铋为主要成分的无铅焊料合金。铋在锡银铋合金中可降低熔融温度。铋的含量越高，机械强度越高，但延展性越差。所以应限制铋的含量。

Alloy, Tin Silver Copper (Sn-Ag-Cu) **45.1951**

An alloy that is used as a lead free solder consisting of tin, silver and copper as the main constituents.

锡银铜合金（Sn-Ag-Cu） **45.1951**

以锡、银、铜为主要成分的无铅焊料合金。

Alloy, Tin Zinc (Sn-Zn) **45.1952**

An alloy that is used as a lead free solder and consisting of tin and zinc as the main constituents. Zn09 alloy has a melting point of 199 °C [390 °F], is closest to the melting point of Sn-Pb alloy among lead free solders, which allows soldering work at present soldering temperatures, but tends to form a stable oxide film, causing difficulty in securing a good solder wetting.

锡锌合金（Sn-Zn） **45.1952**

以锡、锌为主要成分的无铅焊料合金。在无铅焊料之中，锌09合金具有199 °C[390 °F]的熔点，与锡铅合金的熔点接近，可用现行的焊接温度进行焊接，但是易于形成稳定的氧化膜，难以形成良好的焊料润湿。

Alpha Error **91.0033**

The size of a Type I error or the probability of rejecting a hypothesis that is true.

α错误 **91.0033**

第一种类型错误，以原假设为真而被拒绝的概率。

Alphanumerical **25.1729**

Pertaining to data that contain the letters of an alphabet, the decimal digits, and may contain control characters, special characters and the space character.

字母数字 **25.1729**

包含字母、十进制数字的数据，也可以包括控制符、特殊字符及空格符。

Alpha Particle **35.0612**

A He^4 nucleus generated from a nuclear decay that is capable of generating hole-electron pairs in microelectronic devices and switching cells causing soft errors in some devices.

α粒子 **35.0612**

由原子核衰变产生的He^4原子核，能在微电子器件和开关器件中产生空穴电子对，导致软击穿故障。

Alternating Current (ac) **21.1793**

A current that varies with time, commonly applied to a power source that switches polarity many times per second, in the shape of a sinusoidal, square, or triangular wave.

交流电（ac） **21.1793**

随时间而变的电流，通常用于电源每秒切换多次极性的正弦、方波或三角波。

Alternative Hypothesis **93.1324**

The supposition that a significant difference exists between the desired results of two comparable populations. (See also “Null Hypothesis” and “Statistical Hypothesis.”)

备择假设 **93.1324**

两个可比总体的期望结果之间存在显著差异的假设。（又见“原假设，Null Hypothesis”和“统计假设，Statistical Hypothesis”。）

Alumina Substrate **43.1730**

Aluminum oxide used as a ceramic substrate material.

氧化铝基板 **43.1730**

采用氧化铝制作的陶瓷基板。

Ambient **29.0034**

The surrounding environment coming into contact with the system or component in question.

环境 **29.0034**
与所研究的系统或元器件相接触的周围环境。

Amorphous Polymer **40.0035**
A polymer with a random and unstructured molecular configuration.

无定形聚合物 **40.0035**
分子结构为无规则的、非结构性的聚合物。

Amplitude, Voltage **21.0036**
The magnitude of a voltage as measured with respect to a reference, such as a ground plane.

电压振幅 **21.0036**
相对于一个基准点例如接地层所测得的电压幅值。

Analog Circuit **21.0037**
An electrical circuit that provides a continuous relationship between its input and output.

模拟电路 **21.0037**
在输入与输出之间提供连续关系的电路。

Analysis of Variance (ANOVA) **91.0038**
The systematic method of statistically evaluating experimental results in order to separate the sources of variation.

方差分析（ANOVA） **91.0038**
为分离变异源，统计评价试验结果的系统方法。

Anchoring Spur **22.1325**
An extension of a land on a flexible printed board that extends beneath the coverlay to assist in holding the land to the base material. (See Figure A-3.)

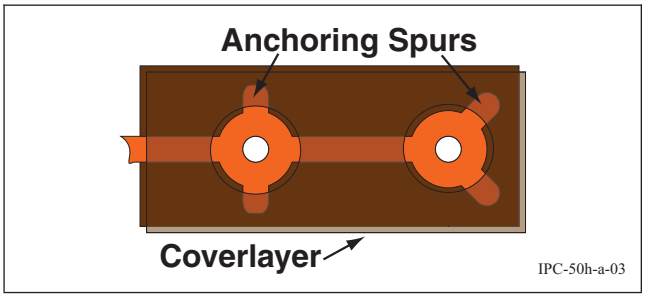
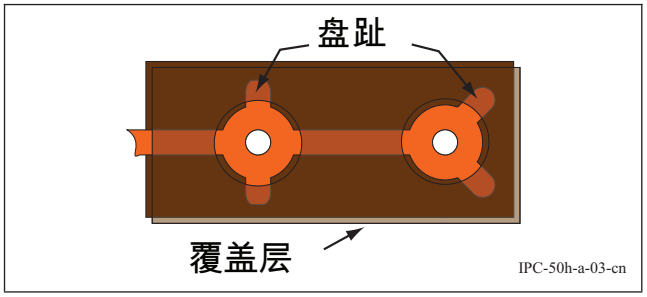


Figure A-3 Lands with Anchoring Spurs

盘趾 **22.1325**
挠性印制板连接盘的一部分延伸至覆盖层下面，用以加固连接盘与基材的连接。（见图A-3。）

Angled Bond **74.0039**
The impression of the first and second bonds that are not in a straight line.



图A-3 带盘趾的连接盘

角形键合 **74.0039**
第一个和第二个键合压痕不在一条直线上。

Anisotropic Conductive Contact **75.0675**
An electrical connection using an anisotropic conductive film or paste wherein conductive particles of gold, silver, nickel, solder, etc. are dispersed. When it is compressed, an electrical connection is attained only in the direction of compression.

各向异性导电连接 **75.0675**
使用内含分散金、银、镍、焊料等导电粒子的各向异性导电膜或膏形成的电连接。当被压缩时，只在受压缩的方向获得电气连接。

Anisotropy **40.0685**
The condition for a substance having differing values for properties, such as permittivity, depending on the direction within the material.

各向异性 **40.0685**
物质的性质（例如电容率）在不同方向上具有不同值的状况。

Annotation **22.0040**
Text, notes, or other identification, constructed by a computer-aided system, intended to be inserted on a drawing, map or diagram.

注解 **22.0040**
由计算机辅助系统制作，用于在图纸、图谱或图表中插入的文字、注释或其它标识。

Annular Ring (Annular Width) **60.0041**
That portion of conductive material completely surrounding a hole. (See Figure A-4.)

孔环（环宽） **60.0041**
完全环绕孔的导电材料部分。（见图A-4。）

Anode (BGA) **33.0689**
The electrode from which the forward current flows within the device.

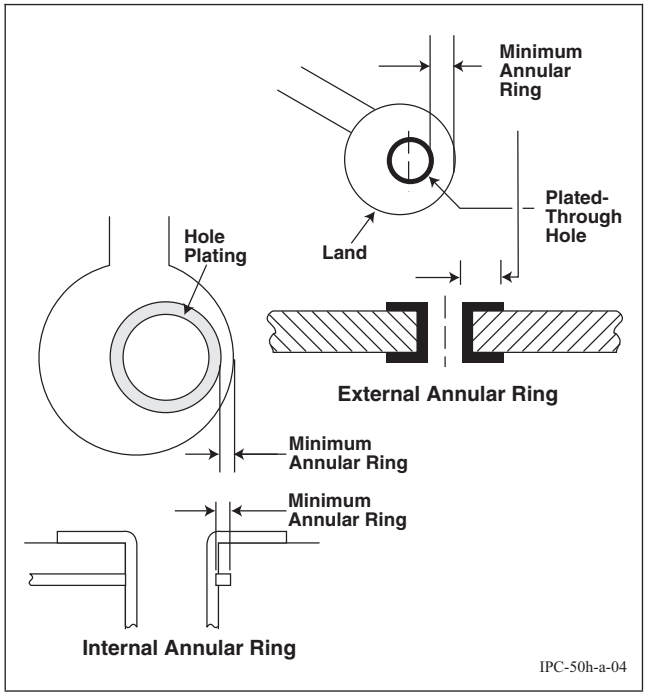
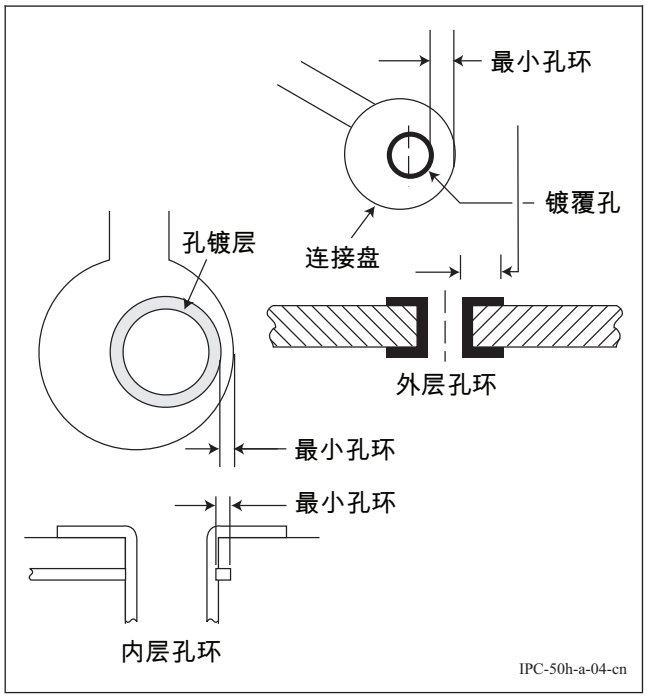


Figure A-4 Annular Ring (Annular Width)



图A-4 孔环（环宽）

阳极（BGA） **33.0689**

器件中的正向电流流出的电极。

Anodic Cleaning **57.0042**

Electrolytic cleaning in which the work is the anode.

阳极清洗 **57.0042**

工件为阳极的电解清洗。

Antipad **22.2173**

An established clearance in the plane to accommodate a hole and its corresponding pad stack.

反盘 **22.2173**

为层上的某个孔所建立的与盘栈尺寸相一致的隔离区。

Aperture (Stencil) **73.0690**

An opening in the stencil-foil.

开孔（模板） **73.0690**

在模板上开的孔。

Apparent Field-of-View Angle **92.0043**

The angular subtense of the field-of-view in the image space of an optical system.

视角 **92.0043**

光学系统的成像空间内视场的张角。

Application Specific Integrated Circuit (ASIC) **33.0692**

A semiconductor device intended to satisfy a unique complete circuit function.

专用集成电路（ASIC） **33.0692**

用于满足特殊完整电路功能的半导体器件。

Aqueous Flux **46.0044**

See “Water Soluble Organic Flux.”

水性助焊剂 **46.0044**

见“水溶性有机助焊剂，Water Soluble Organic Flux”。

Aramid **44.0045**

See “Para-aramid.”

芳酰胺 **44.0045**

见“对芳酰胺，Para-aramid”。

Arc Resistance **92.0047**

The resistance of a material to the effects of a high voltage, low current arc (under prescribed conditions) passing across the surface of the material. (The resistance is stated as a measure of total elapsed time at that voltage required to form a conductive path on the surface - material carbonized by the arc.)

耐电弧性 **92.0047**

材料对通过其表面的高压低电流电弧（在规定条件下）所产生影响的耐受性。（耐受性用在规定电压下，电弧将导体表面材料炭化形成导电通路的总耗时来表示。）

Architecture **11.0046**

The structure of a computer's functional elements that makes it possess specific maximum and minimum capabilities.

体系结构 **11.0046**

使计算机具有特定的最大和最小能力的功能单元结构。

Area Array **34.0751**

A bonding pattern in which edge and additional pads on the inner surface area of the chip are addressed in the bonding scheme. (See Figure A-5.)

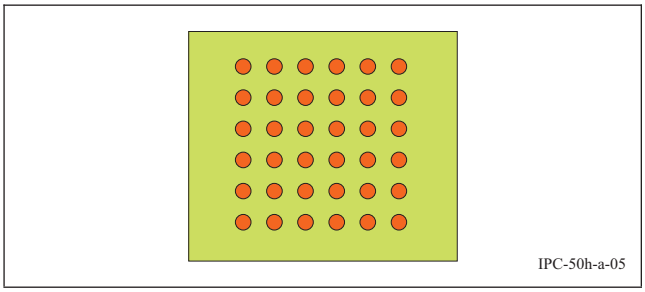
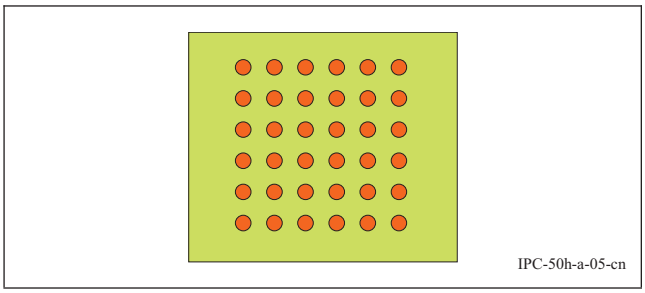


Figure A-5 Area Array

面阵列 **34.0751**

芯片内表面区的边缘及附加焊盘用于键接线路的键接图形。（见图A-5。）



图A-5 面阵列

Area Array Tape Automated Bonding **74.0048**

Tape Automated Bonding where some carrier tape terminations are made to lands within the perimeter of the die.

面阵列载带自动键合 **74.0048**

部分载带终端与芯片周边内连接盘进行连接的载带自动键合。

Area Ratio **73.0758**

The ratio of the area of aperture opening to the area of aperture walls.

面积比 **73.0758**

开孔面积与孔壁面积之比。

Array **22.0049**

A group of elements or circuits arranged in rows and columns on a base material.

阵列 **22.0049**

在基材上成行及成列布置的一组单元或电路。

Artificial Intelligence **11.0050**

The capacity of a machine to perform functions that are normally associated with human intelligence, such as reasoning and learning.

人工智能 **11.0050**

机器执行通常与人类智能有关的功能（例如推理及学习）的能力。

Artwork **22.0051**

An accurately-scaled configuration that is used to produce the "Artwork Master" or "Production Master." (See Figure A-6.)

照相底图 **22.0051**

用于生成照相原版及生产底版的比例准确的图形。（见图A-6。）

Artwork Master **24.0052**

An accurately-scaled, usually 1:1, pattern that is used to produce the "Production Master." (See Figure A-6.)

照相原版 **24.0052**

比例准确，通常为1:1的图形，用于生成生产底版。（见图A-6。）

As-Fired **45.0054**

The condition (values) of thick-film components or the smoothness of ceramic base materials, after they have been processed in a firing furnace and prior to trimming or polishing.

烧结态 **45.0054**

在烧结炉中经加工处理后和修整或抛光前厚膜元器件的状态（值）或陶瓷基材的光滑度。

Aspect Ratio (Film) **74.0055**

The ratio of the length of a film component to its width.

长宽比（膜元器件） **74.0055**

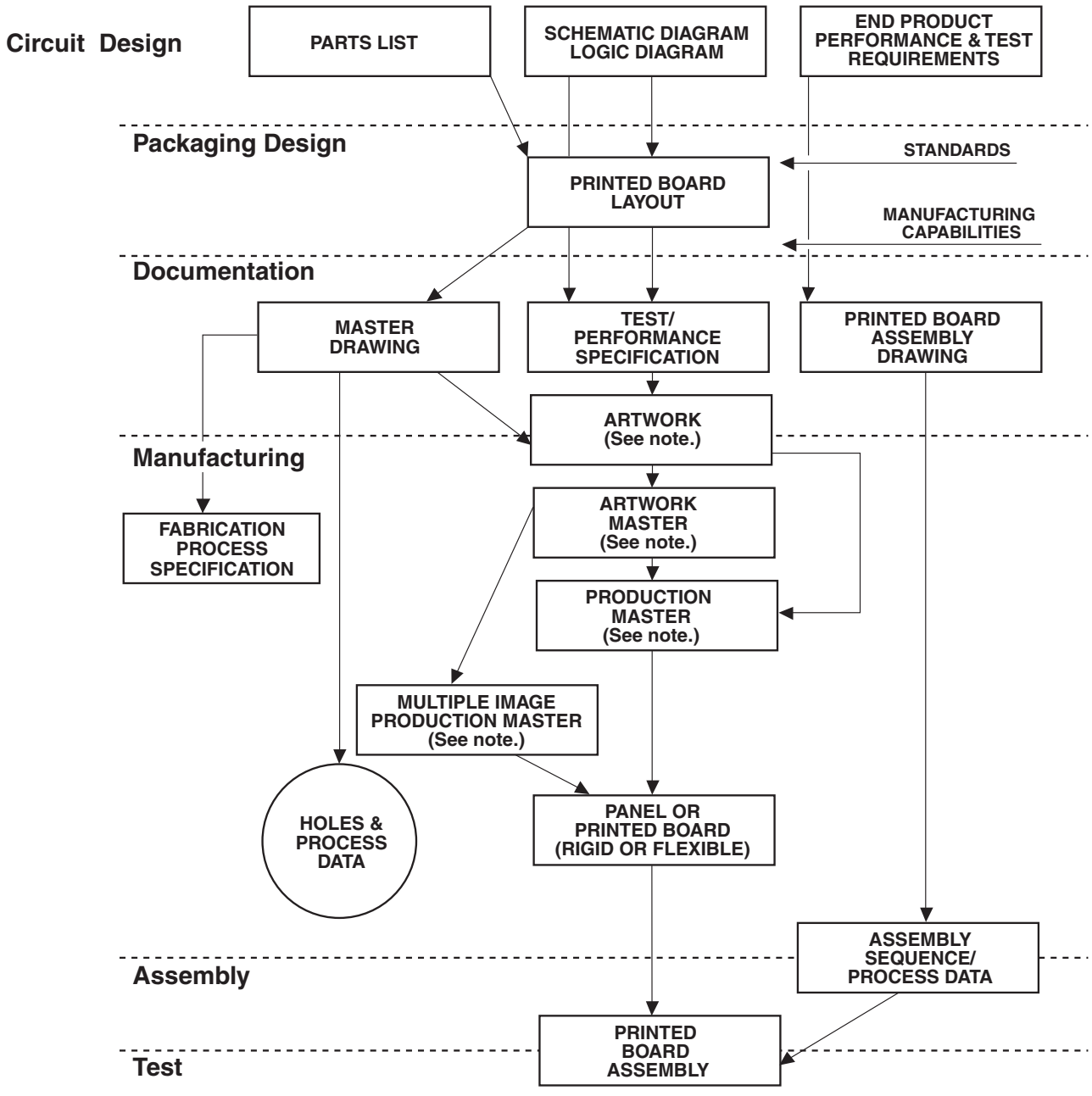
膜元器件的长度与宽度之比。

Aspect Ratio (Hole) **53.0056**

The ratio of the length or depth of a hole to its preplated diameter. (See Figure A-7.)

厚径比（孔） **53.0056**

孔的长度或深度与其电镀前孔径之比。（见图A-7。）



Note: The term "Original" may be used to preface any of the drafting and photographic-tooling terms used in this figure. The "Original" is not usually used in manufacturing processes. In the event a "Copy" is made, the copy must be of sufficient accuracy to meet its intended purpose if it is to take on the name of any one of the terms used in this figure. Other adjectives may also be used to help describe the kind of copy, i.e., "nonstable," "first generation," "record," etc.

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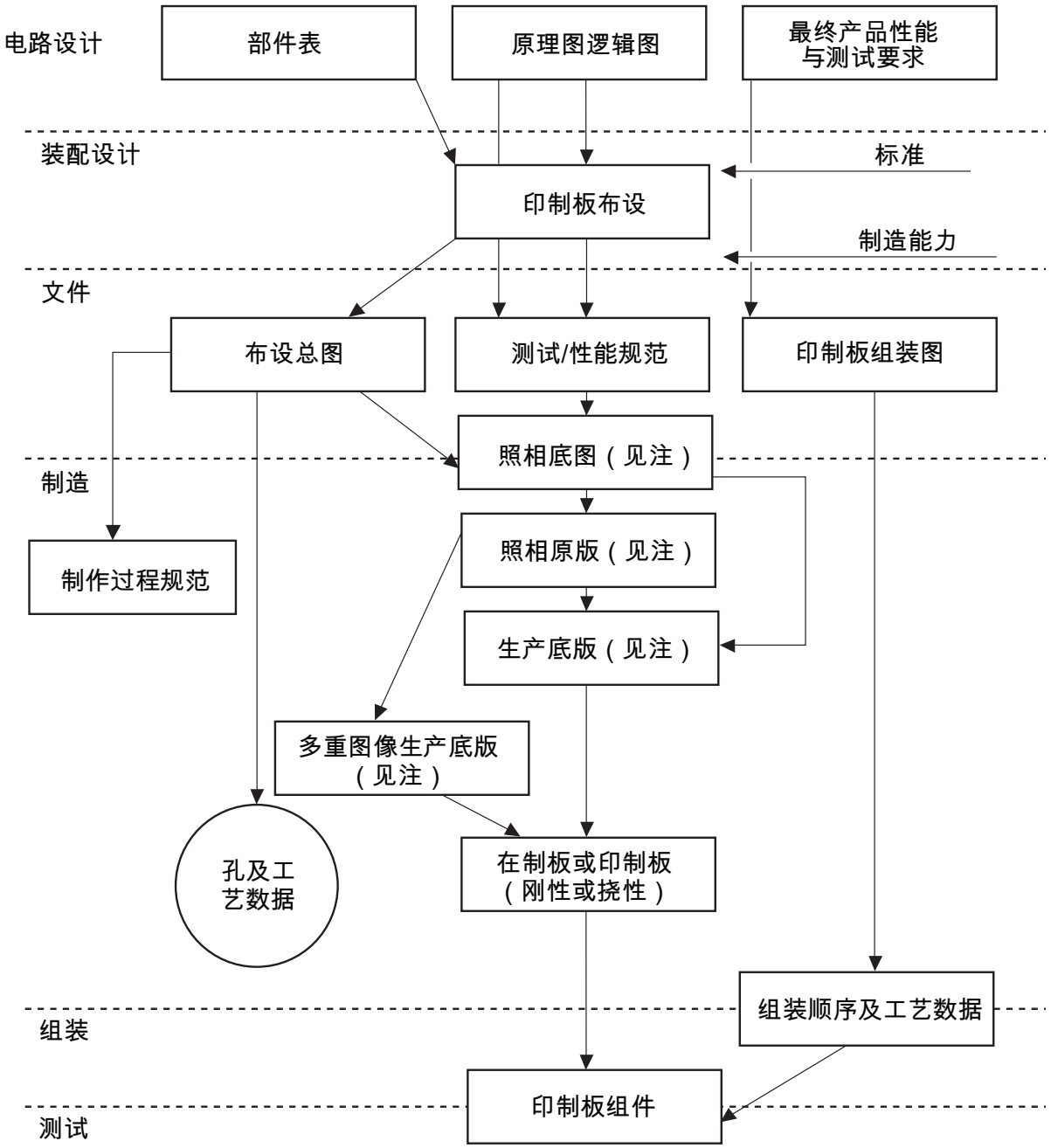
Figure A-6 Artwork (Simplified Flow Chart of Printed Board Design/Fabrication Sequence)



注：“原（Original）”一词可用于本图中任何设计和底片加工术语的前导词，“Original”在制造过程中不常用。一旦产生了“复制件（copy）”，如果本图中所用的某个术语出现“复制”，这个复制件必须有足够的准确度来达到其预期的效果。其他形容词也可用于描述复制件的类别，如“不稳定”、“首次生成”、“记录”等。

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图A-6 印制板设计/制造流程简图

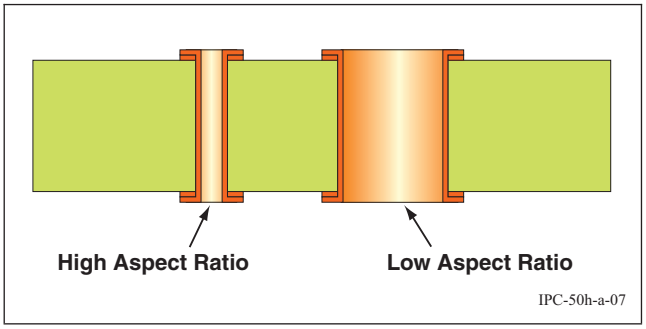
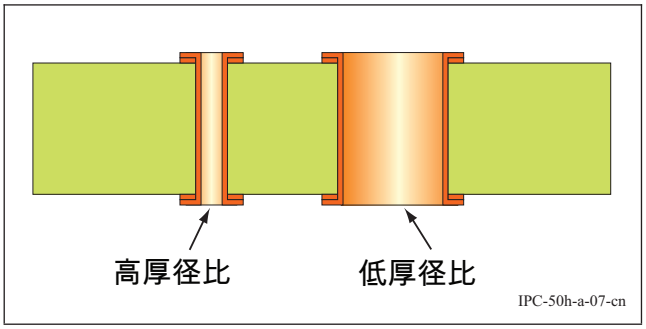


Figure A-7 Aspect Ratio (Hole)



图A-7 厚径比（孔）

Aspect Ratio (Stencil) **73.0808**

The ratio of the width of the aperture to the thickness of the stencil-foil.

宽厚比（模板） **73.0808**

模板开孔的宽度与模板厚度之比。

Assembled Board **80.0057**

See “Assembly.”

已组装板 **80.0057**

见“组装件，Assembly”。

Assembly **80.1327**

A number of parts, subassemblies or combinations thereof joined together. (Note: This term can be used in conjunction with other terms listed herein, e.g., “Printed Board Assembly.”)

组件 **80.1327**

若干部件、次级组件或其组合相互连接在一起。（注：本术语可与其他术语连用，例如：“印制板组件，Printed Board Assembly”。）

Assembly Drawing **26.1328**

A document that depicts the physical relationship of two or more parts, a combination of parts and subordinate assemblies, or a group of assemblies required to form an assembly of a higher order.

组装图 **26.1328**

描述两个或更多部件、部件和次级组装部组合、或用于形成更高等级组件所要求的一组组件的物理关系的文件。

Assembly Language **11.0058**

A computer language made up of brief expressions that an assembler program can translate into a machine language.

汇编语言 **11.0058**

能将汇编程序翻译成机器语言的简单表达式组成的计算机语言。

Assembly Manufacturer **70.1911**

The individual, organization, or company responsible for the assembly process and verification operations necessary to ensure full compliance of assemblies.

组装制造商 **70.1911**

负责组装过程及必要的检验工作，以确保产品完全符合要求的个人、组织或公司。

Assignable Cause **91.0059**

See “Special Cause.”

可查明原因 **91.0059**

见“特殊原因，Special Cause”。

Asymmetric Stripline **21.0060**

A stripline signal conductor that is embedded, but not centered, between two ground planes. (See Figure A-8.)

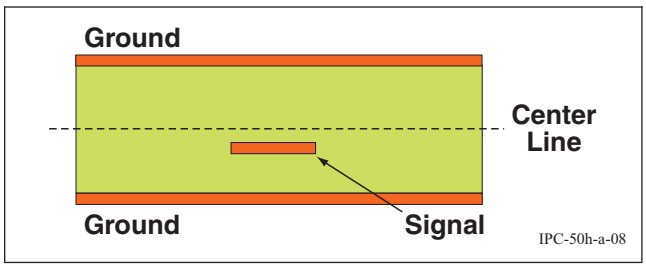


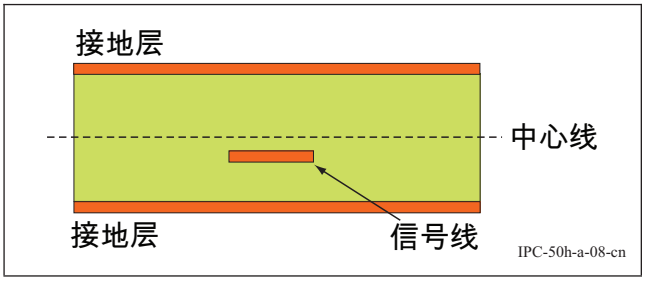
Figure A-8 Asymmetric Stripline

不对称带状线 **21.0060**

埋于两个接地层间，但不在中心的带状信号导线。（见图A-8。）

Attachment Density **22.1823**

The average number of surface mount or through-hole solder joints, based on pitch and land size, that may be accomodated in a prescribed unit area e.g., cm^2, considering land size within the unit area to accommodate solder joint attachment.



图A-8 不对称带状线

组装密度 **22.1823**

基于节距和焊盘尺寸，在规定的单位面积例如每cm^2内可容纳的表面贴装或通孔焊点的平均数量。

Attenuation **21.0061**

The reduction in the amplitude of a signal due to losses in the media through which it is transmitted. The unit of measure is decibels (dB).

衰减 **21.0061**

由于信号在传输介质中的损耗而造成信号幅度的减小。测量单位为分贝（dB）。

Attributes Data **94.0062**

Qualitative data that can be counted for recording and analysis purposes.

属性数据 **94.0062**

为了记录及分析能计数的定性数据。

Automated Component Insertion **72.0063**

The act or operation of assembling discrete components to printed boards by means of electronically-controlled equipment.

自动元器件插装 **72.0063**

通过电子控制设备将分立元器件组装到印制板的动作或操作。

Automatic Component Placement **22.0029**

Software that automatically optimizes the layout of components on a printed board.

自动元器件布局 **22.0029**

自动优化印制板上元器件布局的软件。

Automatic Conductor Routing **22.0124**

Software that automatically determines the placement of interconnections on a printed board.

自动导体布线 **22.0124**

自动确定印制板上互连布设的软件。

Automatic Dimensioning **25.1329**

A computer-aided drafting function that automatically generates dimensions, leaders, arrowheads, etc., that make up a complete set of documented dimensions.

自动尺寸标注 **25.1329**

自动生成尺寸值、引出线和箭头等，以得到完整的外形尺寸文件的计算机辅助绘图功能。

Automatic Test Equipment **92.0064**

Equipment that automatically analyzes functional or static parameters in order to evaluate performance.

自动测试设备 **92.0064**

可自动分析功能或静态参数以评价性能的设备。

Automatic Test Generation **92.0065**

Computer generation of a test program based solely on circuit topology with little or no manual programming effort.

测试自动生成 **92.0065**

基于电路捕获、网表或电路连接数据由计算机生成的，很少或没有人工编程参与，测试程序。

AWG Equivalent **92.0066**

The American Wire Gauge (AWG) round-conductor number that is used to designate a flat conductor with an equal cross-sectional area.

等效AWG **92.0066**

用于标示与扁平导线具有相同截面积的圆导线的美国线规线号。

Axial Lead **31.0067**

Lead wire extending from a component or module body along its longitudinal axis. (See Figure A-9.)

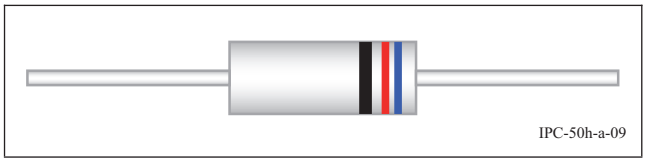
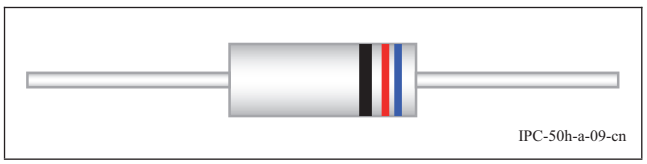


Figure A-9 Axial Lead

轴向引线 **31.0067**

沿元器件或模块体纵轴方向伸出的引线。（见图A-9。）



图A-9 轴向引线

Azeotrope **49.0068**

See “Azeotropic Mixture.”

共沸物 **49.0068**

见“共沸混合物，Azeotropic Mixture”。

Azeotropic Mixture (Azeotrope) **49.1330**

A liquid mixture of two or more substances that behaves like a single substance. The vapor produced by partial evaporization of the liquid has the same composition as the liquid.

共沸混合物（共沸物） **49.1330**

两种或多种物质的混合液体，其性质类似于单一物质。该液体部分蒸发所生成的蒸汽具有与液体相同的组份。

B

B-Stage **41.1343**

An intermediate stage in the reaction of a thermosetting resin in which the material softens when heated and swells, but does not entirely fuse or dissolve when it is in contact with certain liquids. (See also “C-Staged Resin.”)

B阶 **41.1343**

热固性树脂反应的中间阶段，在此阶段材料受热时软化和膨胀，但当与某种液体接触时并不完全融化或溶解。（又见“C阶树脂，C-Staged Resin”。）

B-Staged Material **41.0069**

See “Prepreg.”

B阶材料 **41.0069**

见“预浸材料，Prepreg”。

B-Staged Resin **41.0070**

A thermosetting resin that is in an intermediate state of cure. (See also “C-Staged Resin.”)

B阶树脂 **41.0070**

处于固化中间态的热固性树脂。（又见“C阶树脂，C-Staged Resin”。）

Back Annotation **21.0072**

The process of extracting appropriate information from a completed printed board design and inserting it on the boards schematic diagram.

反向注解 **21.0072**

从完成的印制板设计中提取适当的信息并将其插入到印制板的原理图中的过程。

Back Bonding **74.0073**

Attaching a die to a base material with its circuitry facing away from the base material. (See Figure B-1.)

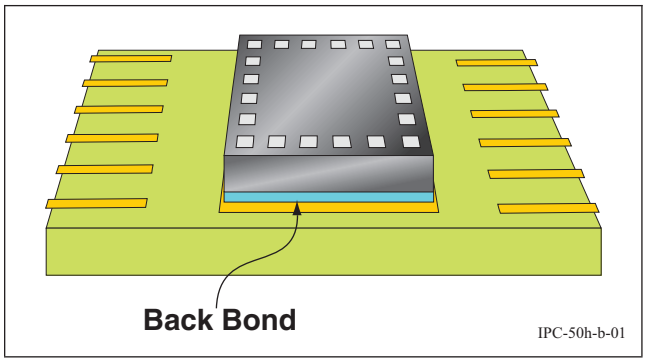
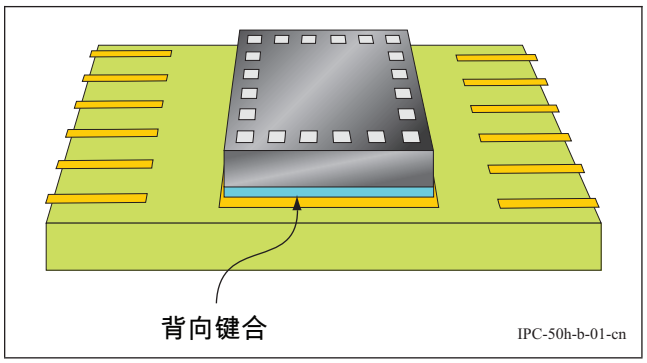


Figure B-1 Back Bonding

背向键合 **74.0073**

将晶片与基材连接，使其线路面与基材相背。（见图B-1。）



图B-1 背向键合

Back Mounting **74.0079**

See “Back Bonding.”

背向安装 **74.0079**

见“背面键合，Back Bonding”。

Back Taper(s) **51.0081**

The constant decrease in diameter along the length of the body of a drill.

倒锥 **51.0081**

直径沿钻头长度方向的持续缩小。

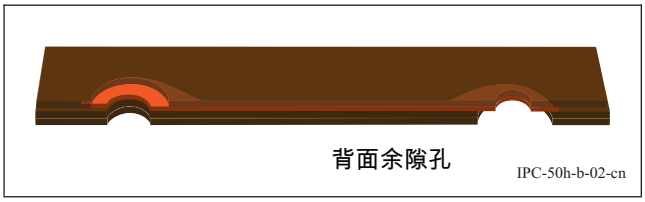
Back-Bared Land **22.0071**

A land in flexible printed wiring that has a portion of the side normally bonded to the base dielectric material exposed by a clearance hole. (See Figure B-2.)

背裸连接盘 **22.0071**

挠性印制线路中的连接盘，其与介质基材相粘接的一面有部分通过隔离孔暴露出来。（见图B-2。）

Figure B-2 Back-Bared Land



图B-2 背裸连接盘

Backdriving **92.0074**

An in-circuit testing technique that drives digital circuitry outputs to a given logic level, by supplying pulses of sufficient electrical current magnitude in parallel with the outputs, in order to overdrive the logic state conditions of the next digital device inputs.

反向驱动 **92.0074**

一种在线测试技术，它由提供与输出平行的足够大小的电流脉冲，驱动数字电路输出至规定逻辑水平，以便加速进入下一个数字输入的逻辑状态条件。

Backfill **36.0075**

Filling a hybrid circuit package with a dry inert gas prior to hermetic sealing.

回填 **36.0075**

密封前用干燥惰性气体填充混合电路。

Background (Artwork) **22.0076**

The nonfunctional area of a phototool.

背景（照相底图） **22.0076**

底版上的非功能性区域。

Background Variable **94.0077**

A parameter of no experimental interest that is not held at a constant value.

背景变量 **94.0077**

不能被控制在定值的无试验意义的参数。

Backlighting **24.0078**

Viewing or photographing by placing an object between a light source and the eye or recording medium.

背光 **24.0078**

将物体放置在光源与眼睛或记录装置间进行观察或拍照。

Backpanel **85.0080**

See “Backplane.”

背板 **85.0080**

见“底板，Backplane”。

Backplane **85.1331**

An interconnection device used to provide point-to-point electrical interconnections. (It is usually a printed board that has discrete wiring terminals on one side and connector receptacles on the other side.) (See also “Mother Board.”)

底板 **85.1331**

用于实现点到点电气互连的互连装置。（通常是一面带有分立布线端子，另一面带有连接器插座的印制板。）（又见“母板，Mother Board”。）

Backup Pin **70.0972**

A supporting pin that is located under a printed board to prevent deflection of the board during component mounting.

支撑销 **70.0972**

位于印制板下防止板在元器件贴装过程中挠曲的支承销钉。

Backward Crosstalk **21.1332**

Noise induced into a quiet line, as seen at the end of the quiet line that is closest to the signal source, because the quiet line has been placed next to an active line. (See also “Forward Crosstalk.”)

反向串扰 **21.1332**

在离信号源最近的无噪音导线末端感应进入的噪声，因为它被放置在工作线路的后面。（又见“正向串扰，Forward Crosstalk”。）

Bake Out **56.0082**

Subjecting a product to an elevated temperature in order to remove moisture and unwanted gasses prior to certain steps in the printed board manufacturing process or prior to final coating.

烘除 **56.0082**

在印制板制作工艺某一步骤或最终涂覆前，使产品经受高温以去除湿气及不需要的气体。

Balanced Transmission Line **21.1333**

A transmission line that has distributed inductance, capacitance, resistance, and conductance elements that are equally distributed between its conductors.

平衡传输线 **21.1333**

在其导线之间均匀分布有电感、电容、电阻和电导元器件的一种传输线。

Ball **34.0976**

A raised metal, (or other conductive material) feature on a package substrate used to facilitate bonding to the next level of interconnect.

焊球 **34.0976**

为便于与下一级互连连接而置于封装基板上的凸起金属（或其它导电材料）。

Ball Array **34.1086**

A group of balls arranged in rows and columns.

球阵列 **34.1086**

成行及成列排列的一组焊球。

Ball Bond **74.0083**

The welded connection of a bond wire to the bond pad of an integrated circuit die. The bond wire is melted to form a ball and the ball is bonded by use of thermocompression or thermosonic techniques.

球形键合 **74.0083**

键合引线至集成电路晶片上键合焊盘的焊接连接。键合引线融熔成为焊球，再应用热压焊及热超声焊技术键接焊球。

Ball Grid Array (BGA) **34.1096**

A surface mount package wherein the bumps for terminations are formed in a grid on the bottom of a package. (See Figure B-3.)

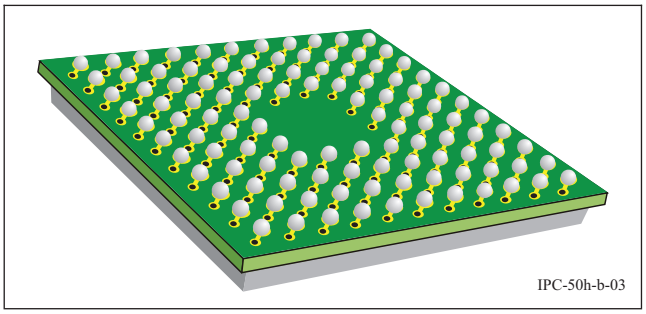


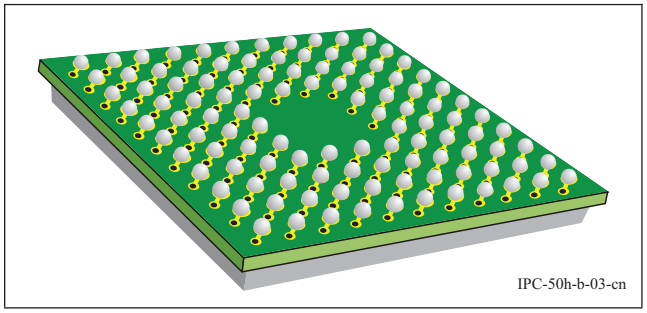
Figure B-3 Ball Grid Array (BGA)

球栅阵列（BGA） **34.1096**

端子凸缘以栅格形式排列于封装底部的表面贴装封装。（见图B-3。）

Ball Lift **74.2127**

A category of ball bond failure in which the ball lifts from the surface of the integrated circuit die bond pad metallization or lifts the metallization from the surface of the underlying oxide or silicon.



图B-3 球栅阵列（BGA）

焊球起翘 **74.2127**

焊球键合失效的一种，焊球从集成电路晶片键合焊金属化层表面起翘或金属化层从氧化基层或硅片表面起翘。

Bar **70.1238**

The dark element of a bar code.

条 **70.1238**

条码中的黑色单元。

Bar Code **70.1292**

A linear arrangement of bars and spaces in a predetermined pattern.

条码 **70.1292**

以预先确定的样式，呈直线型排列的条和空。

Bar Code Marking **70.1731**

An identification code consisting of a pattern of vertical bars whose width and spacing identifies the item marked.

条码标识 **70.1731**

由竖条图形组成的标识码，以其宽度和间隔识别所标识的项目。

Bar Code Printer **70.1353**

A printer with the ability to print bar coded labels and forms.

条码打印机 **70.1353**

能打印条码标签和格式的打印机。

Bar Code Scanner/Reader **70.1354**

A device used for machine reading of a bar code. Readers may be hand held-wands, fixed optical beams, or moving optical beams.

条码扫描器/识别器 **70.1354**

用于机读条码的装置。识读器可以是手动扫描笔、固定光束或移动光束。

Bar Code Symbol **70.1370**
A printed or photographically reproduced bar code composed of parallel bars and spaces of various widths. A bar code symbol contains a leading quiet zone, a start character, data characters, a stop character, and a trailing quiet zone. In some cases, a check character is included.

条码符号 **70.1370**
由不同宽度的平行条和空组成的，可以通过打印或照相技术复制的条码。一个条码符号包括引导空白区、起始符、数据符、终止符和尾部空白区。有时，也包括校验符。

Bare Board **60.0084**
An unassembled (unpopulated) printed board.

裸板 **60.0084**
未组装的（未装元器件的）印制板。

Barrel Crack **96.1444**
A crack of the plated metal on the internal wall of a through-hole. (See also “Circumferential Crack.”) (See Figure B-4.)

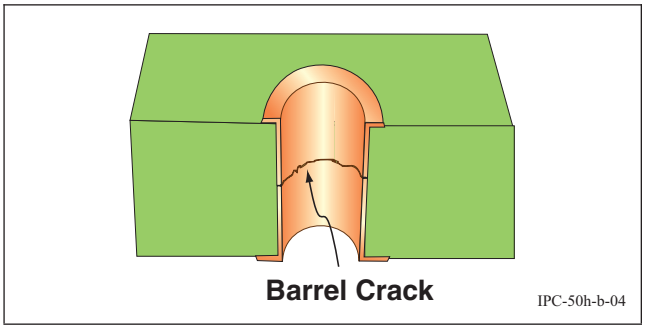
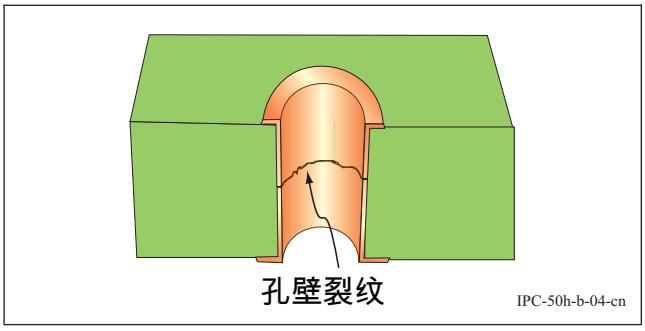


Figure B-4 Barrel Crack

孔壁裂纹 **96.1444**
通孔内壁上镀层金属的裂纹。（又见“环状裂纹，Circumferential Crack”。）（见图B-4。）



B-4 孔壁裂纹

Barrier Metal **74.0085**
A metal used to seal the semiconductor-die lands.

隔离金属 **74.0085**
用于密封半导体芯片连接盘的金属。

Base Film (Flexible Circuits) **40.1471**
The film that is the base material for the flexible printed board and on the surface of which the conductive pattern can be formed. When the heat resistance is required, polyimide film is mostly used, and polyester film is usually used when the heat resistance is not required.

基膜（挠性电路） **40.1471**
用于挠性线路板基材的膜，可在其表面形成导电图形。要求其耐热时，大多采用聚酰亚胺膜，聚酯膜则通常用于无耐热要求时。

Base Material **40.1334**
The insulating material upon which a conductive pattern may be formed. (The base material may be rigid or flexible, or both. It may be a dielectric or insulated metal sheet.)

基材 **40.1334**
可在其上面形成导电图形的绝缘材料。（基材可以是刚性或挠性的，或者兼是。它可以是电介质或者是绝缘的金属板。）

Base Material Thickness **22.1604**
The thickness of the base material excluding conductive foil or material deposited on the surfaces.

基材厚度 **22.1604**
不包括导电箔或表面上所沉积材料的基材厚度。

Base Metal **45.0088**
See “Basis Metal.”

基体金属 **45.0088**
见“金属基材，Basis Metal。”

Base Metal (Solder) **46.1491**
The underlying metal surface to be wetted by solder, also referred to as basis metal.

基体金属（焊料） **46.1491**
被焊料润湿的下层金属表面，也称为金属基材。

Base Plane **30.2011**
The plane that includes the lowest point of the mounting surface of the package, except for packages using stand-offs.

基底面 **30.2011**
包括封装件贴装表面最低点的平面，采用托高的封装件除外。

Base Solderability **92.0089**
The ease with which a metal or metal alloy surface can be wetted by molten solder under minimum realistic conditions.

基本可焊性 **92.0089**

金属或金属合金在最小实现条件下能被熔融的焊料浸润的容易程度。

Baseline Dimensioning **26.0086**

The maximum variation between two features that is equal to the sum of the tolerances on the two feature location dimensions taken from the same origin. (See Figure B-5.)

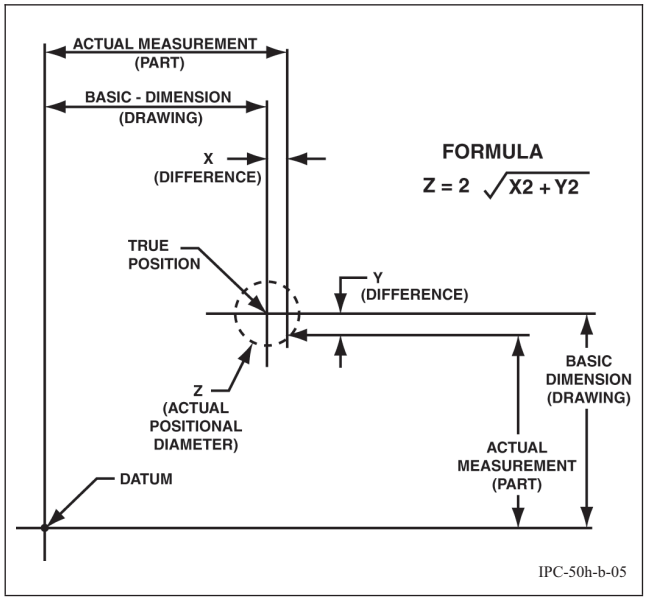
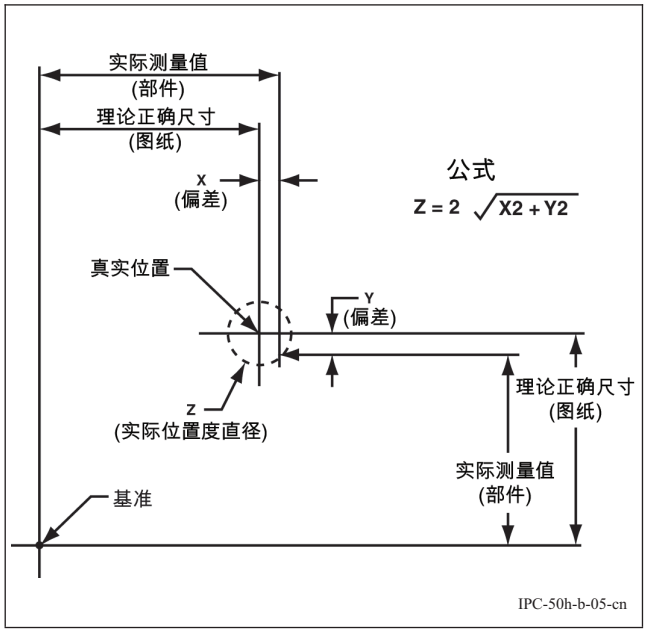


Figure B-5 Example of Feature Location using Baseline Dimensions

基线尺寸标注 **26.0086**

两个要素间的最大变化范围，等于相对于同一原点的两个位置尺寸的最大公差之和。（见图B-5。）



图B-5 使用基线尺寸的要素位置示例

Basic Dimension **26.1335**

A numerical value used to describe the theoretical exact location of a feature or hole. (It is the basis from which permissible variations are established by tolerance on other dimensions in notes or by feature control symbols.)

理论正确尺寸 **26.1335**

用于描述一个要素或孔理论上正确位置的数值。（它是由其它尺寸上标注的公差或由特征控制符确定的允许偏差的基础。）

Basic Specification (BS) **26.1778**

A document that describes the common elements for a set, family or group of products, materials, or services.

基础规范（BS） **26.1778**

描述一套、一族或一组产品、材料或服务的通用要素的文件。

Basic Statistical Method **91.1336**

The application of a theory of variation through the use of basic problem-solving techniques and statistical process control. (This includes control and capability analysis for both variables and attributes data.)

基本统计方法 **91.1336**

使用基本问题解决方法和统计过程控制实施变异分析。（包括对变量数据和属性数据的控制能力和能力分析。）

Basic Wettability **70.0090**

The ease with which a metal or metal alloy can be wetted by molten solder.

基本润湿性 **70.0090**

金属或金属合金能够被熔融的焊料润湿的容易程度。

Basis Material **40.0091**

Material upon which coatings are deposited.

基体材料 **40.0091**

可在其上面沉积涂覆层的材料。

Basis Metal **45.0092**

A metal upon which coatings are deposited.

金属基材 **45.0092**

可在其上面沉积涂覆层的金属。

Batch Oven **56.0093**

A temperature-controlled oven used for drying, baking, curing, etc. where the material being processed is stationary.

成批烘炉 **56.0093**

用于干燥、烘烤、固化等的温控炉, 炉中被处理的材料是静止的。

Batch Processing **11.0094**

Executing a computer-aided program without human input.

批处理 **11.0094**

执行计算机辅助程序，无需人工输入。

Batch Size **17.0095**

See “Lot Size.”

批量 **17.0095**

见“批量，Lot Size”。

Bathtub Curve **93.0096**

A plot of failures versus time. (See Figure B-6.)

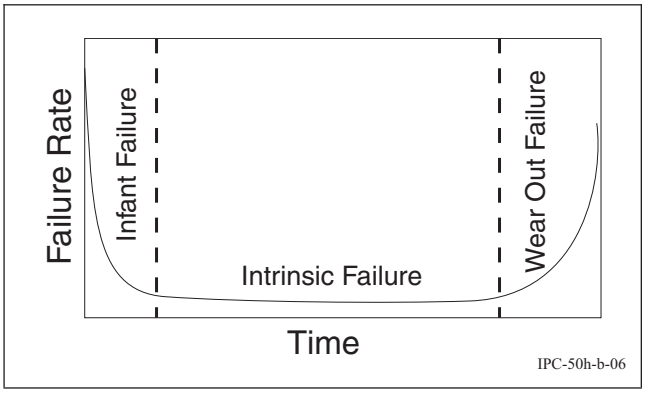
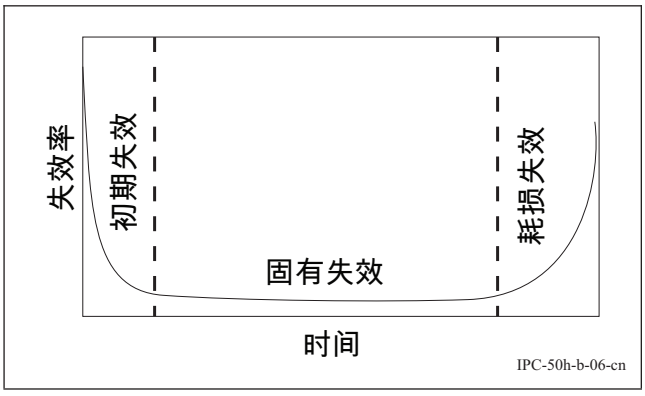


Figure B-6 Bathtub Curve

浴盆曲线 **93.0096**

失效与时间关系的曲线图。（见图B-6。）



图B-6 浴盆曲线

Baume **92.0097**

An arbitrary scale of specific gravities used in the gradation of hydrometers.

波美度 **92.0097**

用于液体比重计分度的一种比重刻度。

Bead (Discrete Wiring) **64.1555**

The external (surface) annular ring of copper plating around a plated-through hole on a fully additive circuit board which functions to conduct heat and promote solder wicking during the soldering of components.

铜圈（分立布线） **64.1555**

全加成电路板上环绕镀覆孔铜镀层的外层（表面）孔环，其功能是在元器件焊接期间导热和促进焊料芯吸。

Beam Lead **33.0100**

A component terminal in the form of a long metallic structural member that is not supported along its length.

梁式引线 **33.0100**

一种元器件引出端子，其形式是整个长度方向无支撑的长金属构件。

Beaming **44.0099**

The operation in which yarn from several section beams is combined on the final warp beam.

并轴 **44.0099**

将很多束成段的纱线结合成最终成卷线束的操作。

Beam-Lead Device **33.0098**

An active or passive chip component with beam leads for interconnecting it to lands on a base material. (See Figure B-7.)

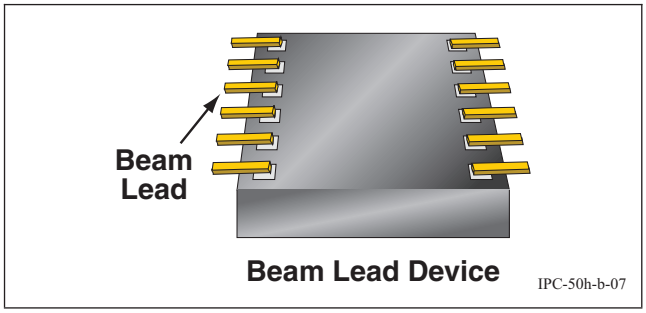


Figure B-7 Beam-Lead Device

梁式引线器件 **33.0098**

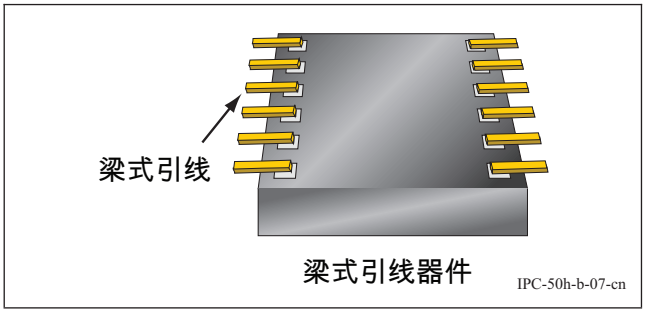
带有用于连接基材焊盘的梁式引线的主动（有源）或被动（无源）片式元器件。（见图B-7。）

Bed-of-Nails Fixture **92.0101**

A test fixture consisting of a frame and a holder containing a field of spring-loaded pins that make electrical contact with a planar test object.

针床夹具 **92.0101**

由框架及包含弹簧针区域的支架组成，用于与平面测试对象进行电接触的测试夹具。



图B-7 梁式引线器件

Bellows Contact **36.1337**

A type of a connector contact that consists of a flat spring that has been folded to provide a very uniform spring rate over the full tolerance range of the mating part.

扁簧接触件 **36.1337**

一种由弯折的扁平弹簧组成的连接器接触件，在配接零件的公差范围内提供均匀回弹率。

Benchmark, Computer **11.0102**

A standard measure of the performance of computers relative to each other, including set-up time, program generation, and data processing capability.

计算机基准 **11.0102**

计算机性能相互比较的一种量度标准，包括安装时间、程序生成及数据处理能力。

Benchmark, Testing **92.0103**

A standard measure of the performance of testers relative to each other, including set-up time, test program generation, and fixturing.

测试基准 **92.0103**

测试设备功能相互比较的一种量度标准，包括安装时间，测试程序生成及定位。

Bending Resistance **92.1565**

The ability of a material to withstand repeated bending to specified parameters without producing cracks and breaks in excess of the specification allowance.

耐弯曲性 **92.1565**

材料耐受重复弯曲至规定参数，而未产生超过规范允许的裂纹或断裂的能力。

Beta Error **91.0104**

The size of a Type II error or the probability of accepting a hypothesis that is false.

β错误 **91.0104**

第二种类型的错误，或原假设不真但被接收的概率。

Bias (Fabric) **44.0105**

Filling yarn that is off-square with the warp ends of a fabric.

纬斜（织物） **44.0105**

织物上的纬纱倾斜，不与经纱相垂直。

Bifurcated Contact **36.1810**

A type of connector contact that usually consists of a flat spring that has been slotted length-wise in order to provide independent contact points with the mating part.

双叉接触件 **36.1810**

连接器接触件的一种，通常由一片长度方向开槽的扁平弹簧组成，为配接件提供独立的接触点。

Bifurcated Solder Terminal **37.0106**

A solder terminal with a slot or slit opening through which one or more wires are placed prior to soldering. (See Figure B-8.)

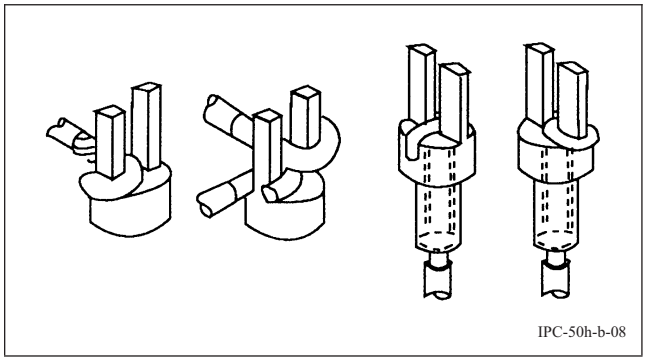
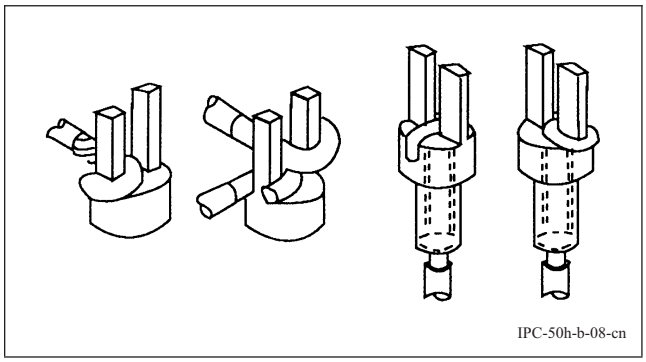


Figure B-8 Bifurcated Solder Terminal

双叉焊接接线柱 **37.0106**

有槽或狭长开口的焊接接线柱，焊接前一根或多根导线可以穿入其中。（见图 B-8。）



图B-8 双叉焊接接线柱

Bilateral Tolerance **26.1572**

A tolerance in which variation is permitted in both directions from the specified dimension.

双向公差 **26.1572**

以指定尺寸为基准允许向两个方向变异的公差。

Binder **47.0107**

Material added to thick-film compositions and unfired base materials to give them additional strength for pre-fire handling. (See also “Glass Binder.”)

粘结剂 **47.0107**

添加在厚膜组分和未烧结基材中的材料，以增加烧结前处置时的强度。（又见“玻璃粘合剂，Glass Binder”。）

Binomial Distribution **94.0108**

A discrete probability distribution that, with certain assumptions, describes the variation of an attribute (proportion).

二项分布 **94.0108**

在某种假定下描述一个属性（比例）变化的离散型概率分布。

Biochemical Oxygen Demand **92.0109**

A standardized measure used for estimating the degree of contamination of water.

生化需氧量 **92.0109**

用来估算水受到污染程度的一种标准化量度。

Biocide **76.0110**

A general name for any substance that kills or inhibits the growth of micro-organisms.

生物杀伤剂 **76.0110**

任何能杀死或抑制微生物生长的物质的统称。

Bipolar Device **33.1573**

A device in which both majority and minority carriers are present. Bi-polar and Metal-Oxide Semi-conductor (MOS) are the two most common device types.

双极器件 **33.1573**

一种（半导体）器件，其中既有少数质流子又有多数质流子。双极和金属氧化物半导体（MOS）是两种最常见的器件类型。

Birdcage **37.1338**

Stranded wire whereby the strands in the stripped portion between the covering of an insulated wire and a soldered connection, or an end-tinned lead, have separated from the normal lay of the strands.

呈鸟笼状散开的导线 **37.1338**

在绝缘皮覆盖部分与焊接端或上锡引线之间被剥除绝缘皮部分的股线，已经松散而无法保持多股线的原状。

Bismaleimide **41.0111**

A resin that has the generic chemical structure of an aromatic chemical group that is attached to two (or “Bis”) maleimide groups.

双马来酰亚胺 **41.0111**

具有连接两个（双）马来酰亚胺基的芳烃化学基团化学结构的树脂。

Bismaleimide Triazine **41.0112**

A resin that contains a mixture of bismaleimide and triazine resins.

双马来酰亚胺三嗪 **41.0112**

由双马来酰亚胺和三嗪树脂混合组成的树脂。

Blank **41.1339**

An unprocessed or partially processed piece of base material or metal clad base material, that has been cut from a sheet or panel, that has the rough dimensions of a printed board. (See also “Panel.”)

料板 **41.1339**

从整张基材或在制板上剪裁下来未经加工或部分加工过的基材或覆金属箔基材，其尺寸与印制板相近。（又见“在制板，Panel”。）

Blanking **51.1574**

Cutting a sheet of material into pieces to the specified blank design.

开料 **51.1574**

将一张材料剪裁成指定大小的料板。

Bleeding **52.0113**

A condition in which a plated hole discharges process material or solution from crevices or voids or a condition in which a resist migrates beyond the image area.

渗出 **52.0113**

从金属化孔的裂缝或空洞排出工艺材料或溶液的现象，或是阻焊剂从成像区域边缘扩散的现象。

Blends **41.0114**

Mixtures of resins.

混合物 **41.0114**

树脂的混合物。

Blind Via **22.0115**

A via extending only to one surface of a printed board. (See Figure B-9.)

盲孔 **22.0115**

只延伸至印制板一个表面的导通孔。（见图B-9。）

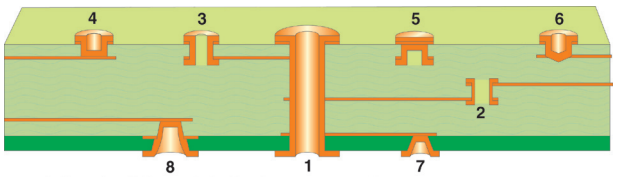
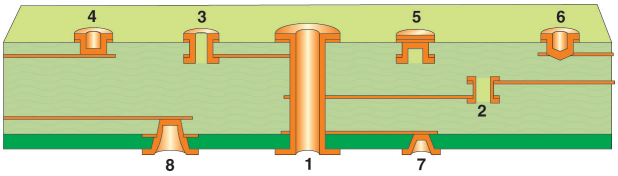


Figure B-9 Blind and Buried Vias



图B-9 盲孔和埋孔

Blister **96.1340**

Delamination in the form of a localized swelling and separation between any of the layers of a laminated base material, or between base material and conductive foil or protective coating, or solder mask.

起泡 **96.1340**

表现为层压板基材的层与层之间、或基材与导电箔或基材与保护涂层、基材与阻焊膜之间的局部膨胀和分离形式的分层。

Blocking Variables **94.0116**

A relatively-homogeneous set of conditions within which different conditions of primary variables are compared.

分组变量 **94.0116**

一组相对均一的条件，不同条件的初始变量可以在其间进行比较。

Blow Hole **53.0117**

A void caused by outgassing.

气孔 **53.0117**

由排气而产生的空洞。

Board **60.0118**

See “Printed Board,” and “Multilayer Printed Board.”

板 **60.0118**

见“印制板，Printed Board”和“多层印制板，Multilayer Printed Board”。

Board Fabricator **50.1912**

The individual, organization, or company responsible for the fabrication of the bare printed board, including all process and verification operations necessary to ensure full compliance with customer requirements.

印制板制造商 **50.1912**

负责制作裸印制板的个人、组织或公司，制作包括确保完全符合用户要求所必须的全部过程和验证的运作。

Board Thickness **41.1583**

The thickness of the metal-clad base material or printed board including the conductive layer.

板厚 **41.1583**

包括导电层的覆金属箔基材或印制线路板的厚度。

Body Land Clearance **51.1341**

That portion of the land diameter of a drill that is decreased in order to provide clearance behind the margin. (See Figure B-10, Feature K.)

钻体刃带间隙 **51.1341**

为刃带背面留出间隙的钻瓣直径的缩小部分。（见图B-10，“Feature K，要素K。）

Bond **74.0120**

An interconnection that performs a permanent electrical and/or mechanical function.

键合 **74.0120**

实现永久性的电气和（或）机械功能的互连。

Bond Deformation **74.0123**

The plastic-flow change in the form of a lead caused by a bonding tool during a termination process.

键合变形 **74.0123**

在端接过程中，由键合工具引起的引线形状的塑性流动变形。

Bond Enhancement Treatment **74.0125**

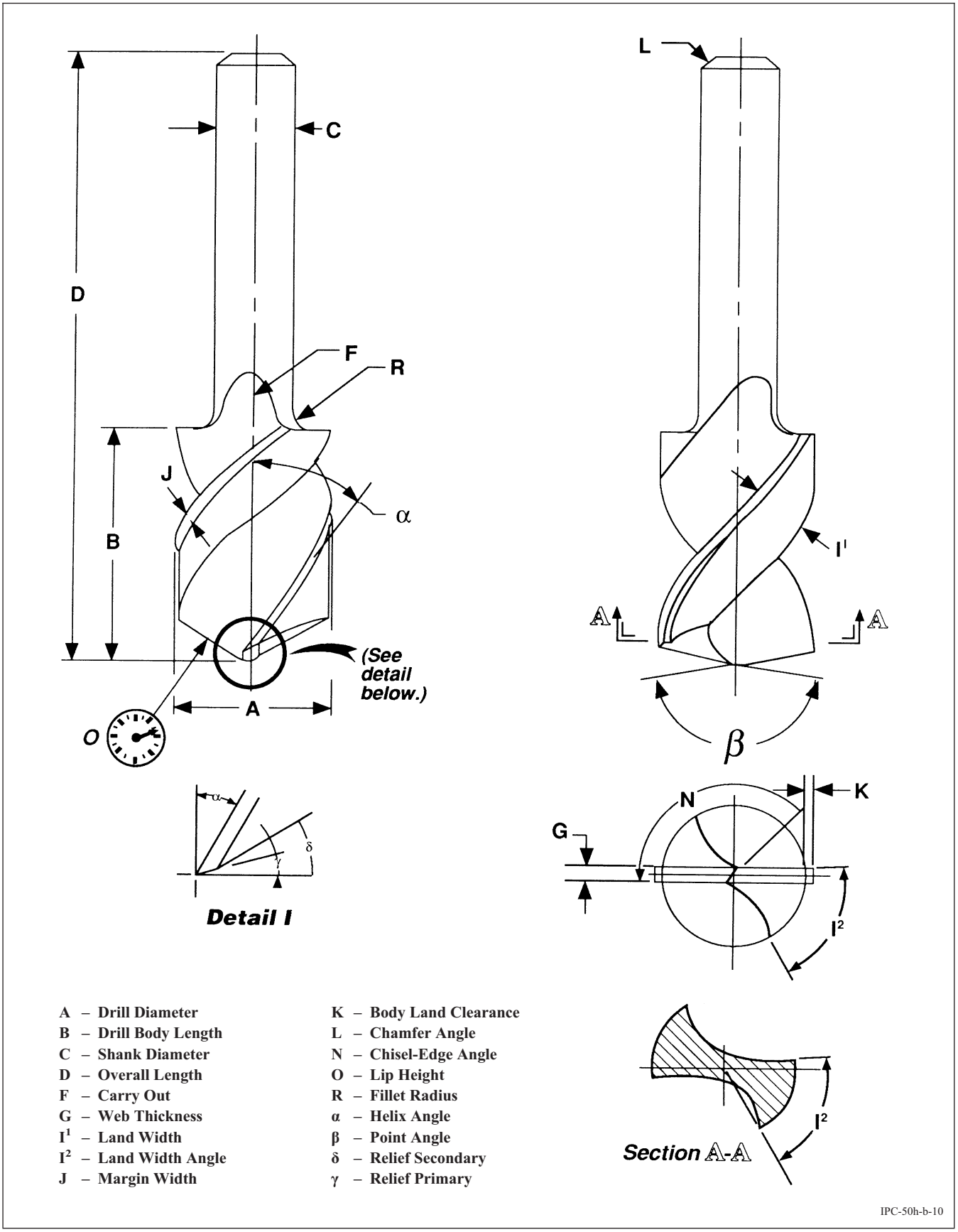
The improvement of the adhesion of a metal foil surface to an adjacent layer of material to which it is being attached.

粘合增强处理 **74.0125**

改善金属箔表面与它所附着的相邻材料层之间粘合力的处理。

Bond Envelope **74.0126**

The range of termination parameters within which acceptable bonds may be formed.



A – Drill Diameter
B – Drill Body Length
C – Shank Diameter
D – Overall Length
F – Carry Out
G – Web Thickness
I^1 – Land Width
I^2 – Land Width Angle
J – Margin Width
K – Body Land Clearance
L – Chamfer Angle
N – Chisel-Edge Angle
O – Lip Height
R – Fillet Radius
α – Helix Angle
β – Point Angle
δ – Relief Secondary
γ – Relief Primary

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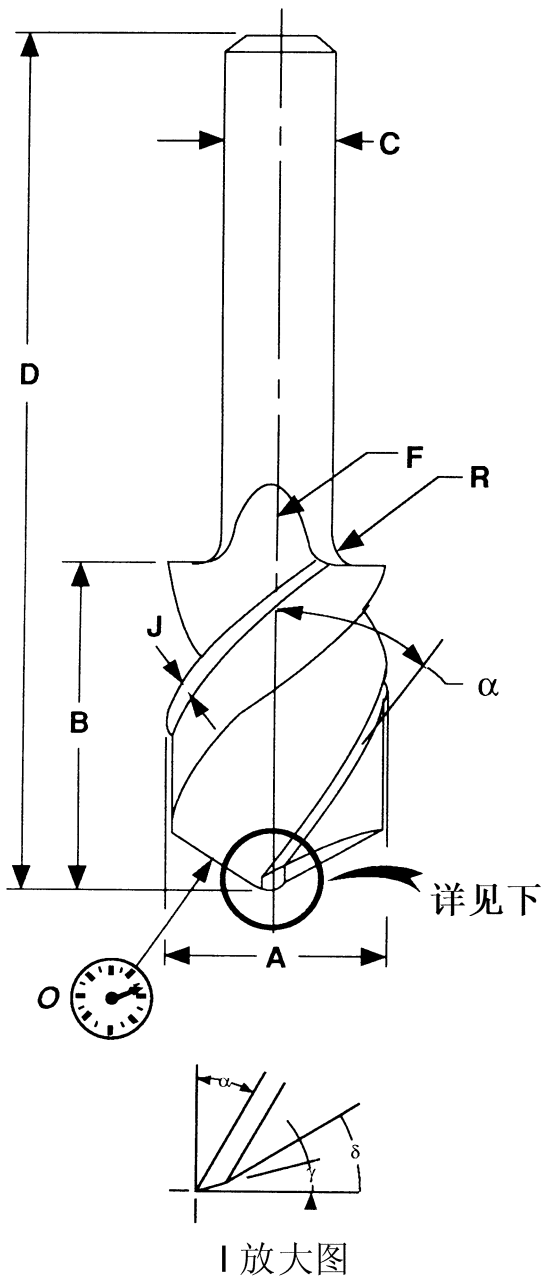
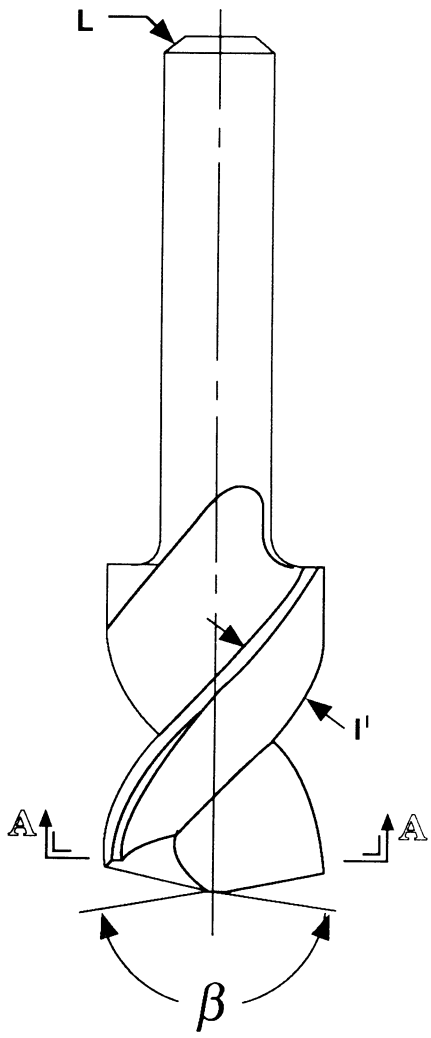
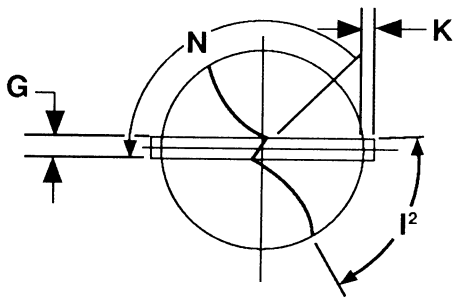
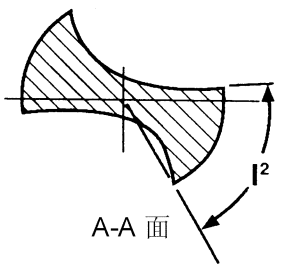
Figure B-10 Drill Features









A	钻头直径	K	钻体间隙
B	钻体长度	L	倒角
C	钻柄直径	N	横刃角
D	总长	O	刃缘高度
F	排屑口	R	接缝半径
G	钻芯厚度	α	螺旋角
I^1	刃带宽度	β	顶角
I^2	刃带宽度角	δ	第二后角
J	棱边宽度	γ	第一后角

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图B-10 钻头要素

键合参数限 **74.0126**
形成可接受键合的端接参数范围。

Bond Interface **74.0133**
The common area between a lead and a land to which it has been terminated.

键合界面 **74.0133**
引线与被端接连接盘之间的公共区域。

Bond Land **74.0134**
See “Bonding Area.”

键合连接盘 **74.0134**
见“键合区，Bonding Area”。

Bond Lift-Off **74.0135**
The failure mode whereby a bonded lead separates from the surface to which it has been joined.

键合脱离 **74.0135**
被键合引线从其相连接的表面分离的失效模式。

Bond Schedule **74.0136**
The values of termination machine parameters.

键合参数表 **74.0136**
键合机的参数值。

Bond Separation **74.0137**
The distance between the termination points of the first bond and the second bond.

键合间隔 **74.0137**
第一键合点和第二键合点之间的距离。

Bond Site **74.0138**
That portion of the bonding area where the actual termination takes place.

键合位置 **74.0138**
键合区内实际发生端接的部分。

Bond Strength **60.0139**
The force perpendicular to a board’s surface required to separate two adjacent layers of the board, expressed as force per unit area.

粘合强度 **60.0139**
使印制板的两个相邻层分开时所需要的垂直于板面的力，以单位面积力来表示。

Bond Surface **74.0141**
See “Bonding Area.”

键合面 **74.0141**
见“键合区，Bonding Area”。

Bond-to-Bond Distance **74.0121**
The distance from the bonding site on a die to the corresponding bonding site on a lead frame, interconnecting base material, etc.

键合间距离 **74.0121**
从芯片上的键合位置到引线框、互连基材上相应的键合位置间的距离。

Bond-to-Die Distance **74.0122**
The distance from the heel of a beam lead to the die.

芯片键合距离 **74.0122**
从梁式引线的跟部到芯片的距离。

Bondability **74.1342**
Those surface characteristics and conditions of cleanliness of a bonding area that must exist in order to provide for the capability to achieve a successful termination.

可键合性 **74.1342**
为提供有效端接能力，一个键合区所必需的表面特性及清洁度状况。

Bonding Area **74.0128**
The area defined by the extent of a land or portion of a terminal to which a lead is to be bonded.

键合区 **74.0128**
由连接盘范围或端子部分与引线被键合的确定的区域。

Bonding, Die **74.0127**
See “Die Bonding.”

芯片键合 **74.0127**
见“芯片键合，Die Bonding”。

Bonding Island **74.0129**
See “Bonding Area.”

键合岛 **74.0129**
见“键合区，Bonding Area”。

Bonding Layer **55.0130**
An adhesive layer used in bonding together other discrete layers of a multilayer printed board during lamination.

粘接层 **55.0130**
层压时，用于将多层印制板各分离层粘结在一起的粘合层。

Bonding Pad (IC) **33.1585**
An area of metallization on an integrated circuit die that permit connection of fine wires or circuit element to the die.

键合盘（IC） **33.1585**
在集成电路晶片上的一块金属化区域，可实现细金属线或电路元器件与晶片的连接。

Bonding Time **70.1586**
The time duration from the commencement of thermo heat-up until the reflow profile is completed.

键合时间 **70.1586**
从开始加热到再流曲线完成的时间段。

Bonding Tool **74.0131**
The instrument used to position leads or discrete wires over a land and to impart sufficient energy to complete the termination.

键合工具 **74.0131**
用于将引线或分立金属线定位在连接盘上并给予足够能量来完成端接的工具。

Bonding Wire **74.0132**
Fine gold or aluminum wire used for making electrical connections between lands, lead frames, and terminals.

键合金属线 **74.0132**
用于在连接盘、引线框架、端子之间形成电气连接的细金丝或铝丝。

Border Area **22.0142**
The region on a base material that is external to that of the end-product being fabricated within it.

边沿区 **22.0142**
被制作的最终产品以外的基材区域。

Border Data **22.0143**
Patterns that appear in the border area, such as tooling features, test patterns, and registration marks.

边沿数据 **22.0143**
出现在边沿区的图形，例如定位要素、测试图形及对准标记。

Boss **22.0144**
See “Land.”

凸台 **22.0144**
见“连接盘，Land”。

Boss (Connector) **37.0145**
A raised section on a connector that fits into a specific slot in the positive polarization or keying feature of a mating connector.

凸台（连接器） **37.0145**
连接器上的突起部分，可装入配接连接器的定位极性或键控装置内的特定槽中。

Bounce Pad (Discrete Wiring) **64.1588**
An isolated area in a copper plane which acts solely as a stop for the laser drilling operation.

反弹盘（分立布线） **64.1588**
铜层上仅用于阻止激光钻孔操作的独立区域。

Bow (Fabric) **44.0146**
Filling yarn that lies in an arc across the width of a fabric.

弓纬（织物） **44.0146**
纬纱沿织物宽度方向呈现弧形。

Bow (Sheet, Panel, or Printed Board) **60.1218**
The deviation from flatness of a board characterized by a roughly cylindrical or spherical curvature such that, if the product is rectangular, its four corners are in the same plane. (See Figure B-11.) (See also “Twist.”)

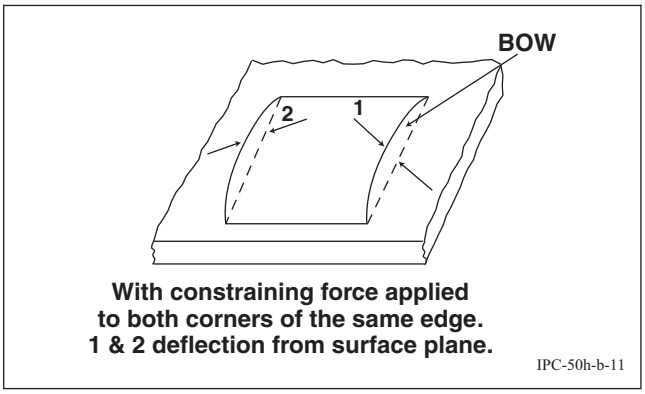
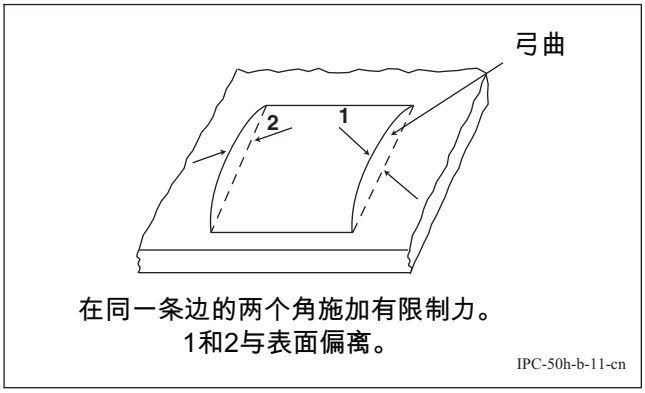


Figure B-11 Bow

弓曲（整板、在制板或印制板） **60.1218**
板子相对于平面的一种形变，可近似地用圆柱形或球面形曲率来表示。如果产品为矩形，板角四点落在一个平面上。（见图B-11。）（又见“扭曲，Twist”。）

Brainstorming **94.0147**
The generation of an all-inclusive list of potential causal factors that are possible contributors to process problems.

头脑风暴法 **94.0147**
列出可能有助于分析过程问题的所有潜在影响因素清单的过程。



图B-11 弓曲

Breakaway **54.1589**

The function of excising printed boards or printed board assemblies from their panel structure after all processing has been completed. (See Figure B-12.)

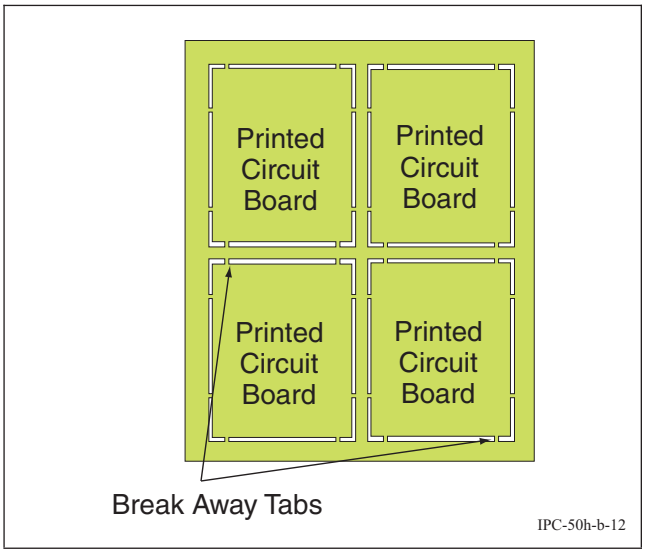


Figure B-12 Breakaway

分离 **54.1589**

在全部制程完成后，将印制板或印制板组件从在制板上分开的功能。（见图B-12。）

Breakout **60.0148**

See “Hole Breakout.”

破出 **60.0148**

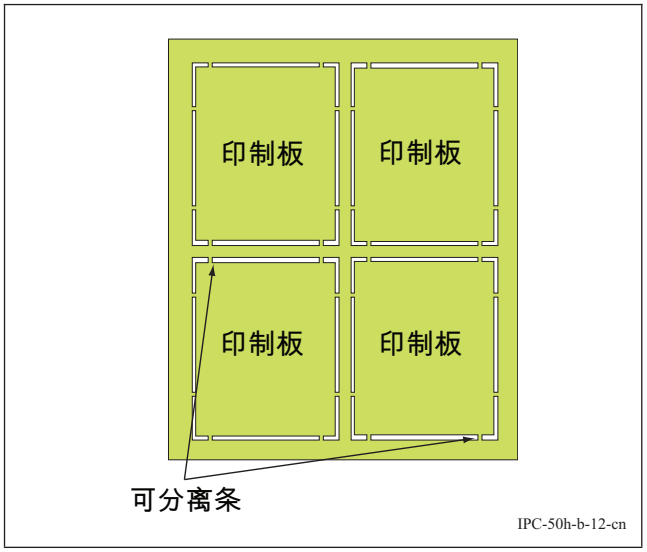
见“孔破出，Hole Breakout”。

Bridging, Electrical **70.0149**

The unintentional formation of a conductive path between conductors. (See also “Solder Bridging.”)

电气桥接 **70.0149**

导线之间形成的不应有导电通路。（又见“焊料桥接，Solder Bridging”。）



图B-12 分离

Brightness **24.0150**

See “Luminance.”

光亮度 **24.0150**

见“亮度，Luminance”。

Broken Pick **35.0151**

A filling yarn that is missing from a portion of the width of a fabric.

断纬 **35.0151**

织物宽度部分缺少纬纱。

Brominated Epoxy **41.0152**

An epoxy resin containing chemically-bound bromine which is added to act as a flame retardant.

溴化环氧树脂 **41.0152**

添加了化合溴作为阻燃剂的环氧树脂。

Brown Streak (Base Materials) **40.1590**

A thin vein or stain seen in the reinforcement that can range from light amber to nearly chocolate brown. It usually runs within a fiber bundle for 3 to 13 mm [0.13 to 0.512 in]. It is most commonly found in the warp yarns and may appear singly or in multiples, or in a pattern. It is due to the remnants of the glass binder agent, which the weaver did not remove.

棕色条纹（基材） **40.1590**

增强材料上可以看见的细条纹或瑕疵。颜色范围从淡黄色到巧克力色，通常出现在纤维束中3mm到13mm [0.13in到0.512in]之间。往往以单个，或多个，或图案出现于经纱方向。它是由于玻璃粘合剂的残余物未被清除干净引起的。

Brown Thread (Base Materials) **40.1591**
See “Brown Streak.”

棕色丝（基材） **40.1591**
见“棕色条纹，Brown Streak”。

Bubble Effect **76.0153**
The entrapment of air, solvent or moisture bubbles in a protective coating.

气泡效应 **76.0153**
指夹留在保护涂层内的空气、溶剂或湿气气泡。

Buffer Material **76.0154**
A resilient material that is used to protect a crack-sensitive component from the stresses generated by a conformal coating.

缓冲材料 **76.0154**
一种弹性材料，用来保护易开裂元器件免受由敷形涂覆所产生的应力。

Bugging Height **74.0155**
The distance between a land and the lower surface of a beam lead caused by the deformation of the lead during bonding.

障碍高度 **74.0155**
由于键合时引线变形，造成的连接盘与梁式引线下表面之间的距离。

Build-up Process **61.1593**
See “Sequential Lamination.”

积层工艺 **61.1593**
见“顺序层压，Sequential Lamination”。

Bulge **60.0156**
A swelling of a printed board that is usually caused by internal delamination or separation of fibers.

凸起 **60.0156**
由于内部分层或纤维分离而造成印制板隆起的现象。

Bulk Conductance **92.0157**
Conductance between two points of a homogeneous material.

体积电导 **92.0157**
匀质材料两个点之间的电导。

Bulls-Eye **20.0158**
A stylized pattern that is located in the border area in order to aid in alignment.

靶心 **20.0158**
位于边缘区的一种特定图形，用以帮助对准。

Bulk Packaging **30.1596**
A method for packaging loose parts, into a bag or case.

散装 **30.1596**
将散乱的零件装在一个袋子或盒子内的方法。

Bulk Reflow **75.1597**
Reflow of multiple components, with simultaneous attachment, by an infrared (IR), convection/IR, convection, or vapor phase reflow (VPR) process.

批量再流焊 **75.1597**
通过红外、对流/红外、对流或气相再流工艺，对多个元器件同时进行再流焊连接。

Bump **34.1598**
A means of providing a (electrical) connection to the terminal area of a device. A small mound is formed on the device or substrate pads and is used as a contact for face-down loading.

凸点 **34.1598**
一种为器件的端接区提供（电）连接的方法。在器件上或基板焊垫上形成小垛，用作面向下负载的接触点。

Bump (Die) **74.0159**
A raised metal feature on a die land or tape carrier tape that facilitates inner-lead bonding.

凸点（芯片） **74.0159**
芯片连接盘或载带上的金属突起部分，以便进行内引线键合。

Bump Array **34.1599**
A group of bumps arranged in rows and columns.

凸点阵列 **34.1599**
一组成行成列排布的凸点。

Bump Contact **34.1601**
A contacting pad that rises substantially above the surface level of the chip.

凸点触点 **34.1601**
实质上高出芯片表面的接触垫。

Bumped Die **74.0160**
A semiconductor die with raised metal features that facilitate inner-lead bonding. (See Figure B-13.)

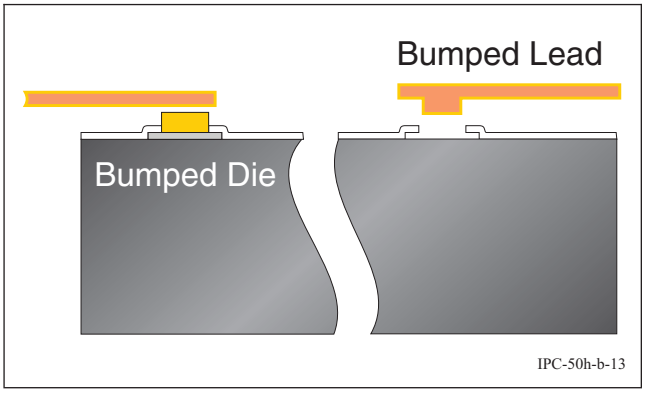
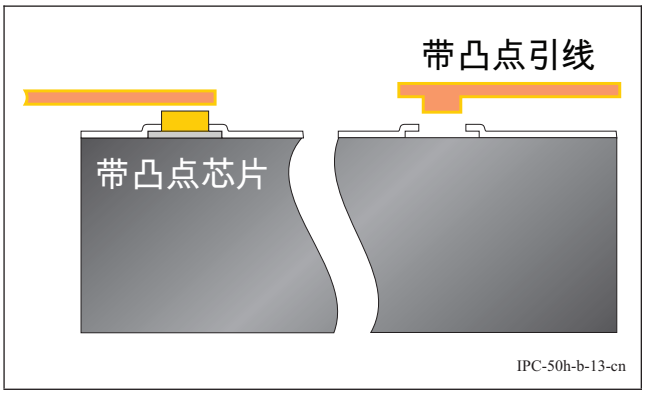


Figure B-13 Bumped Die

带凸点芯片 **74.0160**

带有金属突起部分的半导体芯片，以便进行内引线键合。（见图B-13。）



图B-13 带凸点芯片

Bumped Tape **74.0161**

Carrier tape with raised metal features that facilitate inner-lead bonding.

带凸点载带 **74.0161**

带有金属突起部分的载带，以便进行内引线键合。

Bumped Wafer **74.0162**

A semiconductor wafer with raised metal features on its die lands that facilitate inner-lead bonding.

带凸点晶圆 **74.0162**

在其芯片连接晶片上带有金属突起部分的半导体晶圆，以便进行内引线键合。

Buried Via **22.0163**

A via that does not extend to the surface of a printed board. (See Figure B-9.)

埋孔 **22.0163**

未延伸至印制板表面的导通孔。（见图B-9。）

Burn-In **95.0164**

The process of electrically stressing a device at an elevated temperature, for a sufficient amount of time to cause the failure of marginal devices (Infant Mortality).

老化 **95.0164**

在高温下对器件进行电应力处理，经过足够长的时间使处于合格边缘状态的器件产生失效（早期失效）。

Burn-In, Dynamic **95.0165**

Burn-in at high temperatures that simulates the effects of actual or simulated operating conditions.

动态老化 **95.0165**

模拟在实际影响或模拟工作状态下的高温老化。

Burn-In, Static **95.0166**

Burn-in at high temperatures with unvarying voltage, either forward or reverse bias.

静态老化 **95.0166**

以恒定电压，既可是正向偏压，也可是反向偏压的高温老化。

Burn-Off **74.0167**

See “Flame-Off.”

熔断 **74.0167**

见“烧断，Flame-Off”。

Burnt Resin (Base Materials) **40.1602**

See “Treater Dirt.”

烧焦树脂（基材） **40.1602**

见“浸胶异物，Treater Dirt”。

Burr **92.1603**

Small lumps or masses with an irregular shape, convex to a surface, which occur as a result of a machine process such as drilling or gouging.

毛刺 **92.1603**

由机械加工例如钻孔或刨削而导致的凸起于表面的不规则小块。

Bus **21.0168**

One or more conductors used for transmitting data signals or power.

总线 **21.0168**

用于传输数据信号或电源的一根或多根导线。

Bus Bar **37.0169**

A conduit, such as a component or conductor on a printed board, that is used for distributing electrical energy. (See also “Plating Bar.”)

汇流条 **37.0169**

用来分配电能的通道，例如印制板上的元器件或导线。（又见“电镀工艺导线，Plating Bar”。）

Butt Leads **36.1732**

A SMT lead form where leads extend horizontally from about the center of a component body, formed down at a 90 degree angle and end immediately below the component body without additional bends.

垛形引线（I形引线） **36.1732**

一种表面贴装引线的形式。引线从元器件体中心水平地伸出，以90°角向下成形，且直接终止于低于元器件体处，不再弯曲。

Butt Plating Joint **60.2145**

A joint between two or more conductors of a printed board, at the end of one or both, and either at right angles or oblique to the grain of the conductors, with no overlap of the conductors.

对接电镀接点 **60.2145**

印制电路板上两个或多个导体之间的接点，位于其中一个导体或两个导体的末端，与导体走向成直角或锐角，但导体不互相重叠。

Butt Plating Joint (Wrap Plating) **60.2146**

The consequent via structure of a surface interconnect termination with the absence of wrap plating. (See Figure B-14.)

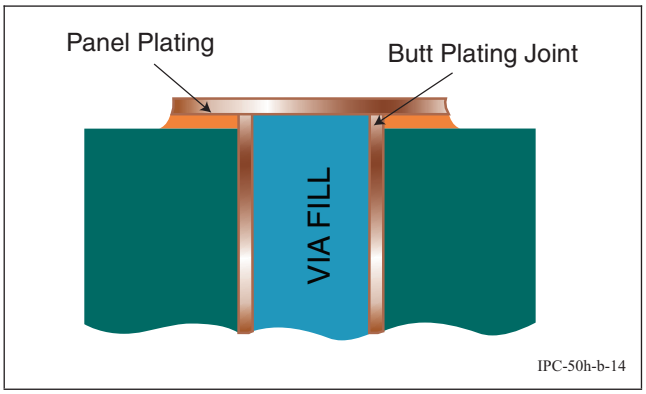
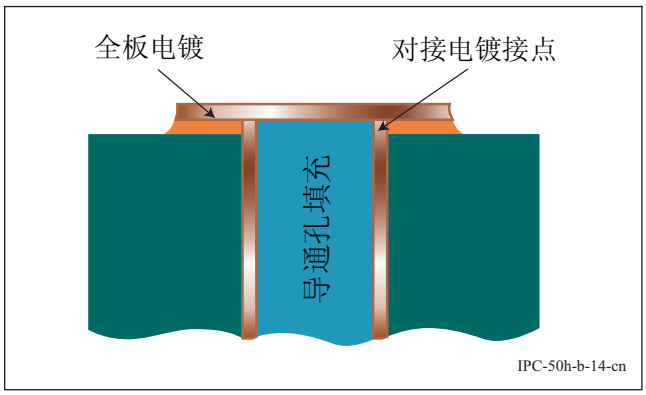


Figure B-14 Butt Plating Joint (Wrap Plating)

对接电镀接点（包覆镀层） **60.2146**

无包覆镀层的表面互连端子的导通孔结构。（见图B-14。）



图B-14 对接电镀接点（包覆镀层）

Butter Coat **41.0170**

An increased amount of resin on the outer surface of a base material.

厚涂层 **41.0170**

基材外表面上树脂的增厚层。

Button Plating **60.2143**

The process of plating only in the holes and on pads. (See Figure B-15).

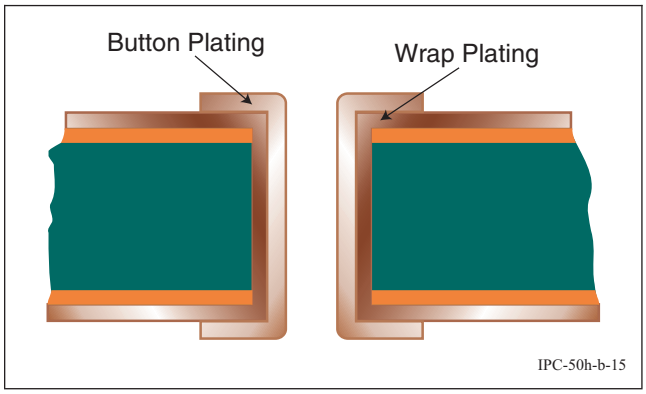
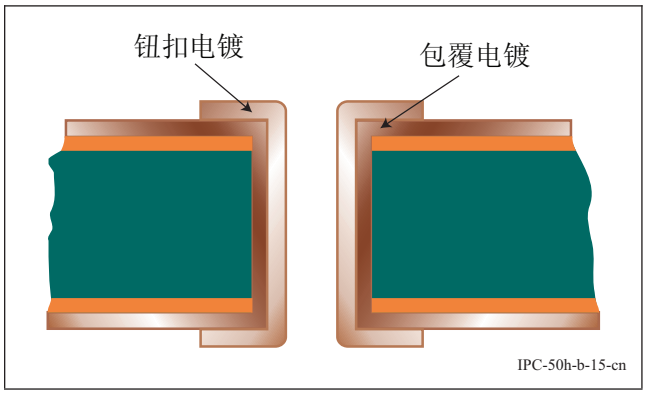


Figure B-15 Button Plating

钮扣电镀 **60.2143**

只电镀孔内和焊盘的工艺。（见图B-15。）



图B-15 钮扣电镀

C

C-Staged Resin **41.0171**
A resin in its final state of cure. (See also "B-Staged Resin.")

C阶树脂 **41.0171**
处于固化最后阶段的树脂。(又见"B阶树脂，B-Staged Resin"。)

Camber **92.0172**
The planar deflection of a flat cable or flexible laminate from a straight line.

弯度 **92.0172**
挠性板或扁平电缆的平面偏离直线的程度。

Cant **70.2183**
The angle between the bottom mounting surface of a component and the top surface of the printed board.

倾斜角 **70.2183**
元器件底部安装面与印制板上表面之间的角度。

Cap Lamination **55.0176**
A process for making multilayer printed boards with surface layers of metal-clad laminate bonded in a single operation. (See also "Foil Lamination.")

覆盖层压 **55.0176**
采用单面覆金属箔基板作表层，以一次层压法制作多层印制电路板的过程。(又见"覆箔层压，Foil Lamination"。)

Capability Detail Specification (CapDS) **26.1780**
A document that establishes the specific requirements, noted in a detailed specification, in order to establish the level of capability that a manufacturer possesses when he has demonstrated that he has met those requirements.

能力详细规范（CapDS） **26.1780**
一份建立了明确要求的文件，详细规范中给出了这些要求的注释，以便制造商证明他达到这些要求时，确定他所拥有的能力水平。

Capability Index (Cp) **91.0306**
See "Capability Performance Index."

能力指数（Cp） **91.0306**
见"能力特性指数，Capability Performance Index"。

Capability Performance Index (Cp) **79.1806**
The ratio of the measured performance of a process compared to specified limits.

能力特性指数（Cp） **79.1806**
测量得到的过程特性与规定界限之比。

Capability Performance, Lower (Cpkl) **91.1367**
A measure of the relationship between the performance of a process and the lower specification limit. (See also "Capability Performance, Upper.")

能力特性，下限（Cpkl） **91.1367**
过程特性和下规格极限之间关系的量度。(又见"能力特性，上限，Capability Performance, Upper"。)

Capability Performance, Upper (Cpku) **91.1344**
A measure of the relationship between the performance of a process and the upper specification limit. (See also "Capability Performance, Lower.")

能力特性，上限（Cpku） **91.1344**
过程特性和上规格极限之间关系的量度。(又见"能力特性，下限，Capability Performance, Lower"。)

Capability Test Board (CTB) **94.1784**
A printed board specifically designed to act as a capability qualifying component (CQC), or to be used by manufacturer to evaluate process variation, process control, or continuous improvement procedures.

能力测试板（CTB） **94.1784**
专门设计的印制板，用来作为能力鉴定部件(CQC)，或被制造商用来对过程变化、过程控制或持续改进程序进行评估。

Capability Test Segment (CTS) **94.1785**
A segment or portion of a capability test board (CTB), containing a set or group of individual test patterns (ITP), intended to be used to demonstrate a specific level of printed board complexity or manufacturing capability.

能力测试块（CTS） **94.1785**
能力测试板的一部分或一个分块，包含一套或一组独立测试图形，用来证明印制板复杂性或制造能力的特定水平。

Capacitance **21.1794**
A measure of the ability of two adjacent conductors separated by an insulator to hold a charge when a voltage is impressed between them.

电容 **21.1794**
对两个被绝缘体分隔开的相邻导体施加电压时，其储存电荷能力的量度。

Capacitance Density **21.0173**
The amount of capacitance available per unit area.

电容密度 **21.0173**

每单位面积可得到的电容的量。

Capacitive Coupling **21.0174**

The electrical interaction between two conductors that is caused by the capacitance between them.

电容耦合 **21.0174**

两个导体间的电容所引起的电相互作用。

Capillary **74.0175**

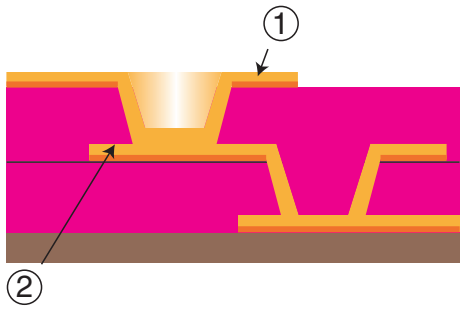
A hollow bonding tool used to guide wire to the bonding site and to be used to apply pressure during the bonding cycle. (See also "Wedge Tool.")

毛细导管 **74.0175**

用于将金属线引导至键合位置并在键合期间施加压力的中空键合工具。(又见"楔焊工具，Wedge Tool"。)

Capture Land (Via Top Land) **22.2116**

The land portion of a microvia connecting from an exterior conductor. (See Figure C-1.)



Note 1. Capture Land
Note 2. Target Land

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Figure C-1 Capture and Target Land (Microvia)

诱捕连接盘（导通孔顶部连接盘） **22.2116**

与外部导体连接的微导通孔的连接盘部分。(见图C-1)。

Card **60.0177**

See "Printed Board."

卡板 **60.0177**

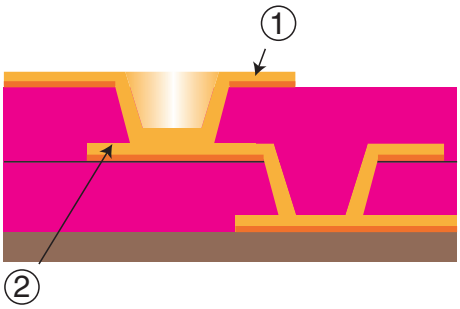
见"印制板，Printed Board"。

Card-Edge Connector **22.0178**

See "Edge-Board Connector."

卡边连接器 **22.0178**

见"板边连接器，Edge-Board Connector"。



注1. 诱捕连接盘
注2. 目标连接盘

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图C-1 诱捕连接盘和目标连接盘（微导通孔）

Card-Insertion Connector **22.0179**

See "Edge-Board Connector."

插卡连接器 **22.0179**

见"板边连接器，Edge-Board Connector"。

Carrier **30.1605**

Container that directly holds components, such as a tray, tube, or tape and reel.

载体 **30.1605**

用来直接盛装零件的容器，例如托盘、管子、卷带或卷轴。

Carrier (Foil) **45.0180**

A temporary support medium that facilitates the handling of thin and soft-metal foils.

载体（箔） **45.0180**

临时性支撑介质，使又软又薄的金属箔便于处理。

Carrier Tape **36.1345**

The carrier for conductors used in tape-automated bonding. (See also "Multilayer Carrier Tape," "Single-Layer Carrier Tape," "Two-Layer Carrier Tape" and "Three-Layer Carrier Tape.")

载带 **36.1345**

用于自动载带焊接机上承载导体的载体带。(又见"多层载带，Multilayer Carrier Tape"、"单层载带，Single-Layer Carrier Tape"、"双层载带，Two-Layer Carrier Tape"及"三层载带，Three-Layer Carrier Tape"。)

Carry-Out **51.0181**

The curved back portion of the flute of a drill.

排屑口 **51.0181**

钻头上容屑槽后部的弧形部分。

Cartridge **30.1606**
A container for components that facilitates the loading and unloading of them.

料盒 **30.1606**
盛放元器件的容器，便于元器件的装卸。

Castellation **33.0182**
A recessed metalized feature on the edge of a leadless chip carrier that is used to interconnect conducting surfaces or planes within or on the chip carrier. (See Figure C-2.)

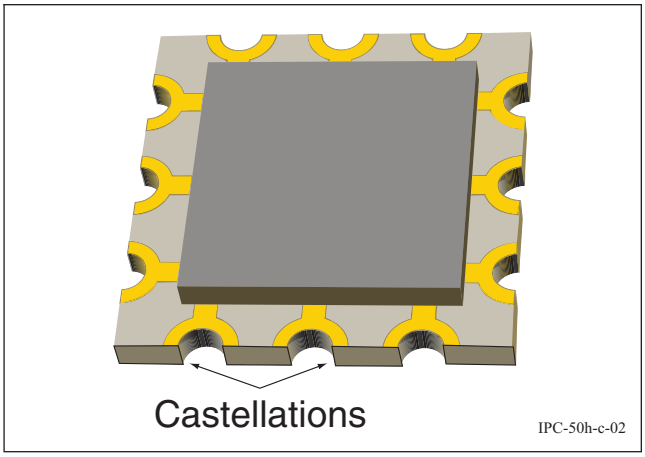
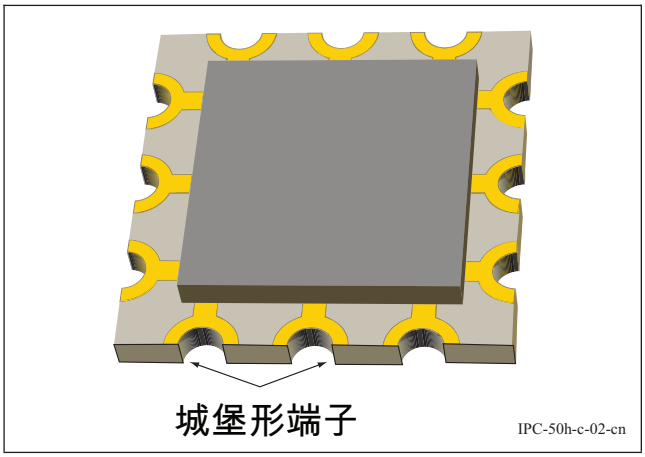


Figure C-2 Castellation

城堡形端子 **33.0182**
无引线芯片载体边缘上凹入的金属化构件，用以与芯片载体上面或内部的导电表面或平面间互连。（见图C-2。）



图C-2 城堡形端子

Catalyst (Resin) **40.0183**
A chemical that is used to initiate the reaction or increase the speed of the reaction between a resin and a curing agent.

催化剂（树脂） **40.0183**
用来触发树脂与固化剂之间反应或增加其反应速度的化学物质。

Catalyzing **53.0184**
See “Activating.”

催化 **53.0184**
见“活化，Activating”。

Cathodic Cleaning **57.0185**
Electrolytic cleaning in which the work is the cathode.

阴极清洗 **57.0185**
将工件作为阴极的电解清洗。

Cation Exchange **59.0186**
See “Ion Exchange.”

阳离子交换 **59.0186**
见“离子交换，Ion Exchange”。

Cationic Reagent **59.0187**
Surface-active substances that have the active constituent in the positive ion.

阳离子表面活性剂 **59.0187**
活性组分为正离子的表面活性剂。

Cause-and-Effect Diagram **94.0188**
A problem solving tool that uses a graphic description of various process elements in order to analyze potential sources of process variation.

因果图 **94.0188**
一种解决问题的工具，对各种过程要素作图解描述，用来分析过程变异的潜在根源。

Center-to-Center Spacing **22.1346**
The nominal distance between the centers of adjacent features on any single layer of a printed board. (See Figure C-3.) (See also “Pitch.”)

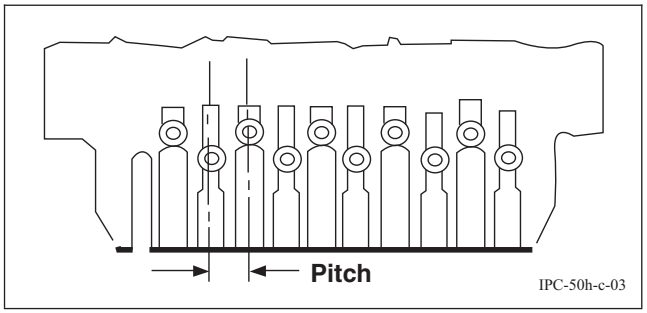
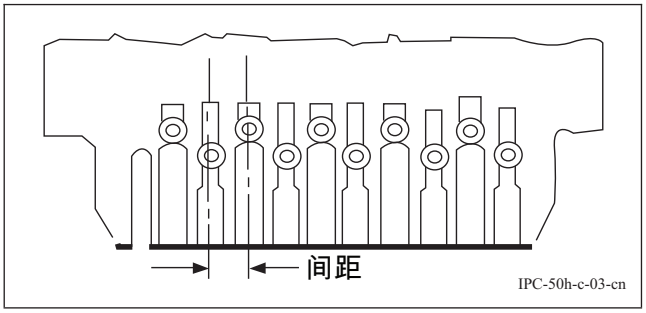


Figure C-3 Center-to-Center Spacing (pitch)

中心距 **22.1346**
印制板任一层中相邻两导体中心之间的标称距离。（见图C-3。）（又见“间距，Pitch”。）



图C-3 中心距 （间距）

Centering Force **73.1733**

The force required by the pick-up tooling to center a surface mounting device in its proper location on a substrate.

对中力 **73.1733**

拾取装置将表面贴装器件放在基材的适当位置中心所必需的力。

Centerwire Break **74.0189**

A failure mode in a wire pull test whereby the wire fractures at approximately its midspan.

金属线中心断裂 **74.0189**

金属线拉伸测试中的一种失效模式，金属线在其跨距中点附近断裂。

Centipoise **46.1608**

A metric unit of the measure of viscosity equal to 1/100 poise. See “Poise.”

厘泊 **46.1608**

粘度的米制量度单位，等于泊的百分之一。（又见“泊，Poise”。）

Central Line **91.0190**

The line on a control chart that depicts the average or median value of the items being plotted.

中心线 **91.0190**

控制图上描述所标绘项目的均值或中间值的线。

Ceramic Dual-in-line Package (CERDIP) **31.1611**

A dual in-line-package that has a package body of ceramic material and hermetically sealed by a glass. (See also “Dual-in-line Package.”)

陶瓷双列直插式封装（CERDIP） **31.1611**

封装体为陶瓷材料并用玻璃密封的双列直插式封装。（又见“双列直插式封装，Dual-In-Line Package”。）

Ceramic Pin Grid Array **31.1612**

A pin grid array package (PGA) made of a ceramic material, hermetically sealed by metal, with leads formed on a grid extending from the bottom of the package.

陶瓷针栅阵列 **31.1612**

针栅阵列封装（PGA），由陶瓷材料制成并用金属密封，引线从封装体底部伸出呈栅格状排列。

Ceramic Quad Flat Pack (CQFP) **33.1613**

A quad flat package (QFP) made of a ceramic material, hermetically sealed by metal, with leads extending from all four sides.

陶瓷方形扁平封装（CQFP） **33.1613**

由陶瓷材料制成并用金属密封的方形扁平封装（QPF），引线从四周伸出。

Certification **17.0191**

The verification that specified training or testing has been performed and that required proficiency or parameter values have been attained.

认证 **17.0191**

对已完成规定的培训或测试且达到了所要求的熟练程度或参数值的验证。

Chain Dimensioning **26.0192**

The maximum variation between two features that is equal to the sum of the tolerances on the intermediate distances.

链式尺寸标注 **26.0192**

两要素间的最大变异等于各中间距离公差之和。

Chalking (Cured Solder Mask) **47.1005**

When the solder mask is degraded such that fine particulates can be removed from the surface.

粉化（固化的阻焊膜） **47.1005**

当阻焊膜退化时，细颗粒就会从表面脱落的一种现象。

Chamfer (Drill) **51.0193**

The angle at the end of a drill shank.

倒角（钻头） **51.0193**

钻柄末端的斜角。

Character **70.1615**

A letter, digit, or other special form that is used to represent data in a bar code symbol. (See also “Bar Code Symbol.”)

符号 **70.1615**

条码符号中用来表示数据的字母、数字或其它他特殊形式。（又见“条码符号，Bar Code Symbol”。）

Characteristic Curve **24.1347**

A plot of photographic product optical-density data versus the logarithm of the exposure used to characterize the response of the material to exposure and development. (See Figure C-4.)

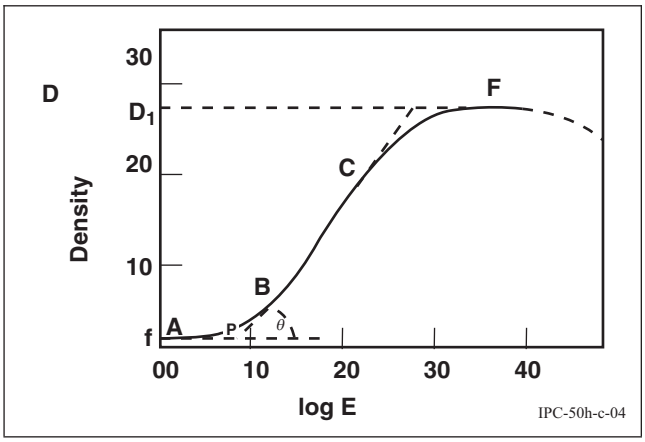
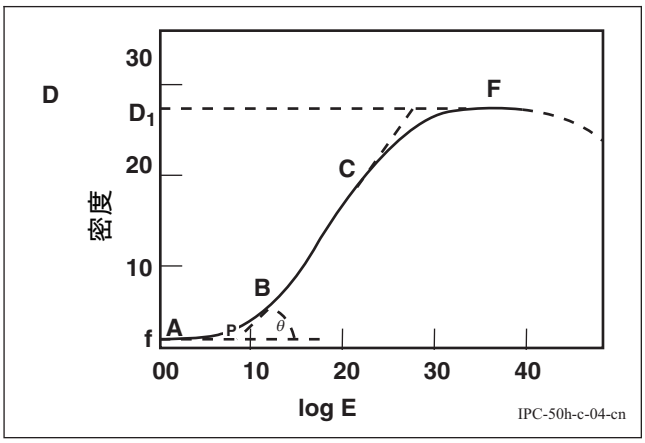


Figure C-4 Typical Characteristic Curve

特性曲线 **24.1347**

照相材料光密度值与曝光量对数值的关系曲线图，用以描述材料对曝光量和显影的响应。（见图C-4。）



图C-4 典型特性曲线

Characteristic Impedance **21.0194**

The resistance of a parallel conductor structure to the flow of alternating current (AC), usually applied to high speed circuits, and normally consisting of a constant value over a wide range of frequencies.

特性阻抗 **21.0194**

平行导体结构对交流电流动的阻抗，通常应用于高速电路，正常情况下，在很宽的频率内有一个恒定值。

Check List **94.1219**

A compilation of the specified criteria that may be evaluated during an audit or inspection.

检查清单 **94.1219**

审核时或检验时用作评价的规定准则的汇集。

Check Plot **94.0195**

An interim drawing used for graphical data verification.

校查图 **94.0195**

用于图形数据验证的临时绘图。

Check Sheet **94.0196**

A form that is used for data collection.

校查表 **94.0196**

用来收集数据的一种表格。

Chelate Compound **76.0197**

A compound in which metal is contained as an integral part of a ring structure.

螯合物 **76.0197**

含有金属作为环状结构一部分的化合物。

Chelating Agent **76.0198**

A compound capable of forming a chelate compound with a metal ion.

螯合剂 **76.0198**

能与金属离子形成螯合物的化合物。

Chemical Conversion Coating **57.0199**

A protective coating produced by the chemical reaction of a metal with a chemical solution.

化学转换涂层 **57.0199**

金属与化学溶液经化学反应而生成的一种保护涂覆层。

Chemical Resistance **40.1616**

The resistance of an insulating material to the degradation of surface characteristics, such as surface roughness, swelling, tackiness, blistering or color change, beyond the specified allowance by exposure to chemicals such as acids, alkalis, salts, or solvents.

耐化学性 **40.1616**

绝缘材料暴露在酸、碱、盐或溶剂等化学物质中，其表面特性劣化不超出规定允许范围的抵抗能力，表面特性指表面粗糙度、膨胀、粘着性、起泡或颜色改变。

Chemical Vapor Deposition **45.0202**

The deposition of a film onto the surface of a substrate by the chemical reduction of a vapor on contact with the base material.

化学气相沉积 **45.0202**

蒸气与基材相接触产生化学还原反应，在基材表面沉积薄膜的过程。

Chemical Wire Stripping **37.0203**

The process of removing insulation from wire using chemical compounds.

化学剥线 **37.0203**

采用化合物从导线上去除绝缘皮的过程。

Chemically-Deposited Printed Circuit **50.0201**

See “Additive Process.”

化学沉积印制电路 **50.0201**

见“加成法，Additive Process”。

Chemically-Deposited Printed Wiring **50.0200**

See “Additive Process.”

化学沉积印制线路 **50.0200**

见“加成法，Additive Process”。

Chemisorption **74.1348**

The formation of bonds between the surface molecules of a metal, or other material of high surface energy, and another gas or liquid substance in contact with it.

化学吸附 **74.1348**

金属或其它高表面能材料的表面分子，与其它气体或液体物质接触时形成的相互结合。

Chessman **74.0204**

A disk, knob or lever used to manually control the position of a bonding tool with respect to land.

操作杆 **74.0204**

用于手动控制键接工具相对于连接盘位置的一种圆盘、按钮或把手。

Chip **35.0205**

See “Die.”

芯片 **35.0205**

见“晶片，Die”。

Chip Carrier **33.0208**

A low-profile, usually square, surface-mount component semiconductor package whose die cavity or die mounting area is a large fraction of the package size and whose external connections are usually on all four sides of the package. (It may be leaded or leadless.)

芯片载体 **33.0208**

一种薄外形、通常是正方形的表面贴装元器件的半导体封装，其芯片腔体或芯片安装区占封装尺寸的大部分，它的外部连接通常位于封装的四周（可以有引线也可以无引线）。

Chip-and-Wire **74.0206**

An assembly method that uses discrete wires to interconnect back-bonding die to lands, lead frames, etc.

芯片-金属线 **74.0206**

用分立金属线实现背连芯片与连接盘、引线框架互连的组装方法。

Chip-in-Board (CIB) **74.1617**

An electronic component where a chip is inserted into an opening of a ceramic of glass-epoxy substrate and bonded by wire bonding or TAB techniques. The object of this technique is to reduce the thickness of the COB assembly. The chip may be covered by a resin after bonding.

板内芯片直装（CIB） **74.1617**

一种将芯片嵌入陶瓷或玻璃纤维环氧树脂基板的开口内，并通过引线键合或TAB技术键合在一起的电子元器件。这种技术的目的是减少芯片直接贴装（COB）组件的厚度。键合后可用树脂覆盖芯片。

Chip-on-Board (COB) **86.0207**

A printed board assembly technology that places unpackaged semiconductor dice and interconnects them by wire bonding or similar attachment techniques. Silicon area density is usually less than that of the printed board. (See Figure C-5.)

板上芯片直装（COB） **86.0207**

放置未封装半导体晶粒并采用引线键合或类似的连接技术实现其互连的印制板电子组装技术。硅表面的密度通常比印制板的低。（见图C-5。）

Chip-on-Board Assembly **74.1618**

A printed board assembly using a combination of uncased chips and other devices. The silicon area density is less than 30%.

板上芯片直装组件 **74.1618**

将未封装芯片和其他器件结合的印制板组件。硅表面的密度低于30%。

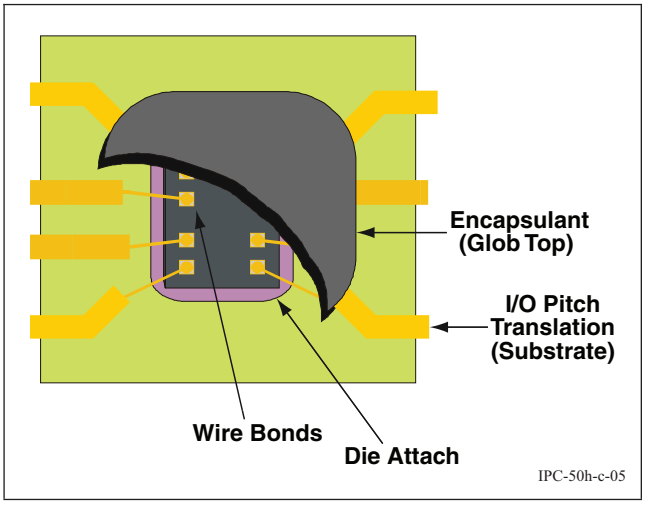
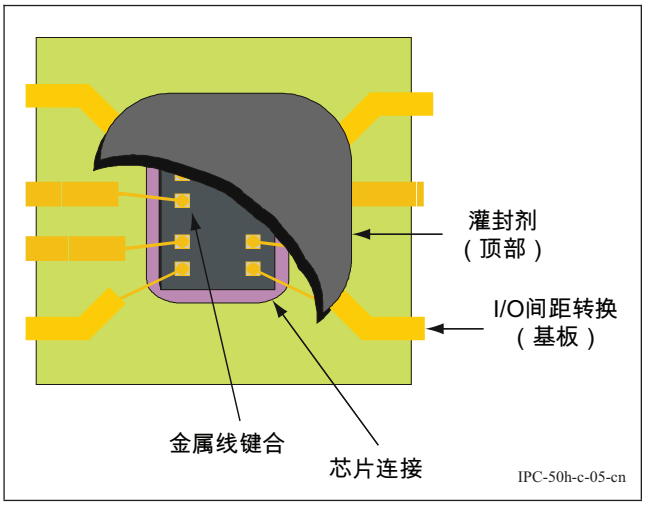


Figure C-5 Chip-on-Board



图C-5 板上芯片直装

Chip-on-Flex (COF) **74.1619**

Semiconductor chip mounted directly onto flexible printed board.

挠性板上芯片直装（COF） **74.1619**

将半导体芯片直接安装在挠性印制板上。

Chip-on-Glass (COG) **74.1620**

An assembly technology that uses an unpackaged semiconductor die mounted directly on a glass substrate such as a glass plate for liquid crystal display (LCD).

玻璃基板芯片直装（COG） **74.1620**

将未封装芯片直接安装在玻璃基板例如液晶显示器（LCD）的玻璃板上的组装技术。

Chip Scale Package (CSP) **74.2152**

The direct attachment of a chip to a substrate without an interposer.

芯片尺寸封装（CSP） **74.2152**

不采用中介基板而实现芯片与基板的直接连接。

Chipped Point **51.0209**

A condition whereby the amount of chips on the leading edge of a drill point exceeds an allowable value.

钻尖缺损 **51.0209**

钻尖切削刃的缺损量超出了允许值的状况。

Chipping **51.0257**

A piece of a panel or board that has broken away.

碎边角 **51.0257**

从在制板或单板上分离出来的一部分。

Chisel **74.0210**

A tool used for wedge and ultrasonic bonding.

劈刀 **74.0210**

用于楔形超声键合的工具。

Chisel-Edge Angle **51.0211**

The angle between the leading cutting edge and the intersection of the primary and secondary relief facets of a drill point.

横刃角 **51.0211**

主切削刃与钻尖的第一和第二主后面的交线之间的夹角。

Chopped Bond **74.0212**

A bond with excessive deformation such that the strength of the bond is greatly reduced.

压陷键合 **74.0212**

具有过度形变导致键合力大大减小的键合。

Circuit **21.0213**

A number of electrical elements and devices that have been interconnected to perform a desired electrical function.

电路 **21.0213**

许多电气部件和器件互连在一起以实现预期的电气功能。

Circuit Board **60.1625**

See “Printed Board.”

电路板 **60.1625**

见“印制板，Printed Board”。

Circuit Card **60.0214**

See “Printed Board.”

电路卡 **60.0214**

见“印制板，Printed Board”。

Circuit Density **22.1824**

The average quantity of electronic components (prefabricated or part of the interconnecting structure) on a unit area of a printed board considering one or both sides for component mounting.

电路密度 **22.1824**

单面或双面安装元器件的印制板中单位面积上电子元器件（预制的或互连结构部分）的平均数量。

Circuitry Layer **22.0215**

A layer of a printed board containing conductors, including ground and voltage planes.

电路层 **22.0215**

印制板中含有导体（包括接地层、电压层）的层。

Circumferential Separation **96.1349**

A crack or void in the plating extending around the entire circumference of a plated through hole, a solder fillet around lead wire or eyelet, or the interface between a solder fillet and a land.

环状断裂 **96.1349**

沿着镀通孔整个圆周的镀层、引线或空心铆钉周围的焊缝、或焊缝与连接盘的界面处的裂缝或空洞。

Circumferential Thermodes **74.1734**

A contact tool used for inner-lead and outer-lead gang bonding.

环形热电极 **74.1734**

用于内引线和外引线多点键合的接触工具。

Clad (adj.) **55.1350**

A condition of the base material to which a relatively-thin layer or sheet of metal foil has been bonded to one or both of its sides, e.g., “a metal-clad base material.”

覆箔的（形容词） **55.1350**

在基材的一面或两面粘接有相对较薄的金属层或金属片的状况，例如“覆金属箔基材”。

Clearance Hole **22.1811**

A hole in a conductive pattern that is larger than, and coaxial with a hole in the base material of a printed board. (See Figure C-6.)

隔离孔 **22.1811**

导电图形上的孔，大于印制板基材中与之同心的孔。（见图C-6。）

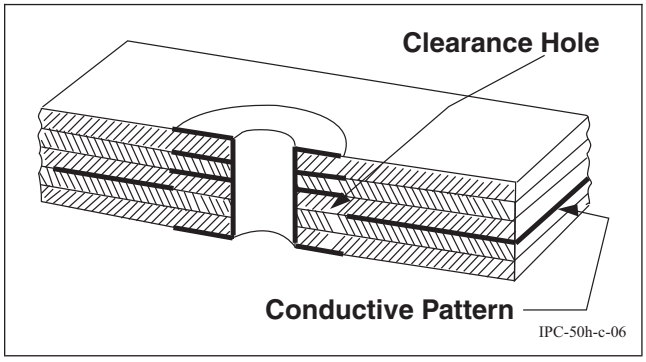
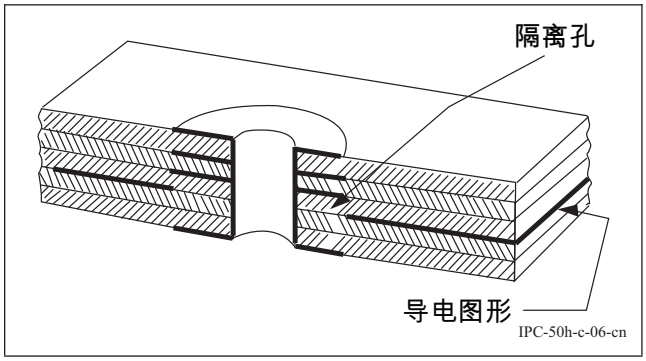


Figure C-6 Clearance Hole



图C-6 隔离孔

Clinched Lead **72.1351**

A component lead that is inserted through a hole in a printed board and is then formed in order to retain the component in place and in order to make metal-to-metal contact with a land prior to soldering. (See also “Partially-Clinched Lead.”)

折弯引线 **72.1351**

元器件引线穿过印制板的安装孔然后弯折成形使元器件固定，且在焊接前与焊盘形成金属与金属接触。（又见“部分折弯引线，Partially-Clinched Lead”。）

Clinched-Wire Interfacial Connection **72.0217**

See “Clinched-Wire Through Connection.”

弯线面间连接 **72.0217**

见“弯线贯穿连接，Clinched-Wire Through Connection”。

Clinched-Wire Through Connection **72.1352**

A connection made by a bare wire that has been passed through a hole in a printed board and subsequently formed (clinched) and soldered to the conductive pattern on each side of the board. (See Figure C-7.)

弯线贯穿连接 **72.1352**

将裸导线穿过印制板的孔，然后折弯成形与印制板两面的导电图形焊接形成的连接。（见图C-7。）

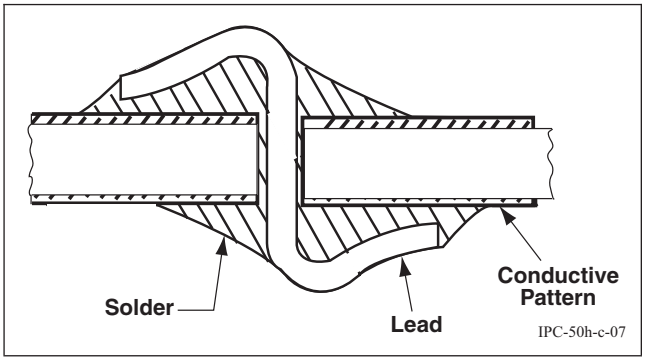
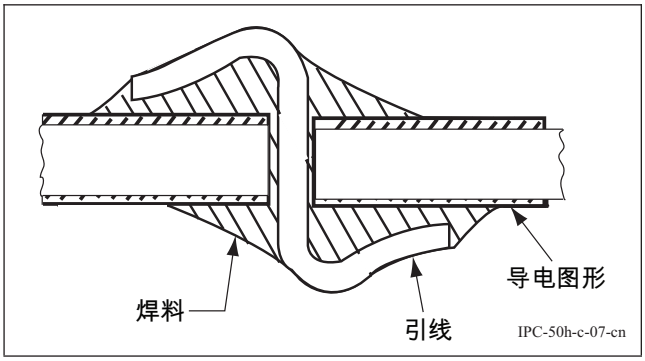


Figure C-7 Clinched-Wire Through Connection



图C-7 弯线贯穿连接

Closed-Entry Contact **37.0218**

A type of female connector contact that prevents the entry of an oversized mating part. (See also "Open-Entry Contact.")

闭口接触件 **37.0218**

能防止尺寸过大配接件插入的凹形连接器接触件。（又见"开口接触件，Open-Entry Contact"。）

Co-Firing **56.0219**

The simultaneous processing of thick-film circuit elements during one firing cycle.

共烧 **56.0219**

在一次焙烧周期中对厚膜电路元器件的同步处理。

Coaxial Cable **37.0220**

A cable in the form of a central wire surrounded by a conductor tubing or sheathing that serves as a shield and return.

同轴线缆 **37.0220**

中心导线被起屏蔽和回路作用的导电管或导电护套环绕的线缆。

Code 39 **70.1626**

A type of bar code named because it contains nine elements, bars and spaces, with three wide elements and six narrow elements.

39条码 **70.1626**

一种条码名称，它的一个条码字符由九个包含条和空的单元组成，其中有三个是宽单元，其余六个是窄单元。

Code Density **70.1627**

The number of characters per unit length in a bar code symbol.

条码密度 **70.1627**

条码符号中单位长度内的字符个数。

Coefficient of Thermal Expansion (CTE) **40.0221**

The linear dimensional change of a material per unit change in temperature. (See also "Thermal Expansion Mismatch.")

热膨胀系数 **40.0221**

每单位温度变化引起材料的线性尺寸改变。（又见"热膨胀不匹配，Thermal Expansion Mismatch"。）

Cohesion (Pressure Sensitive Tape) **75.1628**

The ability of a pressure sensitive adhesive to resist splitting.

附着性（压敏胶带） **75.1628**

压敏粘合剂抵抗撕开的能力。

Cohesion Failure **96.0222**

The rupture of an adhesive bond such that the separation appears to be within the adhesive.

附着失效 **96.0222**

粘接接合的断裂，其分离发生在粘合剂内。

Coined Lead **22.0223**

The end of a round lead that has been formed to have parallel surfaces that approximate the shape of a ribbon lead.

扁圆引线 **22.0223**

经过成型、有类似带状引线平行表面的圆引线末端。

Cold Flow (Pressure Sensitive Tape) **75.1629**

The tendency of some pressure sensitive adhesives to act like a heavy viscous liquid and exhibit a limited amount of flow over a period of hours or days at room temperature.

冷流动（压敏胶带） **75.1629**

某些压敏胶粘剂呈现类似粘稠液体的倾向，在室温下经过几个小时或几天显示有限的流动。

Cold Hand Cleaning **76.0224**

Cleaning with a soft brush and rinsing in a small open tank of chlorinated solvent or isopropanol. (Propan-2-01.)

手工冷清洗 **76.0224**

用软毛刷清洗并在装有氯化溶剂或异丙醇（丙醇-2-01）的小敞口箱内漂洗。

Cold Machine Cleaning **76.0225**

Cleaning with a chlorinated solvent and an inline brush or wave cleaner.

机器冷清洗 **76.0225**

在氯化溶剂中用内置毛刷或波峰清洗机清洗。

Cold Solder Connection **97.0226**

A solder connection that exhibits poor wetting, and that is characterized by a grayish, porous appearance. (This is due to excessive impurities in the solder, inadequate cleaning prior to soldering, and/or the insufficient application of heat during the soldering process.) (See also “Rosin Solder Connection.”)

冷焊接连接 **97.0226**

焊接连接呈现出润湿不良及灰色多孔外观。（这是由于焊料杂质过多，焊前清洁不佳，和/或焊接工艺期间加热不足造成的。）（又见“松香焊料连接，Rosin Solder Connection”。）

Color Selectivity **24.1630**

The preferential absorption of thermal radiation caused by emitted energy with wavelength frequencies in the visible band of from 0.39-0.78 microns.

颜色选择性 **24.1630**

对可见光波段内波频率长在0.39μm至0.78μm之间的发射能量所产生的热辐射的优先吸收。

Color Temperature **24.1355**

A measure of the energy distribution over the visible spectral range of a light source with a continuous spectrum, expressed in degrees Kelvin (K). (See also “Effective Color Temperature.”)

色温 **24.1355**

衡量连续频谱光源在可见光谱范围内能量分布的量度，用开尔文（K）来表示。（又见“有效色温，Effective Color Temperature”。）

Column Grid Array (CGA) **34.2184**

A surface mount package wherein the columns for termination are formed in a grid on the bottom of a package.

柱栅阵列（CGA） **34.2184**

位于封装体底部的柱状端子排成栅格阵列的表面贴装封装。

Comb Pattern **22.0227**

A set of interdigitated comblike arrays of uniformly-spaced conductors. (See Figure C-8.)

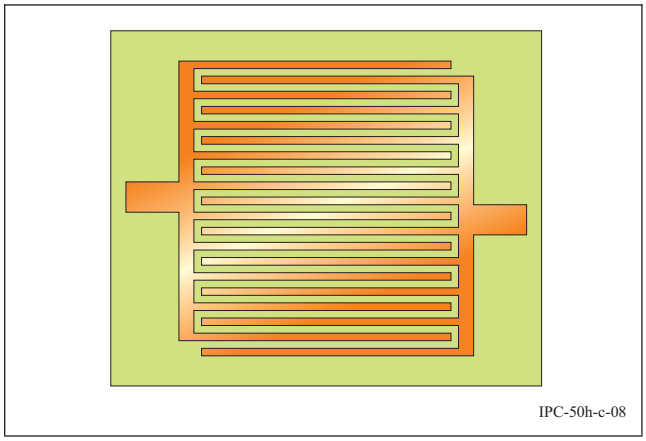
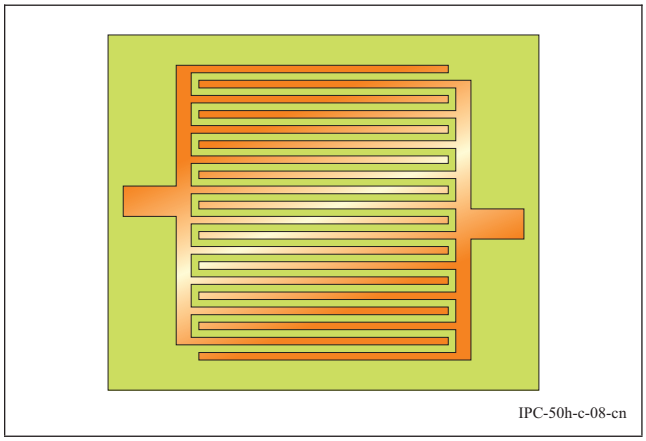


Figure C-8 Comb Pattern

梳型电路 **22.0227**

交错排列的等间距梳状导体。（见图C-8。）



图C-8 梳型电路

Combination Mask **47.1631**

A type of screen mask that is composed of two areas wherein the one is located in the center of the screen mask and is made by a metal screen mesh with a printing image, and the other is located in the periphery of the screen mask and is made by a thin elastic material.

组合掩模 **47.1631**

一种由两部分组成的网印掩模：一部分是位于网印掩模中央的带有印刷图形的金属印网，另一部分则是位于印网外围的薄弹性材料。

Comment Record **25.0228**

A record that provides, or refers to, additional descriptive material that further clarifies the control of a data set.

注释记录 **25.0228**

提供或引用附加的描述性材料，以进一步阐明数据设置控制的记录。

Common Cause **91.0229**
A source of variation that affects all the individual values of the output of a process.

普遍原因 **91.0229**
影响过程输出所有单个值的变异源。

Compensated Artwork **24.0230**
Production master or artwork data that has been enlarged or reduced in order to meet the needs of subsequent processing requirements.

已补偿照相底版 **24.0230**
已经过放大或缩小处理以满足后序加工要求的生产原图或底版数据。

Compensation Circuit **21.0231**
An electrical circuit that alters the functioning of another circuit to which it is applied to achieve desired performance.

补偿电路 **21.0231**
为了达到所希望的性能，作用于其它电路以改变其功能的电气电路。

Compiler **11.0232**
A software module that analyzes and converts programs from a high-level language to binary machine codes.

编译程序 **11.0232**
对程序进行分析，并将其从高级语言转换为二进制机器码的软件模块。

Complex Ion **76.0233**
An ion composed of two or more ions or radicals that are capable of an independent existence.

络离子 **76.0233**
由能独立存在的两个或更多离子或根构成的离子。

Compliant Bond **74.0235**
A bond that uses an elastically- and/or plastically-deformable member to impart the required energy to the lead.

柔性键合 **74.0235**
采用弹性和/或塑料可变形构件将所需能量传给引线的键合。

Component **30.0236**
An individual part or combination of parts that, when together, perform a design function(s). (See also “Discrete Component.”)

元器件 **30.0236**
可执行一定设计功能的单个部件或多个部件的组合。（又见“分立元器件，Discrete Component”。）

Component Density **22.0237**
The quantity of components on a unit area of printed board.

元器件密度 **22.0237**
单位面积印制板上元器件的数量。

Component Hole **20.0238**
A hole that is used for the attachment and/or electrical connection of component terminations, including pins and wires, to a printed board.

元器件孔 **20.0238**
用于将元器件端子（包括插针和导线）与印制板固定和/或实现电气连接的孔。

Component Lead **30.1356**
The solid or stranded wire or formed conductor that extends from a component to serve as a mechanical or electrical connector, or both. (See also “Component Pin.”)

元器件引线 **30.1356**
从元器件本体延伸出的单根或多股金属线或成型导体，用于实现机械或电气连接，或机械和电气连接。（又见“元器件插针，Component Pin”。）

Component Mounting **70.0239**
The act of attaching components to a printed board, the manner in which they are attached, or both.

元器件安装 **70.0239**
将元器件固定到印制板上的动作，或元器件在印制板上的固定方式，或兼指二者。

Component Mounting Orientation **22.1357**
The direction in which the components on a printed board or other assembly are lined up electrically with respect to the polarity of polarized components, with respect to one another, and/or with respect to the board outline.

元器件安装方向 **22.1357**
印制板或其它组件上元器件的（电气）排列方向，通常根据极性元器件的极性、元器件彼此之间的相互关系和/或印制板外形来排列。

Component Mounting Site **70.1632**
A location on a Packaging and Interconnecting structure (P&I) that consists of a land pattern and conductor fan-out to additional lands for testing or vias that are associated with the mounting of a single component.

元器件安装位置 **70.1632**
封装和互连结构（P&I）上的位置，包括一个连接盘图形及伸向测试用附加连接盘的导体输出或与安装单个组件有关的导通孔。

Component Pin **30.0240**
A component lead that is not readily formable without being damaged. (See also “Component Lead.”)

元器件插针 **30.0240**
不损坏就难以变形的元器件引线。（又见“元器件引线，Component Lead”。）

Component Side **22.0241**
See “Primary Side.”

元器件面 **22.0241**
见“主面，Primary Side”。

Component Thermal Masses **30.1735**
The ability of a part to absorb or retain heat energy, usually relative to its overall size and weight.

元器件热容量 **30.1735**
元器件吸收或保持热能的能力，通常与其外形尺寸和重量有关。

Composite (Phototool) **24.0242**
A photograph that consists of a combination of two separate (aligned) images.

组合底片（底片） **24.0242**
由两个单独的（对齐的）图形组合而成的照片。

Composite Record **25.1358**
A collection of records that make up an electrical pattern that is used repeatedly in a design. (The definition and relationship of such records are covered and referred to as “subroutine definition” and “subroutine definition call.”)

组合记录 **25.1358**
一种在设计中重复使用的制作电气图形的记录集合。（这种记录的定义和相互关系间被称为“子程序定义”及“子程序定义调用”。）

Composite Test Pattern (CTP) **24.1792**
A grouping of individual test patterns into specific arrangements, to reflect control and precision capability of a manufacturer or manufacturing process.

组合测试图形（CTP） **24.1792**
一组特定排列的独立测试图形，反映制造商或制造过程的控制能力和精度。

Compound Die Set **51.1633**
A set consisting of a punch and matching die used to punch holes, details or the outlines of panels and/or printed boards.

组合冲切装置 **51.1633**
包括冲头和冲模的组合冲切装置，用于印制线路板和在制板的冲孔和外形加工。

Compression Seal **36.0243**
A tight joint made between an component package and its leads that is formed as heated metal cools and shrinks around a glass insulator.

收缩密封 **36.0243**
被加热金属围绕玻璃绝缘体冷却、收缩而形成的元器件封装和引线之间的紧密接合。

Computer Numerical Control (CNC) **11.0244**
A system that utilizes a computer and software as the primary numerical control technique. (See also “Numerical Control.”)

计算机数字控制（CNC） **11.0244**
利用计算机和软件作为主要数字控制技术的系统。（又见“数字控制，Numerical Control”。）

Computer-Aided Design (CAD) **22.1359**
The interactive use of computer systems, programs, and procedures in the design process wherein the decision-making activity rests with the human operator and a computer provides the data manipulation function.

计算机辅助设计（CAD） **22.1359**
在设计过程中交互使用计算机系统、程序和作业，其中操作人员作出决定，而计算机提供数据处理功能。

Computer-Aided Engineering (CAE) **21.1360**
The interactive use of computer systems, programs, and procedures in an engineering process wherein the decision-making activity rests with the human operator and a computer provides the data manipulation function.

计算机辅助工程（CAE） **21.1360**
在工程过程中交互式使用计算机系统、程序和作业，其中操作人员作出决定，而计算机提供数据处理的功能。

Computer-Aided Manufacturing (CAM) **25.1361**
The interactive use of computer systems, programs, and procedures in various phases of a manufacturing process wherein the decision-making activity rests with the human operator and a computer provides the data manipulation functions.

计算机辅助制造（CAM） **25.1361**
在制造过程的各个阶段交互使用计算机系统、程序和作业，其中操作人员作出决定，而计算机提供数据处理的功能。

Concentration Polarization **54.0245**
That portion of polarization electrode produced by concentration changes at the metal-environment interface.

浓差极化 **54.0245**
在金属与环境的界面由于浓度改变而产生的电极的部分极化。

Condensation Soldering **75.1681**
See “Vapor Phase Soldering.”

冷凝焊 **75.1681**
见“汽相焊接，Vapor-Phase Soldering”。

Conditional End-of-Test **25.0246**
A command in a test program to stop the execution of the program when a particular condition, or set of conditions, is reached.

有条件测试结束 **25.0246**
测试程序中，当达到一个特定条件或一组条件时，停止执行程序的指令。

Conditioning **92.0247**
The time-related exposure of a test specimen to a specified environment(s) prior to or after testing and before evaluation.

预处理 **92.0247**
在测试前后，以及在评估前，将试样暴露于特定环境下一定时间。

Conductance **40.1635**
A measure of conductivity of a material.

电导 **40.1635**
材料电导率的量度。

Conducting Salt **54.0248**
A salt added to a plating solution in order to increase its conductivity.

导电盐 **54.0248**
加入电镀溶液中以增加其电导率的一种盐。

Conductive Foil **45.0249**
A sheet of metal that is used to form a conductive pattern on a base material.

导电箔 **45.0249**
用来在基材上形成导电图形的金属片。

Conductive Ink **45.2171**
A low viscosity liquid medium with a suspended powder of an electrically conductive material.

导电墨 **45.2171**
含有导电悬浮粉末的低粘度液态介质。

Conductive Medium **45.2170**
A material with a suspended powder of an electrically conductive material. (See also conductive paints, inks, pastes.)

导电介质 **45.2170**
含有导电悬浮粉末的材料。（又见导电漆、导电墨及导电膏。）

Conductive Paint **45.1636**
A high viscosity liquid medium with a suspended powder of an electrically conductive material.

导电涂料 **45.1636**
含有导电悬浮粉末的高粘度液态介质。

Conductive Paste **45.1637**
A conductive material used to make conductive patterns and through holes on a base material consisting of silver, copper, nickel, carbon, etc. in a cream-like form.

导电膏 **45.1637**
用于在基材上制作导电图形或通孔的膏状导电材料，其导电成份可以是膏状形态的银、铜、镍、碳等。

Conductive Pattern **22.1362**
The configuration or design of the conductive material on a base material. (This includes traces, lands, vias, planes, and passive components when these are an integral part of the printed board manufacturing process.)

导电图形 **22.1362**
导电材料在基材上的布局或设计。（其中包括线条、连接盘、导通孔、层及在印制板制作中形成的被动（无源）元器件。）

Conductivity (Electrical) **40.0250**
The ability of a substance or material to conduct electricity.

电导率 **40.0250**
物质或材料导通电流的能力

Conductivity (Thermal) **40.2169**
The ability of a substance or material to conduct heat.

热导率 **40.2169**
物质或材料导热的能力。

Conductor **22.0251**
A single conductive path in a conductive pattern that includes traces, conductive holes, lands, and planes.

导体 **22.0251**
导电图形中的单个导电通道，包括线条、导电孔、连接盘和层。

Conductor Base Spacing **60.0252**
The spacing between conductor at the plane of the surface of a base material. (See also “Design Spacing of Conductors.”) (See Figure C-9.)

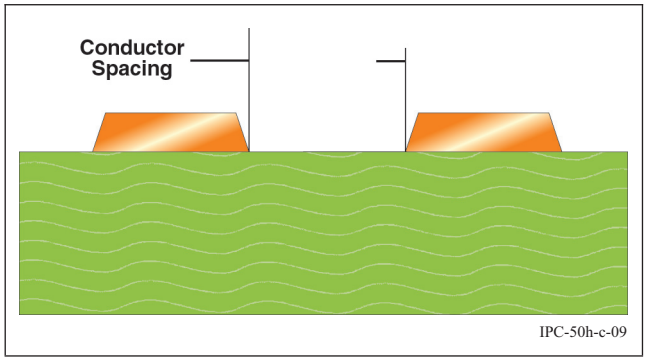
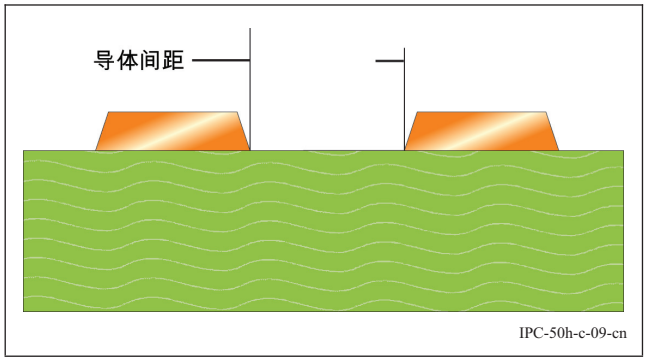


Figure C-9 Conductor Base Spacing

导体底距 **60.0252**
基材表面所位于平面之处导体之间的间距。（又见“导体设计间距，Design Spacing of Conductors”。）（见图C-9。）



图C-9 导体底距

Conductor Base Width **60.0253**
The width of a conductor at the plane of the surface of a base material. (See also “Conductor Width” and “Design Width of Conductors.”)

导体底宽 **60.0253**
基材表面处导线的宽度。（又见“导体宽度，Conductor Width”和“导体设计宽度，Design Width of Conductors”。）

Conductor Layer No. 1 **25.0254**
The first layer of a printed board that has a conductive pattern on or adjacent to its primary side.

第一层导体层 **25.0254**
印制板主面上或邻近主面的第一层导电图形。

Conductor Line **22.0256**
See “Conductor Trace.”

导体线 **22.0256**
见“导体线条，Conductor Trace”。

Conductor Layer **22.0848**
The total conductive pattern formed on one side of a single layer of a base material. (This may include all or a portion of ground and voltage planes.)

导体层 **22.0848**
在基材的单个层的某一面上形成的全部导电图形。（可以包括全部或部分的接地层与电源层。）

Conductor Nick **96.1932**
A reduction in a conductor trace cross-sectional area (internal or external) which may or may not expose the base material.

导体缺口 **96.1932**
导体线条横截面面积（内层或外层）的减少，可能会也可能不会暴露基材。

Conductor Path **22.0257**
See “Conductor Trace.”

导体路径 **22.0257**
见“导体线条，Conductor Trace”。

Conductor Pattern **22.0258**
See “Conductive Pattern.”

导体图形 **22.0258**
见“导电图形，Conductive Pattern”。

Conductor Pitch **22.1638**
The distance between the centers of adjacent conductor traces.

导体节距 **22.1638**
相邻导体线条中心之间的距离。

Conductor Protrusion **96.1640**
A random extension of conductor pattern that reduces the conductor spacing below the minimum requirement.

导体突出 **96.1640**

导体图形的不规则延伸，导致导体间隔小于最低要求。

Conductor Side **22.0259**

The side of a single-sided printed board that contains the conductive pattern.

导体面 **22.0259**

单面印制板上包含导电图形的面。

Conductor Spacing **60.1363**

The observable distance between adjacent edges (not center-to-center spacing) of isolated conductive patterns in a conductor layer. (See Figure C-10.) (See also "Center-to-Center Spacing.")

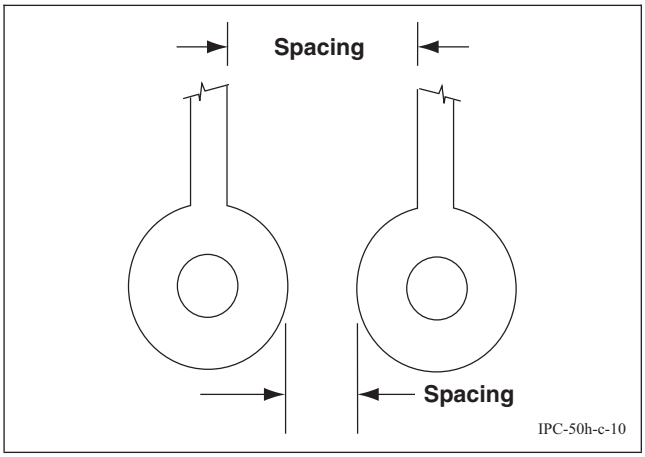
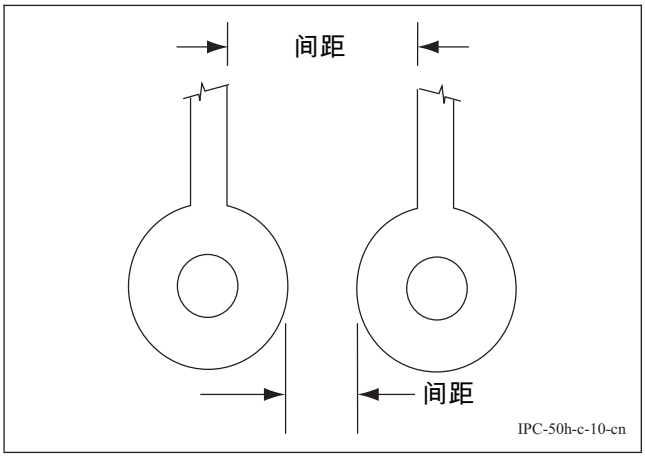


Figure C-10 Conductor Spacing

导体间距 **60.1363**

在一个导电层上，孤立导电图形的相邻边缘之间的可见距离（不是中心到中心的距离）。（见图C-10。）（又见"中心距，Center-to-Center Spacing"。）



图C-10 导体间距

Conductor Thickness **22.1707**

Thickness of a conductor including additional metallic coatings but excluding nonconductive coatings.

导体厚度 **22.1707**

包括附加的金属涂覆层在内的导线厚度，但不包含非导电涂层。

Conductor Trace **22.2172**

A single conductive linear entity (element) which has length, width and thickness.

导体线条 **22.2172**

具有长度、宽度及厚度的单个导电线状实体（元素）。

Conductor Track **22.0261**

See "Conductor Trace."

导体路线 **22.0261**

见"导体线条，Conductor Trace"。

Conductor Width **60.1364**

The observable width of a conductor trace at any point chosen at random on a printed board as viewed from directly above unless otherwise specified. (See also "Design Width of Conductor Traces or Planes" and "Conductor Base Width.")

导体宽度 **60.1364**

印制板导体线条上随机选取的一点，从其正上方观察到的导体线条宽度，除非另有规定。（又见"导体线条或层的设计宽度, 及导体基底宽度"。）

Confidence Interval **94.1365**

The determination, with a specified degree of confidence, as to whether or not a particular characteristic is within ascertained limits of a population.

置信区间 **94.1365**

以规定的置信度，确定一个特定的特性是否在总体规定的界限内。

Confirmation Run **94.0262**

A test of the results that are obtained during an experimental design in order to prove if the results are reproducible in an actual application.

确认试验 **94.0262**

对实验设计中得到的结果进行测试，以证实这个结果在实际应用中可以再现。

Conformal Coating **76.0263**

An insulating protective covering that conforms to the configuration of the objects coated (e.g., Printed Boards, Printed Board Assembly) providing a protective barrier against deleterious effects from environmental conditions.

敷形涂覆 **76.0263**

一种绝缘保护涂覆层，其外形与被涂覆的物体（例如印制板、印制板组件）一致，可提供保护隔离层以防止环境条件的有害影响。

Conformance Test Coupon Set **92.1641**

A complement of test coupons which are comprised of various coupon types, each of which is designed for a specific test or tests, but which were all made in the same manufacturing lot.

符合性测试用的附连板组 **92.1641**

由各种测试图形组成的一整套测试板，每种测试板针对一种具体的测试或测试组，但都是在同一生产批次内制造的。

Conformal Via **22.1644**

A type of build-up via in which the conductor layer of a uniform thickness is formed conforming to the shape of a hole in the insulating layer.

共形导通孔 **22.1644**

一种积层法导通孔，可形成与绝缘层中孔的形状一致、厚度均匀的导体层。

Confounding **94.0264**

A situation whereby certain effects cannot be separated from other effects.

混淆 **94.0264**

一些影响不能与其他影响分开的状态。

Connector **37.0265**

A device used to provide mechanical connect/disconnect service for electrical terminations.

连接器 **37.0265**

为电气端接点提供机械连接与断开的装置。

Connector Area **22.0269**

That portion of printed wiring used for the purpose of providing external connections.

连接器区 **22.0269**

用于提供外部连接的印制线路部分。

Connector Contact **22.0270**

The conducting member of a connecting device that provides a separable connection.

连接器接触件 **22.0270**

提供可分离连接的连接装置的导电部分。

Connector Housing **37.0271**

A plastic shell that holds electrical contacts in a specific field pattern that may also have polarization/keying bosses or slots.

连接器外壳 **37.0271**

将电接触件以特定形状固定的塑料外壳，也可以有极性/键控凸台或槽。

Connector, One-Part **22.0266**

See “Edge-Board Connector.”

单件连接器 **22.0266**

见“板边连接器，Edge-Board Connector”。

Connector Tang **37.0272**

That portion of a printed board that mates with an edge-board connector.

连接插头 **37.0272**

印制板上与板边连接器相配接的部分。

Connector, Two-Part **22.0267**

A connector containing two sets of discretely-formed mating metal contacts.

双件连接器 **22.0267**

具有两套分别成形的配接金属接触件的连接器。

Connector, Two-Part, Printed Board **37.0268**

A two-part connector wherein at least one set of contacts is mechanically and electrically attached to a printed board.

印制板双件连接器 **37.0268**

一种双件连接器，其中至少一套接触件用作与印制板的机械和电气连接。

Constraining Core **44.0273**

A supporting plane that is internal to a packaging and interconnecting structure.

抑制芯 **44.0273**

封装和互连结构内部的支撑面。

Consumer’s Risk **94.0274**

See “Beta Error.”

使用方风险 **94.0274**

见“β错误，Beta Error”。

Contact Angle (Bonding) **74.0275**

The angle between the bonding lead or wire and the bonding land.

接触角（键合） **74.0275**

键合引线之间或金属线与键合连接盘之间的夹角。

Contact Angle (Soldering) **75.1326**

The angle of a solder fillet that is enclosed between a plane that is tangent to the solder/basis-metal surface and a plane that is tangent to the solder/air interface. (See Figure C-11.)

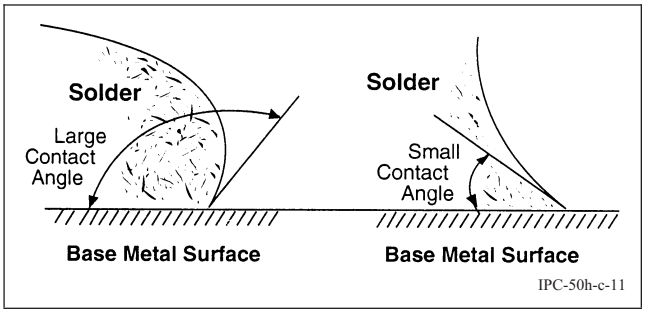
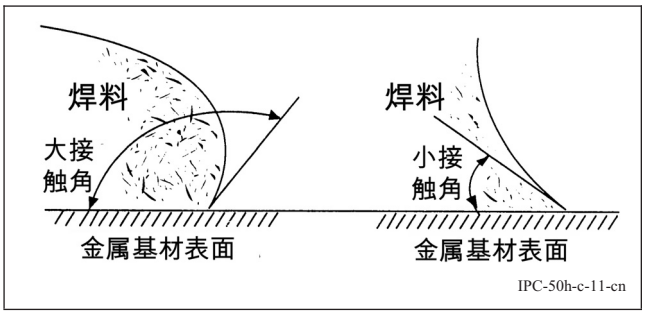


Figure C-11 Soldering Contact Angle

接触角（焊接） **75.1326**

焊料/金属基材表面的切面与焊料/空气界面的切面之间形成的焊料填充角。（见图C-11。）



图C-11 Soldering Contact Angle

Contact Area **22.0276**

The common area between a conductor and a connector through which the flow of electricity takes place.

接触区 **22.0276**

电流流经其中的导体与连接器之间的公共区域。

Contact Corrosion **96.0277**

See “Crevice Corrosion.”

接触腐蚀 **96.0277**

见“裂隙腐蚀，Crevice Corrosion”。

Contact Length **96.0278**

The distance of travel made by a contact in touch with another during the insertion and removal of a connector.

接触长度 **96.0278**

在插拔连接器时，接触件接触另一个接触件所经过的行程。

Contact Plating **53.1647**

The plating applied to the parts of a printed board that are used as the electrical contact to the circuit outside.

接触镀层 **53.1647**

涂敷在部分印制线路板上的镀层，用作与外部电路实现电气接触。

Contact Printing **24.1366**

A photographic light-exposure process that transfers an image from one base material to the photosensitive surface of another base material while both base materials are in mechanical contact with each other.

接触成像 **24.1366**

一种照相曝光过程，当两个基材相互接触时，将一个基材上的图像转印到另一个基材的感光面上。

Contact Resistance **70.0279**

The electrical resistance of metallic surfaces, under specified conditions, at their interface in the contact area.

接触电阻 **70.0279**

在规定条件下，金属表面接触区界面处的电阻。

Contact Retention Force **96.0280**

The minimum axial load in either direction that a contact withstands while it is in its normal position in a connector insert.

接触保持力 **96.0280**

接触件插入连接器中正常位置时，轴向两个方向所承受的最小负载。

Contact Spacing **22.0281**

See “Pitch.”

接触间距 **22.0281**

见“节距，Pitch”。

Contact Spring **37.0282**

The spring member of a socket-type contact that forces the engaging pin-type contact into a position of positive intimate contact.

接触弹簧 **37.0282**

插座型接触件的弹簧部分，可使针型接插件插至可靠紧密接触的位置。

Contained Paste Transfer Head **73.1648**

A stencil printer head that holds, in a single replaceable component, the squeegee blades and a pressurized chamber filled with solder paste.

焊膏转移头 **73.1648**
一种漏印板印刷头，为单个可更换部件，包括刮刀和充满焊膏的加压腔。

Contamination Host Material **76.0283**
The material within which contamination is deposited or entrapped.

污染宿主材料 **76.0283**
沾有或夹带有污染物的材料。

Continuity **92.0284**
An uninterrupted path for the flow of electrical current in a circuit.

连通性 **92.0284**
电路中电流流动的连续路径。

Continuity Test **92.1649**
Resistance test to insure all the required points have electrical continuity.

连通性测试 **92.1649**
电阻测试以确保所有要求的点具有电气连通性。

Contract Services **17.0285**
Printed-board manufacturing processing operations that are performed for or by another vendor outside the manufacturer's facility.

合同服务 **17.0285**
由或为制造商工厂之外的其他供方进行的印制板制造加工操作。

Control Chart **91.1368**
A graphic representation of a characteristic of a process that shows plotted values of some statistic gathered from characteristic, a central line, and one or two statistically-derived control limits.

控制图 **91.1368**
一种表示工艺特性的图表，显示了收集到的特性的统计数据、一条中心线及一条或两条根据统计得出的控制极限。

Control Console **11.0286**
A device terminal used to manipulate and maintain the operating system of a computer.

操纵台 **11.0286**
用于控制和维护计算机操作系统的设备终端。

Control Drawing **22.0287**
See "Master Drawing."

控制图 **22.0287**
见"布设总图，Master Drawing"。

Control Limits **91.0290**
The maximum allowable variation of a process characteristic due solely to common causes.

控制限 **91.0290**
只是由于共同原因引起的过程特性的最大允许变异。

Controlled Collapse, Component Connection **75.0289**
See "Controlled Collapse Soldering."

可控塌落元器件连接 **75.0289**
见"可控塌陷焊接，Controlled Collapse Soldering"。

Controlled Collapse, Bonding **74.1650**
A bonding technique that makes termination by reflowing the solder bump on a chip and connecting it to the land on the printed board.

可控塌落键合 **74.1650**
一种键合技术，通过芯片上焊料凸点的再流形成端接，将其与印制电路板的焊盘连接。

Controlled Collapse, Soldering **75.1651**
A technique for soldering a component (i.e., flip chip, chip scale package, BGA) to a substrate, where the component connection surface tension forces of the liquid solder supports the weight of the component and controls the height of the joint.

可控塌落焊接 **75.1651**
将元器件（例如倒芯片、芯片规模封装、BGA）焊接到基板的一种技术，连接元器件的熔融焊料的表面张力支撑元器件的重量，并控制焊点的高度。

Convected Energy **75.1736**
Heat transferred through circulation of fluid or gas.

对流能 **75.1736**
通过液体或空气循环而传递的热量。

Convection **21.1652**
Heat transfer that occurs at the interface of a solid and a fluid or gas that is due to their differences in temperature.

对流 **21.1652**
在固体与液体或气体的接触面由于温度差异发生的热传递。

Convection Controlled **21.1653**
Thermal transfer in which the characteristics, such as flow rate, velocity, and temperature are precisely controlled.

受控对流 **21.1653**

特性如流量、速度及温度均被精确控制的热传递。

Convection Forced **21.1654**

Convection that occurs by forcing the fluid over the solid media.

强制对流 **21.1654**

通过强制流体流过固体介质发生的对流。

Conveyor, Edge **70.0291**

A transporting mechanism that supports a product by the edges.

边缘传送带 **70.0291**

通过边缘支撑产品的传送机构。

Conveyor, Mesh **70.0292**

A transporting mechanism that fully supports the product.

网状传送带 **70.0292**

可支撑整个产品的传送机构。

Conveyor, Secondary **70.0293**

A transporting mechanism used beneath the edge conveyor to catch a fallen product.

二级传送带 **70.0293**

用于边缘传送带下面以承接跌落产品的传送机构。

Cooldown **75.1655**

The period of time during which the solder joints go through a liquidus phase and become solid.

冷却 **75.1655**

焊点由液相变为固相所经历的时间。

Coordinatograph **92.0294**

An X- and Y-coordinate plotting and measuring machine.

坐标仪 **92.0294**

X和Y坐标绘制和测量设备。

Coplanar Leads **33.0295**

The flat beam leads of a component package that have been formed so that they can simultaneously contact one plane of a base material.

共面引线 **33.0295**

已成型的元器件封装扁平悬梁式引线，可以同时接触到基材的一个平面。

Coplanarity **33.1656**

The distance in height between the lowest and highest leads when the component is in its seating plane.

共面性 **33.1656**

当元器件处于同一个安装平面时，最低引线与最高引线之间在高度上的距离。

Copolymerize **49.0847**

The creation of a polymer by the joining of two or more different monomers in repeating chain.

共聚 **49.0847**

以重复链共聚两种或多种不同单体形成聚合物的反应。

Copper Island **45.2180**

A piece of copper generated during plane formation that is not connected to power, ground or a signal (active). When the term is used regarding a single layer of data, it may be connected using a via to another layer (see Figure C-12). Several methods of plane generation exist that can generate copper islands.

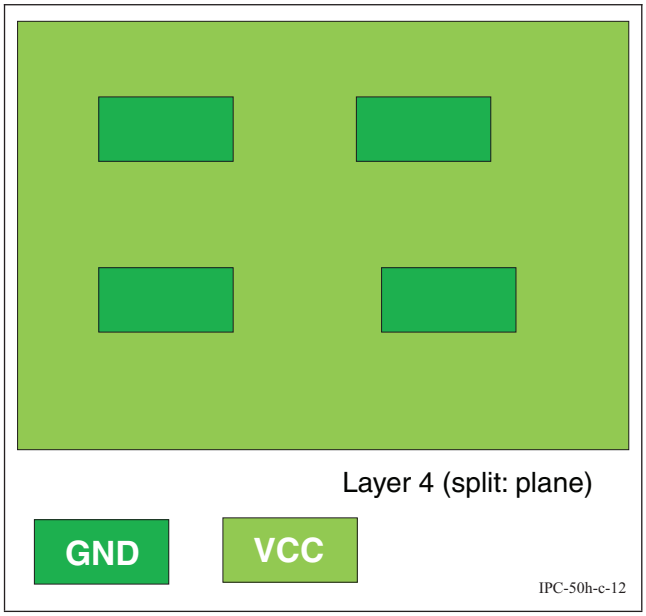


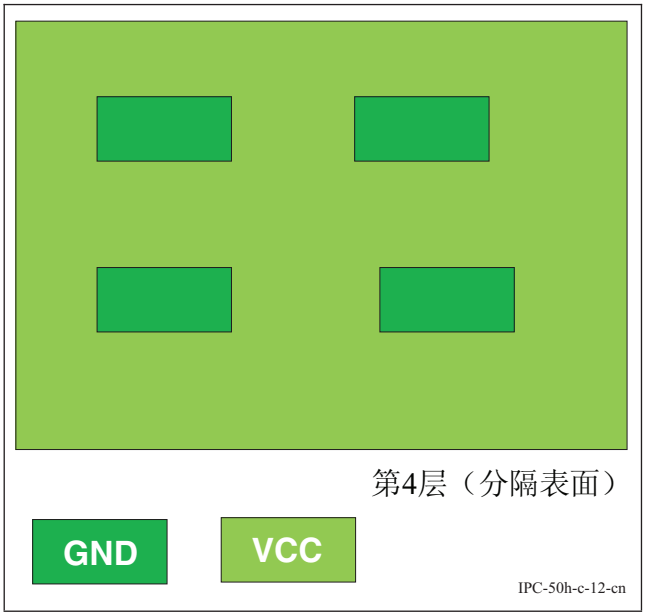
Figure C-12 Copper Island (Data)

铜岛 **45.2180**

面形成期间生成的一片铜，其不与电源、地或信号（主动）连接。对于提供电气数据的单一层，采用该术语时，可采用导通孔使其与另一层连接（见图C-12）。有多种方法可在面形成时生成铜岛。

Copper Thickness **41.1657**

The thickness dimension of the copper cladding on a base material.



图C-12 铜岛（数据）

铜厚 **41.1657**

基材上所覆铜箔的厚度。

Copper Weight **41.1658**

The mass of copper per unit area for a foil, typically expressed in ounces per square foot or grams per square centimeters (these units are not equivalent).

铜重 **41.1658**

单位面积铜箔质量，通常表示为盎司/平方英尺或克/平方厘米。（这些单位不相等。）

Copper-Mirror Test **92.0296**

A test of the corrosivity of a flux on a copper film that is vacuum-deposited on a glass plate.

铜镜测试 **92.0296**

助焊剂对真空沉积至玻璃板上的铜薄膜的腐蚀性测试。

Corner Crack (Knee Crack) **96.1659**

A crack in the plated metal at the knee (the intersection of the hole barrel and the pad or land) of a plated through-hole.

拐角裂纹 **96.1659**

电镀金属在镀覆孔拐角处（孔壁与焊盘或连接盘相交处）的裂纹。

Corner Marks **22.0297**

The marks at the corners of artwork whose inside edges establish, or help to establish, the borders and contour of a printed board.

角标 **22.0297**

照相底版上拐角处的标记，以其内侧边缘来确定或帮助确定印制板的边界和轮廓。

Coronizing **44.0298**

Continuous heat cleaning and weave setting.

高温处理 **44.0298**

连续热清洗和织物定型。

Corrosion (Chemical/Electrolytic) **76.0299**

The attack of chemicals, flux, and flux residues on base metals.

腐蚀（化学/电解） **76.0299**

化学品、助焊剂以及助焊剂残留物对金属基材的侵蚀。

Corrosive Flux **75.0300**

Flux that contains levels of halides, amines, or organic acids that cause corrosion of copper.

腐蚀性助焊剂 **75.0300**

含有一定量的卤化物、胺或有机酸等会腐蚀铜的助焊剂。

Cosine Law (Illumination) **24.1369**

A law of illumination that states that the flux radiated or received in a given direction varies with the projected area of the receiver or emitter in a plane that is perpendicular to the direction of the flux.

余弦定律（照明） **24.1369**

说明给定方向上辐射或接受的光通量与垂直于光通方向平面上接受面的投影面积成正比的照明定律。

Cost of Quality **94.0301**

The money spent in the creation, control, and evaluation of quality and the consequences of the failure to meet specified requirements.

质量成本 **94.0301**

为达到指定要求，用于建立、控制和评价质量以及失效后果所需付出的费用。

Coupon **92.0302**

See “Test Coupon.”

附连板 **92.0302**

见“附连测试板，Test Coupon”。

Coupon (Breakaway) **92.1220**

Coupons made as an integral part of the end product printed board and connected as one piece, except one edge of the coupon has perforations or a thin section connected to the printed board which can be easily broken off without damaging either the coupon or the board.

附连板（可分离） **92.1220**

附连板制成为与成品板连在一起的一部分，但附连板的一个边有邮票孔或较薄部分与成品板相连，可以很容易地分开，对附连板或成品板都不会造成损伤。

Covercoat **42.2139**

Material deposited as a liquid onto the circuitry that subsequently becomes a permanent dielectric coating. (See "Cover Material.")

覆盖涂层 **42.2139**

涂覆在电路上的液体材料，随后成为一种永久性介电涂层。（见“覆盖材料，Cover Material”。）

Coverfilm **42.0303**

Film made from i) a homogeneous, single component; ii) separate layers of generically similar chemistries; or iii) as a composite blend. (See "Cover Material.")

覆盖膜 **42.0303**

由i）单组分均质材料；ii）类似的化合物独立层；iii）混合物制成的膜。（见“覆盖材料，Cover Material”。）

Coverlay **42.0304**

Film and adhesive made from separate layers of generically different chemistries. (See "Cover Material.")

覆盖层 **42.0304**

由属性不同的化合物独立层制成的膜和粘合剂。（见“覆盖材料，Cover Material”。）

Cover Layer (Discrete Wiring) **64.1660**

A polymeric material which is applied to a circuit board over surface wired levels.

覆盖层（分立导线） **64.1660**

涂覆在电路板表面的布线上的聚合材料。

Cover Material **42.2179**

A thin dielectric material used to encapsulate circuitry, most commonly for flexible circuit applications.

覆盖材料 **42.2179**

用于包封电路的薄的介电材料，最常用于挠性电路。

Cpk Index (Cpk) **91.0307**

A measure of the relationship between the scaled distance between the process mean value and the closest specification limit.

过程能力指数（Cpk） **91.0307**

过程平均与最接近的规格限之间比例距离关系的量度。

Crack, Foil **90.0308**

A break or separation that extends partially or completely through a layer of metallic foil.

金属箔裂纹 **90.0308**

部分或全部穿透金属箔层的破裂或分离。

Crack, Plating **90.0309**

A break or separation that extends partially or completely through a metallic coating(s), its overplate, or both.

镀层裂纹 **90.0309**

部分或全部穿透金属镀层、它的外镀层或二者同时穿透的破裂或分离。

Cracking **90.0310**

A condition that makes breaks or separations in coatings that extend through to an underlying surface.

裂缝 **90.0310**

涂覆层中形成破裂或分离，延伸至底层表面的状况。

Cratering (Chip-Out) **95.1663**

A category of ball bond failure in which the ball lifts from the surface of the integrated circuit die bond pad, taking with it a portion of the bond pad metallization and the underlying oxide or silicon.

陷坑 **95.1663**

一种球形键合失效，焊球从集成电路芯片键合焊盘上翘起，附带了一部分键合焊盘金属层和下面的氧化物或硅。

Cratering (Wire Bonding) **74.0311**

A defect in which a portion under a die is torn loose by an excessive amount of ultrasonic wire-bonding energy.

陷坑（金属线键合） **74.0311**

芯片底部的局部因过量的超声金属线键合能量而被撕开变松的缺陷。

Crazing (Base Material) **51.0312**
An internal condition that occurs in reinforced laminate base material whereby glass fibers are separated from the resin at the weave intersections. (This condition manifests itself in the form of connected white spots or crosses that are below the surface of the base material.) It is usually related to mechanically-induced stress. (See “Measling.”)

微裂纹（基材） **51.0312**
发生于增强的层压板基板内部的一种状况。在织物交织处玻璃纤维与树脂分离。（此现象表现为在基材表面下出现的白色斑点或交叉。）这种现象通常与机械应力有关。（又见“白斑，Measling”。）

Crazing (Conformal or Solder Mask Coating) **76.0313**
A network of fine cracks on the surface of or within the coating.

微裂纹（敷形涂覆或阻焊膜涂层） **76.0313**
涂覆层表面或内部细小的网状裂纹。

Crease **92.0314**
A ridge in a material that is caused by a fold or wrinkle being placed under pressure.

褶痕 **92.0314**
材料由于受压时折叠或皱褶所形成的皱纹。

Creel **44.0315**
A device used as a yarn package rack to hold warp ends for a section beam.

经轴架 **44.0315**
放置筒子纱的装置，用来夹持送往分经轴上的经纱。

Creep **40.0316**
Time-dependent strain occurring under stress.

蠕变 **40.0316**
在应力作用下所产生的与时间有关的应变。

Creep Endurance **40.1661**
Resistance against a time dependent strain occurring under stress on a material.

耐蠕变性 **40.1661**
材料抵抗应力作用下产生与时间有关的应变的能力。

Creep Resistant Holding Power (Pressure Sensitive Tape) **46.1869**
The ability of a pressure sensitive adhesive tape to resist static forces of shear applied the same plane as the backing.

抗蠕变保持力（压敏胶带） **46.1869**
压敏胶带抵抗作用于同一背撑面的静态剪切力的能力。

Creepage Distance **21.2080**
The shortest path between two conductors, which includes traces, terminals and structures, measured along the surface of the insulation.

爬电距离 **21.2080**
沿绝缘表面测量所得的两个导体（包括导线、接线柱及结构件）之间的最短路径。

Crevice Corrosion **97.0317**
Localized corrosion that is the result of the formation of a crevice between a metal and a nonmetal, or between two metal surfaces.

裂隙腐蚀 **97.0317**
由于在金属和非金属表面间或两种金属表面间形成裂隙而引起的局部腐蚀。

Crimp Contact **37.0318**
A type of connector contact whose nonmating end is a hollow cylinder that can be crimped onto a wire inserted within it.

压接接触件 **37.0318**
其非配接端是一个中空圆柱的连接器接触件，可以将其压接到插入的导线上。

Critical Current Density **53.0319**
The current density above which a new and sometimes undesirable reaction occurs.

临界电流密度 **53.0319**
高于此电流密度时，会发生新的有时是不希望的反应。

Critical Defect **94.0320**
Any anomaly specified as being unacceptable.

致命缺陷 **94.0320**
任何被规定为不可接受的异常。

Critical Humidity **76.1371**
The relative humidity above which the atmospheric corrosion rate of a given metal increases sharply or above which the insulation decreases sharply.

临界湿度 **76.1371**
高于此相对湿度时，大气对特定金属的腐蚀率会急剧增加，或绝缘性能会急剧下降。

Critical Operation **91.0321**

One procedure of a total process that has a significant impact on the characteristics of the completed product.

关键操作 **91.0321**

整体过程中对成品特性有显著影响的一个步骤。

Critical Solution Temperature **76.0322**

The temperature above or below which two liquids are miscible in all proportions.

临界溶液温度 **76.0322**

高于或低于此温度时，两种液体可以按任何比例混合。

Crop Marks **22.0323**

See “Corner Marks.”

剪切标记 **22.0323**

见“角标，Corner Marks”。

Cross-Over (Discrete Wiring) **64.1662**

A point where tow or more discrete insulated wires intersect and cross each other.

交叉（分离布线） **64.1662**

两条或更多的分离绝缘导线相互交叉的点。

Cross-Sectioning **92.0324**

See “Microsectioning.”

剖切 **92.0324**

见“显微剖切，Microsectioning”。

Crosshatching **22.0325**

The breaking up of large conductive areas by the use of a pattern of voids in the conductive material. (See Figure C-13.)

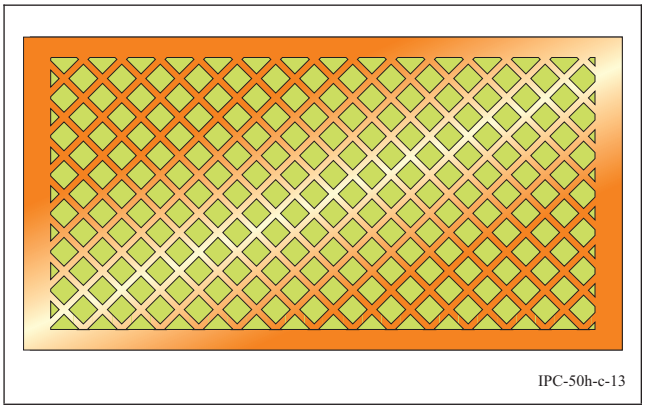
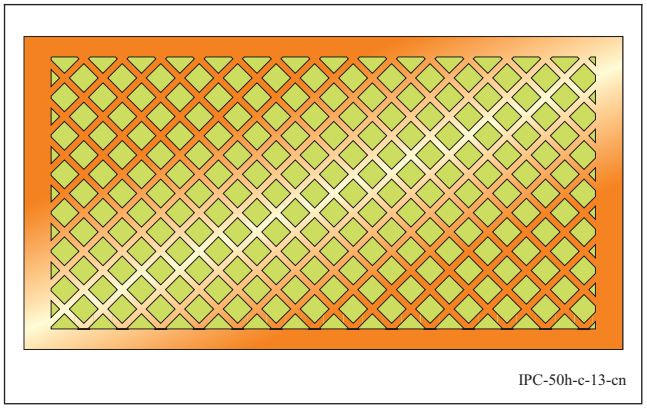


Figure C-13 Crosshatching

开窗口 **22.0325**

在导电材料上用空格图形分割大面积导电区域。（见图C-13。）



图C-13 开窗口

Crossing Count **22.1372**

The unit for measuring optimum component placement characteristics that is based on the number of times there are crossovers of the signal conductor that are used to provide electrical interconnection between devices.

交叉数 **22.1372**

以器件之间提供电气互连的信号导体的交叉次数为基础的衡量元器件最佳布局的指标。

Crosslink **40.0326**

The formation of chemical bonds between molecules in a thermosetting resin.

交联 **40.0326**

在热固性树脂中分子之间形成的化学键。

Crosstalk **21.0327**

The undesirable interference caused by the coupling of energy between signal paths. (See also “Backward Crosstalk” and “Forward Crosstalk.”)

串扰 **21.0327**

由于信号通道之间能量耦合所产生的不希望的干扰。（又见“反向串扰，Backward Crosstalk”和“正向串扰，Forward Crosstalk”。）

Crystalline Polymer **40.0328**

A polymer with a regular, structured molecular configuration.

晶体聚合物 **40.0328**

一种具有规则结构分子形状的聚合物。

Cubic Components **30.1737**

A part with a three-dimensional shape having the form of a cube.

立方体元器件 **30.1737**

一种具有三维外形立方体形状的元器件。

Cumulative Tolerance **22.1373**

The summation of the tolerances that are permitted between functionally-related features. (See also "Baseline Dimensioning," "Basic Dimension," "Chain Dimensioning" and "Direct Dimensioning.")

累积公差 **22.1373**

功能相关的要素之间允许的公差总和。（又见“基线尺寸标注，Baseline Dimensioning”、“基准尺寸标注，Basic Dimensioning”、“链式尺寸标注，Chain Dimensioning”及“直接尺寸标注，Direct Dimensioning”。）

Cup Solder Terminal **37.0329**

A cylindrical solder terminal with a hollow opening into which one or more wires are placed prior to soldering. (See Figure C-14.)

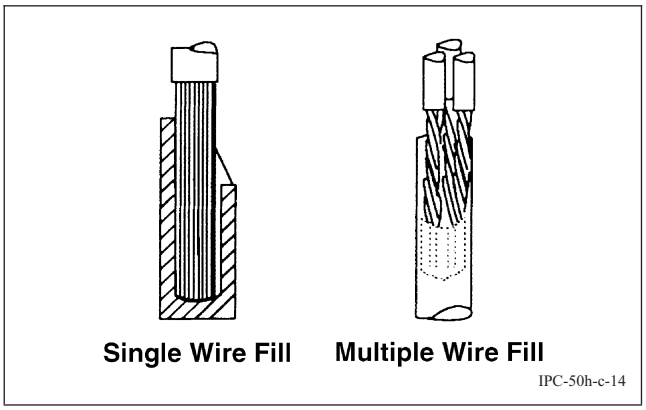
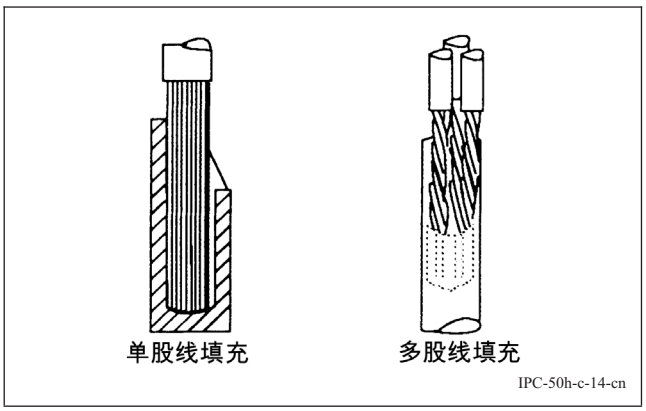


Figure C-14 Cup Solder Terminal

焊锡杯 **37.0329**

有中空开口的圆筒形焊接接线柱，焊接前一根或多根导线可放于中空开口内。（见图C-14。）



图C-14 焊锡杯

Cupping (BGA) **34.2141**

A condition of a ball grid array (BGA) package after reflow where the corners turn up and away from the printed board laminate surface. This condition in the worse case causes the balls on the outside row to be in tension and the balls in the center to be in compression. (Opposite of "Doming (BGA).")

杯形（BGA） **34.2141**

再流焊后，球栅阵列（BGA）封装角部位向上翻起，远离印制板表面。严重时会造成外围的焊料球被拉伸，而中心部分的焊料球被挤压。（与“拱形（BGA），Doming（BGA）”相反的状况。）

Cure **56.0330**

A chemical reaction that changes the physical properties of a substance, e.g., an adhesive.

固化 **56.0330**

改变物质（例如粘接剂）物理特性的化学反应。

Cure Time **56.0331**

The time at which ultimate physical properties of a curing thermosetting plastic composition are reached.

固化时间 **56.0331**

固化中热固性塑性组份达到最终物理性能所需时间。

Curing Agent **56.0332**

A chemical substance that can react with a resin in order to physically harden the resin.

固化剂 **56.0332**

能与树脂反应，使树脂物理硬化的化学物质。

Current **21.1795**

The flow or movement of electrons in a conductor as the result of a voltage difference between the ends of the conductive path.

电流 **21.1795**

由于导电通路两端的电压差，导致电子在导体中流动或移动。

Current-Carrying Capacity **21.1374**

The maximum electrical current that can be carried continuously by a conductor, under specified conditions, without causing objectable degradation of electrical and mechanical properties of the product.

载流量 **21.1374**

在规定条件下，一个导体能够连续地承载，而不会造成产品的电气和机械性能明显降低的最大电流。

Customer Detail Specification (CDS) **26.1779**
A document that establishes the specific requirements, noted in a detailed specification, in order to tailor these to meet the needs of a custom product, material, or service.

客户详细规范（CDS） **26.1779**
为满足定制的产品、材料或服务的需要，建立具体要求并在详细规范中注明的文件。

Customer Test Data **92.1664**
Normal performance data generated at incoming inspection by the customer.

客户测试数据 **92.1664**
用户在来料检验时所产生的常规性能数据。

Cusum Chart **91.0333**
A diagram that depicts cumulative deviation from a target.

累积和图 **91.0333**
描述对目标值的累积偏差的图表。

Cut-and-Peel **24.0334**
See “Cut-and-Strip.”

切割剥离 **24.0334**
见“切割剥除，Cut-and-Strip”。

Cut-and-Strip **24.0335**
The making of artwork by cutting a pattern in a resist and stripping away the unwanted areas or resist.

切割剥除 **24.0335**
制作照相底图的方法，在抗蚀膜上切割图形，并将不需要的区域或抗蚀膜剥除。

Cut-Off **74.0336**
The operation that follows the final bonding step that separates the bond from the source of the wire.

切断 **74.0336**
在键合的最后一道工序之后，将键合点与键合金属线分离的操作。

Cylindrical Components **30.1738**
A part having the shape of a cylinder.

圆柱形元器件 **30.1738**
具有圆柱形状的元器件。

D

D Curve **24.0347**
See “Characteristic Curve.”

D曲线 **24.0347**
见“特性曲线，Characteristic Curve”。

Damage **94.1665**
The result of an event that degrades a product, e.g., component, printed board, module, etc., beyond the form, fit and function limits of the governing document.

损坏 **94.1665**
导致产品（例如元器件、印制板、模块等）受到损害，超出有关控制文件规定的形状、配合和功能要求的一个事件的结果。

Dambar **36.1666**
A portion of the lead frame that prevents mold compound from flowing to the end of the lead frame.

挡条 **36.1666**
引线框架的一部分，可阻止封装料流向引线框架的末端。

Data Capture **25.0340**
The automatic collection of information from a given machine or other information source.

数据获取 **25.0340**
从给定的设备或其它的信息来源自动收集信息。

Data File **11.0341**
A database organized in a specific manner for a specific application.

数据文件 **11.0341**
为特定的应用以特定的方式构成的数据库。

Data Layer **25.0342**
A specific group of related records that are within any individual data-information module.

数据层 **25.0342**
位于任何单独数据信息模块内的一组特定的相关记录。

Data Logging **11.0343**
The ability of a host computer or test analyzer to store analyzed data along with statistical data.

数据记录 **11.0343**
计算机主机或测试分析仪存储已分析数据与统计数据的能力。

Data-Entry Device **25.0337**
A device terminal used to enter information into a computer system. (See also “Control Console.”)

数据输入设备 **25.0337**

用于向计算机系统输入信息的设备终端。（又见“操纵台，Control Console”。）

Data-Information Module (DIM) **25.0338**

A group of records that contain related data that describe a specific function or task.

数据信息模块（DIM） **25.0338**

包含描述特定功能或任务的相关数据的一组记录。

Database **11.0339**

A comprehensive collection of information that is so structured that some or all of its data may be used to create queries about related items contained within it.

数据库 **11.0339**

信息的全面集合，其结构是使其中部分或全部数据可以从其有关所含项目进行查询。

Date Code **30.1739**

Marking of products to indicate their date of manufacture.

日期码 **30.1739**

显示产品制造日期的标志。

Datum **22.0344**

The theoretically-exact point, axis or plane that is the origin from which the location of geometric characteristics of features of a part are established.

基准 **22.0344**

以理论上准确的点、线或面为原点，由此建立零件要素几何特征的位置。

Datum Axis **22.1667**

The theoretical axis derived from the true geometric counterpart of a specified feature (i.e., tooling hole, fiducial) as established by the extremities of contacting points of the actual datum feature.

基准轴 **22.1667**

由表示具体要素（例如：定位孔、基准）的实际几何对应物导出的理论轴，是通过实际基准要素的接触点端部确定的。

Datum Feature **22.0345**

An actual feature of a part that is used to establish a datum.

基准要素 **22.0345**

用于建立基准的部件实际要素。

Datum Reference **22.0346**

A defined point, line or plane that is used to locate a pattern or layer for manufacturing purposes, inspection purposes, or both.

基准参考 **22.0346**

为了制造、检验，用于定位图形或层的规定点、线或面。

Datum Target **22.1668**

A specified point or area on a printed board used to establish a datum.

基准目标 **22.1668**

印制板上用于建立基准的规定点或区域。

Daughter Board **81.1669**

A printed board that is fastened to a mother board and electrically connected.

子板 **81.1669**

固定于母板上并与之实现电气连接的印制板。

Decomposition Temperature (TD) **55.2085**

The temperature at which a base laminate material experiences an established percentage of weight loss using Thermogravimetric Analysis (TGA).

分解温度（TD） **55.2085**

采用热重分析法使层压板基材的重量损失达到规定百分比时的温度。

Decoupling **21.1375**

The absorbing of noise pulses in power supply lines, that was generated by switching logic devices, so as to prevent the lines from disturbing other logic devices in the same power-supply circuit.

退耦 **21.1375**

在电源电路中吸收由于开关逻辑器件产生的噪音脉冲，以防止同一电源电路中其它逻辑器件受到干扰。

Defect **90.0348**

Nonfulfillment of a requirement related to an intended or specified use.

缺陷 **90.0348**

无法满足预期或规定使用要求的情况。

Defect Identification **90.0349**

The provision for recording the location of a detected anomaly.

缺陷标识 **90.0349**

记录已检出异常的位置的规定。

Definition **52.1701**
Degree of conformity of the pattern edges with the production master.

逼真度 **52.1701**
图形边缘与生产底版的一致程度。

Definition (Phototool) **24.0350**
The clarity of detail in an optically-produced image.

清晰度（底片） **24.0350**
光学形成的图像细节的清晰程度。

Degradation **90.0351**
A decrease in the performance characteristics or service life of a product.

退化 **90.0351**
产品的性能特性或服务寿命的减少。

Degrees of Freedom (df) **94.0352**
The number of comparisons that are available in order to learn about an event.

自由度（df） **94.0352**
为了了解一个事件，所能得到的比较量的数目。

Delamination **55.1376**
A separation between plies within a base material, between a base material and a conductive foil, or any other planar separation within a printed board. (See also “Blister.”)

分层 **55.1376**
印制板上绝缘基材层间、基材与导电箔间或内部任何平面间的分离现象。（又见“起泡，Blister”。）

Delivered Panel (DP) **50.1788**
A production or prototype panel, or portion of either, intended to contain one or more printed boards in a specific arrangement or cluster, in order to facilitate economic assembly and testing in the next level of manufacturing. (See also “Pallet (Printed Board).”)

交付拼板（DP） **50.1788**
生产拼板或原型拼板，或其中一种的一部分，设计含有以特定形式排列的一组一种或多种印制板，以便在下一级生产中降低组装与测试成本。（又见“托盘（印制板），Pallet（Printed Board）”。）

Delivery Inspection **92.1670**
See “Final Inspection.”

交付检验 **92.1670**
见“最终检验，Final Inspection”。

Dendritic Growth **90.0353**
Metallic filaments that grow between conductors in the presence of condensed moisture and an electric bias. (See also “Whiskers.”)

树枝状生长 **90.0353**
有冷凝湿气及存在电偏压时，导体间生长的金属细丝。（又见“晶须，Whiskers”。）

Dendritic Migration **90.0354**
Migration that proceeds through an insulator in a “treeing” fashion.

树枝状迁移 **90.0354**
以“树枝状结晶”形式发生的穿过绝缘体的迁移。

Denier **44.0355**
The weight, in grams, of 9000 meters of fiber, filament or yarn.

丹尼尔 **44.0355**
长度为9000米的纤维、细线或纱的重量，以克为单位。

Densitometer **24.0356**
An instrument that is used to measure the amount of light that has been absorbed by a photographic film.

显像密度计 **24.0356**
用于测量被照相底片所吸收光的量的仪器。

Density (Material) **40.1675**
The mass of a substance per unit volume.

密度（材料） **40.1675**
物质单位体积的质量。

Density (Phototool) **24.0357**
The logarithm of the value of opacity.

光密度（底片） **24.0357**
遮光率的对数。

Dent **45.0358**
A smooth depression in conductive foil that does not significantly reduce the foil’s thickness.

压痕 **45.0358**
箔厚度未明显减少的导电箔内的平滑凹陷。

Dentrices **90.0359**
See “Dendritic Migration.”

树枝状物 **90.0359**
见“树枝状迁移，Dendritic Migration”。

Dependent of Feature Size **22.0360**

The concept that permits tolerances of form or position to vary in proportion to, and dependent on, a feature's size.

要素尺寸相关原则 **22.0360**

允许外形或定位公差与要素尺寸成比例变化，即其取决于要素尺寸的概念。

Depth of Field (Optical) **24.0361**

The range of distances along the axis of an optical instrument, usually a camera lens, through which an object will produce a relatively distinct image.

景深（光学） **24.0361**

为使物体保持相对清晰的图像，沿光学仪器的（通常指照相机镜头）轴向的距离范围。

Desiccant **30.1679**

An absorbent material used to maintain a low relative humidity.

干燥剂 **30.1679**

用于维持低相对湿度的吸收材料。

Design Automation **20.1377**

The use of computer systems, programs, and procedures in the design process wherein, the computer is responsible for the decision-making activity and data manipulation function.

设计自动化 **20.1377**

设计过程中计算机系统、程序及步骤的使用，由计算机负责决策行为及数据处理功能。

Design Spacing of Conductor Traces or Planes **22.0364**

The spacing between conductors as delineated or otherwise noted on the master drawing. (See also "Conductor Base Spacing.")

导体线条或导体面的设计间距 **22.0364**

布设总图上绘制或注明的相邻导体之间的距离（又见"导体基底间距，Conductor Base Spacing"。）

Design Width of Conductor Trace or Plane **22.0365**

The width of conductors as delineated or otherwise noted on the master drawing. (See also "Conductor Base Width" and "Conductor Width.")

导体线条或导体面的设计宽度 **22.0365**

布设总图上绘制或注明的导体宽度（又见"导体基底宽度，Conductor Base Width"和"导体宽度，Conductor Width"。）

Design Rule **22.0363**

Guidelines that determine automatic conductor routing behavior with respect to specified design parameters.

设计规则 **22.0363**

根据特定设计参数确定导体自动布设过程的准则。

Design-Rule Checking **22.0362**

The use of a computer-aided design program to perform continuity verification of all conductor routing in accordance with appropriate design rules.

设计规则检查 **22.0362**

使用计算机辅助设计程序，按照适当的设计规则，对所有导体布线的连通性进行验证。

Desmear **57.0366**

The removal of friction-melted resin and drilling debris from a hole wall.

去钻污 **57.0366**

去除孔壁上的摩擦熔融树脂和钻屑。

Destructive Physical Analysis (DPA) **92.1680**

A process of determination of device construction or failure modes.

破坏性物理分析（DPA） **92.1680**

确定元器件结构或失效模式的过程。

Detail Specification **26.1740**

A detailed written description of a part or a process.

详细规范 **26.1740**

对一个零件或一个过程的书面详细描述。

Detailed Specification (DS) **26.1781**

A document that describes the exact requirements for a specific product, material, or service.

详细规范（DS） **26.1781**

描述特定产品、材料或服务精确要求的文件。

Detection **91.0367**

A strategy that attempts to identify and separate acceptable and unacceptable outputs from a process.

检测 **91.0367**

力图识别和区分一个过程的可接受输出与不可接受输出的策略。

Developing (Phototool) **24.0368**

The chemical treatment of radiation-modified photosensitive material in order to produce an image.

显影（底片） **24.0368**

对已感光的光敏材料进行的化学处理以显出影像。

Development (Resist) **52.1682**

The process of exposing a photoresist to a chemical solution which dissolves unwanted material and without affecting wanted material. The standard method of distinguishing between wanted and unwanted material is by polymerizing the resist so as to make it less soluble in the development solvent.

显影（抗蚀剂） **52.1682**

将光致抗蚀剂暴露于化学溶液中，溶解不需要的材料，保留需要的材料的工艺过程。区别需要及不需要材料的标准方法是让抗蚀剂聚合，使其在显影溶剂中不易溶解。

Device **30.0369**

An individual electrical circuit element that cannot be further reduced without destroying its stated function.

器件 **30.0369**

一个独立的电路元器件，如不损坏其原有功能则无法再作分割。

Dewetting **97.0370**

A condition that results when molten solder coats a surface and then recedes to leave irregularly-shaped mounds of solder that are separated by areas that are covered with a thin film of solder and with the basis metal not exposed. (See Figure D-1.)

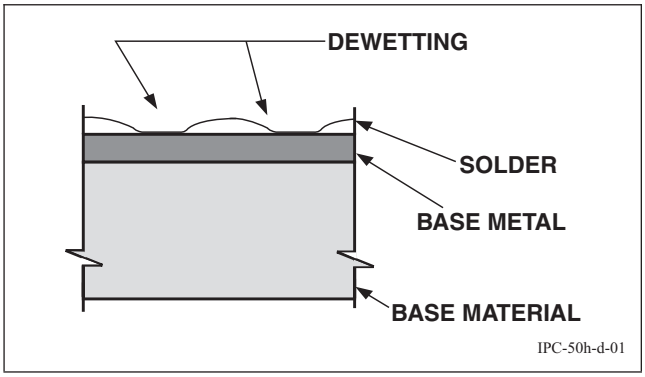


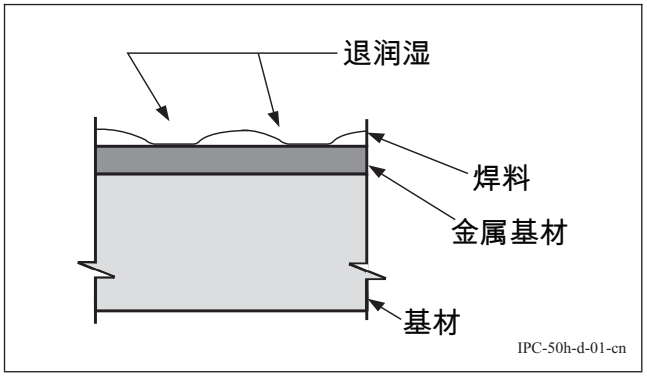
Figure D-1 Dewetting

退润湿 **97.0370**

熔融焊料涂覆在金属表面上然后焊料回缩，导致形成由焊料薄膜覆盖且未暴露金属基材的区域分隔开的不规则焊料堆的一种状况。（见图D-1。）

Dewetting (Base Materials) **40.1684**

A loss or reduction of resin coverage from localized or large areas of reinforcement.



图D-1 退润湿

半润湿（基材） **40.1684**

局部或大面积的增强材料所涂覆树脂的缺失或减少。

Diazo Material **24.0371**

A nonsilver, room-light handling, ultraviolet-sensitive material, used as a coating film for creating phototools.

重氮材料 **24.0371**

不含银盐且可在室内光线下处置的紫外光敏感材料，可用作生成底片的涂层膜。

Dibasic Acid **76.0372**

An acid containing two atoms of acidic hydrogen in a molecule.

二元酸 **76.0372**

一个分子中含有两个酸性氢原子的一种酸。

Dice **35.0373**

Two or more die.

芯片群 **35.0373**

两个或多个芯片。

Dicing **35.1685**

The separating of semiconductor wafers into individual die.

切片 **35.1685**

将半导体晶圆分割成单个芯片。

Dicyandiamide **41.0374**

A solid curing agent for epoxy resins.

双氰胺 **41.0374**

环氧树脂用固体固化剂。

Die **35.0375**

The uncased and normally leadless form of an electronic component that is either active or passive, discrete or integrated. (See also “Dice.”)

芯片 **35.0375**
无外壳的电子元器件，通常为无引线形式，可以是有源的或无源的，分立的或集成的。（又见“芯片群，Dice”。）

Die Attached Pad **35.1688**
See “Die Pad.”

芯片连接盘 **35.1688**
见“芯片焊盘，Die Pad”。

Die Bonding **74.0376**
The attachment of a die to base material.

芯片键合 **74.0376**
将芯片连接到基材上。

Die Mount Pad **35.1689**
See “Die Pad.”

芯片安装盘 **35.1689**
见“芯片焊盘，Die Pad”。

Die Pad **35.1687**
A land on which the integrated circuit die is mounted during the assembly process.

芯片焊盘 **35.1687**
组装过程中集成电路芯片贴装在其上的连接盘。

Die Paddle **35.1686**
The central portion of the lead frame on which the die and adhesive are placed during the attachment process.

芯片座 **35.1686**
引线框架的中心部分，连接过程中粘接剂和芯片放置于其上。

Die Shrink **35.1690**
Method of reducing silicon area used for the same circuitry by reducing layout feature size by a common percentage for all levels.

芯片缩小 **35.1690**
通过按照相同比例减小同一电路各层布局要素尺寸的大小，减小同一电路所用硅片面积的方法。

Die Stamping (Conductor) **53.1691**
A process to make a conductive circuit in which the patterns are stamped out of a metal sheet.

模具压印法（导体） **53.1691**
制造导电电路的一种工艺，导电图形是从金属薄片上冲压出来的。

Dielectric **40.0377**
A material with a high resistance to the flow of direct current, and which is capable of being polarized by an electrical field.

电介质 **40.0377**
对直流电流有高阻抗，且能够被电场极化的材料。

Dielectric Breakdown **21.1378**
The complete failure of a dielectric material that is characterized by a disruptive electrical discharge through the material that is due to deterioration of material or due to an excessive sudden increase in applied voltage.

介电击穿 **21.1378**
由于材料老化或施加的电压过度骤增而引起绝缘材料的完全失效，表现为贯穿材料的击穿放电。

Dielectric Constant **21.1379**
The ratio of the capacitance of a configuration of electrodes with a specific material as the dielectric between them to the capacitance of the same electrode configuration with a vacuum or air as the dielectric. See “Permittivity.”

介电常数 **21.1379**
规定结构的电极间，以某种材料作为介质时的电容量与相同结构电极间以真空或空气作介质时的电容量之比。（又见“电容率，Permittivity”。）

Dielectric Fluid **21.0378**
A fluid that has excellent dielectric strength, excellent volume resistivity, a low dielectric constant, and a low dissipation factor.

绝缘液 **21.0378**
具有极佳介电强度、极佳体积电阻率、低介电常数及低损耗因数的液体。

Dielectric Strength **21.1380**
The maximum voltage that a dielectric can withstand under specified conditions without resulting in a voltage breakdown, usually expressed as volts per unit dimension.

介电强度 **21.1380**
介电质在规定条件下能承受且不会造成电压击穿的最大电压，通常以每单位面积上的伏特表示。

Differential Etching **54.1692**
The process of removing copper from a conductive pattern that has been plated on a starting thin copper foil such that the portions of the thin starting foil are completely removed and the thicker plated portions are slightly reduced by the etchant.

差分蚀刻法 **54.1692**
一种从导电图形上除去铜的过程。因导电图形的原有薄铜箔已被电镀增厚，以致在蚀刻过程中，原有的薄铜箔部分被完全除去，而电镀增厚的导电图形部分蚀刻后稍微减薄。

Diffusion Bond **74.0379**
A bond formed in the absence of any liquid phase at any time prior to or during the joining process.

扩散键合 **74.0379**
在键合工艺前或键合工艺中任何时间均无液相所形成的键合。

Digital Circuit **21.0380**
An electrical circuit that provides two (binary) or three distinct relationships (states) between its input and output.

数字电路 **21.0380**
在其输入与输出间提供两种（二进制）或三种明显关系（状态）的电路。

Digitizing (CAD) **25.0381**
The converting of feature locations on a flat plane to its digital representation in X-Y coordinates.

数字化（CAD） **25.0381**
将平面上的要素位置转换成用X-Y坐标数字表示。

Dilution Ratio **76.1221**
The maximum number of unit volumes of hydrocarbons that can be added per unit volume of active solvent in order to cause the first trace of gelation to occur when the concentration of nitrocellulose in the solution is 8-grams per 100-milliliters.

稀释比 **76.1221**
当溶液中硝化纤维素的浓度为8g / 100ml时，为了产生最初的胶凝迹象，每单位体积活性溶剂中可以加入烃的最大单位体积数。

Dimensional Stability **21.1381**
A measure of the dimensional change of material that is caused by factors such as temperature changes, humidity changes, chemical treatment (aging), and stress exposure.

尺寸稳定性 **21.1381**
由于温度变化、湿度变化、化学处理（老化）及经受的应力等因素导致的材料尺寸变化的量度。

Dimensioned Hole **22.0382**
A hole in a printed board whose location is determined by physical dimensions or coordinate values that do not necessarily coincide with the stated grid.

尺寸孔 **22.0382**
印制板中由物理尺寸或坐标值确定位置的孔，它不必与规定的网格重合。

Dimorphism **40.0383**
The existence of a substance in two different crystalline forms.

双晶现象 **40.0383**
物质结构中存在两种不同晶形。

Dip Soldering **75.1382**
The making of soldered terminations simultaneously by bringing the solder side of a printed board with through-hole mounted components into contact with the surface of a static pool of molten solder. (See also “Drag Soldering.”)

浸焊 **75.1382**
将装有通孔插装器件的印制板焊接面与静止的熔融焊料槽表面接触，同时形成焊接端接。（又见“拖焊，Drag Soldering”。）

Diphase Cleaning **76.0384**
Cleaning by means of solutions that contain a solvent layer and an aqueous layer.

双相清洗 **76.0384**
利用含有溶剂层及水层的溶液进行清洗。

Dipole (Electronic) **21.0385**
An assemblage of atoms or subatomic particles, separated by a finite distance, that have equal electric charges of opposite sign.

偶极（电子） **21.0385**
电荷相等但电性相反且相隔一定距离的原子或亚原子粒子集合。

Dipole Moment **21.1383**
Molecules in which the atoms, their electrons, and their nuclei, are so arranged that one part of the molecule has a positive electrical charge while the other part is negatively charged

偶极矩 **21.1383**
分子中原子、电子及其原子核的排列方式，使分子的一部分具有正电荷，而另一部分具有负电荷。

Direct Cleaning **76.0386**
See “Cathodic Cleaning.”

直接清洗 **76.0386**
见“阴极清洗，Cathodic Cleaning”。

Direct Current (DC) **21.1796**
A current produced by a voltage source that does not vary with time and is normally provided by power supplies, transformers or batteries to power electronic circuits.

直流电（DC） **21.1796**
由电压源产生的不随时间变化的电流，通常由电源、变压器或电池向电子电路供电。

Direct Current Cleaning **76.0387**
See “Cathodic Cleaning.”

直流电清洗 **76.0387**
见“阴极清洗，Cathodic Cleaning”。

Direct Dimensioning **22.0388**
The maximum variation between two features that is controlled by the tolerance on the dimension between the features.

直接尺寸标注 **22.0388**
由两要素间尺寸公差所控制的两要素间最大变差。

Discrepant Material **92.0389**
Material that does not conform to specification.

不合格材料 **92.0389**
不符合规范的材料。

Discrete Component **30.0392**
A separate part of a printed board assembly that performs a circuit function, e.g., a resistor, a capacitor, a transistor, etc.

分立元器件 **30.0392**
印制板组装件中执行一项电路功能的独立部件，如电阻、电容、晶体管。

Discrete Wiring **64.1693**
A conductive pattern established by techniques other than printing, plating, and/or etching, that provides point-to-point connections in a predetermined arrangement on a common base.

分立线路 **64.1693**
通过印刷、电镀和/或蚀刻以外的技术建立的导电图形，在共同的基材上按照预先确定的布局实现点到点的连接。

Discrete Wiring Board **64.0390**
A base material upon which discrete wiring techniques are used to obtain electrical interconnections.

分立布线板 **64.0390**
采用分立线路技术实现电气互连的基材。

Discrete Wiring Board Assembly **64.0391**
An assembly that uses a discrete wiring board for component mounting and interconnecting purposes.

分立布线板组件 **64.0391**
用分立布线板实现元器件安装及互连的组件。

Dispersant (Organosol) **41.0393**
A liquid component that has a solvating or peptizing action on a resin so as to aid in dispersing and spreading it.

分散剂（有机溶剂） **41.0393**
对树脂有溶解或胶溶作用的液体组分，以帮助分散及涂布树脂。

Disperse Phase (Suspension) **41.0394**
The particles of solid material dispersed in a liquid medium.

分散相（悬浮） **41.0394**
分散在液体介质中的固体材料颗粒。

Dispersing Agent **41.0395**
A surface-active agent added to a suspending medium to promote uniform separation of extremely-fine solid particles.

分散剂 **41.0395**
加在悬浮介质中以促进超细固体颗粒的均匀分散的表面活性剂。

Disposition (Defects) **91.1694**
The determination of how defects should be treated. Dispositions include, but are not limited to, rework, use as is, scrap or repair.

处置（缺陷） **91.1694**
如何处理缺陷的决定。处置包括但并不只限于返工、照样使用、报废或维修。

Dissipation Factor **21.0396**
The ratio of loss current to charging current. The dissipation factor or loss tangent, tanδ, is given by εO/εN, where εN and εO are the real and imaginary parts of the permittivity. (See “Permittivity.”) The loss tangent is a parameter used to express the tendency of insulators or dielectrics to absorb some of the energy in an ac signal.

损耗因子 **21.0396**
损耗电流与充电电流之比。损耗因数或损耗正切（tanδ）由εO/εN得出，εN和εO分别为电容率的实部和虚部（见“电容率，Permittivity”）。损耗正切是用以表示绝缘体或介质吸收交流信号能量趋势的参数。

Dissolution of Metallization **36.1741**
The process of dissolving metal, usually by the introduction of chemicals. (See also “Leaching, Metallization.”)

金属层溶蚀 **36.1741**
通常由于采用化学品引起的溶解金属的过程。（又见“金属层浸析，Leaching, Metallization”。）

Dissolution of Termination Metallization (Leaching) **75.1695**
See “Leaching, Metallization.”

端子金属层溶蚀（浸析） **75.1695**
见“金属层浸析，Leaching, Metallization”。

Distance to Neutral Point (DNP) **35.1696**
The linear separation of a joint from the neutral point on a chip. This dimension controls the strain on the joint imposed by expansion mismatch between chip and substrate.

距中点距离（DNP） **35.1696**
焊点距芯片中点的直线距离。这个尺寸可控制由芯片与基板之间膨胀错位导致的焊点张力。

Distributed Numerical Control (DNC) **25.0398**
A network that links computer programs or computer-aided systems to numerically-controlled machine tools.

分布式数控（DNC） **25.0398**
连接计算机程序或计算机辅助系统到数控设备的网络。

Disturbed Solder Connection **97.1384**
A solder connection that is characterized by the appearance that there was motion between the metals being joined when the solder was solidifying.

受扰焊接连接 **97.1384**
焊料凝固时，由于被连接金属之间有移动而在外观上表现出来的焊接连接。

Doming (BGA) **34.2142**
A condition of a ball grid array (BGA) package after reflow where the corners turn down and toward the printed board laminate surface. This condition in the worse case causes the balls on the outside row to be in compression and the balls in the center to be in tension. (Opposite of “Cupping (BGA).”)

拱形（BGA） **34.2142**
再流焊后，球栅陈列（BGA）封装角部位向下弯曲，朝向印制板表面。严重时会造成位于外围的焊料球被挤压，而中心部分的焊料球被拉伸。（与“杯形（BGA），Cupping（BGA）”相反的状况。）

Don’t Care Area **22.0399**
See “Exclusion Area.”

忽略区 **22.0399**
见“免检区，Exclusion Area”。

Doping **35.0400**
The addition of an impurity to alter the conductivity of a semiconductor die.

掺杂质 **35.0400**
为改变半导体芯片的导电率而加入一种杂质。

Double-Sided Assembly **80.0401**
A packaging and interconnecting structure with components mounted on both the primary and secondary sides. (See also “Single-Sided Assembly.”)

双面组件 **80.0401**
主面及其次面都安装元器件的封装与互联结构。（又见“单面组件，Single-Sided Assembly”。）

Double-Sided Printed Board **60.0402**
A printed board with a conductive pattern on both of its sides.

双面印制板 **60.0402**
两面均有导电图形的印制版。

Double-Sided Flexible Printed Wiring Board **62.1697**
See “Flexible Double-Sided Printed Board.”

双面挠性印制线路板 **62.1697**
见“挠性双面印制板，Flexible Double-Sided Printed Board”。

Double-Sided Printed Wiring Board **60.1698**
See “Double-Sided Printed Board.”

双面印制线路板 **60.1698**
见“双面印制板，Double-Sided Printed Board”。

Doubled-Treated Foil (DTF) **45.1700**
Application of a chemical adhesion promoter treatment that is placed on both surfaces of the copper (matte and drum sides).

双面处理金属箔（DTF） **45.1700**
采用化学附着催化剂处理铜箔的两个表面（粗面和鼓面）。

Download, Computer **11.1385**
The transfer of computer programs or data from a computer to a lower-level computer.

计算机下载 **11.1385**

将计算机程序或数据从一台计算机传输至低级别的计算机。

Download, Tester **92.0403**

The ability of a test analyzer to provide failure analysis and data logging information to a host computer.

测试仪下载 **92.0403**

测试分析仪向计算机主机提供失效分析和数据记录信息的能力。

Drafting Image **26.0404**

An image that is part of a master drawing or layout.

绘制图像 **26.0404**

部分布设总图或电路图的图像。

Drag Soldering **75.1386**

The making of soldered terminations by moving the solder side of a supported printed board with through-hole mounted components through the surface of a static pool of molten solder. (See also “Dip Soldering.”)

拖焊 **75.1386**

移动受支撑的装有通孔插装元器件的印制板组件焊接面通过静止的熔融焊料槽表面形成焊接端接。（又见“浸焊，Dip Soldering”。）

Drain Wire **37.0405**

An uninsulated wire that is used for the electrical termination of a shield or ground plane.

加蔽线 **37.0405**

用作屏蔽层或接地层电气端接的非绝缘导线。

Drawbridged Component **73.0406**

See “Tombstoned Component.”

吊桥元器件 **73.0406**

见“墓碑状元器件，Tombstoned Component”。

Drilling **51.1703**

A process for making holes using a drill bit or laser.

钻孔 **51.1703**

采用钻头或激光制作孔的工艺。

Drill Bit **51.1702**

A rod with spiral flutes (grooves) and an obtuse angled point with sharpened cutting edges used to make holes by rotary action.

钻头 **51.1702**

带有螺旋凹槽（沟）的杆，头部为带有刃口的钝角尖，通过旋转运动制作孔。

Drill Body Length **51.0407**

The distance from the drill point to the intersection of the drill diameter and shoulder angle.

钻体长度 **51.0407**

从钻尖至钻头直径与肩角部交线处的距离。

Drill Diameter **51.0408**

The actual size of the drill body.

钻头直径 **51.0408**

钻体的实际尺寸。

Drill Point Concentricity **51.0409**

The total variation of the location of the chisel point of a rotated drill shank.

钻尖同心度 **51.0409**

旋转钻柄的钻尖位置总变差。

Dross **75.0410**

Oxide and other contaminants that form on the surface of molten solder.

焊渣 **75.0410**

熔融焊料表面形成的氧化物及其它污染物。

Drying (Solder Paste) **75.1708**

Ambient or heating process to evaporate volatile components from solder paste which may or may not result in melting of rosin/resin.

烘干（焊膏） **75.1708**

蒸发焊膏中挥发性组分的室温或加热过程，这些组分可能会、也可能不会导致松香/树脂熔融。

Dry Film Resist **52.1705**

A composite material where a photosensitive emulsion that is sensitive to portions of the light spectrum and is either carried by or sandwiched between polymer release films and is used to expose imagery on printed boards.

干膜抗蚀剂 **52.1705**

均匀掺有或夹有感应光谱的感光乳剂聚合薄膜，是用于印制板曝光成像的合成材料。

Dry Glass (Clad Laminate) **41.1706**

A general reference to the appearance of a laminate where the reinforcement is highly visible, due to low/lost resin content or poor wetting/encapsulation of the resin to the reinforcement, although the resin coverage is acceptable.

干玻（覆箔层压板） **41.1706**

明显可见增强材料的层压板外观的通称，原因是树脂含量低/缺失或树脂对增强材料的润湿/密封不佳，尽管树脂涂覆可接收。

Dual Fixture **92.0411**

A test fixture with two separate bed-of-nails units.

双组夹具 **92.0411**

具有两套分离的针床单元的测试夹具。

Dual-Inline Package (DIP) **31.1387**

An electronic device package with a rectangular housing and two parallel rows of electrical connecting pins, usually protruding from the longer sides of the package and bent downward.

双列直插封装（DIP） **31.1387**

具有矩形壳体的电子元器件封装，通常其两列平行的电子连接插针从封装本体的长边向外引出，再向下弯曲。

Dual-Strip Line **21.1797**

A balanced stripline configuration (See “Stripline” and “Balanced Transmission Line.”) This structure consists of two layers of signal lines located between two reference planes.

双带状线 **21.1797**

一种平衡带状线构造。（见“带状线，Stripline”和“平衡传输线，Balanced Transimission Line”。）该结构由位于两个基准面之间的两层信号线组成。

E

E Glass **44.0423**

A low alkali lime alumina borosilicate glass with good electrical properties.

E玻璃 **44.0423**

具有良好电气性能的低碱石灰氧化铝硼硅酸盐玻璃。

Edge Definition **92.0415**

The reproduction fidelity of a pattern’s edge relative to the production master.

边缘精度 **92.0415**

从生产底版制成图形时其边缘的再现精度。

Edge Detection **92.0416**

The ability to recognize (differentiate) the location of an edge.

边缘检查 **92.0416**

判别（区别）边缘位置的能力。

Edge Rate **21.0417**

The rate of change in voltage with time of a logic signal transition.

前沿速率 **21.0417**

逻辑信号跳变时电压随时间的变化率。

Edge Short **74.0418**

An electrical short caused by carrier tape leads making contact with the edge of a semiconductor die.

边缘短路 **74.0418**

由于载带引线与半导体芯片边缘相接触引起的电气短路。

Edge Spacing **22.0419**

The distance of a pattern or component body from the edges of a printed board. (See also “Margin.”)

边缘间距 **22.0419**

导电图形或元器件本体到印制板边缘的距离。（又见“边距，Margin”。）

Edge-Board Connector **37.0412**

A connector that is used specifically for making nonpermanent interconnections with the edge-board contacts on a printed board.

板边连接器 **37.0412**

专门用于实现与印制板板边接触片非永久性互连的连接器。

Edge-Board Contact(s) **22.0413**

Printed contact(s) on or near any edge of a printed board, that are used specifically for mating with edge-board connectors.

板边接触片 **22.0413**

印制板任意边缘或附近的印制接触片，专用于与板边连接器配接。

Edge-to-Edge Spacing **22.0414**

See “Conductor Spacing.”

边至边间距 **22.0414**
见“导体间距，Conductor Spacing”。

Edge-Transmission Attenuation **21.1388**
The loss of a logic signal’s switching-edge sharpness that has been caused by the absorption of the highest-frequency components by the transmission line.

边沿传输衰减 **21.1388**
由于传输线对高频成分的吸收而引起的逻辑信号转换边沿尖锐度的损耗。

Effective Color Temperature **24.0420**
A color temperature based on an approximation of an equivalent continuous spectrum resultant source, expressed in degrees Kelvin (K).

有效色温 **24.0420**
基于等效连续光谱合成源的近似值的色温，以开氏度数（K）表示。

Effective Focal Length **24.0421**
A measure of the distance from the principal point of a magnification device’s optical system to the corresponding focal point.

有效焦距 **24.0421**
放大设备的光学系统的主点到其相应焦点距离的量度。

Effective Permittivity **21.0422**
The permittivity of a mixed media configuration, such as air and the solid dielectrics used in microstrip, that has the equivalent electromagnetic wave propagation characteristics of a single dielectric medium.

有效电容率 **21.0422**
混合电介质结构的电容率，例如用于微带线内的空气和固体电介质，相当于电磁波在单一电介质的传输特性。

Effective Relative Dielectric Constant **21.1798**
The relative permittivity (see “Dielectric Constant”) of a mixed media configuration, such as air and the solid dielectrics used in microstrip, that has the equivalent electromagnetic wave propagation characteristics of a single dielectric medium.

有效相对介电常数 **21.1798**
混合介质结构的相对介电常数（见“介电常数，Dielectric Constant”。），例如用于微波传送带内的气体和固体电介质，相当于电磁波在单一电介质的传输特性。

Elastomeric Connector **36.0424**
A pliant strip of flexible material with insulating and conductive elements intended for providing electrical interconnections.

弹性连接器 **36.0424**
具有用以实现电气互连的绝缘和导电部件的易弯曲挠性材料片。

Electrical Characteristics **21.1742**
The distinguishing electrical traits or properties of a component or assembly.

电气特性 **21.1742**
元器件或组件的显著的电气特性或属性。

Electrical Clearance **21.2079**
The shortest distance between two conductors, which includes traces, terminals and structures, measured through air.

电气间隙 **21.2079**
两个导体（包括导体线条、接线柱和导体构件）之间的最小直线距离。

Electrical Resistance **21.1712**
See “Resistance.”

电气阻抗 **21.1712**
见“电阻，Resistance”。

Electrodeposited Foil **45.0425**
A metal foil that is produced by electrodeposition of the metal onto a material acting as a cathode.

电沉积金属箔 **45.0425**
将金属电沉积在材料上作为阴极而形成的金属箔。

Electrodeposition **53.0426**
The deposition of a conductive material from a plating solution by the application of electrical current.

电沉积 **53.0426**
通过施加电流，电镀溶液中导电材料的沉积。

Electroless Deposition **53.0427**
The deposition of conductive material from an autocatalytic plating solution without the application of electrical current.

无电沉积 **53.0427**
不施加电流，自动催化电镀溶液中导电材料的沉积。

Electroless Plating **53.0428**
See “Electroless Deposition.”

无电电镀 **53.0428**

见“无电沉积，Electroless Deposition”。

Electrolytic Cleaning **76.0429**

Cleaning in which a current is passed through an alkaline solution with the part to be cleaned being one of the electrodes.

电解清洗 **76.0429**

以被清洗件作为电极之一，在碱性溶液中通以电流而进行的清洗。

Electrolytic Corrosion **76.1713**

Corrosion caused by an electrochemical reaction.

电解腐蚀 **76.1713**

电化学反应造成的腐蚀。

Electrolytic Corrosion Factor (Pressure Sensitive Tape) **75.1714**

A measure of the pressure sensitive adhesive tape's corrosive effect on a copper conductor.

电解腐蚀因子（压敏胶带） **75.1714**

压敏胶带对铜导体的腐蚀作用的量度。

Electrolytic Deposition **53.0430**

See “Electrodeposition.”

电解沉积 **53.0430**

见“电沉积，Electrodeposition”。

Electromagnetic Interference (EMI) **21.0431**

Unwanted electromagnetic energy that may couple into electrical circuits and adversely affect their performance.

电磁干扰（EMI） **21.0431**

可能耦合于电路中且对电路性能起反作用的不需要的电磁能。

Electromigration **96.1715**

An undesirable phenomenon in which metal ions migrate through a suitable medium under the influence of an electrical field.

电迁移 **96.1715**

在电场的影响下，不希望发生的金属离子迁移穿过适当介质的现象。

Electron-Beam Bonding **74.0432**

Terminations made by heating with a stream of electrons in a vacuum.

电子束键合 **74.0432**

通过真空装置中的电子射流加热形成端接。

Electroplating **53.0433**

See “Electrodeposition.”

电镀 **53.0433**

见“电沉积，Electrodeposition”。

Electrostatic Discharge (ESD) **21.1716**

The rapid spontaneous transfer of electrostatic charge, induced by a high electrostatic field.

静电放电（ESD） **21.1716**

由高静电场引发的静电荷快速自发的转移。

Element (Bar Code) **70.1717**

In a bar code, a generic term referring to a bar or space.

元素（条码） **70.1717**

条码中关于条或空的通称。

Elementary Diagram **26.0434**

A computer-generated schematic diagram with annotations.

接线原理图 **26.0434**

计算机生成的具有注解的原理图。

Elongation **70.0435**

The increase in length of a material that is caused by a tensile load.

延伸 **70.0435**

拉伸负荷引起的材料长度的增加。

Embedded Active Component (Device) **49.2167**

An active device that is inserted or formed between the layers of the primary interconnect substrate. It should have terminals which can connect with the layers of the substrate.

埋入式主动（有源）元器件（器件） **49.2167**

插入或成形于主互连基板的层之间的主动（有源）器件。这类元器件应该有能与基板的层连接的端子。

Embedded Component **30.0436**

A discrete component that is fabricated as an integral part of a printed board. (See Figure E-1.)

埋入式元器件 **30.0436**

被制作为印制板中不可分割部分的分立或有源元器件。（见图E-1。）

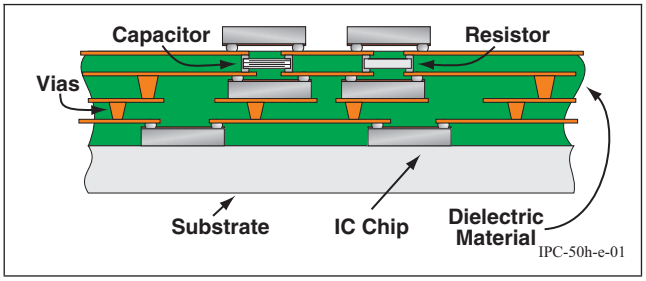
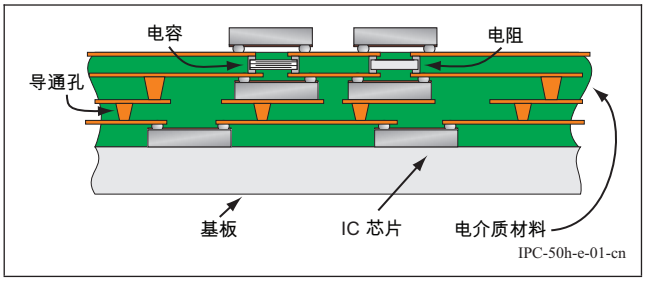


Figure E-1 Embedded Component



图E-1 埋入式元器件

Embedded Component (Inserted) **49.2165**

A functional component that is inserted between the layers of the primary interconnect substrate, as opposed to being on the surface.

埋入式元器件（插入） **49.2165**

与位于PCB表面的元器件不同，此类元器件为插入主互连基板的层之间的功能元器件。

Embedded Component (Formed) **49.2166**

A component that is created, from raw materials, inside the primary interconnect substrate, as opposed to being on the surface.

埋入式元器件（成形） **49.2166**

与位于PCB表面的元器件不同，此类元器件是由原材料成形于主互连基板内的元器件。

Embedded Copper (Base Materials) **45.1718**

An inclusion which is composed of copper and sourced from the cladding, and may be particles from treatment transfer, broken away copper tooth, or spurious copper.

埋铜（基材） **45.1718**

源于覆层的由铜组成的夹杂物，可能是处理转移的铜颗粒、断裂的铜刺，也可能不是铜。

Embedded Fiber (Base Materials) **44.1825**

An inclusion which has an insignificant width or diameter but has significant length, usually but not always in a curly or twisted configuration, generally from organic sources such as clothing or packaging materials.

埋纤（基材） **44.1825**

一种宽度或直径可忽略、但长度较明显的夹杂物，通常为但不总是弯曲或扭曲外形，一般源于有机物，如布料或包装材料。

Embedded Passive **49.0096**

A sheet of resistive, capacitive or inductive material which is laminated onto a dielectric, and either etched or lased away to define individual resistors, capacitors or inductors.

埋入式被动（无源）材料片 **49.0096**

电阻性、电容性或电感性材料片层压在电介质上，通过蚀刻或激光方法确定单个电阻、电容或电感。

Embedded Passive Component (Device) **49.2161**

A passive component that may be formed or placed inside the primary interconnect substrate, as opposed to being mounted on the surface. Formed embedded passive components may be singulated (embedded discrete) or embedded distributed (planar) structures. (See Figure E-2.)

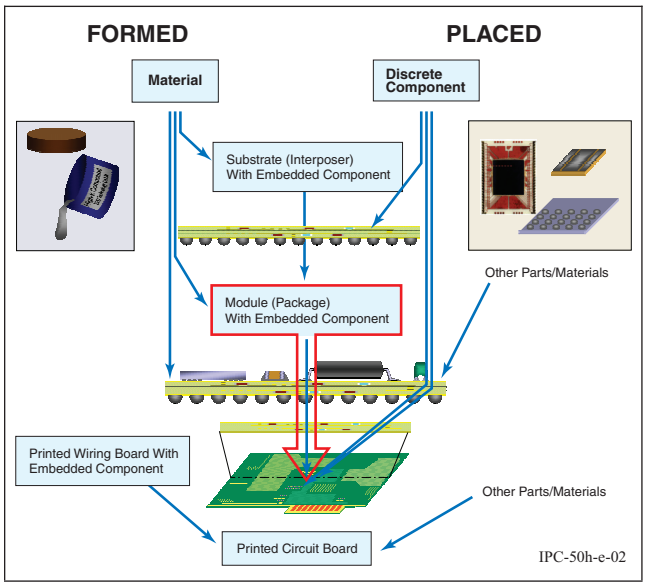


Figure E-2 Embedded Passive Component (Device)

埋入式被动（无源）元器件（器件） **49.2161**

与贴装在表面的元器件不同，此类元器件为可成形于或放置在主互连基板内的无源器件。成形后的埋入式无源器件可以是单件式（埋入分立）或埋入分布（平面）结构。（见图E-2。）

Emulsifying Agent **76.0437**

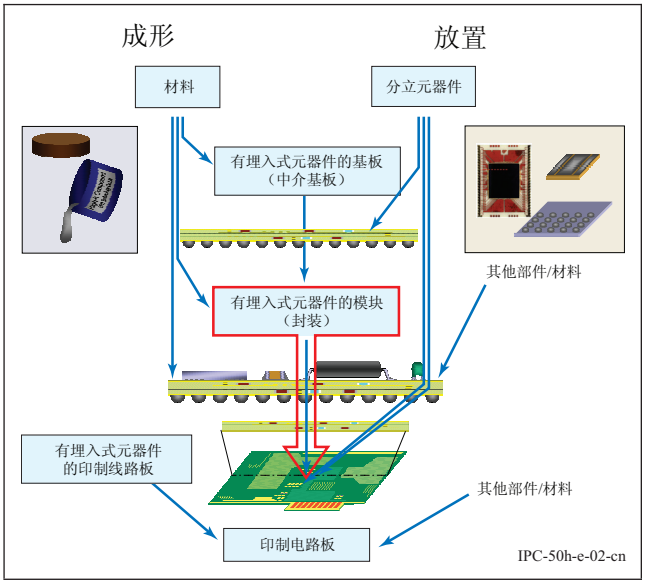
A substance that increases the stability of an emulsion.

乳化剂 **76.0437**

能增加乳液稳定性的物质。

Emulsion **76.0439**

A stable mixture of two or more immiscible liquids held in suspension by small percentages of emulsifiers.



图E-2 埋入式被动（无源）元器件（器件

乳液 **76.0439**

由少量乳化剂保持两种以上不相溶液体悬浮的稳定混合物。

Encapsulant **76.0440**

See “Potting Compound.”

封装剂 **76.0440**

见“灌封化合物，Potting Compound”。

End Item **20.0441**

See “End Product.”

最终成品 **20.0441**

见“最终产品，End Product”。

End Missing **44.0442**

A very small portion of the warp in a fabric that may have been broken in the pick-out of waste material.

断经 **44.0442**

织物中可能因摘除废纱，而引起很小一段经纱断裂。

End Product **20.0443**

An individual part or assembly in its final completed state.

最终产品 **20.0443**

处于最终完成状态的独立零部件或组件。

End Mill **51.1719**

A rod with straight or spiral flutes (grooves) sharpened as a cutting surface(s) and a flat or shaped end with cutting teeth, used for surface or side milling by rotary action.

端铣刀 **51.1719**

带有垂直或螺旋状凹槽的滚筒，被削尖成锋利的表面和平的或某种形状的端部，带有锋利的牙齿，通过旋转运动用作表面或侧面研磨。

Engineering Drawing **26.0444**

A document that discloses the physical and functional end-product requirements of an item by means of pictorial and/or textual presentations.

工程图 **26.0444**

用图示和/或文字来表示说明一项最终产品的物理要求和功能要求的文件。

Entry/Backup Material **51.1720**

A material which when placed on the top (entry) and/or bottom (backup) of a stack of printed boards being drilled or routed, supports the edges of drilled holes or routed profile such that the presence of burrs is minimized.

盖板/垫板 **51.1720**

钻孔或外形加工时，放在一叠印制板顶部的盖板（进刀板）和/或底部的垫板， 用于支撑钻孔或铣外形的的材料，其目的是为了减少毛刺产生。

Epoxy Glass Substrate **41.1743**

A two-part epoxy resin that polymerizes spontaneously when the two components are mixed and combined with glass fiber to form a substrate.

环氧玻璃基板 **41.1743**

双组分环氧树脂，当两组分混合时可自发地聚合并与玻璃纤维结合形成基板。

Epoxy Novolac **41.0445**

A multifunctional resin having epoxy groups attached to a novolac group(s).

环氧酚醛 **41.0445**

一种附有酚醛基团的环氧基团多官能树脂。

Epoxy Resin **40.1721**

A thermosetting resin containing at least two reactive oxirane rings that is made by the reaction of epichlorohydrine and bis-phenol A.

环氧树脂 **40.1721**

由环氧氯丙烷和双酚A缩聚反应而制成的至少含有两个活性环氧基团的热固树脂。

Epoxy Smear **51.0446**

See “Resin Smear.”

环氧钻污 **51.0446**

见“树脂钻污，Resin Smear”。

Equilibrium Wetting **75.1722**

The degree of wetting in which the forces of wetting are in equilibrium with the forces of gravity. The visible indication of this is that the wetting balance curve describing the wetting action when the rate of change approaches zero.

润湿平衡 **75.1722**

润湿力与重力处于平衡状态下的润湿程度。可用变化率趋近于零时的润湿称量曲线直观表示润湿作用大小。

Equivalent Series Resistance (ESR) **21.0447**

A loss parameter used to compare two capacitors of equal value in order to determine their relative effectiveness as filters.

等效串联电阻（ESR） **21.0447**

用于比较两等值电容器的损耗参数，以确定其作为滤波器的相对有效性。

Escape Rate **94.0448**

The ratio of the number of defective items not detected to the total number inspected, expressed as a percentage.

漏失率 **94.0448**

以百分率表示在被检总数中未检出的有缺陷部品数量的比率。

Escapes **94.0449**

Critical defects that are missed by an inspection system.

漏失 **94.0449**

被检验系统遗漏的致命缺陷。

Etch Factor **54.0452**

The ratio of the depth of etch to the amount of lateral etch, i.e., the ratio of conductor thickness to the amount of undercut. (See Figure E-3.)

蚀刻因子 **54.0452**

蚀刻深度与侧蚀刻量之比，即导体厚度与侧蚀量之比。（见图E-3。）

Etchant **54.0450**

A solution used to remove the unwanted portion of material from a printed board by a chemical reaction.

蚀刻剂 **54.0450**

通过化学反应从印制板上去除不需要部分材料的溶液。

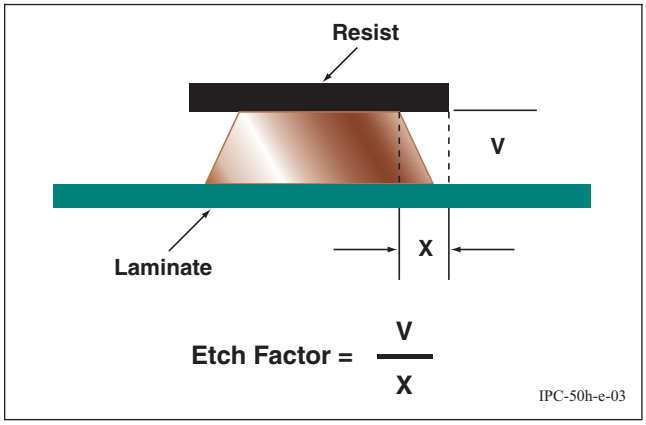
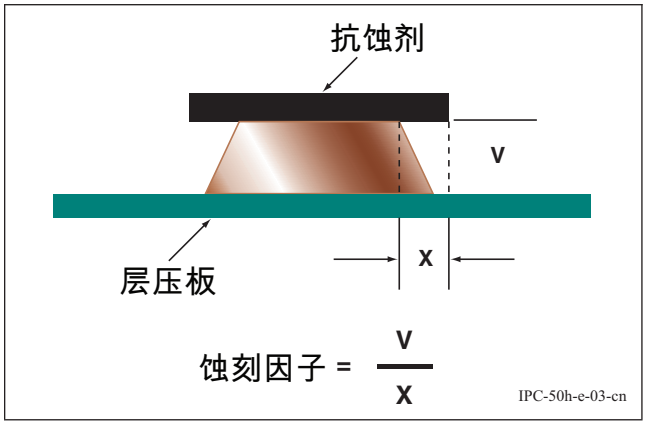


Figure E-3 Etch Factor



图E-3 蚀刻因子

Etchback **54.1389**

The controlled removal of nonmetallic materials from the sidewalls of holes in order to remove resin smear and to expose additional internal conductor surfaces. (See Figure E-4.)

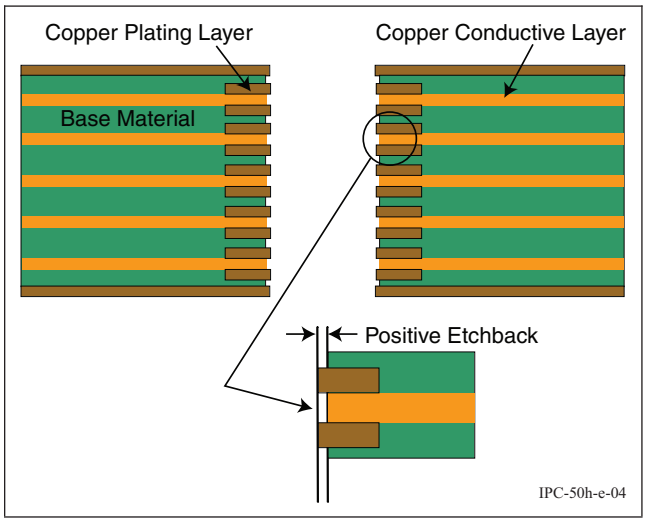
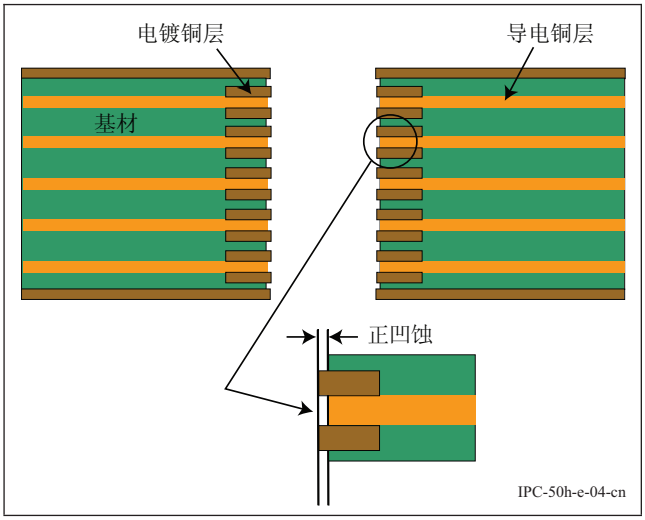


Figure E-4 Etchback

凹蚀 **54.1389**

为了去除树脂钻污及进一步暴露内层导体表面，而有控制的除去孔壁的非金属材料。（见图E-4）。



图E-4 凹蚀

Etched Printed Boards **60.0451**

A printed board having a conductive pattern that was formed by the chemical removal of unwanted portions of a conductive foil.

已蚀刻印制板 **60.0451**

已用化学方法去除导电箔的不需要部分而形成的具有导电图形的板子。

Etching **54.0453**

The chemical, or chemical and electrolytic, removal of unwanted portions of conductive or resistive material.

蚀刻 **54.0453**

用化学或电化学方法去除导电或抗蚀材料的不需要部分。

Etching Indicator **54.1390**

A wedge-shaped or other specified pattern that is affixed to a conductive foil in order to indicate the quality of etching. (See Figure E-5.)

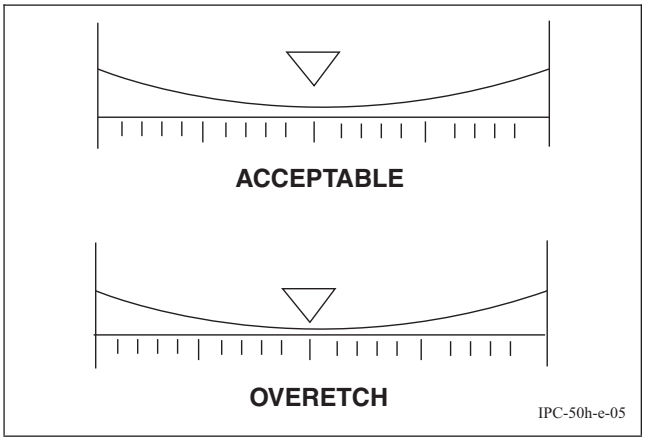
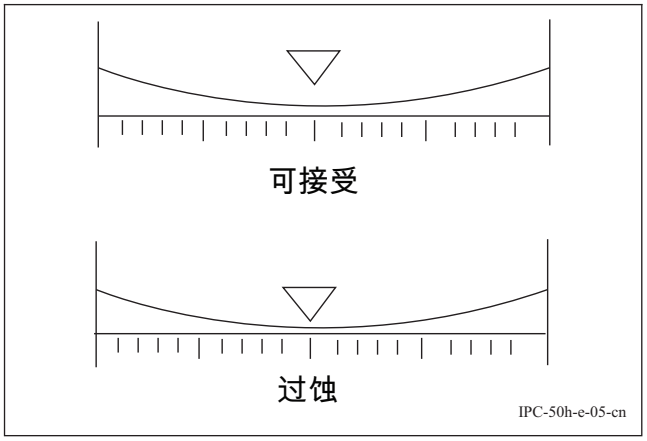


Figure E-5 Etching Indicator

蚀刻指示图 **54.1390**

附加在导电箔上用以显示蚀刻质量的楔形图或其他规定形状的图形。（见图E-5。）



图E-5 蚀刻指示图

Etch Resist **54.1723**

An organic or metal plated material used to protect the conductive pattern image from the etching chemistry. The organic material may be photosensitive.

抗蚀剂 **54.1723**

用于保护导电图形图像避免化学物质蚀刻的有机物或金属电镀材料。有机材料可以是感光的。

Ethanol **76.1744**

A solvent used in cleaning electrical assemblies (Ethylalcohol).

乙醇 **76.1744**

用于清洗电子组件的溶剂（乙基酒精）。

Eutectic (Solder) **75.1391**

The alloy composition at which a solder alloy melts/freezes completely without going through a pasty (partially solid) phase.

共晶（焊料） **75.1391**

焊料合金不经过糊状相（部分固体）就完全熔融或凝固的合金组成。

Eutectic **75.1392**

An isothermal reversible reaction in which on cooling a liquid solution is converted into two or more intimately-mixed solids, with the number of solids formed being the same as the number of components in the system.

共晶 **75.1392**

一种等温可逆反应，其中冷却时，液相溶液转化为两种以上紧密混合固相，形成的固相数与系统中组分数相同。

Eutectic Die Attach **74.0454**
The mounting of a semiconductor die to a base material with a preform of a eutectic metal alloy that is brought to its eutectic melting temperature.

共晶芯片连接 **74.0454**
采用达到共晶熔融温度的预成型共晶金属合金将半导体芯片安装到基材上的过程。

Eutrophication **76.0455**
The enrichment of either fresh or salt water by a chemical element or compound.

富营养化 **76.0455**
由于化学元素或化合物使新鲜水或含盐水增浓。

Excess Solder Connection **75.1393**
A solder connection that is characterized by the complete obscuring of the surfaces of the connected metals and/or by the presence of solder beyond the connection area.

过量焊接连接 **75.1393**
其特征表现为被连接金属表面被完全遮蔽和/或焊料超出连接区的焊接连接。

Exchange Reaction **76.1317**
A chemical reaction in which atoms of the same element in two different molecules, or in two different positions in the same molecule, transfer places.

交换反应 **76.1317**
两个不同分子中或同一分子的两个不同位置中相同元素的原子交换位置的化学反应。

Excising **73.0457**
The cutting of the unterminated (outer) leads of an inner-lead bonded die in order to separate it from the carrier tape subsequent to further assembly processing.

切割 **73.0457**
将内引线键合芯片的未端接（外部）的引线切断，以使其与芯片载带分开，进行后续的组装加工。

Excitation Current **21.0458**
The root-mean-square (RMS) current flowing in a selected winding when the rated voltage and frequency is applied.

励磁电流 **21.0458**
选定的绕组中施以额定电压及频率时所流过电流的均方根值。

Exclusion Area **92.0459**
A predetermined region where inspection is excluded.

免检区 **92.0459**
预定不作检查操作的区域。

Exfoliation **76.0460**
Scaling from a surface in flakes or layers as a result of corrosion.

鳞皮 **76.0460**
腐蚀造成的表面片状或层状剥落。

Experimental Error **93.0461**
A variation that is due to a measurement error, a chance occurrence, or other factors.

实验误差 **93.0461**
由于测量误差、偶然因素及其它因素引起的变异。

Exposure **52.1724**
The process of generating a pattern within a photosensitive material through a chemical reaction using either laser direct imaging or conventional imaging with a working phototool.

曝光 **52.1724**
采用激光直接成像或带有工作照相底版常规成像技术，通过化学反应在感光材料上产生图形的过程。

Exposure Time (Component) **30.1914**
The compensation factor which accounts for the time after bake that the component manufacturer requires to process the components prior to bag seal.

暴露时间（元器件） **30.1914**
元器件制造商需要在烘焙后至装袋密封前对元器件进行处理所用时间的补偿因素。

External Layer **22.0462**
A conductive pattern on the surface of a printed board.

外层 **22.0462**
印制板表面的导电图形。

Extraction, Liquid-Liquid **76.0463**
See “Solvent Extraction.”

液液萃取 **76.0463**
见“溶剂萃取，Solvent Extraction”。

Extraction Tool **77.0464**
A device used for removing a contact from a connector body or insert, a component from a socket, or a printed board from its enclosure.

取出工具 **77.0464**

用于从连接器本体或插入物中取出接触件、从插座中取出元器件、或从壳体中取出印制板的装置。

Extraneous Copper (Base Materials) **92.2072**

A portion of the copper cladding which could not be etched off. Usually due to a contaminate stuck to the clad laminate which acts as a barrier to etching.

残余铜（基材） **92.2072**

不能被蚀刻掉的一部分铜覆层。通常是由于污物粘附于覆箔层压板上而阻碍了蚀刻。

Extraneous Metal **92.0465**

Unwanted metal, usually copper, that remains on a base material after chemical processing.

残余金属 **92.0465**

化学处理后基材上残留的多余金属，通常指铜。

Eyelet **37.0466**

A short metallic tube, the ends of which can be formed outward in order to fasten it within a hole in material such as a printed board.

空心铆钉 **37.0466**

其两端能成形为向外翻的金属短管，以便固定在材料如印刷板的孔内。

F

F (Fisher) Test **94.0468**

A test that attempts to determine if two populations have the same variance.

F（费歇尔）测试 **94.0468**

确定二个总体是否具有相同方差的测试。

F Ratio **93.0552**

The ratio of one variance value to another.

F比率 **93.0552**

一个方差值与另一个方差值之比。

FCC System **37.0486**

A complete flat-conductor cabling system that is suitable for installation under carpet squares. (See “Flat Cable.”)

FCC系统 **37.0486**

适合安装在地毯下的全扁平导体电缆敷设系统。（又见“扁平电缆，Flat Cable”。）

Fabrication Allowance **26.1725**

A dimensional value added to a printed board feature or feature location intended to assure that manufacturing variations can maintain certain physical or performance characteristics of the end product.

制作余量 **26.1725**

印刷板特征或特征位置尺寸的增加值，以确保制造变异后仍能保证终端产品的一些物理或性能特性。

Fabrication Panel **41.2148**

See “Panel.”

制作在制板 **41.2148**

见“在制板，Panel”。

Face Bonding **74.0469**

Attaching a die to a base material with its circuitry facing the base material.

面键合 **74.0469**

使芯片电路面向基板而实现芯片与基板的连接。

Face Down Bonding **74.1753**

A method of attaching a component or circuit chip to a substrate by inverting the chip and bonding chip contacts to the mirror-image contact points on the substrate.

面向下键合 **74.1753**

将元器件或电路芯片连接到基板上的邦定方法，它通过反转芯片并将芯片键合到基板上的镜像连接点来实现。

Face up Bonding **74.1799**

A type of integrated circuit bonding wherein the back of the die is attached to a base material.

面向上键合 **74.1799**

一种集成电路键合方式，其中芯片的背面与基板连接。

Factorial Experiment **94.0470**

An experimental design that evaluates every possible combination of events.

析因实验 **94.0470**

评价事件每种可能组合的实验设计。

False Alarm **92.0471**

An anomaly identified by an inspection system that is not a critical defect.

假警报 **92.0471**

检验系统将非致命缺陷识别为异常。

False Alarm Rate **92.0472**
The ratio of the number of acceptable items detected to the total number inspected, expressed as a percentage.

假警报率 **92.0472**
有缺陷的可接受部品数与检验总数之比，以百分比表示。

Farad **21.1808**
A unit of electrical capacitance.

法拉 **21.1808**
电容的单位。

Far-End Crosstalk **21.0473**
See “Forward Crosstalk.”

远端串扰 **21.0473**
见“正向串扰，Forward Crosstalk”。

Fatigue Life **96.0474**
The number of cycles of stress that can be sustained prior to failure for a stated test condition.

疲劳寿命 **96.0474**
规定测试条件下，材料在失效之前，所能经受的应力循环次数。

Fatigue Limit **96.0475**
The maximum stress below which a material can presumably endure an infinite number of stress cycles.

疲劳极限 **96.0475**
当最大应力小于某一数值时，材料可经受无限次应力循环，而不发生失效，此应力值即为疲劳极限。

Fatigue Strength **96.1394**
The maximum strength that can be sustained for a specific number of cycles without failure, with the stress being completely reversed within each cycle unless otherwise stated.

疲劳强度 **96.1394**
材料能经受一定次数的应力循环而不发生失效的最大强度，除非另有规定，每个循环中应力完全反向。

Fatigue-Strength Reduction Factor (Kf) **96.1395**
The ratio of the fatigue strength of a member or specimen with no stress concentration to the fatigue strength with stress concentration.

疲劳强度降低系数（Kf） **96.1395**
构件或试样在没有应力集中时的疲劳强度与有应力集中时的疲劳强度之比。

Fatty Acid **76.0476**
A carboxylic acid derived from, or contained in, an animal or vegetable fat or oil.

脂肪酸 **76.0476**
动物或植物脂肪或油中存在的或衍生出的羧基酸。

Fatty Ester **76.0477**
A fatty acid with the active hydrogen replaced by the alkyl group of a monohydric alcohol.

脂肪脂 **76.0477**
其活性氢被单羟基醇的烃基所取代的脂肪酸。

Fault **90.0478**
Any condition that causes a device or circuit to fail to operate in a proper manner.

故障 **90.0478**
任何导致设备或电路不能以正常方式工作的状况。

Fault Dictionary **90.0479**
A list of elements in which each element consists of a fault signature that can be used to detect a fault.

故障表 **90.0479**
可用于检测故障的要素表，其中每个要素包括一个故障表征。

Fault Isolation **92.0480**
The identification process used to determine the location of a fault to within a small number of replaceable components.

故障隔离 **92.0480**
用于确定在少量可替换元器件范围内故障位置的鉴别过程。

Fault Localization **91.0481**
The identification process used to determine the location of a fault to within a general area of a circuit.

故障定位 **91.0481**
用于确定在电路整个区域内故障位置的鉴别过程。

Fault Masking **92.0482**
A condition that occurs when one fault conceals the existence of another.

故障屏蔽 **92.0482**
一个故障掩盖另一个故障的存在时所发生的状况。

Fault Modes **92.0483**
The various ways faults may occur.

故障模式 **92.0483**
故障可能发生的各种方式。

Fault Resolution **92.0484**
A measure of the capability of a test process to perform failure isolation.

故障分辨率 **92.0484**
测试过程实现故障隔离的的能力量度。

Fault Signature **92.0485**
The characteristic, unique erroneous response produced by a specific fault.

故障表征 **92.0485**
特定故障产生的唯一的错误反应特征。

Fault Simulation **92.1396**
A process that allows for the prediction or observation of a system's behavior in the presence of a specific fault without actually having that fault occur.

故障模拟 **92.1396**
预测或观察系统在发生特定故障时的运转状态的过程，实际上并没有真正发生故障。

Feather Length **44.0487**
The distance from the last warp end of a fabric to the end of the pick.

毛边长度 **44.0487**
织物最边上一根经纱末端到纬纱末端之间的距离。

Feature **22.0488**
The general term that is applied to a physical portion of a part, such as a surface, hole or slot.

要素 **22.0488**
零件实体部分，如表面、孔或槽的通用术语。

Feature Window **74.0491**
An opening in the insulation material of a carrier tape that allows for the creation and bonding of separated leads.

要素窗 **74.0491**
载带绝缘材料中的开口，用于分立引线的形成和键合。

Feature-Based Modeling **21.0489**
A computer-based modeling method that is based on the use of part features instead of geometric entities.

基于要素建模 **21.0489**
采用部件要素代替几何实体的计算机建模方法。

Feature-Location Record **25.0490**
A type of record that defines lines, points, and annotations.

要素位置记录 **25.0490**
定义线、点及注解的记录形式。

Fiber Exposure **91.0492**
The exposure of reinforcing fibers that are within machined, abraded, or chemical-attacked areas of a base material. (See also "Weave Exposure.")

露纤维 **91.0492**
基材因机械加工、磨损、或化学侵蚀而露出增强纤维。（又见 "露织物，Weave Exposure"。）

Fiducial (Mark) **22.0493**
A printed board feature (or features) that is (are) created in the same process as the conductive pattern and that provides a common measurable point for component mounting with respect to a land pattern or land patterns.

基准（标记） **22.0493**
与导电图形同时生成的印制板要素，为根据焊盘图形安装元器件提供了公共可测点。

Field Trimming **77.0494**
The adjusting of the value of a resistor in order to modify a circuit output voltage or current.

现场修整 **77.0494**
调整电阻值以修改电路输出电压或输出电流。

Filiform Corrosion **76.0495**
Corrosion that develops under organic coatings on metals in the form of randomly distributed fine hairlines that are usually curved, wavy, or coiled.

线状腐蚀 **76.0495**
发生在有机涂层下的金属腐蚀，通常为曲线状、波状、或卷曲状的不规则分布细线。

Fill **44.0496**
Yarns that are woven in a crosswise direction of a fabric.

纬线 **44.0496**
横向织入织物的纱线。

Filler **44.0497**
A substance that is added to a material to improve its solidity, bulk, or other properties.

填料 **44.0497**
加入材料中以改善材料的硬度、体积或其他特性的物质。

Fillet, Adhesive **75.0498**

The portion of an adhesive that fills the corner, or the angle formed, where two adherends are joined. (See Figure F-1.)

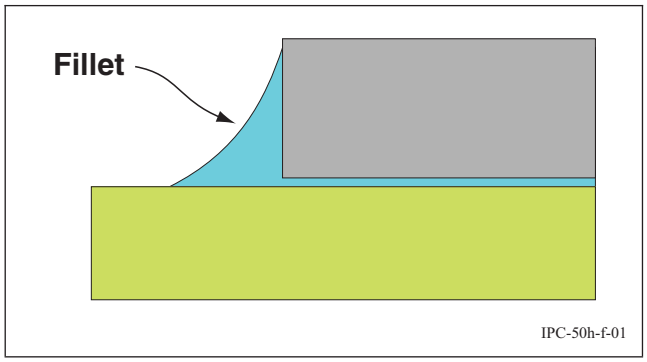
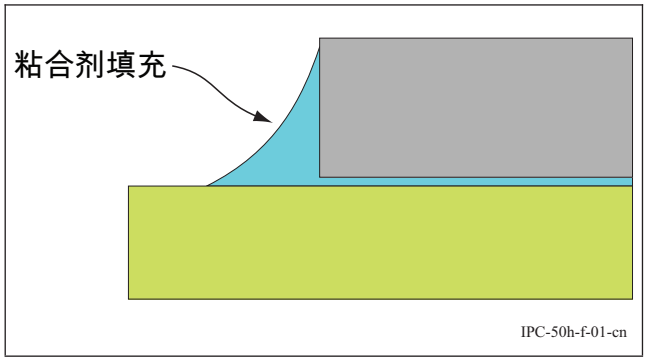


Figure F-1 Fillet, Adhesive

粘合剂填充 **75.0498**

粘合剂的一部分，填充在二个粘合体结合的角落或形成的角。（见图F-1。）



图F-1 粘合剂填充

Fillet, Solder **75.0499**

See “Solder Fillet.”

焊料填充 **75.0499**

见“焊料填充，Solder Fillet”。

Film **45.0500**

Single or multiple layers of material used to form hybrid circuit elements, interconnections, and crossovers. (See also “Thin Film” and “Thick Film.”)

膜 **45.0500**

用于形成混合电路元器件、互连和跨接的单层或多层材料。（又见“薄膜，Thin Film”和“厚膜，Thick Film”。）

Film Conductor **45.0501**

A conductor formed in place on a base material by depositing a conductive material using screening, plating or evaporating techniques.

膜导体 **45.0501**

采用网印、电镀或蒸镀技术在基材上沉积导电材料所形成的导体。

Film Network **53.0502**

An electrical network composed of thin-film and/or thick-film components on a base material.

膜网络 **53.0502**

由基材上的薄膜和/或厚膜元器件组成的电气网络。

Final Inspection **92.1671**

An evaluation of quality characteristics relating to a standard, specification, or design drawing prior to shipping to the customer.

最终检验 **92.1671**

产品交付客户之前，根据标准、规范或设计图纸对其质量特征的评价。

Final Seal **76.1397**

The manufacturing process that completes the enclosure of a microcircuit so that further internal processing cannot be performed without removing a lid or otherwise disassembling the package.

最终密封 **76.1397**

将微电路封入罩内的制造过程，之后如不去除罩或将封装解体就无法对其内部进行进一步的加工。

Fine Leak **95.0504**

A leak in a sealed package that is less than 0.00001 cubic centimeters per second at one atmosphere of differential air pressure.

细泄漏 **95.0504**

压力差为一个大气压时，已密封封装中小于0.00001 cm^3/s的泄漏。

Fine Pitch QFP **33.1837**

A quad flat pack (QFP) package with the lead pitch at or less than 0.65 mm [0.025 in] centers.

细间距QFP **33.1837**

引线中心间距小于等于0.65mm[0.025in]的方形扁平（QFP）封装。

Fine-Pitch BGA/Chip Scale Package (CSP) **33.1838**

Ball grid array with less than 1 mm [0.039 in] pitch. This is also known as Chip Scale Package (CSP).

细间距BGA/芯片规模封装（CSP） **33.1838**

间距小于1mm[0.039in]的球栅阵列，也称为芯片规模封装（CSP）。

Fine-Pitch Technology (FPT) **80.0503**

A surface-mount assembly technology with component terminations on less than 0.65 mm [0.025 in] centers.

精细节距技术（FPT） **80.0503**

元器件端子中心距小于0.65mm[0.025in]的表面组装技术。

Fingers **22.0505**

See “Edge-Board Contacts.”

手指 **22.0505**

见“板边接触片，Edge-Board Contacts”。

Finished Fabric **44.0506**

A fabric that has been treated in order to aid its compatibility with resins.

经处理织物 **44.0506**

已经处理的织物，以提高其与树脂的兼容性。

Finished Board **60.2149**

See “Printed Board.”

成品板 **60.2149**

见“印制板，Printed Board”。

Finite-Element Analysis (FEA) **21.1398**

A computer-based analysis method that subdivides geometric entities into successively smaller elements and links a series of equations to each element so that they can then be analyzed simultaneously.

有限元分析（FEA） **21.1398**

基于计算机的分析方法，将几何实体分为连续的更小单元，并将一系列公式与每个单元链接，从而可以对这些单元同时进行分析。

Finite-Element Modeling (FEM) **21.0507**

The use of a model to represent a problem that can be evaluated by finite-element analysis.

有限元建模（FEM） **21.0507**

使用模型表示能用有限元分析法进行评定的问题。

Fire (v.) **56.0508**

To heat a circuit so that its thick-film components are transformed into their final form.

烧结（动词） **56.0508**

加热电路使其厚膜元器件转变成最终形式。

Firing Sensitivity **56.0509**

The percentage change of film component characteristics caused by a change in peak firing temperature, expressed as percent per degree centigrade.

烧结敏感度 **56.0509**

烧结峰值温度变化引起的膜元器件特性变化百分率，用每摄氏度百分比表示。

First Article **91.0511**

A part or assembly that has been manufactured prior to the start of a production run for the purpose of ascertaining whether or not the manufacturing processes used to fabricate it are capable of making items that will meet all applicable end-product requirements.

首件 **91.0511**

在正式生产前所制造出的部件或组件，以确认所采用的制造工艺是否能制造出满足所有适用的终端产品要求的部品。

First Bond **74.0512**

The initial termination in a sequence of bonds made to form a conductive path. (See also “Second Bond.”)

首键合 **74.0512**

形成导电通路的一系列键合中的首端接。（又见“第二键合，Second Bond”。）

First Radius **74.0513**

The radius of the front edge of a bonding-tool foot.

第一半径 **74.0513**

键合工具底座的前缘半径。

First Search **74.0514**

The moment at which the final adjustment is made in the location of the bonding area under the bonding tool prior to making the first bond.

首次搜索 **74.0514**

完成首键合前，定位接合工具下的键合区时所进行的最后调整时刻。

First-Pass Yield **91.0510**

The statistical average of the number of finished units in a group that pass all tests without any rework, expressed in percent.

直通率 **91.0510**

一组成品中通过所有测试而无需任何返工的产品数量的统计平均值，用百分数表示。

Fish Eye **44.0516**

A small area of a fabric that resists resin wetting that can be caused by the resin system, fabric and treating.

鱼眼 **44.0516**

可能因树脂系统、织物或处理造成的阻碍树脂浸润小区域织物。

Fish Eye (Adhesive) **46.1839**

Relatively small deformations (pock marks) in the adhesive coating.

鱼眼（粘合剂） **46.1839**

粘合涂层内相对小的变形（麻点）。

Fishbone Diagram **91.0515**

See “Cause-and-Effect Diagram.”

鱼骨图 **91.0515**

见“因果图，Cause-and-Effect Diagram”。

Fisheye (Prepreg) **44.1840**

A localized area of the reinforcement where the resin coverage is significantly diminished although intact, forming a circular depression, much like a shallow volcano.

鱼眼（预浸材料） **44.1840**

增强材料局部区域虽有树脂覆盖，但明显减少，形成一个圆凹陷区，很像一个浅火山。

Fisheyes (Pressure Sensitive Tape) **46.1841**

In pressure sensitive tape, relatively small deformations or pockmarks within the adhesive coating.

鱼眼（压敏胶带） **46.1841**

压敏胶粘带中粘接涂覆层内相对小的变形或麻点。

Fissuring **56.0517**

The cracking of a conductor or dielectric material caused by stresses occurring during firing.

裂隙 **56.0517**

烧结期间由应力引起的导体或电介质材料开裂。

Fixed Contact **37.0518**

A type of connector contact that is permanently retained within the connector body or insert.

固定接触件 **37.0518**

永久性地保留在连接器本体或嵌入物中的连接器接触件。

Fixed-Effect Model **91.1399**

A specific experimental treatment whereby the conclusions reached apply only to the factor levels considered in the analysis and the interferences are restricted to the experimental levels. (See also “Random-Effects Model.”)

固定效应模式 **91.1399**

特殊的实验处理模式，由此获得的结论仅用于分析中所考虑的因素，干扰也只限于实验水平。（又见“随机效应模式，Random-Effects Model”。）

Fixture, Test **92.0519**

A device that interfaces between test equipment and the unit under test.

测试夹具 **92.0519**

将测试设备与待测试单元连接起来的装置。

Flag **74.0520**

The support area on a die or lead frame. (See Figure F-2.)

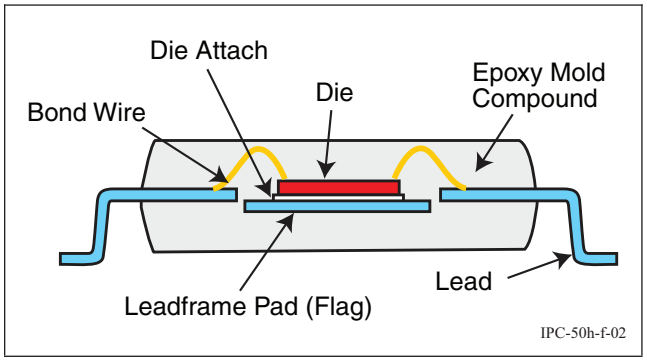
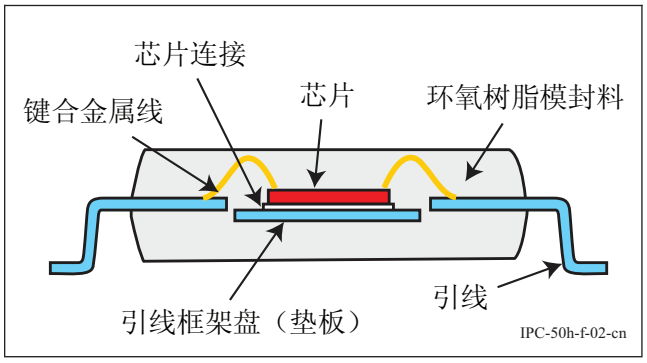


Figure F-2 Flag

垫板 **74.0520**

芯片或引线框架上的支撑区域。（见图F-2。）



图F-2 垫板

Flame-Off **74.0521**

The use of a flame to sever a wire and to form a ball for the next ball-bonding termination.

烧断 **74.0521**

用火焰烧断金属线，并形成下一个球键合端接点用球。

Flame Resistance **40.1842**

The degree to which a given substance will resist being ignited when exposed to a flame.

耐燃性 **40.1842**

给定物质暴露于火焰中时，能抵抗被点燃的能力。

Flame Retardance **40.1843**

The tendency of the material, when burning, to self-extinguish once the source of ignition is removed.

阻燃性 **40.1843**

材料燃烧时，撤走点火源后，材料自身熄灭的趋势。

Flammability **40.1844**

The tendency of the material to ignite and burn when subjected to an ignition source.

可燃性 **40.1844**

材料接触到点火源时，点燃和燃烧的趋势。

Flare **51.1400**

The undesirable enlarged and tapered area around a punched hole that is on the side of the material through which the punch exited during hole formation. (See Figure F-3.)

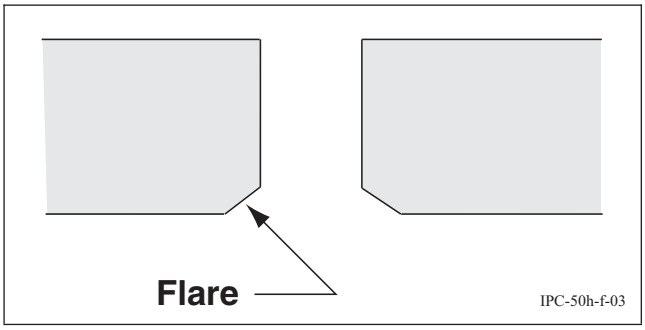
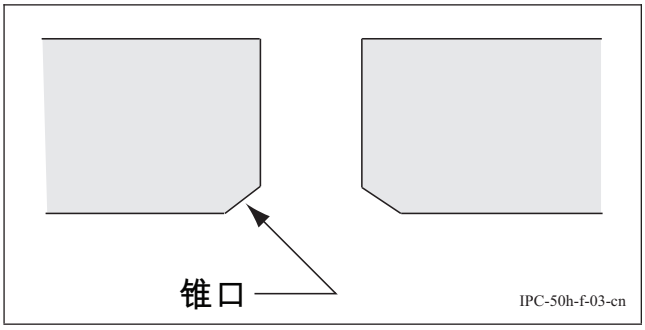


Figure F-3 Flare

锥口 **51.1400**

冲孔成型时，在冲床退出的材料面冲压孔周围形成了不需要的扩大和锥形区域。（见图F-3。）



图F-3 锥口

Flash Distillation **76.1401**

Distillation in which an appreciable proportion of liquid is quickly converted to a vapor in such a way that the final vapor is in equilibrium with the final liquid.

急骤蒸馏 **76.1401**

可估比例的液体很快转化为蒸汽而最终蒸汽与最终液体相平衡的蒸馏。

Flashover **21.1845**

An electric discharge that takes place around or on the surface of an insulator between conductors with different potentials when a path becomes sufficiently ionized to sustain an electric arc.

飞弧 **21.1845**

当通路足以电离维持电弧时，不同电势导体之间的绝缘体表面或周围发生的放电。

Flat Cable **37.0522**

Two or more parallel, round or flat, conductors that are contained in the same plane of a flat insulating base material.

扁平电缆 **37.0522**

包含在扁平绝缘基材相同平面内的两个或两个以上平行的、圆或扁平导体。

Flat Conductor **40.1800**

A rectangular conductor that is wider than it is high.

扁平导体 **40.1800**

宽度大于厚度的矩形导体。

Flat Pack **33.0523**

A rectangular component package that has a row of leads extending from each of the longer sides of its body that are parallel to the base of its body.

扁平封装 **33.0523**

其本体两个长边均伸出一排与其本体基底相平行的引线的矩形元器件封装。

Flex-Rigid Double-Sided Printed Board **63.1570**

See “Rigid-Flex Double-sided Printed Board.”

挠刚性双面印制板 **63.1570**

见“刚挠性双面印制板，Rigid-Flex Double-Sided Printed Board”。

Flex-Rigid Printed Board **63.0524**

See “Rigid-Flex Printed Board.”

挠刚性印制板 **63.0524**

见“刚挠性印制板，Rigid-Flex Printed Board”。

Flex-Rigid Printed Wiring Board **63.1847**
See "Rigid-Flex Printed Board."

挠刚性印制线路板 **63.1847**
见"刚挠性印制板，Rigid-Flex Printed Board"。

Flexible Double-Sided Printed Board **62.1581**
Double-sided printed board, either printed circuit or printed wiring, using a flexible base material only.

挠性双面印制板 **62.1581**
只采用挠性基材制作的印制线路或印制电路双面印制板。

Flexible Material Interconnect Construction (FMIC) **70.1846**
The integration of passive and active components with mechanical components (including switches and connectors) on a flexible or thin base material, i.e., flexible printed board, in order to produce an electronic assembly.

挠性材料互连结构（FMIC） **70.1846**
为了形成电子组件，在挠性或薄基材上即挠性印制板上无源及有源元器件与机械元器件（包括开关和连接器）的集成。

Flexible Multilayer Printed Board **62.1582**
Multilayer printed board, either printed circuit or printed wiring, using flexible base materials only. Different areas of the flexible multilayer printed board may have different number of layers and thicknesses.

挠性多层印制板 **62.1582**
只采用挠性基材的印制电路或印制线路多层印制板。挠性多层印制板的不同区域可以有不同的层数和不同的厚度。

Flexible Printed Board **62.1579**
A printed board using a flexible base material only. May be partially provided with electrically nonfunctional stiffeners and/or coverlay.

挠性印制板 **62.1579**
只采用挠性基材的印制板。其部分区域可能有非电气功能增强板和/或覆盖层。

Flexible Printed Circuit **62.0525**
A patterned arrangement of printed circuitry and components that utilizes flexible base material with or without flexible coverlay.

挠性印制电路 **62.0525**
采用带有或没有挠性覆盖层的挠性基材的印制电路和元器件图形排列。

Flexible Printed Wiring **62.0526**
A patterned arrangement of printed wiring that utilizes flexible base material with or without flexible coverlay.

挠性印制线路 **62.0526**
采用带有或没有挠性覆盖层的挠性基材的印制线路图形排列。

Flexible Single-Sided Printed Board **62.1580**
Single-sided printed board, either printed circuit or printed wiring, using flexible base materials only.

挠性单面印制板 **62.1580**
只采用挠性基材的印制电路或印制线路单面印制板。

Flexural Failure **91.0527**
A failure that is caused by the repeated flexing of a material.

挠曲破坏 **91.0527**
材料经受重复挠曲而导致的失效。

Flexural Strength **44.0528**
The tensile strength of the outermost fiber of a material that is being bent.

弯曲强度 **44.0528**
材料被弯曲时，最外层纤维的拉伸强度。

Flip Chip **74.0530**
A leadless monolithic, circuit element structure that electrically and mechanically interconnects to a base material through the use of conductive bumps. (See Figure F-4.)

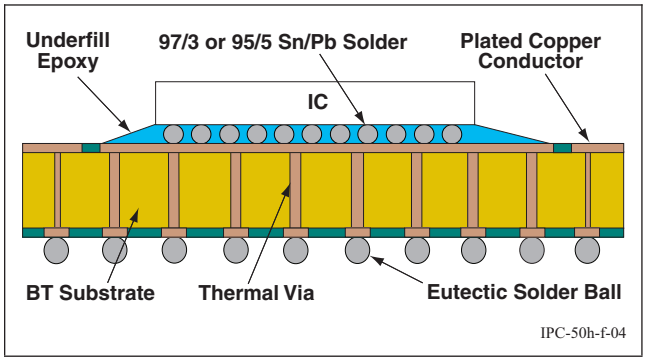
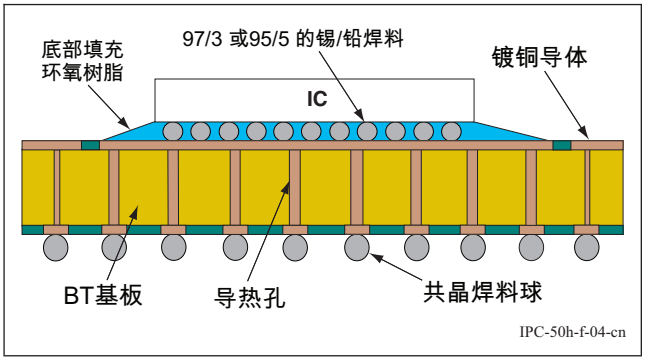


Figure F-4 Flip Chip

倒装芯片 **74.0530**
通过导电凸点实现与基材的电气和机械互连的无引线单片电路元器件结构。（见图F-4。）

Flip-Chip Mounting **74.0529**
The mounting and interconnecting of a flip chip component to a base material.



图F-4 倒装芯片

倒装芯片安装 **74.0529**

倒装芯片元器件在基材上的安装及与其基材的互连。

Float **44.0531**

A warp or fill yarn that does not interlace with the next designated yarn, but passes over or under two or more adjacent yarns.

跳线 **44.0531**

经纱或纬纱，其未与下一根纱线相交织，而从上面或下面跳过二根以上的纱线。

Floating Bushing **37.0533**

A connector mounting device that allows for connector body movement in order to facilitate its alignment with a mating part or mating assembly.

浮动衬套 **37.0533**

可使连接器本体移动以使本体与相配接的部件或组件易于对准的连接器安装装置。

Floating-Annulus Tape-Automated Bonding **74.0532**

A carrier tape format that uses a free-floating annulus ring to separate suspended leads.

浮动环载带自动键合 **74.0532**

采用自由浮动圆环分离悬浮引线的载带形式。

Flocculant **76.0534**

A substance that induces flocculation.

絮凝剂 **76.0534**

诱发絮凝作用的物质。

Flocculation **76.0535**

The combination or aggregation of suspended solid particles in such a way that they form small clumps or tufts that resemble wool.

絮凝作用 **76.0535**

悬浮固体颗粒结合或聚集成絮状的小凝块或团簇。

Floor Life **30.1848**

The allowable time period for a moisture-sensitive device to be exposed to normal room environment after removal from a moisture barrier bag and before a solder reflow process.

现场寿命 **30.1848**

湿敏器件拆除防潮袋后，在再流焊工艺前，暴露在正常室内环境下所允许的时间周期。

Flow Soldering **75.0536**

A wave, drag or dip soldering process where the product is brought into contact with molten solder in order to attach electronic components to the interconnecting surface.

流动焊接 **75.0536**

波峰焊接、拖焊或浸焊工艺，产品与熔融焊料相接触，实现电子元器件与互连表面的连接。

Flow Soldering (Nitrogen Process) **75.1934**

A flow soldering process, carried out in a nitrogen atmosphere, intended to retard oxidation of solder and board conductive surfaces and improve solder wetting.

流动焊接（氮气工艺） **75.1934**

在氮气中完成的流动焊接工艺，目的是阻止焊料和板子导体表面的氧化且改善焊料润湿。

Flush Conductor **22.0537**

A conductor whose outer surface is in the same plane as is the surface of the insulating material adjacent to the conductor.

齐平导体 **22.0537**

导体外表面与其相邻的绝缘基材表面处于同一平面的导体。

Flux **75.0538**

A chemically and physically active compound that, when heated, promotes the wetting of a base metal surface by molten solder by removing minor surface oxidation and other surface films and by protecting the surfaces from reoxidation during a soldering operation.

助焊剂 **75.0538**

化学和物理活性混合物，加热时能除去表面少量氧化物和其他表面薄膜，同时防止被焊接表面在焊接过程中再次氧化，以促进熔融焊料对金属基材的润湿。

Flux Activation Temperature **75.0540**

The temperature at which flux becomes active enough to remove oxides from the metals being joined.

助焊剂活化温度 **75.0540**

助焊剂达到足够活性以除去被连接金属氧化物的温度。

Flux Activity **75.0541**

The degree or efficiency with which a flux promotes wetting of a surface with molten solder. (See also “Solder-Spread Test,” “Wetting Balance.”)

助焊剂活性 **75.0541**

助焊剂促进熔融焊料润湿金属表面的程度或效率。（又见“焊料铺展测试，Solder-Spread Test”和“润湿平衡，Wetting Balance”。）

Flux Characterization **76.0542**

A series of tests that determines the basic corrosive and conductive properties of fluxes and flux residues.

助焊剂性能鉴定 **76.0542**

确定助焊剂及其残留物的基本腐蚀性和导电性能的一系列测试。

Flux Residue **76.0543**

A flux-related contaminant that is present on or near the surface of a solder connection.

助焊剂残留物 **76.0543**

出现在焊接连接表面或其附近，与助焊剂有关的污染物。

Flux-Cored Solder **46.0539**

A wire or ribbon of solder that contains one or more continuous flux-filled cavities along its length.

助焊剂芯焊料 **46.0539**

沿长度方向含有一条或多条连续助焊剂芯的线状或带装焊料。

Flux-Spatter Test **76.1402**

A semiquantitive test that characterizes the ability of flux and flux residues, upon rapid heating of the flux, to remain in one area rather than form a dispersion of fine droplets.

助焊剂飞溅测试 **76.1402**

确定助焊剂受到快速加热时，助焊剂及其残留物维持在一个区域内而不是形成分散的细颗粒的半定量测试。

Fluxing **75.1745**

The efficiency with which a flux promotes wetting of a surface with molten solder.

助焊 **75.1745**

助焊剂促进熔融焊料润湿表面的效率。

Foil Burr **51.0544**

A rough edge or area that remains on the surface of a foil after it has been cut, pierced, or drilled.

金属箔毛刺 **51.0544**

经过切割、冲切或钻孔后在箔表面上留有的粗糙边缘或区域。

Foil Lamination **55.0545**

A process for making multilayer printed boards with surface layer(s) of metal foil bonded in a single operation. (See also “Cap Lamination.”)

覆箔层压 **55.0545**

制作多层印制板的工艺，在一次层压中粘合金属箔作表面层。（又见“覆盖层压，Cap Lamination”。）

Foil Profile **45.0546**

The roughness of a foil surface that results from the manufacture of the foil and/or from a bond-enhancement treatment.

箔轮廓 **45.0546**

由箔的制造过程和/或粘合增强处理形成的金属箔表面粗糙度。

Foot Length **74.0547**

The longer dimension of the bonding surface of a wedge-type bonding tool.

底座长度 **74.0547**

楔型键合工具的键合表面的长方向尺寸。

Footprint **22.0548**

See “Land Pattern.”

印制焊脚 **22.0548**

见“连接盘图形，Land Pattern”。

Forced Gas Convection Soldering **75.1746**

Reflow soldering using forced hot air or nitrogen gas as the primary source of heat.

强制热风对流焊接 **75.1746**

采用强制热风或氮气作为主要加热源的再流焊接。

Forced-Field Analysis **93.1403**

A technique that is used to help solve a problem by identifying those forces that are preventing improvement (restraints) and those forces that affect improvement (drives).

强力场分析 **93.1403**

通过识别哪些力阻止改进（遏制作用）和哪些力有利于改进（推动作用）来帮助解决问题的一种方法。

Foreign Material **90.1854**

See “Inclusion.”

外来物 **90.1854**

见“夹杂物，Inclusion”。

Foreign Material (Soldering) **75.1404**

A lumpy, irregular coating that has covered, or partially covered, particles of material that are located on, but are different than, the material or coating of the items to be soldered.

外来物（焊接） **75.1404**

覆盖或部分覆盖于被焊接对象的材料或涂层上且与之不同的粗糙不规则材料涂层。

Fork Contact **37.1405**

A type of female connector contact that consists of flat spring metal that has been formed into a two tine “fork-like” shape so that it mates with a spade contact.

叉形接触件 **37.1405**

一种凹形连接器接触件，它由加工成双叉形状的扁金属弹簧组成，以便与铲形接触件配接。

Form **22.0549**

The shape of a feature.

外形 **22.0549**

要素的形状。

Forward Crosstalk **21.1406**

Noise induced into a quiet line, as seen at the end of the quiet line that is the farthest from the signal source, because the quiet line has been placed next to an active line. (See also “Backward Crosstalk.”)

正向串扰 **21.1406**

由于无信号线置于有信号线附近，在无信号线远离信号源的一端可见到的无信号线感应到的噪声。（参见“反向串扰，Backward Crosstalk”。）

Fractional-Factorial Experiment **91.0550**

An experiment whereby only a portion of the complete factorial is run.

部分因子实验 **91.0550**

全部因子中仅部分因子在运行的实验。

Frame Pitch **74.0551**

The distance from the centerline of one tape-automated bonding frame to the centerline on the next frame site on a reel of carrier tape.

框节距 **74.0551**

成卷的载带上一个载带自动键合框的中心线到另一个框中心线的距离。

Frequency, Electrical Current **21.1856**

The number of cycles (hertz) or completed alterations per unit of time.

电流频率 **21.1856**

单位时间的循环次数（赫兹）或单位时间完成的交变次数。

Frit (Semiconductor) **35.1857**

A glass composition with a relatively low softening point.

玻璃料（半导体） **35.1857**

软化点相对低的玻璃组分。（译者注：添加在浆料中，用于增加贵金属的凝聚和附着效果；使空白陶瓷基板上的金属粉和金属化合物在高温烧结后，形成牢固的贵金属电路系统。）

From-To List **21.0553**

Written instructions in the form of a list that indicates the locations of wiring terminations.

接线表 **21.0553**

以表格形式表示接线端接点位置的书面指令。

Fully Additive Process **53.1407**

An additive process wherein the entire thickness of electrically isolated conductors is obtained by the use of electroless deposition. (See also “Semi-Additive Process.”)

全加成法工艺 **53.1407**

用无电沉积方法形成有完整厚度电隔离导体的加成法工艺。（又见“半加成法工艺，Semi-Additive Process”。）

Fully Electroless Process **53.0554**

See “Fully Additive Process.”

全无电工艺 **53.0554**

见“全加成法工艺，Fully-Additive Process”。

Functional Tester **92.0556**

Equipment that analyzes the unit under test as a complete functional entity by applying inputs and sensing outputs.

功能测试仪 **92.0556**
通过施加输入并感应输出，分析作为完整功能整体的被测试单元的测试设备。

Functionality, Resin or Curing Agent **41.0555**
The number of reactive groups per molecule.

树脂或固化剂官能数 **41.0555**
每个分子的反应性基团数量。

Fused Coating **56.0557**
A metallic coating, usually a tin or solder alloy, that has been melted and solidified to form a metallurgical bond to a basis metal.

热熔涂覆层 **56.0557**
通常为锡或焊料合金的金属涂覆层，经熔融及固化后形成与金属基材的冶金接合。

Fusing **56.1676**
Melting of a metallic coating (usually electrodeposited tin or tin-lead) on a conductive pattern, followed by solidification.

热熔 **56.1676**
金属涂覆层在导电图形上（通常是电镀锡或锡铅）熔融，然后固化。

Fusing Fluid **56.0467**
The heat-transfer medium used to attain a fused coating.

热熔液 **56.0467**
用于获得热熔涂覆层的传热介质。

Fusing Flux **56.1408**
An activated organic fluid that is used in the fusing of a tin-lead plating on a basis metal. (The application of these predominantly water-soluble fluids is usually followed by the use of a fusing oil.)

热熔助焊剂 **56.1408**
用于在金属基材上热熔锡铅镀层的活性有机液体。（通常应用这些起主要作用的水溶性液体后，再使用热熔油。）

Fusing Oil **56.1409**
A thermally-stable, nonactivated, fluid that is used in the fusing of tin lead plating on a basis metal. (The application of these predominantly water-soluble fluids is usually preceded by the use of a fusing flux.)

热熔油 **56.1409**
一种热稳定非活性液体，用于在金属基材上热熔锡铅镀层。（通常先使用热熔助焊剂后，再应用这些起主要作用的水溶性液体。）

G

Galvanic Corrosion **76.1410**
Corrosion associated with the current of a galvanic cell consisting of two dissimilar conductors in an electrolyte or two similar conductors in dissimilar electrolytes.

电流腐蚀 **76.1410**
由一种电解质内两种不同导体或不同电解质内二种相同导体组成的原电池的电流引起的腐蚀。

Galvanic Deposition **53.0560**
See “Electrodeposition.”

电镀沉积 **53.0560**
见“电沉积，Electrodeposition”。

Galvanic Displacement **53.0561**
See “Immersion Plating.”

电镀置换 **53.0561**
见“浸镀，Immersion Plating”。

Gang Bonding **74.0562**
The making of several terminations simultaneously. (See also “Single-Point Bonding.”)

群点键合 **74.0562**
同时形成几个端接点的键合。（又见“单点键合，Single-Point Bonding”。）

Gas Blanket **75.0564**
A flowing inert gas atmosphere used to keep metallization from oxidizing.

气层 **75.0564**
用于防止金属化层氧化的惰性气流。

Gas-Tight Area **97.0563**
The common area between mated metal surfaces from which gas vapors and impurities are excluded.

气密区 **97.0563**
相配接金属面之间排除气体蒸汽和杂质进入的公共区域。

Gauge Precision **22.0559**
The absolute precision achieved in measuring feature size or feature location.

量具精密度 **22.0559**
测量要素尺寸或要素位置时达到的绝对精度。

Gaussian Distribution **94.1807**

See “Normal Distribution.”

高斯分布 **94.1807**

见“正态分布，Normal Distribution”。

Gel Time **55.0566**

The time in seconds required for prepreg to change its physical state from that of a solid material to a liquid, and then back to a solid material.

胶凝时间 **55.0566**

半固化片物理状态的改变，即从固体经液体再变为固态所需的时间，以秒为单位。

Gelation Particle **44.0565**

Microparticles of precured, usually translucent, resin in a laminate system.

胶化颗粒 **44.0565**

层压板中预固化的通常为半透明的树脂颗粒。

Generative Process Planning **91.0567**

A computer-based method whereby new process plans are created that are based on part or product information and manufacturing capabilities.

生成过程规划 **91.0567**

根据零件或产品信息及生产能力，使用计算机生成新工艺计划的方法。

Generic Specification (GS) **26.1782**

A document that describes as many general requirements as possible, pertaining to a set, family or group of products, materials, or service.

总规范（GS） **26.1782**

描述一套、一族或一组产品、材料或服务的尽可能齐全的通用要求文件。

Geometric Tolerance **22.0568**

A tolerance that is used to control form, profile, orientation, location and runout.

几何公差 **22.0568**

用于控制外形、形状、定向、位置和偏心的公差。

Gerber Data **25.1411**

A type of data that consists of aperture selection and operation commands and dimensions in X- and Y-coordinates. (The data is generally used to direct a photoplotter in generating photoplotted artwork.)

格柏数据 **25.1411**

由孔径选择、操作指令及X、Y坐标尺寸组成的数据类型。（这种数据可直接用于光绘机而产生光绘底片。）

Glass Binder **44.0569**

Glass powder added to a thick-film resistive or conductive ink in order to bind together the metallic particles after firing.

玻璃粘合剂 **44.0569**

为使金属颗粒在烧结后粘接在一起，添加到厚膜电阻或导电油墨中的玻璃粉。

Glass Cloth **44.1858**

A pliable material made by weaving glass fiber bundles into a fabric layer.

玻璃布 **44.1858**

通过把玻璃纤维束编织为织布层而制成的柔软材料。

Glass Fabric **44.1859**

Fabric woven with glass yarns.

玻璃织物 **44.1859**

用玻璃纱织成的织物。

Glass Distortion (Base Materials) **44.1860**

A localized variance in the linearity of the yarns of the reinforcement.

玻璃扭曲（基材） **44.1860**

增强材料中纱线直线性的局部变化。

Glass Transition Temperature (T_g) **55.1412**

The temperature at which an amorphous polymer, or the amorphous regions in a partially-crystalline polymer, changes from being in a hard and relatively-brittle condition to being in a viscious or rubbery condition.

玻璃化温度 **55.1412**

非晶态聚合物或部分结晶但仍属非晶态的聚合物，从硬而相对脆性的玻璃态转变为粘流态或高弹态时的温度。

Glass Yarn **44.1861**

A generic term for a continuous strand (collection) of twisted glass filaments (fibers) in a form suitable for weaving.

玻璃纱 **44.1861**

以适合编织的方式形成的一股（组）连续绞合的玻璃丝（纤维）的总称。

Globule Method **97.1862**
A test method that evaluates the solderability of a surface using a small ball of solder.

焊球测试法 **97.1862**
采用小焊料球评定表面可焊性的测试方法。

Go/No-Go Test **92.0570**
A testing process that yields only a pass or a fail condition.

通过/不通过测试 **92.0570**
仅产生通过或失效状态的测试过程。

Golden Assembly **92.0571**
See “Known Good Assembly.”

黄金组件 **92.0571**
见“确认好组件，Known Good Assembly”。

Golden Board **92.0572**
See “Known Good Board.”

黄金板 **92.0572**
见“确认好板，Known Good Board”。

Gouge **92.0573**
A form of wear that consists of a wide groove deformation, accompanied by material removal, that penetrates a considerable distance below a surface.

凿槽 **92.0573**
磨损的外形，即伴随有材料去除的宽沟槽变形，穿透表面且低于表面相当距离。

Graded Wedge **54.0574**
See “Etching Indicator.”

定级楔形图 **54.0574**
见“蚀刻指示图，Etching Indicator”。

Grading Frame **44.0575**
Equipment used to continuously inspect fabric by the use of backlighting.

分级系统 **44.0575**
采用背光连续检查织物所用设备。

Green Strength **56.0577**
The strength of substance, joint, or assembly before it has been cured (set).

未固化强度 **56.0577**
物质、接合点或组装件在固化前的强度。

Greige **44.0578**
Fabric in a loom state that has no finish.

生坯布 **44.0578**
处于织布状态还未完工的织物。

Grey-Scale Processing **92.0576**
The utilizing of more than one level of signal strength, intensity or amplitude to perform an inspection operation.

灰度处理 **92.0576**
采用多个等级信号强度、亮度或幅度完成检验操作。

Grid **22.1812**
An orthogonal network of two sets of parallel equidistant lines that is used for locating points on a printed board.

网格 **22.1812**
两组等距离平行直线正交而成的网络，用于定位印制板上的点。

Gross Leak **95.0580**
A leak in a sealed package that is greater than 0.00001 cubic centimeters per second at one atmosphere of differential air pressure.

重泄漏 **95.0580**
压力差为一个大气压时，已密封封装中大于0.00001 cm^3/s的泄漏。

Ground **20.0581**
A common reference point for electrical circuit returns, shielding, or heat sinking.

接地 **20.0581**
电气电路回路、屏蔽层或散热片的公共基准点。

Ground Plane **20.1413**
A conductor layer, or portion thereof, that serves as a common reference for electrical circuit returns, shielding, or heat sinking. (See also “Signal Plane” and “Voltage Plane.”)

接地层 **20.1413**
用作电气电路回路、屏蔽层或散热片的公共基准导体层或部分导体层。（参见“信号层，Signal Plane”和“电压层，Voltage Plane”。）

Ground Plane Clearance **22.1414**
Removed portions of a ground plane that isolate it from a hole in the base material to which the plane is attached. (See Figure G-1.) (See also “Signal Plane” and “Voltage Plane.”)

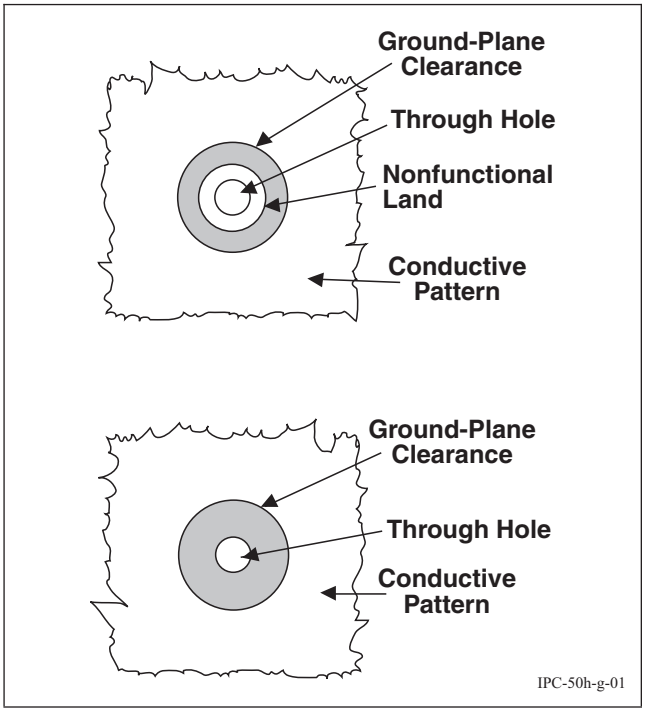
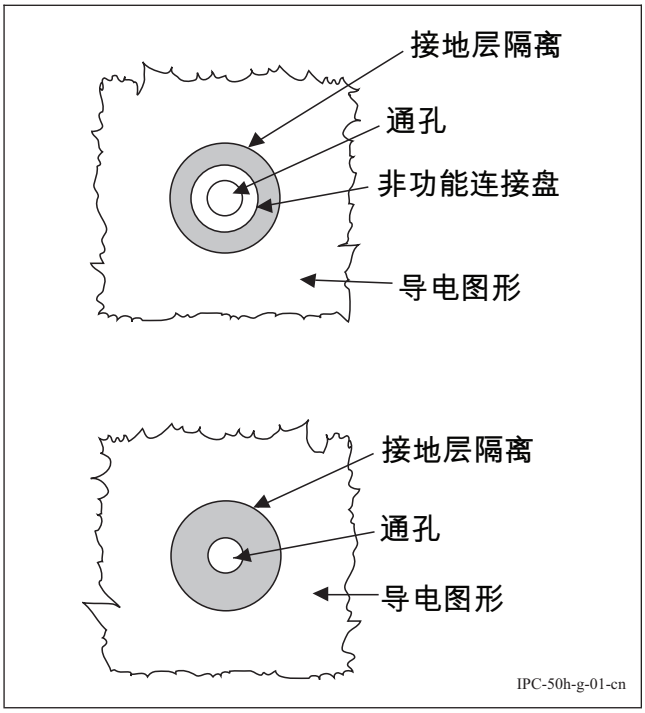


Figure G-1 Ground (or Voltage) Plane Clearance

接地层隔离 **22.1414**

从基材内孔周围蚀刻去除的部分接地层，可使接地层与同基材内的孔连接的层相隔离。（见图G-1。）（又见“信号层，Signal Plane”和“电压层，Voltage Plane”。）



图G-1 接地层（或电压层）隔离

Guarding **92.0582**

The in-circuit testing process of ensuring that a shunt path does not interfere with the testing of a device.

保护 **92.0582**

确保分路不会干扰器件测试的在线测试过程。

Guide Pin **37.0583**

A connector interfacing device that allows for connector body movement in order to facilitate contact alignment prior to contact engagement.

引导销 **37.0583**

允许连接器本体移动的连接器接口装置，以便于接触件在啮合前的对准。

Gull Wing Leads **36.1747**

An SMT lead form. Leads extending horizontally from the component body centerline, bent downward immediately past the body and then bent outward just below the bottom of the body, thus forming the shape of a gull’s wing.

翼形引线 **36.1747**

SMT引线的一种形式，引线从元器件本体中心线水平向外延伸，沿元器件体边缘垂直向下至元器件本体时，再向外弯曲，因而形成鸥翼形状的引线。

H

Halide Content (Flux) **76.0584**

The ratio of the mass of free halides to the mass of solids in a flux expressed in mass percent of free chloride ion.

卤化物含量（助焊剂） **76.0584**

助焊剂中游离卤化物质量与固体物质量之比，表示为游离氯离子的质量百分比。

Haloing **51.1415**

Mechanically-induced fracturing or delamination, on or below the surface of a base material, that is usually exhibited by a light area around holes or other machined features.

晕圈 **51.1415**

由于机械加工引起的基材表面上或表面下的破裂或分层，通常表现为在孔周围或其它机械加工部位的四周呈现泛白区域。

Hand Soldering **75.0585**

Soldering using a soldering iron or other hand-held, operator-controllable apparatus.

手工焊接 **75.0585**

用烙铁或其它操作者可以控制的手持装置进行的焊接。

Hard Wiring **75.0587**

Electrical wiring that is inseparable from an assembly without the use of special tools and processes.

硬连线 **75.0587**
不采用特殊工具或工艺就无法将其与组件分开的电气连线。

Hardeners **56.0586**
See “Curing Agent.”

硬化剂 **56.0586**
见“固化剂，Curing Agent”。

Header (Connector) **37.0589**
A pin field that is positioned in a 3- or 4-sided plastic housing that mounts directly onto a printed board.

接插件（连接器） **37.0589**
定位在直接安装在印制板上的3面或4面塑料外壳内的插针区。

Header (Module) **36.0590**
The base of an electronic component package that contains leads.

基座（模块） **36.0590**
含有引线的电子元器件封装基体。

Heat Absorption Coefficient **21.1863**
The degree to which various materials absorb heat or radiant energy when compared to each other.

吸热系数 **21.1863**
衡量不同材料吸收热量或辐射能量的程度的物理量。

Heat Cleaning **44.0591**
A process in which organic yarn binder (size) is removed from a fabric. (See also “Sizing.”)

热清洗 **44.0591**
从织物上除去纱线有机粘接剂（浆料）的过程。（又见“上浆，Sizing”。）

Heat Column **75.0592**
The heating element in a eutectic die bonder or wire bonder that is used to bring the base material up to its bonding temperature.

热杆 **75.0592**
在共晶芯片键合机或金属线键合机中用来升高基材到键合温度的加热元器件。

Heat of Fusion **56.0593**
The quantity of heat required to convert a unit weight of solid material to its liquid state.

熔化热 **56.0593**
将一个单位重量的固态材料转变为液态所需要的热量。

Heat Resistance **21.1864**
The degree to which a material resists changes in its physical properties when subjected to changes in temperature.

耐热性 **21.1864**
当经受温度变化时，材料抵抗物理属性变化的能力。

Heatsink **30.0594**
A mechanical device that is made of a high thermal-conductivity and low specific-heat material that dissipates heat generated by a component or assembly.

散热片 **30.0594**
用高导热性和低比热材料制成的机械装置，可散发元器件或组件所产生的热量。

Heatsink Plane **22.0595**
A continuous sheet of metal on or in a printed board that functions to dissipate heat away from heat generating components.

散热层 **22.0595**
印制板内或印制板上的一种连续金属片，其作用是消散元器件产生的热量。

Heatsink Tool **75.1416**
A heatsink that is temporarily attached to a heat-sensitive component in order to minimize the transfer of heat from the component lead to the component body during a soldering operation.

散热工具 **75.1416**
焊接操作过程中，一种暂时连接于对热敏感元器件的散热片，使元器件引线传到元器件本体的热量达到最小。

Heavy Mark (Fabric) **44.0596**
A filling defect that extends across the width of a fabric containing in excess of two picks per inch from nominal.

厚段（织物） **44.0596**
贯穿织物宽度的纬线缺陷，每英寸长度内的纬纱数比标称值多2根以上。

Heel, Bonding **74.0598**
The part of a lead adjacent to a termination that has been deformed by the edge of the bonding tool.

键合倾斜 **74.0598**

由于键接工具的边棱造成的靠近端接点的引线部分变形。

Heel Break **97.0599**

The rupture of a lead at the heel of a bond.

跟部断裂 **97.0599**

引线在键合跟部发生的断裂。

Heel Crack **97.0600**

A crack across the width of a lead at the heel of a bond.

跟部裂缝 **97.0600**

在键合跟部发生的横跨引线宽度的裂缝。

Heel (Drill) **51.0597**

The trailing edge of a drill land.

后棱（钻头） **51.0597**

钻头刃带的后缘。

Heel Fillet **73.1866**

The solder fillet formed in the land area behind the lead. (See Figure H-1.)

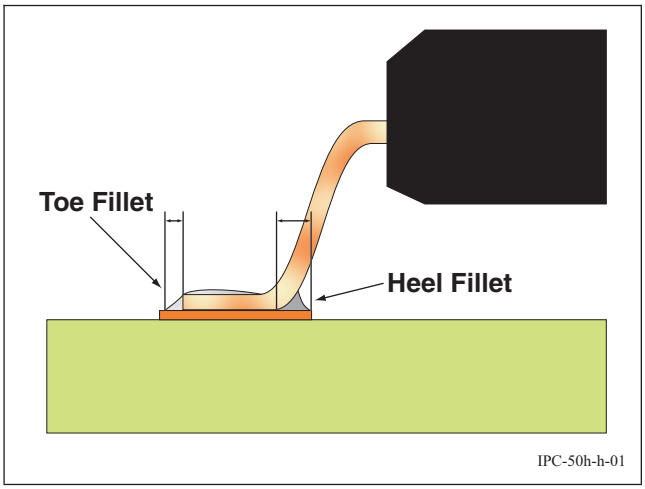


Figure H-1 Heel Fillet

跟部填充 **73.1866**

在引线后的连接盘区域所形成的焊料填充。（见图H-1。）

Helix Angle **51.0601**

The angle of the spiral generated by the flute of a drill with respect to the axis of the drill.

螺旋角 **51.0601**

钻头排屑槽与钻头轴线形成的螺旋形角。

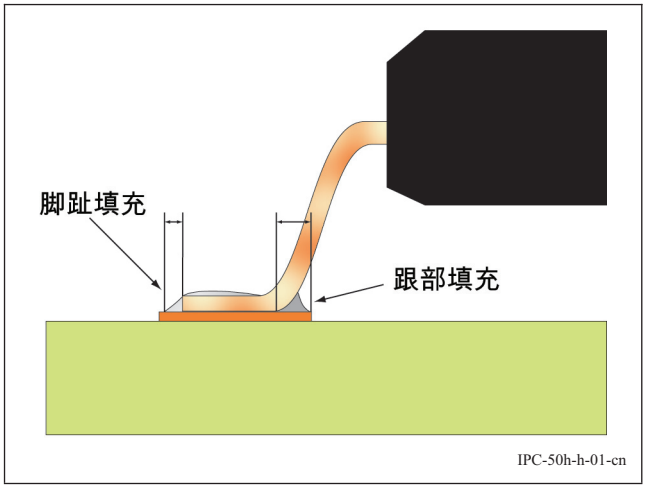


Figure H-1 Heel Fillet

Hermaphroditic Contact **37.0602**

A type of connector contact that mates with a contact that is identical to itself.

等同接合接触件 **37.0602**

可与其相同的接触件配接的连接器接触件。

Hermetic (Sealed) **30.1867**

The condition of sealing a component from incoming gases to a specific of inward diffusion normally less than 1 x 10^{-6} cubic cm per second.

密封 **30.1867**

气体向元器件内扩散的速度通常小于1 x $10^{-6}cm^3/s$的元器件密封状况。

Heterocyclic **76.0603**

A cyclic or ring structure, often in the shape of a pentagon, in which one or A cyclic or ring structure, often in the shape of a pentagon, in which one or more of the atoms in the ring is an element other than carbon.

杂环化合物 **76.0603**

一般为五边形的环状结构，在该结构中有一个或多个原子不是碳原子。

Hierarchical Database **11.0604**

A database that is arranged in a tree-like structure of logic.

分级数据库 **11.0604**

以树型逻辑结构排列的数据库。

High Density Interconnect (HDI) **22.2182**

A generic term for substrates or boards with a higher circuit density per unit area than conventional printed boards.

高密度互连（HDI） **22.2182**

单位面积电路密度比传统印制板的电路密度高的基板或电路板通用术语。

High Density Plastic Quad Flat Pack **33.1868**

A QFP with greater than 196 leads at a pitch of 0.4 millimeters.

高密度塑料方形扁平封装 **33.1868**

引线数大于196根，间距为0.4mm的QFP封装。

High-Impedance State **21.0605**

See “Tri-State.”

高阻抗状态 **21.0605**

见“三态，Tri-State”。

High-Voltage Wire **37.0606**

Insulated wire, with an insulation thickness that is determined by corona-related factors, that is used for voltages over 240 Vac RMS or over 340 Vdc.

高压线 **37.0606**

由电晕放电相关因子确定绝缘厚度的一种绝缘线，用于超过240的交流电压（均方根）或超过340V的直流电压（DC）。

Hipot Test **92.0607**

A method in which the unit under test is subjected to a high alternating current (AC) voltage.

高压测试 **92.0607**

待测单元经受高交流电压测试的方法。

Histogram **91.0608**

A graph that depicts values that were obtained by dividing the range of a data set into equal intervals and that plots the number of data points in each interval. (See Figure H-2.)

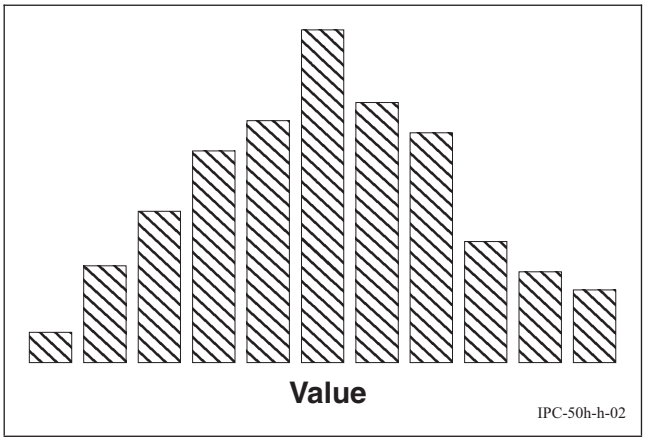
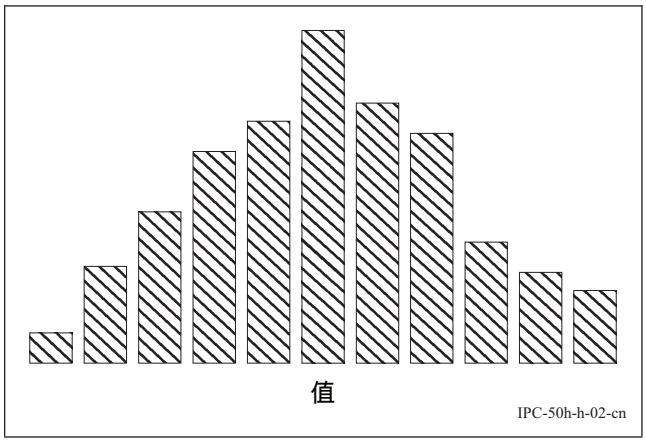


Figure H-2 Histogram

直方图 **91.0608**

将数据范围设置成等间距并以每个间距内的数据点数来绘制数据值而得到的图。（见图H-2。）



图H-2

Hole, Knee **53.1711**

The intersection of the wall of a hole at the outermost surface of the printed board. (See Figure H-3.)

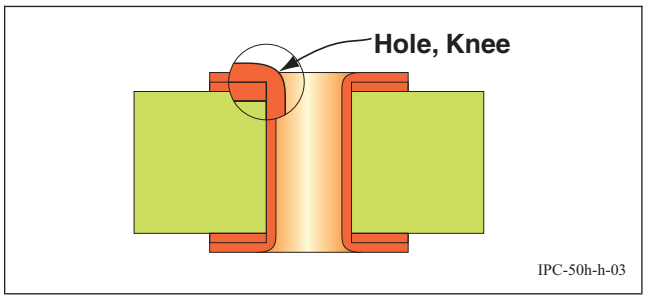
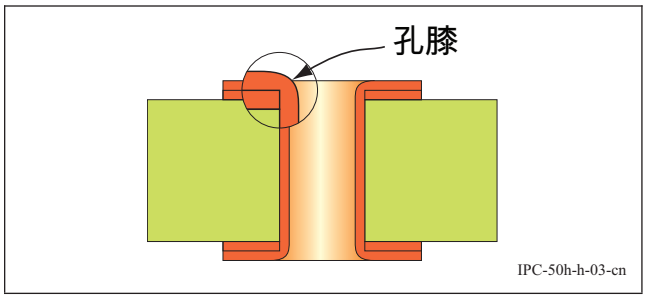


Figure H-3 Hole, Knee

孔膝 **53.1711**

PCB最外层表面与孔壁的交叉部分。（见图H-3。）



图H-3 孔膝

Hole Base Positioning **51.1870**

The positioning of a printed board/panel or board assembly/array using tooling holes on the board to facilitate further manufacturing.

孔基准定位 **51.1870**

为便于后续的生产，使用板上的定位孔定位印制板/在制板或板组件/排列。

Hole Breakout **60.1699**

A condition in which a hole is not completely surrounded by the land. (See Figure H-4.)

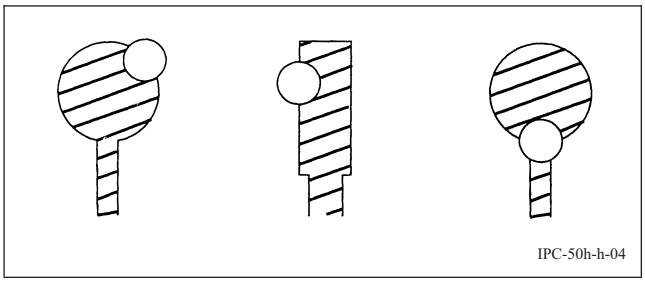
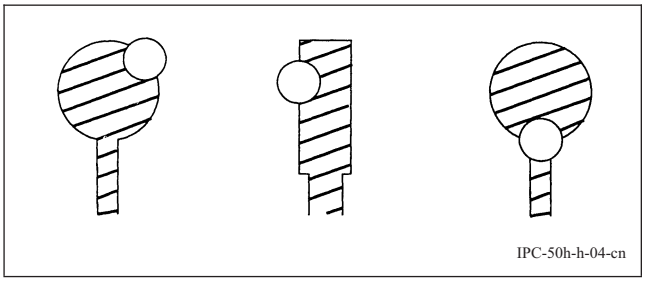


Figure H-4 Hole Breakout

孔破出 **60.1699**

孔未完全被连接盘包围的状况。（见图H-4。）



图H-4 孔破出

Hole Density **22.0610**

The quantity of holes in a unit area of printed board.

孔密度 **22.0610**

单位面积印制板中孔的数量。

Hole Edge Roughness **51.1709**

Unevenness of the edge of a hole formed by drilling or punching.

孔边粗糙度 **51.1709**

由于钻孔或冲压孔所形成的孔边缘不平整的情况。

Hole Filling Process **52.1979**

A process of adding a conductive or nonconductive fill material to a plated through-hole, followed by adding an etch resist that covers the hole and its land. The process also includes etching away of the unwanted copper and subsequent stripping of the etch resist.

填孔工艺 **52.1979**

将导电或非导电填充材料填加到镀覆孔内，再填加抗蚀剂覆盖孔及其连接盘的过程。该过程还包括蚀刻去除不需要的铜，再剥除抗蚀剂的步骤。

Hole Plugging Process **52.1980**

A process of plugging a plated through-hole with liquid solder mask material after the circuit configuration has been completed in order to prevent chemistry from entering the hole during the assembly process.

塞孔工艺 **52.1980**

在电路结构完成之后，为了阻止组装工艺期间化学物质进入孔中，用液体阻焊油墨将镀覆孔堵塞的过程。

Hole Location **22.0611**

The dimensional position of the center of a hole.

孔位 **22.0611**

孔中心的位置尺寸。

Hole Pattern **22.1621**

The arrangement of all the holes in a printed board or production board.

孔图 **22.1621**

印制板或在制板中所有孔的排列。

Hole Pull Strength **53.0613**

The load or pull force along the axis of a plated-through hole that will rupture the hole.

孔拉出强度 **53.0613**

沿镀覆孔的轴向可使孔破裂的负载或拉力。

Hole Roughness **51.1710**

The coarseness of a hole (at the knee of the hole) or on the wall (barrel) of the hole caused by drilling or punching.

孔粗糙度 **51.1710**

由于钻孔或冲压孔而导致孔（孔膝处）或孔壁粗糙。

Hole Void **53.0614**

A void in the metallic deposit of a plated-through hole that exposes the base material. (See Figure H-5.)

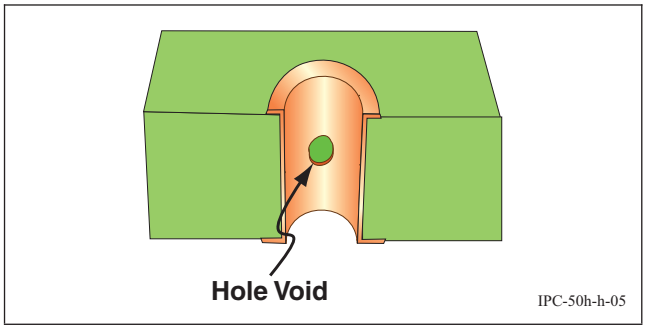
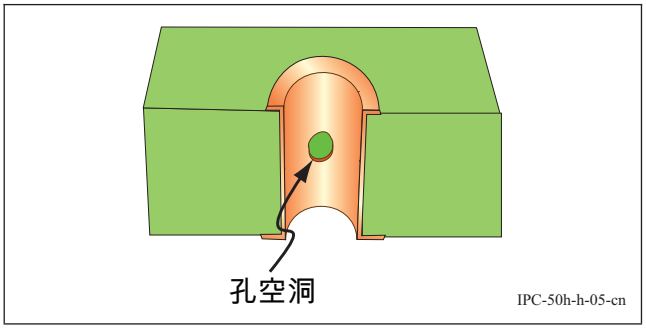


Figure H-5 Hole Void

孔空洞 **53.0614**

导致镀覆孔金属沉积内暴露出基材的空洞。（见图H-5。）



图H-5 孔空洞

Homocyclic **76.0615**

A ring compound containing only one kind of atom in its ring structure.

同素环化合物 **76.0615**

在环形结构中只含有一种原子的环形化合物。

Homologous Series **76.0616**

A series of organic compounds in which each successive member has one more CH2 group in its molecule than the preceding member.

同源系列 **76.0616**

其每个后续分子较前一个分子增加一个CH2基团的有机化合物系列。

Homopolymer **76.0617**

A polymer derived from a single monomer with the aid of initiators that act in the manner of catalysts.

均聚物 **76.0617**

在引发剂作用下，以催化的方法单一的单体所形成的聚合物。

Hook **51.0618**

The rake condition in the flute face of a drill. (See Figure H-6.)

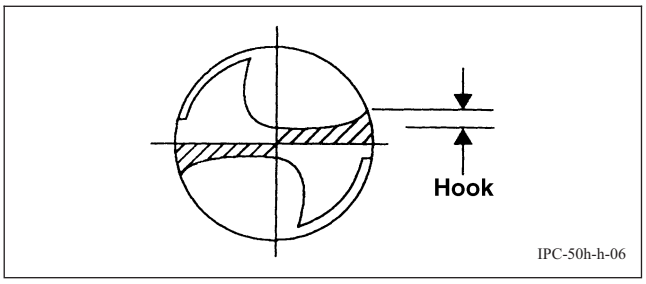
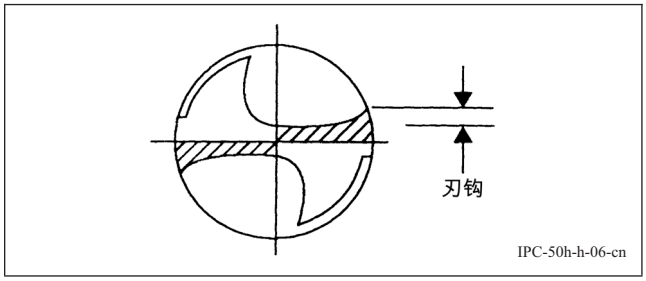


Figure H-6 Hook

刃钩 **51.0618**

钻头排屑面的倾斜状态。（见图H-6。）



图H-6 刃钩

Hook Solder Terminal **37.0619**

A solder terminal with a curved feature around which one or more wires are wrapped prior to soldering. (See Figure H-7.)

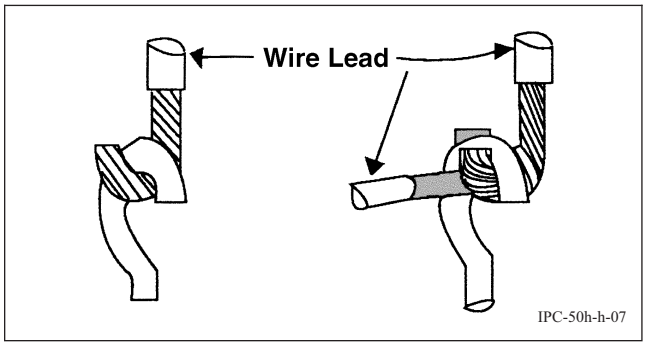
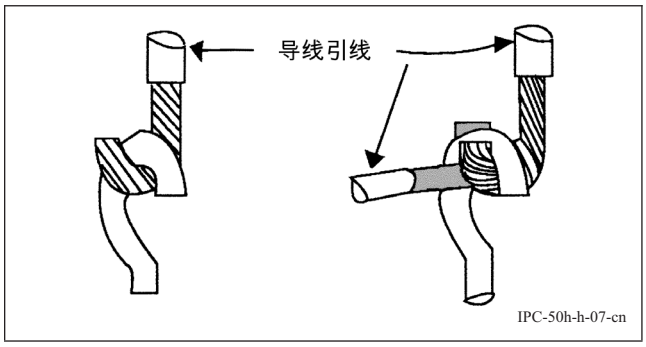


Figure H-7 Hook Solder Terminal

钩形焊接接线柱 **37.0619**

焊接前可缠绕一条或多条导线的弯曲形状焊接接线柱。（见图H-7。）



图H-7 钩形焊接接线柱

Horn **74.0620**

A cone-shaped object that transmits ultrasonic energy from a transducer to a bonding tool.

喇叭 **74.0620**

将超声波能量从振子传送到键接工具的锥形物体。

Hot Air (Solder) Leveling (HASL) **53.1871**

A physical deposition process using a solder bath into which the printed board is immersed into a molten solder bath and withdrawn across a set of hot air knives (forced hot air flow) used to remove excess solder.

热风（焊料）整平（HASL） **53.1871**

物理沉积工艺，即将印制板浸入熔融的焊料槽中，取出后采用一组热风刀（强制热风流）去除印制板上多余的焊料。

Hot Air Reflow Soldering **75.1872**

A method of reflow soldering where heated air is circulated in a reflow chamber.

热风再流焊接 **75.1872**

热风在再流焊炉膛内循环加热的再流焊接方法。

Hot Bar **75.1873**

A bonding tool for soldering leads of TAB of QFP to substrate using local heat and pressure.

加热棒 **75.1873**

用局部热量和压力将QFP的TAB引线焊接到基板上的键合工具。

Hot Plate Reflow Soldering **75.1748**

Reflow soldering using direct contact or close proximity to a hot plate as the primary source of heat.

热板再流焊接 **75.1748**

利用发热板的直接接触或紧密作为主要热源而进行的再流焊接。

Humidity Aging **92.1874**

The exposure to a humid environment as a preconditioning step before a test for component reliability.

潮湿老化 **92.1874**

在元器件可靠性测试之前，将其暴露在潮湿环境下进行预处理。

Humidity Indicator Card (HIC) **92.1875**

A card on which a moisture sensitive chemical is printed such that it will change color from blue to pink when the indicated relative humidity is exceeded.

湿度指示卡（HIC） **92.1875**

印有湿敏化学药物质的卡片，当指示卡的颜色由蓝色变为红色时则表示相对湿度超标。

Hybrid Circuit **83.1417**

A circuit comprising insulating base material with various combinations of interconnected film conductors, film components, semiconductor dice, passive components and bonding wire.

混合电路 **83.1417**

在绝缘基材上由薄膜导体、薄膜元器件、半导体芯片、无源元器件和键合金属线等不同互连组合而成的电路。

Hybrid Integrated Circuit **83.1418**

A circuit comprising insulating base material with various combinations of interconnected film conductors, film components, semiconductor dice, passive components and bonding wire that perform the same function as a monolithic semiconductor integrated circuit.

混合集成电路 **83.1418**

在绝缘基材上由薄膜导体、薄膜元器件、半导体芯片、无源元器件和键合金属线等不同互连组合而组成的电路，其能执行与单块半导体集成电路相同的功能。

Hybrid Microcircuit **83.1419**

A circuit comprising insulating base material with various combinations of interconnected film conductors, film components, semiconductor dice, passive components and bonding wire.

混合微电路 **83.1419**

在绝缘基材上由薄膜导体、薄膜元器件、半导体芯片、无源元器件和键合金属线等不同互连组合而成的电路。

Hydrocarbon Tolerance **76.0621**

See “Dilution Ratio.”

碳氢化合物容限 **76.0621**

见“稀释比，Dilution Ratio”。

Hydrolytic Stability **76.0622**

The degree of resistance of a polymer to permanent property changes from hydrolytical effects.

水解稳定性 **76.0622**

聚合物受水解用而引起永久性的性能变化的耐受程度。

Hydrophilic Matter **76.0623**

See “Polar Matter.”

亲水物质 **76.0623**

见“极性物质，Polar Matter”。

Hydrophilic Solvent **76.0624**

See “Polar Solvent.”

亲水溶剂 **76.0624**

见“极性溶剂，Polar Solvent”。

Hydrophobic Matter **76.0625**

See “Nonpolar Matter.”

疏水物质 **76.0625**

见“非极性物质，Nonpolar Matter”。

Hydrophobic Solvent **76.0626**

See “Nonpolar Solvent.”

疏水溶剂 **76.0626**

见“非极性溶剂，Nonpolar Solvent”。

Hydrotrope **76.0627**

A chemical that can increase the aqueous solubility of slightly-soluble organic chemicals.

水溶助剂 **76.0627**

能增加难溶有机化学物在水中溶解度的化学物。

Hydrotrophe **76.0628**

See “Hydrotrope.”

水溶助长性 **76.0628**

见“水溶助剂，Hydrotrope”。

Hypersorption **76.0629**

The process by which activated carbon selectively absorbs less-volatile components from a gaseous mixture while the more-volatile components are unaffected.

超吸附 **76.0629**

活性碳从气体混合物中选择性地吸收较低挥发性成分，而易挥发成分不受影响的过程。

Hypotheses Test **91.0630**

An objective method to determine and quantify, within known levels of risk, whether or not a hypothesis is either accepted or rejected.

假设测试 **91.0630**

在已知风险水平内，无论假设是接收还是拒收，定性和定量的客观测试方法。

I

Icicle **75.0631**

See “Solder Projection.”

焊料毛刺 **75.0631**

见“焊料拉尖，Solder Projection”。

Identical Processing **91.0632**

Fabrication that is conducted under conditions that have demonstrated the capability to produce measurable attributes within a narrow band of variability.

等同加工 **91.0632**

证明能够在很小变化范围内生产可测量特征的条件下进行的生产加工。

Illuminance **24.0633**

Luminous flux striking a surface.

照度 **24.0633**

照射于一个表面的光通量。

Illumination **24.0634**

See “Illuminance.”

照明度 **24.0634**

见“照度，Illuminance”。

Image Blur **52.1575**

The state that a part of an image of the original film is not reproduced on the resist or in the pattern transfer.

图像模糊 **52.1575**

原始底片的部分图象不能再现于阻焊剂上或不能形成图形转移的状态。

Immersion Attitude **75.1749**

The positioning of an object when immersed in a solder bath.

浸入位置 **75.1749**

物体浸入到焊接槽中的位置。

Immersion Conditions **95.1750**

Test conditions resulting when surface mount device package leads are immersed into a solder bath to check resistance to soldering temperatures.

浸入条件 **95.1750**

表面贴装器件的封装引线浸入到焊接槽中，以检查耐焊接温度而形成的测试条件。

Immersion Plating **53.0635**

The chemical deposition of a thin metallic coating over certain basis metals that is achieved by a partial displacement of the basis metal.

浸镀 **53.0635**

在某种金属基材上化学沉积一层薄金属涂覆层，它是通过部分置换金属基材而实现。

Impedance **21.1801**
The resistance to the flow of current, represented by an electrical network of combined resistance, capacitance and inductance, in a conductor as seen by an AC source of varying time voltage. The unit of measure is ohms.

阻抗 **21.1801**
电流通过时的阻力，它相当于电阻、电容和电感作用组合的电气网络，如在导体中看到的电压随时间变化的交流电那样。其计量单位为欧姆。

Impulse Current Soldering **75.1876**
See “Parallel-Gap Soldering.”

脉冲电流焊接 **75.1876**
见“双极焊接，Parallel-Gap Soldering”。

In-Circuit Testing **92.0636**
The application of test signals directly to a device’s input terminals and sensing the results directly from the device’s output terminals.

在线测试 **92.0636**
直接将测试信号加在器件的输入端，并从器件的输出端检测结果的测试。

In-Process Inspection **91.1879**
An evaluation of quality characteristics relating to a standard, specification, or design drawing during the manufacturing cycle and prior to completion of all manufacturing processes.

过程检验 **91.1879**
在制作过程中和所有制作过程完成之前，根据标准、规范或设计图纸对质量特征的评定。

Inclusions **90.0637**
Foreign particles, metallic or nonmetallic, that may be entrapped in an insulating material, conductive layer, plating, base material, or solder connection.

夹杂物 **90.0637**
夹裹在绝缘材料、导体层、镀层、基材、或焊接连接中的金属或非金属外来颗粒。

Indentation **45.0638**
See “Dent.”

凹痕 **45.0638**
见“压痕，Dent”。

Independent of Size **22.0639**
The concept that requires the tolerance of form or position to vary independent of, and without regard to, feature size.

尺寸独立原则 **22.0639**
形位公差要求与要素尺寸变化无关的概念。

Index Edge **22.0640**
See “Locating Edge.”

标志边 **22.0640**
见“定位边，Locating Edge”。

Index Edge Marker **22.0641**
See “Locating Edge Marker.”

标志边标识 **22.0641**
见“定位边标识，Locating Edge Marker”。

Indexing Hole **22.0642**
See “Tooling Hole.”

标志孔 **22.0642**
见“定位孔，Tooling Hole”。

Indexing Notch **22.0643**
See “Locating Notch.”

标志口 **22.0643**
见“定位切口，Locating Notch”。

Indexing Slot **22.0644**
See “Locating Slot.”

标志槽 **22.0644**
见“定位槽，Locating Slot”。

Individual Test Pattern (ITP) **24.1791**
A single test pattern designed and intended to serve a specific evaluation technique for determining a particular aspect(s) of a manufacturer or manufacturing process capability.

单独测试图形（ITP） **24.1791**
为了确定制造商或制造过程在某一方面的能力而设计并用于特定评估的单独测试图形。

Individual Test Specimen (ITS) **92.1790**
A single test specimen that contains an individual test pattern (ITP) and is used to determine a particular aspect(s) of a manufacturer or manufacturing process capability.

单独试样（ITS） **92.1790**
含有一个单独测试图形（ITP）的单个试样，用于测定制造商或制作过程在某一方面的能力。

Inductance **21.1802**

The property of a conductor that allows it to store energy in a magnetic field induced by a current flowing through it. The unit of measure is henry (H).

电感 **21.1802**

由于电流流过导线而产生磁场，使导体储存能量的特性。其计量单位是亨利（H）。

Infrared Reflow (IR) **75.1751**

Remelting of solder using infrared heating as the primary source of energy.

红外再流（IR） **75.1751**

利用红外加热作为主要能源使焊料重熔。

Infrared Soldering **75.1877**

A reflow soldering using infrared energy as the source of heat. (See “Infrared Reflow.”)

红外焊接 **75.1877**

利用红外能量作为热源的再流焊接。（又见“红外再流，Infrared Reflow”。）

Initiating **53.0645**

See “Activating.”

引发 **53.0645**

见“活化，Activating”。

Inner Layer **22.1878**

See “Internal Layer.”

内层 **22.1878**

见“内层，Internal Layer”。

Inner-Lead Bond (ILB) **74.0646**

The connection between a conductor on a bonding tape and a bare die. (See also “Outer-Lead Bond.”)

内引线键合（ILB） **74.0646**

键合带上的导体与裸芯片之间的连接。（又见“外引线键合，Outer-Lead Bond”。）

Innerlayer Connection **22.1427**

A conductor that connects conductive patterns on internal layers of a multilayer printed board, e.g., a plated-through hole. (See also “Interfacial Connection.”)

层间连接 **22.1427**

连接多层印制板内层上导电图形的导体，如镀覆孔。（又见“面间连接，Interfacial Connection”。）

Inorganic Flux **75.0647**

An aqueous flux solution of inorganic acids and halides. (See also “Acid Flux.”)

无机助焊剂 **75.0647**

含有无机酸和卤化物的水溶性助焊剂溶液。（又见“酸性助焊剂，Acid Flux”。）

Input Vector **92.0648**

A set of logic values to be applied to the complete set of input test points at any one point in time.

输入矢量 **92.0648**

被及时施加到整组输入测试点中任意点的一组逻辑值。

Insert (Connector) **37.1420**

The element that holds connector contacts in their proper arrangement and electrically insulates the contacts from one another and from the connector shell.

嵌入物（连接器） **37.1420**

可保持连接器接触件正确排列，并使接触件相互绝缘，且与连接器外壳绝缘的零件。

Insertion Loss **21.1880**

The ratio of transmitted electromagnetic power to incident power, usually expressed in decibel (dB) units. This loss of power includes losses by conversion to heat in the dielectric and in the conductors.

插入损耗 **21.1880**

输出的电磁功率与入射波功率之比，通常用单位分贝（dB）表示。功率的损耗包括在电介质和导体内转换成热的损耗。

Inspection Facility **92.1421**

The combination of equipment, personnel, and procedure resources that perform inspection measurements and evaluations for the purpose of ascertaining the conformance of a product to applicable specifications.

检验设施 **92.1421**

为确定产品与适用技术规范的符合性而完成检验测量和评定的设备、人员与程序资源的组合。

Inspection Lot **92.1422**

A collection of units of product that are identified and treated as a unique entity from which a sample is drawn and inspected in order to determine conformance with acceptability criteria.

检验批 **92.1422**

作为特定的整体鉴别和处理的产品单元集合，从中抽取一个样品检验来确定其与所适用可接受性准则的符合性。

Inspection Overlay **91.0649**

A positive or negative transparency that is made from the production master and that is used as an inspection aid.

覆盖检验板 **91.0649**

由生产底版制成的正相或反相透明底片，用作检验的辅助工具。

Inspection Personnel **92.0650**

Those individuals that inspect products for the purpose of ascertaining the conformance of a product to applicable specifications.

检验人员 **92.0650**

为确定产品与适用规范的符合性而检验产品的人员。

Inspection Rate **92.0651**

The number of features per unit of time that can be evaluated at specified false-alarm and escape-rate settings.

检验速率 **92.0651**

在规定的假警报和漏失率的设定下，单位时间内能被评定的要素的数量。

Instrument Bus **21.1423**

Four common lines or channels to which any analog test instrument can be connected via a multiplexer and any unit under test circuit mode that can be connected via a scanner.

测试仪器总线 **21.1423**

四条公共线路或通道，可通过多路转换器与任何模拟测试仪器连接，也可通过扫描仪与待测试电路模型的任一单元连接。

Insufficient Solder Connection **97.1424**

A solder connection that is characterized by the incomplete coverage of one or more of the surfaces of the connected metals and/or by the presence of incomplete solder fillets.

焊接连接不充分 **97.1424**

被连接金属出现一个或多个表面未被完全覆盖和/或焊料填充不完整的焊接连接。

Insulation **40.1813**

A material with a high resistance to the flow of electrical current. (See also “Dielectric.”)

绝缘体 **40.1813**

对电流流动具有高阻抗的材料。（又见“电介质，Dielectric”。）

Insulation Resistance **21.1425**

The electrical resistance of an insulating material that is determined under specific conditions between any pair of contacts, conductors, or grounding devices in various combinations.

绝缘电阻 **21.1425**

在规定条件下，任何一对各种组合的接触件、导体、或接地装置之间测得的绝缘材料的电阻。

Integrated Circuit **30.1426**

A combination of inseparable associated circuit elements that are formed in place and interconnected on or within a single base material to perform a particular electrical function.

集成电路 **30.1426**

为执行特定的电气功能，在单一的基材上面或内部形成并实现互连的一种不可分割的电路元器件组合。

Integrated Passive Component **30.2162**

A passive electrical component (resistor, capacitor, etc.) that is embedded and integrated within the cross section, or layers, of a printed board.

集成被动（无源）元器件 **30.2162**

埋入或集成入印制板横截面内或多层内的被动（无源）电气元器件（电阻、电容等）。

Inter-Test Time (ITT) **92.0652**

The duration between two successive driver strobes.

测试间隔时间（ITT） **92.0652**

驱动器两个连续选通脉冲之间的持续时间。

Interconnection Density **22.1822**

The average number of conductors, based on conductor width and clearance, that may be routed in a prescribed unit area, e.g., cm^2, considering that there is no restriction within the area to the routing condition and that the conductor length is equal to the unit length of the prescribed area.

互连密度 **22.1822**

基于导体宽度和间隔，在规定的单位面积内如cm^2可以布局的导体平均数，考虑到布局状况区域没有限制，导体长度等于规定面积的单位长度。

Interface Resistance **37.0653**

See “Contact Resistance.”

界面电阻 **37.0653**

见“接触电阻，Contact Resistance”。

Interfacial Connection **22.0654**

A conductor that connects conductive patterns on both sides of a printed board, e.g., a plated-through hole. (See also “Interlayer Connection.”)

面间连接 **22.0654**

连接印制板两面导电图形的导体，如镀覆孔。（又见“层间连接，Interlayer Connection”。）

Intergranular Corrosion **76.0655**

Corrosion that occurs preferentially at grain boundaries.

晶间腐蚀 **76.0655**

首先在晶粒分界处发生的腐蚀。

Interlaminar Metallization **53.0656**

Metal through-migration that is the result of metal deposition or migration along delaminated areas of the interior of a laminate.

层内金属化 **53.0656**

沿着层压板内部分层部位发生金属沉积或迁移，导致金属贯穿迁移。

Interlayer Connection **22.1614**

An electrical connection between two or more layers of conductive patterns on or in a printed board.

层间连接 **22.1614**

印制板上或内部不同层导电图形之间的电气连接。

Intermetallic Compound, Solder **75.1428**

An intermediate layer in a wetted solder connection between the wetted surface and the solder, consisting of the solution of at least one constituent of the wetted surface and at least one constituent of the solder.

焊料金属间化合物 **75.1428**

由被润湿表面的至少一种成分与焊料的至少一种成分所组成的位于润湿表面与焊料之间的润湿焊点内的中间层。

Intermittent Fault **97.0657**

A fault whose effect on a circuit appears and disappears at irregular intervals.

间歇故障 **97.0657**

以不规则的间隔出现和消失而影响电路的故障。

Internal Capability Assessment **91.1881**

Periodic supplier verification of data captured through process control and analyzed for variation that exceeds the performance limits desired by the manufacturing processes.

内部能力评估 **91.1881**

通过获取供应商过程控制的数据并分析超出制造过程所希望的性能极限的变异，对其进行周期性验证。

Internal Layer **22.0658**

A conductive pattern that is contained entirely within a multilayer printed board.

内层 **22.0658**

完全包含在多层印制板内部的导电图形。

Interposer **30.2153**

A material placed between two surfaces giving electrical insulation, redistribution of electrical connections, mechanical strength and/or controlled mechanical and thermal separation between the two surfaces.

中介基板 **30.2153**

介于两个表面之间的一种材料，可实现两个表面的电气绝缘、重新分布电气连接、并可提高机械强度、控制两个表面的机械和热分离。

Interstitial Via **22.0659**

See “Blind Via” and “Buried Via.”

中间孔 **22.0659**

见“盲孔，Blind Via”和“埋孔，Buried Via”。

Intrusive Soldering **75.1882**

A process in which the solder paste for the through-hole components is applied using a stencil or syringe to accommodate through-hole components that are inserted and reflow-soldered together with the surface-mount components.

通孔再流焊接 **75.1882**

采用漏印模板或注射器给通孔插装元器件施加焊膏，使通孔插装元器件与表面贴装元器件一起完成再流焊接的工艺。

Intumescence **56.0660**

The foaming or swelling of a material when it is exposed to high surface temperatures or flames.

膨胀 **56.0660**

材料暴露于高表面温度或火焰时发生的起泡和膨胀。

Ion Exchange **76.0661**
A reversible chemical reaction between a solid and a fluid by means of which ions are interchanged from one substance to another.

离子交换 **76.0661**
利用一种固体和一种液体之间离子从一种物质到另一种物质之间的交换而进行的可逆化学反应。

Ionic Cleanliness **76.0663**
The degree of surface cleanliness with respect to the number of ions or weight of ionic matter per unit square of surface.

离子清洁度 **76.0663**
用单位表面积内所含有的离子数量或离子物质重量来表示表面清洁的程度。

Ionizable (Ionic) Contamination **76.1222**
A polar (ionic) compound, usually a processing residue, that dissolves in water as free ions. (This includes flux activators, finger prints, etching or plating salts, etc., that decrease the resistivity of water when they are dissolved in it.)

可电离（离子）污染物 **76.1222**
一种极性（离子）混合物，通常是加工后的残留物，溶于水中成为自由离子（包括助焊剂的活化剂、手指印、蚀刻或电镀盐等，它们溶于水时，能降低水的电阻率。）

Isotropy **40.1885**
The condition for a substance having a value for a property that is the same in all directions.

各向同性 **40.1885**
物质在所有方向上都有相同特性值的状态。

J

J-Leads **36.1752**
The preferred surface mount lead form used on PLCCs, so named because the lead departs the package body near its Z axis centerline, is formed down and then rolled under the package. Leads so formed are shaped like the letter “J.”

J型引线 **36.1752**
首选用于PLCC的表面贴装引线形式，引线从靠近封装本体的Z轴中心线向外伸出，并向下延伸，然后再向内弯曲至封装体底部，这样成型的引线类似字母“J”，因此得名。

Jet Wave Soldering **75.1886**
A type of wave soldering that uses a pump to force solder up through a narrow slit to form a solder jet.

喷射波峰焊接 **75.1886**
采用泵强制焊料向上通过一个窄缝形成焊料喷射的波峰焊接。

Job Set **25.0664**
A group of one or more data-information modules.

作业包 **25.0664**
一个或多个数据信息模块组合。

Jumper Wire **37.0665**
A discrete electrical connection that is part of the original design and is used to bridge portions of the basic conductive pattern formed on a printed board.

跳线 **37.0665**
一种分立的电气连接，是原始设计的一部分，用于跨接印制板上形成的部分基本导电图形。

Junction Temperature **35.0666**
The temperature of the region of a transition between the p-type and n-type semiconductor material in a transistor or diode element.

结温度 **35.0666**
晶体管或二极管元器件中P型和N型半导体材料之间过渡区的温度。

Just-in-Time (JIT) **17.1429**
Production control techniques that minimize inventory by delivering parts and material to a manufacturing facility just before they are incorporated into a product.

即时管理（JIT） **17.1429**
使库存量保持最少的生产控制技术，即就在产品开始生产之前，才将其所需的零部件和材料送至制造车间。

K

Kerf **77.0667**
A laser-beam or abrasive-jet cut (slit) in a film component as a part of the trimming operation.

切口 **77.0667**
膜元器件内激光束或磨削射流的切口，作为修整操作的一部分。

Key **37.0668**
A device that assures that the coupling of two components can occur in only one position.

锁键 **37.0668**
确保两个元器件接合仅处于唯一位置的装置。

Keying (n.) **37.1430**
A device that is used in addition to, or in lieu of, a polarization feature to assure that the coupling of identical mating components can occur in only one position.

锁定键（名词） **37.1430**
用于补充或代替极性要素的装置，确保相同配接组件的接合处于唯一位置。

Keying **37.1431**
The use of a device in addition to, or in lieu of, a polarizing feature to assure that the coupling of identical mating components can occur in only one direction.

键锁定（动词） **37.1431**
使用补充或代替极性要素的装置，确保相同配接元器件的接合仅处于唯一位置。

Keying Slot **22.1432**
A slot in a printed board that permits the printed board assembly to be plugged into its mating connector and prevents the board from being plugged into any other connector. (See also “Polarizing Slot.”)

键槽 **22.1432**
只能使印制板组件插入与之配接的连接器中，并防止板插入到其它连接器中的印制板内的槽。（又见“极性槽，Polarizing Slot”。）

Keyway **37.0669**
A general term that encompasses both keying slots and polarizing slots.

键销槽 **37.0669**
包括键槽和极性槽的通用术语。

Knot (Base Materials) **44.1887**
A clump of reinforcement material formed either by the yarn within the web of the fabric or which was deposited onto the web during the treating process.

节瘤（基材） **44.1887**
由纤维布网中纱线或者在处理过程中沉积在布网上的纱线形成的增强材料块。

Known Good Board (KGB) **92.0671**
A correctly fabricated printed board that serves as a standard unit by which others can be compared.

已知好板（KGB） **92.0671**
制作正确的印制板，可作为其它板与之对比的标准板。

Known Good Assembly (KGA) **92.0670**
A correctly operating printed board assembly that serves as a standard unit by which others can be compared.

已知好组件（KGA） **92.0670**
运行正常的印制板组件，可作为其它组件与之对比的标准组件。

Known Good Die (KGD) **35.0846**
A die-form semiconductor product that provides assurance of equivalent quality and reliability as its conventionally packaged counterparts.

已知良好芯片（KGD） **35.0846**
芯片形式的半导体产品，同其按惯例封装的对应物一样可提供同样的品质和可靠性保证。

Known Tested Die (KTD) **92.2150**
A die-form semiconductor product functionally verified by probing tests equal to the expected performance of the packaged product, without full quality assurance by supplier(s). The requirements for testing are AABUS.

已测试合格芯片（KTD） **92.2150**
通过探针测试验证其功能与封装产品的预期性能相同的芯片形式的半导体产品，但无供应商的完全质量保证。测试要求由供需双方协商确定。

Kovar **45.1888**
An alloy of 53% iron, 17% cobalt, 29% nickel and trace elements, with a thermal expansion approximately matching that of alumina ceramics and sealing glasses.

科瓦铁镍钴合金 **45.1888**
由53%的铁，17%的钴，29%的镍和其他微量元素组成的合金，其热膨胀与氧化铝陶瓷及密封玻璃相匹配。

L

L Cut **77.1433**
A trim notch in a film component that is created by a cut that starts perpendicular to the component’s major axis and then turns ninety degrees to complete the trimming operation.

L形切割 **77.1433**
膜元器件内的修整槽，从垂直于元器件主轴开始切割，然后转90º而完成修整操作。

Laminate (n.) **55.0672**
A product made by bonding together two or more layers of material.

层压板（名词） **55.0672**
将两层以上材料粘合在一起制成的产品。

Laminate Thickness **41.0673**

The thickness of single- or double-sided metal-clad base material prior to any subsequent processing. (See also "Board Thickness.")

层压板厚度 **41.0673**

在任何后续加工前，单面或双面覆金属箔基材的厚度。（又见"板厚度，Board Thickness"。）

Laminate Void **91.0674**

The absence of resin or adhesive in an area that normally contains them.

层压板空洞 **91.0674**

在应正常含有树脂或粘合剂的区域未见树脂或粘合剂。

Lamination (Dry Film) **52.1889**

The process of adhering a dry film photo resist or solder mask to a substrate utilizing heat and pressure.

贴膜（干膜） **52.1889**

利用热量和压力，将光致干膜或阻焊膜附着在基板上的过程。

Lamination (Multilayer) **55.1890**

The process of bonding one or more innerlayers together with an adhesive layer or layers (such as pre-preg) utilizing a combination of heat and pressure.

层压（多层） **55.1890**

利用热量和压力，用粘合层（如半固化片）将一个或多个内粘接在一起的过程。

Land **22.1622**

A portion of a conductive pattern usually used for the connection and/or attachment of components.

连接盘 **22.1622**

通常用于连接和/或固定元器件的导电图形部分。

Land (Drill) **51.0676**

The peripheral portion of the drill body that is between adjacent drill flutes.

刃带（钻头） **51.0676**

钻头的相邻排屑槽之间的周边部分。

Land Grid Array (LGA) **33.1891**

A generic rectangular component package with termination lands located in a grid pattern on the bottom of the package.

盘栅阵列（LGA） **33.1891**

位于封装体底部的盘状端子排成栅格阵列的矩形元器件封装。

Land Pattern **22.0678**

A combination of lands that is used for the mounting, interconnection and testing of a particular component.

连接盘图形 **22.0678**

用于特定元器件安装、互连和测试的连接盘组合。

Land Tearing **96.1892**

The tearing of a land from a base material during a test of land adhesion robustness.

连接盘撕裂 **96.1892**

测试连接盘粘接强度过程中，连接盘与基材撕裂。

Land Width Angle (Drill) **51.1223**

The angle between the leading edge and the heel of a drill land as measured at the drill axis.

刃带宽度角（钻头） **51.1223**

在钻头轴处测量所得的钻头刃带的前缘到后棱之间的夹角。

Land Width (Drill) **51.0679**

The perpendicular distance from the leading edge to the heel of a drill land.

刃带宽度（钻头） **51.0679**

从钻头刃带的前缘到后棱的垂直距离。

Landless Hole **22.0677**

A plated-through hole without land(s).

无连接盘孔 **22.0677**

没有连接盘的镀覆孔。

Landless Via **22.1893**

A via in which the land diameter is designed to be less than or equal to the via diameter.

无连接盘导通孔 **22.1893**

连接盘直径设计为小于或等于导通孔直径的导通孔。

Lap Shear Strength **74.0680**

The shearing pressure at which an adhesive-bonded (and cured) lap joint fails. (See also "Shear Strength" and "Torsional Strength.")

搭接剪切强度 **74.0680**

使粘合剂粘合（并已固化）的搭接点失效的切剪压力。（又见“剪切强度，Shear Strength”和“抗扭强度，Torsional Strength”。）

Large-Scale Integration (LSI) **30.0681**

An integrated circuit with over 100 gates.

大规模集成电路（LSI） **30.0681**

多于100个门的集成电路。

Larger-the-Better Characteristic **91.1434**

A parameter of quality that improves performance as its value increases. (See also “Nominal-Is-Best Characteristic” and “Smaller-the-Better Characteristic.”)

越大越好特性 **91.1434**

其数值增加时性能改进的质量参数。（又见“标称最佳特性，Nominal-Is-Best Characteristic”和“越小越好特性，Smaller-the-Better Characteristic”。）

Laser Bonding **53.1894**

A process effecting a metal-to-metal bond of two conductors by welding them together with a laser beam as a heat source.

激光键合 **53.1894**

用激光束作为加热源将两个导体焊接在一起形成金属与金属键合的过程。

Laser Direct Imaging (LDI) **52.1895**

The selective exposure of patterns onto a photosensitive material (such as dry film or liquid) without using a working phototool (artwork master).

激光直接成像（LDI） **52.1895**

不采用底片（照相底版）在光敏材料（如干膜或湿膜）上进行选择性图形曝光的方法。

Laser Scanner (Bar Code) **70.1896**

A bar code scanner that uses laser technology to read bar codes; has the ability to read from distances and on curved surfaces.

激光扫描器（条码） **70.1896**

采用激光技术阅读条码的条码扫描器，其具备从远距离及从曲面上读取条码的能力。

Laser Soldering **75.1897**

Method to reflow solder by optically concentrating and applying a laser beam to the part to be soldered or its individual leads.

激光焊接 **75.1897**

通过光聚中并将激光束施加于待焊部件或其单根引线上，实现再流焊接的方法。

Laser Trimming **77.0682**

The modification of a film component’s value by the removal of film by applying heat from a focused laser source.

激光修整 **77.0682**

通过采用聚焦激光源的热量去除膜来改变膜元器件的值。

Laser Via **22.1898**

See “Microvia (Build-Up Via).”

激光导通孔 **22.1898**

见“微导通孔（叠层导通孔），Microvia (Build-Up Via)”。

Latch (Connector) **37.0683**

A device at both ends of a connector header that is used to hold in place and eject a mating receptacle connector.

弹簧锁（连接器） **37.0683**

连接器的顶盖两端的装置，用于固定位置和弹出配接的连接器插座。

Layback **51.0684**

The negative rake angle or rolled condition in the face of a drill flute. (See Figure L-1.) (See also “Hook” and “Overlap, Drill.”)

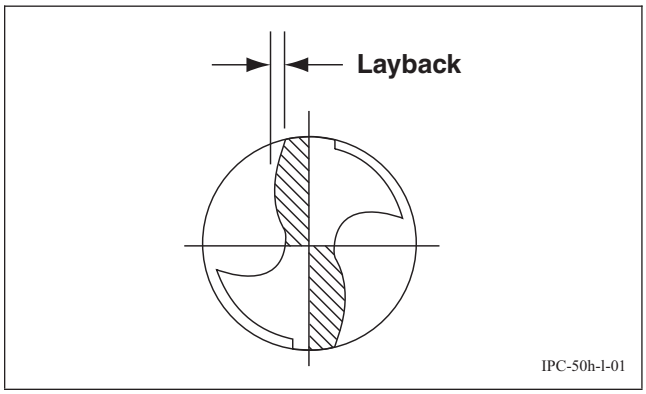
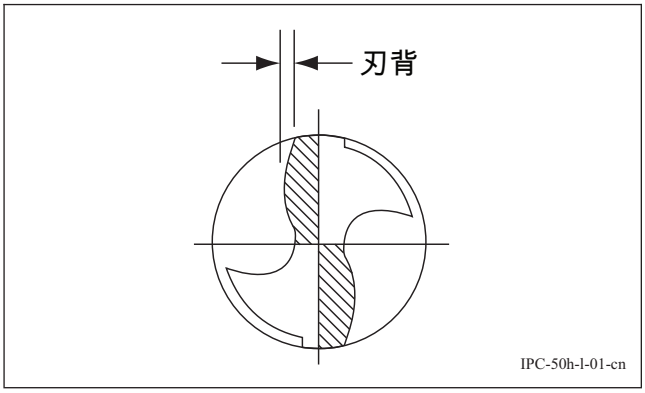


Figure L-1 Layback

刃背 **51.0684**

钻头排屑槽面的负倾斜角或卷曲状态。（见图L-1。）（又见“刃钩，Hook”和“钻头重叠，Overlap, Drill”。）



图L-1 刃背

Lay-up **55.1900**

The process of combining one or more innerlayers, and prepreg or adhesive layer(s) into a lamination package. The package may consist of innerlayers, outerlayers and copper foil.

叠层 **55.1900**

将一张或多张印制板内层、半固化片或粘结层结合到一个层压包内的过程。层压包可由内层、外层和铜箔组成。

Layer **22.1624**

Stratum of a printed board. Layers are differentiated according to their function (conductor layer, insulating layer) and their location.

层 **22.1624**

印制板层，可根据其功能（导体层、绝缘层）及其位置进行区分。

Layer-to Layer-Registration **55.1899**

The process of aligning circuit features (lands) on individual layers of a printed board through the use of tooling image location features (fiducials) or tooling holes.

层间对位 **55.1899**

通过使用定位图像的位置特征（基准点）或定位孔，使印制板对准每个独立层的电路要素（连接盘）的过程。

Layer-to-Layer Spacing **22.0686**

The thickness of dielectric material between adjacent layers of conductive patterns in a printed board. (See Figure L-2.)

层间间距 **22.0686**

印制板中相邻导电图形之间电介质材料的厚度。（见图L-2。）

Leaching, Metallization **75.0687**

The loss or removal of a basis metal or coating during a soldering operation.

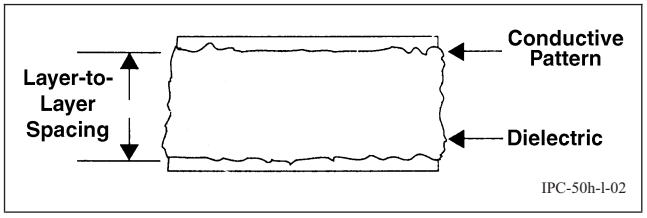
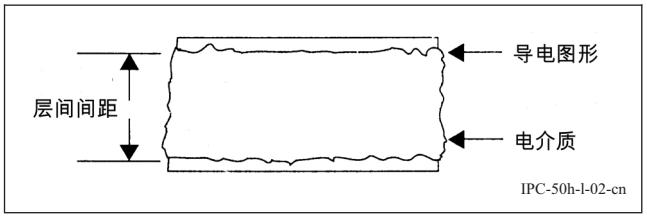


Figure L-2 Layer-to-Layer Spacing



图L-2 层间间距

金属层浸析 **75.0687**

焊接过程同金属基材或涂覆层的流失或转移。

Lead **36.0688**

A length of insulated or uninsulated metallic conductor that is used for electrical interconnections.

引线 **36.0688**

用于电气互连的一段绝缘或非绝缘金属导体。

Lead Extension **75.0691**

That part of a lead or wire that extends beyond a solder connection.

引线延伸 **75.0691**

延伸在焊点之上的导线或金属线部分。

Lead Fingers **36.1901**

The interior ends of the lead frame leads to which the bond wires are connected to complete the circuit from the integrated circuit die bond lands.

引线手指 **36.1901**

与键合金属线连接的引线框架引线内端，通过金属线再与集成电路芯片键合连接盘连接形成电路。

Lead Frame **36.1902**

The metallic portion of the device package on which the integrated circuit die is mounted and connected from the die or dice bonding sites to the structure that becomes the outer leads of the package.

引线框架 **36.1902**

集成电路芯片安装在其上的器件封装金属部分，它将芯片或裸芯片键合点与该结构连接起来，而成为封装的外引线。

Lead Free Plating **45.1903**

A metallic plating with an alloy containing no more than 0.1% of lead.

无铅镀层 **45.1903**

合金内铅含量不多于0.1%的金属镀层。

Lead Free Solder **75.1904**

An alloy that does not contain more than 0.1% lead (Pb) by weight as its constituent and is used for joining components to substrates or for coating surfaces.

无铅焊料 **75.1904**

其组成成份中铅的重量百分比不大于0.1%的合金，用于将元器件连接到基板或涂覆层表面。

Lead Mounting Hole **22.0695**

See “Component Hole.”

引线安装孔 **22.0695**

见“元器件孔，Component Hole”。

Lead Pin **36.0696**

See “Component Pin.”

引线插针 **36.0696**

见“元器件插针，Component Pin”。

Lead Projection **73.0697**

The distance that a component lead protrudes through the side of a printed board that is opposite from the one upon which the component is mounted.

引线伸出长度 **73.0697**

元器件引线从与元器件安装面相对的印制板面伸出的距离。

Lead Wire **36.0698**

See “Component Lead.”

引线 **36.0698**

见“元器件引线，Component Lead”。

Leaded Chip Carrier **31.1224**

A chip carrier whose external connections consist of leads that are around and down the side of the package. (See also “Leadless Chip Carrier.”)

有引线芯片载体 **31.1224**

其外部连接由围绕封装体四周并延伸至底部的引线组成的芯片载体。（又见“无引线芯片载体，Leadless Chip Carrier”。）

Leaded Surface-Mount Component **33.1435**

A surface-mount component for which external connections consist of leads that are around and down the side of the package. (See Figure L-3.) (See also “Leadless Surface-Mount Component.”)

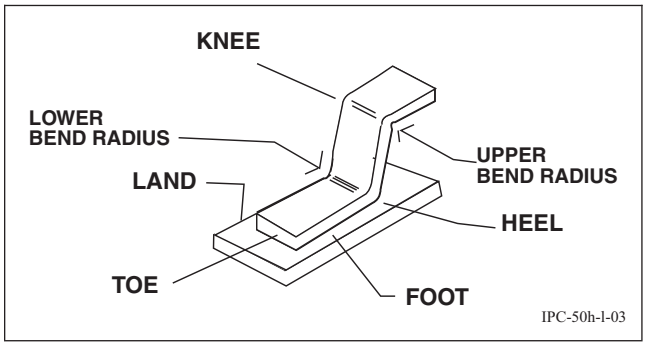
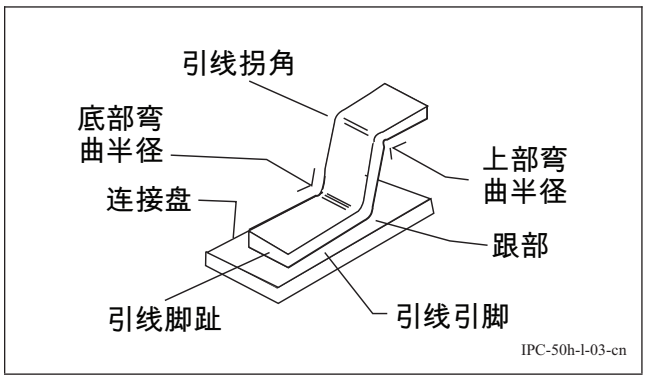


Figure L-3 Leaded-Surface Mount Component Gull-Wing Shaped Lead

有引线表面贴装元器件 **33.1435**

其外部连接由围绕封装体四周并延伸至底部的引线构成的表面贴装元器件。（见图L-3。）（又见“无引线表面贴装元器件，Leadless Surface Mount Components”。）



图L-3 翼形有引线表面安装元件

Leadless Chip Carrier **33.1436**

A chip carrier whose external connections consist of metallized terminations that are an integral part of the component body. (See also “Leaded Chip Carrier.”)

无引线芯片载体 **33.1436**

由同属元器件本体的金属化端接点构成外部连接的芯片载体。（又见“有引线芯片载体，Leaded Chip Carrier”。）

Leadless Component **30.1754**

See “Leadless Surface Mount Components.”

无引线元器件 **30.1754**

见“无引线表面贴装元器件，Leadless Surface Mount Components”。

Leadless Device **33.0694**
See “Die” and “Leadless Surface Mount Component.”

无引线器件 **33.0694**
见“芯片，Die”和“无引线表面贴装元器件，Leadless Surface Mount Component”。

Leadless Inverted Device **33.1437**
A single or multiple device package, where integrated circuits and/or passive devices are mounted in a cavity on the bottom of a leadless ceramic or organic carrier, which is inverted for surface mount attachment to a printed board assembly.

无引线倒置器件 **33.1437**
单个或多个器件的封装，集成电路和/或被动（无源）器件放置在无引线陶瓷或有机载体底部腔体内，将其倒置，形成与印制板组件的表面贴装连接。

Leadless Surface-Mount Component **33.1438**
A surface-mount component whose external connections consist of metallized terminations that are an integral part of the component body. (See also “Leaded Surface-Mount Component.”)

无引线表面贴装元器件 **33.1438**
其外部连接由已成为元器件本体整体部分的金属端子组成的表面贴装元器件，（又见“有引线表面贴装元器件，Leaded Surface-Mount Component”。）

Leakage Current **21.0699**
The undesired flow of electrical current over or through an insulator.

泄漏电流 **21.0699**
非期望的流经绝缘体的电流。

Learn Time **92.0700**
The time it takes to do initial programming (teaching) to store feature coordinate locations and other data in an inspection/test machines memory.

学习时间 **92.0700**
为将要素坐标位置存储在检测/测试机的存储器中进行程序初始化所需要的时间。

Least Material Condition (LMC) **22.0701**
The condition in which a feature of size contains the least amount of material within the stated limits of size.

最小材料条件（LMC） **22.0701**
实际要素在规定的尺寸范围内含有最少量材料的状态。

Legend **22.1439**
A format of letters, numbers, symbols and patterns that are used primarily to identify component locations and orientations for convenience of assembly and maintenance operations.

图例 **22.1439**
印制板上主要用来识别元器件位置和方向的字母、数字、图形和符号格式，以便于组装和维护操作。

Leno End Out **44.0702**
Warp-end wrapper that is missing from the end of a fabric.

纱罗边毛边 **44.0702**
织物末端由经纱作收口的纱罗边松脱。

Leveling **56.0703**
See “Fusing and HASL/HAL”

整平 **56.0703**
见“熔融和HASL/HAL，Fusing and HASL/HAL”。

Leveling Flux **56.0704**
See “Fusing Flux.”

整平助焊剂 **56.0704**
见“热熔助焊剂，Fusing Flux”。

Leveling Oil **56.0705**
See “Fusing Oil.”

整平油 **56.0705**
见“热熔油，Fusing Oil”。

Library **20.0706**
A catalog of related items that contains all of the information about the items that is necessary for processing by a computer program.

库 **20.0706**
指计算机程序处理所需要的全部信息内容的目录汇编。

Lifted Land **60.0707**
A land that has fully or partially separated (lifted) from the base material, regardless of whether or not any resin is lifted with the land.

连接盘浮起 **60.0707**
连接盘与基材全部或部分分离（浮起），无论树脂是否随连接盘浮起。

Lift-off **97.1905**
See “Solder Fillet Lifting.”

升离 **97.1905**

见“焊料填充起翘，Solder Fillet Lifting”。

Light Mark (Fabric) **44.0708**

A filling defect that extends across the width of a fabric containing less than one pick per 25 mm from nominal.

薄段（织物） **44.0708**

织物整个幅宽方向的纬向瑕疵，每25毫米长度的纬线数比标称值缺少1根以上。

Limits of Size **20.0709**

The specified maximum and minimum sizes.

尺寸界限 **20.0709**

规定的最大和最小尺寸。

Line **20.0710**

See “Conductor Trace.”

线 **20.0710**

见“导体线条，Conductor Trace”。

Line Coupling **21.0711**

The interaction between two transmission lines that is caused by their mutual inductance and the capacitance between them.

传输线耦合 **21.0711**

两条传输线之间由于互感和互容所产生的交互作用。

Lip Height **51.0712**

The perpendicular distance from one primary cutting edge to another.

刃缘高度 **51.0712**

从主切削刃到另一切削刃之间的垂直距离。

Liquidus, Solder **75.1906**

The temperature at which a solder alloy is completely melted.

焊料液相线 **75.1906**

焊料合金完全熔化时的温度。

Liquefaction (Cured Solder Mask) **47.0927**

When cured (solid) solder mask becomes partially to fully liquefied.

液化（已固化阻焊膜） **47.0927**

已固化的（固态）阻焊膜部分或完全液化。

Load Capacitance **21.0713**

The capacitance seen by the output of a logic circuit or other signal source.

负载电容 **21.0713**

逻辑电路或其它信号源输出的电容量。

Load Time **92.0714**

The time it takes to load a unit in an inspection/test machine and to perform any necessary programming or machine alignment.

装载时间 **92.0714**

在检验或测试仪器上装载一个测试单元以及进行一切必要的编程或机械调整所耗费的时间。

Loading Direction **70.1907**

The direction of board passing through an assembly line viewed from the operator side.

装载方向 **70.1907**

从操作人员的视点看电路板流经装配线的方向。

Local Fiducial **20.0715**

A fiducial mark (or marks) used to locate the position of a land pattern for an individual component on a printed board.

局部基准点 **20.0715**

印制板上用来确定印制板上个别元器件连接盘图形位置的基准点（或标记）。

Local Intelligence **25.0716**

The capability of a work station to independently process data without the use of a host or central processing unit.

局部智能 **25.0716**

工作站在不使用主机或中央处理器的情况下独立处理数据的能力。

Local Reflow Soldering **75.1908**

The process of reflow soldering using the heat that is directly supplied to the local area to be reflowed by an energy beam (laser), soldering iron or hot air reflow tool.

局部再流焊接 **75.1908**

采用激光、电烙铁或热风再流焊装置对局部区域直接进行加热的再流焊接工艺。

Locating Accuracy (Component) **73.1909**

The accuracy in positioning of a component described by the amount of displacement from the desired position.

定位精度（元器件） **73.1909**

通过与理想位置的偏移量描述的元器件定位精度。

Locating Edge **20.0028**

A tooling feature in the form of the edge of a printed board.

定位边 **20.0028**

以印制板的边作为定位要素。

Locating Edge Marker **20.0717**

A symbol that is used to identify which edge of a printed board is the index edge.

定位边标识 **20.0717**

用来确定印制板的某一边为基准边的符号。

Locating Hole **20.0718**

See “Tooling Hole.”

定位孔 **20.0718**

见“定位孔，Tooling Hole”。

Locating Notch **20.0719**

A tooling feature in the form of a notch in a printed board.

定位切口 **20.0719**

以印制板的切口为定要素。

Locating Slot **20.0720**

A tooling feature in the form of a slot in a printed board.

定位槽 **20.0720**

以印制板上的槽为定要素。

Location Hole **20.1726**

A hole or notch in the panel or printed board to enable either to be positioned accurately.

定位孔 **20.1726**

用于精确定位在制板或印制板的孔或槽口。

Logic **21.0721**

The functional digital circuits used to perform computational functions.

逻辑电路 **21.0721**

用以完成计算功能的功能数字电路。

Logic Diagram **21.1440**

A drawing that depicts the multistate device implementation of logic functions with logic symbols and supplementary notations that show the details of signal flow and control, but not necessarily the point-to-point wiring.

逻辑图 **21.1440**

运用逻辑符号和辅助标识描述多种状态器件逻辑功能执行过程的图，可显示详细的信号流程和控制，但不必标出点到点之间的连线。

Logic Family **21.1441**

A collection of logic functions using the same form of electronic circuit, e.g., emitter-coupled logic (ECL), transistor-transistor logic (TTL), complementary metal-oxide semiconductor logic (CMOS).

逻辑系列 **21.1441**

指使用相同形式电路的逻辑功能的集合，如：发射极耦合逻辑电路（ECL），晶体管–晶体管逻辑电路（TTL）和互补金属氧化半导体逻辑电路（CMOS）。

Long-Term Capability **91.0722**

The capability of a process that exhibits statistical control over an extended period of time.

长期能力 **91.0722**

过程在较长时间期限内的统计控制能力。

Loom Beam **44.0723**

A large flanged cylinder onto which all warp yarns are wound and from which the yarns enter the loom.

织机经轴 **44.0723**

大的带凸缘的圆柱体，其上缠绕所有经纱，并由此进入织布机。

Loop Height **76.0725**

The magnitude of deviation of a wire from a straight path between its end attachment points.

线弧高度 **76.0725**

金属线的弯曲顶点距其两端接点连接直线间的距离。

Loop, Wire **76.0724**

The curve (arc) in a bonding wire between its end attachment points.

线环 **76.0724**

在两端连接点之间键合线中的曲线（弧线）。

Loss Tangent **21.0726**

See “Dissipation Factor.”

损耗正切 **21.0726**

见“损耗因子，Dissipation Factor”。

Lot Size **91.1442**
A collection of units produced in one continuous, uninterrupted fabrication run.

批量 **91.1442**
连续不间断制程中生产的产品的集合。

Low Residue Solder Paste **75.1910**
A solder paste wherein the ionic, nonionic, and carrier residues after soldering are controlled to low level.

低残留焊膏 **75.1910**
焊接后其离子、非离子以及载体残留物均控制在很低水平的焊膏。

Luminance **24.0727**
A measure of light flux reflected or emitted from a surface.

亮度 **24.0727**
从一个表面反射或发射出的光通量的度量。

Luminous Energy **24.0728**
A measure of light flux flow rate, usually in units of lumen-seconds.

光能 **24.0728**
光通量流速的度量，通常以流明秒为单位。

Luminous Flux **24.0729**
A measure of flow of visible light energy past any given point in space.

光通量 **24.0729**
可见光能通过空间内任一指定点的流通量的度量。

Lyophilic **76.1225**
A characterization of material that readily goes into colloidal suspension in a liquid.

亲液性 **76.1225**
材料在液体中易转化为胶状悬浮体的特征。

Lyophobic **76.0730**
A characterization of material that exists in a colloidal state with a tendency to repel liquids.

疏液性 **76.0730**
材料以胶体形式存在且排斥液体的特征。

M

Machine Language **11.0732**
The actual language, usually a binary code, that is used by a computer when it performs operations.

机器语言 **11.0732**
计算机执行操作时采用的实际语言，通常为二进制代码。

Machined Contact **37.0731**
A type of connector contact that consists of solid spring metal that has been formed by machining. (See also “Sheet-Metal Contact.”)

机械接触件 **37.0731**
由加工成型的硬弹性金属组成的连接器接触件。（又见“金属片接触件，Sheet-Metal Contact”。）

Magnification Power **92.0733**
The ratio of the tangent of one-half of the angle (beta) subtended by the image of an object (H), as seen through and centered in the field of view of the magnification device, to the tangent of one-half of the angle (alpha) subtended by the object (H) as seen at 10 inches by the unaided eye. (See Figure M-1.)

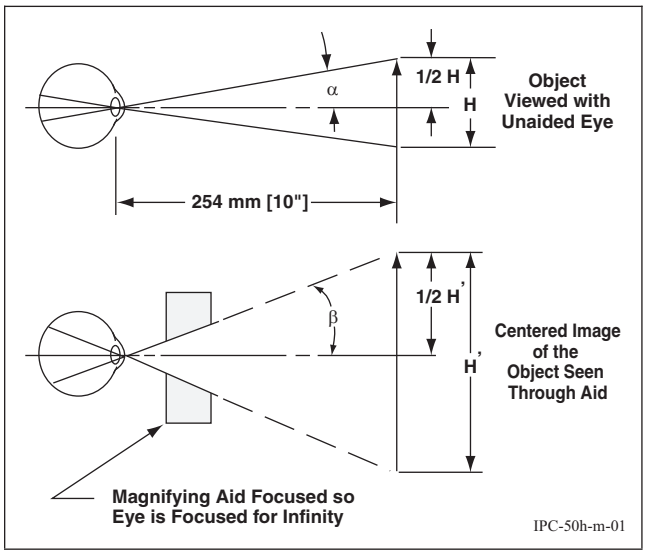


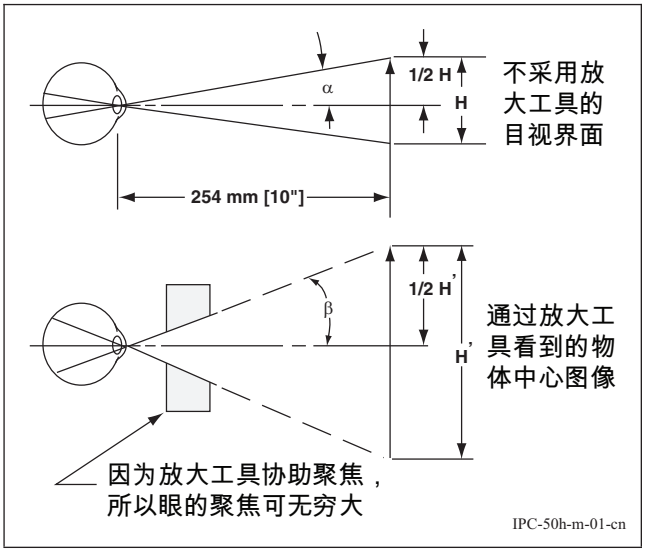
Figure M-1 Magnification Power Parameters

放大率 **92.0733**
通过放大设备的中间位置正对物体影像所看上去的半角（β）的正切与用肉眼从距离物体10英寸的地方正看上去的半角（α）的正切之比值。（见图M-1。）

Major Defect **94.0734**
A defect that is likely to result in a failure of a unit or product or that materially reduces its usability for its intended purpose.

主要缺陷 **94.0734**
有可能导致某一装置或产品失效或者其适用性显著降低的缺陷。

Manhattan Distance **25.0735**
The orthogonal distance between two points.



图M-1 放大率参数

曼哈顿距离 **25.0735**

指两点间的垂直距离。

Manual Data Input **25.0736**

Computer data that is manually generated with or without the aid of a data-entry device, such as a keyboard, lightpen, mouse, etc.

人工数据输入 **25.0736**

通过人工生成的计算机数据，无论是否借助数据输入装置，如键盘、光笔以及鼠标等。

Manual Soldering **75.0737**

See “Hand Soldering.”

人工焊接 **75.0737**

见“手工焊接，Hand Soldering”。

Manufacturing Drawing **26.1634**

A working document that shows the dimensional limits or grid locations that are applicable to any and all parts of a product to be fabricated, including the arrangement of conductors and nonconductive patterns or elements; the size, type, and location of holes; and all other necessary information.

加工图 **26.1634**

指描述待加工产品任何一个零件或全部零件的尺寸大小或网格位置的生产文件，包括导线、非导电图形或元器件的排列和孔的大小、形状与位置等所有其它必要信息的文件。

Manufacturing Hole **20.0738**

See “Tooling Hole.”

加工孔 **20.0738**

见“定位孔，Tooling Hole”。

Margin (Flat Cable) **37.0739**

The distance between the reference edge of a flat cable and the nearest edge of the first conductor. (See also “Edge Spacing.”)

边距（扁平电缆） **37.0739**

扁平线缆的基准边与其第一个导体最近边之间的距离。（又见“边缘间距，Edge Spacing”。）

Margin Width (Drill) **51.0740**

The thickness of the cylindrical portion of a drill land that is perpendicular to the leading edge.

棱边宽度（钻头） **51.0740**

指钻头圆柱部分的刀刃口到钻头实体部分的垂直距离。

Mark (Fabric) **44.0741**

A heavy or light area in a fabric that is due to excessive or insufficient filling yarns.

织痕（织物） **44.0741**

由于引纬过密或过稀而导致织物出现局部过厚或过薄的现象。

Marking **47.2185**

Recording of traceability and legend information on hardware.

标记 **47.2185**

在硬件上记录可追溯信息及符号信息。

Mask **47.0742**

A coating material, in a specific pattern, that is used to mask or protect selected areas of conductive circuitry during manufacturing or testing from the action of an etchant, plating, solder, etc.

掩膜 **47.0742**

用来掩蔽或保护选定导电电路区域的特定图形上的涂覆层材料，以使该区域在制造或测试期间免受蚀刻剂、电镀、焊接等的影响。

Mass Lamination **55.1443**

The simultaneous lamination of a number of pre-etched, multiple-image, C-staged resin panels or sheets that are sandwiched between layers of B-staged resin and copper foil. (See also “Cap Lamination” and “Foil Lamination.”)

叠合层压 **55.1443**

将多张预先蚀刻好的具有线路图形的C阶树脂内层板，夹在B阶树脂半固化片与铜箔之间同时进行层压。（又见“覆盖层压，Cap Lamination”和“覆箔层压，Foil Lamination”。）

Mass Soldering **75.1678**

Methods of soldering in which many joints are made in the same operation.

群焊 **75.1678**

在同一次作业中同时完成很多焊接点的焊接方法

Master Dot Pattern **26.0743**

See “Hole Pattern.”

点总图 **26.0743**

见“孔图，Hole Pattern”。

Master Drawing **26.0744**

A control document that shows the dimensional limits or grid locations that are applicable to any and all parts of a product to be fabricated, including the arrangement of conductors and nonconductive patterns or elements; the size, type, and location of holes; and all other necessary information.

设计总图 **26.0744**

用以描述待制产品所需的部分或全部的尺寸范围或网格位置的控制文件，包括导体和非导电图形或组件的排布，孔的尺寸、类型和位置以及其它必需的信息。

Master Line **22.0745**

See “Design Width of Conductor.”

主传输线 **22.0745**

见“导体设计宽度，Design Width of Conductor”。

Master Pattern **24.0746**

See “Production Master.”

底版图形 **24.0746**

见“生产底片，Production Master”。

Maximum Material Condition (MMC) **22.0747**

The condition in which a feature of size contains the most amount of material within the stated limits of size.

最大材料条件（MMC） **22.0747**

尺寸要素在规定的尺寸范围内包含最多材料量的状况。

Mealing **76.1814**

A condition in the form of discrete spots or patches that reveals a separation at the interface between a conformal coating and a base material on the surface of a printed board, on the surface of an attached component, or both.

起斑 **76.1814**

显示覆形涂层与印制板表面基材或元器件表面基材间存在分离的离散斑点或斑纹状况。

Measling **55.0748**

A condition that occurs in laminated base material in which internal glass fibers are separated from the resin at the weave intersection. (This condition manifests itself in the form of discrete white spots or “crosses” that are below the surface of the base material. It is usually related to thermally-induced stress.) (See also “Crazing, Base Material.”)

白斑 **55.0748**

层压基材内玻璃纤维与树脂在织物交叉处发生分离的状况。（通常表现为基材表面下不连续的白色方块或“十字”纹，一般与热应力有关。）（参见“微裂纹，基材，Crazing, Base Material”。）

Mechanical Stress **95.1755**

To subject a mechanical component to a process of physical stress.

机械应力 **95.1755**

使机械构件承受物理应力的过程。

Mechanical Wrap **75.0749**

The physical securing of a wire lead or component lead around a solder terminal.

机械绕接 **75.0749**

将导线或元器件引线缠绕到焊接端子上的机械固定。

Meniscus **92.0750**

The contour of a shape that is the result of the surface-tension forces that take place during wetting. (See Figure M-2.)

弯液面 **92.0750**

润湿过程中，由于表面张力的作用而引起的外形轮廓。（见图M-2。）

Message (Bar Code) **70.1915**

A string of characters encoded into a bar code symbol of a specific length.

信息（条码） **70.1915**

编译成一定长度条码符号的一串字符。

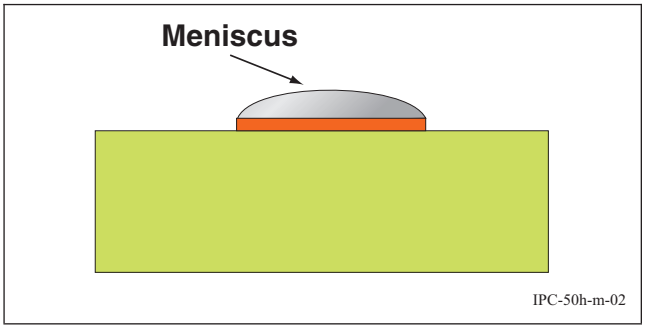
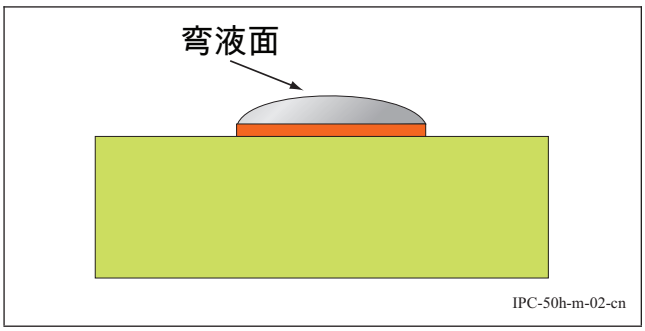


Figure M-2 Meniscus



图M-2 弯液面

Metal-Clad Base Material **41.1609**

Base material covered with conductive foil on one or both sides.

覆金属箔基材 **41.1609**

单面或双面覆有导电箔的基材。

Metal-Clad Laminate **41.0752**

See “Metal-Clad Base Material.”

覆金属箔层压板 **41.0752**

见“覆金属箔基材，Metal-Clad Base Material”。

Metal Core Printed Board **61.1587**

A printed board having a metal core as the support for the printed board structure, usually used as a heat sink or power supply grounding layer.

金属芯印制板 **61.1587**

以金属芯为结构支撑的印制电路板，金属芯通常作为散热层或电源接地层。

Metal Migration **96.1445**

The electrolytic transfer of metal ions along an electrically conductive path from one metal surface to another when an electrical potential is applied to the two metal surfaces.

金属迁移 **96.1445**

当电压作用于两个金属表面时，金属离子沿着导电通路从一金属表面到另一金属表面的电解转移。

Metal Migrativity **96.0754**

The comparative rate of the velocity of metal migration under the same conditions.

金属迁移率 **96.0754**

相同条件下金属迁移速度的相对比率。

Metal Surface Migration **96.1226**

The migration of metal on the surface of an electrical insulator.

金属表面迁移 **96.1226**

金属在绝缘体表面上的迁移。

Metal Through Migration **96.0662**

The migration of metal through an electrical insulator.

金属贯穿迁移 **96.0662**

金属贯穿通过绝缘体的迁移。

Metalized Land Areas **22.1756**

A pattern of conductive material used on a substrate to interconnect electronic components. Widened conductor areas used as attachment point for wire bonding or other devices.

金属化连接盘区域 **22.1756**

实现基板上电子元器件互连的导电材料图形，加宽的导体区域用作导线键合或其它器件的连接点。

Metalization (n.) **53.0753**

A deposited or plated thin metallic film that is used for its protective and/or electrical properties.

金属化（名词） **53.0753**

通过沉积或电镀方法形成的薄金属膜，用于保护和/或提供电气性能。

Microbond **74.0756**

A termination made with a small diameter wire, i.e., 0.025 mm [0.001 in] or less.

微键合 **74.0756**

用直径不大于0.025mm[0.001in]的金属线制成的端接点。

Microcircuit **30.0757**

A relatively high density combination of equivalent circuit elements that are interconnected so as to perform as an indivisible electronic circuit component.

微电路 **30.0757**

为作为一个不可分割的电子电路元器件运行而互连在一起的高密度等效电路元器件组合。

Microcircuit Module **86.1446**

A combination of microcircuits and discrete components that are interconnected so as to perform as an indivisible circuit assembly.

微电路模块 **86.1446**

为作为一个不可分割的电路组件运行而互连在一起的微电路和分立元器件组合。

Microelectronics **30.0759**

The area of electronic technology with, or applied to, the realization of electronic systems from extremely-small electronic elements, devices or parts.

微电子学 **30.0759**

应用于由极小的电子元器件、器件或部件构成的电子系统的电子技术领域。

Micron **26.1916**

A linear dimension equal to $1x10^{-6}$ meters or $39.4x10^{-6}$ inches

微米 **26.1916**

等于$1x10^{-6}$ m 或 $39.4x10^{-6}$ in 。

Microprobe **92.0760**

A small sharp-pointed object with a positional handle that is used to make temporary electrical contact to a land on a semiconductor for testing purposes.

微探针 **92.0760**

带有定位柄的小尖状物，可用于与半导体上连接盘的短暂电气接触进行测试。

Microsectioning **92.1447**

The preparation of a specimen of a material, or materials, that is to be used in a metallographic examination. (This usually consists of cutting out a cross-section, followed by encapsulation, polishing, etching, staining, etc.)

显微剖切 **92.1447**

用于金相分析的材料样品制备。（通常包括截面切割、灌封、抛光、蚀刻、染色等）

Microstrip **21.0761**

A transmission line (see “Transmission Line”) structure that consists of a signal conductor that runs parallel to and is separated from a much wider reference plane. (See Figure M-3.)

微带线 **21.0761**

由与一个很宽的参考面平行且相分离的信号导体组成的一种传输线结构。（参见“传输线，Transmission”。）（见图M-3。）

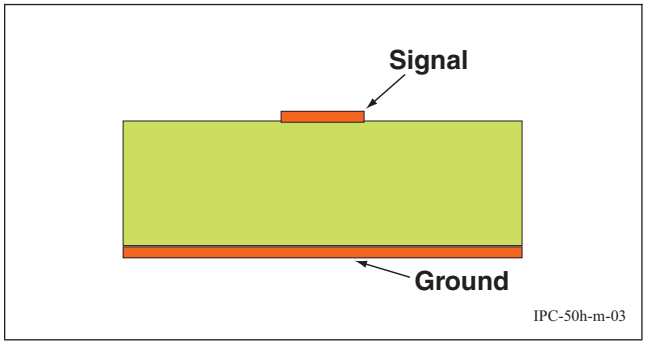
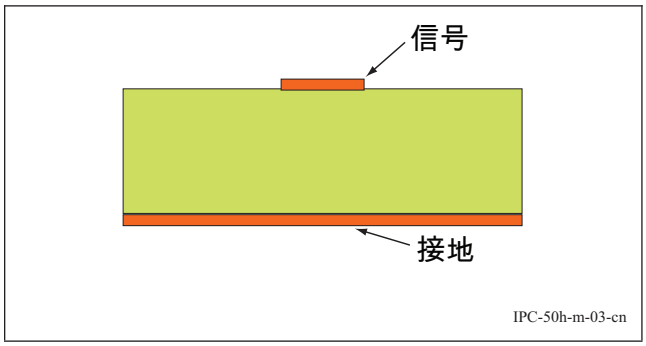


Figure M-3 Microstrip



图M-3 微带线

Microvia (Build-Up Via) **22.1595**

A blind or subsequently buried hole that is ≤0.15 mm [≤0.006 in] in diameter and formed either through laser or mechanical drilling, wet/dry etching, photo imaging, or conductive ink-formation followed by a plating operation.

微导通孔（积层导通孔） **22.1595**

直径小于0.15mm[0.006in]的盲孔或埋孔，可以通过机械钻孔、激光打孔、曝光成像或干湿膜蚀刻方式形成微孔，也可以用导电油墨形成继之以电镀加工形成。

Microwave Integrated Circuit **21.0762**

An integrated circuit that performs at microwave frequencies.

微波集成电路 **21.0762**

在微波频率下运行的集成电路。

Microwave Laminate **40.1917**

A laminate of metal cladding on dielectric substrate of composition selected to be suitable for circuit boards intended for operation at microwave frequencies.

微波层压板 **40.1917**

为了适用于可在微波频率下运行的电路板而选择的复合电介质基板上的覆金属箔层压板。

Microwaves **21.1918**

A term generally applied to radio waves in the frequency range of 1 GHz to 100 GHz. It generally refers to the frequency range where circuits and device interconnects are described as distributed elements instead of lumped elements.

微波 **21.1918**

适用于频率范围在1 GHz到100 GHz的无线电波术语。通常指电路和器件互连采用分布元器件而非集总元器件的频率范围。

Migration (Pressure Sensitive Tape) **75.1919**

The movement between tape components or between the tape and the surface to which it is applied, over a long period of time.

迁移（压敏胶带） **75.1919**

胶带组分之间或者胶带与其作用的表面之间经过一段长时间后发生的转移。

Migration Rate **96.0763**

The distance over which metal migration proceeds in a given unit of time.

迁移速率 **96.0763**

在给定的单位时间内金属迁移的距离。

Migration Resistance **96.1920**

That property of a printed board that resists insulation degradation by electromigration of metal atoms of a conductor under the influence of a difference in electrical potential.

耐迁移 **96.1920**

印制线路板阻挡在电势差的作用下导体的金属原子发生电迁移而引起绝缘性能下降的能力。

Migration Velocity **96.0764**

See “Migration Rate.”

迁移速度 **96.0764**

见“迁移速率，Migration Rate”。

Minimum Annular Ring **22.0766**

See “Minimum Annular Width.”

最小孔环 **22.0766**

见“最小环宽，Minimum Annular Width”。

Minimum Annular Width **22.0765**

The minimum width of metal(s) at the narrowest point between the edge of a hole and the outer edge of a circumscribing land. (This determination is made to the drilled hole on internal layers of multilayer printed boards and to the edge of the plating on external layers of multilayer and double-sided printed board.)

最小环宽 **22.0765**

孔边缘与外接连接盘外缘之间最窄处的金属宽度。（多层板内层从钻孔孔壁起，多层板外层和双面板从镀层边沿起度量。）

Minimum Bump Pitch **36.1921**

Minimum pitch between the center of any two perfectly aligned bumps.

最小凸点间距 **36.1921**

排列整齐的任何两个完整的金属凸点之间的最小间距。

Minimum Electrical Spacing **21.1451**

The minimum allowable distance between adjacent conductors, or between conductors and noncommon conductors such as mounting hardware, ground, etc., at a given voltage and altitude, that is sufficient to prevent dielectric breakdown, corona, or both, from occurring between the conductors.

最小电气间隙 **21.1451**

在给定的电压和海拔高度下，足以防止导线之间产生介质击穿或电晕放电, 或二者同时兼有时，相邻导体、导体与安装硬件、导体与接地线之间所允许的最小距离。

Minor Defect **91.0767**

A defect that is not likely to result in a failure of a unit or product or that does not materially reduce its usability for its intended purpose.

次要缺陷 **91.0767**

不会导致单元或产品失效、或不会对其预期使用性能造成严重影响的缺陷。

Mirrored Pattern **24.0768**

A pattern whose orientation denotes a transposition from right reading. (See Figure M-4.)

镜像图形 **24.0768**

表示其方位是从正向图形翻转过来的一种图形。（见图M-4。）

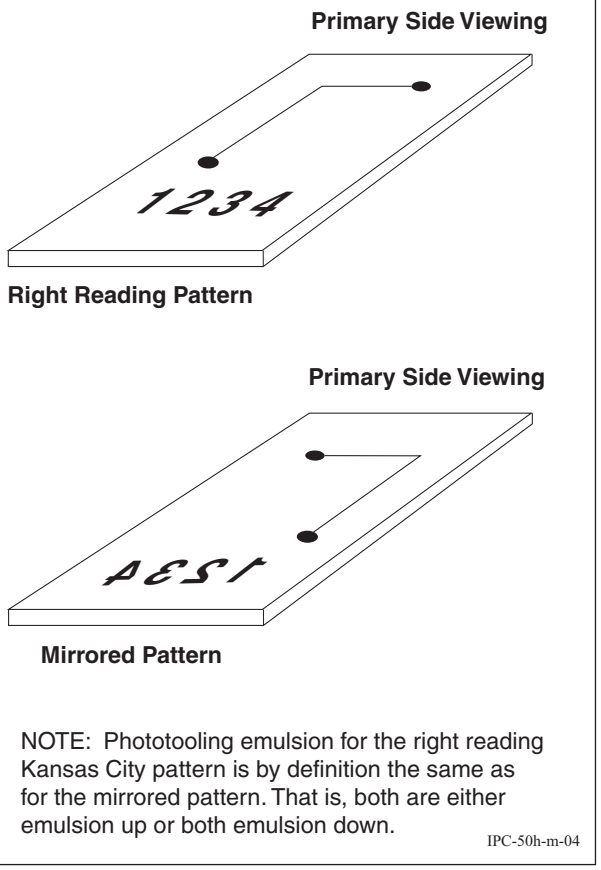


Figure M-4 Mirrored and Right-Reading Patterns

Mis-Pick **44.0769**

A break in the pattern of cloth from selvage to selvage that is caused by a missing filling yarn.

缺纬 **44.0769**

由于引纬时缺少纬纱而造成织物的整个幅宽出现纬纱缺损的状况。

Mislocated Bond **74.0770**

See “Off Bond.”

错位键合 **74.0770**

见“偏离键合，Off Bond”。

Misregistration **50.0771**

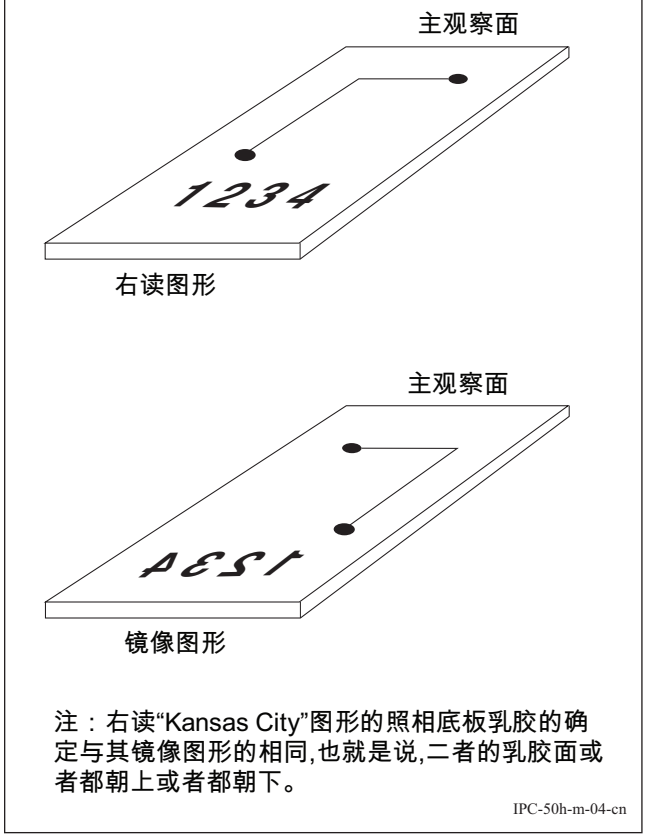
Imperfect registration.

重合不良 **50.0771**

不良的对位。

Mixed Component-Mounting Technology **70.1452**

A component mounting technology that uses both through-hole and surface-mounting technologies on the same packaging and interconnecting structure.



图M-4 镜像图形与右读图形

元器件混装技术 **70.1452**

在同一封装及互连构件上同时使用通孔插装与表面贴装两种工艺的元器件安装技术。

Mixed-Effects Model **91.0772**

An experimental treatment that contains elements of both deterministic effects and random-effects models.

混合效应模式 **91.0772**

既包含固定效应模式又包含随机效应模式的试验处理方法。

Mixed Technology **70.1757**

In surface mounting, refers to mixing through hole component and surface mounting components on the same side of a printed board.

混装技术 **70.1757**

在印制板的同一面既有通孔插装元器件又有表面贴装元器件的表面贴装技术。

Modal Form **25.0773**

The technique whereby a data description or other pertinent command is given only once at the beginning of a related set of data.

模态格式 **25.0773**

仅在相关的数据进行初始设置时提供一次数据描述或其它相关指令的技术。

Modification **77.0774**

The revision of the functional capability of a product in order to satisfy new acceptance criteria.

修改 **77.0774**

为了新的验收标准而对产品功能进行的修订。

Module **80.0775**

A separable unit in a packaging scheme.

模块 **80.0775**

封装体系中的可分离单元。

Module Board **67.1922**

A substrate on which bare die and surface-mount components are attached and interconnected and intended to be further assembled to a product planar board.

模块板 **67.1922**

安装互连有裸芯片和表面贴装元器件的基板，以便可以进一步组装到成品面板上。

Moisture Absorption **40.1923**

Under specified test conditions, the weight percentage of moisture absorbed by a material.

吸湿性 **40.1923**

在特定测试条件下，材料所吸收湿气的重量百分比。

Moisture Barrier Bag (MBB) **30.1924**

A bag that is electrostatic discharge (ESD) safe and is designed to restrict the ingress of water vapor used to package moisture-sensitive devices.

隔潮袋（MBB） **30.1924**

用于包装湿敏元器件的防静电且防水汽侵入的袋子。

Moisture Resistance **40.1925**

The measure of how well the insulation characteristics of a material are maintained when exposed to temperature and humidity.

防潮性 **40.1925**

材料暴露在高温、高湿环境下时，其保持绝缘特性的量度。

Molded Interconnection Device **67.1926**

A combination of molded plastic substrate and conductive patterns that provide both the mechanical and electrical functions of an electronic interconnection package.

模制互连器件 **67.1926**

由模制塑料基板和导电图形的组合，可为电子互连封装提供机械和电气功能。

Molecular Dye-Imaging Material **24.0776**

See “Diazo Material.”

分子染色成像材料 **24.0776**

见“重氮材料，Diazo Material”。

Monolithic Integrated Circuit **30.0777**

An integrated circuit in the form of a monolithic structure.

单片集成电路 **30.0777**

单片结构的集成电路。

Montreal Protocol **76.1758**

An agreement by industrialized nations, at a meeting held in Montreal, Canada, to eliminate chlorofluorocarbons from all processes by 1995.

蒙特利尔公约 **76.1758**

工业化国家在加拿大蒙特利尔召开的会议上签订的一项协议，该协议规定自1995年起从所有的生产中取消含氟氯烃化合物。

Mother Board **85.0778**

A printed board assembly that is used for interconnecting arrays of plug-in electronic modules. (See also “Backplane.”)

母板 **85.0778**

用以互连一组插入式电子模块的印制板组件。（又见“底板，Backplane”。）

Mounting Hole **20.0779**

A hole that is used for the mechanical support of a printed board or for the mechanical attachment of components to a printed board.

安装孔 **20.0779**

用于印制板的机械支撑或将元器件机械固定到印制板上的孔。

Mounting Tack Time **73.1927**

The interval of time required for mounting one component or all components on one printed board.

安装时间 **73.1927**

在一块印制板上安装一个元器件或全部元器件所需要的时间。

Muffle **75.0780**

An enclosure with a rectangular or oval cross-section that is located between the heating elements and the parts being processed that contains the atmosphere required for the reflow soldering process.

隔离罩 **75.0780**

位于加热元器件与被加热物体之间的截面为矩形或椭圆形的封闭空间, 其中包含有再流焊工艺所需要的热氛围。

Multi-Vari **91.0781**

A nonmathematical method for determining the sources of variation.

多变元 **91.0781**

确定变异源的非数学方法。

Multichip Integrated Circuit **86.0782**

See “Multichip Module.”

多芯片集成电路 **86.0782**

见“多芯片模块，Multichip Module”。

Multichip Microcircuit **86.0783**

See “Multichip Module.”

多芯片微电路 **86.0783**

见“多芯片模块，Multichip Module”。

Multichip Module (MCM) **86.0784**

A microchip module consisting primarily of closely-spaced integrated circuit dice that have a silicon area density of 30% or more.

多芯片模块（MCM） **86.0784**

由硅片密度不少于30%的密集集成电路芯片组成的微芯片模块。

Multichip Module-Ceramic (MCM-C) **86.1928**

Multichip module primarily using hybrid processing technology where materials of the mounting structure are ceramic or glass-ceramic alternatives.

陶瓷多芯片模块（MCM-C） **86.1928**

采用陶瓷或玻璃陶瓷材料，通过混合加工技术产生的多芯片模块。

Multichip Module Deposited (MCM-D) **86.1929**

Multichip module where unreinforced dielectric and conductive materials are added sequentially to form an interconnecting structure on a substrate.

沉积多芯片模块（MCM-D） **86.1929**

通过在基材上顺序增加非增强电介质和导电材料而形成互连结构的多芯片模块。

Multichip Module Laminate (MCM-L) **86.1930**

Multichip modules built primarily using printed board manufacturing processes and materials.

层压多芯片模块（MCM-L） **86.1930**

主要采用印制板制作工艺和材料制成的多芯片模块。

Multilayer Carrier Tape **36.0785**

Carrier tape with two or more conductor layers.

多层载带 **36.0785**

有两层或二层以上导体层的载带。

Multilayer Printed Board **60.1227**

The general term for a printed board that consists of rigid or flexible insulation materials and three or more alternate printed wiring and/or printed circuit layers that have been bonded together and electrically interconnected.

多层印制板 **60.1227**

采用刚性或柔性绝缘材料与三层以上已粘接在一起且已实现电气互连的印制线路或印制电路层交替组成的印制板。

Multilayer Printed Circuit Board **60.0786**

A multilayer printed board with three or more printed circuit layers.

多层印制电路板 **60.0786**

有三层以上印制电路层的多层印制板。

Multilayer Printed Circuit Board Assembly **80.0787**

An assembly that uses a multilayer printed circuit board for component mounting and interconnecting purposes.

多层印制电路板组件 **80.0787**

采用多层印制电路板实现元器件安装和互连的组件。

Multilayer Printed Wiring Board **60.0788**

A multilayer printed board with only printed wiring for its conductive layers.

多层印制线路板 **60.0788**
仅用印制线路作为导电层的多层印制板。

Multilayer Printed Wiring Board Assembly **80.0789**
An assembly that uses a multilayer printed wiring board for component mounting and interconnecting purposes.

多层印制线路板组件 **80.0789**
采用多层印制线路板实现元器件安装和互连的组件。

Multilevel Experiment **91.0790**
The evaluation of a small number of factors at a large number of levels.

多重实验 **91.0790**
在多个级别下对少量因子的评估。

Multiple Image Production Master **24.1643**
A production master having at least two 1:1 scale patterns.

多重图像生产底版 **24.1643**
至少含有两个比例为1:1图形的生产底版。

Multiple Indications **91.0791**
An anomaly that is detected and reported more than once.

多重迹象 **91.0791**
任何多于一次被检到或报告的异常情况。

Multiple Pattern **24.1645**
The arrangement of two or more 1:1 scale patterns contained within the size of one panel.

拼图 **24.1645**
一块在制板内排列有二个或更多比例为1:1的图形。

Multiple Printed Board **50.1646**
A printed panel in which one or more patterns occur two or more times, processed as a single unit and subsequently divided.

多印制板 **50.1646**
一种或多种图形出现两次或多次的印制在制板。加工时可将其作为独立件进行处理，完工后再将其分开（裁板）。

N

Nail Heading **51.0794**
The flared condition of copper on an inner conductive layer of a multilayer printed board that is caused by hole-drilling. (See Figure N-1.)

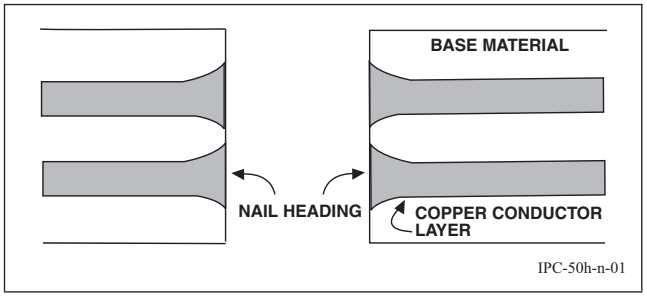
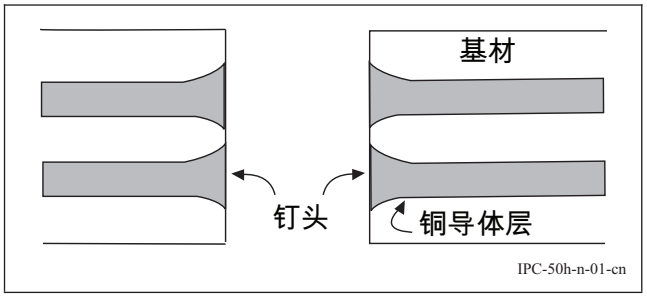


Figure N-1 Nail Heading

钉头 **51.0794**
多层印制板中由于钻孔造成内层导电层铜箔端部向外张开的状况。（见图N-1。）



图N-1 钉头

Nail **92.0792**
See “Probe, Test.”

钉 **92.0792**
见“测试探针，Probe, Test”。

Nailhead Bond **74.0793**
See “Ball Bond.”

钉头式键合 **74.0793**
见“球形键合，Ball Bond”。

Near-End Crosstalk **21.0795**
See “Backward Crosstalk.”

近端串扰 **21.0795**
见“反向串扰，Backward Crosstalk”。

Neckbreak **74.0796**
A break in a bond immediately above a ball bond.

断颈 **74.0796**
位于球形键合点正上方的键合断裂。

Negative **24.0797**
An artwork, artwork master, or production master in which the pattern being fabricated is transparent to light and the other areas are opaque.

负片 **24.0797**

所制作的图形为透明、其它区域为不透明的照相底图、照相原版或生产底板。

Negative Etchback **54.0798**

Etchback in which the inner conductor layer material is recessed relative to the surrounding base material. (See Figure N-2.)

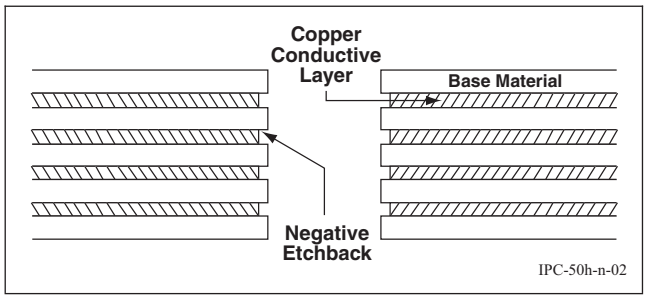
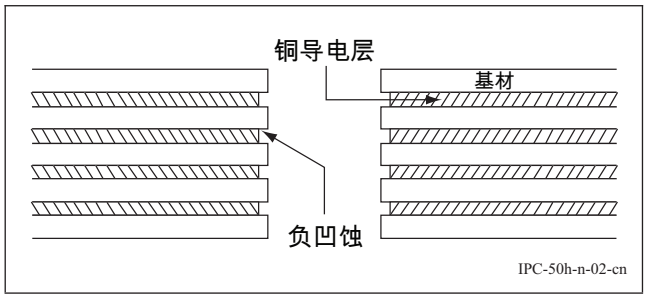


Figure N-2 Negative Etchback

负凹蚀 **54.0798**

内层的导电层材料相对于周围基材呈凹缩状的凹蚀。（见图N-2。）



图N-2 负凹蚀

Negative Pattern **24.1639**

See “Negative.”

负像图形 **24.1639**

见“负片，Negative”。

Negative-Acting Resist **52.1448**

A resist that is polymerized by light and which, after exposure and development, remains on a surface in those areas that were under the transparent areas of a production master.

负性抗蚀剂 **52.1448**

受光照而聚合的抗蚀剂，曝光、显影后会留在生产底版透明区域下的表面上。

Neighborhood Processing **92.0799**

The determination of information about a location or pixel by the use of information obtained about its neighbors.

相邻处理 **92.0799**

通过利用其邻域的信息来确定位置或像素的信息。

Nesting **25.1176**

Embedding data in levels of other data so that certain routines may be executed or accessed continuously in loops.

嵌套 **25.1176**

在其它数据等级中嵌入数据，以便在循环中连续执行或访问一些子程序。

Net **21.1177**

An entire string of electrical connections from the first source point to the last target point, including lands and vias.

网络 **21.1177**

从第一个源点到最后一个目标点的完整电气连接线，包括连接盘和导通孔在内。

Net List **21.1178**

A list of alphanumeric representations, each of which is used to describe a group of two or more points that are electrically common.

网表 **21.1178**

用字母数字表示的表，其中每个字符用来描述一组两个和两个以上电位相同的点。

Neutral Point **35.1931**

The neutral point is usually the geometric center which defines the point at which there is no relative motion of the chip during thermal cycling.

中点 **35.1931**

几何图形的中心，可以确定热循环周期中芯片在该点上没有相对的运动。

Nick **60.1179**

A cut or notch in a wire on the surface or in the edge of a conductor.

缺口 **60.1179**

表面导线内或导体边缘的切口或凹口。

Node **21.1180**

The endpoint of an electrical network branch or the junction of two or more branches.

节点 **21.1180**

电气网络分支的端点或两个或多个分支的交叉点。

Nodule **60.1181**

A mass or small lump with an irregular shape that is convex to a surface.

结瘤 **60.1181**

凸出于表面的不规则形状块状物或瘤状物。

Noise (Process Control) **91.1182**

Factors in a manufacturing process that are uncontrollable or too costly to control.

干扰（过程控制） **91.1182**

制造过程中产生的不可控制或控制成本过高的因素。

Nominal **26.1935**

The design target dimension for a physical characteristic of a product or a feature to which a tolerance may be applied that establishes the limits of variation from the target that are acceptable.

标称 **26.1935**

产品或要素物理特性的设计目标尺寸，该值允许有可接受的公差，以建立与目标值的差异范围。

Nominal Cured Thickness **55.1449**

The thickness of a multilayer printed board, or the distance between two adjacent layers of a multilayer printed board, after the prepreg has been cured at the temperature and pressure specified for that particular class of resin flow.

标称固化厚度 **55.1449**

在特定树脂流动级别规定的温度和压力下，半固化片固化后的多层印制板的厚度、或多层印制板相邻层间的距离。

Nominal Value **26.1936**

The center value between a minimum and maximum allowance.

标称值 **26.1936**

最小允许值与最大允许值之间的中间值

Nominal-Is-Best Characteristic **91.1450**

A parameter of quality that optimizes performance at its nominal value. (See also “Larger-the-Better Characteristic” and “Smaller-the-Better Characteristic.”)

标称最佳特性 **91.1450**

达到标称值时可使性能最佳化的质量参数（又见“越大越好特性，Larger-the-Better Characteristic”和“越小越好特性，Smaller-the-Better Characteristic”。）

Nonactivated Flux **75.1183**

A natural or synthetic-resin flux without activators.

非活性助焊剂 **75.1183**

不含活性剂的天然或合成树脂助焊剂。

Nonconductive Pattern **22.1184**

A configuration that is formed by the functional nonconductive material of a printed circuit, e.g., dielectric, resist, etc.

非导电图形 **22.1184**

由印制电路功能性非导电材料，如绝缘体、阻焊剂等形成的结构。

Nonfunctional Interfacial Connection **22.1453**

A plated-through hole in a double-sided printed board that electrically connects a printed conductor on one side of the board to a nonfunctional land on the other side of the board. (See Figure N-3.)

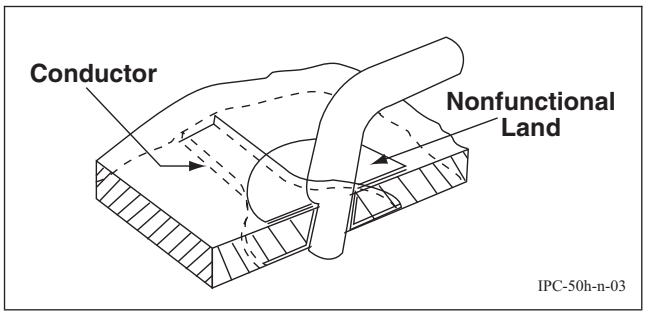
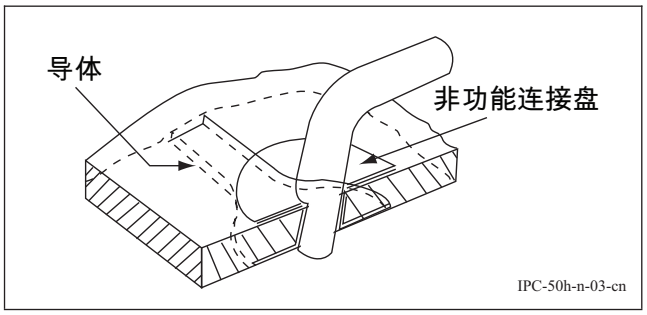


Figure N-3 Nonfunctional Interfacial Connection

非功能面间连接 **22.1453**

双面印制板中的镀覆孔，它可实现板一面的印制导体和板另一面的非功能连接盘的电气连接。（见图N-3。）



图N-3 非功能界面连接

Nonfunctional Land **22.1185**

A land that is not connected electrically to the conductive pattern on its layer.

非功能连接盘 **22.1185**

未与同层导电图形实现电气连接的连接盘。

Nonfunctional Terminal Area **22.1186**

See “Nonfunctional Land.”

非功能端子区 **22.1186**

见“非功能连接盘，Nonfunctional Land”。

Nonionic Contaminant **76.1187**

A residue that does not readily ionize in water.

非离子污染物 **76.1187**

在水中不易电离的残留物。

Nonpolar Matter **76.1188**

A substance that cannot be dissolved in water that is soluble in hydrophobic solvents.

非极性物质 **76.1188**

不溶于水但能溶解于憎水性溶剂的物质。

Nonpolar Solvent **76.1454**

A liquid that is not ionized to the extent that it is electrically conductive, that can dissolve nonpolar compounds (such as hydrocarbons and resins), and cannot dissolve polar compounds (such as inorganic salts.)

非极性溶剂 **76.1454**

不能电离至可导电程度的液体，能够溶解非极性化合物（如烃和树脂），但不能溶解极性化合物（如无机盐）。

Nonwetting (Solder) **75.1189**

The inability of molten solder to form a metallic bond with the basis metal. (See Figure N-4.)

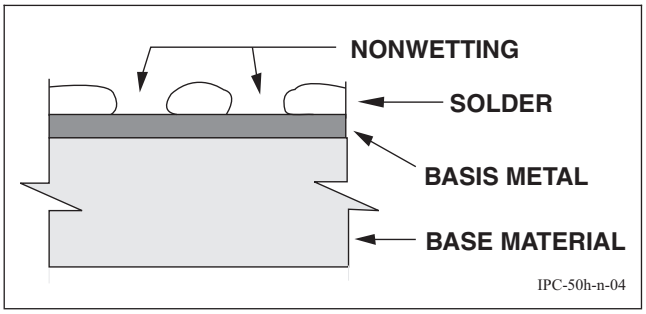
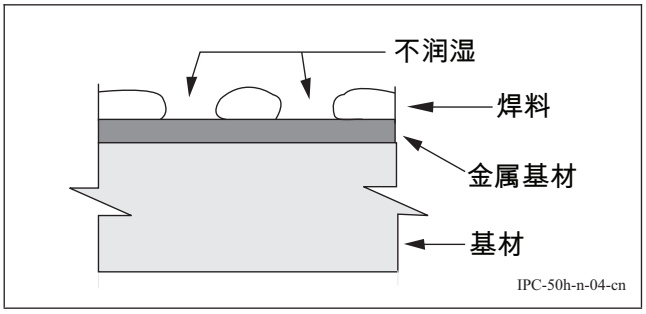


Figure N-4 Nonwetting (Solder)

不润湿（焊料） **75.1189**

熔融的焊料未能与金属基材形成金属键。（见图N-4。）



图N-4 不润湿（焊料）

Nonwoven Glass Mat **44.1937**

Glass fibers chopped into defined lengths (typically less than 50 mm) and uniformly distributed in random orientation into a horizontal plane and bound together with suitable chemical means.

无纺玻璃毡 **44.1937**

将玻璃纤维切成规定长度（一般小于50mm），在同一平面上均匀地任意散开，并通过适当的化学方法粘合在一起。

Normal Distribution **94.1191**

A mathematically-defined continuous distribution of values that has a bell shape that is perfectly symmetrical about a mean value. (See Figure N-5.)

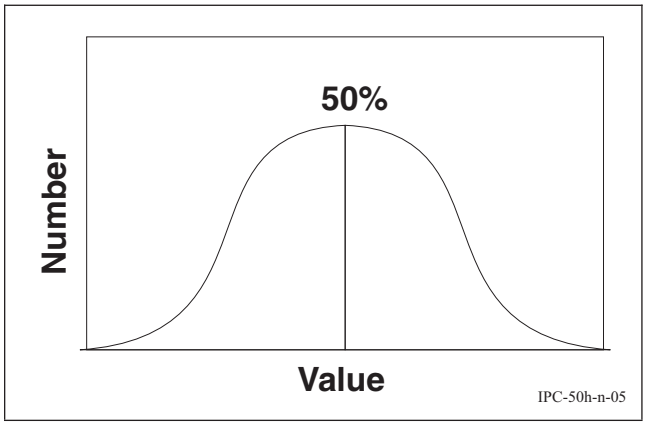
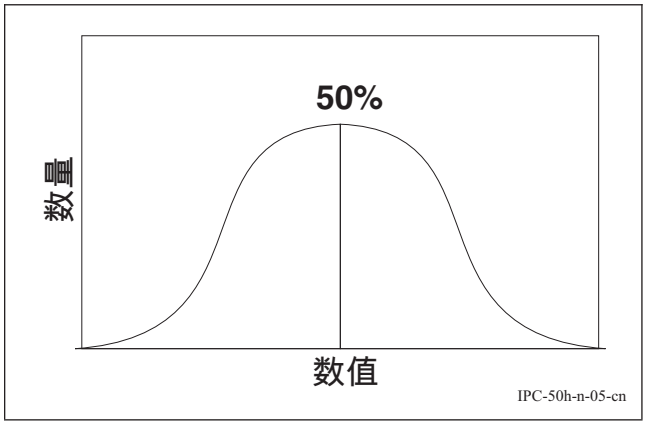


Figure N-5 Normal Distribution

正态分布 **94.1191**

由数学定义的数值的连续分布，它呈完全对称于平均值的钟形。（见图N-5。）



图N-5 正态分布

Normal-Mode Rejection (NMR) **21.1190**

The amount of noise superimposed on the input signal of a direct-current (DC) digital voltmeter that the instrument is capable of rejecting.

串模干扰抑制（NMR） **21.1190**
仪器能够抑制的叠加在直流数字电压计输入信号上的噪音量。

Null Hypothesis **91.1455**
The supposition that no significant difference exists between the desired results of two comparable populations. (See also “Alternative Hypothesis” and “Statistical Hypothesis.”)

原假设 **91.1455**
二个可比总体的预期结果之间不存在显著差异的假定。（又见“备选假设，Alternative Hypothesis”和“统计假设，Statistic Hypothesis”。）

Numerical Control (NC) (Machining) **25.1193**
The automatic control of electromechanical devices by means of a digital input to an electronic controller.

数字控制（NC）（加工） **25.1193**
通过向电子控制器输入数字来实现对机电设备的自动控制。

Numerical Control (NC) (Computer Aided Design) **20.1192**
The use of mathematics to define, design or test geometric quantities that are used in a computer-aided technology.

数字控制（NC）（计算机辅助设计） **20.1192**
使用数学方法定义、设计或测试计算机辅助技术中所使用的几何量。

O

Object Code **25.0801**
The output from a computer compiler or assembler that is, or is suitable for, processing into executable machine codes.

目标代码 **25.0801**
计算机编译程序或汇编程序的输出，可或适于处理为可执行的机器代码。

Objective Evidence **91.1939**
Documentation in the form of hard copy, computer data, video, or other media.

客观证据 **91.1939**
硬拷贝、计算机数据、视频或其他媒介形式的文档。

Object-Oriented Database **11.0800**
A database that combines graphics and text to describe objects.

面向对象数据库 **11.0800**
结合图形及文本来描述对象的数据库。

Occluded Contaminant **76.0802**
A contaminant that is totally contained in an insulating material.

夹留污染物 **76.0802**
完全包含在绝缘材料内的污染物。

Occlusion **76.0803**
Uniform molecular adhesion between a precipitate and a soluble substance, or between a gas and a metal.

吸留 **76.0803**
在沉淀物与可熔物之间、或气体与金属之间的均匀分子粘附。

Odd-Shape Chip Type Component **30.1704**
Parts with rectangular or cylindrical shapes, i.e., semi-fixed resistor or trimmer.

异形片式元器件 **30.1704**
长方形或圆柱形零件，如半固定电阻或微调电容器。

Off Bond **74.0804**
A termination that has some portion of the bonding area extending off the bonding land.

偏离键合 **74.0804**
部分键合区域延伸离开连接盘的端接点。

Off-Contact Printing **52.1789**
A printing method wherein the image or mask is not in continuous contact with the material to be printed.

非接触印刷 **52.1789**
图像或掩膜不连续接触待印刷材料的印刷方法。

Offset Land **22.0805**
A land that is intentionally not in physical contact with its associated component hole.

偏置连接盘 **22.0805**
特意不与其有关的元器件孔进行物理接触的连接盘。

Offset Terminal Area **22.0806**
See “Offset Land.”

偏置终端区 **22.0806**
见“偏置连接盘，Offset Land”。

Omnibus Ring **36.0807**
See “Support Ring.”

公共环 **36.0807**
见“支撑环，Support Ring”。

On-Contact Printing **52.1940**

A printing method wherein the imaged mask is in continuous contact with the material to be printed.

接触印刷 **52.1940**

图像或掩膜连续接触待印刷材料的印刷方法。

One-Piece Connector **37.0809**

See “Edge-Board Connector.”

单件连接器 **37.0809**

见“板边连接器，Edge-Board Connector”。

One-Sided Board **60.0810**

See “Single-Sided Printed Board.”

一面板 **60.0810**

见“单面印制板，Single-Sided Printed Board”。

Oozing (Pressure Sensitive Tape) **75.1941**

In pressure sensitive tape technology, a squeezing out of the adhesive from under the backing.

渗出物（压敏胶带） **75.1941**

压力敏感胶带工艺中，从衬板下面的粘结层被挤压出来的粘合剂。

Opacity (Photographic) **24.0811**

The reciprocal of the transmittance ratio for a photographic image.

不透明度（照相） **24.0811**

照相图像透光度的倒数。

Opaquer **24.1456**

A material that, when added to a resin system, renders laminate sufficiently opaque, so that the yarn or weave of the reinforcing material cannot be seen with the unaided eye using either reflected or transmitting light.

遮光剂 **24.1456**

加入树脂体系中使被层压板不透明的材料，无论是在反射光还是透射光下用肉眼都看不到增强材料中的纱线或织物。

Open Circuit Potential **21.0814**

The potential of a cell from which no current flows in the external circuit.

开路电势 **21.0814**

外部电路无电流通过时原电池的电势。

Open, Electrical **92.0812**

A fault that causes two electrically-connected points to become separated.

电气开路 **92.0812**

造成两个电气连通点断开的故障。

Open-Entry Contact **37.0813**

A type of female connector contact that does not prevent the entry of an oversized mating part. (See also “Closed-Entry Contact.”)

开口接触件 **37.0813**

一种不能阻止过大尺寸配接部件插入的内孔连接器接触件。（又见“闭口接触件，Closed-Entry Contact”。）

Open Point **51.1457**

The amount of misalignment between the trailing edge of the junction line between the primary and secondary drill-point clearance angles when they are ahead of the drill centerline. (See Figure O-1.)

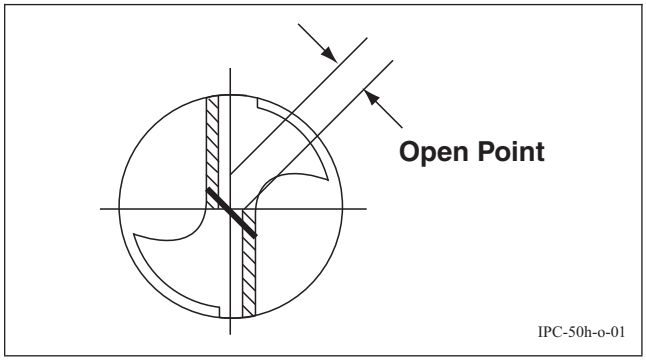
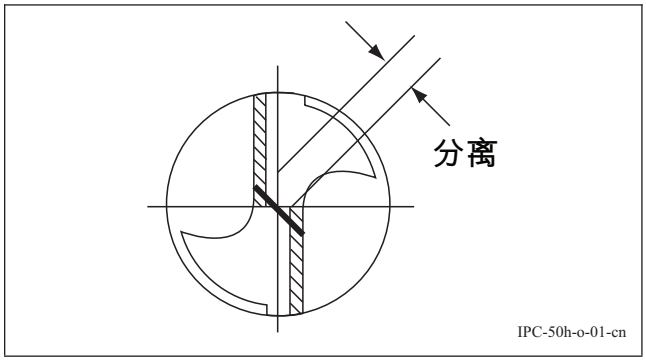


Figure O-1 Open Point

分离 **51.1457**

当钻头的第一、第二余隙角之间的交线位于其中心线前面时，其后缘的不重合程度。（见图O-1。）



图O-1 分离

Open Time **75.1194**

The maximum duration of the interval from the application of an adhesive to the formation of a satisfactory bond. (See also “Working Time.”)

间隔时间 **75.1194**

从施加粘合剂到形成满意的粘接所需要的最长时间间隔。（又见“作业时间，Working Time”。）

Optical Image **24.1195**

An image that is projected onto a viewing screen.

光学影像 **24.1195**

被投影到显示屏上的图像。

Organic Contamination **76.1196**

A type of contamination derived from an organic substance.

有机污染物 **76.1196**

由有机物产生的污染物。

Organic Flux **75.1942**

Flux primarily composed of organic materials other than rosin or resin.

有机助焊剂 **75.1942**

主要由有机材料而不是松香或树脂组成的助焊剂。

Organic Solderability Preservative (OSP) **47.2086**

An organic compound that reacts selectively with copper surfaces forming a thin, uniform film that prevents copper oxidation and helps maintain solderability after extended printed board storage.

有机可焊性保护剂（OSP） **47.2086**

能与铜表面起选择性反应形成均匀薄膜的有机化合物，形成的薄膜可防止印制板长期贮存后铜的氧化并保持其可焊性。

Original Production Master **24.1943**

The original artwork or computer data file used to produce the production master that serves as the phototool in the manufacturing image transfer process.

原始生产底版 **24.1943**

用于生成生产底版的原始照相底图或计算数据文件，可作为制造图像转移工艺的照相底版。

Orthochromatic Emulsion **24.1197**

A photographic emulsion that is spectrally sensitive to the violet, blue, and green portions of the visible light spectrum.

正色乳剂 **24.1197**

对可见光谱中的紫色、蓝色及绿色部分光谱敏感的感光乳剂。

Orthogonal-Array Experiment **91.1458**

A balanced evaluation whereby the average effect of a factor is determined while the levels of all other factors in the design are systematically changed.

正交实验 **91.1458**

一种平衡评定，其中确定一个因素的平均影响后，设计中的所有其它因素水平都将系统地改变。

Outer-Lead Bond (OLB) **74.1198**

The connection between a conductor on a bonding tape and the base material. (See also “Inner-Lead Bond.”)

外引线键合（OLB） **74.1198**

键合载带上导体与基材之间的连接。（又见“内引线键合，Inner-Lead Bond”。）

Outgassing **53.1199**

The gaseous emission from a material exposed to heat or reduced air pressure, or both.

排气 **53.1199**

暴露于热或低气压，或两者兼有环境下的材料内的气体排出。

Outgrowth **45.1459**

The increase in size of one side of a conductor that is caused by plating that is in excess of that delineated on the production master. (See Figure O-2 and Figure O-3.)

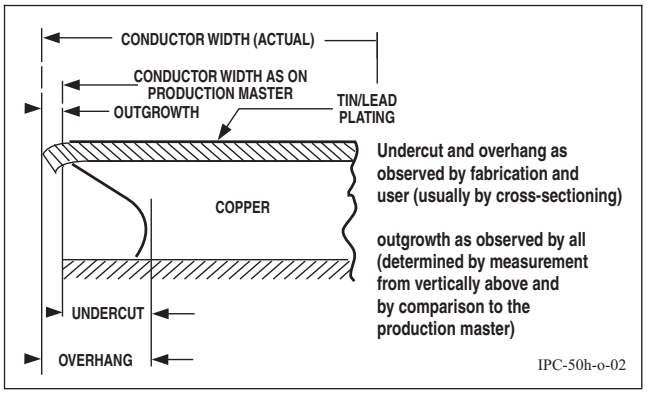


Figure O-2 Outgrowth, Overhang, and Undercut

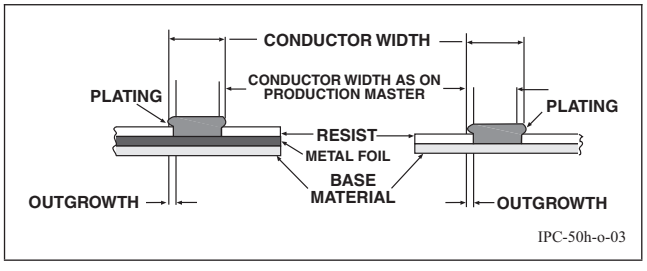
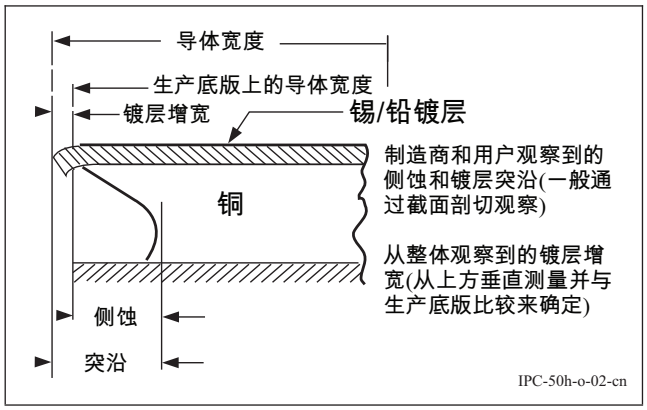


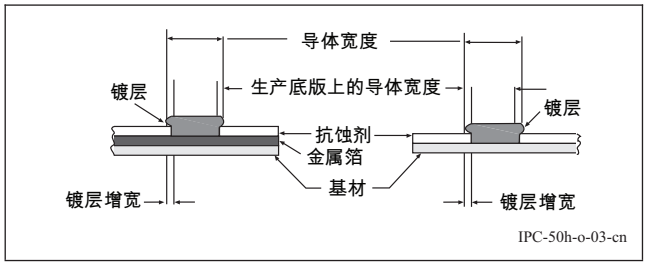
Figure O-3 Outgrowth, Overhang, and Undercut

镀层增宽 **45.1459**

由于镀层引起的导体一侧宽度的增加，其超过了生产底版上标示的宽度。（见图O-2、图O-3。）



图O-2 镀层增宽、镀层突沿和侧蚀



图O-3 镀层增宽、镀层突沿和侧蚀

Output Vector **91.1228**

The set of logic values, either expected or measured, for all output points at a particular test step of a unit under test.

输出矢量 **91.1228**

测试单元在特定的测试步骤中，所有输出点的一组逻辑值，即可以是期望值也可以是测量值。

Overall Length **51.1200**

The distance from the end of a drill shank to the cutting end of the tool, including the point.

钻刀总长度 **51.1200**

从钻柄的端部到工具切削端端之间包括钻尖的距离。

Overcoat **76.0815**

A thin film of insulating material that is applied over a semiconductor die for the purposes of mechanical and contamination protection.

覆盖层 **76.0815**

为了对半导体芯片进行机械保护并防止污染而在其表面涂覆的绝缘材料薄膜。

Overhang **60.0816**

The sum of outgrowth and undercut. (See Figure O-3.) (If undercut does not occur, the overhang is the same as the outgrowth.)

镀层突沿 **60.0816**

镀层增宽与侧蚀的总和。（见图O-3。）（如果没有侧蚀，镀层突沿就等于镀层增宽。）

Overheated Solder Connection **75.0817**

A solder connection that is characterized by solder surfaces that are dull, chalky, grainy, and porous or pitted.

过热焊接连接 **75.0817**

焊料表面为暗淡、灰化、颗粒状、多孔或有麻点特征的焊接连接。

Overlap (Film) **67.0818**

The contact area between a film component and a film conductor.

重叠（膜） **67.0818**

膜元器件与膜导体之间的接触区域。

Overlap (Drill) **51.1229**

The amount of misalignment between the trailing edge of the junction line between the primary and secondary drill-point clearance angles when they are behind the drill centerline. (See Figure B-4 and Figure O-4.) (See also “Layback.”)

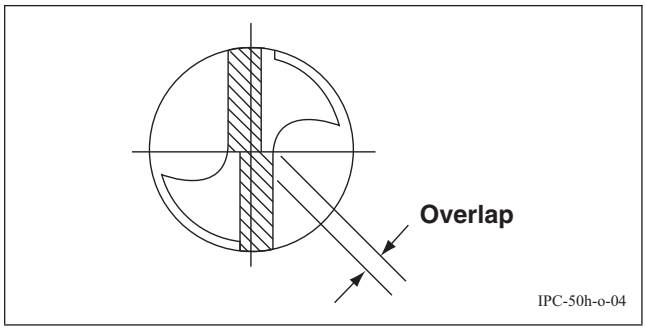


Figure O-4 Overlap

重叠（钻头） **51.1229**

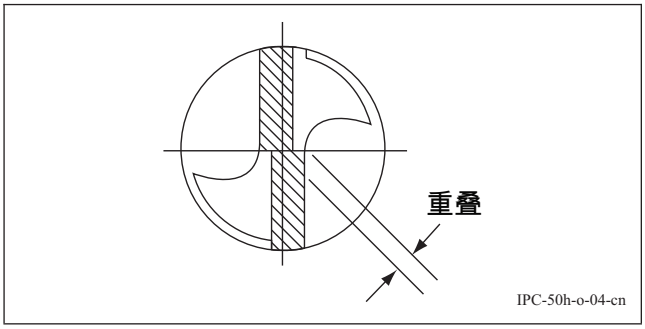
钻头的第一、第二余隙角连接线位于其中心线后面时，其后缘的不重合度。（见图D-2和O-4。）（参见“刃背，Layback”。）

Overplate **53.1673**

Conformal metallic deposition on a previously formed conductive pattern or part thereof.

外镀层 **53.1673**

在已形成的全部或部分导电图形上，再镀上一层与其形状一致的金属沉积层。



图O-4 重叠

Overprinting **75.1944**

The use of stencils with apertures larger than the pads or annular rings on the board.

套印 **75.1944**

用开孔大于板上焊盘或孔环直径的模板进行印刷。

Oxide Transfer **41.0819**

See “Treatment Transfer.”

氧化物转移 **41.0819**

见“处理物转移，Treatment Transfer”。

Oxygen Concentration Cell **76.0820**

A galvanic cell resulting primarily from differences in oxygen concentration.

氧浓差电池 **76.0820**

主要由于氧气浓度差而形成的原电池。

P

Package **30.1460**

The container for a circuit component, or components, that is used to protect its contents and to provide terminals for making connections to the rest of the circuit.

封装 **30.1460**

电路元器件的外壳，用以保护其内部元器并为实现与其他电路的连接提供端子。

Package Cap **30.0821**

A cuplike package cover.

封装罩 **30.0821**

杯状封装外壳。

Package Cover **30.0053**

The cover that encloses the contents in the cavity of a package in the final sealing operation.

封装外壳 **30.0053**

在最后的封装操作中将元器件密封在封装腔内的外壳。

Package Lid **30.0822**

A flat package cover.

封装盖 **30.0822**

扁平的封装外壳。

Packaging and Interconnecting Assembly **60.0823**

The general term for an assembly that has components mounted on either or both sides of a packaging and interconnecting structure.

封装及互连组件 **60.0823**

封装和互连结构的任一面或两面装有电子元器件的组件的统称。

Packaging and Interconnection Structure **60.1461**

The general term for a completely processed combination of base materials, supporting planes or constraining cores, and interconnection wiring that are used for the purpose of mounting and interconnecting components.

封装及互连结构 **60.1461**

用于安装和互连元器件的已完成加工的基材、支撑板或抑制芯以及互连线路组合的通称。

Package Cracking **95.1945**

Cracks in a plastic integrated circuit package caused by stress that results from exposure to reflow solder temperature. These cracks may propagate from the die or die pad to the surface of the package, or only extend part way to the surface or lead fingers.

封装裂纹 **95.1945**

由于暴露在再流焊接温度下产生的应力所导致的塑料集成电路封装内裂缝，这些裂缝可以从芯片或芯片焊盘扩散到封装表面，或者只扩散到封装表面的部分线路或引线手指上。

Packaging Density **20.1462**

The relative quantity of functions (components, interconnection devices, mechanical devices, etc.) per unit volume. (This is usually expressed by qualitative terms such as high, medium, and low.)

封装密度 **20.1462**

单位体积内功能元器件（元器件、互连器件，机械零件等）的相对数量。（通常用定性术语如高、中、低来表示。）

Pad **20.0824**

See “Land.”

焊盘 **20.0824**

见“连接盘，Land”。

Pad Cratering **96.2176**

A separation of the pad from the printed board resin/weave composite or within the composite immediately adjacent to the pad as a result of mechanical and/or thermal stress.

盘坑裂 **96.2176**

由于机械和/或热应力的作用，盘与印制板树脂/织物复合物分离、或盘下复合物内部分离。

Paddle **35.1946**

See “Die Pad.”

焊盘垫 **35.1946**

见“芯片焊盘，Die Pad”。

Pallet (Printed Board) **40.2002**

The printed board image or patterns plus the additional contiguous deliverable material from the panel. This may include tabs, fiducials, tooling holes, etc.

拼托板（印制板） **40.2002**

一块或多块线路板和其它与拼板相连的可交付材料。这可能包括工艺边、基准点、定位孔等。

Panchromatic Emulsion **24.0825**

A photographic emulsion that is spectrally sensitive to all portions of the visible light spectrum.

全色乳剂 **24.0825**

对可见光谱中所有部分都敏感的感光乳剂。

Panel **41.1463**

A rectangular sheet of base material or metal-clad material of predetermined size that is used for the processing of one or more printed boards and, when required, one or more test coupons. (See also “Blank.”)

在制板 **41.1463**

一种预定尺寸的矩形基材或覆金属箔基材，可用于加工一块或多块印制板。需要时，还包含一块或多块附连测试板。（又见“料板，Blank”。）

Panel Drawing **26.0826**

A document that shows the production master with related manufacturing patterns and artifacts that relate to the fabrication of printed boards.

制板文件 **26.0826**

显示含有与制作印制板有关的生产图形及制品的生产底版的文件。

Panel Plating **53.0827**

The plating of an entire surface of a panel including holes.

全板电镀 **53.0827**

对在制板整个表面包括所有通孔进行的电镀。

Para-aramid **44.1464**

The generic term that describes fibers that are made from wholly aromatic polyamide, amide polymers in which at least 85% of the amide linkages are directly attached to two benzene rings at the para position in the polymer chain.

对芳酰胺 **44.1464**

在聚合链上至少有85%的酰胺直接交连在两个苯环的对位上的全芳酰胺、酰胺聚合物制成的纤维通称。

Parallel Pair **22.0828**

Two conductors that are side-by-side at a controlled spacing.

平行线对 **22.0828**

在受控间距内并排的二个导体。

Parallel-Gap Soldering **75.1465**

The passing of an electrical current through a high-resistance space between two parallel electrodes in order to provide the energy required to make a soldered termination.

双极焊接 **75.1465**

为了提供制作焊接端接所需的能量，在两个平行电极之间的高阻抗间隔中通过电流。

Parallel-Gap Welding **75.1466**

The passing of an electrical current through a high-resistance space between two parallel electrodes in order to provide the energy required to make a welded termination.

双极熔接 **75.1466**

为了提供制作熔接端接所需的能量，在两个平行电极之间的高阻抗间隔中通过电流。

Parameter Record **25.0829**

A record that defines the characteristics of a subsequent set of records such as job identification, electrical description, tolerances, etc.

参数记录 **25.0829**

详细说明作业标识、电气说明、公差等的一组连续记录特性的一个记录。

Pareto Analysis **94.0830**

A problem-solving technique whereby all potential problem areas or sources of variation are ranked according to their contribution to the end result.

帕拉多分析 **94.0830**

根据其对最终结果的影响，将所有潜在问题区域或变异源进行排列的一种解决问题方法。

Partial Lift **74.0831**

A bonded lead that has been partially removed from the bonding area.

局部起翘 **74.0831**

已与键合区部分脱离的键合引线。

Partially-Clinched Lead **72.1467**

A component lead that is inserted through a hole in a printed board and is then formed in order to retain the component in place and but not necessarily in order to make metal-to-metal contact with a land prior to soldering. (See also “Clinched Lead.”)

部分折弯引线 **72.1467**

将元器件的引线穿过印制板的通孔后弯折从而固定元器件位置，但无需在焊接前将金属引线同连接盘接触。（又见“折弯引线，Clinched Lead”。）

Passivation **57.0832**

The formation of an insulating layer to protect a surface from contaminants, moisture and particulate matter.

钝化（处理） **57.0832**

为防止物体表面受污染、受潮或粘附颗粒物质而在其表面生成一种绝缘层。

Passive Array **30.2163**

Comprises multiple passive components of like function, which are formed on the surface of a separate substrate and packaged in a single SMT case. The case is then mounted on the primary interconnect substrate of the system. Examples include an array of capacitors or resistors. See Figure P-1.

被动（无源）阵列 **30.2163**

由形成在一个单独的基板板上，并封装在单一的SMT壳体内的多个具有相似功能的被动（无源）元器件组成。该壳体可贴装在系统的主互连基板上。如电容或电阻阵列。见图P-1。

Passive Base Material **44.0834**

Base material, that does not exhibit transistance, that serves as the physical support and thermal sink for film circuits.

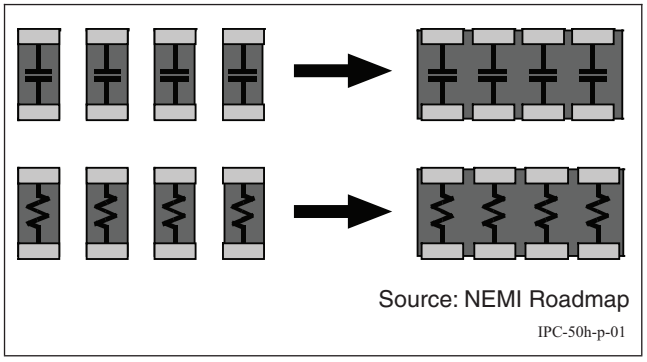
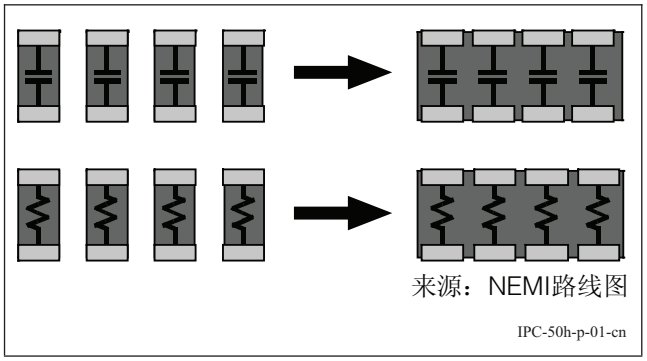


Figure P-1 Passive Array



图P-1 Passive Array

惰性基材 **44.0834**

不具备晶体管效应，只用作膜电路的物理支撑和散热片的基材。

Passive Component (Element) **30.1468**

A discrete electronic device that behaves in a fixed way in response to a signal of a given characteristic. (This includes components such as resistors, capacitors, inductors and transformers.)

被动（无源）元器件（元素） **30.1468**

以固定的方式对给定的信号做出反应的分立电子器件。（包括电阻、电容、电感和变压器等元器件。）

Passive Network **30.2164**

Passive networks comprise multiple passive components of more than one function, which are formed on the surface of a separate substrate and packaged in a single SMT case. The case is then mounted on the primary interconnect substrate of the system. Passive networks typically have some internal connections to form simple functions such as terminations or filters.

无源网络 **30.2164**

由多个具有一种以上功能的被动（无源）器件组成的无源网络，无源器件形成于单独的基板表面，且封装在单个的SMT壳体内。该壳体再安装在系统的主要互连基板上。无源网络通常有内部连接以形成简单的功能如：终端器或滤波器。

Passive-Active Cell **76.0833**
A cell whose electromotive force is due to the potential difference between a metal in an active state and the same metal in a passive state.

钝化-活化电池 **76.0833**
由活性状态金属与惰性状态同种金属之间的电势差产生电动势的原电池。

Paste Flux **75.0836**
A flux formulated in the form of a paste to facilitate its application. (See also "Solder Paste" and "Solder-Paste Flux.")

膏状助焊剂 **75.0836**
为了便于使用而配制成膏状形式的助焊剂。（见“焊膏，Solder Paste”和“焊膏助焊剂，Solder Paste Flux”。）

Paste-in-Hole **75.1883**
See "Intrusive Soldering."

通孔内焊接 **75.1883**
见“插入焊接，Intrusive Soldering”。

Paste Soldering **75.0835**
A soldering method that uses a solder paste applied to the land, device termination, or both.

焊膏焊接 **75.0835**
将焊膏涂敷在连接盘和/或器件端子的一种焊接方法。

Path (Electrical) **20.0837**
See "Conductor."

通路（电气） **20.0837**
见“导体，Conductor”。

Pattern **20.0838**
The configuration of conductive and nonconductive materials on a base material, and the circuit configuration on related tools, drawings and masters.

图形 **20.0838**
基材上的导电或非导电材料布局，以及有关底片、图纸及底版上的电路布局。

Pattern Area **20.0839**
The section of a designated configuration that includes the pattern and background.

图形区 **20.0839**
包括图形和背景的指定布局部分。

Pattern Plating **53.0840**
The selective plating of a conductive pattern and associated holes.

图形电镀 **53.0840**
对导电图形及相关孔的选择性电镀。

Peel Adhesion (Pressure Sensitive Tape) **75.1958**
The force required to break the bond between pressure sensitive tape and the surface to which it is applied.

剥离附着力（压敏胶带） **75.1958**
从与其相粘结的物体表面剥离压敏胶带所需要的力。

Peel Strength **92.0841**
The force per unit width that is required to peel a conductor foil from a laminate perpendicular to the surface of the substrate.

剥离强度 **92.0841**
从层压板上剥离单位宽度的导电箔所需要的垂直于基板表面的力。

Peeling (Cured Solder Mask) **47.1203**
The loss of a portion of the solder mask from the printed board resulting from a lack of adhesion.

剥离（已固化的阻焊膜） **47.1203**
由于粘附力不足，导致阻焊膜从印制板上局部脱落。

Percent Contribution **91.0842**
The amount that a single factor contributes to a total variation, expressed as a percent.

影响百分率 **91.0842**
指单一因子在总变异中所占的比例，采用百分比表示。

Percent of the Field of View **92.0843**
The specific part of interest of the minimum required field of view of a magnification device.

视场百分比 **92.0843**
放大装置最小要求视场内研究对象的指定部分。

Perforated (Pierced) Solder Terminal **37.1469**
A flat-metal solder terminal with an opening through which one or more wires are placed prior to soldering. (See Figure P-2.)

穿孔焊接接线柱 **37.1469**
具有一个开孔的扁平金属焊接接线柱，焊接前可将一根或多根导线穿过其中的孔。（见图P-2。）

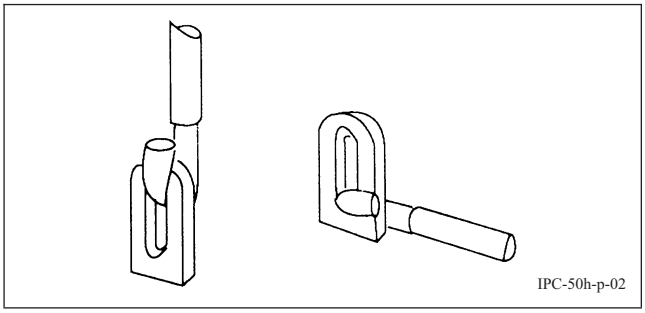
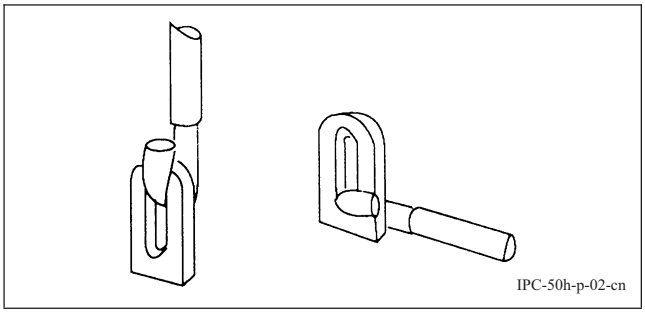


Figure P-2 Perforated (Pierced) Solder Terminal



图P-2 穿孔焊接接线柱

Perforation **54.1959**

A mechanical method that removes a portion of the material outlining the board, in order to facilitate ease of breakout (removal) from the manufacturing/assembly panel. (See "Breakaway.")

邮票孔 **54.1959**

为了便于分割制作/组装在制板，从板周边去除部分材料的机械方法。（又见“分离，Breakaway”。）

Perimeter Sealing Area **30.0844**

The surface on the perimeter of the cavity of a package that is used for attachment to the package cover.

周边密封区 **30.0844**

用于固定封装外壳的封装腔周边的表面。

Permanent Resist **52.0845**

A resist that is not removed after processing, e.g., plating resist that is used in a fully-additive process.

永久性抗蚀剂 **52.0845**

加工后不被去除的抗蚀剂，如：用于全加成工艺电镀抗蚀剂。

Permeability **21.1803**

A general term used to express various relationships between magnetic induction and magnetizing force.

导磁率 **21.1803**

用于表示磁感应及磁化力之间各种关系的通称。

Permittivity **21.1961**

The square root of the ratio of the electromagnetic wave propagation characteristics of free space to that of the dielectric medium. The permittivity, ε, of a material is, in general, a complex-valued (has real and imaginary parts) parameter. The real and imaginary parts of ε are given by εN and εO. See "Dielectric Constant."

电容率 **21.1961**

自由空间的电磁波传播特性与电介质的电磁波传播特性之比的平方根。材料的电容率是一个复数（有实数和虚数部分）参数。ε的实数和虚数部分分别以εN、εO来表示。（又见“介电常数，Dielectric Constant”。）

Personality Plate **92.0234**

A translator fixture plate drilled to match the product under test.

专用模板 **92.0234**

与待测产品相匹配的已钻孔的转换夹具板。

Phenolic Resin **41.1962**

A thermosetting phenol and aldehyde compound resin used in printed board applications that are environmentally benign in terms of moisture, temperature and cycling exposures.

酚醛树酯 **41.1962**

应用于印制线路板用覆箔板的由热固型酚类和醛类化合物缩聚形成的树脂，这种树脂在潮湿、温度和循环暴露方面对环境是无害的。

Photographic Fog **24.1470**

Any unwanted increase in density on a negative-working photographic product or a loss of density on a positive-working product that appears on exposed and processed glass film or paper that is not the result of image exposure.

照片灰雾 **24.1470**

任何不需要的负像底片上的黑度增加，或正像底片上的黑度降低；它们显现于曝过光并处理过的玻璃板、底片或照相纸上，但不是图像曝光所致。

Photographic Image **24.0456**

An image in a photomask or in an emulsion that is on a film or plate.

底片图像 **24.0456**

底片或照相板上光掩膜或感光乳剂中的图像。

Photographic Layer **52.0850**

A light-sensitive layer of material that is capable of being exposed and processed so that it yields a visible image.

感光层 **52.0850**
能被曝光并处理产生可视图像的材料的光敏层。

Photographic Operation **24.0851**
A procedure or technique that prepares a phototool for subsequent processing.

照相作业 **24.0851**
为后续工艺而制备照相底版的工序和技术。

Photographic Plate **24.0852**
A "soda-lime-silica" sheet of glass with a photographic layer.

照像板 **24.0852**
具有感光层的钠钙硅玻璃板。

Photographic-Reduction Dimension **53.0255**
The dimensions on an artwork master, such as the distance between lines or between two specified points, that indicate the extent to which the artwork master is to be photographically reduced. (The value of the dimension refers to the 1:1 scale and must be specified.)

照相缩制尺寸 **53.0255**
照相原版上的尺寸，如线段之间或两个规定点之间的距离，可表明拍摄后照相原版被缩小的程度。（该尺寸值是指1:1的比例，必须对其加以规定。）

Photomaster **24.0853**
See "Artwork Master."

照相原版 **24.0853**
见"照相原版，Artwork Master"。

Photometry **24.0854**
The measurement of the effect of the intensity and energy of visible light on the human eye.

光度学 **24.0854**
可见光的强度和能量对人眼的影响的量度。

Photoplotting **24.0855**
A photographic process whereby an image is generated by a controlled-light beam that directly exposes a light-sensitive material.

光绘 **24.0855**
用受控的光束直接曝光光敏材料形成图像的照相过程。

Photoprint **52.0856**
The process of forming a circuit pattern image by exposing photo-sensitive material to light energy.

光成像 **52.0856**
用穿过照相底片的光来固化光敏聚合材料以形成电路图形图像的工艺。

Photoresist **52.1472**
A photo-chemically reactive material, which polymerizes upon exposure to ultraviolet energy at a given wavelength customarily used to define an etching, plating, or selective stripping pattern on a substrate.

光致抗蚀剂 **52.1472**
暴露在指定波长的紫外光能量下就能聚合的光化学反应材料，用来在基板上进行形成蚀刻、电镀或选择性剥离图形。

Photoresist Image **52.0857**
An exposed and developed image in a coating on a base material.

光致抗蚀图像 **52.0857**
基材涂层内经曝光、显影后的图像。

Phototool **24.0858**
A phototool is a physical film, Mylar® (or similar), which contains the pattern that is used to produce a circuitry image on a photo-sensitive material by way of exposure to light-energy such as UV light. (See also "Artwork," "Artwork Master," "Production Master," "Working Master.")

底片 **24.0858**
底片是一种物理膜，Mylar（或类似材料），将其暴露于光源，如UV光下，其上的图形在感光材料上生成电路图像。（可参见"照相底图，Artwork"，"照相原版，Artwork Master"，" 生产底版，Production Master"，"工作原版、Working Master"。）

Phototooling **24.0859**
The entire group of photographic products that are used to produce a pattern on a base material.

底片组 **24.0859**
用于在基材上产生图形的一组完整的照相产品。

Phototooling Aid **24.0860**
A photographic product that is used to assist in the inspection of, but not the transfer of, imaged patterns.

辅助底片 **24.0860**
用来辅助检验，但不是转移图像图形的一种照相产品。

Photo Via **22.1963**
A via formed by the photo process.

光致导通孔 **22.1963**

采用感光工艺形成的导通孔。

Physical Vapor Deposition **45.1964**

The deposition of a film onto the surface of a substrate by the physical transfer of vapor from the source to the substrate. (See also “Chemical Vapor Deposition.”)

物理汽相沉积 **45.1964**

通过汽相从源到基板的物理转移在基板表面沉积一层膜。（又见“化学气相沉积， Chemical Vapor Deposition”。）

Pick **44.0861**

Filling yarn that runs crosswise to the entire width of a fabric.

纬纱 **44.0861**

横向穿过织物整个宽度的纱线。

Pick-Up Force **73.1760**

The force required to pick up a surface mounting component from its packaging medium for placement on a substrate.

拾取力 **73.1760**

为了将表面贴装元器件贴装到基板上，从包装介质中取出表面贴装元器件所需要的力。

Pick-Up Tool **73.1759**

A tool used to pick up surface mount components from a packaging medium for placement on a substrate and which may be hand activated or a part of a pick-and-place machine.

拾取工具 **73.1759**

为了将表面贴装元器件贴装到基板上，从包装介质中取出表面贴装元器件所使用的工具，可以是手动的，或是贴装机的一部分。

Pilot Hole **22.0862**

See “Tooling Hole.”

导向孔 **22.0862**

见“定位孔，Tooling Hole”。

Pin Grid Array (PGA) **31.1965**

A square or rectangular component package with pins protruding from the bottom surface with a pitch perpendicular to the plane of the package. (See Figure P-3.)

针栅阵列（PGA） **31.1965**

带有从封装底部伸出且与封装平面垂直的插针的方形或矩形元器件封装。（见图P-3。）

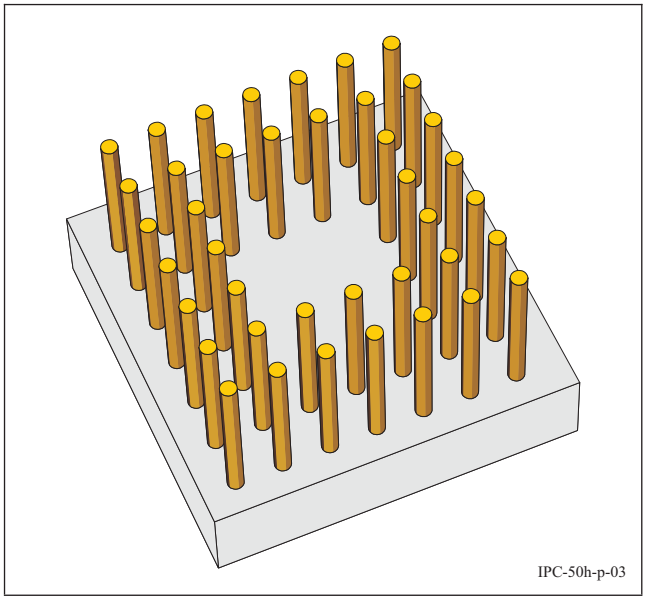
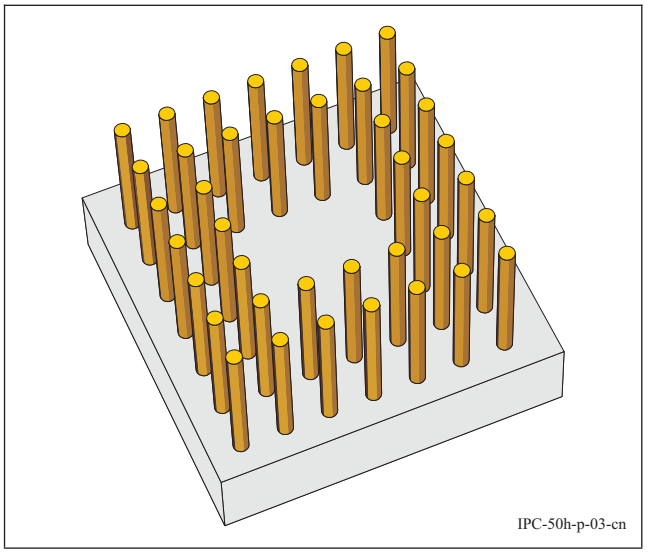


Figure P-3 Pin Grid Array



图P-3 针栅阵列

Pin Lamination **55.1966**

A manufacturing technique utilizing pins to align various innerlayers and prepreg (adhesive layers) during the multilayer lay-up and lamination process.

销钉层压 **55.1966**

在多层板的叠合和层压过程中采用销钉对准各种内层和半固化片（粘合层）的制造技术。

Pin-hole (Base Materials) **41.1967**

An open point in the resin coverage of the reinforcement, usually within the window formed by adjacent yarns in x and y directions.

针孔（基材） **41.1967**

位于增强材料上树脂覆盖处的敞口点，通常位于由X和Y方向上相邻的纱线形成的窗口内。

Pinhole (Material) **92.0863**

An imperfection in the form of a small hole that penetrates entirely through a layer of material. (See also “Pit” and “Solder Connection Pinhole.”)

针孔（材料） **92.0863**

完全穿透一层材料的小孔形式的缺陷。（又见“麻点，Pit”和“焊接连接针孔，Solder Connection Pinhole”。）

Pinhole (Phototool) **24.0864**

A clear defect that is completely within a black pattern or in the black background of a clear pattern.

针孔（底片） **24.0864**

完全在黑色图形之内或在透明图形的黑色背景范围内的透明缺陷。

Pin-In-Hole **75.1884**

See “Intrusive Soldering.”

孔中插针焊接 **75.1884**

见“插入焊接，Intrusive Soldering”。

Pink Ring **55.0865**

A zone around a through-hole/innerlayer interface from which a copper oxide coating has been chemically removed.

粉红环 **55.0865**

用化学方法去除铜氧化层后通孔/内层界面周围的粉色区域。

Pit **92.0866**

An imperfection in the form of a small hole that does not penetrate entirely through a layer of foil. (See also “Pinhole, Material.”)

麻点 **92.0866**

未完全穿透金属箔层的小孔形式的缺陷。（又见“针孔（材料），Pinhole (Material)”。）

Pitch **22.1473**

The nominal center-to-center distance between adjacent features. (When the features are of equal size and their spacing is uniform, the pitch is usually measured from the reference edge of the adjacent features.)

间距 **22.1473**

相邻要素之间的标称中心距离。（当要素大小相同且其间隔均匀时，通常从相邻要素的基准边测量间距。）

Pixel **25.0867**

The smallest definable picture element area capable of being displayed.

像素 **25.0867**

能够被显示的最小可确定的像点面积。

Placement Force **73.1761**

The force required to deposit a surface mount component.

贴放力 **73.1761**

放置一个表面贴装元器件所需要的力。

Plain Hole **22.1968**

See “Unsupported Hole.”

平孔 **22.1968**

见“非支撑孔，Unsupported Hole”。

Plain Weave **44.0868**

A fabric configuration whereby each warp end goes over one pick and under the next, and whereby each pick goes over one warp end and under the next.

平纹编织 **44.0868**

经纱、纬纱一上一下交叉编织而成的织物结构。

Planar Resistor **45.1969**

An etched or deposited resistive element incorporated within or on the surface of the printed board.

平面电阻 **45.1969**

位于线路板表面或线路板内部的蚀刻或沉积阻抗元器件。

Planar-Mount Device **33.0869**

See “Surface-Mount Component (SMC).”

平面贴装器件 **33.0869**

见“表面贴装元器件（SMC），Surface-Mount Component (SMC)”。

Planar Board **60.1970**

A substrate on which bare chips and surface- and insertion-mount components are mounted. After being mounted with these components, the substrate is no longer heated for mounting on other planar boards. It generally includes motherboards, daughter cards, etc.

平面板 **60.1970**

安装有裸芯片、表面贴装元器件和插装元器件的基板。安装这些元器件后，该基板将不再被加热安装到其它平面板上。通常包括母板、子卡板等。

Plastic **40.0870**

Any of a group of synthetic or natural organic materials that may be shaped when softened and then hardened.

塑料 **40.0870**

先软化然后硬化即可定型的任何一组合成或天然有机材料。

Plastic QFP (PQFP) **33.1973**

See “Quad Flat Pack.”

塑封QFP（PQFP） **33.1973**

见“方形扁平封装，Quad Flat Pack”。

Plastic Ball Grid Array (PBGA) **33.1971**

A polymer based package with interconnects formed of tin-lead or lead-free solder spheres. The solder interconnects are located in an array area in board side of package.

塑封球栅阵列（PBGA） **33.1971**

锡铅焊料球形成互连的聚合物基封装，焊料互连以阵列形式位于封装底部。

Plastic Deformation **40.0871**

Deformation that does, or will, remain permanent after removal of the load that caused it.

塑性变形 **40.0871**

去除引起变形的负载后，仍保持或将永久保持的变形。

Plastic Device **30.0872**

A semiconductor component wherein the package or encapsulant is plastic.

塑封器件 **30.0872**

其封装或密封为塑料的半导体元器件。

Plastic Leaded Chip Carrier (PLCC) **33.1972**

A surface mount family of integrated circuit packages with leads exiting from all four sides of the package, generally with a 1.27 mm [0.050 in] lead-to-lead pitch.

塑封有引线芯片载体（PLCC） **33.1972**

封装四周都有引线伸出的表面贴装系列集成电路封装，引线间距通常为1.27mm[0.050in]。

Plastic QUAD Flat Pack (PQFP) **33.1974**

A surface mount family of integrated circuit packages, bounded on all four sides by bumpers, with leads exiting from all four sides of the package and formed into a “gull-wing” lead format.

塑封方形扁平封装（PQFP） **33.1974**

一种表面贴装系列的集成电路封装，四边均缚有保护引线共面性和避免引线变形的“角耳”，引线从封装体的四周向外延伸，并成型为“鸥翼”形式。

Plate Finish, Laminating **55.1474**

The surface finish, without modification by subsequent processing, of the metal on metal-clad base material that results from direct contact with laminating press plates.

层压模板抛光 **55.1474**

让层压模板相互之间直接磨擦而产生光滑表面的一种无需后续修整的表面处理方法。

Plated-Through Hole (PTH) **22.1475**

A hole with plating on its walls that makes an electrical connection between conductive patterns on internal layers, external layers, or both, of a printed board. (See Figure P-4.)

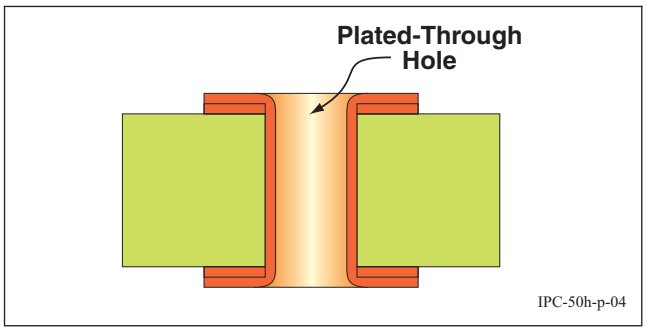
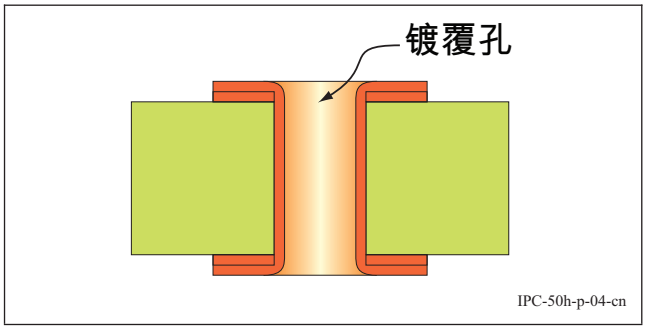


Figure P-4 Plated-Through Hole (PTH)

镀覆孔（PTH） **22.1475**

孔壁镀覆有金属的孔，其可实现印制板内层、外层或内外层上导电图形之间的电气连接。（见图P-4。）



图P-4 镀覆孔（PTH）

Plated-Through Hole Structure Test **92.1476**

The visual examination of the metallic conductors and plated-through holes of a printed board after the dielectric material has been dissolved away.

镀覆孔结构测试 **92.1476**

将镀覆孔的介质材料溶解后对印制板金属导体和镀覆孔进行的目检。

Plating **53.0874**

Chemical or electrochemical deposition of metal on an entire surface (see "Panel Plate") or on a conductive pattern (see "Pattern Plate").

电镀 **53.0874**

金属在整个表面（见“全板电镀，Panel Plate”）或导电图形（见“图形电镀，Pattern Plate”）上化学或电化学的沉积。

Plating Bar **53.0876**

The conductive path that temporarily interconnects areas of a conductive pattern that are to be electroplated. (See also "Bus Bar.")

电镀工艺导线 **53.0876**

与待电镀的导电图形暂时性互连的导电通路。（见“汇流排，Bus Bar”。）

Plating, Burned **53.0875**

A rough, dull electrodeposit that was caused by excessive plating current density.

镀层烧焦 **53.0875**

因电镀电流密度过大而产生的粗糙无光泽的电沉积。

Plating Fold **53.2168**

A condition at an area of hole sidewall irregularity where the plating conditions cause the edges of a plating cavity to fuse together and form an enclosure. This cavity can entrap contaminants or process chemistry. (See Figure P-5.)

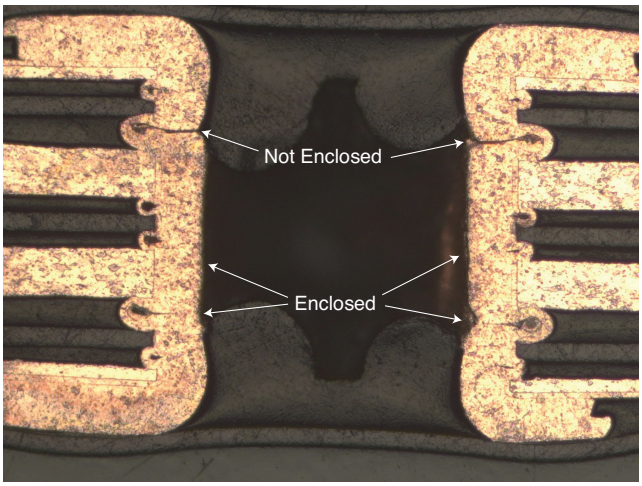
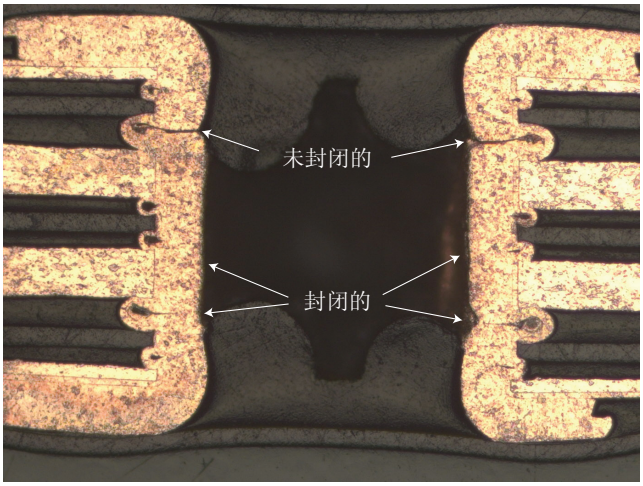


Figure P-5 Plating Fold

镀层折叠 **53.2168**

铜层折叠一般发生在孔侧壁不规则的区域，这种镀层状况会造成镀层空洞边缘熔合在一起并封闭。这种空穴会截留污物或工艺化合物。（见图P-5。）



图P-5 镀层折叠

Plating Resist **52.1975**

An organic material intended to prevent the deposition of metallic plating on specific portions of copper planes that are on the surface of copper-clad laminate or printed board outerlayers.

电镀抗蚀剂 **52.1975**

用于防止金属镀层沉积在覆铜箔层压板或印制板外层铜表面指定部分的有机材料。

Plating Solution **45.1976**

A chemical solution containing metal ions used in plating a metal-film on a substrate. Also may be referred to as an electrolyte.

电镀溶液 **45.1976**

含有金属离子的化学溶液，可用于在基板上电镀金属膜。这种溶液又可称为电解液。

Plating Thief **53.1477**

A racking device, or nonfunctional pattern on a panel, that is used to help achieve a more uniform current density on plated parts during an electroplating process.

分流阴极 **53.1477**

电镀工艺中使用的挂具或在制板上的非功能图形，可使电镀件上的电流密度更均匀。

Plating, Palladium **53.1953**

One of the lead-free platings using palladium. The basis metal should be Cu or Ni, but not Fe-Ni because of corrosion.

钯镀层 **53.1953**

采用钯的一种无铅镀层，基底金属应采用铜或镍，由于腐蚀问题不应采用铁/镍合金。

Plating, Tin (Sn) **53.1954**

One of the lead-free platings using tin only and employed mainly for passive chip components. When using Tin (Sn) plating, the occurrence of whiskers is a possibility and should be avoided.

锡（Sn）镀层 **53.1954**

只采用锡的一种无铅镀层，主要用于无源片式元器件。采用锡镀层时，可能会出现锡晶须，应尽量避免。

Plating, Tin Bismuth (Sn-Bi) **53.1955**

One of the lead-frees plating using tin with bismuth added to no more than about 3%.

锡铋（SnBi）镀层 **53.1955**

主要采用锡的一种无铅镀层，锡中填加了不大于3%的铋。

Plating, Tin Copper (Sn-Cu) **53.1956**

One of the lead-frees plating using tin with copper added no to more than about 2.5%.

锡铜（SnCu）镀层 **53.1956**

主要采用锡的一种无铅镀层，锡中填加了不大于2.5%的铜。

Plating, Tin Silver (Sn-Ag) **53.1957**

One of the lead-free platings using tin with silver added to about 3%.

锡银（SnAg）镀层 **53.1957**

主要采用锡的一种无铅镀层，锡中填加了不大于3%的银。

Plating Up **53.0877**

The electrochemical deposition of a conductive material on a base material that takes place after the base material has been made conductive.

镀层加厚 **53.0877**

在已处理为导电的基材上再电化学沉积导电材料。

Plating Void **53.1977**

An isolated location where the plating is absent or the plating thickness is less than the minimum specified copper thickness.

镀层空洞 **53.1977**

无镀层或镀层厚度小于规定的最小铜厚度的孤立点。

Plenum **54.1978**

A chamber that is used to uniformly distribute a fluid, e.g., air, nitrogen, or other gas, into a processing chamber.

增压箱 **54.1978**

用于将流体，如空气、氢气或其它气体均匀地分布到加工腔内的箱体。

Plied Yarn **44.0878**

Yarn with two or more twisted yarns.

合股线 **44.0878**

由两股以上的绞合纱线组成的纱。

Plotting **24.0879**

The mechanical converting of X-Y positional information into a visual pattern, such as artwork.

绘图 **24.0879**

采用机械方法将X-Y位置信息转换为可视图形，如照相底图。

Plug Connector **37.0880**

The unmounted half of a two-piece connector pair that mates with a receptacle connector.

插塞式连接器 **37.0880**

两件式连接器中与插座连接器配接的未固定的另一半。

Point Angle **51.0881**

The included angle between the two primary cutting edges of a drill.

顶角 **51.0881**

钻头的两主切削面所构成的夹角。

Poise **46.1607**

A metric unit of measure of viscosity expressed as dyne-seconds per square centimeter.

泊 **46.1607**

量度粘度的公制单位，表示为达因秒每平方厘米。

Poisson Distribution **91.1478**

A discrete probability distribution for attributes data that is particularly applicable when there are many opportunities for the occurrence of an event but a low probability on each trial.

泊松分布 **91.1478**

属性数据的离散性概率分布，特别适用于发生的机会很多、但每次试验中的概率很低的事件。

Polar Matter **76.0883**
A substance that can dissolve in water and hydrophilic solvents.

极性物质 **76.0883**
能溶于水和亲水溶剂中的物质。

Polar Solvent **76.1815**
A liquid that is ionized to the extent that it is electrically conductive, that can dissolve polar compounds (such as hydrocarbons and resins), but cannot dissolve nonpolar compounds (such as inorganic salts).

极性溶剂 **76.1815**
一种可电离至导电的液体，它能溶解极性化合物（如碳氢化合物和树脂），但不能熔解非极性化合物（如无机盐）。

Polarized Component **30.1981**
A component wherein the terminations are assigned as positive or negative electrical polarity.

极性元器件 **30.1981**
端子被明确指定为正电极或负电极的元器件。

Polarizing Slot **22.0882**
A slot in the edge of a printed board that is used to assure the proper insertion and location of the board in a mating connector. (See also “Keying Slot.”)

极性槽 **22.0882**
位于印制板边缘用来确定板子在配接的连接器内正确插入和定位的槽。（又见“键槽，Keying Slot”。）

Polyester **42.1982**
The synthetic polymer that has more than two ester radicals in the main chain.

聚酯 **42.1982**
主链上有两个以上酯基团的合成聚合物。

Polyimide **42.1983**
The synthetic polymer that has more than two imide radicals in the main chain.

聚酰亚胺 **42.1983**
主链上有两个以上酰亚胺基团的合成聚合物。

Polymer **40.1479**
A compound of high molecular weight that is derived from either the joining together of many small similar or dissimilar molecules or by the condensation of many small molecules by the elimination of water, alcohol, or some other solvent.

聚合物 **40.1479**
由许多相似或不相似的分子单位聚合连接在一起，或者由许多小分子缩聚，再除去水、乙醇或其他溶剂而形成的高分子量化合物。

Polymer Reversion **76.1480**
The irreversible softening or liquifaction of a polymer as the result of hydrolysis due to the bombardment of the polymer with vapor molecules that contain an active hydroxyl group.

聚合物裂解 **76.1480**
由于含活性羟基的蒸汽分子对聚合物的轰击，水解引起不可逆的聚合物软化或液化。

Polymerize **40.0884**
To form a polymer or polymeric compound.

聚合 **40.0884**
形成聚合物或聚合混合物。

Polymerized Rosin **76.0885**
Rosin that has reacted with itself during the course of a soldering operation.

聚合松香 **76.0885**
在焊接操作期间与自身发生反应的松香。

Porosity (Solder) **75.0886**
A solder coating with an uneven surface and a spongy appearance that may contain a concentration of small pinholes and pits.

疏孔（焊料） **75.0886**
焊料涂覆层由于含有密集的小针孔和麻点使其表面不均匀且外观多孔。

Positional Tolerance **22.0887**
The amount that a feature is permitted to vary from its true-position location.

定位公差 **22.0887**
针对要素准确位置所允许的变动量。

Positive Pattern **24.0888**
An artwork, artwork master, or production master in which the pattern being fabricated is opaque to light and the other areas are transparent.

正像图形 **24.0888**
待加工的线路图形为不透明、而其它区域为透明的照相底图、照相原版或生产底版。

Positive-Acting Resist **52.1481**

A resist that is decomposed (softened) by light and which, after exposure and development, is removed from those areas of surface that were under the transparent areas of a production master.

正性抗蚀剂 **52.1481**

见光分解（软化）的抗蚀剂，在曝光和显影后，生产底版透明区域下面的抗蚀剂被除去。

Post **37.0889**

See “Terminal.”

端柱 **37.0889**

见“接线柱，Terminal”。

Post Curing **56.0890**

Heat aging in order to stabilize material through stress relieving.

后固化 **56.0890**

通过消除应力来稳定材料的加热老化。

Postprocessing **25.0891**

Manipulating data after it has been generated or run through a batch process.

后处理 **25.0891**

通过批处理产生或运行数据后，再对其进行处理。

Postprocessor **25.1482**

A software procedure or program that interprets data and formats it into data that is readable by a numerically-controlled machine or by other computer programs.

后处理程序 **25.1482**

将数据或格式转换为数控设备或其它计算机程序可读的数据的软件程序。

Potting Compound **47.0892**

A material, usually organic, that is used for the encapsulation of components and wires.

灌封化合物 **47.0892**

用于灌封元器件和导线的材料，通常为有机化合物。

Power Dissipation **21.0893**

The energy used by an electronic device in the performance of its function.

功耗 **21.0893**

电子器件在执行其功能过程中所耗用的能量。

Power Factor **21.0894**

The cosine of the angle of phase difference between current and the voltage applied.

功率因素 **21.0894**

所施加的电流和电压之间相位差的角的余弦。

Power of Experiment **91.0895**

The probability of rejecting the results of the null hypothesis when it is false and of accepting the alternative hypothesis when it is true.

实验功效 **91.0895**

当原假设结果为伪时，拒绝该结果；以及当备择假设为真时，接收该结果的概率。

Power of Source **24.0896**

See “Radiant Intensity.”

源功率 **24.0896**

见“辐射强度，Radiant Intensity”。

Power Plane **22.0897**

See “Voltage Plane.”

电源层 **22.0897**

见“电压层，Voltage Plane”。

Power Plane Inductance **21.1804**

The inductance in response to AC noise, seen on a DC backplane system.

电源层电感 **21.1804**

在直流电背板系统上可见的响应交流干扰的电感。

Preconditioning **71.1762**

Preparation of a component or assembly for processing or testing.

预处理 **71.1762**

为了进行加工或测试，对元器件或组件所作的准备工作。

Preferred Solder Connection **75.0899**

A solder connection that is smooth, bright, and feathered-out to a thin edge in order to indicate proper solder flow and wetting action. Also no bare metal is exposed within the solder connection and there are no sharp protrusions of solder or the evidence of contamination, e.g., embedded foreign material.

优质焊点 **75.0899**

光滑、明亮并呈羽状的薄边缘焊点，它表明焊处具有适宜的焊料流动及润湿作用。此外，焊点内不裸露金属基材且无尖锐焊料凸出物和污染物，如夹裹的外来物。

Pre-finish (n.) **55.0898**

A coupling agent that is applied on a fiber in order to improve compatibility with resins.

预调整剂 **55.0898**

为了改善纤维与树脂的兼容性而涂敷在纤维上的耦合剂。

Pre-setting **73.1986**

The fixing of component(s) to prescribed position using adhesive to prevent the movement of components during soldering.

预定位 **73.1986**

使用粘合剂将元器件固定到规定的位置，以防止元器件在焊接过程中移动。

Preflow **55.0900**

See “Stabilization Period.”

预流动 **55.0900**

见“稳定期，Stabilization Period”。

Pregelation Particle **92.0901**

See “Prepreg.”

预凝胶粒子 **92.0901**

见“预浸材料，Prepreg”。

Preheat (n.) **56.0902**

A preliminary phase of a process during which the product is heated at a predetermined rate from ambient temperature to a desired elevated temperature.

预热（名词） **56.0902**

将产品按照预定的速度从室温加热至预定升高温度的过程初始阶段。

Preheat Force **75.1984**

In hot-bar conductive soldering, that portion of the force profile where light contact pressure is made during preheat between a thermode and the component leads being terminated to allow for wetting of the metals being joined prior the application of the full bonding force.

预热力 **75.1984**

在热棒传导焊接中，力曲线的一部分，即在热电极与被端接的元器件引线之间的预热期间施加的轻接触压力，可在施加全部的结合力之前，润湿被连接的金属。

Preheating (v.) **56.1483**

The raising of the temperature of a material(s) above the ambient temperature in order to reduce the thermal shock and to influence the dwell time during subsequent elevated-temperature processing.

预热（动词） **56.1483**

为了减少热冲击和在后续的升温过程中影响保温时间，使材料温度升高至室温以上。

Preimpregnated Bonding Sheet **41.0903**

See “Prepreg.”

预浸粘结片 **41.0903**

见“预浸材料，Prepreg”。

Prepreg **41.0904**

A sheet of material that has been impregnated with a resin cured to an intermediate stage, i.e., B-staged resin.

预浸材料 **41.0904**

已浸有固化至中间阶段即B阶树脂的材料片。

Pressfit Contact **37.0905**

An electrical contact that can be pressed into a hole in an insulator or printed board with or without plated-through holes.

压合接触件 **37.0905**

能够被压入绝缘体孔内或有镀覆孔或无镀覆孔的印制板内的电气接触件。

Pretinning **53.0906**

See “Tinning.”

预上锡 **53.0906**

见“上锡，Tinning”。

Primary Flare **51.0907**

A condition whereby the drill’s primary relief is wider at its periphery than it is at its center. (See Figure P-6.)

外倾 **51.0907**

钻头第一后脚在圆周处比其在中心处宽的状况。（见图P-6。）

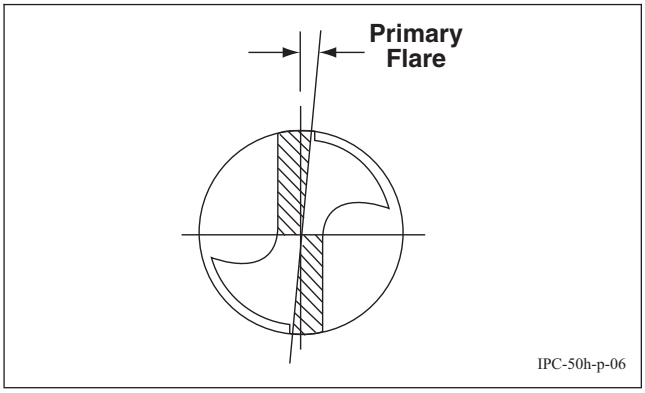
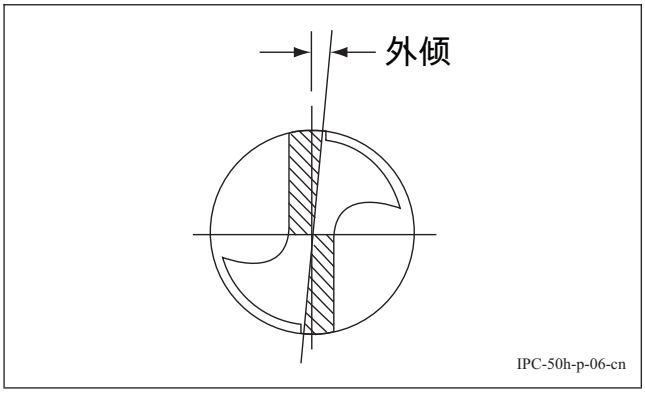


Figure P-6 Primary Flare



图P-6 外倾

Primary Relief **51.0908**

The clearance angle at the outer corner of the cutting edge of a drill point.

第一后角 **51.0908**

钻尖的切削刃部分外角处的余隙角。

Primary Side **22.1484**

The side of a packaging and interconnecting structure that is so defined on the master drawing. (It is usually the side that contains the most complex or the most number of components.)

主面 **22.1484**

布设主图中所规定的封装与互连结构面。（通常是包含有最复杂或最多元器件的一面。）

Primary Stage of Manufacture **92.0909**

That time during the manufacturing of a product when it is ready for inspection prior to shipment.

制造主要阶段 **92.0909**

产品在整个制造过程中处于发货前、备好待检验的阶段。

Primary Taper **51.0910**

A condition whereby the primary relief is wider at the center of a drill than it is at the periphery. (See Figure P-7.)

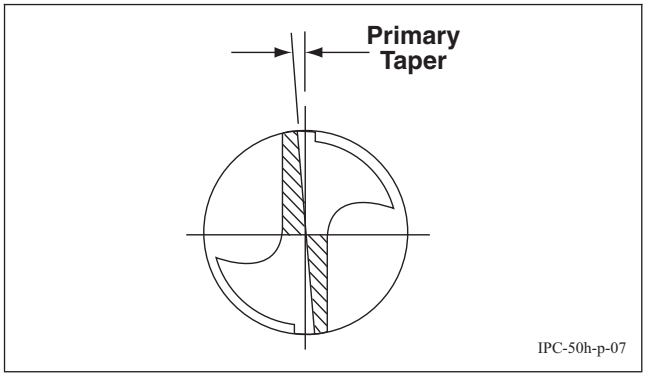
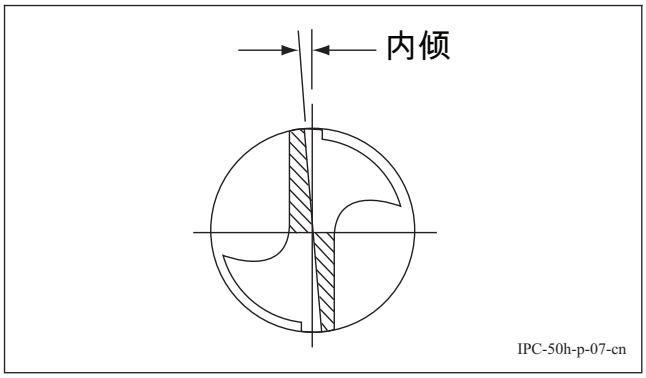


Figure P-7 Primary Taper

内倾 **51.0910**

钻头第一后脚在中心处比其在圆周处宽的状况。（见图P-7。）



图P-7 内倾

Print Contrast Signal **70.1987**

In bar code symbols, a comparison between the reflectance of the bars and spaces.

印刷对比信号 **70.1987**

条码符号中，条与空反射系数之间的比较。

Printed Board (PB) **60.1485**

The general term for completely processed printed circuit and printed wiring configurations. (This includes single-sided, double-sided and multilayer boards with rigid, flexible, and rigid-flex base materials.)

印制板（PB） **60.1485**

加工完毕的印制电路与印制线路结构的通称。（它包括采用刚性、柔性以及刚挠性基材制成的单面、双面和多层板。）

Printed Board Assembly **80.0911**

The generic term for an assembly that uses a printed board for component mounting and interconnecting purposes.

印制板组件 **80.0911**

对采用印制板来装连元器件的组件的通称。

Printed Board Assembly Drawing **26.1486**
The document that shows a printed board, separately manufactured components, and any information necessary to describe the joining of them together in order to perform a specific function.

印制板组装图 **26.1486**
用以图示印制板和独立制造的元器件，以及描述如何将其连接到一起以完成特定功能的所有必要信息的文件。

Printed Circuit **60.0912**
A conductive pattern that is composed of printed components, printed wiring, discrete wiring, or a combination thereof, that is formed in a predetermined arrangement on a common base. (This is also a generic term that is used to describe a printed board that is produced by any of a number of techniques.)

印制电路 **60.0912**
由在公用基材上按照预定布局形成的印制元器件、印制线路、分立线路或其组合组成的导电图形。（它也是用于描述由各种技术制作的印制板的通称。）

Printed Circuit Board **60.1487**
Printed board that provides both point-to-point connections and printed components in a predetermined arrangement on a common base. (See also “Printed Wiring Board.”)

印制电路板 **60.1487**
在公共基材上按照预定布局提供点到点连接及印制元器件的印制板。（又见“印制线路板，Printed Wiring Board”。）

Printed Circuit Board Assembly **80.0913**
An assembly that uses a printed circuit board for component mounting and interconnecting purposes.

印刷电路板组件 **80.0913**
采用印制电路板实现元器件安装和互连的组件。

Printed Component **52.0914**
A part (such as an inductor, resistor, capacitor, or transmission line) that is formed as part of the conductive pattern of a printed board.

印制元器件 **52.0914**
作为印制板导电图形一部分所形成的部件（如电感、电阻、电容和传输线等）。

Printed Components, Conductive Inks **52.1600**
Component (e.g., printed inductor, resistor, capacitor or transmission line) forming part of the pattern of a printed circuit.

导电油墨印制元器件 **52.1600**
用导电油墨形成的并成为印制电路图形一部分的元器件（如印制电感、电阻、电容或传输线等）。

Printed Contact **22.0915**
A portion of a conductive pattern that serves as one part of a contact system.

印制接触片 **22.0915**
作为接触件系统的一部分而形成的部分导电图形。

Printed Edge-Board Contact **22.0916**
See “Edge-Board Contact.”

印制板边接触片 **22.0916**
见“板边接触片，Edge-Board Contact”。

Printed Wiring **60.1488**
A conductive pattern that provides point-to-point connections but not printed components in a predetermined arrangement on a common base. (See also “Printed Circuit.”)

印制线路 **60.1488**
在公共基材上，按预定的布局提供点到点连接但没有印制元器件的导电图形。（又见“印制电路，Printed Circuit”。）

Printed Wiring Board **60.1489**
A printed board that provides point-to-point connections but not printed components in a predetermined arrangement on a common base. (See also “Printed Circuit Board.”)

印制线路板 **60.1489**
在公共基材上，按预定的布局提供点到点连接但没有印制元器件的印制板。（又见“印制电路板，Printed Circuit board”）

Printed Wiring Board Assembly **80.0917**
An assembly that uses a printed wiring board for component mounting and interconnecting purposes.

印制线路板组件 **80.0917**
采用印制线路板实现元器件安装和互连的组件。

Printing **52.1592**
Act of reproducing a pattern on a surface by any process.

印制 **52.1592**
采用任何工艺在表面上复制图形的动作。

Probe Point **92.0919**

The predetermined location on a printed board where electrical contact can be made to exposed circuitry for electrical diagnostic purposes.

探针测试点 **92.0919**

在线路板上预先设计的裸露的电气接触点，被用来检测电气性能。

Probe, Test **92.0918**

A spring-loaded metal device used to make electrical contact between test equipment and the unit under test.

测试探针 **92.0918**

在测试设备与待测单元之间起到电气连接作用的带弹簧金属零件。

Process Average **91.0920**

The location of the distribution of measured values of a particular process characteristic.

过程平均 **91.0920**

特殊过程特性测量值的分布位置。

Process Indicator **91.0921**

A detectable anomaly, other than a defect, that is reflective of material, equipment, personnel, process and/or workmanship variation.

制程警示 **91.0921**

可检测出的反映材料、设备、人员、工艺和/或工艺变异的异常，但不是缺陷。

Process Spread **91.0922**

The extent to which the individual values of a process may vary.

制程散布 **91.0922**

制程的单个值可能变化的范围。

Processability **70.1763**

Suitable and capable of being processed.

可加工性 **70.1763**

适合及能够被加工。

Producer's Risk **93.0923**

See "Alpha Error."

生产方风险 **93.0923**

见"α错误，Alpha Error"。

Production Board **60.1490**

A printed board or discrete-wiring board that has been manufactured in accordance with the applicable detailed drawings, specifications, and procurement requirements.

成品板 **60.1490**

按照适用的详细图纸、规范及采购要求制造出来的印制板或分立线路板。

Production Data **94.1988**

Normal performance data from manufacturing runs generated as a quality assurance function. This data can be compiled, analyzed, and reported as support for product compliance to a standard by the manufacturer.

生产数据 **94.1988**

制造过程中所生成的正常性能数据，可以起到保证质量的作用。可对这些数据进行编辑、分析并报告，作为制造商产品与标准一致性的支持依据。

Production Master **24.1642**

A 1:1 scale pattern that is used to produce rigid or flexible printed boards within the accuracy specified on the master drawing. (See also "Multiple-Image Production Master" and "Single Image Production Master.")

生产底版 **24.1642**

1:1比例的图形，可用于按照布设主图规定精度生产刚性或挠性印制板。（又见"多重图像生产底版，Multi-Image Production Master"，"单个图像生产底版，Single Image Production Master"。）

Production Panel (PP) **50.1787**

An arrangement of printed boards fabricated from laminate or base materials as a group in a specific cluster to facilitate economic fabrication techniques using controlled and documented chemical, mechanical and electrical processes.

生产拼版（PP） **50.1787**

为了便于经济生产，采用受控和文档化的化学、机械的和电子工艺，用层压板或基材制作的一组特定印制板的排列。

Production Printed Board (PPB) **50.1786**

A printed board fabricated from laminate or base materials in an environment that consists of controlled and documented chemical, mechanical and electrical processes used in combination to produce the features and characteristics of the final printed board product.

成品印制板（PPB） **50.1786**

用层压板或基材在受控的、文档化的、可生产出最终印制板产品的性能和特性的化学、机械和电气工艺相结合的条件下制作出的印制板。

Proficiency **91.1989**

The capability to perform tasks in accordance with requirements and verification procedures.

熟练程度 **91.1989**

按照要求和验证工艺规程完成任务的能力。

Profile Factor **92.1492**

The amount by which the overall average thickness of a metal exceeds the thickness that is calculated from the established density of the metal and the area of the sample.

外形因素 **92.1492**

金属的总平均厚度超出根据已知（公认）金属密度以及样本面积计算而得厚度的数量。

Propagation Delay **21.1493**

The time from output to input required for a signal to travel along a transmission line, or the time required for a logic device to receive an input stimulus, perform its function, and present a signal at its output.

传输延迟 **21.1493**

信号延传输线从输出到输入所需要的时间，或指一个逻辑器件从接收到一个输入脉冲、完成其功能、到输出一个信号所需要的时间。

Proportional Dimensions **92.0924**

The distortion of an optical system used in a magnification device.

比例尺寸 **92.0924**

用于放大装置中的光学系统变形。

Protective Isolation Coating **47.2181**

Adhesive material having a known dielectric used to insulate conductors.

保护性绝缘涂层 **47.2181**

含有已知介质的粘性材料，用于隔离导体。

Protrusion of Conductor **96.1990**

See “Conductor Protrusion.”

导体突出 **96.1990**

见“导体突出，Conductor Protrusion”。

Pull Strength **92.0925**

See “Bond Strength.”

拉拔强度 **92.0925**

见“粘合强度，Bond Strength”。

Pull-off Strength (SMD) **97.1991**

The force required to remove a surface mount device (SMD) mounted on a printed board by the application of a force that is perpendicular and away from the surface upon which it is mounted.

拉离强度（SMD） **97.1991**

去除贴装在印制板上的一个表面贴装器件（SMD）时所需的垂直于器件贴装表面的力。

Pull-Out Strength **97.1816**

The force, normal to the printed board, required to separate the metallic wall of a plated-through hole from the base material.

拉出强度 **97.1816**

使镀覆孔金属层与基材分离所需的垂直于印制板的力。

Pulse, Digital **21.1494**

A logic signal that switches from one digital state to the other and back again in a short period of time, and that remains in the original state for most of the time.

数字脉冲 **21.1494**

在较短期间内从一种数字状态转换到另一种状态并在短时间内又返回的逻辑信号，在大多数时间都处于初始态。

Pulse Soldering **75.0926**

Soldering by the heat generated by pulsing an electrical current through a high resistance point of the joint area and the solder.

脉冲焊接 **75.0926**

由脉冲电流通过连接区域和焊料所组成的高电阻点产生热所进行的焊接。

Punching **51.1992**

Formation of a hole, a slot, or a finished board by use of a female die and a male punch.

冲压 **51.1992**

采用冲模和冲头形成孔、槽或成品板。

Push Back **51.1993**

The process of returning the printed board or printed board assembly that has been remove from the panel, back into its original position.

复位 **51.1993**

将已从在制板上裁下的印制板或印制板组件放回到原始位置的过程。

Push-Off Strength **97.0928**

The force required to dislodge a leadless component by the application of a force that is parallel to the surface upon which it is mounted.

推离强度 **97.0928**

移去无引线元器件所需的平行于元器件贴装表面的力。

Q

QFP with Bumper (BQFP) **33.1835**

A QFP package with a guarding bumper.

带护耳的QFP（BQFP） **33.1835**

带有护耳的QFP封装。

Quad Flat J-Lead (QFJ) **33.2156**

A generic rectangular component package, containing an electronic device, with leads on all four sides that are formed in a “J” shape.

矩形扁平J形引线封装（QFJ） **33.2156**

含有电子器件且引线在封装体四周成形为“J”形的矩形元器件封装。

Quad Flat No-Lead (QFN) **33.2157**

A generic rectangular component package outline wherein the metal pad terminations are formed on four sides of the bottom of a package.

矩形扁平无引线封装（QFN） **33.2157**

金属连接盘端子成形于封装体底部四周的矩形元器件封装。

Quad Flat Pack (QFP) **33.1836**

A generic rectangular component package, containing an electronic device, with leads on all four sides that are formed in a “gullwing” shape.

方形扁平封装（QFP） **33.1836**

含有电子器件且在封装体四周形成鸥翼形引线的矩形元器件封装。

Qualification Agency **94.1212**

The organization that is used to perform documentation reviews and audits of an inspection or testing facility.

鉴定机构 **94.1212**

对有关文件进行评审、对一项检验或测试设备进行审核的组织。

Qualification Testing **94.1213**

The demonstration of the ability to meet all of the requirements specified for a product.

鉴定测试 **94.1213**

实证产品能满足所有规定要求的能力测试。

Qualitative Analysis **92.1214**

The subdivision of chemistry concerned with the identification of materials.

定性分析 **92.1214**

与材料鉴别有关的化学分支。

Quality Conformance Testing **94.1496**

Qualification testing that is performed on a regularly-scheduled basis in order to demonstrate the continued ability of a product to meet all of the quality requirements specified.

质量一致性测试 **94.1496**

为了证明一个产品能满足所有规定质量要求的连续能力，而定期进行的质量鉴定测试。

Quality-Conformance Test Circuitry **92.1495**

A portion of a printed board panel that contains a complete set of test coupons that are used to determine the acceptability of the board(s) on the panel.

质量符合性测试电路 **92.1495**

在制板内含有的一套完整的测试附连板部分，用来确定在制板内印制板质量的可接受性。

Quality System **90.1913**

A set of interrelated or interacting quality elements within an organization’s operations.

质量体系 **90.1913**

一个组织运行中的一套相关或相互影响的质量要素。

Quality Management System **94.2177**

A management system which directs an organization in regards to quality.

质量管理体系 **94.2177**

指导一个组织有关质量方面的管理体系。

Quantitative Analysis **92.1215**

Chemical determination of the composition of mixtures or the constituents of a pure compound without regard to quantity.

定量分析 **92.1215**
化学测定合成物或纯化合物的成份，但不考虑其含量。

Quartz Fiber (Electrical Grade) **44.1994**
Quartz yarn or fiber, which is to be used to develop the reinforcment for printed board applications.

石英纤维（电子级） **44.1994**
用于增加印制板增强材料强度的石英纱或石英纤维。

Quasi-Interfacial Connection **22.1216**
See “Interfacial Connection.”

准界面连接 **22.1216**
见“面间连接，Interfacial Connection”。

Quasi-Interfacial Plated-Through Hole **22.1201**
See “Nonfunctional Interfacial Connection.”

准界面镀覆孔 **22.1201**
见“非功能面间连接，Nonfunctional Interfacial Connection”。

Quiet Zone (Bar Code) **70.1996**
In a bar code symbol, the area that contains no markings, immediately preceding the start character and following the stop character.

空白区（条码） **70.1996**
条形码符号中不包含标识的区域，其直接位于起始符之前并紧接在终止符之后。

Quill **44.1202**
A bobbin onto which filling yarns are wound.

线轴 **44.1202**
缠绕纱线的主轴。

R

Radial Lead Component **31.1997**
A component where the leads are located on the bottom, radially and parallel to the central axis.

径向引线元器件 **31.1997**
引线位于元器件本体底部，并与中轴线平行呈放射状排列的元器件。

Radiant Flux **56.1304**
The amount of power that is incident on a surface, expressed in watts.

辐射通量 **56.1304**
入射在表面上的能量的总和，用瓦特表示。

Radiant Intensity **56.1305**
The amount of power from a point source that is generated through a solid angle, measured in watts per steradian.

辐射强度 **56.1305**
通过多面角上的一个点光源所产生的动力，按瓦特/球面度计算。

Radiation, Infrared **21.1998**
Thermal radiation emitted in the infrared region of the electromagnetic spectrum.

红外辐射 **21.1998**
电磁频谱中红外区内发射出的热辐射。

Radiation, Long Wave, Infrared **21.1999**
Infrared energy that is radiated at a wavelength that is between 5 and 100 microns.

长波红外线辐射 **21.1999**
在5微米至100微米之间的波长下辐射的红外能。

Radiation, Medium Wave Infrared **21.2000**
Infrared energy that is radiated at a wavelength that is between 2.5 and 5 microns.

中波红外线辐射 **21.2000**
在2.5微米至5微米之间的波长下辐射的红外能。

Radiation, Near Infrared **21.2001**
See “Radiation, Short Wave Infrared.”

近红外线辐射线 **21.2001**
见“短波红外线辐射，Radiation, Short Wave Infrared”。

Radiation, Re-emitted Infrared **21.2003**
That portion of thermal energy absorbed by a media that is in turn emitted in the infrared portion of the electromagnetic spectrum.

红外再辐射 **21.2003**
被介质吸收的一部分热能再通过电磁波频谱红外部分辐射出来。

Radiation, Short Wave Infrared **21.2004**
Infrared energy that is radiated at a wave length that is between 0.78 and 2.5 microns.

短波红外线辐射 **21.2004**
在0.78微米至2.5微米之间的波长下辐射的红外能。

Radiator, Focused **56.1306**

A reflector that is incorporated in the back of an emitter for the purpose of concentrating energy to produce a point or line of heat.

聚焦辐射器 **56.1306**

安装在发射器后部的一种反射装置，目的是为了将能量聚集到一起以产生点热源或线热源。

Radiator, Nonfocused **56.1307**

A diffusing reflector that is incorporated in the back of an emitter for the purpose of scattering energy over an area.

非聚焦反射器 **56.1307**

安放在发射器后部的一种弥散反射装置，目的是为了将能量扩散到整个区域。

Radiometry **24.1308**

The measurement of radiation in the optical spectrum. (This includes infrared (IR), ultraviolet (UV), and visible.)

辐射线测定 **24.1308**

对光谱辐射线的量度。（包括红外线、紫外线及可见光线。）

Random Sample **91.1311**

A set of individuals that is taken from a population in such a way that each possible individual in the population has an equal chance of being selected.

随机样本 **91.1311**

以使总数中的每一独立个体被选中的机会均等的方式从总数中任意选取的一组个体。

Random-Effects Model **91.1497**

A specific experimental treatment whereby a random sample is taken from a large population of treatments in such a manner that the conclusions reached can be extended to the entire population and the inferences are not restricted to the experimental levels.

随机效应模式 **91.1497**

一种特殊的试验处理方式，它从大量的处理总体中随机抽取样本，得出的处理结论可扩展至全体对象，且推论不局限于试验水平。

Randomization **91.1309**

The random selection of experimental runs in order to minimize biases that are due to unknown or uncontrollable factors in an experimental design.

随机选择 **91.1309**

由于试验设计中具有不可知或不可控因素，因此试验时需任意选择试验对象，以便将试验结果之间的差异降到最低限度。

Randomness **91.1310**

A situation in which any individual event has the same mathematical probability of occurring as does all of the other events within the set of events.

随机性 **91.1310**

任何一项单独事件的发生具有与一个系列事件中的所有其它事件的发生相同数学概率的一种情况。

Rebond **74.1312**

A termination made at, on top of, or adjacent to, the location of a prior bond.

再键合 **74.1312**

在前一个键合位置的顶部或相邻处实现的又一个端接点。

Receptacle Connector **37.1313**

The fixed or stationary half of a two-piece connector pair that mates with a plug connector.

插座式连接器 **37.1313**

可与插入式连接器配接的两件式连接器中固定的连接器。

Reciprocity Failure **91.1314**

The deviation from the Reciprocity Law.

互易失效 **91.1314**

与互易定律相偏离。

Reciprocity Law **91.1498**

A general law that pertains to photo-chemical reactions that states the mass of photoproduct from such a reaction is determined simply by the total exposure involved.

互易定律 **91.1498**

关于光化学反应的一个通用定律，即光化反应物的总量仅仅由总曝光量所决定。

Rectangular Leads **36.1764**

A lead form or leg shape whose cross section is rectangular in shape.

矩形引线 **36.1764**

截面为矩形的引线形式或引腿形状。

Reduction Marks **22.1316**
A set of stylized patterns in the border area of an artwork between which the photographic-reduction dimension is defined.

缩图标志 **22.1316**
在底片的边界区域内用来确定照相缩小尺寸的一组固定图形。

Reed **44.1230**
A thin comb made of pressed steel wires between which warp ends are drawn after passing through the needle eyes.

钢筘 **44.1230**
由模压钢丝制成的薄形梳形装置，经纱在穿过针眼后抽过其间。

Reference Dimension **26.1231**
A dimension without a tolerance that is used only for informational purposes that does not govern inspection or other manufacturing operations.

参考尺寸 **26.1231**
仅用于说明情况而不是用来指导检验或其它生产操作的无公差尺寸。

Reference Edge **22.1232**
The edge of a cable or conductor from which measurements are made.

基准边 **22.1232**
用作测量的电缆或导体边。

Reference Hole **22.1233**
See “Tooling Hole.”

基准孔 **22.1233**
见“定位孔，Tooling Hole”。

Reference Master **24.1234**
Artwork that is free of defects.

基准底图 **24.1234**
没有缺陷的照相底图。

Reflection, Signal Propagation **21.1499**
The fraction of a propagating signal that is reflected back toward its source after the signal has encountered a discontinuity in the electrical impedance of the transmission line on which it is traveling.

信号传播反射 **21.1499**
传播信号由于在传输线上传送时遇到电气阻抗的骤变，又反射回信号源的一小部分传播信号。

Reflection Coefficient **21.2005**
The percentage of power (or voltage) reflected from a load that is attached to a circuit or transmission line.

反射系数 **21.2005**
附加到电路或传输线的负载的反射功率（或电压）的百分比。

Reflectivity **21.2006**
The percentage of incident infrared energy that reflects from the surface. (See “Transmissivity.”)

反射率 **21.2006**
从表面反射回的入射红外能百分比。（又见“透射率，Transmissivity”。）

Reflow Soldering **75.1500**
The joining of surfaces that have been tinned and/or have solder between them, placing them together, heating them until the solder flows, and allowing the surface and the solder to cool in the joined position.

再流焊接 **75.1500**
将已经上锡或其间已有焊料的表面放在一起，将其加热直到焊料流动，再使连接处的表面和焊料冷却，而形成的连接。

Reflow Soldering (Nitrogen Process) **75.1933**
A reflow soldering process, carried out in a nitrogen atmosphere, intended to retard oxidation of solder and board conductive surfaces and improve solder wetting.

再流焊接（氮气工艺） **75.1933**
在氮气环境下进行的再流焊接工艺，目的在于阻止焊料和板导电表面的氧化并促进焊料的润湿。

Reflow Spike **75.1235**
The portion of the reflow soldering process during which the temperature of the solder is raised to a value that is sufficient to cause the solder to melt.

再流焊峰值 **75.1235**
再流焊工艺中的一部分，在该过程中焊料的温度升至足以使焊料熔融的温度值。

Reflow Temperature **75.2007**
The temperature range of a reflow soldering process during which the solder is in its liquidus phase.

再流温度 **75.2007**
再流焊接过程中使焊料保持液相状态时的温度范围。

Regardless of Feature Size **22.1236**

A geometric tolerance or datum reference that applies at any increment of size of a feature that is within its size tolerance.

要素尺寸无关 **22.1236**

一个要素尺寸，在其几何公差或基准参考尺寸范围内，任意增量均适用。

Registered Production Master **24.1237**

A production master that incorporates physical registration features.

带定位生产底版 **24.1237**

包含物理定位要素的生产底版。

Registration **50.1240**

The degree of conformity of the position of a pattern (or portion thereof), a hole, or other feature to its intended position on a product.

重合度 **50.1240**

产品上的图形（或部分图形）、孔或其它要素的实际位置与其指定位置一致性的程度。

Registration Mark **22.1315**

A stylized pattern (symbol) that is used as a reference point for registration.

重合标记 **22.1315**

用作重合基准点的固定图形（符号）。

Regression Analysis **91.1241**

The use of statistics to investigate and model the relationships between parameters and results.

回归分析 **91.1241**

用于研究和模拟参数与结果之间关系的统计方法。

Relative Permittivity (ε_r) **21.2008**

The ratio of the permittivity of a material to that of free space.

相对电容率（ε_r） **21.2008**

一种材料的电容率与真空介质的电容率之比。

Release Liner (Pressure Sensitive Tape) **75.2009**

A web or sheet of material covering the adhesive side of a pressure sensitive tape.

释放隔离衬（压力敏感带） **75.2009**

覆盖压力敏感带粘合剂面的一层网状或片状材料。

Reliability **90.1501**

The probability that a component, device, or assembly will function properly for a definite period of time under the influence of specific environmental and operational conditions.

可靠性 **90.1501**

指元器件、器件或组装件在特定的环境及作业条件影响下，在规定的时间周期内进行正常运行的概率。

Re-melting Separation **75.2010**

The phenomenon in which solder on the previously soldered surface is re-melted by the heat being applied for soldering on the opposite side, causing separation of the solder and a component termination, or between the solder and a land (pad).

再熔融分离 **75.2010**

当对已焊接表面的反面进行焊接时，由于所施加的热量使之前已焊接表面的焊料再次熔融，从而造成焊料与元器件引出端，或焊料与连接盘分离的现象。

Removable Contact **37.1242**

A type of connector contact that is not permanently retained within the connector body or insert.

可移动接触件 **37.1242**

非永久保留在连接器本体或嵌入物内的连接器接触件。

Render True Color **24.1243**

The color aberrations of an optical system that have been sufficiently corrected so as to allow a magnification device to resolve the required details.

呈现真色度 **24.1243**

已经充分校整的光学系统色度偏差，以使放大装置能够分辨所要求的细节。

Repair **77.1502**

The act of restoring the functional capability of a defective article. In common usage, repair may restore the hardware to compliance with applicable drawing or specifications. In stringent [military] usage, rework is in compliance whereas repair restores functionality without being in compliance.

维修 **77.1502**

使有缺陷产品功能恢复的行为。一般情况下维修可恢复硬件，使其符合所适用的图纸或技术规范。严格[军用]情况下，返工能够符合其要求，但维修只可恢复其功能，却不符合其要求。

Repeat Set-Up Time **92.1244**

The set-up time for a unit that is identical to one previously evaluated.

重复设置时间 **92.1244**

使一个单元与之前评定的单元完全相同所需的设置时间。

Repeatability (Accept/Reject) Decisions **91.1503**

The percentage of features that show the same acceptance or rejection status on a minimum of three consecutive tests using identical operating modes and conditions in a statistically-significant random sampling of three units.

重复性（接受/拒绝）判定 **91.1503**

在抽取三个单元的统计有效随机抽样中，使用相同的操作方式及条件，在至少三个连续测试中显示相同的接收或拒收状态的性能百分比率。

Residue **76.1245**

Any visual or measurable form of process-related contamination.

残留物 **76.1245**

任何直观的、或可检测的与工艺相关的污染物。

Resin **40.1246**

A natural or synthetic resinous material. (See also “Rosin” and “Synthetic Resin.”)

树脂 **40.1246**

天然或合成的树脂类材料。（又见“Rosin，松香”和“Synthetic Resin，合成树脂”。）

Resin Flux **75.1247**

A resin and small amounts of organic activators in an organic solvent.

树脂助焊剂 **75.1247**

含有树脂和少量有机活性剂的有机溶剂。

Resin Particle (Base Material) **44.1985**

An inclusion that is normally amber to brown and slightly translucent, composed of a particle of nonindigenous and previously dried or cured resin that may appear similar to “treater dirt” which tends to be less translucent, darker and chunkier.

树脂颗粒（基材） **44.1985**

混入树脂中的已经干燥或凝固的树脂颗粒，通常呈琥珀色至褐色和半透明状，看上去与浸润污物相似，只是更暗、更小，也不那么透明。

Resin Recession **60.1504**

The presence of voids between the plating of a plated-through hole and the wall of the hole as seen in microsections of plated-through holes that have been exposed to high temperatures. (See Figure R-1.)

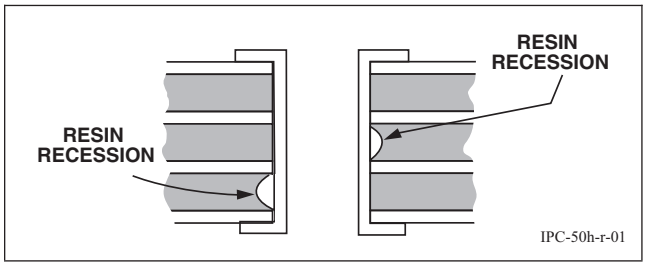
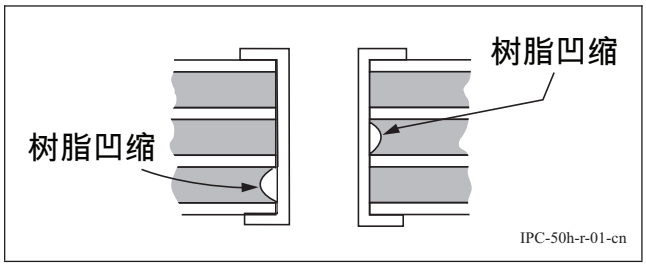


Figure R-1 Resin Recession

树脂凹缩 **60.1504**

镀覆孔镀层与孔壁之间存在的空洞，可从经受高温后的镀覆孔显微切片中观察到这种现象。（见图R-1。）



图R-1 树脂凹缩

Resin Smear **51.1506**

Base material resin that covers the exposed edge of conductive material in the wall of a drilled hole. (This resin transfer is usually caused by the drilling operation.)

树脂钻污 **51.1506**

覆盖在钻孔孔壁裸露的导电材料表面的基材树脂。（这种树脂转移通常是由钻孔操作造成的。）

Resin-Rich Area **41.1505**

The location in a printed board of a significant thickness of unreinforced surface-layer resin that is of the same composition as the resin within the base material.

富树脂区 **41.1505**

印制板中有显著厚度而无增强材料的表面树脂层区域，该区域的树脂成份与基材内部的树脂相同。

Resin-Starved Area **41.1507**

The location in a printed board that does not have a sufficient amount of resin to completely wet out the reinforcing material. (Evidence of this condition is often in the form of low-gloss dry spots or exposed fibers.)

缺树脂区 **41.1507**
印制板中因树脂含量不足，未能完全浸润增强材料的某些区域。（这种状况通常表现为无光泽的干裂斑点或露纤维）。

Resist (Mask) **52.1508**
See “Mask.”

阻焊剂（膜） **52.1508**
见“掩膜，Mask”。

Resistance **21.1805**
The restriction to the flow of electrons, determined by Ohms law; the quotient of DC voltage, applied to the extremes of a conductor or insulator, and the current flowing through it.

电阻 **21.1805**
由欧姆定律确定的对电子流动的限制，等于施加在导体或绝缘体两端的直流电压除以通过导体的或绝缘体的电流的商。

Resistance Soldering **75.1248**
Soldering by a combination of pressure and heat generated by passing a high current through two mechanically-joined conductors.

电阻钎焊 **75.1248**
通过流经两个机械连接导体的高电流所产生的热及施加压力而进行的钎焊。

Resistance to Solvents **76.2012**
The ability of the base laminate and other materials to resist damage to the material when exposed to solvents.

耐溶剂性 **76.2012**
基材层压板及其它材料暴露于溶剂中时，抵抗材料被损坏的能力。

Resistance Welding **75.1249**
Welding by a combination of pressure and heat generated by passing a high current through two mechanically-joined conductors.

电阻熔焊 **75.1249**
通过流经两个机械连接导体的高电流所产生的热及施加压力而进行的熔焊。

Resistive Clad Laminate **45.2013**
A clad laminate containing resistive material that is used in making planar resistors.

电阻覆金属箔层压板 **45.2013**
含有用于制作平面电阻的电阻材料的覆金属箔层压板。

Resistor Drift **92.1250**
The change in resistance of a resistor caused by aging, usually expressed as a percent change per 1,000 hours.

电阻漂移 **92.1250**
由于电阻老化造成的阻抗变化，通常用每1000个小时的变动百分率来表示。

Resolving Power **24.1509**
The ability of a photographic system to maintain the separate identity of parallel lines and spaces in a developed image when their relative displacement is small.

解像力 **24.1509**
图像显影中平行线条及其间隔相对位移较小时，照相系统保持其分离、可识别的能力。

Response Variable **91.1251**
The dependent variable being studied.

响应变量 **91.1251**
分析中的应变量。

Return Loss **21.2014**
Level of the reflected signal which is a result of a mismatch between a load and a source. It is usually expressed as the ratio of reflected power to incident power in dB units.

回波损耗 **21.2014**
当负载与信号源不匹配时所产生的反射信号的强弱。通常以反射能量与入射能量的比值来表示，以dB为单位。

Reversal Development **24.1252**
The reversing of the tone of an image on a photographic emulsion from that which can be accomplished with conventional developing.

反转显影 **24.1252**
为感光乳剂上的图像直接翻制成正像而采取的显影。

Reverse Current Cleaning **76.1253**
See “Anodic Cleaning.”

反向电流清洗 **76.1253**
见“阳极清洗，Anodic Cleaning”。

Reverse Etch back **54.2015**
See “Negative Etch back.”

反向凹蚀 **54.2015**
见“负凹蚀，Negative Etchback”。

Reverse-Treated Core **41.2016**

A core (inner layer) whereby the copper foil is laminated to the base material with the drum side down.

反向处理芯板 **41.2016**

铜箔鼓面朝下层压到基材上的芯板（内层）。

Reverse-Treated Foil (RTF) **45.2017**

Metal foil on which the drum or smooth side has been chemically treated to make the surface rougher for increased adhesion to bonded surfaces

反向处理金属箔（RTF） **45.2017**

对金属箔的鼓面或光滑面进行化学处理，使其表面更粗糙，增加与所粘接表面的粘附力。

Reverse Image **52.1254**

The pattern of resist on a printed board that is used to allow for the exposure of conductive areas for subsequent plating.

负像 **52.1254**

印刷板上用来使导电区域暴露出来进行后续电镀的抗蚀剂图形。

Reversion **96.1510**

A chemical reaction in which a polymerized material partially or completely degenerates to a lower polymeric state or to the original monomer. (This is usually accompanied by significant changes in physical and mechanical properties.)

裂解 **96.1510**

聚合后的材料部分地或完全地退化到更低的聚合态或原始单体状态的化学反应。（通常伴随有明显的物理和机械特性变化。）

Rework **77.1511**

The act of reprocessing noncomplying articles, through the use of original or alternate equivalent processing, in a manner that assures compliance of the article with applicable drawings or specifications.

返工 **77.1511**

通过使用原工艺或替代的等效工艺，确保不合格产品符合适用图纸或技术规范的再加工。

Rheology **40.2018**

The study of the change in form and flow of matter, generally characterized by elasticity, viscosity, and plasticity.

流变学 **40.2018**

对具有弹性、粘性和塑性特点物质的流动及形式变化的研究。

Ribbon Cable **37.1255**

A flat cable with round conductors.

带状电缆 **37.1255**

导体为圆形的扁平电缆。

Ribbon Interconnect **37.1256**

A flat narrow ribbon of metal used to make interconnections to lands, lead frames, etc.

带状互连 **37.1256**

用于互连连接盘、引线框架等的扁平窄金属带。

Right Reading **24.1257**

A photo tool pattern-orientation that is the same as the artwork master when it is viewed from the primary side of a product. (See Figure M-4 and Figure R-2.)

右读 **24.1257**

从产品的主面观察时，与照相原版方向相同的底片图形方向。（见图M-4和R-2。）

Right Reading Down **24.1512**

An orientation of a phototool in which the pattern is right and the emulsion is on the surface that is away from the viewing surface. (See Figure M-4 and Figure R-2.)

右读朝下 **24.1512**

图形为右读、而乳胶面是背向观察面的底片方向。（见图M-4和R-2。）

Right Reading Up **24.1513**

An orientation of a phototool in which the pattern is right reading and the emulsion is on the surface that is toward the viewing surface. (See Figure M-4 and Figure R-2.)

右读朝上 **24.1513**

图形为右读、而乳胶面是朝向观察面的底片方向。（见图M-4和R-2。）

Rigid Double-Sided Printed Board **61.1577**

Double-sided printed board, either printed circuit or printed wiring, using rigid base materials only.

刚性双面印制板 **61.1577**

采用刚性基材制作的双面印制电路板或印制线路板。

Rigid Multilayer Printed Board **61.1578**

Multilayer printed board, either printed circuit or printed wiring, using rigid base materials only.

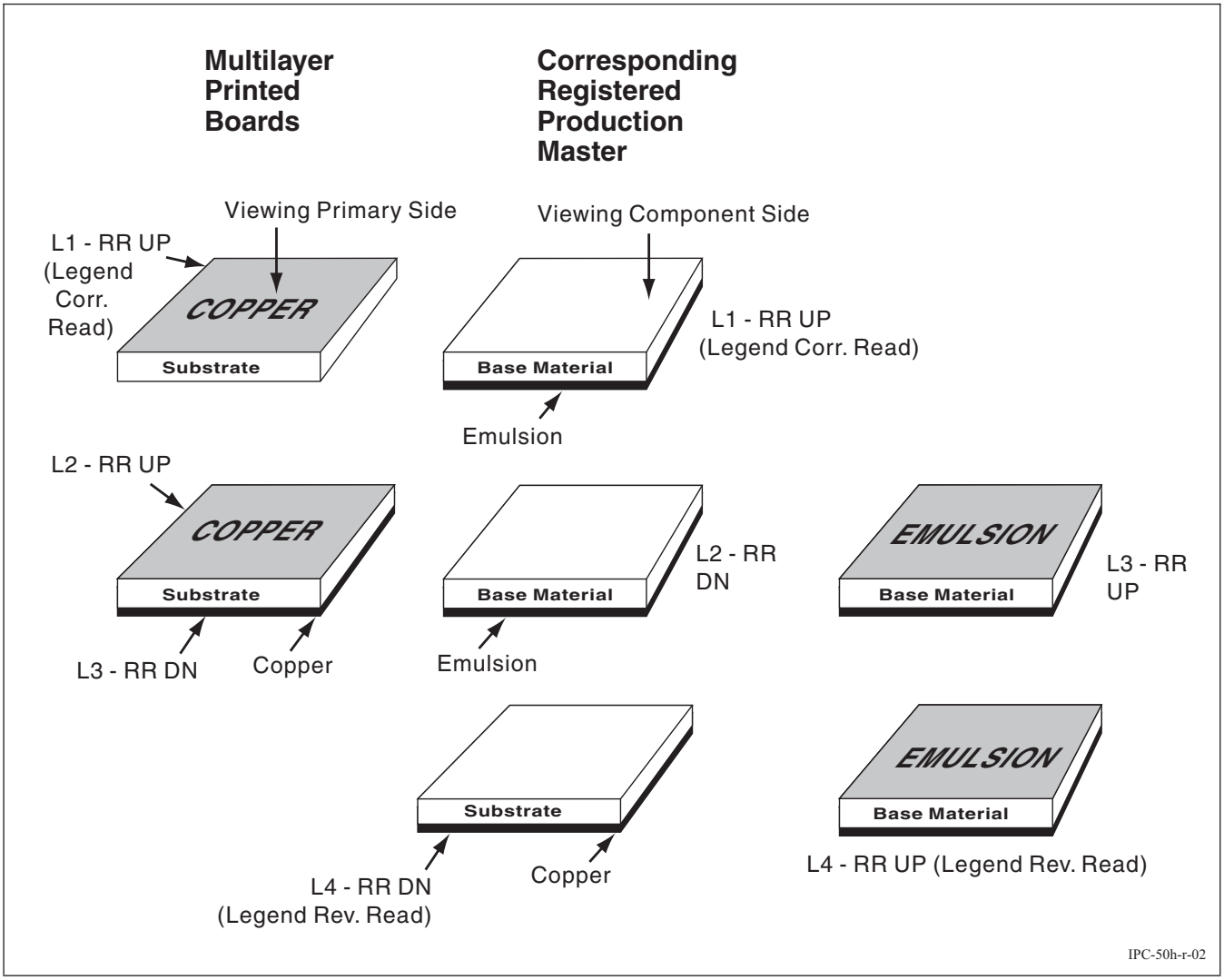
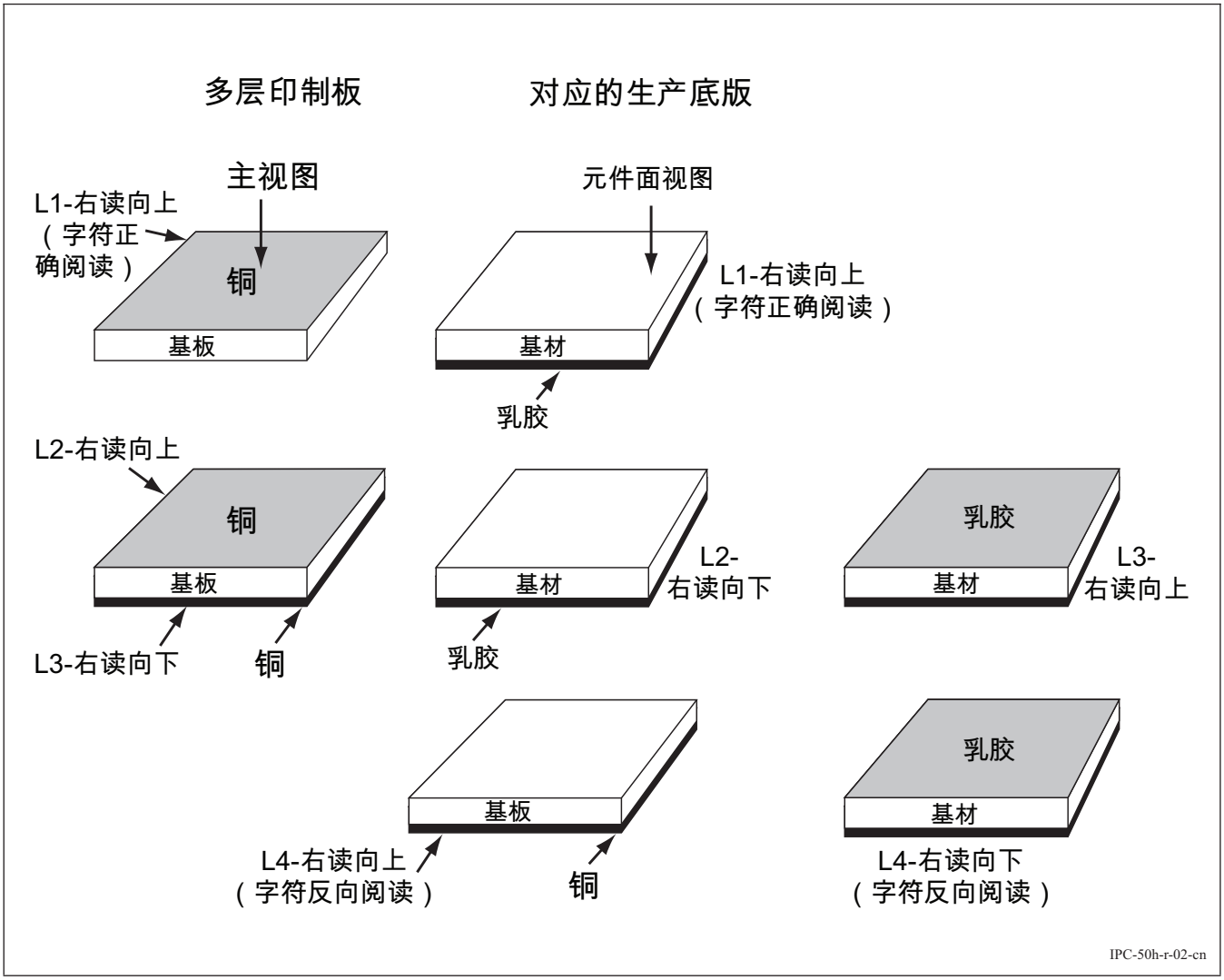


Figure R-2 Printed Board Viewing Orientations

Notes:

1. A precise definition of image tone and orientation necessitates that the orientation of the pattern and the legend be separately identified. For example: Layer 1-Pos RR DN (Legend Corr. Read) or Layer 2-Pos RR UP (Legend Rev. Read) (There is no such thing as wrong reading.)
2. By definition, all layer patterns are viewed from the same direction. (This view defines RR for the pattern appearance of all layers; this is not the same as viewing the final board copper head on.)
3. Legend is usually correct reading when viewing the copper; therefore, on occasion alphanumerics must be reversed reading when the pattern is right reading by definition.
4. Production master emulsion must be presented against the board copper in the stack up. Therefore, production master emulsion orientation is opposite to individual copper layer orientation, i.e., if copper is RR UP by definition, corresponding production master must be RR DN.
5. When specifying artwork tone and orientation, remember the board layup and the purpose of the artwork, i.e., file copy, artwork master, or production master, etc.
6. In manual designs the artwork is usually prepared at an enlarged scale with tapes and other drafting aids. The artwork master is produced from the artwork by photographic reduction.
7. In semiautomated designs, there may be no artwork by definition. Typically, an enlarged color-coded printed wiring layout on a gridded format is prepared for subsequent digitizing and photoplotting. This procedure may yield intermediate phototools which can be photographically processed into an artwork master or it may directly yield an artwork master, working master, or production master.
8. In fully automated systems, there is usually no artwork or printed wiring layout prepared. A computerized procedure from a form of the electrical schematic by total computerization or a combination of computer and interactive design procedures is prepared. This procedure may yield intermediate phototools or the artwork master, working master, or production master directly.



图R-2 印制板视图方向

注：

1. 图像品质和方向的精确确定需要分别规定图形和字符的方向。例如：第一层-右读向下（字符正确阅读）或第二层-右读向上（字符反向阅读）（错误阅读时不会出现这种情况）。
2. 定右读方向后，从同一个方向观察识别所有层次的图形。（该图确定了所有图层图形外表的右读，但它与最终铜面图形的迎面识别读法不同）。
3. 从铜面看时字符通常都可被正确阅读，因此根据规定右读图形时，有时必须反向阅读字符和数字。
4. 层中生产底版乳胶必须紧贴板的铜面。因此生产底版的乳胶方向和对应的铜面方向相对，比如规定铜层为右读向上时，对应的生产底版乳胶的方向必须是右读向下。
5. 定了照相底图方向和品质时，切记板的叠层和照相底图的用途，如文件拷贝、照相原版或生产底版等。
6. 手动设计时，会采用卷尺等其他草图设计工具对尺寸进行预放来准备照相底图。照相原版是由照相缩版照相底图得到的。
7. 半自动设计时，一般没有规定的照相底图。典型的，以网格模式上布设已扩大尺寸的彩色编码的印制线路为后期的数字化和绘图作准备。这个过程可产生中间底版，而该底版可通过照相方式加工成为照相原版、或直接产生照相原版、工作原版和生产底版。
8. 在全自动系统中，一般不需要准备照相底图和进行印制线路布线。通过完全由计算机处理的电气原理图方式或计算机和交互设计程序结合的方式形成计算机化的过程。该过程可直接产生中间底版、或照相原版、工作原版，或生产底版。

刚性多层印制板 **61.1578**
只采用刚性基材制作的多层印制电路板或多层印制线路板。

Rigid Printed Board **61.1571**
A printed board using rigid base materials only.

刚性印制板 **61.1571**
只采用刚性基材制作的印制板。

Rigid Single-Sided Printed Board **61.1576**
Single-sided printed board, either printed circuit or printed wiring, using rigid base materials only.

刚性单面印制板 **61.1576**
只采用刚性基材制作的单面印制电路板或印制线路板。

Rigid-Flex Double-Sided Printed Board **63.1584**
Double-sided printed board, either printed circuit or printed wiring, using combinations of rigid and flexible base materials.

刚挠性双面印制板 **63.1584**
采用刚性和挠性基材制作的双面印制电路板或印制线路板。

Rigid-Flex Printed Board **63.1258**
A printed board with both rigid and flexible base materials.

刚挠性印制板 **63.1258**
采用刚性与挠性两种基材制作的印制板。

Rise Time (Transition Duration) **21.1259**
The time required for a logic-signal voltage to switch from 10 to 90 percent of the difference between logic states.

上升时间（过渡时间） **21.1259**
逻辑状态转换时，逻辑信号电压从状态差数的10%上升（转换）到90%所需要的时间。

Risk Management Factor (RMF) **94.1777**
The maximum tolerable percentage of possible defects within a lot (group) of units, based on approximately 95% confidence level.

风险管理因子 **94.1777**
在约95%的置信度的基础上，一批产品可能存在缺陷的最大容许百分比。

Roadmap **26.1260**
A printed nonconductive pattern that delineates the components and circuitry on a printed board in order to aid in servicing and repairing the final assembly.

标识图 **26.1260**
印制板上示意元器件和电路的非导电图形，有助于成品组件的维修及返修。

Robber **53.1261**
See “Plating Thief.”

分流 **53.1261**
见“分流阴极，Plating Thief”。

Roll-to-Roll Process **42.2019**
A method of manufacturing flexible printed circuits using a continuous roll process, rather than individual panels.

成卷式生产工艺 **42.2019**
采用连续成卷工艺，而不是单个在制板生产挠性线路板的方法。

Rosin **46.1514**
A hard, natural resin, consisting of abietic and primaric acids and their isomers, some fatty acids and terpene hydrocarbons, that is extracted from pine trees and subsequently refined.

松香 **46.1514**
从松树中提取并精练的一种硬质天然树脂，由松脂酸和伯酸以及它们的同份异构体、某些脂肪酸和萜烃组成。

Rosin Flux **46.1262**
Rosin in an organic solvent or rosin as a paste with activators.

松香助焊剂 **46.1262**
有机溶剂中的松香或具有活性剂的膏状松香。

Rosin Solder Connection **75.1515**
A solder connection that has practically the same appearance as does a cold solder connection, but that also shows evidence of entrapped rosin separating the surfaces to be joined. (See also “Cold Solder Connection.”)

过量松香焊接连接 **75.1515**
从外观上看与冷焊接连接几乎完全相同，有残留的松香分离待焊接表面的迹象。（又见“冷焊接连接，Cold Solder Connection”。）

Rotational Error **25.1263**
The angular misalignment of a functional pattern with respect to the X and Y axes.

旋转误差 **25.1263**
功能图形相对于X和Y轴的角偏差。

Router (CAD) **22.1264**

A computer program that automatically determines paths between points to be interconnected.

布线器（CAD） **22.1264**

自动确定互连点间路径的计算机程序。

Router Bit **51.2020**

A straight or shaped rotary cutting tool used in a power router to cut, trim or shape materials by rotary action.

铣刀 **51.2020**

直形或异形的旋转切削工具, 用于铣切工件的端面、孔、槽等。

Routing **54.2021**

A mechanical method that removes a portion of the material outlining a printed board, using a cutting bit, in order to facilitate ease of breakout (removal) from the manufacturing/assembly panel.

铣切 **54.2021**

为了便于制造/组装在制板的分割，用铣刀去除印制板部分材料，显现出印制板轮廓的一种方法。

Routing Mark **25.1265**

An artwork feature that is used to define the periphery of a printed board.

铣切标记 **25.1265**

用来确定印制板外形的照相底图要素。

Roving **44.1266**

A collection of parallel strands of filaments assembled with or without an intentional twist.

粗纱 **44.1266**

由平行细丝加捻或不加捻而形成的一股纱。

Rubber Banding **22.1267**

A technique for displaying a straight line with one endpoint fixed and the other end following the commands of a manual data input device.

橡皮带式生成线 **22.1267**

呈现直线的技术，直线的一端固定，而另一端根据人工数据输入装置的指令而确定。

Run **91.1268**

A consecutive number of points that consistently increase or decrease, or that are consistently above or below the central line of a SPC control chart.

链 **91.1268**

SPC控制图中连续上升或下降、或连续位于中心线上方或下方的一系列点。

Run Chart **91.1269**

A graphic representation of plotted values of some variable gathered from a process characteristic with respect to a central line that can be analyzed by run.

链图 **91.1269**

根据某一工艺特性及其中心线，收集的一些变量的绘图值而绘制的图，可通过链，对其进行分析。

Run Time **92.1271**

The time elapsed while a unit is in an inspection or testing machine.

运行时间 **92.1271**

在检验或测试设备上运行一个单位需要的时间。

Runout **24.1270**

The sum of the cumulative-pitch error across a number of functional patterns on a step-and-repeat phototool.

累积误差 **24.1270**

分步重复曝光底片上多个功能图形的累积间距误差之和。

Runtime System **11.1272**

The collection of software programs required to perform the actual testing and diagnosis of a unit under test.

实时系统 **11.1272**

完成待测试单元实际测试和诊断所需的软件程序的集合。

S

Sacrificial Protection **45.1274**

The preferential corrosion of a metal coating in order to protect the substrate metal.

牺牲性保护 **45.1274**

为了保护基板金属，对金属覆盖层进行的预先腐蚀。

Sacrificial-Foil Laminate **31.1273**

A base material with a treated-metal foil which is subsequently removed, for the purpose of impressing a microporous topography on the surface of the base material.

牺牲箔层压板 **31.1273**

具有经处理的金属箔的基材，后续工序中再将金属箔去除，目的是使基材表面具有微孔结构。

Sagging **74.1275**
See “Wire Sag.”

下垂 **74.1275**
见“金属线下垂，Wire Sag”。

Sample Qualification **90.2022**
Producing a product with a given set of parameters intended for evaluation as a sample of manufacturing capability.

样品鉴定 **90.2022**
用预先给定的一组参数生产一个产品，将其作为体现制造能力的样品进行评估。

Saponifier **76.1276**
An aqueous organic- or inorganic-base solution with additives that promote the removal of rosin and/or water-soluble flux.

皂化剂 **76.1276**
一种含有添加剂的有机或无机水溶性溶液，可加速去除松香和/或水溶性助焊剂。

Satin Weave **44.1516**
A fabric configuration where the surface is almost entirely made up of warp filling adjacent yarns, thereby producing a smooth surface. (The intersection points do not fall in a straight diagonal, or twill, but in a patterned formation.)

缎纹组织 **44.1516**
几乎完全由经线填充相邻的纱线构成表面的织物结构，因而可形成光滑的表面。（组织点不会落在对角直线或斜纹组织上，而是以一定的图形形式排列。）

Scalar Processing **11.1277**
The use of a computer architecture in which single operations are performed on data elements.

标量处理 **11.1277**
可在数据元素上完成单个操作的计算机结构的使用。

Scan Rate **92.0755**
The rate at which a machine scans the surface of the unit being evaluated, expressed in surface area per unit of time or time per unit area of surface.

扫描速率 **92.0755**
机器扫描待评定单元表面的速率，用单位时间内扫描的表面面积或扫描单位表面积需要的时间来表示。

Scan-Dead Time **92.1278**
The time during a scanning process when data is not being collected from the unit being evaluated.

扫描空载时间 **92.1278**
扫描过程中未从被评定单元收集到数据的时间。

Scanner, Test **92.0693**
A program controlled relay matrix used for connecting any unit-under-test circuit mode to the analog instrument bus.

测试扫描仪 **92.0693**
控制用于连接任何测试中单元电路模式与模拟仪器总线的继电器矩阵程序。

Scanning Acoustical Microscopy (SAM) **92.2078**
A method of nondestructive inspection used for identifying buried interfaces of dissimilar materials. Also referred to as C-SAM.

声学扫描显微镜（SAM） **92.2078**
用于鉴定不同材料内界面的无损检测方法。也称为C-SAM。

Scanning Electron Microscope (SEM) **92.2023**
A microscope that makes use of a scanning beam of electrons to display details smaller than 100 angstroms in size (surface only).

电子扫描显微镜 **92.2023**
利用电子扫描束来显示尺寸（只限表面）小于100埃的零件的显微镜。

Scatter Diagram **94.0991**
A graph that depicts the relationships between an independent variable and a dependent response variable.

散布图 **94.0991**
描述自变量和应变量之间相互关系的图。

Scavenged Air **14.2024**
Vapors and aerosols removed from a processing area to help ensure that there is no process fluid in the workplace.

净化空气 **14.2024**
从加工区域去除蒸汽和悬浮物，以帮助确保工作场所内无制程液体。

Schematic Diagram **26.1107**
A drawing that shows, by means of graphic symbols, the electrical connections, components and functions of a specific circuit arrangement.

原理图 **26.1107**
借助图形符号表示具体电路布局的电气连接、元器件和功能的图。

Scoop-Proof Connectors **37.1239**
Connectors that incorporate features that prevent contact damage during mating and unmating.

防划损连接器 **37.1239**
具有在插拔过程中防止接触件受损功能的连接器。

Screen Printing **52.1204**
The transferring of an image to a surface by forcing a suitable media with a squeegee through an imaged-screen mesh.

网印 **52.1204**
利用刮刀施加压力将适宜的介质通过有图形的网孔，将图形转移到表面。

Scribe Coat **24.1205**
A stable base material, such as glass or film, with an opaque coating.

划线涂层 **24.1205**
具有不透明涂层的稳定基材，如玻璃或胶片。

Scribing **24.1279**
The cutting of the opaque coating, but not the base material, on a scribe-coat material.

刻线 **24.1279**
在划线涂层材料上切割不透明涂层，但不切割基材。

Scrubbing **74.1280**
The rubbing of the lead wire and bonding land in order to break up oxide layers and to improve bondability.

磨刷 **74.1280**
为了去除氧化层和提高键合性对引线和键合连接盘进行的研磨。

Scum **52.2025**
A resist residue remaining on the substrate's surface following development.

残渣 **52.2025**
显影后残留在基板表面的抗蚀残留物。

Search Height **74.1281**
The height of a bonding tool above the bonding area prior to it being lowered to make the termination.

搜索高度 **74.1281**
键合工具被降低进行端接之前高出键合区的高度。

Seating Plane **30.2026**
The surface on which a component rests.

底座面 **30.2026**
元器件放置在其上的表面。

Second Bond **74.1283**
The second termination in a sequence of bonds made to form a conductive path. (See also "First Bond.")

第二键合 **74.1283**
形成导电通路的一系列键合中的第二个端接点。（又见"第一键合，First Bond"。）

Secondary Relief **51.1282**
The clearance angle that is behind the primary relief of a drill point.

第二后角 **51.1282**
钻尖的第一面角后面的余隙角。

Secondary Side **22.1517**
That side of a packaging and interconnecting structure that is opposite the primary side. (It is the same as the "solder side" on through-hole mounting technology.)

辅面 **22.1517**
与主面相对的封装互连结构面。（与通孔安装技术的"焊接面，solder side"相同。）

Section Beam **44.1284**
A flanged cylinder onto which yarn is drawn and accumulated from the yarn bobbins or packages.

接线轴 **44.1284**
纱线从其上拉抻并从纱线线轴或线包处聚集的带突缘的辊子。

Sectional Specification (SS) **26.1783**
A document that describes the specific requirements pertaining to a portion of a set, family, or group of products, materials or services.

分规范（SS） **26.1783**
描述关于一套、一系列或一组产品、材料或服务的一部分具体要求的文件。

Seed Layer **53.1286**
See "Activating Layer."

强化层 **53.1286**
见"活化层，Activating Layer"。

Seeding **53.1285**
See "Activating."

强化 **53.1285**

见“活化，Activating”。

Self Declaration **94.2027**

The manufacturer’s view of its products and process capabilities in order to meet the customer’s requirements, the requirements of a standard, and/or the applicable associated specification sheet(s).

自我声明 **94.2027**

制造厂商为了表明满足客户的要求、标准要求和或所适用的规范细则而对其产品和过程能力的观点。

Self Test **92.1287**

The ability of an analyzer to appraise itself prior to performing a test procedure.

自检测试 **92.1287**

分析仪器在执行测试程序之前对自身进行评定的能力。

Self-Alignment Effect **73.2028**

An effect that pulls an SMD to the center of the land by the surface tension of the solder during reflow soldering.

自对中效应 **73.2028**

在再流焊接过程中通过焊料表面张力将SMD拉至焊盘中心的一种效应。

Selvage **44.1288**

The edge of the fabric where the body of the fabric ends as defined by the last warp yarn.

织边 **44.1288**

由最后一股经线确定的处于织物主体末端的织物边缘。

Semi-Additive Process **53.1518**

An additive process wherein the entire thickness of electrically-isolated conductors is obtained by the combined use of electroless metal deposition and electroplating, etching, or both. (See also “Fully-Additive Process.”)

半加成法工艺 **53.1518**

电绝缘导体的整个厚度是结合化学沉积金属和电镀或蚀刻，或与电镀及蚀刻并用形成的一种加成法工艺。（又见“全加成法工艺，Fully-Additive Process”。）

Semi-Rigid Cable **37.2029**

A coaxial cable that has a solid outer conductor.

半刚性电缆 **37.2029**

具有实心外导体的一种同轴电缆。

Semiconductor **30.1289**

A solid material, such as silicon, that has a resistivity that is midway between that of a conductor and of a resistor.

半导体 **30.1289**

电阻率介于导体和绝缘体之间的一种固体材料，如硅。

Semiconductor Carrier **74.1290**

A package for semiconductor die.

半导体载体 **74.1290**

半导体芯片的封装。

Sensitivity Control **91.1519**

The provisions that allow a machine to be set to acceptance and rejection thresholds that correspond to the end-use requirements for the units being evaluated.

灵敏度控制 **91.1519**

允许设定机器的验收和拒收阈值的措施，该阈值符合被评定单元的终端使用要求。

Sensitizing **53.1291**

See “Activating.”

敏化 **53.1291**

见“活化，Activating”。

Separable Component Part **30.1520**

A replaceable component part with a body that is not chemically bonded, excluding protective coatings, solder, and potting compounds, to the base material.

可分离元器件部件 **30.1520**

主体与基材不是以化学方法连接在一起的可更换的元器件部分，不包括保护涂层、焊料和灌封化合物。

Sequential Lamination **61.1594**

The process of manufacturing multilayer printed boards in which multiple double-sided printed boards with interconnecting holes between conductive patterns on both sides are laminated or combined, after which additional layers (usually single-sided) are attached to the partially completed board stackup.

顺序层压 **61.1594**

制造多层印制板的一种工艺。先将双面具有导电图形、内部互连过孔的多块双面印制板层压或组合在一起，然后在半成品叠层上再粘附另外的附加层（通常是单面）。

Sequentially-Laminated Multilayer Printed Board **61.1521**

A multilayer printed board that is formed by laminating together through-hole plated double-sided or multilayer boards. (Thus, some of its conductive layers are interconnected with blind or buried vias.)

顺序层压多层印制板 **61.1521**

将镀覆通孔双面板或多层板层压在一起形成的多层印制板。（因此，它的某些导电层是通过盲孔或埋孔实现互连。）

Serial Number **16.2175**

A consecutive identifier of an individual unit of identical units.

序列号 **16.2175**

相同部件中单个部件的连续标识符。

Serpentine Cut **77.1293**

A trimming cut in a film component in the shape of a wavy (serpentine) pattern.

螺旋形切割 **77.1293**

膜元器件内波纹（蛇形）形状的修整切割。

Service Temperature (Flexible Circuits) **42.2137**

The maximum, continuous temperature exposure that a flexible printed wiring material may withstand without degradation beyond 50% of both initial peel strength and dielectric breakdown for a 100,000 hour lifetime.

工作温度（挠性电路） **42.2137**

在100000小时寿命期内，挠性印制线路材料原始剪切强度和介质耐电压下降不超过50%的最大连续工作温度。

Set-Up Time **92.1522**

The time required to change hardware and software, to set-up necessary windows, and to run calibration and verification tests in order to ensure that a system is ready for operation.

设置时间 **92.1522**

为确保系统准备好运行而更改硬件或者软件、设置必要的窗口、运行校正和验证测试所需要的时间。

Shadowing, Etchback **54.1294**

A condition that occurs during an etchback process in which the dielectric material immediately next to the foil is not removed completely. (See Figure S-1.) (This can occur even though an acceptable amount of etchback may have been achieved elsewhere.)

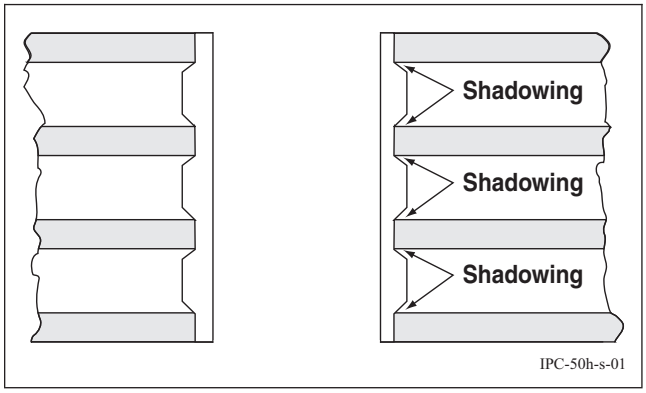
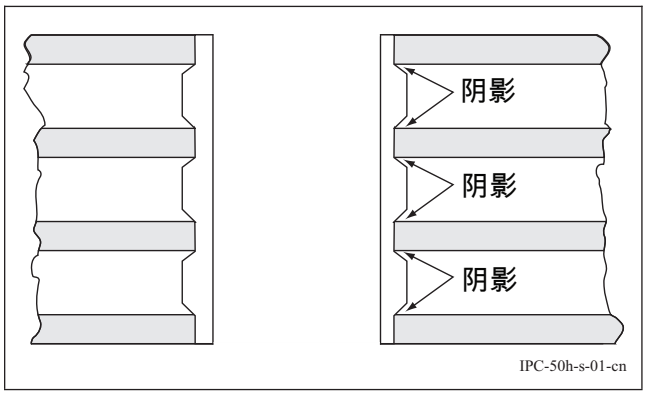


Figure S-1 Shadowing

凹蚀阴影 **54.1294**

发生在凹蚀过程中的一种状况，即紧靠金属箔的介质材料没有被完全除去。（即使其它地方的凹蚀量是可接受的，这种状况也会发生。）（见图S-1。）



图S-1 阴影

Shadowless Illumination **24.1523**

The illumination of the area of interest by the light source of a magnifying device so that no shadows fall on the area of interest from objects in the field of view that are not of prime interest.

无影照明 **24.1523**

由放大装置的光源照射物体，使区域内的主要观察对象上无非主要观察对象的阴影。

Shank **51.1295**

The cylindrical part of a drill that is held in the spindle of a drilling machine.

钻柄 **51.1295**

夹持在钻孔机器主轴内的钻头圆柱部分。

Shank Diameter **51.1297**

The actual size of a drill shank.

钻柄直径 **51.1297**

钻柄的实际尺寸。

Shank-to-Drill Body Concentricity **51.1296**
The total variation of the location of the outside diameter of a rotating drill shank.

钻柄对钻体同心度 **51.1296**
旋转的钻柄外径位置相对于钻体的总变差。

Shear Strength **92.1298**
The force required to shear apart adhesive-bonded (and cured) materials and/or components. (See also "Lap Shear Strength" and "Torsional Strength.")

剪切强度 **92.1298**
剪切分离粘合剂连接（并固化）的材料和/或元器件所需的力。（又见"搭接剪切强度，Lap Shear Strength"和抗扭强度，Torsional Strength"。）

Shear Test **92.1765**
The maximum stress a material can withstand in shear; the value of the force achieved when shearing stress is applied to a solder joint or wire bond to determine the breaking load.

剪切测试 **92.1765**
材料在剪切过程中能承受的最大应力；在焊点或金属线键合处施加剪切应力以确定负载断裂时所达到的力的值。

Sheet Capacitance **92.1524**
The electrical capacitance of a material as measured from one electrode to another, expressed in a unit of capacitance (e.g., farads or microfarads) per unit area.

片电容 **92.1524**
从一个电极到另一个电极测得的材料的电容，以单位面积上的电容量（如法拉或微法拉）来表示。

Sheet Resistance **92.1525**
The electrical resistance of a planar film of a resistive material with uniform thickness as measured across opposite sides of a unit square pattern, expressed in ohms per square.

片电阻 **92.1525**
具有均匀厚度的平面薄膜电阻材料的电气阻抗，通过测量一个单位面积图形的对边而得，用每单位面积的欧姆表示。

Sheet-Metal Contact **37.1299**
A type of connector contact that consists of flat spring metal that has been formed by either stamping or bending. (See also "Machined Contact.")

金属片接触件 **37.1299**
通过冲压或弯曲成型的扁平弹簧金属组成的连接器接触件。（又见"机制接头，Machined Contact"。）

Shelf Life **90.1526**
The length of time a material, substance, or product can be stored, under specific environmental conditions, while it meets all applicable specification requirements and remains suitable for its intended use.

保存期限 **90.1526**
材料、物质、或者产品在特定环境条件下，能满足所有适用的技术规范要求，并能有效使用的储存时间长度。

Shield **21.1300**
The material around a conductor or group of conductors that limits electromagnetic and/or electrostatic interference.

屏蔽层 **21.1300**
在导体或者一组导体周围能够限制电磁干扰和/或静电干扰的材料。

Shielding, Electronic **21.1527**
A physical barrier, usually electrically conductive, that reduces the interaction of electric or magnetic fields upon devices, circuits, or portions of circuits.

电子屏蔽层 **21.1527**
可减轻电场或磁场对器件、电路、或部分电路的交互影响的物理阻挡层，通常是导电的。

Short, Electrical **92.1301**
A fault that connects two or more points that are normally electrically separated.

电气短路 **92.1301**
使正常时为电气隔离的两个或多个点形成连接的故障。

Short-Term Capability **91.1302**
The capability of a process that exhibits statistical control over a brief period of time.

短期能力 **91.1302**
过程在较短时间周期内呈现出的统计控制的能力。

Shoulder Angle **51.0929**
The angle of the blended transition from the drill shank diameter to the drill body diameter.

肩角 **51.0929**
从钻柄直径到钻体直径交叉过渡的角度。

Shrinkage Cavity **97.2031**
A cavity or crack occurring around the surface of a soldered area after solidification of the solder joint that does not penetrate into the inside of the soldered area.

缩孔 **97.2031**
焊点固化后在焊接区表面形成的空穴或裂纹，这种裂纹不会延伸至焊接区内部。

Shrink SOP (SSOP) **33.2030**
A family of component packages with four sizes, each having the ability to provide lead pitches between 0.625 mm [0.0025 in] and 0.3 mm [0.012 in].

缩小型SOP（SSOP） **33.2030**
有四种尺寸的元器件封装系列，每种尺寸的封装引线间距都在0.625mm[0.0025in]至0.3mm[0.012in]之间。

Shuttle **44.0930**
The device that holds the quill of the filling yarn and carries it back and forth across the width of the fabric.

梭子 **44.0930**
夹持填充纱线的线轴并携带纱往返穿过织物宽度的装置。

Sigma (σ) **94.0931**
The lowercase Greek letter that is used to designate a standard deviation of a population.

西格玛 **94.0931**
用来表示总体标准差的小写希腊字母。

Signal **21.0932**
An electrical impulse of a predetermined voltage, current, polarity and pulse width.

信号 **21.0932**
预先确定了电压、电流、极性和脉冲宽度的电脉冲。

Signal Conductor **22.0934**
An individual conductor that is used to transmit an impressed electrical signal.

信号导体 **22.0934**
用来传输外加电信号的单个导体。

Signal Line **22.0935**
A conductor used to transmit a logic signal from one part of a circuit to another.

信号线 **22.0935**
用来将逻辑信号从电路的一部分传输到另一部分的导体。

Signal Plane **22.0936**
A conductor layer that carries electrical signals. (See also “Ground Plane” and “Voltage Plane.”)

信号层 **22.0936**
传输电气信号的导体层。（又见“接地层，Ground Plane”和“电压层，Voltage Plane”。）

Signal-to-Noise Ratio (Process Control) **91.0933**
A response variable that takes into consideration both parameter mean and parameter variation values.

信噪比（过程控制） **91.0933**
包括参数平均值和参数变异值在内的响应变量。

Silk screening **52.0937**
See “Screen Printing.”

丝印 **52.0937**
见“网印，Screen Printing”。

Silver Migration **92.0938**
The ionic removal of silver and its redeposition in an adjacent area under the influence of migration-inducing conditions.

银迁移 **92.0938**
在诱发迁移条件的影响下，银离子移动并在相邻区域重新沉积。

Silver Streak (Base Materials) **96.2033**
See “Tunnel Void.”

银条纹（基材） **96.2033**
见“管状空洞，Tunnel Void”。

Simulated Aging **92.0939**
The artificial exposure of material to conditions of both high and low temperature and humidity in an attempt to produce changes that occur during its extended exposure to normal environmental conditions.

模拟老化 **92.0939**
将材料暴露于高低温和高低湿度条件下，以使其产生将其置于常规环境条件下发生的变化。

Simulated Datum **92.0940**
The surface or feature(s) on a fixture, used as a machine reference, which is correlated to the original board or assembly datum.

模拟基准 **92.0940**
用作加工参考的夹具表面或特征，其与板或组件的初始基准有关。

Single Chip Package (SCP) **33.2034**
An integrated circuit package containing only one semiconductor die.

单芯片封装（SCP） **33.2034**
只含有一块半导体芯片的集成电路封装。

Single-Image Production Master **24.0941**
A production master that is used in the process of making only one printed board. (See also “Multiple-Image Production Master.”)

单个图像生产底版 **24.0941**
制作单块印制板过程中使用的生产底版。（又见“多重图像生产底版，Multiple-Image Production Master”。）

Single-Inline Package (SIP) **31.0942**
A component package with one straight row of pins or wire leads.

单列直插封装（SIP） **31.0942**
具有一排笔直的插针或金属引线的元器件封装。

Single-Layer Carrier Tape **36.1528**
The carrier for conductors used in tape-automated bonding that consists only of a metal foil. (See also “Multilayer Carrier Tape,” “Two-Layer Carrier Tape,” and “Three-Layer Carrier Tape.”)

单层载带 **36.1528**
仅由一层金属箔组成用于自动载带键合的导体载带。（又见“多层载带，Multilayer Carrier Tape”和“两层载带，Two-Layer Carrier Tape”和“三层载带，Three-Layer Carrier Tape”。）

Single-Point Bonding **74.0943**
The making of terminations one at a time. (See also “Gang Bonding.”)

单点键合 **74.0943**
每次只制作一个端接点。（又见“群点键合，Gang Bonding”。）

Single-Sided Assembly **80.0944**
A packaging and interconnecting structure with components mounted only on one side. (See also “Double-Sided Assembly.”)

单面组件 **80.0944**
元器件只安装在基板一面的封装互连结构。（又见“双面组件，Double-Sided Assembly”。）

Single-Sided Printed Board **60.0945**
A printed board with a conductive pattern on only one side.

单面印制板 **60.0945**
只在一面有导电图形的印制板。

Singulate **51.2178**
The act of extracting one unit from a set, as in, stepped images and multiple embedded components.

提取单片 **51.2178**
从一组集合中例如分步式方法复制出的图像和多个嵌入式元器件分离出一个单元个体的动作。

Sizing **44.0948**
The method of applying size i.e., starch, to a group (width) of warp yarns on a continuous basis.

上浆 **44.0948**
连续向一组（幅）经线加浆料即浆糊的方法。

Skin Depth **21.2035**
The depth into a conductor for which the reciprocal of the current associated with a propagating electromagnetic signal is flowing. The depth becomes less as frequency increase.

趋肤深度 **21.2035**
导体深度，与传播电磁信号相关的电流成倒数关系。深度随着频率的增加而降低。

Skin Effect **21.0946**
The increase in resistance of a conductor at microwave frequencies that is caused by the tendency of electric current to concentrate at the conductor’s surface.

趋肤效应 **21.0946**
微波频率下由于电流趋向集中于导体表面而引起导体阻抗的增加。

Skip Via **22.2036**
A via that directly connects conductive layers of build-up/HDI layers that are not adjacent with each other.

跳孔 **22.2036**
直接连接积层或HDI层的互相不相邻导电层的导通孔。

Skipping **52.0947**
When a coating or resist does not cover the spaces between adjacent conductors.

漏印 **52.0947**
涂层或阻焊剂，未覆盖相邻导体之间的间距。

Slice **35.0949**
See “Wafer.”

薄片 **35.0949**
见“晶圆，Wafer”。

Sliver **96.0950**
A slender portion of plating overhang that is partially or completely separated from a conductor edge.

镀屑 **96.0950**
与导体边缘部分或全部分离的镀层突沿的细小部分。

Slump **73.0951**
The distance that a substance, e.g., adhesive, moves after it has been applied.

塌落 **73.0951**
物质如粘合剂在涂敷后移动的距离。

Small Outline J-Lead (SOJ) **33.2158**
A generic rectangular component package, whose chip cavity or mounting area occupies a major portion of the package area, with leads on two opposing sides that are formed in a "J" shape.

小外形J形引线封装（SOJ） **33.2158**
常见的矩形元器件封装，其芯片腔体或安装区域占据了封装区域的主要部分，而在其两个对边成形有J形引线。

Small Outline No-Lead (SON) **33.2159**
A generic rectangular component package outline wherein the metal pad terminations are formed on two sides of the bottom of the package.

小外形无引线封装（SON） **33.2159**
常见的的矩形元器件封装，其金属端子连接盘成形于封装底部的两边。

Small Outline Package (SOP) **33.2160**
A generic rectangular component package, whose chip cavity or mounting area occupies a major portion of the package area, with leads or metal pad surfaces on two opposing sides.

小外形封装（SOP） **33.2160**
常见的矩形元器件封装，其芯片腔体或安装区域占据了封装区域的主要部分，在其两个对边有引线或金属连接盘面。

Smaller-the-Better Characteristic **91.1817**
A parameter of quality that improves performance as its value decreases. (See also "Larger-the-Better Characteristic" and "Nominal-is-Best Characteristic.")

越小越好特性 **91.1817**
其数值减少时可提高性能的质量参数。（又见"越大越好特性，Larger-the-Better Characteristic"和"标称值最好特性，Nominal-Is-Best Characteristic"。）

Smear Removal **54.0953**
See "Desmear."

钻污去除 **54.0953**
见"去钻污，Desmear"。

Smeared Bond **74.0952**
A bond impression that has been distorted or enlarged by excess lateral movement of the bonding tool or holding device fixture.

模糊键合 **74.0952**
由于键合工具或固定器件的夹具的过度横向移动造成的接合区变形或增大。

Socket Contact **37.0954**
A female connector contact.

插座接触件 **37.0954**
一种凹形连接器接触件。

Soft Error **35.2037**
A temporary electrical state error in a circuit caused by a transient event.

软故障 **35.2037**
由于瞬时事件引发的临时电气状态错误。

Softening (Cured Solder Mask) **47.0873**
A decrease in hardness as evidenced by a decrease in pencil (scratch) hardness test results.

软化（已固化的阻焊膜） **47.0873**
铅笔（划痕）硬度测试结果显示的硬度降低。

Solarization **24.0955**
A decrease in density with increased exposure.

曝光过度 **24.0955**
由于增加曝光量而导致密度下降。

Solder **46.0956**
A metal alloy with a melting temperature that is below 427 °C [800 °F].

焊料 **46.0956**
熔融温度低于427 °C[800 °F]的金属合金。

Solder Ball **75.0959**
A small sphere of solder adhering to a laminate, resist, or conductor surface. (This generally occurs after wave solder or reflow soldering.)

焊料球 **75.0959**

附着于层压板、阻焊剂或者导体表面的小球形焊料。（通常发生于波峰或者再流焊之后。）

Solder Bath **75.1767**

A container or vessel of molten solder into which component parts or assemblies are immersed.

焊料槽 **75.1767**

熔融焊料的容器，元器件或组件可浸入其中。

Solder Bridging **75.0960**

The unwanted formation of a conductive path of solder between conductors.

焊料桥连 **75.0960**

导体之间由焊料形成的有害的导电通路。

Solder Bump **74.0961**

A round ball of solder used to make interconnections between a flip-chip component and a base material during controlled-collapse soldering.

焊料凸点 **74.0961**

在可控坍塌焊接过程中，用于在倒装芯片器件和基材之间形成互连的圆球形焊料。

Solder Coat **53.0962**

A layer of solder that is applied directly from a molten solder bath to a conductive pattern.

焊料涂层 **53.0962**

直接从熔融焊料槽中涂覆到导电图形上的一层焊料。

Solder Connection **75.0963**

A metallurgical connection serving electrical/mechanical/thermal functions that employs solder for the joining of two or more metal surfaces. (See also, “Cold Solder Connection,” “Disturbed Solder Connection,” “Excess Solder Connection,” “Insufficient Solder Connection,” “Overheated Solder Connection,” “Preferred Solder Connection,” and “Solder Connection Pinhole.”)

焊接连接 **75.0963**

采用焊料连接两种或者两种以上金属表面，起电气、机械、导热作用的一种冶金连接。（又见“冷焊接连接，Cold Solder Connection”、“受扰焊接连接，Disturbed Solder Connection”、“过量焊接连接，Excess Solder Connection”、“不充分焊接连接，Insufficient Solder Connection”、“过热焊接连接，Overheated Solder Connection”、“完美焊接连接，Preferred Solder Connection”和“焊接连接针孔，Solder Connection Pinhole”。）

Solder Connection Pinhole **75.0964**

A small hole that penetrates from the surface of a solder connection to a void of indeterminate size within the solder connection.

焊接连接针孔 **75.0964**

从焊料连接表面渗入到焊接连接内尺寸不定的空洞内的小孔。

Solder Contact **37.2039**

A type of connector contact whose nonmating end is in the form of a hollow cylinder, cup, eyelet, or hook that can be soldered to a wire in contact with it.

焊接接触件 **37.2039**

连接器接触件，其非配接端的形状有空心圆柱体状、杯状、穿孔状、或钩状，能够焊接到与其接触的导线上。

Solder Cream **46.0965**

See “Solder Paste.”

焊膏 **46.0965**

见“焊膏，Solder Paste”。

Solder Destination Side **73.2040**

The side of the printed board or mounting structure that the solder flows toward.

焊接终止面 **73.2040**

焊料流向印制板或安装结构的那一面。

Solder Dissolution **70.2041**

A phenomenon whereby metals (i.e., Ag, Pd, Cu) are dissolved in the solder.

焊料溶蚀 **70.2041**

金属（如银、钯、钴）等溶解于焊料的一种现象。

Solder Embrittlement **75.0966**

The reduction in mechanical properties of a metal as a result of local penetration of solder along grain boundaries.

焊料脆化 **75.0966**

由于焊料沿着晶界的局部渗透而引起金属机械属性的下降。

Solder Fillet **75.0967**

Solder, with a normally concave surface, that is at the intersection of the metal surfaces of the solder connection.

焊料填充 **75.0967**

位于焊接连接金属表面交叉处、具有正常内凹表面的焊料。

Solder Fillet Lifting **97.1833**
The phenomenon in which a solder fillet is lifted off from a land on a board mainly during the flow soldering process. Usually, the phenomenon is more likely to occur on the primary side rather than on the secondary side which is exposed to flow soldering.

焊料填充起翘 **97.1833**
在流动焊接工艺中填充焊料升起与板上焊盘分离的现象。通常，该现象更可能发生于暴露在流动焊接中的焊接主面，而不是辅面。

Solder Fillet Tearing **97.1834**
The tearing of a solder fillet from a land (pad). The term often refers to a re-melting separation that happens in mixed component-mounting in lead-free soldering process.

焊料填充撕裂 **97.1834**
焊料填充与连接盘（垫）撕裂。该术语常指发生在无铅焊接工艺混装元器件安装中的再熔分离。

Solder Flow-up **70.2042**
The phenomenon in which molten solder flows from the solder contact side, through a plated-through hole, and wets the non-solder contact periphery, spreading to the component terminations.

焊料爬升 **70.2042**
熔融的焊料从焊料接触面通过镀覆孔润湿非焊料接触的四周，蔓延到元器件端子的现象。

Solder Joint **75.2043**
See “Solder Connection.”

焊点 **75.2043**
见“焊料连接，Solder Connection”。

Solder Leveling **53.1677**
A solder coating process that causes redistribution and/or partial removal of excess molten solder from a printed board by applying sufficient heat and mechanical force.

焊料整平 **53.1677**
通过施加足够的热量和机械力重新分配印制板上的熔融焊料并/或除去印制板上部分多余熔融焊料的焊料涂覆工艺。

Solder Luster **75.2044**
A state in which the surface of a solder fillet is smooth and lustrous.

焊料光泽 **75.2044**
焊料填充的表面平滑且有光泽的状态。

Solder Mask **47.0973**
A heat-resisting coating material applied to selected areas to prevent the deposition of solder upon those areas during subsequent soldering.

阻焊膜 **47.0973**
涂敷到选定区域的耐热涂层材料，防止在后续焊接中焊料沉积到这些区域。

Solder Mask Aperture **22.0977**
An opening in a solder mask.

阻焊剂开孔 **22.0977**
阻焊剂中的开口。

Solder Meniscus **75.1766**
The contour of a solder shape that is the result of the surface-tension forces that take place during wetting.

焊料弯液面 **75.1766**
在润湿期间产生的表面张力所导致的焊料外形轮廓。

Solder Paste **46.1818**
Finely divided particles of solder, with additives to promote wetting and to control viscosity, tackiness, slumping, drying rate, etc, that are suspended in a cream flux.

焊膏 **46.1818**
含有能促进润湿并控制粘度、触变性、塌落、干燥速度等添加剂的细小颗粒状焊料，其悬浮于膏状焊剂中。

Solder-Paste Flux **75.0957**
Solder paste without the solder particles.

焊膏助焊剂 **75.0957**
未含焊料颗粒的焊膏。

Solder Paste Printing Bleed **75.2045**
A spread of solder paste beyond the opening of screen mask.

焊膏印刷溢出 **75.2045**
焊膏蔓延超出网板开孔。

Solder Plug **75.0974**
A core of solder in a plated-through hole.

焊料塞 **75.0974**
镀覆孔内的焊料芯。

Solder Powder **46.2046**
A small particle of solder having a spherical or irregular shape.

焊料粉 **46.2046**
球形或不规则形状的焊料小颗粒。

Solder Projection **75.0975**
An undesirable protrusion of solder from a solidified solder joint or coating.

焊料拉尖 **75.0975**
凝固焊点或涂层上多余的焊料突出物。

Solder Reflow **75.2047**
See “Reflow Soldering.”

焊料再流 **75.2047**
见“再流焊接，Reflow Soldering”。

Solder Resist **47.1674**
See “Solder Mask.”

阻焊剂 **47.1674**
见“阻焊膜，Solder Mask。”

Solder Side **22.0978**
The secondary side of a single-sided assembly.

焊接面 **22.0978**
单面组件的辅面。

Solder, Silver-Tin **46.2049**
Lead-tin solder with a percent of silver added to prevent the silver dissolution phenomenon, thus increasing the melting point according to the silver content.

锡银焊料 **46.2049**
为防止银溶析现象在锡铅焊料中加入一定比例的银，因而焊料熔点会依据银的含量而升高。

Solder Spread Test **92.1819**
The determination of a relative measure of solder flux efficiency that is obtained by determining the area of spread of a specified weight of solder that has been placed on a specially prepared and fluxed metallic surface.

焊料铺展测试 **92.1819**
一定重量的焊料置于专门准备并涂有助焊剂的金属表面，测量其扩展面积来相对测量焊料焊剂的效率。

Solder Source Side **73.2048**
The side of the printed board or mounting structure to which solder is applied.

焊接起始面 **73.2048**
施加焊料的印制板或安装结构面。

Solder Sputter **75.0979**
Extraneous fragments of solder with an irregular shape.

焊料飞溅 **75.0979**
不规则形状的焊料外飞碎片。

Solder Terminal **37.0980**
An electrical/mechanical connection device that is used to terminate a discrete wire or wires by soldering. (See also “Bifurcated Solder Terminal,” “Cup Solder Terminal,” “Hook Solder Terminal,” “Perforated (Pierced) Solder Terminal,” and “Turret Solder Terminal.”)

焊接接线柱 **37.0980**
通过焊接收尾分立导线的电气/机械连接装置。（又见“双叉焊接接线柱，Bifurcated Solder Terminal”、“焊锡杯，Cup Solder Terminal”、“钩形焊接接线柱，Hook Solder Terminal”、“穿孔焊接接线柱，Perforated (Pierced) Solder Terminal”和“塔形焊接接线柱，Turret Solder Terminal”。）

Solder Webbing **75.0981**
A continuous film or curtain of solder that is parallel to, but not necessarily adhering to, a surface that should be free of solder.

锡网 **75.0981**
与不应有焊料的表面平行但不一定会粘附其上、连续的膜状或帘幕状焊料。

Solder Wicking **75.0982**
The capillary movement of solder between metal surfaces, such as strands of wire.

焊料芯吸 **75.0982**
焊料在金属表面间，如导线股线，的毛细管移动现象。

Solderability **75.0958**
The ability of a metal to be wetted by molten solder.

可焊性 **75.0958**
金属被熔融焊料浸润的能力。

Soldering **75.0968**
The joining of metallic surfaces with solder and without the melting of the base material.

焊接 **75.0968**
用焊料连接金属表面，但不需熔化金属基材的连接。

Soldering Ability **75.0969**
The ability of a specific combination of components to facilitate the formation of a proper solder joint.

焊接能力 **75.0969**
有助于良好焊点形成的特定组合成分的能力。

Soldering Flux **75.0970**
See “Flux.”

焊接助焊剂 **75.0970**
见“助焊剂，Flux”。

Soldering Iron **75.1768**
Common name for a tool which is used to heat components and to reflow solder.

烙铁 **75.1768**
用来加热元器件和熔化焊料的工具的通用名称。

Soldering Iron Tip **75.0971**
The portion of a soldering iron that is used for the application of the heat that melts the solder.

烙铁头 **75.0971**
用来施加熔化焊料热量的烙铁的一部分。

Soldering Oil (Blanket) **75.1529**
Liquid formulations that are used in intermix wave soldering and as coverings on static and wave soldering pots in order to eliminate dross and to reduce surface tension during the soldering operation.

焊接油（覆盖层） **75.1529**
用于混合波峰焊接并作为静态及动态波峰焊槽保护层的液体制剂，以在焊接操作期间去除氧化渣及减小表面张力。

Soldering Temperature Resistance **75.1865**
The ability of the material to withstand the exposure of being subjected to molten or reflow solder temperatures without changing the physical properties of the material in excess of an acceptance criteria.

耐焊接温度 **75.1865**
材料暴露于熔融、或焊料回流的温度下，但其物理特性变化没有超过验收标准的能力。

Solderless Wrap **75.1530**
The connecting of a solid wire to a square, rectangular, or V-shaped terminal by tightly wrapping a solid-conductor wire around the terminal with a special tool.

无焊绕接 **75.1530**
用特殊工具将实心导体紧紧地缠绕在端子上，从而实现实心导线与方形、矩形或V型端子的连接。

Solid-State Bond **74.0983**
See “Diffusion Bond.”

固态键合 **74.0983**
见“扩散键合，Diffusion Bond”。

Solid-Tantalum Chip Component **32.0984**
A capacitor in a leadless package whose dielectric material is solid tantalum.

固体钽片式元器件 **32.0984**
电介质为固体钽的无引线封装电容。

Solidus (Soldering) **75.2050**
The temperature at which a solder alloy begins to melt.

固相线（焊接） **75.2050**
焊料合金开始熔化的温度。

Solvent **76.0985**
A nonreactive liquid substance that is capable of dissolving another substance.

溶剂 **76.0985**
能够溶解另一种物质的非活性液态物质。

Solvent Cleaning **76.0986**
The removal of organic and inorganic soils using a blend of polar and nonpolar organic solvents.

溶剂清洗 **76.0986**
采用极性和非极性有机溶剂混合物去除有机和无机污物。

Solvent Extraction **76.1531**
The removal of one or more components from a liquid mixture by intimate contact with a second liquid that is nearly insoluble in the first liquid and which dissolves the impurities and not the substance that is to be purified.

溶剂萃取 **76.1531**
通过完全接触几乎不溶解于第一种液体的第二种液体，从液体混合物中去除一种或多种组分，其中第二种液体溶解的是杂质而不是需要提纯的物质。

Solvent Pop **76.0987**
Blistering caused by entrapped solvent.

溶剂爆泡 **76.0987**
由于残留的溶剂造成的起泡。

Solvent Release **76.0988**
The ability to permit solvents to evaporate.

溶剂释放 **76.0988**
允许溶剂蒸发的能力。

Solvent Wash **76.0989**
See “Solvent Cleaning.”

溶剂洗涤 **76.0989**
参见“溶剂清洗，Solvent Cleaning”。

Space (Bar code) **70.2051**
The light element of a bar code.

空（条码） **70.2051**
条码的浅色部分。

Spacing **22.0990**
See “Center-to-Center Spacing,” “Conductor Spacing,” “Edge Spacing,” and “Pitch.”

间距 **22.0990**
见“中心间距，Center-to-Center Spacing”、“导体间距，Conductor Spacing”、“边距，Edge Spacing”、和“引线间距，Pitch”。

Spade Contact **37.0992**
A type of male connector contact that consists of flat metal that mates with a fork contact.

铲形接触件 **37.0992**
由可与叉状接触件配接的扁平金属组成的凸形连接器接触件。

Spalling **97.0993**
The chipping, fragmenting or separation of a surface coating, or the cracking, breaking or splintering of materials, due to heat.

散裂 **97.0993**
由于受热导致表面涂层碎裂、分裂或分离，或导致材料的脆裂、断裂、劈裂。

Span **22.0994**
The distance from the reference edge of the first conductor in a group of parallel conductors to the reference edge of the last conductor in the group.

跨距 **22.0994**
从一组平行导体的第一个导体基准边到该组导体中最后一个导体的基准边之间的距离。

Special Cause **91.0995**
A source of variation that is intermittent, unpredictable, or unstable that affects only some of the individual values of process output.

特殊原因 **91.0995**
只影响过程输出的一些个别值的间歇性的、不可预测的或不稳定的变异源。

Special Characters **70.2052**
Non-alphabetic or numeric characters in a bar code symbol.

特殊字符 **70.2052**
在条码符号中的非字母或数字字符。

Specific Gravity **40.2053**
The ratio of the weight of a given volume of a substance to the weight of an equal volume of water.

比重 **40.2053**
给定体积物质的重量与同等体积水的重量之比。

Specific Solderability **75.0997**
The ease with which a metal or alloy can be wetted under specific conditions.

特定可焊性 **75.0997**
在特定条件下，某种金属或者合金可被润湿的难易度。

Specification Drawings **26.1532**
A document that shows the dimensional limits that are applicable to any or all parts of a component and any other information that is necessary to describe the product to be fabricated.

技术图纸 **26.1532**
表明适用于元器件的任何部分或所有部分的尺寸极限，以及描述待制造产品所必需的其它信息的文件。

Specification Limits **91.0996**
The requirements for judging acceptability of a particular characteristic.

规格限 **91.0996**
判断特定特性可接受性的要求。

Specimens **92.1769**
Samples of a material, device or circuit, representative of the production lot, which are selected for testing.

试样 **92.1769**
被选定做测试的代表生产批量的材料、器件或电路的样品。

Specks **70.2054**
Ink splatter not part of a bar code pattern.

斑点 **70.2054**
不属于条形码图形部分的油墨飞溅点。

Splay **51.0998**
The tendency of a rotating drill bit to make off-center, out-of-round, holes that are not perpendicular to the drilling surface.

斜孔 **51.0998**
旋转钻头钻出偏心、不圆，且与被钻表面不垂直的孔。

Split (Fabric) **44.0999**
An opening in a fabric that results from having either the pick or end breaking in two.

裂缝（织物） **44.0999**
由于经线或纱线断裂成两部分而导致的织物开口。

Spot Size **70.2055**
The diameter of the focused image of the emitter in bar code.

点尺寸 **70.2055**
条码中发射器聚焦图像的直径。

Spotting Out **96.1000**
The delayed appearance of spots and blemishes on plated or finished surfaces.

疵点显现 **96.1000**
在镀覆或涂饰表面上斑点或疵点的滞后显现。

Spread **73.1001**
The distance of a substance, e.g., adhesive, moves after it has been applied at ambient conditions.

铺展 **73.1001**
室温条件下，物质如粘合剂被涂敷后移动的距离。

Spread (Values) **91.1002**
A general concept for the extent by which values in a distribution differ from one another.

离散（数值） **91.1002**
一定范围内所分布的数值彼此不同的总概念。

Sprocket **74.1003**
A perforation along the edge of a carrier tape that is used to move and align the tape during the tape fabrication, assembly, and testing operations.

输送定位孔 **74.1003**
沿着载带边缘的穿孔，在制造、组装、测试操作期间，用于移动和对准载带。

Spur **24.1004**
An undesirable clear projection from a clear photographic pattern or a dark projection from a dark photographic pattern.

凸刺 **24.1004**
明亮照相图形中的不良明亮突出，或暗照相图形中的不良暗色突出。

Spurious Signal **21.1006**
See “Crosstalk.”

寄生信号 **21.1006**
见“串扰，Crosstalk”。

Sputtering **53.1007**
The ejection of atoms caused by ion bombardment of a target material in a plasma environment and the subsequent deposition of ejected atoms onto the surface of the substrate.

溅涂 **53.1007**
由高能离子轰击等离子源使原子移动，并连续沉积在基材表面成为薄膜。

Squeegee **75.2056**
A metal or rubber blade used to wipe a material (ink or solder paste) across a stencil or silk screen to force the material through the openings in the screen or stencil, onto the surface of a printed board or mounting structure.

刮刀 **75.2056**
金属或橡胶刀片，用于在模板或丝网推动材料（油墨或者焊膏），以使材料通过模板或丝网开口沉积到印制板或安装结构的表面。

Stability **91.1008**
The absence of special causes of variation.

稳定性 **91.1008**
不存在变异的特殊原因。

Stabilization Period **57.1009**
The period of time in the reflow profile after preheat and before the reflow spike occurs where the temperature of the metals being joined are allowed to equalize.

稳定期 **57.1009**
再流焊温度曲线中，预热后到再流焊峰值前使待连接金属件温度保持相等所经历的时间周期。

Stable Process **91.1010**
A process that is in statistical control.

稳定工艺 **91.1010**

处于统计控制中的过程。

Stack Pin **51.2057**

The metal pin used for fastening and positioning of a panel(s) in hole drilling or peripheral cutting.

支撑销 **51.2057**

钻孔或铣板时用来紧固及定位在制板的金属销。

Stacked Via/Microvia **61.2058**

A via/microvia structure formed by stacking one or more build-up vias/microvias in a build-up multilayer providing an interlayer connection between three or more conductive layers.

叠层导通孔/微导通孔 **61.2058**

通过在积层多层内叠加一个或者多个的积层导通孔/微导通孔形成的导通孔/微导通孔结构，可实现三层以上的内层连接。

Stain Proofing **76.1011**

The retardation of the oxidation of a metal surface.

防锈处理 **76.1011**

抑制金属表面氧化的处理。

Staking, Adhesive **73.1012**

The bonding or attaching of components, or component elements, to a surface or together by the application of small quantities of adhesive material.

粘合固定 **73.1012**

通过施加少量粘合材料将元器件或元器件局部与表面或整体粘接或连接在一起。

Staking, Mechanical **75.1533**

The attaching of metallic devices, such as solder terminals and eyelets, by the upsetting of the portion of the device that protrudes through a hole in a base material.

机械固定 **75.1533**

通过镦锻器件凸出于基材通孔上的部分，实现金属器件如焊接端子及空心铆钉的连接。

Stamped Printed Wiring **60.1013**

Wiring that is produced by die stamping and bonding a metal foil to a base material.

冲压印制线路 **60.1013**

在基材上粘合一层金属箔并由模具冲压形成线路。

Stand-Off **70.1770**

A post or protrusion used to facilitate raising a surface mounting device above the surface of the substrate.

托高 **70.1770**

有助于抬高基板表面上的表面贴装器件的柱形托架或凸起物。

Standard Deviation of a Population **91.1534**

A measure of the distribution of a population about a mean value that is equal to the square root of the variance of a process output. (See also “Sigma.”)

总体标准差 **91.1534**

总体关于平均值分布的量度，平均值等于过程输出方差的平方根。（又见“西格马，Sigma”。）

Standard Laboratory Conditions **92.2086**

A laboratory environment with a temperature of 23 ± 3 °C and a relative humidity of 55 ± 10%.

标准实验室条件 **92.2086**

温度23±3 °C及相对湿度55±10%的实验室环境。

Standard (Electrode) Potential **76.1535**

The reversible potential from an electrode process when all products and reactants are at unit activity on a scale in which the potential for a standard hydrogen half-cell is zero.

标准（电极）电势 **76.1535**

以标准氢半电池电位为零，来衡量一个电极反应的所有生成物和反应物单位活度时可逆电势。

Standoff Solder Terminal **37.1014**

See “Turret Solder Terminal.”

高脚焊接接线柱 **37.1014**

见“塔形焊接接线柱，Turret Solder Terminal”。

Start/Stop Characters **70.2059**

Distinct characters at the beginning and end of each bar code symbol that provide directional information for the decoding logic.

起始/终止符 **70.2059**

每个条码符号中起始和结束的区别符号，可提供用于编码逻辑的方向信息。

Static Electricity **21.2060**

An electrical charge (potential) at rest.

静电 **21.2060**

静止的电荷（电势）。

Static Electricity Control **21.2061**
A technique where materials and systems are employed to eliminate/discharge static electricity buildup by providing continuous discharge paths.

静电控制 **21.2061**
通过提供连续的放电路径，采用材料和系统消除/释放所累积的静电的方法。

Static Relative Permittivity **21.2062**
The ratio of the capacitance (Cx) of a given configuration of electrodes with a specified dielectric, filling all the region pf electro potential field, to the capacitance (Cv) of the same electrode configuration with a vacuum (or air) as the dielectric.

静态相对介电常数 **21.2062**
用特定电介质填满所有电势场区域的指定结构电极的电容量（Cx）与用真空（空气）作为电介质的同样结构电极的电容量（Cv）之比。

Statistical Control **91.1015**
The condition of describing a process from which all special causes of variation have been eliminated and, thereby, only common causes remain.

统计控制 **91.1015**
描述已消除了所有变异的特殊原因，只剩下共同原因的过程状况。

Statistical Hypothesis **91.1016**
An assumption that is made about a population being sampled. (See also “Alternative Hypothesis” and “Null Hypothesis.”)

统计假设 **91.1016**
对被抽样总体所作的假设。（又见“备择假设，Alternative Hypothesis”和“原假设，Null Hypothesis”。）

Statistical Process Control (SPC) **91.1536**
The use of statistical techniques to analyze a process or its output so as to be able to take appropriate action in order to achieve and maintain a state of statistical control and to improve process capability.

统计过程控制（SPC） **91.1536**
采用统计技术分析一个过程或其输出，以便能够采取适当的措施达到并保持统计控制状态及改善过程能力。

Statistical Quality Control (SQC) **91.1017**
The use of statistical techniques to document and assure end product compliance with requirements.

统计质量管理（SQC） **91.1017**
采用统计技术证明并确保最终产品符合要求。

Steam Aging **92.2063**
The exposure of a finish to an environment humidified by steam to precondition the finish for reliability.

蒸汽老化 **92.2063**
将成品暴露于通过水蒸汽增湿的环境中，以便为可靠性对成品进行预处理。

Stencil (Solder Paste/Adhesive) **75.1849**
A thin sheet of material containing openings to reflect a specific pattern, designed to transfer a paste-like material to a substrate for the purpose of component attachment.

模板（焊膏/粘合剂） **75.1849**
含有设计的特定图形开口的薄材料板，用于将类似膏状的材料转移到基板上，从而实现元器件的连接。

Stencil Border **75.1850**
Peripheral tensioned mesh, either polyester or stainless steel, which keeps the stencil foil flat and taut, connecting the foil to the frame.

模板边 **75.1850**
保持模板箔平整绷紧并连接到框架上的聚脂或者不锈钢材料制成的四周拉紧边。

Stencil Foil **75.1851**
The metal area of the stencil, which contains the print pattern.

模板箔 **75.1851**
含有印刷图形的模板金属区域。

Stencil Frame **75.1855**
A device onto which the stencil-foil is mounted. This may be tubular or cast aluminum with the border permanently mounted using an adhesive cast frame sizes are referenced from the inside. Tubular frame sizes are referenced from the outside.

模板框架 **75.1855**
模板箔安装在其上的装置，可以是带有用粘合剂永久安装的模板边的铝管或铸铝制成。铸铝框架大小根据内侧尺寸而定，铝管框架大小根据外侧尺寸而定。

Stencil (Solder Mask) **52.1852**
A thin sheet of material containing openings designed to transfer paste-like solder mask material to a substrate to form the protective pattern.

模板（阻焊膜） **52.1852**
含有设计的开孔的薄材料板，用于将类似膏状的阻焊膜材料转移到基板上形成保护图形。

Stencil Step **75.1853**
A stencil with more than one stencil-foil thickness.

阶梯模板 **75.1853**
金属箔厚度多于一种的模板。

Step Plating **53.2064**
A plating phenomena wherein the plating does not plate to the edge (sidewall) of the plating resist.

阶梯状电镀 **53.2064**
不能电镀所电镀抗蚀剂边缘（侧壁）的电镀现象。

Step Scale **24.1537**
A series of regularly-spaced tones that range from black, through intermediate shades of gray, to white that is used as a reference scale for exposure control in a photo-fabrication process.

光梯尺 **24.1537**
一种有规则间隔的从黑色经灰色过渡到白色的色调，用于感光加工过程控制曝光的参照尺度。

Step Soldering **75.1019**
The making of solder connections by sequentially using solder alloys with successively-lower melting temperatures.

分步焊接 **75.1019**
按序用熔融温度逐步降低的焊料合金进行焊接连接。

Step Wedge **24.1020**
See “Step Scale.”

感光级谱 **24.1020**
见“光梯尺，Step Scale”。

Step-and-Repeat **24.1018**
A method of dimensionally positioning multiples of the same or intermixed functional patterns accurately within a given area on the phototool or by repetitious contact, projection printing or photoplotting.

步进-和-重复 **24.1018**
通过重复接触、影印或光绘在底片指定区域精确定位多个相同或不同功能图形的方法。

Stiffener Board **60.2065**
A material fastened to the surface of a printed board to increase its mechanical strength.

增强板 **60.2065**
固定在印制板表面以加强其机械强度的材料。

Stitch Bond **74.1021**
A bond made with a capillary-type bonding tool whereby the wire is not formed into a ball prior to bonding.

跳点键合 **74.1021**
用毛细管形键合工具形成的键合，键合前金属线不形成球形。

Straight-Through Lead **72.1022**
A component lead that extends through a hole and is terminated without subsequent forming.

直通引线 **72.1022**
直接伸入孔中且无需后续成形就可端接的元器件引线。

Strain Relief (Connector) **37.1023**
A receptacle connector device that prevents the disturbance of the contact and cable terminations.

释力夹（连接器） **37.1023**
可防止接触件及线缆端接点干扰的插座连接器装置。

Stress Corrosion Cracking **95.1024**
Spontaneous cracking produced by the combined action of corrosion and residual or applied static stress.

应力腐蚀裂纹 **95.1024**
由腐蚀、残留或所施加的静态应力的共同作用而产生的自然裂纹。

Stress Relief **36.1025**
The portion of a component lead or wire lead that is formed in such a way as to minimize mechanical stresses after the lead is terminated.

应力消除 **36.1025**
元器件的引线或导线引线收尾后，其中部分再适当成形以使机械应力降低到最低程度。

Stress Relief (Clad Laminate) **41.2066**
The process used to reduce tension between the copper foil and the core material of a clad laminate.

应力消除（覆金属箔层压板） **41.2066**
减少铜箔与覆金属箔层压板芯材之间张力的工艺。

Strike Plating **53.2067**
A thin plating used as a base for subsequent plating.

闪镀层 **53.2067**
作为后续电镀基底的薄镀层。

Stringing **73.1026**
The forming of a “tail” of adhesive as the dispensing tool pin or needle is withdrawn from the deposited adhesive.

拉丝 **73.1026**
当点涂工具针与点涂的粘合剂分离时，形成粘合剂“拖尾”。

Strip (Resist Stripping) **52.2069**
The process of removing unneeded masking material, such as a photoresist or metallic etch resist, after a processing step is completed.

剥离（抗蚀剂剥离） **52.2069**
完成一道工序后，除去不需要的掩膜材料，如光致抗蚀剂或金属抗蚀剂的过程。

Stripback **44.1027**
Broken filaments along a yarn strand that are pushed back and protrude above the fiber plane.

断纱折回 **44.1027**
断丝延着纱线折回并从织物平面突起。

Stripline **21.1028**
A transmission line structure that consists of a signal line that runs parallel to and is sandwiched between and separated by a dielectric from two reference planes.

带状线 **21.1028**
与由电介质隔开的两个基准面平行并位于其中的信号线组成的传输线结构。

Structurally-Similar Construction **90.1029**
Material combinations and materials whose construction details will not affect test results at the primary stage of manufacture.

结构类似构造 **90.1029**
其组成细节不会影响到制造初期测试结果的材料组合及材料。

Stub **21.1030**
A branch of the main signal line of a signal net that is usually used to reach a load that is not on the direct signal path.

支线 **21.1030**
信号网络中主信号线的分支线，通常用于通向不在直接信号通路上的负载。

Stud Via **22.2070**
A via formed with a conductive stud, or pin.

栓导通孔 **22.2070**
用导电栓或销形成的导通孔。

Stud-Mount Termination **30.1031**
See “Straight-Through Lead.”

直装端子 **30.1031**
见“直通引线，Straight-Through Lead”。

Subgroup **91.0140**
A subset of a population that is analyzed dependently in order to eliminate assignable causes of variation.

子群 **91.0140**
为了消除变异的可辩识的原因而单独分析的总体子集。

Subnet **21.1206**
A single source and a single target point that, together with associated vias, lands, and preplaced items, are completely connected by route segments within one net.

子网络 **21.1206**
由布线段将其与相关导通孔、连接盘、预置元器件完全连接在一个网络内的单个源和单个目标点。

Substrate **41.1207**
See “Base Material.”

基板 **41.1207**
见“基材，Base Material”。

Substrate Bending Test **92.1771**
A test applied to a substrate to determine its resistance to bending and the effects of bending to the substrate and any components mounted on the substrate.

基板弯曲测试 **92.1771**
确定基板抗弯曲能力及弯曲对基板和安装在基板上元器件的影响的测试。

Subsurface Corrosion **96.1208**
Formation of isolated particles of corrosion products beneath a metal surface.

表面下腐蚀 **96.1208**
金属表面下孤立的腐蚀性产物颗粒的形成。

Subtractive Process **50.1209**
The fabricating of a conductive pattern by the selective removal of unwanted portions of a conductive foil.

减成法工艺 **50.1209**
通过选择性地去除无用导电箔而制作成导电图形的工艺。

Sum of Squares **91.1210**
The variance of a parameter computed from the variance (square of the standard deviation) of several contributing factors. The sum of squares is based on the variation in the factors being normally distributed.

平方和 **91.1210**
由几个起作用因子的方差（标准偏差平方）计算得到一个参数的方差。平方和以正态分布的因子方差为基础。

Support Ring **36.1033**
Dielectric material that is used to hold beam leads in place relative to one another outside of a packaged device.

支撑环 **36.1033**
用于固定封装器件外梁式引线相互位置的绝缘材料。

Supported Hole **22.1211**
A hole in a printed board that has its inside surfaces plated or otherwise reinforced.

支撑孔 **22.1211**
其内表面被电镀或作其它加固的印制板内的孔。

Supporting Plane **44.1032**
A planar structure that is a part of a packaging and interconnecting structure in order to provide mechanical support, thermo-mechanical constraint, thermal conduction and/or electrical characteristics. (It may be either internal or external to the packaging and interconnecting structure.) (See also “Constraining Core.”)

支撑面 **44.1032**
提供机械支撑、热机械抑制、导热和/或导电特性平面结构，为封装互连结构的一部分。（既可以在封装互连结构的内部，也可在其外部。）（可见“抑制芯，Constraining Core”。）

Surface Insulation Resistance (SIR) **92.1538**
The electrical resistance of an insulating material between a pair of contacts, conductors or grounding devices in various combinations, that is determined under specified environmental and electrical conditions.

表面绝缘电阻（SIR） **92.1538**
在一对接触件、导体或各种组合接地器件之间绝缘材料的电阻，在指定环境和电气条件下测定。

Surface Mount Component (SMC) **30.1034**
A leaded or leadless device (part) that is capable of being attached to a printed board by surface mounting.

表面贴装元器件（SMC） **30.1034**
可以通过表面贴装的方式连接到印制板的有引线或无引线器件（部件）。

Surface Mount Device (SMD) **30.1772**
See “Surface Mount Component (SMC).”

表面贴装器件（SMD） **30.1772**
见“表面贴装元器件（SMC），Surface Mount Component（SMC）”。

Surface Mounting Technology (SMT) **73.1035**
The electrical connection of components to the surface of a conductive pattern that does not utilize component holes.

表面贴装技术（SMT） **73.1035**
元器件不采用元器件孔，与导电图形表面实现电气连接。

Surface Resistance **21.2073**
The ratio of DC voltage to the current flowing between two electrodes of specified configuration that contacts the same side of a material. Expressed in ohms.

表面电阻 **21.2073**
两个接触材料同一面的指定结构电极之间的电压与流经其中的电流之比，用欧姆表示。

Surface Tension **75.1036**
The natural, inward, molecular-attraction force that inhibits the spread of a liquid at its interface with a solid material.

表面张力 **75.1036**
阻止液体在液体与固体材料交界面处扩展的固有的、向内的分子吸引力。

Surge **21.1037**
A transient variation in the current and/or potential at a point in a circuit.

电涌 **21.1037**
电路中某点电流或电压的瞬时变化。

Swaged Lead **72.1539**
A component lead wire that extends through a hole in a printed board and its lead extension is flattened (swaged) to secure the component to the board during manufacturing operations.

压扁引线 **72.1539**

元器件引线穿入印制板孔后，压平（压扁）其伸出的引线，以使元器件在生产操作中固定在印制板上。

Swell-and-Etch Process **53.1540**

The surface treatment of a base material in order to promote the adhesion of an electroless metal deposit by softening the surface with a solvent and then exposing the surface to an oxidizing solution in order to create a microporous surface.

溶胀-蚀刻工艺 **53.1540**

为了提高化学金属沉积的附着力而进行的基材表面处理，即用一种溶剂软化表面，然后将其暴露于氧化溶液中以形成多微孔表面。

Swelling (Cured Solder Mask) **47.0261**

An increase in volume, noted as an increase in solder mask thickness due to absorption of another material such as a solvent.

膨胀（已固化的阻焊膜） **47.0261**

由于吸收其它物质, 如溶剂，导致体积增加，表现为阻焊膜厚度增加。

Symbology (Bar Code) **70.2075**

The structural characteristics of bar code symbols.

符号象征（条码） **70.2075**

条码符号的结构特征。

Synthetic Activated Flux **75.1038**

A highly-activated organic flux whose post-soldering residues are soluble in halogenated solvents.

合成活性助焊剂 **75.1038**

其焊后残留物可以溶解在卤化溶剂中的高活性有机助焊剂。

Synthetic Resin **75.1039**

A synthetic organic polymer or a chemically-treated natural resin.

合成树脂 **75.1039**

合成的有机聚合物或经化学处理的天然树脂。

System **80.2151**

An assemblage or combination of parts forming a complex or unitary electronic whole.

系统 **80.2151**

由组件或部件组合而成的复杂或单一电子整体。

System Effective Color Temperature **24.1040**

The effective color temperature measured using an optical system's light source to illuminate the target area.

系统有效色温 **24.1040**

使用光学系统光源照亮目标区域而测得的有效色温。

System in Package (SiP) **35.2155**

A multi-chip package (MCP) that performs a system function.

系统级封装（SiP） **35.2155**

完成一个系统功能的多芯片封装。

T

Tab **22.1042**

See "Printed Contact."

片 **22.1042**

见"印制接触片，Printed Contact"。

TAB **75.1041**

See "Tape Automated Bonding."

TAB **75.1041**

见"载带自动键合，Tape Automated Bonding"。

Tackiness **73.2076**

The adhesion between solder paste applied on a land and a SMD component.

粘着性 **73.2076**

焊盘上的所涂敷焊膏与SMD元器件之间的粘附力。

Tail, Bonding **75.1043**

The free end of wire extending beyond the bond impression of a wire bond from the heel.

键合尾线 **75.1043**

金属线延伸在键合点上，从键合点根部起的游离线头。

Tail Pull **75.1044**

The removal of excess wire after a wedge or ultrasonic bond is made.

尾线割除 **75.1044**

楔焊或超声焊键合之后多余金属线的去除。

Tangency (Cross section) **60.2068**

An archaic term previously used to describe evidence of pad edge. The term is not an inspectable concept.

相切（横截面） **60.2068**

用于描述盘边缘状况的旧术语。该术语是一个不可观察的概念。

Tape **75.1045**

See “Carrier Tape.”

带 **75.1045**

见“载带，Carrier Tape”。

Tape Automated Bonding **75.1046**

A fine-pitch technology that provides interconnections between die and base materials with conductors that are on a carrier tape. (See Figure T-1.)

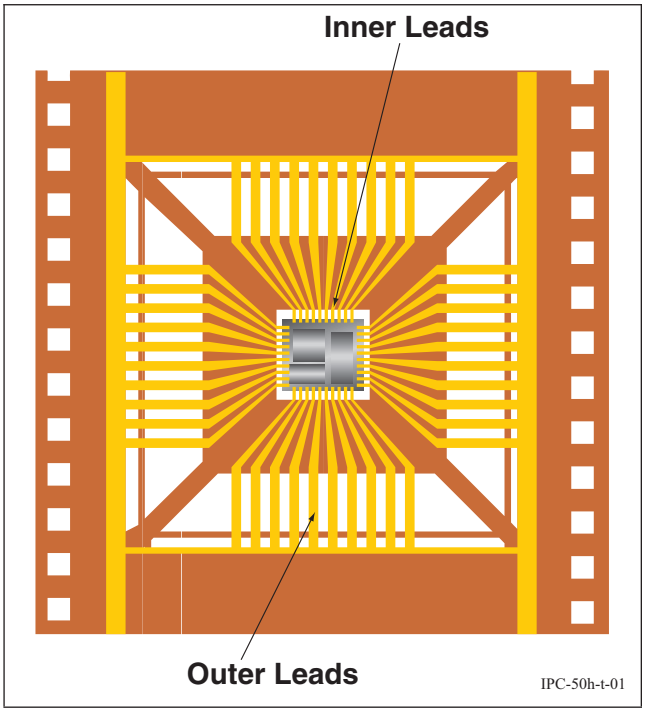


Figure T-1 Tape Automated Bonding

载带自动键合 **75.1046**

用在载带上的导体实现芯片和基体材料之间互连的细间距技术。（见图T-1）。

Tape Carrier Package (TCP) **33.2077**

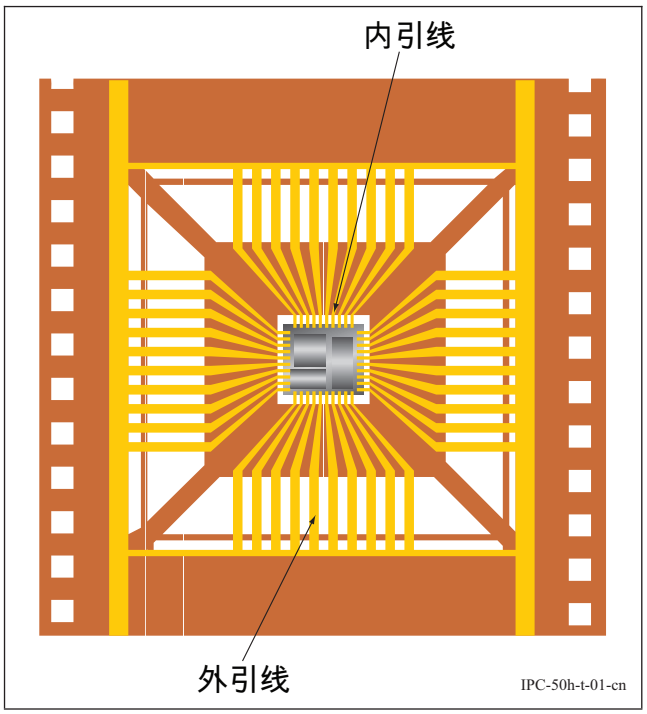
A semiconductor package that has the TAB connection and is coated by a resin.

载带封装（TCP） **33.2077**

具有TAB连接并且用树脂涂敷的半导体包装。

Taped Component **71.1541**

A component that is attached to a continuous tape in order to facilitate the use of automatic component incoming inspection, lead forming, assembling and testing.



图T-1 载带自动键合

带式元器件 **71.1541**

元器件附着于一根连续的带子上，以便自动进行元器件来料检验、引线成形、组装和测试。

Target Land (Via Bottom Land) **22.2117**

The land portion of a microvia connecting to an internal conductor. (See also “Capture Land.”)

目标连接盘（导通孔底部连接盘） **22.2117**

与内部导体连接的微导通孔的连接盘部分。见“Capture Land，诱捕连接盘”。

Tear (Base Materials) **96.2078**

A rip or split in either direction of the resin-coated reinforcement fabric in a base material dielectric structure.

撕裂（基材） **96.2078**

基材电介质结构内涂有树脂的增强织物任一方向上的裂缝或裂口。

Tear (Fabric) **44.1047**

A large rip in a fabric that is usually caused by excessive tension being applied during processing or caused by a weakness in the fabric.

撕裂（织物） **44.1047**

通常是由于加工过程中施加过大张力或织物强度低所造成的大裂口。

Temperature Delta (ΔT) **75.1672**
The range between upper and lower temperature limits as measured on a product (component, board or assembly) in a reflow heating process or end use environment.

温度差（ΔT） **75.1672**
在回流加热过程或者实际使用环境中，在一个产品（元器件，板或组件）上量测得的较高温度与较低温度之间的范围。

Temperature Leveling **75.2079**
A process to make the temperature difference across a board as uniform as possible by preheating the board, or through the heating and melting of solder used in component attachment.

温度均匀化 **75.2079**
通过预热板子或加热及熔化连接元器件所用焊料，使一块板子的温度尽可能一致的过程。

Temperature Profile **75.1048**
The depiction of the temperature that a selected point traverses as it passes through the reflow process.

温度曲线 **75.1048**
选定点通过再流工艺时所经历温度的描述。

Temperature, Reflow, Maximum **70.2080**
The maximum temperature that any portion of a product will reach during the reflow soldering process.

最高再流焊温度 **70.2080**
再流焊工艺期间产品任意一个部分将达到的最高温度。

Tenter Frame **44.1049**
A machine test maintains fabric width during drying by means of clips running on two parallel endless chains.

拉幅机 **44.1049**
利用在两个平行的循环链条上运行的布铗保持干燥期间织物宽度的机器。

Tenting **52.1050**
See “Via, Tented.”

掩蔽 **52.1050**
见“导通孔，掩蔽，Via, Tented。”

Terminal **37.1051**
A metallic device that is used for making electrical connections. (See also “Solder Terminal.”)

接线柱 **37.1051**
用来形成电气连接的金属装置。（又见“焊接接线柱，Solder Terminal”。）

Terminal Area **22.1052**
See “Land.”

终端区域 **22.1052**
见“连接盘，Land”。

Terminal Clearance Hole **22.1053**
See “Access Hole.”

终端隔离孔 **22.1053**
见“余隙孔，Access Hole”。

Terminal Hole **22.1054**
See “Component Hole.”

终端孔 **22.1054**
见“元器件孔，Component Hole”。

Terminal Pad **22.1055**
See “Land.”

终端焊盘 **22.1055**
见“连接盘，Land”。

Terminations **22.1773**
To connect a line to a terminal, distributing frame, switch or matrix.

端子 **22.1773**
其可实现导线与接线柱、分布框架、开关或矩阵转换电路的连接。

Terpenes **76.1774**
(Turpentine.) A solvent used in cleaning electrical assemblies.

萜烯 **76.1774**
用于清洗电子组件的溶剂（松节油）。

Test Board **92.1683**
A printed board or discrete-wiring board that is deemed to be suitable for determining the acceptability of a group of boards that were, or will be, produced with the same fabrication processes. (See also “Capability Test Board.”)

测试板 **92.1683**
被认为适合于确定用或将用相同加工工艺生产的一批板可接受性的印制板或分立线路板。（又见“能力测试板，Capability Test Board”。）

Test Coupon **92.1820**
A portion of quality conformance test circuitry that is used for a specific test, or group of related tests, in order to determine the acceptability of a product.

附连测试板 **92.1820**
用于特定测试或一组相关测试的质量符合性测试电路的一部分以确定产品的可接受性。

Test Coupon Set **92.2081**
A complement of test coupons that are comprised of various test coupon types, each of which is designed for a specific test, that are all made in the same manufacturing lot.

附连测试板组 **92.2081**
由各种类型的附连测试板组成的全套附连测试板，每一个附连测试板都为特定的测试所设计并且在相同的生产批中制造。

Test Language **92.1057**
A high-level language used to write a test program.

测试语言 **92.1057**
用于编写测试程序的高级语言。

Test Master **92.1058**
Artwork that contains specified anomalies or degrees of defect that an inspection or testing system should be capable of detecting.

测试原版 **92.1058**
包含一个检验或测试系统能够检测出的特定差异或缺陷程度的照相底图。

Test Pattern **92.1059**
A pattern that is used for inspection or testing purposes.

测试图形 **92.1059**
用于检验或测试的图形。

Test Point **92.1060**
A special point of access to an electrical circuit that is used for electrical testing purposes.

测试点 **92.1060**
连接电气电路的特定点，用作电气测试。

Test Program **92.1061**
The set of instructions to a tester that controls the unit under test.

测试程序 **92.1061**
指挥控制待测单元测试仪的一组指令。

Test Set **92.1062**
The unique combination of test programs and test fixtures that control the unit under test.

测试装置 **92.1062**
控制待测试单元的测试程序及测试夹具的特定组合。

Test Step **92.1063**
The application of a single input vector.

测试步骤 **92.1063**
单一输入向量的应用。

Testing Personnel **92.1056**
Those individuals that test products for the purpose of ascertaining the conformance of a product to applicable specifications.

测试人员 **92.1056**
为了判定产品与适用规范符合性的目的而测试产品的那些人员。

Tetrafunctional Resins **75.1064**
Materials that have four reactive groups per molecule.

四官能团树脂 **75.1064**
每个分子具有四个活性基团的材料。

Thermal Coefficient of Expansion (TCE) **21.1065**
See “Coefficient of Thermal Expansion (CTE).”

膨胀热系数（TCE） **21.1065**
见“热膨胀系数（CTE），Coefficient of Thermal Expansion（CTE）”。

Thermal Conductivity **20.1066**
The property of a material that describes the rate at which heat will be conducted through a unit area of the material for a given driving force.

热导率 **20.1066**
材料的一种性能，描述在给定驱动力下该材料单位面积传热的速率。

Thermal Cure **40.2082**
A chemical reaction using heat energy that hardens organic substances such as adhesives and coating materials.

热固化 **40.2082**
采用热能使有机物质如粘合剂和涂层材料固化的化学反应。

Thermal Expansion **21.2083**
Expansion of the material when subjected to a temperature increase.

热膨胀 **21.2083**
温度升高时材料的膨胀。

Thermal Mismatch (Expansion) **20.1067**
The absolute difference between the thermal expansion of two materials that are bonded together. (See also "Coefficient of Thermal Expansion (CTE).")

热膨胀不匹配 **20.1067**
两种接合在一起的材料之间热膨胀的绝对差。（又见“热膨胀系数，Coefficient of Thermal Expansion (CTE)”。）

Thermal Mismatch **21.2084**
Difference in coefficients of thermal expansion of materials that are bonded together.

热失配 **21.2084**
连接在一起的材料的热膨胀系数有差异。

Thermal Plane **22.2085**
See "Heatsink Plane."

散热层 **22.2085**
见“散热层，Heatsink Plane”。

Thermal Relief **22.1068**
A designed partial clearance around holes that are subject to soldering in large conductor areas (ground planes, voltage planes, thermal planes, etc.). Relief is required to provide thermal resistance during the soldering process. (See Figure T-2.)

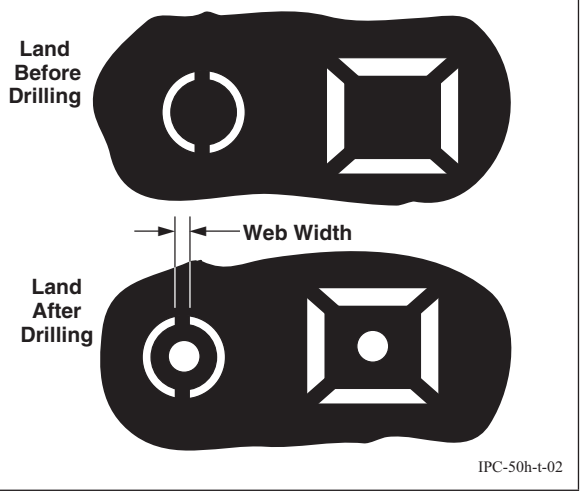
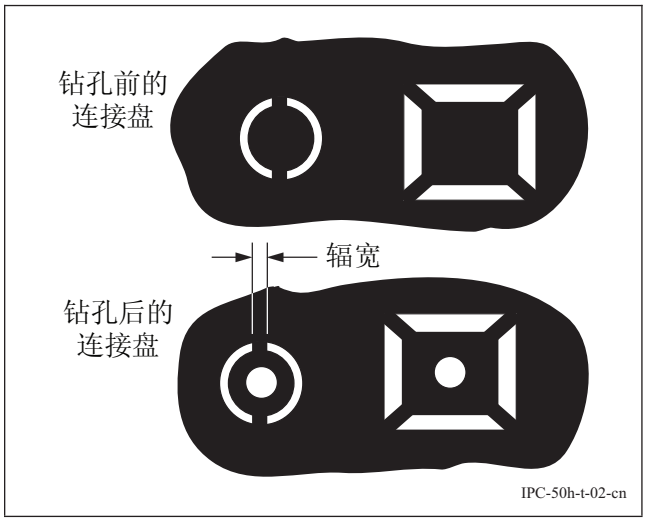


Figure T-2 Thermal Relief

热隔离 **22.1068**
在经受焊接的大导体面（接地层、电源层、散热层等）的孔周围所设计的局部间隙。在焊接过程中热隔离起到阻止热量流失的作用。（见图T-2。）



图T-2 热隔离

Thermal Resistance **21.2086**
The resistance of a material to the passage of thermal energy usually measure in °C/W.

热阻 **21.2086**
材料对热能传递的阻抗，测量单位通常为ºC/W。

Thermal Shock Resistance **21.2087**
A measure of how well a material stands up to rapid changes in temperature.

耐热冲击 **21.2087**
材料承受温度快速变化的能力的量度。

Thermal Shock Test **92.2088**
One of the environmental tests to check the property changes of a product or material caused by rapid heating and cooling.

热冲击测试 **92.2088**
检查由于快速加热和冷却而导致的产品或者材料特性变化的一种环境测试。

Thermal Shunt **30.1069**
See "Heatsink."

热分流 **30.1069**
见“散热片，Heatsink”。

Thermal Sonic Bonding **74.2089**
The bonding of wires to metal pads on an integrated circuit by means of heat and ultrasonic scrubbing of wire into the pad to create a metallurgic bond.

热超声键合 **74.2089**

利用热和超声刮擦焊盘内的金属线，使金属线与集成电路上的金属焊盘键合而形成金属键。

Thermal Zone **50.1542**

A metal-integrity evaluation zone that extends a specified distance beyond the ends of the lands in a microsection of a vertical portion of a plated-through hole. (Unless otherwise specified, the extended distance is 0.08 mm [0.003 in].)

受热区 **50.1542**

金属完整性评价区，即从镀覆孔纵向横截面内的连接盘末端向外延伸规定距离。（除非另有规定，延伸距离为0.08mm[0.003in]。）

Thermocompression Bonding **74.1543**

The joining together of two materials without an intermediate material by the application of pressure and heat in the absence of electrical current.

热压键合 **74.1543**

无需中间材料及电流，通过施加压力和热量将两种材料结合在一起。

Thermode **75.1070**

A contact heating element that is used to generate reflow soldering heat.

热电极 **75.1070**

用于产生再流焊接热量的接触式加热元器件。

Thermode Temperature Gradient **75.2090**

The temperature difference between one end of a thermode and the other after steady-state temperatures are attained.

热电极温度梯度 **75.2090**

达到恒定温度后，热电极一端与另一端之间的温度差别。

Thermode Temperature Variation **75.2091**

The maximum difference of temperatures of a point on a controlled-temperature thermode over a period of time.

热电极温度变异 **75.2091**

一个周期时间内，温控热电极上一个点温度的最大差别。

Thermoplastic **40.1071**

A plastic that can be repeatedly softened and reshaped, without any significant change in inherent properties, by exposure to heat and hardened by cooling.

热塑性塑料 **40.1071**

加热时能够反复软化和再成形，固有特性不会有显著改变，且冷却时会硬化的塑料。

Thermoset **40.1544**

A plastic that undergoes a chemical reaction when exposed to elevated temperatures that leads to it having a relatively infusible or crosslinked stated that cannot be softened or reshaped by subsequent heating.

热固性塑料 **40.1544**

暴露于高温下时会发生化学反应的一种塑料，使其具有相对不熔或交联的状态，在后续加热时不会软化或再成形。

Thermosonic Bonding **74.1072**

Terminations made by combining thermocompression and ultrasonic bonding principles.

热超声键合 **74.1072**

利用热压和超声波键合形成的端子。

Thick Film **45.1545**

A film, greater than 0.1 mm [0.004 in] thick, deposited by screen printing and subsequently fired at high temperatures in order to fuse it into its final functional form.

厚膜 **45.1545**

厚度大于0.1mm[0.004in]的膜，通过丝印沉积，然后在高温下烧结，以熔合达到最后的功能形态。

Thick-Film Circuit **83.1073**

A microcircuit in which passive components of a ceramic-metal composition are formed on base material by screening and firing.

厚膜电路 **83.1073**

通过丝印和烧结在基材上形成陶瓷-金属成份无源元器件的微电路。

Thick-Film Hybrid Circuit **83.1074**

A hybrid circuit with thick-film components and interconnections.

厚膜混合电路 **83.1074**

具有厚膜元器件及互连的混合电路。

Thick-Film Network **83.1075**

A hybrid circuit comprised only of thick-film components and interconnections.

厚膜网络 **83.1075**

仅由厚膜元器件及互连组成的混合电路。

Thin Film **45.1079**

A film, less than 0.1 mm [0.004 in] thick, deposited by accretion process, such as vacuum or pyrolytic deposition.

薄膜 **45.1079**

厚度小于0.1mm[0.004in]的膜，由加积工艺如真空或热解沉积法沉积形成。

Thin-Film Hybrid Circuit **83.1076**

A hybrid circuit with thin-film components and interconnections. (See also “Hybrid Circuit.”)

薄膜混合电路 **83.1076**

具有薄膜元器件及互连的混合电路。（又见“混合电路，Hybrid Circuit”。）

Thin-Film Integrated Circuit **83.1077**

A hybrid integrated circuit comprised only of thin-film components and interconnections. (See also “Hybrid Integrated Circuit.”)

薄膜集成电路 **83.1077**

仅由薄膜元器件及互连组成的混合集成电路。（又见“混合集成电路，Hybrid Integrated Circuit”。）

Thin-Film Network **83.1078**

A hybrid circuit comprised only of thin-film components and interconnections.

薄膜网络 **83.1078**

仅由薄膜元器件及互连组成的混合电路。

Thin Foil **45.1080**

A metal sheet that is less than 0.02 mm [0.0007 in] thick.

薄金属箔 **45.1080**

厚度小于0.02mm[0.0007in]的金属薄片。

Thin Quad Flat Pack (TQFP) **33.2092**

A surface mount family of integrated circuit packages with a thin polymer body.

薄方形扁平封装（TQFP） **33.2092**

具有薄聚合体的表面贴装系列集成电路封装。

Thin Small Outline Package (TSOP) **33.2093**

A package that has the same features as the SOP package except that its thickness is reduced to 0.8 -1.2 mm [0.0315 - 0.0472 in].

薄小外形封装（TSOP） **33.2093**

具有与SOP封装相同特征，但其厚度减少至0.8mm-1.2mm[0.0315in-0.0472in]的封装。

Thinner (Liquid) **76.1081**

A nonactivated solvent or solvent system that is used to replace evaporated solvent and to reduce the solids content of another substance.

稀释剂（液体） **76.1081**

非活性溶剂或溶剂系统，用于补充蒸发的溶剂和减少另一种物质中的固体含量。

Thixotropic Ratio **49.1082**

An indication of thixotropy in the form of the ratio of viscosities measured at two different shear rates.

触变率 **49.1082**

以在两种不同的剪切速率下测得的粘性之比表示触变性的指标。

Thixotropy **49.1083**

A property of a substance, e.g., an adhesive system, that allows it to get thinner upon agitation and thicker upon subsequent rest.

触变性 **49.1083**

物质的一种特性，如粘合剂系统，在搅动时变得较稀，而在停止时变得较稠。

Three-Layer Carrier Tape **36.1546**

The carrier for conductors used in tape-automated bonding that consists of a dielectric layer, an adhesive, and a etched metal-foil conductor layer. (See also “Multilayer Carrier Tape,” “Single-Layer Carrier Tape,” and “Two-Layer Carrier Tape.”)

三层载带 **36.1546**

载带自动键合中所用导体的载体，由绝缘层、粘合层和蚀刻的金属箔导体层组成。（又见“多层载带，Multilayer Carrier Tape”、“单层载带，Single-Layer Carrier Tape”和“双层载带，Two-Layer Carrier Tape”。）

Threshold **21.1084**

The magnitude of intensity that delineates that a signal is representative of a changed state.

阀值 **21.1084**

描述代表变化状态的信号强度的幅度。

Through Connection **22.2094**

The electrical connection to connect conductor patterns on the front side through to the back side of a printed board. See “Interfacial Connection.”

贯穿连接 **22.2094**
印制板两面导电图形的电气连接。（又见“界面连接，Interfacial Connection”。）

Through-Hole Mounting **72.1085**
See ‘Through-Hole Technology (THT).”

通孔插装 **72.1085**
见“通孔组装技术，Through-Hole Technology (THT)”。

Through-Hole Technology (THT) **50.2095**
The electrical connection of components to a conductive pattern by the use of component holes.

通孔组装技术（THT） **50.2095**
利用元器件孔实现元器件与导电图形的电气连接。

Through Migration **90.1087**
See “Dendritic Migration.”

穿透迁移 **90.1087**
见“树枝状迁移，Dendritic Migration”。

Throwing Power **53.2096**
The degree to which a given solution uniformly deposits the plating on any configuration of hole or circuitry pattern and panel shape or thickness.

布散能力 **53.2096**
给定溶液在任何形状的孔或电路图形及任何形状或厚度在制板上均匀沉积镀层的能力。

Tie Bar **53.1088**
See “Plating Bar.”

分流线 **53.1088**
见“电镀工艺导线，Plating Bar”。

Tie-In Tab **62.2138**
A piece of flexible or rigid-flex material left on the board in the form of a tab which continues to hold the finished board within the panel during routing of the flexible material.

连接条 **62.2138**
铣加工挠性材料时，以小片形式留在板子上的一片挠性或刚挠材料，以使成品板留在在制板上。

Tinning **71.1089**
The application of molten solder to a basis metal in order to increase its solderability.

上锡 **71.1089**
将熔融焊料涂敷到金属基材上以增加其可焊性。

Titrometry **92.1090**
See “Volumetric Analysis.”

滴定分析 **92.1090**
见“容量分析，Volumetric Analysis”。

Tolerance **26.1091**
The total amount by which a specific dimension is permitted to vary.

公差 **26.1091**
标定尺寸允许偏离的总量。

Tolerance, Statistical **26.2097**
A tolerance that is based on statistical models.

统计公差 **26.2097**
基于统计模式的公差。

Toleranced Dimension **26.1092**
A dimension with a directly applied tolerance.

带公差尺寸 **26.1092**
直接加入了公差的尺寸。

Tombstoned Component **73.1093**
A defect condition whereby a leadless device has only one of its metallized terminations soldered to a land and has the other metallized termination elevated above and not soldered to its land. (See Figure T-3.)

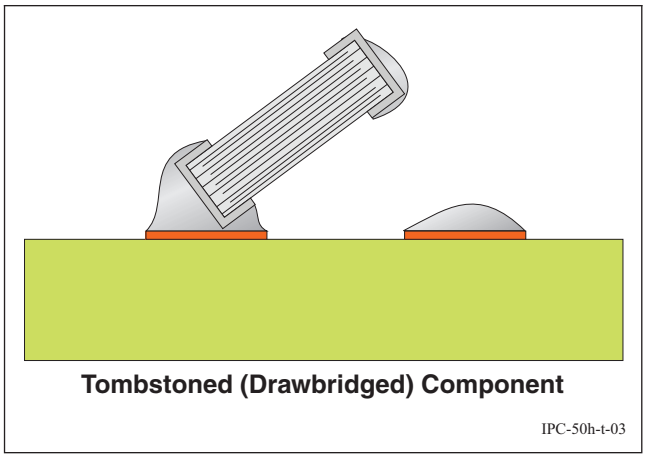
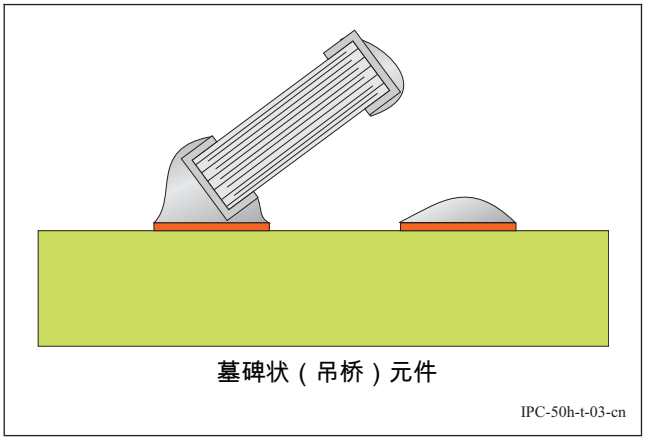


Figure T-3 Tombstoned Component

墓碑状元器件 **73.1093**
一种元器件组装缺陷状况，无引线元器件只有一个金属化端接点焊接在其焊盘上，另一个金属化端接点却抬高，没有焊接在其焊盘上（见图T-3）。



图T-3 墓碑状元件

Tooling Feature **22.1547**
A physical feature that is used exclusively to position a printed board or panel during a fabrication, assembly or testing process. (See also "Locating Edge," "Locating Edge Marker," "Locating Notch," "Locating Slot," and "Tooling Hole.")

定位要素 **22.1547**
在制作、组装、测试过程中专门用来定位线路板或在制板的物理要素。（又见"定位边，Locating Edge"、"定位边标记，Locating Edge Marker"、"定位切口，Locating Notch"、"定位槽，Locating Slot"和"Tooling Hole，定位孔"。）

Tooling Hole **22.1094**
A tooling feature in the form of a hole in a printed board or fabrication panel.

定位孔 **22.1094**
印制板或在制板中孔形式的定位要素。

Torsional Strength **74.1095**
The torque required to separate adhesive-bonded (and cured) materials and/or components. (See also "Lap Shear Strength" and "Shear Strength.")

抗扭强度 **74.1095**
分离用粘合剂粘接（已固化）的材料和/或元器件所需要的扭矩。（又见"搭接剪切强度，Lap Shear Strength"和"剪切强度，Shear Strength"。）

Touch-Up **92.1097**
The identification and elimination of defects in a product.

修版 **92.1097**
识别并消除产品中的缺陷。

Trace **22.1098**
See "Conductor."

轨迹 **22.1098**
见"导体，Conductor"。

Traceability **16.2174**
The tracking of the manufacturer at a minimum or the manufacturing process of each element used in a unit.

可追溯性 **16.2174**
对最低一级制造商或一个部件中所用每种元素的制造工艺的追溯。

Track **22.1099**
See "Conductor."

路径 **22.1099**
见"导体，Conductor"。

Tracking Resistance **92.2098**
See "Arc Resistance."

耐电痕性 **92.2098**
见"耐电弧性，Arc Resistance"。

Transfer Adhesive (Pressure Sensitive Tape) **75.2099**
An unsupported pressure sensitive adhesive coated onto a release treated carrier. The adhesive is then applied to the desired substrate and the release liner removed before assembly.

转移粘接剂（压敏胶带） **75.2099**
在处理过的脱模载体上涂覆无支撑压敏粘接剂，然后将粘接剂施加到所需的基板上，再在组装之前去除可剥离衬底。

Transfer-Bump Tape Automated Bonding **74.1100**
Tape automated bonding that uses discrete bumps between the die lands and carrier tape to facilitate inner-lead bonding.

转移凸点载带自动键合 **74.1100**
为便于内部引线键合，在芯片连接盘与载带之间采用分离凸点的载带自动键合。

Transfer Soldering **75.1101**
The use of a soldering iron to transfer a measured amount of solder, in the form of a ball, chip, or disc, to a solder connection.

转移焊接 **75.1101**
用烙铁将球形、片状或圆片状等定量的焊料转移至焊接连接。

Transmission Cable **21.1102**
Two or more transmission lines in the form of an interconnection-wiring cable.

传输电缆 **21.1102**

两根以上的传输线形成的一种互连电缆。

Transmission Line **21.1103**

A device for guiding or conducting electromagnetic energy from one point to another. A transmission line consists of two or more parallel conductors each separated by a dielectric. (See also “Balanced Transmission Line,” “Microstrip” “Stripline,” and “Unbalanced Transmission Line.”)

传输线 **21.1103**

将电磁能从一点传导到另一点的装置。传输线由两根以上的通过电介质隔离的平行导体组成。（见“平衡传输线，Balanced Transmission Line”、“微带，Microstrip”、“带状线，Stripline”、“非平衡传输线，Unbalanced Transmission Line”。）

Transmissivity **24.2101**

The percentage of incident energy that is transmitted into a material.

透射率 **24.2101**

发射到材料内的入射能量百分比。

Transmittance **24.1104**

The ratio of the amount of light that is transmitted through an object or material to the quantity of light that is incident upon it.

透光率 **24.1104**

透过物体或材料的光量与照射在其上的光量之比。

Tray **70.2102**

A pallet shape that contains SMD components in a form that makes it easy to feed them to an automatic component mounting machine.

盘 **70.2102**

用来盛装SMD元器件的托盘，其形式便于将元器件供给自动元器件贴装机。

Treater Dirt (Base Materials) **44.2103**

An inclusion which appears to be or is confirmed by analysis to be a type of resin particle which has been caught within the structure of the impregnation treater, to be picked up by a subsequent use of the treater; usually in some form of carbonization due to excessive exposure to the treaters heat.

浸胶异物（基材） **44.2103**

被浸胶槽的构件所挡住而形成的似乎是或经分析确认是树脂粒子外来夹杂物，由于过度暴露于处理器的热量下通常以碳化物的形式存在，在后续使用浸胶槽时，要先去除这些异物。

Treatment Transfer **92.1548**

The transfer of copper-foil treatment to a base material as indicated by the presence of black, brown or red streaks after the copper has been removed by etching.

处理物转移 **92.1548**

铜箔处理物处转移到基材上，铜箔被蚀刻去除后显示出黑色、棕色或红色的条纹。

Treatment Transfer (Base Materials) **44.2104**

A dark streak or pattern of streaks within the core butter coat that is formed by the transfer of oxide treatment from the copper foil that may be linear, with the grain of the foil or crescent shaped (due to handling of the foil) and very occasionally of a fine 50 mm [1.97 in] regularly spaced streaky pattern (due to specially configured rollers in the foil treating process).

处理物转移（基材） **44.2104**

由于从铜箔上转移处理氧化物而形成的芯板涂层内的暗条纹或图形，可能为铜箔颗粒状或月牙状（由铜箔处理导致），偶尔出现规则间距50mm[1.97in]的条纹图形（由铜箔处理过程中特殊结构的滚筒导致）。

Treeing **53.1549**

A dendritic-type of plating growth that extends onto the surface that is adjacent to the edge of a conductive pattern. (This is normally caused by excessive plating current.)

树枝状结晶 **53.1549**

镀层在相邻导电图形边缘的表面上镀层长出树枝状结晶。（通常是由于电镀电流过大造成。）

Tri-State **21.1105**

A high-impedance state of an electronic device that effectively disconnects the device output from all other circuitry.

三态 **21.1105**

电子器件的高阻抗状态，可以有效地切断该器件对全部其他电路的输出。

Trim Lines (Pattern) **22.1106**

Lines that define the borders of a pattern. (See also “Corner Marks.”)

外形线（图形） **22.1106**

标定图形边界的线。（又见“角标，Corner Marks”。）

Trim Lines (Printed Board) **22.1550**

Lines that delineate the border of a printed board. (See also “Corner Marks.”)

外形线（印制板） **22.1550**

勾划出线路板边界的线。（又见“角标，Corner Marks”。）

Trimming **77.1108**

The cutting of a film component by a laser beam or abrasive jet in order to modify its value.

修整 **77.1108**

用激光束或磨料射流切割膜元器件以修整它的值。

Trimming Notch **77.1109**

See “Kerf.”

修整槽口 **77.1109**

见“切口，Kerf”。

True Position **22.1110**

The theoretically-exact location for a feature or hole that is established by basic dimensions.

准确位置 **22.1110**

由基本尺寸建立的要素或孔的理论准确位置。

True Position Tolerance **22.1111**

The total permissible deviation from a true position.

准确位置公差 **22.1111**

准确位置所允许的总偏差。

Trumeter **44.1112**

A device used to accurately measure yardage passing a specific point of reference.

精度测量计 **44.1112**

用于精确测量通过一个特定参考点的尺码的装置。

Truth-Table Testing **21.1551**

The application of electrical signals in accordance with a prescribed logic matrix pattern that indicates the outputs that should result from a given pattern of inputs.

真值表测试 **21.1551**

根据表示应来自于输入的给定图形的输出的规定逻辑矩阵图形采用电气信号。

Tuberculation **76.1113**

The formation of localized corrosion products that are scattered over a surface in the form of knob-like mounds.

结节 **76.1113**

产品受局部腐蚀在表面散开形成的节状物。

Tunnel Void, (Base Materials) **96.2032**

A thin vein or fine white line that appears to be within the fiber bundles of the reinforcement, usually a narrow pocket formed by poor nonwetting of a small area of the fiber bundle by the resin. Severe circumstances may result in “silver streaks” seen in the reinforcement.

管状空洞（基材） **96.2032**

增强材料纤维束中呈现的细条纹或细白线，通常为树脂没有润湿小范围的纤维束而造成的窄槽。状况严重时可能会导致在增强材料中看到“银条纹”。

Turnkey System **11.1114**

A self-contained hardware and software system that perform a specific task.

总成系统 **11.1114**

可执行特殊任务的独立的硬件和软件系统。

Turret Solder Terminal **37.1552**

A round post-type stud (stand-off) solder terminal with a groove or grooves around which one or more wires are wrapped prior to soldering. (See Figure T-4.)

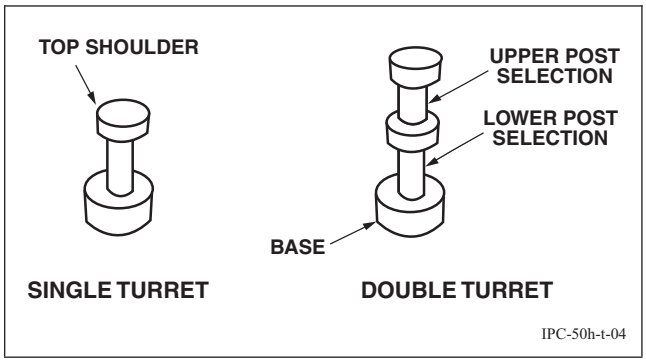
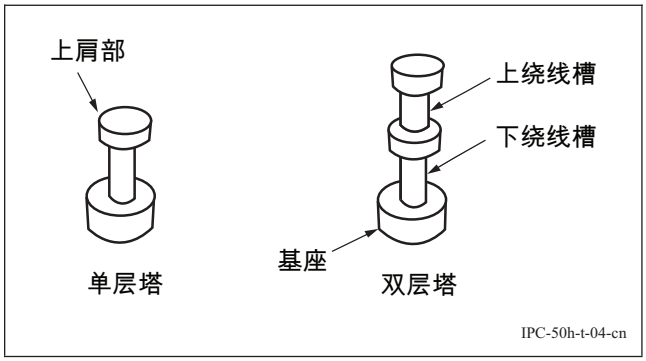


Figure T-4 Turret Solder Terminal

塔形焊接接线柱 **37.1552**

有凹槽的圆柱状（高脚）焊接接线柱，焊接前一根或多根导线可缠绕在槽周围。（见图T-4。）



图T-4 塔形焊接接线柱

Twist **60.1553**

The deformation of a rectangular sheet, panel or printed board, that occurs parallel to a diagonal across its surface, such that one of the corners of the sheet is not in the plane that contains the other three corners.

扭曲 **60.1553**

矩形薄片、在制板或印制板的变形，其与横跨其表面的对角线平行，板的三个角与平面接触，而另一个角不在该平面内。

Two-Layer Carrier Tape **36.1554**

The carrier for conductors used in tape-automated bonding that consists of a dielectric layer with a layer of plated/etched conductors. (See also "Multilayer Carrier Tape," "Single-Layer Carrier Tape," and "Three-Layer Carrier Tape.")

双层载带 **36.1554**

用于载带自动键合的导体载体，由绝缘层和电镀/蚀刻导体层组成。（又见“多层载带，Multilayer Carrier Tape”、“单层载带，Single-Layer Carrier Tape”和“三层载带，Three-Layer Carrier Tape”。）

Two-Piece Contact **37.1115**

A type of discrete connector contact that mates with another discrete formed-metal connector contact. (See also "Edge-Board Contact.")

两件式接触件 **37.1115**

一种分立连接器接触件，可与另一个分立金属成形连接器接触件配接。（又见“板边接触片，Edge-Board Contact”。）

Two-Sided Board **60.1116**

See "Double-Sided Board."

两面板 **60.1116**

见“双面板，Double-Sided Board”。

Type I Error **91.1117**

The rejection of a hypothesis that is true.

I类错误 **91.1117**

原假设为真时而被拒绝。

Type II Error **94.1118**

The accepting of a hypothesis that is false.

II类错误 **94.1118**

原假设为假时而被接受。

U

Ultra-Fine Pitch Technology **80.2105**

A surface-mount assembly technology with component terminations on centers less than or equal to 0.40 mm.

超细间距技术 **80.2105**

元器件焊端中心距小于或等于0.40mm的表面贴装技术。

Ultrasonic Bond **75.2106**

A bond formed when a wire is pressed against the bonding pad and the pressing mechanism is ultrasonically vibrated at high frequency (above 10kHz).

超声键合 **75.2106**

采用超声高频（10 kHz以上）振动压合装置将金属线压在键合盘上而形成的键合。

Ultrasonic Bonding **74.1119**

A termination process that uses ultrasonic-frequency vibration energy and pressure to make the joint.

超声键合 **74.1119**

采用超声频率振动能和压力形成接合点的端接工艺。

Ultrasonic Cleaning **76.1120**

Immersion cleaning that is done by passing high-frequency sound waves through a cleaning medium to cause micro agitation.

超声清洗 **76.1120**

由高频声波通过清洗媒介产生微振动而进行的浸渍清洗。

Ultrasonic Soldering **75.1121**

Fluxless soldering wherein molten solder is vibrated at ultrasonic frequencies while making the joint.

超声焊接 **75.1121**

熔融焊料在超声波频率下振动形成焊点的无助焊剂焊接。

Ultraviolet Cure **40.2107**

A cure of material by exposure to ultraviolet light.

紫外线固化 **40.2107**

通过暴露于紫外光下实现材料的固化。

Unbalanced Transmission Line **21.1556**

A transmission line that has distributed inductance, capacitance, resistance, and conductance elements that are not equally distributed between its conductors.

非平衡传输线 **21.1556**
在其导体之间具有不均匀分布的电感、电容、电阻和电导元器件的传输线。

Uncased Device **35.1122**
A component without a package.

无外壳器件 **35.1122**
没有封装的器件。

Unconditional Test **92.1123**
A test without limitations or restrictions on test mode, test time, etc.

无条件测试 **92.1123**
对测试模式、测试时间等没有限制或约束的测试。

Under Bump Metallization **35.2108**
The solder-wettable terminal area that defines the metallurgy size and area of a soldered connection, such as a solder bump.

凸点底部金属化 **35.2108**
界定了金属化尺寸和焊接连接区域的焊料可浸润端子区域，如焊料凸点。

Undercut, After Fabrication **92.1124**
The distance, measured parallel to the surface of a printed board, from the outer edge of a conductor (excluding overplating and coatings) to the maximum point of the indentation on the same edge of the conductor. (See also “Undercut, In Process” and Figure O-2.)

加工后侧蚀 **92.1124**
从导体一侧外边缘（不包括外镀层和涂层）到同一侧导体的最大凹入点与板面平行的间隔距离。（又见“制程中侧蚀，Undercut, In Process”及图O-2。）

Undercut, In Process **92.1125**
The distance, measured parallel to the surface of a printed board, from the outer edge of a conductor (including etch resist) to the maximum point of the indentation on the same edge of the conductor. (See also “Undercut, After Fabrication.”)

制程中侧蚀 **92.1125**
从导体一侧外边缘（包括抗蚀刻剂）到同一侧导体的最大凹入点与板面平行的间隔距离。（又见“加工后侧蚀，Undercut, After Fabrication”及图O-2。）

Undercut, Resist or Masking Material **54.2109**
A groove or a hollow formed on the side wall of a conductor pattern caused by etching.

蚀刻剂或掩模材料侧蚀 **54.2109**
由于蚀刻造成导电图形侧壁的凹槽或凹陷。

Underplate **53.2110**
The plating made as a base of a surface over-plating usually required as a barrier to prevent leeching of two dissimilar metals into one another.

基底镀层 **53.2110**
作为表面镀层基底的镀层，通常作为防止两种不同金属相互浸析的隔离层。

Underwriters Symbol **94.1126**
A logotype that denotes that a product has been recognized (accepted) by Underwriters Laboratories, Inc. (UL).

安全检测标记 **94.1126**
用来表示产品已经被美国安全检测实验室公司认可（验收）的标记。

Unfil **44.1127**
A device attached to the loom which automatically winds yarn onto quills from yarn packages and maintains a supply of quills for the shuttle.

纡子 **44.1127**
安装在织机上的装置，可自动将纱线从纱线包绕至线轴上并保证将成批纱线提供给织梭。

Unilateral Tolerance **26.2111**
A tolerance in which variation is permitted in one direction only from the specified dimension.

单向公差 **26.2111**
只允许规定的尺寸单方向变化的公差。

Unload Time **92.1128**
The time required to remove a unit from the evaluation equipment, to collect the evaluation data, and to make the system ready for the next unit.

卸载时间 **92.1128**
从评定设备上取下一个单元、收集评定数据并使系统准备好测试下一个单元所需要的时间。

Unsupported Hole **22.1129**
A hole in a printed board that does not contain plating or other type of conductive reinforcement.

非支撑孔 **22.1129**
印制板上无镀层或其它类型导电增强材料的孔。

Upload (Test) **92.1130**
The ability of an analyzer to accept test program data from a host computer.

加负载（测试） **92.1130**
分析仪从主机接受测试程序数据的能力。

Usable Resolution **52.1131**
The smallest image and separation that can be produced, and subsequently processed, in a given emulsion or thickness of photoresist.

有效解像度 **52.1131**
在给定的感光乳胶或光刻胶厚度中可产生并可被后续加工的最小图像及间隔。

User **17.2112**
The individual, organization, company or agency responsible for the procurement of electrical/electronic hardware, and having the authority to define the class of equipment and any variation or restrictions (i.e., the originator/custodian of the contract detailing these requirements).

用户 **17.2112**
负责采购电气/电子部件的个人、组织、公司、合同指定的管理机构或代理，他们有权确定设备级别，提出修 改或限制。（也就是规定详细需求合同的制定者/管理者。）

User Inspection Lot (Material) **91.1132**
All of the material of the same type and, as far as practical, of the same type designation that is produced from the same equivalent batches or lots of constituent material under essentially the same conditions and that is offered for inspection at one time.

用户检验批（材料） **91.1132**
供给一次检验的相同类型，更确切的说，相同批次下生产出的具有相同类标识的所有材料，或在本质上为相同条件下构成的材料批。

V

V-Groove **54.1960**
A mechanical method that removes a portion of the material outlining the board, in order to facilitate ease of breakout (removal) from the manufacturing or assembly panel. (See also “Breakaway.”)

V形槽 **54.1960**
为了使板子便于与在制板或组装板分离，去除板子外围部分材料的机械方法。（又见“分离，Breakaway”。）

Vacuum Evaporation **53.1133**
The deposition of a metal film onto a base material by evaporation techniques.

真空蒸镀 **53.1133**
在真空中通过蒸发技术在基材上沉积上一层金属膜。

Vacuum Head **73.1775**
A handling instrument with a small vacuum cup which is used to pick up chip devices and other surface mounting devices.

真空头 **73.1775**
用于拾取夹片器件和其它表面贴装元器件的处理工具。

Vapor Phase Reflow **75.2113**
See “Vapor Phase Soldering.”

汽相再流 **75.2113**
见“汽相焊接，Vapor-Phase Soldering”。

Vapor-Phase Soldering **75.1557**
A reflow soldering method that is based on the exposure of the parts to be soldered to hot vapors of a liquid that has a boiling-point that is sufficiently high to melt the solder being used.

汽相焊接 **75.1557**
使被焊接部件暴露在其沸点足以使所用焊料融化的液体热蒸汽中的再流焊接方法。

Vapor Recovery **76.2114**
The retrieving of working fluid vapors and aerosols from scavenged air and turning them into reusable working fluids.

蒸汽回收 **76.2114**
从废气中回收工作液蒸气及悬浮物并使其转变成可重新使用的工作液。

Vapor, Saturated **75.2115**
A fluid in its vapor state when it is being heated at a constant pressure at or above its boiling temperature.

饱和蒸汽 **75.2115**
在恒定压力或在沸点以上时被加热的蒸汽状态下的液体。

Variables Data **91.1134**
Quantitative data where measurements are used for analysis.

变量数据 **91.1134**
测量用于分析的定量数据。

Variance **91.1135**

A measure of dispersion that is equal to the square of the average value of deviation from a mean value.

方差 **91.1135**

离散度的量度，标准离差的平方

Vendor Inspection Lot (Material) **91.1558**

All of the material of the same type that have been fabricated within a specified period of time using the same processing procedures and conditions that are offered for inspection at one time.

供应商检查批（材料） **91.1558**

在规定时间周期内、采用同一制程工序和条件制作的用于同一次检查的所有相同型号的材料。

Verification Time **91.1136**

The time required to determine an anomalies location, to evaluate it, and to classify it with respect to predefined criteria.

验证时间 **91.1136**

确定一个异常的位置、对其进行评定及根据预先确定的标准对其分类所需要的时间。

Very Large Scale Integration (VLSI) **30.1559**

Integrated circuits with more than 80,000 transistors on a single die that are interconnected with conductors that are 1 micron or less in width.

甚大规模集成电路 **30.1559**

在单个芯片上的晶体管多于80,000个，通过宽度为1 μm或更细的导体实现其互连的集成电路。

Vesical **92.1137**

A blister formed as the result of vesication.

疱 **92.1137**

由于起疱导致的分层。

Vesication **92.1560**

The formation of blisters at the interface between a semipermeable polymer film coating another material caused by an osmotic effect from the interaction of water soluble matter with moisture. (See also “Measling.”)

起疱 **92.1560**

在一种半渗透性聚合膜与另一种材料的界面之间，由于有潮气的水溶性物质相互作用引发的渗透效应而形成的起泡。（又见“白斑，Measling”。）

Vesicativity Ratio **92.1561**

The ratio of the degrees of vesication produced by a specific mass of a substance to the degree of vesication produced by the same mass of sodium chloride under the same specific conditions.

起泡率 **92.1561**

在相同的特定条件下，一定量的某种物质产生疱的程度与同样量氯化钠产生疱的程度的比率。

Via **22.1562**

A plated-through hole that is used as an interlayer connection, but in which there is no intention to insert a component lead or other reinforcing material. (See also “Blind Via” and “Buried Via.”)

导通孔 **22.1562**

用于内层连接, 但并不插装元器件引线或其他增强材料的镀通孔。（又见“盲孔，Blind Via”和“埋孔，Buried Via”。）

Via, Filled (Type V Via) **22.1828**

A via with material applied into the via targeting a full penetration and encapsulation of the hole.

填塞导通孔（V型导通孔） **22.1828**

将材料涂敷到导通孔内，旨在形成填满材料的孔。

Via, Filled and Capped (Type VII Via) **22.1826**

A Type V via with a secondary metallized coating covering the via. The metallization is on both sides.

填塞及遮蔽导通孔（VII型导通孔） **22.1826**

用辅助金属化涂层覆盖导通孔的第5种导通孔。在孔的两面都有金属层。

Via, Filled and Covered (Type VI Via) **22.1827**

A Type V via with a secondary covering of material (liquid or dry film solder mask) applied over the via. It may be applied from either one side or both sides.

填塞及覆盖导通孔（VI型导通孔） **22.1827**

用辅助覆盖材料(液体或干膜阻焊膜)涂敷在导通孔上的第5种导通孔。可从任一面或双面涂敷孔。

Via Planarization **22.2147**

The process of removing metallization and/or organic materials associated with the surface of a via structure. It is most commonly employed in filled via fabrication. (See Figure V-1.)

导通孔平整化 **22.2147**

去除导通孔表面的金属层和/或有机材料的过程。该方法常用于填充导通孔的制作。（见图V-1）。

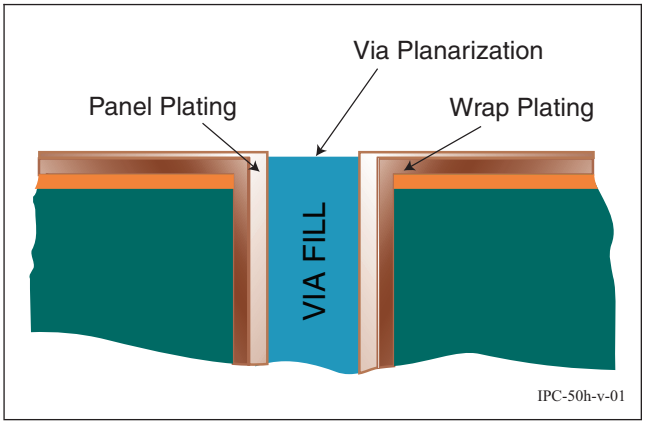
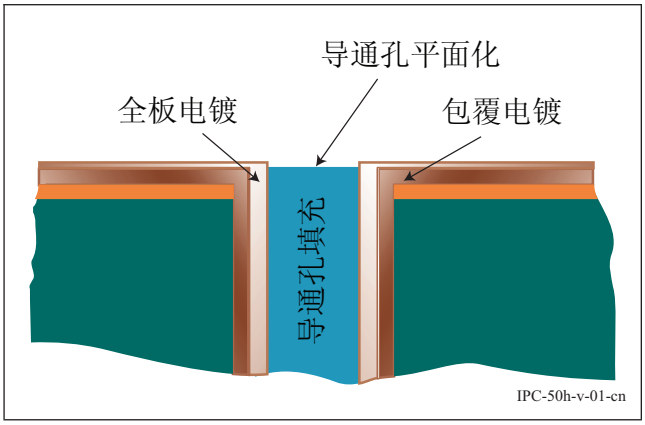


Figure V-1 Via Planarization



图V-1 导通孔平整化

Via, Plugged (Type III Via) **22.1830**
A via with material applied allowing partial penetration into the via. It may be applied from either one side or both sides

堵塞导通孔（III型导通孔） **22.1830**
允许材料部分渗到孔内的导通孔。可从任一面或及双面施加材料。

Via, Plugged and Covered (Type IV Via) **22.1829**
A Type III via with a secondary covering of material applied over the via. The secondary covering may be applied from either one side or both sides.

堵塞及覆盖导通孔（IV型导通孔） **22.1829**
用辅助材料覆盖在导通孔上的第3种导通孔。可从任一面或及双面施加材料。

Via Protection, Bumped **22.2081**
Via protection where the hole plugging or fill material protrudes above the surface of the hole interface producing a convex shape.

导通孔保护，凸面 **22.2081**
孔填塞或填充材料突出于孔表面形成凸面，实现导通孔保护。

Via Protection, Dimpled **22.2082**
Via protection where the hole plugging or fill material recedes below the hole interface producing a concave shape.

导通孔保护，凹面 **22.2082**
孔填塞或填充材料凹陷于孔表面形成凹面，实现导通孔保护。

Via Protection, Planarized **22.2083**
Via protection where the excess hole plugging or fill material protruding above the hole interface has been removed by a process to produce a coplanar surface.

导通孔保护，平整 **22.2083**
通过去除孔面上方多余的孔填塞或填充材料形成同一平面，实现导通孔保护。

Via, Tented (Type I Via) **22.1832**
A via with a mask material (typically dry film) applied bridging over the via wherein no additional materials are in the hole. It may be applied to one side or both.

掩蔽导通孔（I型导通孔） **22.1832**
用掩膜材料（通常为干膜）涂敷在孔上，而孔内无附加材料的导通孔。可从任一面或及双面涂敷材料。

Via, Tented and Covered (Type II Via) **22.1831**
A Type I via with a secondary covering of mask material applied over the tented via.

掩蔽及覆盖导通孔（II型导通孔） **22.1831**
用辅助覆盖掩膜材料覆盖在掩孔导通孔上的导通孔。

Virtual Condition **91.1138**
The boundary generated by the collective effects of maximum/least material condition limits of size of a feature and any applicable geometric tolerances.

实效状态 **91.1138**
由要素的最大/最小实体状况极限及任何可适用几何公差的累计作用生成的边界。

Viscosity **46.1610**
The internal friction of a fluid, caused by molecular attraction, which makes it resist a tendency to flow.

粘性 **46.1610**
由于分子相互吸引，导致液体的内部摩擦，可阻碍液体的流动。

Visible Light (Band) **21.2118**
Electromagnetic radiation that occurs at wavelengths between 0.39 and 0.78 microns.

可见光（波段） **21.2118**
波长为0.39到0.78微米时发生的电磁辐射。

Visual Examination **92.1139**
The qualitative observation of physical characteristics with the unaided eye or within stipulated levels of magnification.

目检 **92.1139**
用肉眼或按规定放大倍数对物理特征进行定性观察。

Void **90.1140**
The absence of any substances in a localized area.

空洞 **90.1140**
局部区域内缺少物质。

Voids (Bar Code) **70.2119**
In bar code symbols, missing ink coverage; generally the width of the voids is more critical than the height.

脱墨（条码） **70.2119**
条码符号中缺少油墨覆盖，通常脱墨宽度比高度更加重要。

Voids (Base Materials) **96.2120**
Circular pockets within the resinous area of the laminate, usually formed by entrapped air of volatiles; usually at or near the surface of the laminate.

空洞（基材） **96.2120**
层压板内树脂区域内的圆形空穴，通常是由于挥发物中截留的空气所形成，一般位于层压板表面或表面附近。

Voltage Plane **22.1563**
A conductor layer, or portion thereof, that serves as a common voltage source at other than ground potential for an electrical circuit, shielding, or heat sinking. (See also “Ground Plane” and “Signal Plane.”)

电压层 **22.1563**
作为公共电压源的导体层或其中的一部分，它不同于用于电气电路、屏蔽及散热的接地层。（见“接地层，Ground Plane”及“信号层，Signal Plane”。）

Voltage Plane Clearance **22.1141**
Removed portions of a voltage plane that isolate it from a hole in the base material to which the plane is attached.

电压层间隙 **22.1141**
为使电压层与基材内的孔及与孔相连接的层隔离，而从电压层上去除的一部分。

Volume Ratio (Composite) **41.1142**
The proportional thickness of one component of a composite material to the total thickness of the composite.

体积比（复合材料） **41.1142**
复合材料一种组分的厚度与复合材料总厚度之比。

Volume Resistivity **21.1143**
The ratio of the electrical potential gradient parallel to the current in a material to the current density, expressed in Megohm-meters.

体积电阻率 **21.1143**
平行于材料中电流的电位梯度与电流密度之比，以兆欧米表示。

Volumetric Analysis **92.1144**
The measurement of the volume of solution consumed in a titration process.

体积分析 **92.1144**
在滴定过程中所消耗的溶液体积的量度。

W

Wafer **35.1145**
A thin slice of semiconductor crystal ingot that is used as a base material.

晶圆 **35.1145**
用于基础材料的半导体单晶薄片。

Wafer Level Package (WLP) **35.2154**
A technique of partial encapsulation and protection of die while still on the wafer and before the wafer is divided into singulated dice.

晶圆级封装（WLP） **35.2154**
晶圆被分割成单个芯片前芯片仍在晶圆上，局部灌封及芯片保护技术。

Waffle Pack **71.1146**
An open compartmentalized container for holding surface-mount components that is suitable for loading the components into automatic handling equipment.

格栅包装 **71.1146**
适合于自动贴片机拾取元器件的盛放表面贴装元器件的敞开式分隔容器。

Wand (Bar Code) **70.2121**
A bar code scanner, usually hand held, used for reading bar codes; may not read from distances and on curved surfaces.

扫描笔（条码） **70.2121**

条码扫描器，通常为手持，用于读取条码，不能从远距离或曲面上读取。

Warper **44.1148**

A machine for preparing and arranging the yarns intended for the warp of the fabric.

整经机 **44.1148**

用于准备及整理供织物经纱用纱线的机器。

Warp **60.1147**

See “Bow.”

翘曲 **60.1147**

见“弓曲，Bow”。

Warp Size **44.1149**

Organic yarn binder (starch) applied to the warp yarn to improve strand integrity, strength and smoothness in order to withstand the rigors of weaving. (See also “Sizing” and “Heat Cleaning.”)

经纱上浆 **44.1149**

为提高股线的完整性、强度及平滑度以承受编织的强度而施加在经纱线上的有机纱线粘合剂（浆糊）。（见“上浆，Sizing”及“热清洗，Heat Cleaning”。）

Waste (Fabric) **44.1564**

A lump or collection of yarn or filament that is woven into a fabric where accumulated contamination off the loom has found its way into the fabric.

废纱（织物） **44.1564**

织物中的一束纱或细丝，由于积聚的污物离开织布机而被织入织物。

Water Vapor Transmission Rate (WVTR) **21.2122**

A measure of the permeability of plastic film or metallized plastic film material to moisture and considered an important rating for moisture barrier bags.

水蒸汽传输率（WVTR） **21.2122**

对塑料膜或金属化塑料膜材料的湿气渗透性的量度，是防湿隔离袋的重要额定值。

Water-Soluble Flux **75.1150**

An organic chemical soldering flux that is soluble in water.

水溶性助焊剂 **75.1150**

可溶于水的有机化学助焊剂。

Wave Soldering **75.1152**

A process wherein an assembled printed board is brought in contact with the surface of a continuously flowing and circulating mass of solder.

波峰焊接 **75.1152**

已组装元器件的印制板与连续流动循环的大量焊料表面接触的过程。

Waveguide **21.1151**

A tube, usually electrically conductive, for conducting radiofrequency signals between circuit or system elements.

波导管 **21.1151**

在线路之间或系统单元间传导无线电频率信号的的管子，通常为导电的。

Wavelength **21.2123**

The distance an electromagnetic wave propagates during one full cycle. It is the ratio of the propagation velocity in length units per unit time to the frequency in cycles per unit time.

波长 **21.2123**

电磁波在一个完整周期内的传播距离。它是每单位时间内的传播长度即传播速率与每单位时间内的周期数即传播频率之比。

Wave Length Spectrum **21.1776**

The distance between three consecutive nodes of a wave, equal to 360 electrical degrees. It is equal to the velocity of propagation divided by the frequency when both are in the same units.

波长频谱 **21.1776**

波的3个连续节点之间的距离，等于360度。它等于在相同单位下，传播速度除以频率。

Waviness **44.1153**

Alternating thick and thin locations in cloth that is woven under varying tension that prevents the even placement of picks.

波纹 **44.1153**

由于织造时张力的改变阻碍纱线的均匀放置，造成织物有厚有薄。

Waviness, (Base Materials) **41.2124**

The surface topography of the laminate, usually metallic-clad, which follows the structure of the reinforcement fabric in an undulating pattern.

波纹（基材） **41.2124**

覆金属箔层压板的表面形态，依增强物结构形成的波浪状图形。

Weave Exposure **55.1154**

A base material surface condition in which unbroken fibers of woven glass cloth are not completely covered by resin.

露织物 **55.1154**

基材表面的状况，玻纤布尚未断裂的纤维未被树脂完全覆盖。

Weave Style (Fabric) **44.2125**

The fabric construction and configuration that interlaces the warp and fill yarn into a woven structure.

编织类型（织物） **44.2125**

经纱和纬纱交织形成的织物组织的构造和外形。

Weave Texture **44.2126**

A surface condition of base material in which a weave pattern of cloth is apparent although the unbroken fibers of woven cloth are completely covered with resin.

显布纹 **44.2126**

基材的一种表面状况，即尚未断裂的织物纤维虽被树脂完全覆盖，但在表面仍显露出来织物的编织图案。

Web Taper **51.1155**

The constant increase in web thickness from the drill point to the opposite end of the flute where the flute carry-out starts.

钻心锥度 **51.1155**

从钻尖到对应出屑槽末端即出屑槽的排屑起点的固定增量。

Web Thickness **51.1156**

The distance between the bottom of adjacent flutes.

钻心厚度 **51.1156**

相邻出屑槽底部之间的距离。

Wedge Bond **74.1157**

A wire bond made with a wedge tool. (See also “Ball Bond.”)

楔形键合 **74.1157**

用楔形工具（劈刀）形成的金属线键合。（又见“球形键合，Ball Bond”。）

Wedge Tool **74.1158**

A bonding tool in the general form of a wedge, with or without a guide hole to position wire under its bonding face. (See also “Capillary.”)

楔形工具 **74.1158**

通常为楔形的键合工具，在其键合面下有或没有定位金属线的导向孔。（又见“微细导管，Capillary”。）

Wetting **75.2128**

The spreading of molten solder or glass on a metallic or nonmetallic surface, with proper application of heat and in some cases flux.

润湿 **75.2128**

在施加适当热量且在某些情况下涂敷助焊剂时，熔融的焊料或玻璃在金属或非金属表面的铺展。

Wetting, Adhesive (Pressure Sensitive Tape) **75.2129**

The chemical and physical phenomenon in which the pressure sensitive adhesive achieves intimate contact with the substrate surface.

粘接剂润湿（压敏胶带） **75.2129**

压敏胶带与基板表面紧密接触时的化学和物理现象。

Wetting Balance **92.1160**

An instrument that is used to measure wetting performance and solderability.

润湿称量仪 **92.1160**

用于测量浸润性能及可焊性的仪器。

Wetting, Solder **75.1159**

The formation of a relatively uniform, smooth, unbroken, and adherent film of solder to a basis metal.

焊料润湿 **75.1159**

焊料在金属基材上形成相对均匀、光滑、连续的附着膜。

Whisker **92.1161**

A slender, acicular metallic growth filament that is between a conductor and a land.

晶须 **92.1161**

导体与焊盘之间生长出的细长、针状细金属丝。

White Spot **92.1566**

A white or translucent subsurface discoloration at unfractured glass knuckles of woven polytetrafluoroethylene (PTFE) material after it has been processed. (See also “Crazing” and “Measling.”)

白斑 **92.1566**

加工完成后，在聚四氟乙烯织物内未碎裂的玻璃纤维下突起的白色、半透明的变色点。（又见“微裂纹，Crazing”和“白斑，Measling”。）

Wicking **75.1162**

The capillary absorption of a liquid along the fibers of a base material. (See also “Solder Wicking.”)

芯吸 **75.1162**

沿着基材纤维毛细吸收液体。（又见“焊料芯吸，Solder Wicking”。）

Wicking (Solder Mask) **47.1995**

A condition where uncured solder mask is drawn from the surface of a panel into the holes (via, mounting or component).

芯吸（阻焊膜） **47.1995**

在制板表面的液态阻焊膜，被吸入孔（导通孔、安装孔或元器件孔）内的状况。

Window **94.1163**

A range of values within which evaluation parameters are defined.

窗口 **94.1163**

规定的评定参数数值的一个范围。

Window (Carrier Tape) **36.1164**

An opening in the dielectric of a carrier tape that exposes the conductors for bonding purposes.

窗口（载带） **36.1164**

为了键合而暴露出导体的载带介质上的开口。

Window (Process) **94.1165**

A range of values within which evaluation parameters are defined.

窗口（工艺） **94.1165**

规定的评定参数数值的范围。

Wipe Soldering **75.1166**

The forming of a joint by applying semifluid solder and shaping the joint by rubbing with a greased cloth pad.

涂擦焊接 **75.1166**

用半流动的焊料形成连接，再用油脂布垫擦拭而使连接成形。

Wiping Action **37.1167**

The sliding action that occurs when connector contacts are mated.

滑触作用 **37.1167**

连接器接触件配接时发生的滑动作用。

Wire Bond **35.2130**

A completed wire connection that provides electrical continuity between the die and a terminal.

金属线键合 **35.2130**

实现芯片与端子之间电气连通的完整金属线连接。

Wire Bond Degradation **95.2131**

A weakening of an integrated circuit ball bond due to stress caused by exposure to reflow soldering temperatures resulting in possible reduction in component reliability.

金属线键合退化 **95.2131**

集成电路焊球键合由于暴露于再流焊接温度下而退化，可能导致元器件可靠性的降低。

Wire Bonding **74.1168**

An interconnection technology using metal wire e.g., Gold, Copper, etc. between a die pad and base material, lead frame, etc.

金属线键合 **74.1168**

利用金、铜等金属线在芯片连接盘与基材、引线框架之间实现互连的技术。

Wire Sag **74.1169**

The failure of a wire to form the desired loop between its bonds.

金属线下垂 **74.1169**

在键合之间金属线不能形成所要求的线环。

Wire Stripping **37.1567**

The removal of a predetermined portion of insulation from an insulated wire without affecting the mechanical or electrical characteristics of the conductors of the remaining insulation.

剥线 **37.1567**

从绝缘的金属线上剥除预先确定的部分绝缘皮，同时不影响剩余绝缘皮内导体的机械或电气性能。

Wire Wrap **75.1170**

See “Solderless Wrap.”

导线绕接 **75.1170**

见“无焊绕接，Solderless Wrap”。

Wire Overcoat (Discrete Wiring) **64.2132**

A secondary polymeric coating of the wire applied over the insulation to aid in the bonding of wires during the wiring process.

导线保护层（分立布线） **64.2132**

施加在导线绝缘层外的第二层聚合涂层，有助于布线过程中导线的连接。

Wire Poke-Through (Discrete Wiring) **64.2133**

A condition of the insulated wire breaking through the cover layer, exposing the insulated wire, especially at the wire cross-over.

导线刺穿（分立布线） **64.2133**

绝缘导线穿过防护层，裸露出绝缘的导线的状况，特别易发生在导线交叉处。

Wire Stub (Discrete Wiring) **64.2134**

The short end of an insulating wire which extends beyond the wall of a plated-through hole.

导线梢（分立布线） **64.2134**

从镀覆孔孔壁伸出的绝缘导线末端。

Wiring Elementary **21.1171**

See “Elementary Diagram.”

布线原理 **21.1171**

见“原理图，Elementary Diagram”。

Wiring Layer (Discrete Wiring) **64.2135**

A network of embedded insulated wires, forming a wiring layer.

布线层（分立布线） **64.2135**

嵌入的绝缘导线网络所形成的布线层。

Wobble Bond **74.1172**

A thermo compression, multi-contact bond made by rocking a bonding tool on a beam lead.

振动键合 **74.1172**

对梁式引线采用振动键合工具而形成的热压多点键合。

Working Master **24.1173**

A 1:1 scale pattern that is used to reproduce the production master.

工作原版 **24.1173**

用于复制生产底版的1:1比例的图形。

Working Time **75.1568**

The maximum period of time that an adhesive can be exposed to ambient conditions with its chemical and physical properties remaining within satisfactory limits for proper dispensing and bonding. (See also “Open Time.”)

作业时间 **75.1568**

粘合剂暴露于周围环境条件下，其化学及物理性能仍可以保持满意的点涂和粘接限度的最长周期时间。（又见“间隔时间，Open Time”。）

Wrap Plating **60.2144**

The electrolytic hole plating deposition continuously extending onto the surface from a plated via structure. (See Figure W-1.)

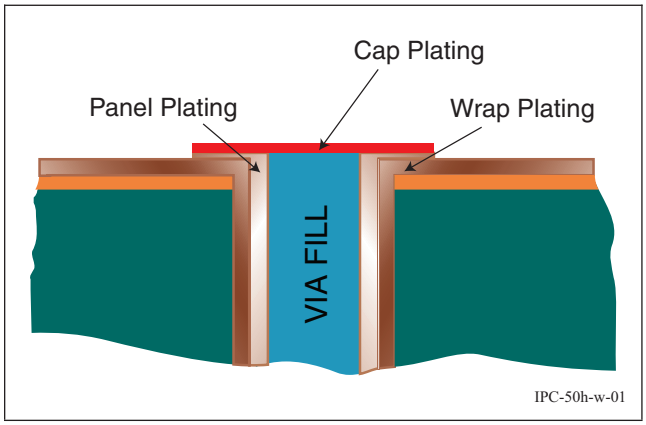
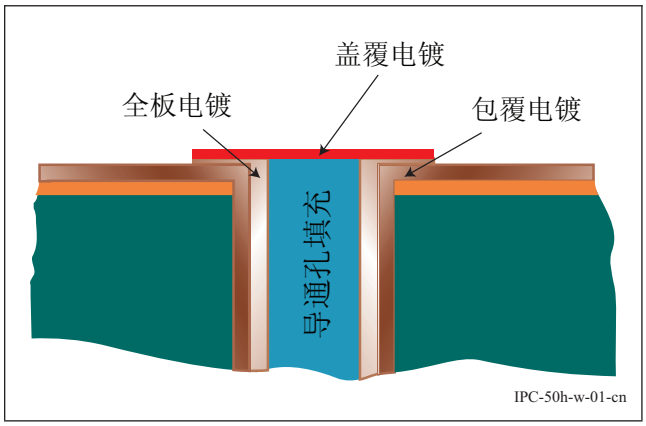


Figure W-1 Wrap Plating

包覆电镀 **60.2144**

孔电解镀层沉积从镀覆的导通孔连续延伸至表面。（见图W-1。）



图W-1 包覆电镀

Wrinkles **76.1569**

Ridges, creases or furrows in a coating or resist that are formed after the material has adhered to a metal, such as solder, that subsequently melts and resolidifies.

皱褶 **76.1569**

材料附着于金属（如焊料）、经熔融及再固化后所形成的的涂层或蚀刻剂内出现的隆起、皱痕或皱纹。

Wrought Foil **45.1174**

A metal foil that is formed by the rolling of cast metal.

压延箔 **45.1174**

由铸造金属碾轧形成的金属箔。

X

X Axis **26.1175**

The horizontal or left-to-right direction in a two-dimensional system of coordinates. (This axis is perpendicular to the Y axis.)

X轴 **26.1175**

二维坐标系中水平的或从左至右的方向的坐标轴。（此轴垂直于Y轴。）

X-Out **22.2140**

A method of identifying a defective part within an array to ensure it is not used (populated, further processed, etc.).

打叉 **22.2140**

标识有缺陷部件的一种方法。以确保该部件不再被使用（组装、进一步加工等）。

Y

Y Axis **26.1303**

The vertical or bottom-to-top direction in a two-dimensional system of coordinates.

Y轴 **26.1303**

二维坐标系中垂直的或从下至上的方向的坐标轴。

Z

Z Axis **26.1809**

The axis perpendicular to the plane formed by the X and Y axes. This axis usually represents the thickness of the board.

Z轴 **26.1809**

垂直于由X轴及Y轴所构成平面的轴，此轴通常表征板的厚度。

Zigzag In-line Package **33.2136**

Package with in-line leads on one side which are arranged in zigzag fashion.

锯齿状直插封装 **33.2136**

单列直插引线排列成锯齿状的封装。

附录A
通用工业缩写词

The acronyms listed here reflect the list of approved acronyms as of the time of release of this document. For a more frequently maintained list, go to www.ipc.org/acronyms.

本附录中所列缩写词为本标准发布之前经核准的缩写词。缩写词会经常进行更新，欢迎登录www.ipc.org/acronyms查询。

— A —

AA	Antenna Array 天线阵
AA	Automatic Acknowledge 自动认可
AAGR	Annual Average Growth Rate 年平均增长率
ABS	Acrylonitrile-Butadiene-Styrene (Plastic) 丙烯腈—丁（二烯）苯（乙烯）（塑料）
AC	Alternate Current 交流（电）
AC	All Call 所有呼叫
ACA	Anisotropically Conductive Adhesive 各向异性导电胶
ACCU	Alternating Current Connection Unit 交流电连接装置
ACI	Automatic Component Inspection 自动元器件检验
AEC	Architecture, Engineering and Construction 结构、工程和构造
ADJ	Adjust 调整；调节
AGC	Automatic Gain Control 自动增益控制
AGR	Annual Average Growth Rate 年平均增长率
AGV	Automated Guided Vehicle 自动导向车辆
AI	Artificial Intelligence 人工智能
AIS	Adhesive Interconnect System 粘接互连系统
AL	Aluminum 铝
AMP	Amperage/Ampere 安培数 / 安培
AMT	Amount 数量
ANG	Angle 角
ANOVA	Analysis of Variance 方差分析
ANSI	American National Standards Institute 美国国家标准学会
AOI	Automated Optical Inspection 自动光学检验
AOQ	Average Outgoing Quality 平均检出质量
APL	Applicable 适用
APR	Automatic Phototool Registration 自动底片定位
APT	Automatically Programmed Tools 自动编程工具
AQL	Acceptable Quality Level 可接受质量水平
AR	Annular Ring 孔环
ARINC	Aeronautical Radio Incorporated 航空无线电
ASAP	As Soon as Possible 尽快
ASCII	American Standard Code for Information Interchange 美国信息交换标准码
ASIC	Application Specific Integrated Circuit 专用集成电路
ASME	American Society Of Mechanical Engineers 美国机械工程师学会
ASQ	American Society For Quality 美国质量学会
ASSY	Assembly 组件
ASTM	American Society for Testing Materials 美国试验与材料学会

ATE Automatic Test Equipment
自动测试设备

ATG Automatic Test Generation
自动测试生成

ATR Air Transport Rack
航空运输架

AU Gold
金

AUTH Authorize/Authorization
授权；许可

AUX Auxiliary
辅助

AVG Average
平均

AVT Accelerated Vesication Test
加速起疱测试

AW Artwork
照相底图

AWG American Wire Gauge
美国线规

AXI Automated X-Ray Inspection
自动X光检查

— B —

BBT Bare Board Test
裸板测试

BC Buried Capacitance
埋电容

BD Board
板

BDMA Benzyldimethylamine
苄基二甲胺

BGA Ball Grid Array
球栅阵列

BITE Built-In Test Equipment
内置测试设备

BK Back
背

BKT Bracket
括号

BKPLN Backplane
底板

BKPNL Back Panel
背板

BLK Black/Block
黑／块

BLNK Blank
空白

BO Breakout
破出

BOD Biochemical Oxygen Demand
生化需氧量

BOM Bill of Material
材料清单

BTO Build To Order
按定单生产

BP Backplane/Backpanel Blueprint
底板／背板／蓝图

BRD Board
板

BS Backside
背面

B&T Bow and Twist
弓曲和扭曲

BT Bismaleimide Triazine
双马来酰亚胺三嗪

BTAB Bumped Tape-Automated Bonding
凸点式载带自动键合

BTM Bottom
底

BVL Bevel
斜面

— C —

C&E Cause And Effect
因果

C3 Command, Control and Communicate
指挥、控制和通讯

C4 Controlled Collapse Component Connection
可控塌落元器件连接

CAD Computer-Aided Design
计算机辅助设计

CAE Computer-Aided Engineering
计算机辅助工程

CAF Conductive Anodic Filaments
阳极导电丝

CAFM Computer-Aided Facilities Management
计算机辅助设备管理

CAGE Commercial and Government Entity
商业及政府机构

CALC Calculate
计算

CALS	Computer-Aided Acquisition and Logistic Support (DOD) 计算机辅助采办和后勤保障（美国防部）
CAM	Computer-Aided Manufacturing 计算机辅助制造
CAP	Capacitor/Capacity 电容 / 容量
CAPP	Computer-Aided Process Planning 计算机辅助工艺设计
CAR	Computer-Aided Repair 计算机辅助返修
CASE	Computer-Aided Software Engineering 计算机辅助软件工程
CAT	Computer-Aided Testing 计算机辅助测试
CBGA	Ceramic Ball Grid Array 陶瓷球栅阵列
CBORE	Counterbore 埋头孔
CC	Conformal Coating 敷形涂覆
CCAPS	Circuit Card Assembly and Processing System 电路卡组件及加工系统
CDA	Copper Development Association 铜矿开发协会
CEE	Career Ending Event 职业终止事件
CEPM	Certified Ems Program Managers 认证EMS项目经理
CET	Certified Electronic Technician 认证电子技术人员
CF	Copper Foil 铜箔
CFM	Continuous Flow Manufacturing 连续流水线制造
CFM	Cubic Feet per Minute 立方英尺每分
CHAR	Character/Characteristic 字符 / 特性
CHG	Change 变化，更改
CHK	Check 校核
CI	Controlled Impedance 受控阻抗
CIM	Computer-Integrated Manufacturing 计算机集成制造
CIRC	Circuit 电路
CISC	Complex Instruction Set Computing 复杂指令系统计算
CITIS	Contractor Integrated Technical Information Services 承包方集成技术信息服务
CL	Class 级
CLN	Clean 清洁
CLR	Clear/Clearance 清楚 / 间隙
CM	Contract Manufacturer 合同制造商
CMC	Copper Moly Copper 铜 / 钼 / 铜
CMOS	Complimentary Metal-Oxide Semiconductor 互补型金属氧化物半导体
CMP	Component 元器件
CNC	Computer Numerical Control 计算机数字控制
CNTR	Center 中心
CNTRL	Control 控制
COB	Chip-on-Board 板上芯片直装
COD	Consumed Oxygen Demand 需氧量
COT	Configure To Order 按定单配置
COTS	Commercial Off The Shelf 商业成品
CoA	Certificate of Analysis 分析证书
CoC	Certificate of Compliance 合格证
COMP	Component 元器件
COND	Conductor/Condition 导线 / 条件
CONF	Conference/Conformance 研讨会 / 一致

CONN Connector
连接器

CONT Continue/Continuity
连续 / 连通性

Cp Capability Performance
能力性能

CPK Process Capability Index (range within specification)
工艺能力指数（技术规范内）

CPL Capability Performance, Lower
能力特性，下限

CPLD Complex Programmable Logic Device
复杂的可编程逻辑器件

CPN Coupon
附连测试板

CPU Capability Performance, Upper
能力特性，上限

CPU Central Processing Unit (Computer)
中央处理器（计算机）

CRC Cyclic Redundancy Check
循环冗余码校验

CRT Cathode-Ray Tube
阴极射线管

CS Component Side
元器件面

CSA Canadian Standards Agency
加拿大标准署

CSG Constructive Solids Geometry
构造实体几何学

CSK Countersink
埋头孔

CSP Chip Scale Package
芯片尺寸封装

CTE Coefficient of Thermal Expansion
热膨胀系数

CU Copper
铜

CVR Cover
覆盖

CVS Cyclic Voltammetry Stripping
循环伏特剥除法

— D —

DAB Designated Audit Body
指定审核机构

DATC Design Automation Technical Committee (IEEE)
设计自动化技术委员会（IEEE）

DBMS Database Management System
数据库管理系统

DC Direct Current
直流（电）

DCAS Defense Contract Administration Service
（美国）国防合同管理服务中心

DCMA Defense Contract Management Agency
（美国）国防合同管理局

DCMC Defense Contract Management Command
（美国）国防合同管理指挥部

DEC Decimal
小数

DEG Degree
度

DEP Deposit.Deposition
沉积

DES Develop-Etch-Strip/Design
显影—蚀刻—去膜 / 设计

DESC Defense Electronics Supply Center
（美国）国防电子供应中心

DF Dryfilm/Difunctional
干膜 / 双官能

DFM Design for Manufacture
可制造性设计

DFSM Dry Film Solder Mask
干膜阻焊膜

DIA Diameter
直径

DIEL Dielectric
电介质

DIM Data-Information Module
数据信息模块

DIM Dimension
尺寸

DIN Deutsches Institute for Normung
德国标准化协会

DIP Dual-Inline Package
双列直插封装

DIST Distribute/Distribution
分配 / 分布

Dk Dielectric Constant
介电常数

DLA Defense Logistics Agency (DOD)
（美国）（国防部）国防后勤署

DMA Direct Memory Access
直接存储器访问

DMSA	Defense Manufacturers and Suppliers Association （美国）国防制造商与供应商协会
DNC	Distributed (or Direct) Numerical Control 直接数字控制
DOC	Document 文件
DOD	Department of Defense （美国）国防部
DOD	Dissolved Oxygen Demand 溶解耗氧量
DOE	Design Of Experiments 实验设计
DOS	Disc Operating System 磁盘操作系统
DP	Drill Program 钻孔程序
DRC	Design Rule Checking 设计规则检查
DRL	Drill 钻孔
DRM	Drawing Requirements Manual 图纸要求手册
DS	Dimensional Stability/Double-sided 尺寸稳定性 / 双面
DSC	Differential Scanning Calorimetry 差分扫描热量测定法
DSP	Die Size Package 芯片尺寸封装
DSP	Digital Signal Processor 数字信号处理器
DTF	Double-Treat Foil 双面处理金属箔
DTL	Detail 细节，详图
DTP	Diameter True Position 实际位置度直径
DTS	Dock To Stock 免验
DVM	Digital Voltmeter 数字电压表
DWV	Dielectric Withstanding Voltage 介电电压
DXF	Data Exchange Format 数据交换格式

— E —

E-AU	Electroless Gold 化学镀金
E-NI	Electroless Nickel 化学镀镍
EA	Each 各
ECAD	Electronic Computer-Aided Design 电子计算机辅助设计
ECC	Error Correction Code 纠错码
ECCB	Electronic Components Certification Board 电子元器件认证板
ECL	Emitter-Coupled Logic 发射极耦合逻辑
ECM	Electronic Countermeasures 电子干扰
ECN	Engineering Change Notice 工程更改通知
ECO	Engineering Change Order 工程更改指令
ECR	Engineering Change Request 工程更改请求
ED	Electrodeposited 电沉积
EDA	Electronic Design Automation 电子设计自动化
EDIF	Electronic Design Interchange Format 电子设计交换格式
EDM	Electro-Discharge Machining 放电加工
EDO	Extended Data Out 扩充数据输出
EIA	Electronic Industries Association （美国）电子工业协会
EIS	Engineering Information System 工程信息系统
ELD	Electro-Luminescent Diode 场致发光二极管
EMC	Electromagnetic Compatibility 电磁兼容性
EMF	Electro-Motive Force 电动势
EMI	Electromagnetic Interference 电磁干扰

EMP	Electromagnetic Pulse 电磁脉冲
EMPF	Electronics Manufacturing Productivity Facility 电子制造生产设施
EMS	Electrical Manufacturing Services 电子制造服务
EMUL	Emulsion 乳胶
ENIG	Electroless Nickel/Immersion Gold 化学镀镍 / 浸金
EPA	Environmental Protection Agency 环境保护署
EPR	Ethylene-Propylene (Copolymer) Resin 乙烯—丙烯（共聚）树脂
EPT	Ethylene-Propylene Terepolymer 乙烯—丙烯三元共聚物
Er	Relative Dielectric Constant 相对介电常数
ESD	Electro-static Discharge/Electro-static Device 静电放电
ESI	Early Supplier Involvement 供应商早期参与
ESR	Equivalent Series Resistance 等效串联电阻
ET	Electrical Test 电测试
ETPC	Electrolytic Tough-Pitch Copper 电解韧铜
EVAL	Evaluation/Evaluate 评价
EX	Example 例
EXP	Expose/Exposure/Expire 暴露 / 曝光 / 到期
EXT	External/Extension 外部 / 扩展

— F —

FA	First Article 首件
FAA	Federal Aviation Administration （美国）联邦航空管理局
FAB	Fabrication/Fabricate 制作
FAI	First Article Inspection 首件检验
FAR	Failure Analysis Report 失效分析报告
FAR	First Article Report 首件报告
FC-CBGA	Flip Chip Ceramic Ball Grid Array 倒装芯片陶瓷球栅阵列
FC-PBGA	Flip Chip Plastic Ball Grid Array 倒装芯片塑封球栅阵列
FCC	Federal Communications Commission （美国）联邦电信委员会
FCC	Flat-Conductor Cable 扁平导体电缆
FCT	Functional Circuit Test 功能电路测试
FEA	Finite-Element Analysis 有限元分析
FEM	Finite-Element Modeling 有限元模拟
FEP	Fluorinated Ethylene-Propylene (Teflon) 氟乙烯 – 丙烯（特氟隆）
FET	Field-Effect Transistor 场效应晶体管
FFT	Fast Fourier Transform 快速傅里叶变换
FGI	Finished Goods Inventory 成品库存清单
FHS	Finished Hole Size 成孔尺寸
FLT	Flat 平
FM	From 自
FMEA	Fault Mode And Effect Analysis 故障模式及影响分析
FNL	Final 最后
FPC	Flexible Printed Circuit 挠性印制电路
FPGA	Field Programmable Gate Array 场可编程门阵列
FPT	Fine-Pitch Technology 细间距技术
FPW	Flex Printed Wiring 挠性印制线路
FREQ	Frequency 频率

FS Farside
远面

FSCM Federal Stock Code for Manufacturers
（美国）联邦制造商股票代码

FTIR Fourier Transform Infra-Red (Spectroscopy)
傅里叶变换红外光谱学

FTP File Transfer Protocol
文件传输协议

FUNC Function/Functional
功能／功能的

— G —

Ga As Gallium Arsenide
砷化镓

GBIB General Purpose Interface Bus
通用接口总线

GLS Glass
玻璃

GMA Gas Metal Arc (Welding)
气体保护金属弧焊（熔焊）

GND Ground
接地

GTA Gas Tungsten Arc (Welding)
气体保护钨弧焊（熔焊）

GTPBGA Glob Top Plastic Ball Grid Array
圆顶塑封球栅阵列

—H —

HAL Hot Air Level
热风整平

HASL Hot Air Solder Leveling
热风焊料整平

HDI High Density Interconnect
高密度互连

HL Hole
孔

HLS Holes
孔（复数）

HRC High Resin Content
高树脂含量

HPGL Hewlett Packard Graphic Language
惠普图形语言

HT Height
高度

HTML Hypertext Markup Language
超文本链接标示语言

HTE High Temperature Elongation
高拉伸性

HTTP Hypertext Transfer Protocol
超文本传输协议

— I —

I/O Input/Output (Terminations)
输入／输出（端子）

IC Integrated Circuit
集成电路

IC Ionic Contamination/Interconnect/Integrated Circuit
离子污染物／互连／集成电路

ICA Isotropically Conductive Adhesive
各向同性导电胶

ICAM Integrated Computer-Aided Manufacturing
集成计算机辅助制造

ICT Inner Circuit Test
内部电路测试

ID Inside Diameter
内径

IDC Insulation-Displacement Connection
绝缘皮穿刺连接

IDENT Identify/Identification
识别／识别

IEC International Electrotechnical Commission
国际电工委员会

IECQ International Electronic Component Qualification System
国际电工委员会电子元器件质量评定体系

IEDR Initial Engineering Design Review
初期工程设计审核

IEEE Institute of Electrical and Electronic Engineers
（美国）电气与电子工程师学会

IEPS International Electronic Packaging Society
国际电子封装学会

IGES Integrated Graphics Exchange System
集成图象交换系统

IL Innerlayer
内层

ILB Inner-Lead Bonding (TAB)
内引线键合（TAB）

IMG Image
图像

IMM Immersion
浸没

IMMAU Immersion Gold
浸金

IMP Impedance
阻抗

INC Incomplete/Incorrect/Incorporate
不完全 / 不正确 / 组成

INCL Include
包括

INSP Inspect/Inspection
检查 / 检验

INT Internal
内部的

INV Inventory
库存清单

IP Internet Protocol
互联网协议

IPM Inches Per Minute
每分钟英寸

IR Infrared
红外

IR Insulation Resistance/Infrared
绝缘电阻 / 红外

IS Inside/Information Systems
内部 / 信息系统

ISCET International Society Of Certified Electronics Technician
电子技术人员认证国际学会

ISHM International Society for Hybrid Microelectronics
国际混合微电子学会

ISO International Standards Organization
国际标准组织

ISS Issue
发布；版本

ITT Inter-Test Time
测试间隔时间

IVH Interstitial Via Hole
裂缝的导通孔

— J —

JEDEC Joint Electronic Device Engineering Council
电子器件工程联合理事会

JIT Just-in-Time (Manufacturing)
即时（制造）

— K —

KGB Known Good Board
已知好板

KGD Known Good Die
已知好芯片

— L —

LAN Local Area Network
局域网

LAM Laminate/Lamination
层压板 / 层压

LBA Logical Block Address
逻辑块地址

LCC Leadless Chip Carrier
无引线芯片载体

LCCC Leadless Ceramic Chip Carrier
无引线陶瓷芯片载体

LCD Liquid Crystal Display
液晶显示

LDA Logic Design Automation
逻辑设计自动化

LED Light-Emitting Diode
发光二极管

LEG Legend
图例

LIF Low Insertion Force
低插拔力

LMC Least Material Condition
最小实体状态

LOC Locate/Location
定位 / 位置

LPI Liquid Photoimageable
液态光致成像

LPI Liquid Photoimageable Solder Mask
液态光致成像阻焊膜

LRC Low Resin Content
低树脂含量

LRU Lowest Replaceable Unit
最小可替换单元

LSI Large Scale Integration (Integrated Circuit)
大规模集成（集成电路）

LSR Laser
激光

LTCC Low Temperature Co-Fired Ceramic
低温共烧陶瓷

LW Line Width
线宽

LYR Layer
层

— M —

MA Mechanical Advantage
机械效益

MAC Maximum Allowable Concentration
最大允许浓度

MAC Media Access Control
介质存取控制

MAP Manufacturing Automation Protocol
制造自动化协议

MATL Material
材料

MATS Material Transport Segment
材料运输部门

MBV Micro-blind Via
微盲导通孔

MCAD Mechanical Computer Aided Design
机械计算机辅助设计

MCAE Mechanical Computer-Aided Engineering
机械计算机辅助工程

MCM Multi Chip Module
多芯片模块

MCP Multi Chip Package
多芯片封装

MDA Methylenedianiline
二苯氨基甲烷

MED Molecular Electronic Device
分子电子器件

MEK Methyl-Ethyl Ketone
甲基•乙基（甲）酮

MELF Metal Electrode Face (Discrete Leadless Component)
金属电极面（分立无引线元器件）

MEMS Micro Electro Mechanical Systems
微电子机械系统

MF Multifunctional
多官能团

MFG Manufacturing
制造

MFR Manufacturer
制造商

MIBK Methyl-Isobutyl Ketone
甲基异丁基（甲）酮

MIN Minimum
最小

MIP Manufacturing Instruction Procedure/ Multiple Inline Package
生产指导程序 / 多列直插封装

MIR Moisture & Insulation Resistance
湿气及绝缘电阻

MITI Ministry of International Trade and Industry (Japan)
（日本）通商产业省

ML Multilayer
多层

MLB Multilayer Board
多层板

MLC Multilayer Chip Capacitor
多层片式电容

MLPCB Multilayer Printed Circuit Board
多层印制电路板

MMC Maximum Material Condition
最大实体状态

MMIC Monolithic Microwave Integrated Circuit
单片微波集成电路

MOS Metal-Oxide Semiconductor
金属氧化物半导体

MRB Material Review Board
材料评审委员会

MRP Material Requirement Planning
材料需求规划

MRP II Manufacturing Resource Planning
制造资源规划

MSI Medium Scale Integration (Integrated Circuit)
中规模集成（集成电路）

MSDS Material Safety Data Sheets
材料安全数据表

MSG Message
信息

MSTR Master
主

MTBF Mean Time Between Failures
平均无故障工作时间

MTL Metal
金属

MTTR Mean Time To Repair
平均返修时间

— N —

NA Not Applicable
不适用

NADCAP National Aerospace and Defense Contractors Accreditation Procedures
国家空间及国防承包商鉴定程序

NASA National Aviation and Space Administration
国家航空与航天管理局

NBR Nitrile Butadiene-Acrylonitrile Rubber
丁腈—丙烯腈橡胶

NBS National Bureau of Standards
国家标准局

NC Numerical Control
数字控制

NCM Non-Conforming Material
不合格材料

NDT Non-Destructive Testing
无损测试

NECQ National Electronics Component Qualification System
国家电子元器件鉴定体系

NEG Negative
负

NEMA National Electrical Manufacturers Association
国家电气制造商协会

NF Non-Functional
非功能

NHS Nominal Hole Size
标称孔径

NI Nickel
镍

NIST National Institute for Science and Technology
国家科学与技术学会

NMR Normal-Mode Rejection
正常拒收

NOM Nominal
标称

NP Non Plated
非电镀

NPI New Product Introduction
新产品导入

NPTH Non Plated Through Hole
非镀覆孔

NS Nearside
近面

NSA National Security Agency
国家安全局

NSTD Non-Standard
非标准

NTS Not-to-Scale
不按比例

— O —

OA Overall
全部；全体

OA Organic Acid (Flux)
有机酸（助焊剂）

OBE Overcome By Events
遭受突发事件

OD Outside Diameter
外径

ODR Oscillating Disk Rheometer
振荡盘式流变计

OEM Original Equipment Manufacturer
原始设备制造商

OFHC Oxygen-Free High-Conductivity Copper
无氧高传导率铜

OL Outerlayer
外层

OLB Outer-Lead Bonding (TAB)
外引线粘合（TAB）

ORG Organize/Organization/Orange
组织（动）/ 组织（名）/ 橙色

ORIG Original
原始

OSHA Occupational Safety Hazards Act
职业安全法

OSI Open Systems Interconnection
开放系统互连

OSI On-Screen Inspection
在屏检验

OSP Organic Solderability Preservative (anti-oxidant coating)
有机可焊性保护剂（防氧化涂层）

OZ Ounce
盎司

— P —

P&IA Packaging and Interconnecting Assembly
封装与互连组件

P&IS Packaging and Interconnecting Structure
封装与互连结构

PAC Pad Array Carrier
焊盘阵列载体

PBA Printed Board Assembly
印制板组件

PBGA Plastic Ball Grid Array
塑封球栅阵列

PBX	Private Branch Exchange 专用交换分机
PC	Personal Computer 个人计算机
PC	Printed Circuit/Production Control 印制电路 / 生产控制
PCA	Printed Circuit Assembly 印制电路组件
PCB	Printed Circuit Board 印制电路板
PCMCIA	Personal Computer Memory Card Industry Association 国际个人电脑存储卡协会
PDES	Product Data Exchange Specification 产品数据交换规范
PDL	Page Description Language 页面描述语言
PEM	Plastic Electronic Module 塑料电子模块
PEP	Post-Etch Punch 蚀刻后冲孔
PGA	Pin Grid Array (Leaded Component Package) 针栅阵列（带引线元器件封装）
PHIGS	Programmer's Hierarchical Interface Graphics Standard 程序员分析介面图形标准
PID	Photo-Imageable Dielectric 光可成像的电介质
PIP	Pin-In-Paste Technology 通孔再流焊接技术
PL	Parts List 部件表
PLC	Place 地点
PLCC	Plastic Leaded Chip Carrier 塑封有引线芯片载体
PLCS	Places 地点（复数）
PLD	Programmable Logic Device 可编程逻辑器件
PLN	Plane/Plan 平面 / 计划
PLNG	Planning 规划
PLNR	Planner 规划者
PLT	Plate 板
PLTD	Plated 电镀
PM	Preventive Maintenance 预防维护
PNL	Panel 在制板
POS	Positive 正
PP	Prepreg 预浸材料
Pp	Process Performance (See Also Cp) 工艺性能（又见Cp）
PPM	Parts Per Million 百万分之几
PPO	Polyphenylene Oxide 聚苯醚
PPS	Polyphenylene Sulfide (Plastic) 聚苯硫（塑料）
PQFP	Plastic Quad Flat Package 塑封方形扁平封装
PROG	Program 程序；纲要；计划
PRT	Planar Resistor Technology 平面电阻技术
PSF	Per Square Foot 每平方英尺
PSI	Pounds Per Square Inch 磅（力）每平方英寸
PSI	Per Square Inch 每平方英寸
PT	Positional Tolerance 位置公差
PT	Perfect Test/Point 完全测试 / 点
PTFE	Polytetrafluoroethylene (Teflon) 聚四氟乙烯（特氟隆）
PTH	Plated-Through Hole 镀覆孔
PTS	Points 点（复数）
PVC	Polyvinyl Chloride 聚氯乙烯
PVT	Production Validation Test 生产验证测试

PB Printed Board
印制板

PWA Printed Wiring Assembly
印制线路组件

PWB Printed Wiring Board
印制线路板

— Q —

QA Quality Assurance
质量保证

QC Quality Control
质量控制

QE Quality Engineer
质量工程师

QFP Quad Flat Pack
方形扁平封装

QML Qualified Manufacturers List
合格制造商一览表

QPL Qualified Products List
合格产品一览表

QPL Quality Product Level
产品质量级别

QTA Quick Turn Around
急件

QUAL Qualification/Qualify
鉴定

— R —

R&R Repeatability And Reproducibility
可重复性和可再现性

RA Rosin Activated (Flux)
活性松香（助焊剂）

RAD Radius/Radii
半径 / 半径（复数）

RAM Random Access Memory
随机存取存储器

REF Reference
参考

REG Registration/Register
重合度；登记 / 注册

REL Release
发布

REM Remove
去除

REP Representative/Represent
代表 / 表现

REQ Request for Quotation
询价

RFI Radio-Frequency Interference
射频干扰

REIN Reinforce
增强

RFP Request for Proposal
建议征集

RFQ Request For Quote
报价请求

REPL Replace
替换

RFS Regardless of Feature Size
要素尺寸无关

RISC Reduced Instruction Set Computing
精简指令系统计算

RMA Rosin Mildly Activated (Flux)
中度活性松香（助焊剂）

RMK Remake
重做

RMS Root Mean Square
均方根

ROM Read Only Memory
只读存储器

RP Rout Program
布线程序

RPM Revolutions Per Minute
转每分

RPR Repair
返修

RPT Report
报告

RSS Ramp Soak Spike
升温–保温–峰值

RT Rout
布线；铣切

RTF Reverse-Treat Foil
反向处理箔

RTS Ramp To Spike
升温到峰值

RTT Resistance From Point to Point
点到点电阻

RTV Room Temperature Vulcanizing
室温硫化

RWK Rework
返工

RwoH Reliability without Hermeticity
无密封的可靠性

— S —

S&R Scrap and Rework
报废及返工

SAC305 A Lead free soldering alloy consisting of Sn96.5, Ag3.0, Cu0.5
Sn 96.5 / Ag 3.0 / Cu 0.5无铅焊料合金

SAE Society of Automotive Engineers
机动工程师学会

SB Should/Shall Be
应该 / 应当是

SBU Sequential Buildup
顺序叠加

SCP Single Chip Package
单芯片封装

SCRN Screen
丝网；屏幕

SEC Solvent Extract Conductivity
溶剂萃取电释

SECT Section
部分；段

SEM Scanning Electron Microscope
电子扫描显微镜

SEM Standard Electronic Module (Navy)
标准电子模块（美国海军）

SEP Separate
单独；分离

SERA Sequential Electrochemical Reduction Analysis
连续电化学还原分析

SFM Surface Feet Per Minute
每分钟平方英尺

SHT Sheet
张；片

SIG Signal
信号

SIP Single Inline Package
单列直插式封装

SIR Surface Insulation Resistance (Resistivity)
表面绝缘电阻（电阻系数）

SLD Solder
焊料

SLDR Solder
焊料

SLT Slot
槽

SMC Surface-Mount Component
表面贴装元器件

SMD Surface Mount Device
表面贴装器件

SMEMA Surface Mount Equipment Manufacturers Association
表面贴装设备制造商协会

SMOBC Solder Mask Over Bare Copper
裸铜覆阻焊工艺

SMOGB Solder Mask Over Gold Body
金本体覆阻焊工艺

SMC Surface Mount Component
表面贴装元器件

SMP Surface-Mount Pad
表面贴装焊盘

SMT Surface Mount Technology
表面贴装技术

SMTA Surface Mount Technology Association
表面贴装技术协会

S/N Serial Number
序列号

SNA Systems Network Architecture
系统网络体系结构

SOC System On a Chip
系统级芯片

SOIC Small-Outline Integrated Circuit
小外形集成电路

SOS Silicon-on-Sapphire
硅蓝宝石；蓝宝石上外延硅

SP Space
间距

SPC Statistical Process Control
统计过程控制

SPEC Specification
规范

SPICE Simulation Program, Integrated Circuit Emphasis
集成电路加强模拟程序

SQ Square
平方

SQC Statistical Quality Control
统计质量控制

SQFT Square Foot
平方英尺

SQIN Square Inch
平方英寸

SQL Structured Query Language
结构式查询语言

SS	Solder Side 焊接面
SSI	Small-Scale Integration (Integrated Circuit) 小规模集成（集成电路）
STD	Standard 标准
STEP	Standard for Exchange of Product Model Data 产品模式数据交换标准
STK	Stock/Stack 库存 / 堆
SYM	Symbol 字符

— T —

TAB	Tape-Automatic Bonding 载带自动键合
TAL	Time Above Liquidus 液相线以上时间
TANG	Tangency 相切
TCE	Thermal Coefficient of Expansion 热膨胀系数
TCP/IP	Transmission Control Protocol / Internet Protocol 传输控制协议 / 互联网协议
TCR	Temperature Coefficient of Resistance 电阻温度系数
T_d	Laminate Temperature of Decomposition 层压板分解温度
TDR	Time-Domain Reflectometer 时域反射计
TEM	Transverse Electromagnetic Mode 横向电磁模式
TEMP	Temperature 温度
TF	Terafunctional 四官能团
TFA	Tree-based Floorplanning Algorithm 树形布置图算法
TFE	Tetrafluoroethylene (Teflon) 树形布置图算法
Tg	Glass Transition Temperature 玻璃化温度
TGA	Thermo Gravimetric Analysis 热重量分析法
TGP	True Grid Position 实际网格位置
TGT	Target 目标
TH	Tooling Hole(s) 定位孔
THK	Thickness 厚度
THP	Through Hole Package 通孔封装
THT	Through-Hole Technology 通孔技术
TIFF	Tagged Image File Format 标记图象文件格式
TMA	Thermo Mechanical Analysis 热机分析
TO	Transistor Outline 晶体管外形
TOL	Tolerance 公差
TOP	Technical and Office Protocol 技术和办公协议
TP	True Position 实际位置
TQM	Total Quality Management 全面质量管理
TR	Transfer 转移，传递
TST	Test 测试
T's & C's	Terms And Conditions 术语及条件
TTL	Transistor-Transistor Logic 晶体管—晶体管逻辑
TU	Touch-Up 修饰
TYP	Typical/Type 典型 / 型号

— U —

UAI	Use As Is 照样使用
UBM	Under Bump Metallization 凸点下金属层
UHF	Ultra-High Frequency 超高频
UL	Underwriter's Laboratories 美国安全检测实验室公司

ULSI Ultra-Large Scale Integration (Integrated Circuit)
超大规模集成（集成电路）

UOS Unless Otherwise Specified
除非另有规定

UPH Unit Per Hour
每小时产能

URL Uniform Resource Locator
统一资源定位器

UUT Unit Under Test
被测单元

— V —

VAR Value-Added Reseller
增值分销商

VHDL VHSIC Hardware Description Language
VHSIC 硬件描述语言

VHF Very-High Frequency
甚高频

VHSIC Very-High Speed Integrated Circuits
甚高速集成电路

VLSI Very-Large Scale Integration (Integrated Circuit)
甚大规模集成（集成电路）

VOC Volatile Organic Compound
挥发性有机化合物

VOLT Voltage
电压

VME Versa-Module Electronic
多模块电子

VSAG VHDL Standardization and Analysis Group
VHDL 标准化及分析组

VSVR Voltage Standing Wave Ratio (IEEE)
电压驻波比（IEEE）

— W —

W/ Width
宽度

W&T Warp and Twist
弓曲和扭曲

WIP Work In Process
在制件

WLP Wafer Level Packaging
晶圆级封装

WSI Wafer-Scale Integration
晶圆级集成

WYSIWYG What You See Is What You Get
所见即所得

WWW World Wide Web
环球信息网

— X —

XIP Execute In Place
芯片内执行

XRF X-Ray Fluorescence
X射线荧光

— Z —

ZAF Z-Axis Adhesive Film
Z轴粘接膜

ZIF Zero-Insertion Force
零插拔力

ZIP Zigzag Inline Package
锯齿状直插封装

Zo Impedance Value
阻抗值

附录B
分类编码的规则和应用

附录B对描述电子印制板组件的管理、设计、制作、组装及测试等各个方面的术语及定义所用的分类码描述符进行了定义。

背景

本标准所应用的分类编码(CC)规则建立于已被国际广泛认可和接受的概念原则之上。该分类编码根据与生产电子产品所需的各种要素及实际惯例有关的各种主题排列术语。

本分类编码(CC)规则尤其适合于互连结构设计、制作、组装和测试，重点为应用于电子封装领域的印制板和印制板组件产品。另外也包括了工艺、材料和元器件性质等术语，以及规定完成产品和服务所必须的商务管理方面的术语。

本分类编码共分为九大类：

1. 管理
2. 电子封装工程和设计
3. 电子封装元器件
4. 电子封装材料
5. 互连结构制作工艺
6. 电子封装互连结构类型和性能
7. 互连结构组装工艺
8. 电子封装互连结构组件类型和性能
9. 电子封装、制作和组装的质量与可靠性

本分类编码的第一部分由三个数字组成，表示与九个大类相对应的分类术语和信息。第一位数字指上述分类编码的大类；第二位数字指大类中的细目；第三位数字没有统一的规定，可供体系的使用者或规范的开发者选择，以允许对一个细目作更加详尽的分配。例如，分类编码“44X”表示：

4.. 大类(电子封装材料)
.4. 细目(增强/抑制芯/散热材料)
..X 可选

此分类编码方案的第二部分设计为四个数字的唯一识别编号，被分配用于某一具体的术语及其定义。这些编号按需要的顺序来分配，从0001开始编号。指定术语的大类和细目，其专有的编号标识就不会有重复。如果是一个行业中通用的术语，能归入多个细目或大类时，应把这个术语的定义按每个大类细目解释清楚。

以术语“空洞”(void)为例，该术语可以有三个专有的编号和定义。一个是印制板层压板内空洞，一个是照相底版乳剂内的空洞，还有一个是焊点内空洞。

IEC 60194中给每个术语分配的编号，前两个数字为大类/细目描述符，其后是一个小圆点(.)，再随后的四个数字给出了各个术语的唯一标识。如4 4.0173、56.2574等。

无论在什么情况下，如果一个术语适用于多处，它被给予了一个两位数字通用细目标识(如20，30)。

该体系具有可鉴别近一万个术语及定义的能力。如果今后一旦超出这个数字，则可以在现有编号的四位数组前添加一个零(0)，以增加一位数。

下列各节描述了标准化的分类编码：

1．管理

10．通用(管理方面)

包含了描述管理功能所需要的通用术语，管理功能涉及运营公司、管理产品或监督过程等许多方面。

11．数据处理

包含与处理数据所用软件与硬件有关的术语，这类数据为管理职责和/或功能数据。

12．人员

包含涉及人员方面术语，并涉及诸如工业医学、安全、保险、防护等术语。

13．设施

包含与完成电子封装功能的工厂或建筑物有关的术语。其中涉及对照明、温度/湿度控制和洒水装置等公共设施、以及现场操作管理等所必需的任何办公设备的要求。

14．环境

包含与管理环境排放物排出、控制或回收活动及所有废物(无害和有害的)处理和处置相关的术语。

15. 财务/采购

包含与会计活动和管理工资、顾客帐户、采购方式以及类似部门功能或活动有关的术语。

16. 存货/发货

包含与材料、零部件和产品进出厂的搬运、贮存和处置有关的术语，其中涉及用于管理记帐、搬运、存放和分发的文件和控制系统。

17. 顾客/供方关系

包含涉及解决顾客的问题或顾客满意度、以及供方选择或供方评估方针的术语。

18. [留作将来扩展]

19. 其他(管理方面)

包含与特殊管理问题有关的术语，这些术语难以归入已有主题。应该注意到，在使用主题“其他”时，包括在其中的术语应该是特殊的和互不相关的。

2. 电子封装工程和设计

20. 通用(工程和设计方面)

包含描述工程和设计原理及策略所需的术语，涉及面向制作、组装和测试的设计领域，以及实现信息流顺畅转换的自动工具。

21. 工程

包含与工程设计相关的术语，包括但不仅限于工程工作站(CAE)软件和方法及硬件技术、传播延迟分析、串扰分析、介质损耗预测、阻抗控制分析、布尔逻辑转换、直接数据传输、热损耗预测等方面。

22. 印制板和印制板组件设计

包含与印制板和印制板组件有关的术语。其中涉及但不仅限于计算机辅助设计(CAD)设备和软件算法，如设计规则检查、CAE工作站直接输入、逻辑门分配或逻辑门交换、固定网格压锁、强力场元器件控制、热敏分析、多向导体布线。

23. 分组件设计

包含与为实现一项电气或电子机械功能由一组元器件组合而成的分组件设计相关的术语。其中涉及但不仅限于计算机自动工具(CAE/CAD)、小型印制电路、混合电路、多芯片模块和其他产品的设计，且涉及由计算机硬件/软件进行的所有布局原理和技术评价。

24. 照相底片生成和照相过程

包含与用于生成电路要素过程的底片有关的术语，电路要素包括主动和被动元器件，以及与生成照相图像转移过程中所用的材料及设备有关的术语。涉及接触与非接触技术、直接与间接(激光像素转移)技术。

25. 电子生产数据生成

包含描述将设计数据转换为制造数控工具的技术及数据格式所涉及的方法所需要用到的术语。其中涉及软件和硬件及转移媒介，如调制解调器、磁盘/磁带、光盘只读存储器和直接电缆连接。

26. 技术文件

包含与硬拷贝和电子媒介有关的术语，涉及到零件图、装配图、规范控制图、技术手册、规范、标准、材料清单，以及电子设备整个使用寿命期内提供物流支持或控制所需要的任何其他信息。

27. [留作将来扩展]

28. [留作将来扩展]

29. 其他(工程和设计方面)

包含与特殊的工程和设计原理与技术相关的术语，这些术语难以归入已有主题。应该注意到，在使用主题“其他”时，包括在其中的术语应该是特殊的和互不相关的。

3. 电子封装元器件

30. 通用(元器件种类方面)

包含描述物理、机械和电气元器件特性需要用到的术语，涉及在开发电子组件中所用的电子、电子机械和机械元器件的封装类型与安装特性。

31. 分立及IC通孔元器件封装

包含与轴向引线与径向引线的通孔插装主动元器件及被动元器件的特性和封装形式有关的术语，以及为适合组装或消除应力所需要的引线整形规范有关的术语。其中涉及但不仅限于电阻、电容、晶体管、单列与双列直插封装、针栅阵列、扼流线圈、变压器、继电器、连接器、连接器插座等。

32．分立表面安装元器件封装

包含与有引线和无引线的分立(单一功能)表面贴装元器件性能和封装形式有关的术语。其中涉及但不仅限于片式电阻/电容、片式钽电容、金属化端面元器件、小外形晶体管、二极管、线圈、扼流线圈、测试点、连接器插座等。

33．表面安装IC封装类型

包含与可在单个半导体芯片内提供集成逻辑(多个)功能的元器件性能与封装形式有关的术语，要将这类元器件灌封以保护芯片，以使其在引线整形或引线/端子其它准备后用于表面贴装。这种元器件的引脚或端子形式在处理之后为表面安装做了准备。其中涉及但不仅限于小外形I/C、陶瓷扁平封装、塑料四边封装、有引线和无引线芯片载体、薄小外形封装、灌封TAB、专用光纤器件等。

34．格栅阵列封装

包含与可在单个半导体芯片内提供集成逻辑(多个)功能、且具有高引线数能力的元器件性能与封装形式有关的术语，要将这类元器件灌封以保护芯片，以备用于安装。其中涉及但不仅限于球栅、柱栅和盘栅阵列。

35．裸芯片和芯片级元器件

包含与裸芯片或增强型芯片(芯片级)元器件性质有关的术语。涉及规定键合位置所必须的性能要求和工艺细节，以及无保护裸芯片互连方法所包括的其它金属层。

36．元器件与元器件引脚/端子材料特性

包含规定元器件封装加工中所用材料所必需的术语。其中涉及但不仅限于灌封或密封材料、形成引线或端子所用金属、电镀材料、塑料、导电/非导电粘合剂等。

37．金属线和电缆的元器件

包含与电子、机电元器件布线、布线线束及布电缆有关的术语。其中涉及散热特性、功率损耗、公差和性能差异。

38．[留作将来扩展]

39．其他(元器件性质方面)

包含与电子、电子机械和机械元器件的特殊物理、机械和电气元器件特性有关的术语，这些术语难以归入已有主题。应该注意到，在使用主题“其他”时，包括在其中的术语应该是特殊的和互不相关的。

4．电子封装材料

40．通用(材料方面)

包含描述材料以及它们的特性、贮存和处置要求所需要用到的术语。这些材料为互连结构或互连结构组件的一部分。工艺消耗材料不包括在本类术语中，这类术语归在应用其的工艺中。

41．刚性印制板基板材料(有机)

包含与刚性印制板制造中所用层压、覆箔和未覆箔材料有关的术语。其中涉及但不仅限于酚醛、环氧(多官能、四官能、BT树脂)、氰酸酯、PTFE(聚四氟乙烯)、聚酰亚胺等，纸增强材料、玻璃(纤维毡、纤维和编织布)等(见44)。

42．挠性印制板基板材料(有机)

包含与挠性及刚挠性印制板制造中所用层压、覆箔和未覆箔材料有关的术语。其中涉及但不仅限于聚酰亚胺薄膜(挤压和浇铸)、聚酯薄膜、PTEE(未增强)等，以及丙烯酸、环氧和其他粘合剂。

43．互连结构用无机基板

包含与设计和制造印制板及其他互连结构所用基板材料有关的术语。这类印制板及其他互连结构需要无机材料具有热稳定性或尺寸稳定性。其中涉及但不仅限于氧化铝、氧化铍、玻璃、瓷化殷钢、铜钼等。

44．增强/抑制芯/散热材料

包含在生产印制板或互连结构中用作增强或添加有机基板材料外层的材料有关的术语。其中涉及但不仅限于纸毡、玻璃毡、玻璃布、不规则玻璃纤维、复合物、芳酰胺纤维、石英、石墨、殷钢等。

45．导电材料(金属箔、膜或镀层)

包括在材料或印制板制作过程中加在有机和无机互连结构上金属覆箔有关的术语。也包括与描述以加成法生产导电表面、平面或零件所用镀敷或网印金属材料有关的术语。

46. 元器件固定材料(导电/非导电)

包含与将电子、电子机械或机械元器件固定到在互连结构上所用材料有关的术语。其中涉及但不仅限于焊料、焊膏、导电粘合剂、绒毛搭扣等。

47. 涂层和永久性掩膜材料

包含与永久性掩膜与涂层材料有关的术语。这类材料将成为印制板、互连结构或其组件的固定部分。其中涉及但不仅限于环氧涂层、丙烯酸、干膜和液态阻焊膜、聚氨酯涂层、油墨等。

48. [留作将来扩展]

49. 其他(材料方面)

包含与特殊的材料属性、特性、处置或存放有关的术语，这些术语难以归入已有主题。应该注意到，在使用主题“其他”时，包括在其中的术语应该是特殊的和互不相关的。

5. 互连结构制作工艺

50. 通用(互连结构制作工艺)

包含描述互连结构制作工艺需要用到的术语，该工艺涉及导体形成、分层、导电孔形成、结构外形或用于制造未组装的安装及互连结构所用的其他制作工艺。

51. 机械加工

包含与用于实现互连结构的制造技术、工艺消耗材料和设备有关的术语。其中涉及但不仅限于孔形成、铣削、冲切、剪裁等。

52. 抗蚀剂和油墨的成像与涂敷

包含与从照相底片(见25)直接或间接转移为互连结构的图形转移技术、电路保护方法、材料和设备有关的术语。除了涉及不同类型(蚀刻、电镀、焊锡)的抗蚀剂外，该类术语还涉及但不仅限于用来转移图例或字符的材料、方法和设备。

53. 金属沉积工艺，包括电镀

包含与制作工艺有关的术语。该制作工艺涉及与通过干法或湿法电镀、化学镀或电镀方法沉积金属有关的互连基板(见45.)、工艺消耗材料、技术和设备。该类术语还涉及但不仅限于表面电镀和沉积、以及通孔、盲孔、埋孔等孔的导电性形成。

54. 材料去除工艺，包括蚀刻

包含与导电和非导电特性形成过程中所涉及的制作技术、工艺消耗材料、材料处理和回收及设备有关的术语。其中涉及但不仅限于铜蚀刻、去钻污(等离子蚀刻、硫酸等)、机械磨削等。

55. 层压、顺序沉积及模制工艺

包含与制作印制板或互连结构时所使用的层压及模制技术、材料、用于组合导电或非导电材料层的设备有关的术语。

56. 热固化/烘烤工艺

包含在有机和无机印制板或互连结构制作中所使用的术语，这类印制板或互连结构要求特殊的加热、红外或烘烤工艺，而这些工艺是硬化或聚合要素或平面所必须的。

57. 清洗和化学处理加工

包含在未组装印制板或互连结构的清洗工艺中用到的技术、材料、规则及设备所用术语。其中涉及但不仅限于溶剂技术、水清洗技术、水/溶剂组合、在线设备、静态皂化、蒸汽脱脂以及超声波等。

58. [留作将来扩展]

59. 其他(互连结构制造过程)

包含与特殊的互连结构制作工艺有关的术语，这些术语难以归入已有主题。应该注意到，在使用主题“其他”时，包括在其中的术语应该是特殊的和互不相关的。

6. 电子封装互连结构类型和性能

60. 通用(互连结构类型和性能)

包含描述互连构件类型及其性能要求需要用到的术语，涉及各种封装类型的描述或本类术语中描述的各种产品的性能问题。

61. 刚性印制板(有机基板)

包含与由刚性基板材料(见41)制成的有和无镀覆孔和/或导通孔的单面、双面及多层印制板有关的术语。

62. 挠性印制板(有机基板)

包含与由挠性基板材料(见42)制成的有和无镀覆孔和/或导通孔的单面、双面及多层印制板有关的术语。

63. 刚挠印制板(有机基板)

包含与由刚性或挠性基板材料(见41和42)组合制成的有和无镀覆孔和/或导通孔的单面、双面及多层印制板有关的术语。

64. 分立线路板(有机基板)

包含与采用61、62或63中所述相同技术制成、但为了实现电气或电子互连再用其他材料、和/或分立导线作补充的印制板有关的术语。

65. 印制板(无机基板)

包含与由无机基板材料(见41)制成的有和无镀覆孔和/或导通孔的单面、双面及多层印制板有关的术语。

66. 模制结构(三维立体)

包含与三维特性的互连结构有关的术语。为了形成安装和或互连结构，在模制工艺中用有机树脂材料(塑料)形成这类安装和/或互连结构。

67. 混合/多芯片模块互连结构

包含与用作分组件的单面、多面或多层混合(陶瓷)电路或模块有关的术语。这类分组件可互连一个以上芯片或改进型(芯片级封装)半导体芯片。

68. [留作将来扩展]

69. 其他(互连结构种类和性能方面)

包含与特殊的互连结构类型或其性能要求有关的术语，这些术语难以归入已有主题。应该注意到，在使用主题“其他”时，包括在其中的术语应该是特殊的和互不相关的。

7. 互连结构组装工艺

70. 通用(组装过程方面)

包含描述组装工艺需要用到的术语，组装工艺涉及元器件处置、放置和连接方面，以及清洗和涂覆工艺要求。

71. 元器件处置、存放和准备

包含为完成组件安装和连接工艺所必需的处置、存放和引线、端子或元器件本体准备有关的术语。包括但不仅限于烘干、上锡、引线折弯、环境控制、上料、存货控制等。

72. 通孔元器件插装

包含与通孔元器件插装有关的术语。这类元器件是通过将元器件引线穿过结构而实现与互连结构的连接。其中涉及但不仅限于与该工艺相关的技术、原理、数据传输、设备等。

73. 表面元器件贴装

包含与表面贴装元器件安装有关的术语。这类元器件是将引线或端子粘合在表面而实现与互连结构的连接。其中涉及但不仅限于与该工艺相关的贴装技术、原理、数据传输、设备等。

74. 裸芯片放置和连接

包含与裸芯片或改进型(芯片级封装)半导体芯片(见35)与无机及有机互连结构的连接和键合有关的术语。其中涉及但不仅限于混合电路、多芯片模块(MCM-L、-C或 -D)以及板上芯片直装。

75. 连接技术

包含与将成品元器件与互连结构完全连接所采用的方法学、技术、工艺消耗材料及设备有关的术语。其中涉及但不仅限于再流焊接、机械焊接、电气/冶金连接(熔焊、金属线键合)、导电粘合剂连接等。

76. 清洗和敷形涂覆工艺

包含与清洗制程中或成品互连基板组件所采用的方法、工艺消耗材料、废料处置以及设备有关的术语，以及与敷形涂覆组件所采用的工艺、材料和设备有关的术语。

77. 返工、返修和修正

包含与在互连结构中去除、更换或添加元器件、或更正/改变电路要素所采用的技术、工具、材料与设备有关的术语，以及与将组件修复至其正常功能有关的术语。

78. [留作将来扩展]

79. 其他(组装过程方面)

包含与特殊的组装、清洗或涂覆工艺有关的术语，这些术语难以归入已有主题。应该注意到，在使用主题“其他”时，包括在其中的术语应该是特殊的和互不相关的。

8. 电子封装互连结构组件类型和性能

80. 通用(组件类型和性能方面)

包含描述组件类型及其性能要求所需要用到的术语，涉及本类术语中规定产品的电子组件类型性质或相关的性能要求。

81. 刚性印制板组件(有机基板)

包含与成品刚性印制板组件的性能要求和性质有关的术语，该类组件在结构的一面或两面安装了电子、电子机械或机械元器件。

82. 挠性/刚挠性印制板组件(有机基板)

包含与成品挠性或刚挠性印制板组件的性能要求和性质有关的术语，该类组件有连续挠曲或挠曲安装的功能，且在结构的一面或两面安装了电子、电子机械或机械元器件。

83. 无机(陶瓷、金属芯等)印制板组件

包含与成品印制板组件或互连结构的性能要求和性质有关的术语，该类组件或互连结构由无机材料制成，在结构的一面或两面安装有元器件。

84. 模制或三维印制板组件

包含与模制平面或三维互连结构的性能要求和性质有关的术语，该结构的任何一面或所有面上安装有电子、电子机械或机械元器件。

85. 背板

包含与成品背板(母板)组件的性能要求和性质有关的术语，该板的一面或两面有连接器和/或其他元器件，其将用于互连两块或更多的其它印制板组件。

86. 多芯片模块

包含与分组件的性能要求和性质有关的术语，该分组件将裸芯片或改进型芯片(芯片级)组装在安装及互连结构的任一面或两面以及里面。这种互连结构可以由有机材料(MCM-L)、陶瓷/陶瓷玻璃材料(MCM-C或混合型)制成，或用沉积的电介质以隔离导电层的无机材料(MCM-D)组成。

87. [留作将来扩展]

88. [留作将来扩展]

89. 其他(组装类型和性能方面)

包含与特殊的组件类型或其性能要求有关的术语。这些术语难以归入已有主题。应该注意到，在使用主题“其他”时，包括在其中的术语应该是特殊的和互不相关的。

9. 电子封装、制作和组装的质量和可靠性

90. 通用(质量与可靠性方面)

包含描述功能的质量和/或可靠性方面所有用到的术语。其中功能涉及工艺的设计、制作、组装、测试和管理功能。

91. 过程控制/SPC

包含与为确保工艺变异保持在可接受的范围内、以及为建立控制的能力及持续改进工艺连续监测工艺变异所使用的技术、方法、工序及设备有关的术语。

92. 检验/测试

包含与为验证所收到的材料与产品是否满足预定用途所使用的技术、方法、工序及设备有关的术语。也包含与为确定质量和可靠性在测试期间所进行的预处理(例如烘烤)、试验及环境与应力条件有关的术语。

93. 可靠性因素与方法

包括与用来确定和预测材料、元器件、互连结构及组件/分组件可靠性的方法、规则、算法有关的术语。

94. 质量管理和保证

包含与评估制造商工艺或其产品的质量所采用的方法、工序、技术、系统及设备有关的术语。其中涉及但不仅限于质量保证检验、过程检验、过程控制、ISO9000标准等。

95. 元器件质量和可靠性

包含与为确定电子、电子机械或机械元器件是否足以承受组装、清洗及涂敷工艺，以及组装后在设备的预期使用环境中能否满足设备预期可靠性要求而准备的技术、方法、工序和设备有关的术语。

96. 互连结构质量和可靠性

包含与为确定未组装的互连结构是否足以承受组装、清洗及涂敷工艺，以及组装后在设备的预期使用环境中能否满足设备预期可靠性要求而准备的技术、方法、工序和设备有关的术语。

97. 电子组装件/分组件质量和可靠性

包含与为确定电子组件或分组件(模块)是否足以承受任何设备测试，以及当设备用于预期使用环境下组件能否以可靠的方式正常运转满而准备的技术、方法、工序和设备有关的术语。

98. [留作将来扩展]

99. 其他(质量可可靠性方面)

包含与特殊的质量或可靠性方面有关的术语。这些术语难以归入已有主题。应该注意到，在使用主题“其他”时，包括在其中的术语应该是特殊的和互不相关的。

附录C
术语分类编码排序

1 Administration
管理

11 Data Processing
数据处理

11.0046 Architecture
体系结构
11.0050 Artificial Intelligence
人工智能
11.0058 Assembly Language
汇编语言
11.0094 Batch Processing
批处理
11.0102 Benchmark, Computer
计算机基准
11.0232 Compiler
编译程序
11.0244 Computer Numerical Control (CNC)
计算机数字控制（CNC）
11.0286 Control Console
操纵台
11.0339 Database
数据库
11.0341 Data File
数据文件
11.0343 Data Logging
数据记录
11.0604 Hierarchical Database
分级数据库
11.0732 Machine Language
机器语言
11.0800 Object-Oriented Database
面向对象数据库
11.0849 Algorithm
算法
11.1114 Turnkey System
总成系统
11.1272 Runtime System
实时系统
11.1277 Scalar Processing
标量处理
11.1385 Download, Computer
计算机下载

14 Environmental
环境

14.0026 Air Contamination
空气污物
14.0027 Air Pollution
空气污染
14.2024 Scavenged Air
净化空气

16 Inventory/Shipping
库存/发运

16.2174 Traceability
可追溯性
16.2175 Serial Number
序列号

17 Customer/Vendor Relations
顾客与供方关系

17.0095 Batch Size
批量
17.0191 Certification
认证
17.0285 Contract Services
合同服务
17.1429 Just-in-Time (JIT)
即时管理（JIT）
17.2112 User
用户

2 Engineering and Design for Electronic Packaging
电子封装工程与设计

20 General (Engineering and Design Issues)
通用（工程和设计方面）

20.0028 Locating Edge
定位边
20.0158 Bulls-Eye
靶心
20.0238 Component Hole
元器件孔
20.0441 End Item
最终成品
20.0443 End Product
最终产品
20.0581 Ground
接地
20.0706 Library
库
20.0709 Limits of Size
尺寸界限
20.0710 Line
线

20.0715 Local Fiducial
局部基准点
20.0717 Locating Edge Marker
定位边标识
20.0718 Locating Hole
定位孔
20.0719 Locating Notch
定位切口
20.0720 Locating Slot
定位槽
20.0738 Manufacturing Hole
加工孔
20.0779 Mounting Hole
安装孔
20.0824 Pad
焊盘
20.0837 Path(Electrical)
通路（电气）
20.0838 Pattern
图形
20.0839 Pattern Area
图形区
20.1066 Thermal Conductivity
热导率
20.1067 Thermal Mismatch (Expansion)
热膨胀不匹配
20.1192 Numerical Control (NC)
(Computer Aided Design)
数字控制（NC）(计算机辅助设计）
20.1377 Design Automation
设计自动化
20.1413 Ground Plane
接地层
20.1462 Packaging Density
封装密度
20.1726 Location Hole
定位孔

21 Engineering
工程

21.0005 Access Protocol
访问协议
21.0036 Amplitude, Voltage
电压振幅
21.0037 Analog Circuit
模拟电路
21.0060 Asymetric Stripline
不对称带状线
21.0061 Attenuation
衰减
21.0072 Back Annotation
反向注解
21.0168 Bus
总线
21.0173 Capacitance Density
电容密度
21.0174 Capacitive Coupling
电容耦合
21.0194 Characteristic Impedance
特性阻抗
21.0213 Circuit
电路
21.0231 Compensation Circuit
补偿电路
21.0327 Crosstalk
串扰
21.0378 Dielectric Fluid
绝缘液
21.0380 Digital Circuit
数字电路
21.0385 Dipole (Electronic)
偶极（电子）
21.0396 Dissipation Factor
损耗因子
21.0417 Edge Rate
前沿速率
21.0422 Effective Permittivity
有效电容率
21.0431 Electromagnetic Interference (EMI)
电磁干扰（EMI）
21.0447 Equivalent Series Resistance (ESR)
等效串联电阻（ESR）
21.0458 Excitation Current
励磁电流
21.0473 Far-End Crosstalk
远端串扰
21.0489 Feature-Based Modeling
基于要素建模
21.0507 Finite-Element Modeling (FEM)
有限元建模（FEM）
21.0553 From-To List
接线表
21.0605 High-Impedance State
高阻抗状态
21.0699 Leakage Current
泄漏电流
21.0711 Line Coupling
传输线耦合
21.0713 Load Capacitance
负载电容
21.0721 Logic
逻辑电路
21.0726 Loss Tangent
损耗正切

21.0761 Microstrip
微带线
21.0762 Microwave Integrated Circuit
微波集成电路
21.0795 Near-End Crosstalk
近端串扰
21.0814 Open Circuit Potential
开路电势
21.0893 Power Dissipation
功耗
21.0894 Power Factor
功率因数
21.0932 Signal
信号
21.0946 Skin Effect
趋肤效应
21.1006 Spurious Signal
寄生信号
21.1028 Stripline
带状线
21.1030 Stub
支线
21.1037 Surge
电涌
21.1065 Thermal Coefficient of Expansion (TCE)
膨胀热系数（TCE）
21.1084 Threshold
阀值
21.1102 Transmission Cable
传输电缆
21.1103 Transmission Line
传输线
21.1105 Tri-State
三态
21.1143 Volume Resistivity
体积电阻率
21.1151 Waveguide
波导管
21.1171 Wiring Elementary
布线原理
21.1177 Net
网络
21.1178 Net List
网表
21.1180 Node
节点
21.1190 Normal-Mode Rejection (NMR)
串模干扰抑制（NMR）
21.1259 Rise Time(Transition Duration)
上升时间（过渡时间）
21.1300 Shield
屏蔽层
21.1332 Backward Crosstalk
反向串扰
21.1333 Balanced Transmission Line
平衡传输线
21.1360 Computer Aided Engineering (CAE)
计算机辅助工程（CAE）
21.1374 Current Carrying Capacity
载流量
21.1375 Decoupling
退耦
21.1378 Dielectric Breakdown
介电击穿
21.1379 Dielectric Constant
介电常数
21.2061 Static Electricity Control
静电控制
21.1380 Dielectric Strength
介电强度
21.1381 Dimensional Stability
尺寸稳定性
21.1383 Dipole Moment
偶极矩
21.1388 Edge Transition Attenuation
边沿传输衰减
21.1398 Finite Element Analysis (FEA)
有限元分析（FEA）
21.1406 Forward Crosstalk
正向串扰
21.1423 Instrument Bus
测试仪器总线
21.1425 Insulation Resistance
绝缘电阻
21.1440 Logic Diagram
逻辑图
21.1441 Logic Family
逻辑系列
21.1451 Minimum Electrical Spacing
最小电气间隙
21.1493 Propagation Delay
传输延迟
21.1494 Pulse,Digital
数字脉冲
21.1499 Reflection, Signal Propagation
信号传播反射
21.1527 Shielding, Electronic
电子屏蔽层
21.1551 Truth-Table Testing
真值表测试
21.1556 Unbalanced Transmission Line
非平衡传输线
21.1652 Convection
对流

21.1653 Convection Controlled
受控对流
21.1654 Convection Forced
强制对流
21.1712 Electrical Resistance
电气阻抗
21.1716 Electrostatic Discharge (ESD)
静电放电（ESD）
21.1742 Electrical Characteristics
电气特性
21.1776 Wave Length Spectrum
波长频谱
21.1793 Alternating Current (ac)
交流电（ac）
21.1794 Capacitance
电容
21.1795 Current
电流
21.1796 Direct Current (DC)
直流电（DC）
21.1797 Dual-Strip Line
双带状线
21.1798 Effective Relative Dielectric Constant
有效相对介电常数
21.1801 Impedance
阻抗
21.1802 Inductance
电感
21.1803 Permeability
导磁率
21.1804 Power Plane Inductance
电源层电感
21.1805 Resistance
电阻
21.1808 Farad
法拉
21.1845 Flashover
飞弧
21.1856 Frequency (Electrical Current)
电流频率
21.1863 Heat Absorption Coefficient
吸收系数
21.1864 Heat Resistance
耐热性
21.1880 Insertion Loss
插入损耗
21.1918 Microwaves
微波
21.1961 Permittivity
电容率
21.1998 Radiation, Infrared
红外辐射
21.1999 Radiation, Long Wave, Infrared
长波红外线辐射
21.2000 Radiation, Medium Wave Infrared
中波红外线辐射
21.2001 Radiation, Near Infrared
近红红外线辐射
21.1206 Subnet
子网络
21.2003 Radiation, Re-mitted Infrared
红外再辐射
21.2004 Radiation, Short Wave Infrared
短波红外线辐射
21.2005 Reflection Coefficient
反射系数
21.2006 Reflectivity
反射率
21.2008 Relative Permittivity
相对电容率
21.2014 Return Loss
回波损耗
21.2035 Skin Depth
趋肤深度
21.2060 Static Electricity
静电
21.2061 Static Electricity Control
静电控制
21.2062 Static Relative Permittivity
静态相对介电常数
21.2073 Surface Resistance
表面电阻
21.2080 Creepage Distance
爬电距离
21.2083 Thermal Expansion
热膨胀
21.2084 Thermal Mismatch
热失配
21.2086 Thermal Resistance
热阻
21.2087 Thermal Shock Resistance
耐热冲击
21.2118 Visible Light (Band)
可见光（波段）
21.2122 Water Vapor Transmission Rate (WVTR)
水蒸汽传输率（WVTR）
21.2123 Wavelength
波长
21.2079 Electrical Clearance
电气间隙

22 Printed Board and Printed Board Assembly Design
印制板和印制板组件设计

22.0029 Automatic Component Placement
自动元器件布局

22.0030 Alignment Mark
对准标记
22.0040 Annotation
注解
22.0049 Array
阵列
22.0051 Artwork
照相底图
22.0061 Attenuation
衰减
22.0071 Back-Bared Land
背裸连接盘
22.0076 Background (Artwork)
背景（照相底图）
22.0115 Blind Via
盲孔
22.0124 Automatic Conductor Routing
自动导体布线
22.0142 Border Area
边沿区
22.0143 Border Data
边沿数据
22.0144 Boss
凸台
22.0163 Buried Via
埋孔
22.0178 Card-Edge Connector
卡边连接器
22.0179 Card-Insertion Connector
插卡连接器
22.0215 Circuitry Layer
电路层
22.0223 Coined Lead
扁圆引线
22.0227 Comb Pattern
梳型电路
22.0237 Component Density
元器件密度
22.0241 Component Side
元器件面
22.0251 Conductor
导体
22.0256 Conductor Line
导体线
22.0257 Conductor Path
导体路径
22.0258 Conductor Pattern
导体图形
22.0259 Conductor Side
导体面
22.0261 Conductor Track
导体路线
22.0266 Connector, One-Part
单件连接器
22.0267 Connector, Two-Part
双件连接器
22.0269 Connector Area
连接器区
22.0270 Connector Contact
连接器接触件
22.0276 Contact Area
接触区
22.0281 Contact Spacing
接触间距
22.0287 Control Drawing
控制图
22.0297 Corner Marks
角标
22.0323 Crop Marks
剪切标记
22.0325 Crosshatching
开窗口
22.0344 Datum
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22.0568 Geometric Tolerance
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22.0644 Indexing Slot
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22.0654 Interfacial Connection
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22.0897 Power Plane
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22.1054 Terminal Hole
终端孔
22.1055 Terminal Pad
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22.1111 True Position Tolerance
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22.1325 Anchoring Spur
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22.1362 Conductive Pattern
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22.1373 Cumulative Tolerance
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22.1595 Microvia (Build-Up Via)
微导通孔（积层导通孔）
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22.1756 Metalized Land Areas
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22.1773 Terminations
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22.1811 Clearance Hole
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22.1823 Attachment Density
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22.1826 Via, Filled and Capped (Type VII Via)
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22.1827 Via, Filled and Covered (Type VI Via)
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22.1828 Via, Filled (Type V Via)
填塞导通孔（V型导通孔）
22.1829 Via, Plugged and Covered (Type IV Via)
堵塞及覆盖导通孔（IV型导通孔）
22.1830 Via, Plugged (Type III Via)
堵塞导通孔（III型导通孔）
22.1831 Via, Tented and Covered (Type II Via)
掩蔽及覆盖导通孔（II型导通孔）
22.1832 Via, Tented (Type I Via)
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22.1878 Inner Layer
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22.1893 Landless Via
无连接盘导通孔
22.1898 Laser Via
激光导通孔
22.1963 Photo Via
光致导通孔
22.1968 Plain Hole
平孔
22.2036 Skip Via
跳孔
22.2070 Stud Via
栓导通孔
22.2085 Thermal Plane
散热层
22.2094 Through Connection
贯穿连接
22.2116 Capture Land (Via Top Land)
诱捕连接盘（导通孔顶部连接盘）
22.2117 Target Land(Via Bottom Land)
目标连接盘（导通孔底部连接盘）
22.2140 X-Out
打叉
22.2147 Via Planarization
导通孔平整化
22.2172 Conductor Trace
导体线条
22.2173 Antipad
反盘
22.2081 Via Protection, Bumped
导通孔保护，凸面
22.2082 Via Protection, Dimpled
导通孔保护，凹面
22.2083 Via Protection, Planarized
导通孔保护，平整
22.2182 High Density Interconnect (HDI)
高密度互连（HDI）

24 Phototool Generation and Photographic Processes
照相底片制作和照相过程

24.0052 Artwork Master
照相原版
24.0078 Backlighting
背光
24.0150 Brightness
光亮度
24.0230 Compensated Artwork
已补偿照相底版
24.0242 Composite (Phototool)
组合底片（底片）
24.0334 Cut-and-Peel
切割剥离
24.0335 Cut-and-Strip
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24.0347 D Curve
D曲线
24.0350 Definition (Phototool)
清晰度（底片）
24.0356 Densitometer
显像密度计
24.0357 Density (Phototool)
光密度（底片）
24.0361 Depth of Field (Optical)
景深（光学）
24.0368 Developing (Phototool)
显影（底片）
24.0371 Diazo Material
重氮材料
24.0420 Effective Color Temperature
有效色温
24.0421 Effective Focal Length
有效焦距
24.0456 Photographic Image
底片图像
24.0633 Illuminance
照度
24.0634 Illumination
照明度

24.0727 Luminance
亮度
24.0728 Luminous Energy
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24.0729 Luminous Flux
光通量
24.0746 Master Pattern
底版图形
24.0768 Mirrored Pattern
镜像图形
24.0776 Molecular Dye-Imaging Material
分子染色成像材料
24.0797 Negative
负片
24.0811 Opacity(Photographic)
不透明度（照相）
24.0825 Panchromatic Emulsion
全色乳剂
24.0851 Photographic Operation
照相作业
24.0852 Photographic Plate
照相板
24.0853 Photomaster
照相原版
24.0854 Photometry
光度学
24.0855 Photoplotting
光绘
24.0858 Phototool
底片
24.0859 Phototooling
底片组
24.0860 Phototooling Aid
辅助底片
24.0864 Pinhole (Phototool)
针孔（底片）
24.0879 Plotting
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24.0888 Positive Pattern
正像图形
24.0896 Power of Source
源功率
24.0941 Single-Image Production Master
单个图像生产底版
24.0955 Solarization
曝光过度
24.1004 Spur
凸刺
24.1018 Step-and-Repeat
步进-和-重复
24.1020 Step Wedge
感光级谱
24.1040 System Effective Color Temperature
系统有效色温
24.1104 Transmittance
透光率
24.1173 Working Master
工作原版
24.1195 Optical Image
光学影像
24.1197 Orthochromatic Emulsion
正色乳剂
24.1205 Scribe Coat
划线涂层
24.1234 Reference Master
基准底图
24.1237 Registered Production Master
带定位生产底版
24.1243 Render True Color
呈现真色度
24.1252 Reversal Development
反转显影
24.1257 Right Reading
右读
24.1270 Runout
累积误差
24.1279 Scribing
刻线
24.1308 Radiometry
辐射线测定
24.1347 Characteristic Curve
特性曲线
24.1355 Color Temperature
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24.1366 Contact Printing
接触成像
24.1369 Cosine Law (Illumination)
余弦定律（照明）
24.1456 Opaquer
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24.1470 Photographic Fog
照片灰雾
24.1509 Resolving Power
解像力
24.1512 Right Reading Down
右读朝下
24.1513 Right Reading Up
右读朝上
24.1523 Shadowless Illumination
无影照明
24.1537 Step Scale
光梯尺
24.1630 Color Selectivity
颜色选择性

24.1639 Negative Pattern
负像图形
24.1642 Production Master
生产底版
24.1643 Multiple Image Production Master
多重图像生产底版
24.1645 Multiple Pattern
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24.1791 Individual Test Pattern (ITP)
单独测试图形（ITP）
24.1792 Composite Test Pattern (CTP)
组合测试图形（CTP）
24.1943 Original Production Master
原始生产底版
24.2101 Transmissivity
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25 Electronic Production Data Generation 电子生产数据生成

25.0228 Comment Record
注释记录
25.0246 Conditional End-of-Test
有条件测试结束
25.0254 Conductor Layer No.1
第一层导体层
25.0337 Data-Entry Device
数据输入设备
25.0338 Data-Information Module (DIM)
数据信息模块（DIM）
25.0340 Data Capture
数据获取
25.0342 Data Layer
数据层
25.0381 Digitizing (CAD)
数字化（CAD）
25.0398 Distributed Numerical Control (DNC)
分布式数控（DNC）
25.0490 Feature-Location Record
要素位置记录
25.0664 Job Set
作业包
25.0716 Local Intelligence
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25.0735 Manhattan Distance
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25.0736 Manual Data Input
人工数据输入
25.0773 Modal Form
模态格式
25.0801 Object Code
目标代码
25.0829 Parameter Record
参数记录
25.0867 Pixel
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25.0891 Postprocessing
后处理
25.1176 Nesting
嵌套
25.1193 Numerical Control (NC) (Machining)
数字控制（NC）（加工）
25.1263 Rotational Error
旋转误差
25.1265 Routing Mark
铣切标记
25.1329 Automatic Dimensioning
自动尺寸标注
25.1358 Composite Record
组合记录
25.1361 Computer-Aided Manufacturing (CAM)
计算机辅助制造（CAM）
25.1411 Gerber Data
格柏数据
25.1482 Postprocessor
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25.1729 Alphanumerical
字母数字

26 Technical Documentation 技术文件

26.0086 Baseline Dimensioning
基线尺寸标注
26.0192 Chain Dimensioning
链式尺寸标注
26.0404 Drafting Image
绘制图像
26.0434 Elementary Diagram
接线原理图
26.0444 Engineering Drawing
工程图
26.0743 Master Dot Pattern
点总图
26.0744 Master Drawing
设计总图
26.0826 Panel Drawing
制板文件
26.1091 Tolerance
公差
26.1092 Toleranced Dimension
带公差尺寸
26.1107 Schematic Diagram
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26.1175 X Axis
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26.1231 Reference Dimension
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26.1260 Roadmap
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26.1303 Y Axis
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26.1328 Assembly Drawing
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26.1335 Basic Dimension
理论正确尺寸
26.1486 Printed Board Assembly Drawing
印制板组装图
26.1532 Specification Drawings
技术图纸
26.1572 Bilateral Tolerance
双向公差
26.1634 Manufacturing Drawing
加工图
26.1725 Fabrication Allowance
制作余量
26.1740 Detail Specification
详细规范
26.1778 Basic Specification (BS)
基础规范（BS）
26.1779 Customer Detail Specification (CDS)
客户详细规范（CDS）
26.1780 Capability Detail Specification (CapDS)
能力详细规范（CapDS）
26.1781 Detailed Specification (DS)
详细规范（DS）
26.1782 Generic Specification (GS)
总规范（GS）
26.1783 Sectional Specification (SS)
分规范（SS）
26.1809 Z Axis
Z轴
26.1916 Micron
微米
26.1935 Nominal
标称
26.1936 Nominal Value
标称值
26.2097 Tolerance, Statistical
统计公差
26.2111 Unilateral Tolerance
单向公差
26.2084 AABUS (As Agreed Upon Between User and Supplier)
AABUS（由供需双方协商确定）

29 Other (Engineering and Design Issues)
其它（工程和设计方面）

29.0034 Ambient
环境

3 Components for Electronic Packaging
电子元器件及其封装

30 General (Component Description Issues)
通用（元器件种类方面）

30.0016 Active Device
主动（有源）器件
30.0019 Add-On Component
外加元器件
30.0053 Package Cover
封装外壳
30.0236 Component
元器件
30.0240 Component Pin
元器件插针
30.0369 Device
器件
30.0392 Discrete Component
分立元器件
30.0397 Active Desiccant
活性干燥剂
30.0436 Embedded Component
埋入式元器件
30.0594 Heatsink
散热片
30.0681 Large-Scale Integration (LSI)
大规模集成电路（LSI）
30.0757 Microcircuit
微电路
30.0759 Microelectronics
微电子学
30.0777 Monolithic Integrated Circuit
单片集成电路
30.0821 Package Cap
封装罩
30.0822 Package Lid
封装盖
30.0844 Perimeter Sealing Area
周边密封区
30.0872 Plastic Device
塑封器件
30.1031 Stud-Mount Termination
直装端子
30.1034 Surface Mount Component (SMC)
表面贴装元器件（SMC）
30.1069 Thermal Shunt
热分流
30.1289 Semiconductor
半导体
30.1356 Component Lead
元器件引线
30.1426 Integrated Circuit
集成电路

30.1460 Package
封装
30.1468 Passive Component (Element)
被动（无源）元器件（元素）
30.1520 Separable Component Part
可分离元器件部件
30.1559 Very Large Scale Integration (VLSI)
甚大规模集成电路
30.1596 Bulk Packaging
散装
30.1605 Carrier
载体
30.1606 Cartridge
料盒
30.1679 Desiccant
干燥剂
30.1704 Odd-Shape Chip Type Component
异形片式元器件
30.1735 Component Thermal Masses
元器件热容量
30.1737 Cubic Components
立方体元器件
30.1738 Cylindrical Components
圆柱形元器件
30.1739 Date Code
日期码
30.1754 Leadless Component
无引线元器件
30.1772 Surface Mount Device (SMD)
表面贴装器件（SMD）
30.1848 Floor Life
现场寿命
30.1867 Hermetic (Sealed)
密封
30.1914 Exposure Time (Component)
暴露时间（元器件）
30.1924 Moisture Barrier Bag (MBB)
隔潮袋（MBB）
30.1981 Polarized Component
极性元器件
30.2011 Base Plane
基底面
30.2026 Seating Plane
底座面
30.2153 Interposer
中介基板
30.2162 Integrated Passive Component
集成被动（无源）元器件
30.2163 Passive Array
被动（无源）阵列
30.2164 Passive Network
无源网络

31 Discrete and IC Through-Hole Component Packages
分立和IC通孔元器件封装

31.0067 Axial Lead
轴向引线
31.0942 Single-Inline Package (SIP)
单列直插封装（SIP）
31.1224 Leaded Chip Carrier
有引线芯片载体
31.1273 Sacrificial-Foil Laminate
牺牲箔层压板
31.1387 Dual-Inline Package (DIP)
双列直插封装（DIP）
31.1611 Ceramic Dual-Inline Package (CERDIP)
陶瓷双列直插式封装（CERDIP）
31.1612 Ceramic Pin Grid Array
陶瓷针栅阵列
31.1965 Pin Grid Array (PGA)
针栅阵列（PGA）
31.1997 Radial Lead Component
径向引线元器件

32 Discrete Surface Mount Component Packages
分立表面贴装元器件封装

32.0984 Solid-Tantalum Chip Component
固体钽片式元器件

33 I/C Package Types for Surface Mounting
表面贴装的I/C封装类型

33.0098 Beam Lead Device
梁式引线器件
33.0100 Beam Lead
梁式引线
33.0182 Castellation
城堡形端子
33.0208 Chip Carrier
芯片载体
33.0295 Coplanar Leads
共面引线
33.0523 Flat Pack
扁平封装
33.0579 All Metal Package
全金属封装
33.0689 Anode (BGA)
阳极（BGA）
33.0692 Application Specific Integrated Circuit (ASIC)
专用集成电路（ASIC）
33.0694 Leadless Device
无引线器件
33.0869 Planar-Mount Device
平面贴装器件
33.1435 Leaded Surface-Mount Component
有引线表面贴装元器件

33.1436 Leadless Chip Carrier
无引线芯片载体
33.1437 Leadless Inverted Device
无引线倒置器件
33.1438 Leadless Surface Mount Component
无引线表面贴装元器件
33.1573 Bipolar Device
双极器件
33.1585 Bonding Pad (IC)
键合盘（IC）
33.1613 Ceramic QUAD Flat Pack (CQFP)
陶瓷方形扁平封装（CQFP）
33.1656 Coplanarity
共面性
33.1835 QFP with Bumper (BQFP)
带护耳的QFP（BQFP）
33.1836 Quad Flat Pack (QFP)
方形扁平封装（QFP）
33.1837 Fine Pitch QFP
细间距QFP
33.1838 Fine-Pitch BGA/Chip Scale Package (CSP)
细间距BGA/芯片规模封装（CSP）
33.1868 High Density Plastic Quad Flat Pack
高密度塑料方形扁平封装
33.1891 Land Grid Array (LGA)
盘栅阵列（LGA）
33.1971 Plastic Ball Grid Array (PBGA)
塑封球栅阵列（PBGA）
33.1972 Plastic Leaded Chip Carrier (PLCC)
塑封有引线芯片载体（PLCC）
33.1973 Plastic QFP (PQFP)
塑封QFP（PQFP）
33.1974 Plastic QUAD Flat Pack (PQFP)
塑封方形扁平封装（PQFP）
33.2030 Shrink SOP (SSOP)
缩小型SOP（SSOP）
33.2034 Single Chip Package (SCP)
单芯片封装（SCP）
33.2077 Tape Carrier Package (TCP)
载带封装（TCP）
33.2092 Thin QUAD Flat Pack (TQFP)
薄方形扁平封装（TQFP）
33.2093 Thin Small Outline Package (TSOP)
薄小外形封装（TSOP）
33.2136 Zigzag In-line Package
锯齿状直插封装
33.2156 Quad Flat J-Lead (QFJ)
矩形扁平J形引线封装（QFJ）
33.2157 Quad Flat No-Lead (QFN)
矩形扁平无引线封装（QFN）
33.2158 Small Outline J-Lead (SOJ)
小外形J形引线封装（SOJ）
33.2159 Small Outline No-Lead (SON)
小外形无引线封装（SON）
33.2160 Small Outline Package (SOP)
小外形封装（SOP）

34 Grid Array Packages
栅阵列封装

34.0751 Area Array
面阵列
34.0976 Ball
焊球
34.1086 Ball Array
球阵列
34.1096 Ball Grid Array (BGA)
球栅阵列（BGA）
34.1598 Bump
凸点
34.1599 Bump Array
凸点阵列
34.1601 Bump Contact
凸点触点
34.2141 Cupping (BGA)
杯形（BGA）
34.2142 Doming (BGA)
拱形（BGA）
34.2184 Column Grid Array (CGA)
柱栅阵列（CGA）

35 Bare Die
裸芯片

35.0151 Broken Pick
断纬
35.0205 Chip
芯片
35.0373 Dice
芯片群
35.0375 Die
芯片
35.0400 Doping
掺杂质
35.0612 Alpha Particle
α粒子
35.0666 Junction Temperature
结温度
35.0846 Known Good Die (KGD)
已知良好芯片（KGD）
35.0949 Slice
薄片
35.1122 Uncased Device
无外壳器件
35.1145 Wafer
晶圆

35.1685 Dicing
切片
35.1686 Die Paddle
芯片座
35.1687 Die Pad
芯片焊盘
35.1688 Die Attached Pad
芯片连接盘
35.1689 Die Mount Pad
芯片安装盘
35.1690 Die Shrink
芯片缩小
35.1696 Distance to Neutral Point (DNP)
距中点距离（DNP）
35.1857 Frit (Semiconductor)
玻璃料（半导体）
35.1931 Neutral Point
中点
35.1946 Paddle
焊盘垫
35.2037 Soft Error
软故障
35.2108 Under Bump Metallization
凸点底部金属化
35.2130 Wire Bond
金属线键合
35.2154 Wafer Level Package (WLP)
晶圆级封装（WLP）
35.2155 System in Package (SiP)
系统级封装（SiP）

36 Component and Lead/Termination Properties 元器件与引线/端子特性

36.0006 Accordion Contact
折叠式接触件
36.0017 Active Metal
活泼金属
36.0075 Backfill
回填
36.0243 Compression Seal
收缩密封
36.0424 Elastomeric Connector
弹性连接器
36.0590 Header (Module)
基座（模块）
36.0688 Lead
引线
36.0696 Lead Pin
引线插针
36.0698 Lead Wire
引线
36.0785 Multilayer Carrier Tape
多层载带
36.0807 Omnibus Ring
公共环
36.1025 Stress Relief
应力消除
36.1033 Support Ring
支撑环
36.1164 Window (Carrier Tape)
窗口（载带）
36.1337 Bellows Contact
扁簧接触件
36.1345 Carrier Tape
载带
36.1528 Single-Layer Carrier Tape
单层载带
36.1546 Three-Layer Carrier Tape
三层载带
36.1554 Two-Layer Carrier Tape
双层载带
36.1666 Dambar
挡条
36.1732 Butt Leads
垛形引线（I形引线）
36.1741 Dissolution of Metallization
金属层溶蚀
36.1747 Gull Wing Leads
翼形引线
36.1752 J-Leads
J形引线
36.1764 Rectangular Leads
矩形引线
36.1810 Bifurcated Contact
双叉接触件
36.1901 Lead Fingers
引线手指
36.1902 Lead Frame
引线框架
36.1921 Minimum Bump Pitch
最小凸点间距

37 Components for Wiring and Cabling 金属线和电缆的元器件

37.0106 Bifurcated Solder Terminal
双叉焊接接线柱
37.0145 Boss (Connector)
凸台（连接器）
37.0169 Bus Bar
汇流条
37.0203 Chemical Wire Stripping
化学剥线
37.0218 Closed-Entry Contact
闭口接触件
37.0220 Coaxial Cable
同轴线缆

37.0265 Connector
连接器
37.0268 Connector, Two-Part, Printed Board
印制板双件连接器
37.0271 Connector Housing
连接器外壳
37.0272 Connector Tang
连接插头
37.0282 Contact Spring
接触弹簧
37.0318 Crimp Contact
压接接触件
37.0329 Cup Solder Terminal
焊锡杯
37.0405 Drain Wire
加蔽线
37.0412 Edge-Board Connector
板边连接器
37.0466 Eyelet
空心铆钉
37.0486 FCC System
FCC系统
37.0518 Fixed Contact
固定接触件
37.0522 Flat Cable
扁平电缆
37.0533 Floating Bushing
浮动衬套
37.0583 Guide Pin
引导销
37.0589 Header (Connector)
接插件（连接器）
37.0602 Hermaphroditic Contact
等同接合接触件
37.0606 High-Voltage Wire
高压线
37.0619 Hook Solder Terminal
钩形焊接接线柱
37.0653 Interface Resistance
界面电阻
37.0665 Jumper Wire
跳线
37.0668 Key
锁键
37.0669 Keyway
键销槽
37.0683 Latch (Connector)
弹簧锁（连接器）
37.0731 Machined Contact
机械接触件
37.0739 Margin (Flat Cable)
边距（扁平电缆）
37.0809 One-Piece Connector
单件连接器
37.0813 Open-Entry Contact
开口接触件
37.0880 Plug Connector
插塞式连接器
37.0889 Post
端柱
37.0905 Pressfit Contact
压合接触件
37.0954 Socket Contact
插座接触件
37.0980 Solder Terminal
焊接接线柱
37.0992 Spade Contact
铲形接触件
37.1014 Standoff Solder Terminal
高脚焊接接线柱
37.1023 Strain Relief (Connector)
释力夹（连接器）
37.1051 Terminal
接线柱
37.1115 Two-Piece Contact
两件式接触件
37.1167 Wiping Action
滑触作用
37.1239 Scoop-Proof Connectors
防划损连接器
37.1242 Removable Contact
可移动接插件
37.1255 Ribbon Cable
带状电缆
37.1256 Ribbon Interconnect
带状互连
37.1299 Sheet-Metal Contact
金属片接触件
37.1313 Receptacle Connector
插座式连接器
37.1338 Birdcage
呈鸟笼状散开的导线
37.1405 Fork Contact
叉形接触件
37.1420 Insert (Connector)
嵌入物（连接器）
37.1430 Keying (n.)
锁定键（名词）
37.1431 Keying (v.)
键锁定（动词）
37.1469 Perforated (Pierced) Solder Terminal
穿孔焊接接线柱
37.1552 Turret Solder Terminal
塔形焊接接线柱

37.1567 Wire Stripping
剥线
37.2029 Semi-Rigid Cable
半刚性电缆
37.2039 Solder Contact
焊接接触件

4 Materials for Electronic Packaging
电子封装材料

40 General (Material Issues)
通用（材料方面）

40.0035 Amorphous Polymer
无定形聚合物
40.0087 Absorptivity, Infra-red
红外吸光率
40.0091 Basis Material
基体材料
40.0183 Catalyst (Resin)
催化剂（树脂）
40.0221 Coefficient of Thermal Expansion (CTE)
热膨胀系数
40.0250 Conductivity (Electrical)
电导率
40.0316 Creep
蠕变
40.0326 Crosslink
交联
40.0328 Crystalline Polymer
晶体聚合物
40.0377 Dielectric
电介质
40.0383 Dimorphism
双晶现象
40.0685 Anisotropy
各向异性
40.0870 Plastic
塑料
40.0871 Plastic Deformation
塑性变形
40.0884 Polymerize
聚合
40.1071 Thermoplastic
热塑性塑料
40.1246 Resin
树脂
40.1334 Base Material
基材
40.1471 Base Film (Flexible Circuits)
基膜（挠性电路）
40.1479 Polymer
聚合物
40.1544 Thermoset
热固性塑料
40.1590 Brown Streak (Base Materials)
棕色条纹（基材）
40.1591 Brown Thread (Base Materials)
棕色丝（基材）
40.1602 Burnt Resin (Base Materials)
烧焦树脂（基材）
40.1616 Chemical Resistance
耐化学性
40.1635 Conductance
电导
40.1661 Creep Endurance
耐蠕变性
40.1675 Density (Material)
密度（材料）
40.1684 Dewetting (Base Materials)
半润湿（基材）
40.1721 Epoxy Resin
环氧树脂
40.1727 Absorption Coefficients
吸收系数
40.1800 Flat Conductor
扁平导体
40.1813 Insulation
绝缘体
40.1842 Flame Resistance
耐燃性
40.1843 Flame Retardance
阻燃性
40.1844 Flammability
可燃性
40.1885 Isotropy
各向同性
40.1917 Microwave Laminate
微波层压板
40.1923 Moisture Absorption
吸湿性
40.1925 Moisture Resistance
防潮性
40.2002 Pallet (Printed Board)
拼托板（印制板）
40.2018 Rheology
流变学
40.2053 Specific Gravity
比重
40.2082 Thermal Cure
热固化
40.2107 Ultraviolet Cure
紫外线固化
40.2169 Conductivity (Thermal)
热导率

41 Rigid Printed Board Substrate Materials (Organic)
刚性印制板基板材料（有机）

41.0069 B-Staged Material
B阶材料

41.0070 B-Staged Resin
B阶树脂

41.0111 Bismaleimide
双马来酰亚胺

41.0112 Bismaleimide Triazine
双马来酰亚胺三嗪

41.0114 Blends
混合物

41.0152 Brominated Epoxy
溴化环氧树脂

41.0170 Butter Coat
厚涂层

41.0171 C-Staged Resin
C阶树脂

41.0374 Dicyandiamide
双氰胺

41.0393 Dispersant (Organosol)
分散剂（有机溶剂）

41.0394 Disperse Phase (Suspension)
分散相（悬浮）

41.0395 Dispersing Agent
分散剂

41.0438 Adhesive Coated Substrate
涂胶基板

41.0445 Epoxy Novolac
环氧酚醛

41.0555 Functionality, Resin or Curing Agent
树脂或固化剂官能数

41.0673 Laminate Thickness
层压板厚度

41.0752 Metal-Clad Laminate
覆金属箔层压板

41.0819 Oxide Transfer
氧化物转移

41.0903 Preimpregnated Bonding Sheet
预浸粘结片

41.0904 Prepreg
预浸材料

41.1142 Volume Ratio (Composite)
体积比（复合材料）

41.1207 Substrate
基板

41.1320 Adhesive-Coated Catalyzed Laminate
涂胶催化层压板

41.1323 Adhesive-Coated Uncatalyzed Laminate
涂胶非催化层压板

41.1339 Blank
料板

41.1343 B-Stage
B阶

41.1463 Panel
在制板

41.1505 Resin-Rich Area
富树脂区

41.1507 Resin-Starved Area
缺树脂区

41.1583 Board Thickness
板厚

41.1609 Metal-Clad Base Material
覆金属箔基材

41.1657 Copper Thickness
铜厚

41.1658 Copper Weight
铜重

41.1706 Dry Glass (Clad Laminate)
干玻（覆箔层压板）

41.1743 Epoxy Glass Substrate
环氧玻璃基板

41.1962 Phenolic Resin
酚醛树酯

41.1967 Pin-Hole (Base Materials)
针孔（基材）

41.2016 Reverse-Treated Core
反向处理芯板

41.2066 Stress Relief (Clad Laminate)
应力消除（覆金属箔层压板）

41.2124 Waviness, (Base Materials)
波纹（基材）

41.2148 Fabrication Panel
制作在制板

42 Flexible Printed Board Substrate Materials (Organic)
挠性印制板基材（有机）

42.0303 Coverfilm
覆盖膜

42.0304 Coverlay
覆盖层

42.1982 Polyester
聚酯

42.1983 Polyimide
聚酰亚胺

42.2019 Roll-to-Roll Process
成卷式生产工艺

42.2137 Service Temperature (Flexible Circuits)
工作温度（挠性电路）

42.2139 Covercoat
覆盖涂层

42.2179 Cover Material
覆盖材料

43 Inorganic Substrates for Interconnecting Structures
互连结构用无机基板

43.1730 Alumina Substrate
氧化铝基板

44 Reinforcement/Constraining Core/Heat Dissipation Materials
增强材料/夹芯/散热材料

44.0045 Aramid
芳酰胺
44.0099 Beaming
并轴
44.0105 Bias (Fabric)
纬斜（织物）
44.0146 Bow (Fabric)
弓纬（织物）
44.0273 Constraining Core
抑制芯
44.0298 Coronizing
高温处理
44.0315 Creel
经轴架
44.0355 Denier
丹尼尔
44.0423 E Glass
E玻璃
44.0442 End Missing
断经
44.0487 Feather Length
毛边长度
44.0496 Fill
纬线
44.0497 Filler
填料
44.0506 Finished Fabric
经处理织物
44.0516 Fish Eye
鱼眼
44.0528 Flexural Strength
弯曲强度
44.0531 Float
跳线
44.0565 Gelation Particle
胶化颗粒
44.0569 Glass Binder
玻璃粘合剂
44.0575 Grading Frame
分级系统
44.0578 Greige
生坯布
44.0591 Heat Cleaning
热清洗
44.0596 Heavy Mark (Fabric)
厚段（织物）
44.0702 Leno End Out
纱罗边毛边
44.0708 Light Mark (Fabric)
薄段（织物）
44.0723 Loom Beam
织机经轴
44.0741 Mark (Fabric)
织痕（织物）
44.0769 Mis-Pick
缺纬
44.0834 Passive Base Material
惰性基材
44.0861 Pick
纬纱
44.0868 Plain Weave
平纹编织
44.0878 Plied Yarn
合股线
44.0930 Shuttle
梭子
44.0948 Sizing
上浆
44.0999 Split (Fabric)
裂缝（织物）
44.1027 Stripback
断纱折回
44.1032 Supporting Plane
支撑面
44.1047 Tear (Fabric)
撕裂（织物）
44.1049 Tenter Frame
拉幅机
44.1112 Trumeter
精度测量计
44.1127 Unfil
纡子
44.1148 Warper
整经机
44.1149 Warp Size
经纱上浆
44.1153 Waviness
波纹
44.1202 Quill
线轴
44.1230 Reed
钢筘
44.1266 Roving
粗纱
44.1284 Section Beam
接线轴

44.1288 Selvage
织边
44.1464 Para-Aramid
对芳酰胺
44.1516 Satin Weave
缎纹组织
44.1564 Waste (Fabric)
废纱（织物）
44.1825 Embedded Fiber (Base Materials)
埋纤（基材）
44.1840 Fisheye (Prepreg)
鱼眼（预浸材料）
44.1858 Glass Cloth
玻璃布
44.1859 Glass Fabric
玻璃织物
44.1860 Glass Distortion (Base Materials)
玻璃扭曲（基材）
44.1861 Glass Yarn
玻璃纱
44.1887 Knot (Base Materials)
节瘤（基材）
44.1937 Nonwoven Glass Mat
无纺玻璃毡
44.1985 Resin Particle (Base Material)
树脂颗粒（基材）
44.1994 Quartz Fiber (Electrical Grade)
石英纤维（电子级）
44.2103 Treater Dirt (Base Materials)
浸胶异物（基材）
44.2104 Treatment Transfer (Base Materials)
处理物转移（基材）
44.2125 Weave Style (Fabric)
编织类型（织物）
44.2126 Weave Texture
显布纹

45 Conductive Materials (Foil, Film or Plating)
导电材料（箔、膜或镀层）

45.0054 As-Fired
烧结态
45.0088 Base Metal
基体金属
45.0092 Basis Metal
金属基材
45.0180 Carrier (Foil)
载体（箔）
45.0202 Chemical Vapor Deposition
化学气相沉积
45.0249 Conductive Foil
导电箔
45.0358 Dent
压痕
45.0425 Electrodeposited Foil
电沉积金属箔
45.0500 Film
膜
45.0501 Film Conductor
膜导体
45.0546 Foil Profile
箔轮廓
45.0638 Indentation
凹痕
45.1079 Thin Film
薄膜
45.1080 Thin Foil
薄金属箔
45.1174 Wrought Foil
压延箔
45.1274 Sacrificial Protection
牺牲性保护
45.1459 Outgrowth
镀层增宽
45.1545 Thick Film
厚膜
45.1636 Conductive Paint
导电涂料
45.1637 Conductive Paste
导电膏
45.1700 Doubled-Treated Foil (DTF)
双面处理金属箔（DTF）
45.1718 Embedded Copper (Base Materials)
埋铜（基材）
45.1888 Kovar
科瓦铁镍钴合金
45.1903 Lead-free Plating
无铅镀层
45.1947 Alloy, Tin Bismuth (Sn-Bi)
锡铋合金（Sn-Bi）
45.1948 Alloy, Tin Copper (Sn-Cu)
锡铜合金（Sn-Cu）
45.1949 Alloy, Tin Silver (Sn-Ag)
锡银合金（Sn-Ag）
45.1950 Alloy, Tin Silver Bismuth (Sn-Ag-Bi)
锡银铋合金（Sn-Ag-Bi）
45.1951 Alloy, Tin Silver Copper (Sn-Ag-Cu)
锡银铜合金（Sn-Ag-Cu）
45.1952 Alloy, Tin Zinc (Sn-Zn)
锡锌合金（Sn-Zn）
45.1964 Physical Vapor Deposition
物理汽相沉积
45.1969 Planar Resistor
平面电阻
45.1976 Plating Solution
电镀溶液

45.2013 Resistive Clad Laminate
电阻覆金属箔层压板
45.2017 Reverse-Treated Foil (RIP)
反向处理金属箔（RTF）
45.2170 Conductive Medium
导电介质
45.2171 Conductive Ink
导电墨
45.2180 Copper Island
铜岛

46 Component Attachment Materials (Conductive/Nonconductive)
元器件固定材料（导电/非导电）

46.0008 Acid-Core Solder
酸性芯焊料
46.0009 Acid Flux
酸性助焊剂
46.0012 Activated Rosin Flux
活性松香助焊剂
46.0015 Activator
活化剂
46.0044 Aqueous Flux
水性助焊剂
46.0539 Flux-Cored Solder
助焊剂芯焊料
46.0956 Solder
焊料
46.0965 Solder Cream
焊膏
46.1262 Rosin Flux
松香助焊剂
46.1491 Base Metal (Solder)
基体金属（焊料）
46.1514 Rosin
松香
46.1607 Poise
泊
46.1608 Centipoise
厘泊
46.1610 Viscosity
粘性
46.1728 Adhesive
粘合剂
46.1818 Solder Paste
焊膏
46.1839 Fisheye (Adhesive)
鱼眼（粘合剂）
46.1841 Fisheyes (Pressure Sensitive Tape)
鱼眼（压敏胶带）
46.1869 Creep Resistant Holding Power (Pressure Sensitive Tape)
抗蠕变保持力（压敏胶带）
46.2038 Adhesion (Pressure Sensitive Tape)
附着力（压敏胶带）
46.2046 Solder Powder
焊料粉
46.2049 Solder, Silver-Tin
锡银焊料

47 Coating and Permanent Masking Materials
涂料和永久性掩蔽材料

47.0107 Binder
粘结剂
47.0261 Swelling (Cured Solder Mask)
膨胀（已固化的阻焊膜）
47.0742 Mask
掩膜
47.0873 Softening (Cured Solder Mask)
软化（已固化的阻焊膜）
47.0892 Potting Compound
灌封化合物
47.0927 Liquefaction (Cured Solder Mask)
液化（已固化阻焊膜）
47.0973 Solder Mask
阻焊膜
47.1005 Chalking (Cured Solder Mask)
粉化（固化的阻焊膜）
47.1203 Peeling (Cured Solder Mask)
剥离（已固化的阻焊膜）
47.1631 Combination Mask
组合掩膜
47.1674 Solder Resist
阻焊剂
47.1995 Wicking (Solder Mask)
芯吸（阻焊膜）
47.2086 Organic Solderability Preservative (OSP)
有机可焊性保护剂（OSP）
47.2181 Protective Isolation Coating
保护性绝缘涂层
47.2185 Marking
标记

49 Other (Material Issues)
其他（材料方面）

49.0068 Azeotrope
共沸物
49.0096 Embedded Passive
埋入式被动（无源）材料片
49.0847 Copolymerize
共聚
49.1082 Thixotropic Ratio
触变率
49.1083 Thixotropy
触变性

49.1330 Azeotropic Mixture (Azeotrope)
共沸混合物（共沸物）
49.2161 Embedded Passive Component (Device)
埋入式被动（无源）元器件（器件）
49.2165 Embedded Component (Inserted)
埋入式元器件（插入）
49.2166 Embedded Component (Formed)
埋入式元器件（成形）
49.2167 Embedded Active Component (Device)
埋入式主动（有源）元器件（器件）

5 Fabrication Processes for Interconnection Structures
互连结构的制造工艺

50 General (Interconnection Structure Fabrication Processes)
通用（互连结构制造工艺）

50.0200 Chemically-Deposited Printed Wiring
化学沉积印制线路
50.0201 Chemically-Deposited Printed Circuit
化学沉积印制电路
50.0771 Misregistration
重合不良
50.1209 Subtractive Process
减成法工艺
50.1240 Registration
重合度
50.1542 Thermal Zone
受热区
50.1646 Multiple Printed Board
多印制板
50.1786 Production Printed Board (PPB)
成品印制板（PPB）
50.1787 Production Panel (PP)
生产拼板（PP）
50.1788 Delivered Panel (DP)
交付拼板（DP）
50.1912 Board Fabricator
印制板制造商
51.2020 Router Bit
铣刀
51.2057 Stack Pin
支撑销
50.2095 Through-Hole Technology (THT)
通孔组装技术（THT）

51 Mechanical Processes
机械加工

51.0081 Back Taper(s)
倒锥
51.0181 Carry-Out
排屑口
51.0193 Chamfer (Drill)
倒角（钻头）
51.0209 Chipped Point
钻尖缺损
51.0211 Chisel-Edge Angle
横刃角
51.0257 Chipping
碎边角
51.0312 Crazing (Base Material)
微裂纹（基材）
51.0407 Drill Body Length
钻体长度
51.0408 Drill Diameter
钻头直径
51.0409 Drill Point Concentricity
钻尖同心度
51.0446 Epoxy Smear
环氧钻污
51.0544 Foil Burr
金属箔毛刺
51.0597 Heel (Drill)
后棱（钻头）
51.0601 Helix Angle
螺旋角
51.0618 Hook
刃钩
51.0676 Land (Drill)
刃带（钻头）
51.0679 Land Width (Drill)
刃带宽度（钻头）
51.0684 Layback
刃背
51.0712 Lip Height
刃缘高度
51.0740 Margin Width (Drill)
棱边宽度（钻头）
51.0794 Nail Heading
钉头
51.0881 Point Angle
顶角
51.0907 Primary Flare
外倾
51.0908 Primary Relief
第一后角
51.0910 Primary Taper
内倾
51.0929 Shoulder Angle
肩角
51.0998 Splay
斜孔
51.1155 Web Taper
钻心锥度

51.1156 Web Thickness
钻心厚度
51.1200 Overall Length
钻刀总长度
51.1223 Land Width Angle (Drill)
刃带宽度角
51.1229 Overlap (Drill)
重叠（钻头）
51.1282 Secondary Relief
第二后角
51.1295 Shank
钻柄
51.1296 Shank-to-Drill Body Concentricity
钻柄对钻体同心度
51.1297 Shank Diameter
钻柄直径
51.1341 Body Land Clearance
钻体刃带间隙
51.1400 Flare
锥口
51.1415 Haloing
晕圈
51.1457 Open Point
分离
51.1506 Resin Smear
树脂钻污
51.1574 Blanking
开料
51.1633 Compound Die Set
组合冲切装置
51.1702 Drill Bit
钻头
51.1703 Drilling
钻孔
51.1709 Hole Edge Roughness
孔边粗糙度
51.1710 Hole Roughness
孔粗糙度
51.1719 End Mill
端铣刀
51.1720 Entry/Backup Material
盖板/垫板
51.1870 Hole Base Positioning
孔基准定位
51.1992 Punching
冲压
51.1993 Push Back
复位
51.2178 Singulate
提取单片

52 Imaging and Application of Resists and Inks
抗使剂和油墨的成像与涂敷

52.0011 Actinic Radiation
有效光
52.0113 Bleeding
渗出
52.0845 Permanent Resist
永久性抗蚀剂
52.0850 Photographic Layer
感光层
52.0856 Photoprint
光成像
52.0857 Photoresist Image
光致抗蚀图像
52.0914 Printed Component
印制元器件
52.0937 Silk screening
丝印
52.0947 Skipping
漏印
52.1050 Tenting
掩蔽
52.1131 Usable Resolution
有效解像度
52.1204 Screen Printing
网印
52.1254 Reverse Image
负像
52.1448 Negative-Acting Resist
负性抗蚀剂
52.1472 Photoresist
光致抗蚀剂
52.1481 Positive-Acting Resist
正性抗蚀剂
52.1508 Resist (Mask)
阻焊剂（膜）
52.1575 Image Blur
图像模糊
52.1592 Printing
印制
52.1600 Printed Components, Conductive Inks
导电油墨印制元器件
52.1682 Development (Resist)
显影（抗蚀剂）
52.1701 Definition
逼真度
52.1705 Dry Film Resist
干膜抗蚀剂
52.1724 Exposure
曝光
52.1789 Off-Contact Printing
非接触印刷
52.1852 Stencil (Solder Mask)
模板（阻焊膜）

52.1889 Lamination (Dry Film)
贴膜（干膜）
52.1895 Laser Direct Imaging (LDI)
激光直接成像（LDI）
52.1940 On-Contact Printing
接触印刷
52.1975 Plating Resist
电镀抗蚀剂
52.1979 Hole Filling Process
填孔工艺
52.1980 Hole Plugging Process
塞孔工艺
52.2025 Scum
残渣
52.2069 Strip (Resist Stripping)
剥离（抗蚀剂剥离）

53 Material Deposition Processes, including Plating
金属沉积过程，包括电镀

53.0002 Accelerator
加速剂
53.0013 Activating
活化
53.0014 Activating Layer
活化层
53.0022 Adhesion Promotion
附着力增强
53.0056 Aspect Ratio (Hole)
厚径比（孔）
53.0117 Blow Hole
气孔
53.0184 Catalyzing
催化
53.0255 Photographic-Reduction Dimension
照相缩制尺寸
53.0319 Critical Current Density
临界电流密度
53.0426 Electrodeposition
电沉积
53.0427 Electroless Deposition
无电沉积
53.0428 Electroless Plating
无电电镀
53.0430 Electrolytic Deposition
电解沉积
53.0433 Electroplating
电镀
53.0502 Film Network
膜网络
53.0554 Fully-Electroless Process
全无电工艺
53.0560 Galvanic Deposition
电镀沉积
53.0561 Galvanic Displacement
电镀置换
53.0613 Hole Pull Strength
孔拉出强度
53.0614 Hole Void
孔空洞
53.0635 Immersion Plating
浸镀
53.0645 Initiating
引发
53.0656 Interlaminar Metallization
层内金属化
53.0753 Metalization (n.)
金属化（名词）
53.0827 Panel Plating
全板电镀
53.0840 Pattern Plating
图形电镀
53.0874 Plating
电镀
53.0875 Plating, Burned
镀层烧焦
53.0876 Plating Bar
电镀工艺导线
53.0877 Plating Up
镀层加厚
53.0906 Pretinning
预上锡
53.0962 Solder Coat
焊料涂层
53.1007 Sputtering
溅涂
53.1088 Tie Bar
分流线
53.1133 Vacuum Evaporation
真空蒸镀
53.1199 Outgassing
排气
53.1261 Robber
分流
53.1285 Seeding
强化
53.1286 Seed Layer
强化层
53.1291 Sensitizing
敏化
53.1322 Additive Process
加成法工艺
53.1407 Fully Additive Process
全加成法工艺
53.1477 Plating Thief
分流阴极

53.1518 Semi-Additive Process
半加成法工艺
53.1540 Swell-and-Etch Process
溶胀–蚀刻工艺
53.1549 Treeing
树枝状结晶
53.1647 Contact Plating
接触镀层
53.1673 Overplate
外镀层
53.1677 Solder Levelling
焊料整平
53.1691 Die Stamping (Conductor)
模具压印法（导体）
53.1711 Hole, Knee
孔膝
53.1871 Hot Air (Solder) Leveling (HASL)
热风（焊料）整平（HASL）
53.1894 Laser Bonding
激光键合
53.1953 Plating, Palladium
钯镀层
53.1954 Plating, Tin (Sn)
锡（Sn）镀层
53.1955 Plating, Tin Bismuth (Sn-Bi)
锡铋（SnBi）镀层
53.1956 Plating, Tin Copper (Sn-Cu)
锡铜（SnCu）镀层
53.1957 Plating, Tin Silver (Sn-Ag)
锡银（SnAg）镀层
53.1977 Plating Void
镀层空洞
53.2064 Step Plating
阶梯状电镀
53.2067 Strike Plating
闪镀层
53.2096 Throwing Power
布散能力
53.2110 Underplate
基底镀层
53.2168 Plating Fold
镀层折叠

54 Material Removal Processes, including Etching
材料除去过程，包括蚀刻

54.0010 Acid Number
酸值
54.0245 Concentration Polarization
浓差极化
54.0248 Conducting Salt
导电盐
54.0450 Etchant
蚀刻剂
54.0452 Etch Factor
蚀刻因子
54.0453 Etching
蚀刻
54.0574 Graded Wedge
定级楔形图
54.0798 Negative Etchback
负凹蚀
54.0953 Smear Removal
钻污去除
54.1217 Acid Value
酸价
54.1294 Shadowing, Etchback
凹蚀阴影
54.1318 Abrasive Trimming
磨削修整
54.1321 Active Trimming
带电修整
54.1389 Etchback
凹蚀
54.1390 Etching Indicator
蚀刻指示图
54.1589 Breakaway
分离
54.1692 Differential Etching
差分蚀刻法
54.1723 Etch Resist
抗蚀剂
54.1821 Abrasion Resistance
耐磨性
54.1959 Perforation
邮票孔
54.1960 V-Groove
V形槽
54.1978 Plenum
增压箱
54.2015 Reverse Etchback
反向凹蚀
54.2021 Routing
铣切
54.2109 Undercut, Resist or Masking Material
蚀刻剂或掩膜材料侧蚀

55 Lamination, Sequential Deposition, and Molding Processes
层压、顺序沉积及模制工艺

55.0130 Bonding Layer
粘接层
55.0176 Cap Lamination
覆盖层压
55.0545 Foil Lamination
覆箔层压

55.0566 Gel Time
胶凝时间
55.0672 Laminate (n.)
层压板（名词）
55.0748 Measling
白斑
55.0865 Pink Ring
粉红环
55.0898 Pre-finish (n.)
预调整剂
55.0900 Preflow
预流动
55.1154 Weave Exposure
露织物
55.1350 Clad (adj.)
覆箔的（形容词）
55.1376 Delamination
分层
55.1412 Glass Transition Temperature (Tg)
玻璃化温度
55.1443 Mass Lamination
叠合层压
55.1449 Nominal Cured Thickness
标称固化厚度
55.1474 Plate Finish, Laminating
层压模板抛光
55.1890 Lamination (Multilayer)
层压（多层）
55.1899 Layer-to Layer-Registration
层间对位
55.1900 Lay-Up
叠层
55.1966 Pin Lamination
销钉层压
55.2085 Time to Decomposition (Td)
分解温度（Td）

56 Thermal Cure/Firing Processes
热固化/烘烤加工

56.0082 Bake Out
烘除
56.0093 Batch Oven
成批烘炉
56.0219 Co-Firing
共烧
56.0330 Cure
固化
56.0331 Cure Time
固化时间
56.0332 Curing Agent
固化剂
56.0467 Fusing Fluid
热熔液
56.0508 Fire (v.)
烧结（动词）
56.0509 Firing Sensitivity
烧结敏感度
56.0517 Fissuring
裂隙
56.0557 Fused Coating
热熔涂覆层
56.0577 Green Strength
未固化强度
56.0586 Hardeners
硬化剂
56.0593 Heat of Fusion
熔化热
56.0660 Intumescence
膨胀
56.0703 Leveling
整平
56.0704 Leveling Flux
整平助焊剂
56.0705 Leveling Oil
整平油
56.0890 Post Curing
后固化
56.0902 Preheat (n.)
预热（名词）
56.1304 Radiant Flux
辐射通量
56.1305 Radiant Intensity
辐射强度
56.1306 Radiator, Focused
聚焦辐射器
56.1307 Radiator, Nonfocused
非聚焦反射器
56.1408 Fusing Flux
热熔助焊剂
56.1409 Fusing Oil
热熔油
56.1483 Preheating (v.)
预热（动词）
56.1676 Fusing
热熔

57 Cleaning and Chemical Treatment Processes
清洗和化学处理工艺

57.0042 Anodic Cleaning
阳极清洗
57.0185 Cathodic Cleaning
阴极清洗
57.0199 Chemical Conversion Coating
化学转换涂层
57.0366 Desmear
去钻污

57.0832 Passivation
钝化（处理）
57.1009 Stabilization Period
稳定期

59 Other (Interconnecting Structure Fabrication Processes)
其他（互连结构制作工艺）

59.0186 Cation Exchange
阳离子交换
59.0187 Cationic Reagent
阳离子表面活性剂

6 Type and Performance of Interconnecting Structures
互连结构的类型和性能

60 General (Interconnecting Structure Type and Performance)
通用（互连结构类型和性能）

60.0041 Annular Ring (Annular Width)
孔环（环宽）
60.0084 Bare Board
裸板
60.0118 Board
板
60.0139 Bond Strength
粘合强度
60.0148 Breakout
破出
60.0156 Bulge
凸起
60.0177 Card
卡板
60.0214 Circuit Card
电路卡
60.0252 Conductor Base Spacing
导体底距
60.0253 Conductor Base Width
导体底宽
60.0402 Double-Sided Printed Board
双面印制板
60.0451 Etched Printed Boards
已蚀刻印制板
60.0707 Lifted Land
连接盘浮起
60.0786 Multilayer Printed Circuit Board
多层印制电路板
60.0788 Multilayer Printed Wiring Board
多层印制线路板
60.0810 One-Sided Board
一面板
60.0816 Overhang
镀层突沿
60.0823 Packaging and Interconnecting Assembly
封装及互连组件
60.0912 Printed Circuit
印制电路
60.0945 Single-Sided Printed Board
单面印制板
60.1013 Stamped Printed Wiring
冲压印制线路
60.1116 Two-Sided Board
两面板
60.1147 Warp
翘曲
60.1179 Nick
缺口
60.1181 Nodule
结瘤
60.1218 Bow (Sheet, Panel, or Printed Board)
弓曲（整板、在制板或印制板）
60.1227 Multilayer Printed Board
多层印制板
60.1319 Access Hole
余隙孔
60.1363 Conductor Spacing
导体间距
60.1364 Conductor Width
导体宽度
60.1461 Packaging and Interconnection Structure
封装及互连结构
60.1485 Printed Board (PB)
印制板（PB）
60.1487 Printed Circuit Board
印制电路板
60.1488 Printed Wiring
印制线路
60.1489 Printed Wiring Board
印制线路板
60.1490 Production Board
成品板
60.1504 Resin Recession
树脂凹缩
60.1553 Twist
扭曲
60.1625 Circuit Board
电路板
60.1698 Double-Sided Printed Wiring Board
双面印制线路板
60.1699 Hole Breakout
孔破出
60.1970 Planer Board
平面板

60.2065 Stiffener Board
增强板
60.2143 Button Plating
钮扣电镀
60.2144 Wrap Plating
包覆电镀
60.2145 Butt Plating Joint
对接电镀接点
60.2146 Butt Plating Joint (Wrap Plating)
对接电镀接点（包覆镀层）
60.2149 Finished Board
成品板

61 Rigid Printed Boards (Organic)
刚性印制板（有机）

61.1521 Sequentially-Laminated Multilayer Printed Board
顺序层压多层印制板
61.1571 Rigid Printed Board
刚性印制板
61.1576 Rigid Single-Sided Printed Board
刚性单面印制板
61.1577 Rigid Double-Sided Printed Board
刚性双面印制板
61.1578 Rigid Multilayer Printed Board
刚性多层印制板
61.1587 Metal Core Printed Board
金属芯印制板
61.1593 Build-Up Process
积层工艺
61.1594 Sequential Lamination
顺序层压
61.2058 Stacked Via/Microvia
叠层导通孔/微导通孔

62 Flexible Printed Boards (Organic)
挠性印制板（有机）

62.0525 Flexible Printed Circuit
挠性印制电路
62.0526 Flexible Printed Wiring
挠性印制线路
62.1579 Flexible Printed Board
挠性印制板
62.1580 Flexible Single-Sided Printed Board
挠性单面印制板
62.1581 Flexible Double-Sided Printed Board
挠性双面印制板
62.1582 Flexible Multilayer Printed Board
挠性多层印制板
62.1697 Double-Sided Flexible Printed Wiring Board
双面挠性印制线路板
62.2138 Tie-In Tab
连接条

63 Flex-Rigid Printed Boards (Organic)
挠刚印制板（有机）

63.0524 Flex-Rigid Printed Board
挠刚性印制板
63.1258 Rigid-Flex Printed Board
刚挠性印制板
63.1570 Flex-Rigid Double-Sided Printed Board
挠刚性双面印制板
63.1584 Rigid-Flex Double-Sided Printed Board
刚挠性双面印制板
63.1847 Flex-Rigid Printed Wiring Board
挠刚性印制线路板

64 Discrete Wiring Boards (Organic)
分立线路板（有机）

64.0390 Discrete Wiring Board
分立布线板
64.0391 Discrete Wiring Board Assembly
分立布线板组件
64.1555 Bead (Discrete Wiring)
铜圈（分立布线）
64.1588 Bounce Pad (Discrete Wiring)
反弹盘（分立布线）
64.1660 Cover Layer (Discrete Wiring)
覆盖层（分立导线）
64.1662 Cross-Over (Discrete Wiring)
交叉（分立布线）
64.1693 Discrete Wiring
分立线路
60.2068 Tangency (Cross Section)
相切（横截面）
64.2132 Wire Overcoat (Discrete Wiring)
导线保护层（分立布线）
64.2133 Wire Poke-Through (Discrete Wiring)
导线刺穿（分立布线）
64.2134 Wire Stub (Discrete Wiring)
导线梢（分立布线）
64.2135 Wiring Layer (Discrete Wiring)
布线层（分立布线）

67 Hybrid/Multichip Module Interconnecting Structures
混合/多芯片模块互连结构

67.0818 Overlap (Film)
重叠（膜）
67.1922 Module Board
模块板
67.1926 Molded Interconnection Device
模制互连器件

7 Assembly Processes for Interconnection Structures 互连结构组装工艺

70 General (Assembly Process Issues) 通用（组装工艺方面）

70.0090 Basic Wettability
基本润湿性

70.0149 Bridging, Electrical
电气桥接

70.0239 Component Mounting
元器件安装

70.0279 Contact Resistance
接触电阻

70.0291 Conveyor, Edge
边缘传送带

70.0292 Conveyor, Mesh
网状传送带

70.0293 Conveyor, Secondary
二级传送带

70.0435 Elongation
延伸

70.0972 Backup Pin
支撑销

70.1238 Bar
条

70.1292 Bar Code
条码

70.1353 Bar Code Printer
条码打印机

70.1354 Bar Code Scanner/Reader
条码扫描器/识别器

70.1370 Bar Code Symbol
条码符号

70.1452 Mixed Component-Mounting Technology
元器件混装技术

70.1586 Bonding Time
键合时间

70.1615 Character
符号

70.1626 Code 39
39条码

70.1627 Code Density
条码密度

70.1632 Component Mounting Site
元器件安装位置

70.1717 Element (Bar Code)
元素（条码）

70.1731 Bar Code Marking
条码标识

70.1757 Mixed Technology
混装技术

70.1763 Processability
可加工性

70.1770 Stand-Off
托高

70.1846 Flexible Material Interconnect Construction (FMIC)
挠性材料互连结构（FMIC）

70.1896 Laser Scanner (Bar Code)
激光扫描器（条码）

70.1907 Loading Direction
装载方向

70.1911 Assembly Manufacturer
组装制造商

70.1915 Message (Bar Code)
信息（条码）

70.1987 Print Contrast Signal
印刷对比信号

70.1996 Quiet Zone (Bar code)
空白区（条码）

70.2041 Solder Dissolution
焊料溶蚀

70.2042 Solder Flow-Up
焊料爬升

70.2051 Space (Bar Code)
空（条码）

70.2052 Special Characters
特殊字符

70.2054 Specks
斑点

70.2055 Spot Size
点尺寸

70.2059 Start/Stop Characters
起始/终止符

70.2075 Symbology (Bar Code)
符号象征（条码）

70.2080 Temperature, Reflow, Maximum
最高再流焊温度

70.2102 Tray
盘

70.2119 Voids (Bar Code)
脱墨（条码）

70.2121 Wand (Bar Code)
扫描笔（条码）

70.2183 Cant
倾斜角

71 Component Handling, Storage and Preparation 元器件操作、贮存和准备

71.1089 Tinning
上锡

71.1146 Waffle Pack
格栅包装

71.1541 Taped Component
带式元器件

71.1762 Preconditioning
预处理

72 Through-Hole Mounting of Components
通孔元器件插装

72.0063 Automated Component Insertion
自动元器件插装
72.0217 Clinched-Wire Interfacial Connection
弯线面间连接
72.1022 Straight-Through Lead
直通引线
72.1085 Through-Hole Mounting
通孔插装
72.1351 Clinched Lead
折弯引线
72.1352 Clinched-Wire Through Connection
弯线贯穿连接
72.1467 Partially-Clinched Lead
部分折弯引线
72.1539 Swaged Lead
压扁引线

73 Surface Mounting of Components
元器件表面贴装

73.0406 Drawbridged Component
吊桥元器件
73.0457 Excising
切割
73.0690 Aperture (Stencil)
开孔（模板）
73.0697 Lead Projection
引线伸出长度
73.0758 Area Ratio
面积比
73.0808 Aspect Ratio (Stencil)
宽厚比（模板）
73.0951 Slump
塌落
73.1001 Spread
铺展
73.1012 Staking, Adhesive
粘合固定
73.1026 Stringing
拉丝
73.1035 Surface Mounting Technology (SMT)
表面贴装技术（SMT）
73.1093 Tombstoned Component
墓碑状元器件
73.1648 Contained Paste Transfer Head
焊膏转移头
73.1733 Centering Force
对中力
73.1759 Pick-Up Tool
拾取工具
73.1760 Pick-Up Force
拾取力
73.1761 Placement Force
贴放力
73.1775 Vacuum Head
真空头
73.1866 Heel Fillet
跟部填充
73.1909 Locating Accuracy (Component)
定位精度（元器件）
73.1927 Mounting Tack Time
安装时间
73.1986 Pre-setting
预定位
73.2028 Self-Alignment Effect
自对中效应
73.2040 Solder Destination Side
焊接终止面
73.2048 Solder Source Side
焊接起始面
73.2076 Tackiness
粘着性

74 Bare Chip Placement and Attachment
裸芯片放置和连接

74.0021 Adhesion Layer
粘接层
74.0039 Angled Bond
角形键合
74.0048 Area Array Tape Automated Bonding
面阵列载带自动键合
74.0055 Aspect Ratio (Film)
长宽比（膜元器件）
74.0073 Back Bonding
背向键合
74.0079 Back Mounting
背向安装
74.0083 Ball Bond
球形键合
74.0085 Barrier Metal
隔离金属
74.0120 Bond
键合
74.0121 Bond-to-Bond Distance
键合间距离
74.0122 Bond-to-Die Distance
芯片键合距离
74.0123 Bond Deformation
键合变形
74.0125 Bond Enhancement Treatment
粘合增强处理

74.0126 Bond Envelope
键合参数限
74.0127 Bonding, Die
芯片键合
74.0128 Bonding Area
键合区
74.0129 Bonding Island
键合岛
74.0131 Bonding Tool
键合工具
74.0132 Bonding Wire
键合金属线
74.0133 Bond Interface
键合界面
74.0134 Bond Land
键合连接盘
74.0135 Bond Lift-Off
键合脱离
74.0136 Bond Schedule
键合参数表
74.0137 Bond Separation
键合间隔
74.0138 Bond Site
键合位置
74.0141 Bond Surface
键合面
74.0155 Bugging Height
障碍高度
74.0159 Bump (Die)
凸点（芯片）
74.0160 Bumped Die
带凸点芯片
74.0161 Bumped Tape
带凸点载带
74.0162 Bumped Wafer
带凸点晶圆
74.0167 Burn-Off
熔断
74.0175 Capillary
毛细导管
74.0189 Centerwire Break
金属线中心断裂
74.0204 Chessman
操作杆
74.0206 Chip-and-Wire
芯片–金属线
74.0210 Chisel
劈刀
74.0212 Chopped Bond
压陷键合
74.0235 Compliant Bond
柔性键合
74.0275 Contact Angle (Bonding)
接触角（键合）
74.0311 Cratering (Wire Bonding)
陷坑（金属线键合）
74.0336 Cut-Off
切断
74.0376 Die Bonding
芯片键合
74.0379 Diffusion Bond
扩散键合
74.0418 Edge Short
边缘短路
74.0432 Electron-Beam Bonding
电子束键合
74.0454 Eutectic Die Attach
共晶芯片连接
74.0469 Face Bonding
面键合
74.0491 Feature Window
要素窗
74.0512 First Bond
首键合
74.0513 First Radius
第一半径
74.0514 First Search
首次搜索
74.0520 Flag
垫板
74.0521 Flame-Off
烧断
74.0529 Flip-Chip Mounting
倒装芯片安装
74.0530 Flip Chip
倒装芯片
74.0532 Floating-Annulus Tape-Automated Bonding
浮动环载带自动键合
74.0547 Foot Length
底座长度
74.0551 Frame Pitch
框节距
74.0562 Gang Bonding
群点键合
74.0598 Heel, Bonding
键合倾斜
74.0620 Horn
喇叭
74.0646 Inner-Lead Bond (ILB)
内引线键合（ILB）
74.0680 Lap Shear Strength
搭接剪切强度
74.0756 Microbond
微键合

74.0770 Mislocated Bond
错位键合
74.0793 Nailhead Bond
钉头式键合
74.0796 Neckbreak
断颈
74.0804 Off Bond
偏离键合
74.0831 Partial Lift
局部起翘
74.0943 Single-Point Bonding
单点键合
74.0952 Smeared Bond
模糊键合
74.0961 Solder Bump
焊料凸点
74.0983 Solid-State Bond
固态键合
74.1003 Sprocket
输送定位孔
74.1021 Stitch Bond
跳点键合
74.1072 Thermosonic Bonding
热超声键合
74.1095 Torsional Strength
抗扭强度
74.1100 Transfer-Bump Tape Automated Bonding
转移凸点载带自动键合
74.1119 Ultrasonic Bonding
超声键合
74.1157 Wedge Bond
楔形键合
74.1158 Wedge Tool
楔形工具
74.1168 Wire Bonding
金属线键合
74.1169 Wire Sag
金属线下垂
74.1172 Wobble Bond
振动键合
74.1198 Outer-Lead Bond (OLB)
外引线键合（OLB）
74.1275 Sagging
下垂
74.1280 Scrubbing
磨刷
74.1281 Search Height
搜索高度
74.1283 Second Bond
第二键合
74.1290 Semiconductor Carrier
半导体载体
74.1312 Rebond
再键合
74.1342 Bondability
可键合性
74.1348 Chemisorption
化学吸附
74.1543 Thermocompression Bonding
热压键合
74.1617 Chip-in-Board (CIB)
板内芯片直装（CIB）
74.1618 Chip-on-Board Assembly
板上芯片直装组件
74.1619 Chip-on-Flex (COF)
挠性板上芯片直装（COF）
74.1620 Chip-on-Glass (COG)
玻璃基板芯片直装（COG）
74.1650 Controlled Collapse Bonding
可控塌落键合
74.1734 Circumferential Thermodes
环形热电极
74.1753 Face Down Bonding
面向下键合
74.1799 Face Up Bonding
面向上键合
74.2089 Thermal Sonic Bonding
热超声键合
74.2127 Ball Lift
焊球起翘
74.2152 Chip Scale Package
芯片尺寸封装（CSP）

75 Joining Techniques
连接技术

75.0289 Controlled Collapse, Component Connection
可控塌落元器件连接
75.0300 Corrosive Flux
腐蚀性助焊剂
75.0410 Dross
焊渣
75.0498 Fillet, Adhesive
粘合剂填充
75.0499 Fillet, Solder
焊料填充
75.0536 Flow Soldering
流动焊接
75.0538 Flux
助焊剂
75.0540 Flux Activation Temperature
助焊剂活化温度
75.0541 Flux Activity
助焊剂活性
75.0558 Adhesive Transfer (Pressure Sensitive Tape)
粘接剂转移（压敏胶带）

75.0564 Gas Blanket
气层
75.0585 Hand Soldering
手工焊接
75.0587 Hard Wiring
硬连线
75.0592 Heat Column
热杆
75.0609 Allowable Temperature
允许温度
75.0631 Icicle
焊料毛刺
75.0647 Inorganic Flux
无机助焊剂
75.0675 Anisotropic Conductive Contact
各向异性导电连接
75.0687 Leaching Metalization
金属层浸析
75.0691 Lead Extension
引线延伸
75.0737 Manual Soldering
人工焊接
75.0749 Mechanical Wrap
机械绕接
75.0780 Muffle
隔离罩
75.0817 Overheated Solder Connection
过热焊接连接
75.0835 Paste, Soldering
焊膏焊接
75.0836 Paste Flux
膏状助焊剂
75.0886 Porosity (Solder)
疏孔（焊料）
75.0899 Preferred Solder Connection
优质焊点
75.0926 Pulse Soldering
脉冲焊接
75.0957 Solder-Paste Flux
焊膏助焊剂
75.0958 Solderability
可焊性
75.0959 Solder Ball
焊料球
75.0960 Solder Bridging
焊料桥连
75.0963 Solder Connection
焊接连接
75.0964 Solder Connection Pinhole
焊接连接针孔
75.0966 Solder Embrittlement
焊料脆化
75.0967 Solder Fillet
焊料填充
75.0968 Soldering
焊接
75.0969 Soldering Ability
焊接能力
75.0970 Soldering Flux
焊接助焊剂
75.0971 Soldering Iron Tip
烙铁头
75.0974 Solder Plug
焊料塞
75.0975 Solder Projection
焊料拉尖
75.0979 Solder Sputter
焊料飞溅
75.0981 Solder Webbing
锡网
75.0982 Solder Wicking
焊料芯吸
75.0997 Specific Solderability
特定可焊性
75.1019 Step Soldering
分步焊接
75.1036 Surface Tension
表面张力
75.1038 Synthetic Activated Flux
合成活性助焊剂
75.1039 Synthetic Resin
合成树脂
75.1041 TAB
TAB
75.1043 Tail, Bonding
键合尾线
75.1044 Tail Pull
尾线割除
75.1045 Tape
带
75.1046 Tape Automated Bonding
载带自动键合
75.1048 Temperature Profile
温度曲线
75.1064 Tetrafunctional Resins
四官能团树脂
75.1070 Thermode
热电极
75.1101 Transfer Soldering
转移焊接
75.1121 Ultrasonic Soldering
超声焊接
75.1150 Water-Soluble Flux
水溶性助焊剂

75.1152 Wave Soldering
波峰焊接
75.1159 Wetting, Solder
焊料润湿
75.1162 Wicking
芯吸
75.1166 Wipe Soldering
涂擦焊接
75.1170 Wire Wrap
导线绕接
75.1183 Nonactivated Flux
非活性助焊剂
75.1189 Nonwetting (Solder)
不润湿（焊料）
75.1194 Open Time
间隔时间
75.1235 Reflow Spike
再流焊峰值
75.1247 Resin Flux
树脂助焊剂
75.1248 Resistance Soldering
电阻钎焊
75.1249 Resistance Welding
电阻熔焊
75.1326 Contact Angle (Soldering)
接触角（焊接）
75.1382 Dip Soldering
浸焊
75.1386 Drag Soldering
拖焊
75.1391 Eutectic (solder)
共晶（焊料）
75.1392 Eutectic
共晶
75.1393 Excess Solder Connection
过量焊接连接
75.1404 Foreign Material (Soldering)
外来物（焊接）
75.1416 Heatsink Tool
散热工具
75.1428 Intermetallic Compound, Solder
焊料金属间化合物
75.1465 Parallel-Gap Soldering
双极焊接
75.1466 Parallel-Gap Welding
双极熔接
75.1500 Reflow Soldering
再流焊接
75.1515 Rosin Solder Connection
过量松香焊接连接
75.1529 Soldering Oil (Blanket)
焊接油（覆盖层）
75.1530 Solderless Wrap
无焊绕接
75.1533 Staking, Mechanical
机械固定
75.1557 Vapor-Phase Soldering
汽相焊接
75.1568 Working Time
作业时间
75.1597 Bulk Reflow
批量再流焊
75.1628 Cohesion (Pressure Sensitive Tape)
附着性（压敏胶带）
75.1629 Cold Flow (Pressure Sensitive Tape)
冷流动（压敏胶带）
75.1651 Controlled Collapse Soldering
可控塌落焊接
75.1655 Cooldown
冷却
75.1672 Temperature Delta △T
温度差（△T）
75.1678 Mass Soldering
群焊
75.1681 Condensation Soldering
冷凝焊
75.1695 Dissolution of Termination Metallization (Leaching)
端子金属层溶蚀（浸析）
75.1708 Drying (Solder Paste)
烘干（焊膏）
75.1714 Electrolytic Corrosion Factor (Pressure Sensitive Tape)
电解腐蚀因子（压敏胶带）
75.1722 Equilibrium Wetting
润湿平衡
75.1736 Convected Energy
对流能
75.1745 Fluxing
助焊
75.1746 Forced Gas Convection Soldering
强制热风对流焊接
75.1748 Hot Plate Reflow Soldering
热板再流焊接
75.1749 Immersion Attitude
浸入位置
75.1751 Infrared Reflow (IR)
红外再流（IR）
75.1766 Solder Meniscus
焊料弯液面
75.1767 Solder Bath
焊料槽
75.1768 Soldering Iron
烙铁

75.1849 Stencil (Solder Paste/Adhesive)
模板（焊膏/粘合剂）
75.1850 Stencil Border
模板边
75.1851 Stencil Foil
模板箔
75.1853 Stencil Step
阶梯模板
75.1855 Stencil Frame
模板框架
75.1865 Soldering Temperature Resistance
耐焊接温度
75.1872 Hot Air Reflow Soldering
热风再流焊接
75.1873 Hot Bar
加热棒
75.1876 Impulse Current Soldering
脉冲电流焊接
75.1877 Infrared Soldering
红外焊接
75.1882 Intrusive Soldering
通孔再流焊接
75.1883 Paste-in-Hole
通孔内焊接
75.1884 Pin-In-Hole
孔中插针焊接
75.1886 Jet Wave Soldering
喷射波峰焊接
75.1897 Laser Soldering
激光焊接
75.1904 Lead-Free Solder
无铅焊料
75.1906 Liquidus, Solder
焊料液相线
75.1908 Local Reflow Soldering
局部再流焊接
75.1910 Low Residue Solder Paste
低残留焊膏
75.1919 Migration (Pressure Sensitive Tape)
迁移（压敏胶带）
75.1933 Reflow Soldering (Nitrogen Process)
再流焊接（氮气工艺）
75.1934 Flow Soldering (Nitrogen Process)
流动焊接（氮气工艺）
75.1941 Oozing (Pressure Sensitive Tape)
渗出物（压敏胶带）
75.1942 Organic Flux
有机助焊剂
75.1944 Overprinting
套印
75.1958 Peel Adhesion (Pressure Sensitive Tape)
剥离附着力（压敏胶带）
75.1984 Preheat Force
预热力
75.2007 Reflow Temperature
再流温度
75.2009 Release Liner (Pressure Sensitive Tape)
释放隔离衬（压力敏感带）
75.2010 Re-Melting Separation
再熔融分离
75.2043 Solder Joint
焊点
75.2044 Solder Luster
焊料光泽
75.2045 Solder Paste Printing Bleed
焊膏印刷溢出
75.2047 Solder Reflow
焊料再流
75.2050 Solidus (Soldering)
固相线（焊接）
75.2056 Squeegee
刮刀
75.2079 Temperature Leveling
温度均匀化
75.2090 Thermode Temperature Gradient
热电极温度梯度
75.2091 Thermode Temperature Variation
热电极温度变异
75.2099 Transfer Adhesive (Pressure Sensitive Tape)
转移粘接剂（压敏胶带）
75.2106 Ultrasonic Bond
超声键合
75.2113 Vapor Phase Reflow
汽相再流
75.2115 Vapor, Saturated
饱和蒸汽
75.2128 Wetting
润湿
75.2129 Wetting, Adhesive (Pressure Sensitive Tape)
粘接剂润湿，（压敏胶带）

76 Cleaning and Conformal Coating Processes
清洗和敷形涂覆工艺

76.0031 Aliphatic Solvents
脂肪族溶剂
76.0032 Alkaline Cleaner
碱性清洗剂
76.0110 Biocide
生物杀伤剂
76.0153 Bubble Effect
气泡效应
76.0154 Buffer Material
缓冲材料
76.0197 Chelate Compound
螯合物

76.0198 Chelating Agent
螯合剂
76.0224 Cold Hand Cleaning
手工冷清洗
76.0225 Cold Machine Cleaning
机器冷清洗
76.0233 Complex Ion
络离子
76.0263 Conformal Coating
敷形涂覆
76.0283 Contamination Host Material
污染宿主材料
76.0299 Corrosion (Chemical/Electrolytic)
腐蚀（化学/电解）（动词）
76.0313 Crazing (Conformal or Solder Mask Coating)
微裂纹（敷形涂覆或阻焊膜涂层）
76.0322 Critical Solution Temperature
临界溶液温度
76.0372 Dibasic Acid
二元酸
76.0384 Diphase Cleaning
双相清洗
76.0386 Direct Cleaning
直接清洗
76.0387 Direct Current Cleaning
直流电清洗
76.0429 Electrolytic Cleaning
电解清洗
76.0437 Emulsifying Agent
乳化剂
76.0439 Emulsion
乳液
76.0440 Encapsulant
封装剂
76.0455 Eutrophication
富营养化
76.0460 Exfoliation
鳞皮
76.0463 Extraction, Liquid-Liquid
液液萃取
76.0476 Fatty Acid
脂肪酸
76.0477 Fatty Ester
脂肪脂
76.0495 Filiform Corrosion
线状腐蚀
76.0534 Flocculant
絮凝剂
76.0535 Flocculation
絮凝作用
76.0542 Flux Characterization
助焊剂性能鉴定
76.0543 Flux Residue
助焊剂残留物
76.0584 Halide Content(Flux)
卤化物含量（助焊剂）
76.0603 Heterocyclic
杂环化合物
76.0615 Homocyclic
同素环化合物
76.0616 Homologous Series
同源系列
76.0617 Homopolymer
均聚物
76.0621 Hydrocarbon Tolerance
碳氢化合物容限
76.0622 Hydrolytic Stability
水解稳定性
76.0623 Hydrophilic Matter
亲水物质
76.0624 Hydrophilic Solvent
亲水溶剂
76.0625 Hydrophobic Matter
疏水物质
76.0626 Hydrophobic Solvent
疏水溶剂
76.0627 Hydrotrope
水溶助剂
76.0628 Hydrotrophe
水溶助长性
76.0629 Hypersorption
超吸附
76.0655 Intergranular Corrosion
晶间腐蚀
76.0661 Ion Exchange
离子交换
76.0663 Ionic Cleanliness
离子清洁度
76.0724 Loop, Wire
线环
76.0725 Loop Height
线弧高度
76.0730 Lyophobic
疏液性
76.0802 Occluded Contaminant
夹留污染物
76.0803 Occlusion
吸留
76.0815 Overcoat
覆盖层
76.0820 Oxygen Concentration Cell
氧浓差电池
76.0833 Passive-Active Cell
钝化–活化电池

76.0883 Polar Matter
极性物质
76.0885 Polymerized Rosin
聚合松香
76.0985 Solvent
溶剂
76.0986 Solvent Cleaning
溶剂清洗
76.0987 Solvent Pop
溶剂爆泡
76.0988 Solvent Release
溶剂释放
76.0989 Solvent Wash
溶剂洗涤
76.1011 Stain Proofing
防锈处理
76.1081 Thinner (Liquid)
稀释剂（液体）
76.1113 Tuberculation
结节
76.1120 Ultrasonic Cleaning
超声清洗
76.1187 Nonionic Contaminant
非离子污染物
76.1188 Nonpolar Matter
非极性物质
76.1196 Organic Contamination
有机污染物
76.1221 Dilution Ratio
稀释比
76.1222 Ionizable (Ionic) Contamination
可电离（离子）污染物
76.1225 Lyophilic
亲液性
76.1245 Residue
残留物
76.1253 Reverse Current Cleaning
反向电流清洗
76.1276 Saponifier
皂化剂
76.1317 Exchange Reaction
交换反应
76.1371 Critical Humidity
临界湿度
76.1397 Final Seal
最终密封
76.1401 Flash Distillation
急骤蒸馏
76.1402 Flux-Spatter Test
助焊剂飞溅测试
76.1410 Galvanic Corrosion
电流腐蚀
76.1454 Nonpolar Solvent
非极性溶剂
76.1480 Polymer Reversion
聚合物裂解
76.1531 Solvent Extraction
溶剂萃取
76.1535 Standard (Electrode) Potential
标准（电极）电势
76.1569 Wrinkles
皱褶
76.1713 Electrolytic Corrosion
电解腐蚀
76.1744 Ethanol
乙醇
76.1758 Montreal Protocol
蒙特利尔公约
76.1774 Terpenes
萜烯
76.1814 Mealing
起斑
76.1815 Polar Solvent
极性溶剂
76.2012 Resistance to Solvents
耐溶剂性
76.2114 Vapor Recovery
蒸汽回收

77 Rework, Repair and Modification
返工、维修和修正

77.0464 Extraction Tool
取出工具
77.0494 Field Trimming
现场修整
77.0667 Kerf
切口
77.0682 Laser Trimming
激光修整
77.0774 Modification
修改
77.1108 Trimming
修整
77.1109 Trimming Notch
修整槽口
77.1293 Serpentine Cut
螺旋形切割
77.1433 L Cut
L形切割
77.1502 Repair
维修
77.1511 Rework
返工

79 Other (Assembly Process Issues)
其他（组装过程方面）

79.1806 Capability Performance Index (Cp)
能力特性指数（Cp）

8 Types and Performance of Assemblies
组件的类型和性能

80 General (Assembly Type and Performance Issues)
通用（组装件类型和性能方面）

80.0057 Assembled Board
已组装板
80.0401 Double-Sided Assembly
双面组件
80.0503 Fine-Pitch Technology (FPT)
精细节距技术（FPT）
80.0775 Module
模块
80.0787 Multilayer Printed Circuit Board Assembly
多层印制电路板组件
80.0789 Multilayer Printed Wiring Board Assembly
多层印制线路板组件
80.0911 Printed Board Assembly
印制板组件
80.0913 Printed Circuit Board Assembly
印制电路板组件
80.0917 Printed Wiring Board Assembly
印制线路板组件
80.0944 Single-Sided Assembly
单面组件
80.1327 Assembly
组件
80.2105 Ultra-Fine Pitch Technology
超细间距技术
80.2151 System
系统

81 Rigid Printed Board Assembly (Organic Substrates)
刚性印制板组件（有机基板）

81.1669 Daughter Board
子板

83 Inorganic (Ceramic, Metal Core, etc.) Printed Board Assemblies
无机（陶瓷、金属芯等）印制板组件

83.1073 Thick-Film Circuit
厚膜电路
83.1074 Thick-Film Hybrid Circuit
厚膜混合电路
83.1075 Thick-Film Network
厚膜网络
83.1076 Thin-Film Hybrid Circuit
薄膜混合电路
83.1077 Thin-Film Integrated Circuit
薄膜集成电路
83.1078 Thin-Film Network
薄膜网络
83.1417 Hybrid Circuit
混合电路
83.1418 Hybrid Integrated Circuit
混合集成电路
83.1419 Hybrid Microcircuit
混合微电路

85 Backplanes
背板

85.0080 Backpanel
背板
85.0778 Mother Board
母板
85.1331 Backplane
底板

86 Multichip Modules
多芯片模块

86.0207 Chip-on-Board (COB)
板上芯片直装（COB）
86.0782 Multichip Integrated Circuit
多芯片集成电路
86.0783 Multichip Microcircuit
多芯片微电路
86.0784 Multichip Module (MCM)
多芯片模块（MCM）
86.1446 Microcircuit Module
微电路模块
86.1928 Multichip Module-Ceramic (MCM-C)
陶瓷多芯片模块（MCM-C）
86.1929 Multichip Module Deposited (MCM-D)
沉积多芯片模块（MCM-D）
86.1930 Multichip Module Laminate (MCM-L)
层压多芯片模块（MCM-L）

9 Quality and Reliability, Fabrication and Assembly
制造与组装的质量和可靠性

90 General (Quality and Reliability Issues)
通用（质量与可靠性方面）

90.0003 Acceptance Quality Level (AQL)
验收质量水平（AQL）
90.0007 Accuracy
精度
90.0018 Actual Size
实际尺寸
90.0025 Aging
老化

90.0308 Crack, Foil
金属箔裂纹
90.0309 Crack, Plating
镀层裂纹
90.0310 Cracking
裂缝
90.0348 Defect
缺陷
90.0349 Defect Identification
缺陷标识
90.0351 Degradation
退化
90.0353 Dendritic Growth
树枝状生长
90.0354 Dendritic Migration
树枝状迁移
90.0359 Dentrices
树枝状物
90.0478 Fault
故障
90.0479 Fault Dictionary
故障表
90.0637 Inclusions
夹杂物
90.1029 Structurally-Similar Construction
结构类似构造
90.1087 Through Migration
穿透迁移
90.1140 Void
空洞
90.1501 Reliability
可靠性
90.1526 Shelf Life
保存期限
90.1854 Foreign Material
外来物
90.1913 Quality System
质量体系
90.2022 Sample Qualification
样品鉴定

91 Process Control/SPC
过程控制/SPC

91.0024 Advanced Statistical Method
高级统计方法
91.0033 Alpha Error
α错误
91.0038 Analysis of Variance (ANOVA)
方差分析（ANOVA）
91.0059 Assignable Cause
可查明原因
91.0104 Beta Error
β错误
91.0140 Subgroup
子群
91.0190 Central Line
中心线
91.0229 Common Cause
普遍原因
91.0290 Control Limits
控制限
91.0306 Capability Index (Cp)
能力指数（Cp）
91.0307 Cpk Index (Cpk)
过程能力指数（Cpk）
91.0321 Critical Operation
关键操作
91.0333 Cusum Chart
累积和图
91.0367 Detection
检测
91.0481 Fault Localization
故障定位
91.0492 Fiber Exposure
露纤维
91.0510 First-Pass Yield
直通率
91.0511 First Article
首件
91.0515 Fishbone Diagram
鱼骨图
91.0527 Flexural Failure
挠曲破坏
91.0550 Fractional-Factorial Experiment
部分因子实验
91.0567 Generative Process Planning
生成过程规划
91.0608 Histogram
直方图
91.0630 Hypotheses Test
假设测试
91.0632 Identical Processing
等同加工
91.0649 Inspection Overlay
覆盖检验板
91.0674 Laminate Void
层压板空洞
91.0722 Long-Term Capability
长期能力
91.0767 Minor Defect
次要缺陷
91.0772 Mixed-Effects Model
混合效应模式
91.0781 Multi-Vari
多变元

91.0790 Multilevel Experiment
多重实验
91.0791 Multiple Indications
多重迹象
91.0842 Percent Contribution
影响百分率
91.0895 Power of Experiment
实验功效
91.0920 Process Average
过程平均
91.0921 Process Indicator
制程警示
91.0922 Process Spread
制程散布
91.0933 Signal-to-Noise Ratio (Process Control)
信噪比（过程控制）
91.0995 Special Cause
特殊原因
91.0996 Specification Limits
规格限
91.1002 Spread (Values)
离散（数值）
91.1008 Stability
稳定性
91.1010 Stable Process
稳定工艺
91.1015 Statistical Control
统计控制
91.1016 Statistical Hypothesis
统计假设
91.1017 Statistical Quality Control (SQC)
统计质量管理（SQC）
91.1117 Type I Error
I 类错误
91.1132 User Inspection Lot (Material)
用户检验批（材料）
91.1134 Variables Data
变量数据
91.1135 Variance
方差
91.1136 Verification Time
验证时间
91.1138 Virtual Condition
实效状态
91.1182 Noise (Process Control)
干扰（过程控制）
91.1210 Sum of Squares
平方和
91.1228 Output Vector
输出矢量
91.1241 Regression Analysis
回归分析
91.1251 Response Variable
响应变量
91.1268 Run
链
91.1269 Run Chart
链图
91.1302 Short-Term Capability
短期能力
91.1309 Randomization
随机选择
91.1310 Randomness
随机性
91.1311 Random Sample
随机样本
91.1314 Reciprocity Failure
互易失效
91.1336 Basic Statistical Method
基本统计方法
91.1344 Capability Performance, Upper (Cpku)
能力特性，上限（Cpku）
91.1367 Capability Performance, Lower (Cpkl)
能力特性，下限（Cpkl）
91.1368 Control Chart
控制图
91.1399 Fixed-Effect Model
固定效应模式
91.1434 Larger-the-Better Characteristic
越大越好特性
91.1442 Lot Size
批量
91.1450 Nominal-Is-Best Characteristic
标称最佳特性
91.1455 Null Hypothesis
原假设
91.1458 Orthogonal-Array Experiment
正交实验
91.1478 Poisson Distribution
泊松分布
91.1497 Random-Effects Model
随机效应模式
91.1498 Reciprocity Law
互易定律
91.1503 Repeatability (Accept/Reject) Decisions
重复性（接受/拒绝）判定
91.1519 Sensitivity Control
灵敏度控制
91.1534 Standard Deviation of a Population
总体标准差
91.1536 Statistical Process Control (SPC)
统计过程控制（SPC）
91.1558 Vendor Inspection Lot (Material)
供应商检查批（材料）

91.1694 Disposition (Defects)
处置（缺陷）
91.1817 Smaller-the-Better Characteristic
越小越好特性
91.1879 In-Process Inspection
过程检验
91.1881 Internal Capability Assessment
内部能力评估
91.1939 Objective Evidence
客观证据
91.1989 Proficiency
熟练程度

92 Inspection/Testing
检验/测试

92.0004 Acceptance Tests
验收测试
92.0043 Apparent Field-of-View Angle
视角
92.0047 Arc Resistance
耐电弧性
92.0064 Automatic Test Equipment
自动测试设备
92.0065 Automatic Test Generation
测试自动生成
92.0066 AWG Equivalent
等效AWG
92.0074 Backdriving
反向驱动
92.0089 Base Solderability
基本可焊性
92.0097 Baume
波美度
92.0101 Bed-of-Nails Fixture
针床夹具
92.0103 Benchmark, Testing
测试基准
92.0109 Biochemical Oxygen Demand
生化需氧量
92.0157 Bulk Conductance
体积电导
92.0172 Camber
弯度
92.0234 Personality Plate
专用模板
92.0247 Conditioning
预处理
92.0284 Continuity
连通性
92.0288 Acceptance Inspection (Criteria)
验收检验（准则）
92.0294 Coordinatograph
坐标仪
92.0296 Copper-Mirror Test
铜镜测试
92.0302 Coupon
附连板
92.0314 Crease
褶痕
92.0324 Cross-Sectioning
剖切
92.0389 Discrepant Material
不合格材料
92.0403 Download, Tester
测试仪下载
92.0411 Dual Fixture
双组夹具
92.0415 Edge Definition
边缘精度
92.0416 Edge Detection
边缘检查
92.0459 Exclusion Area
免检区
92.0465 Extraneous Metal
残余金属
92.0471 False Alarm
假警报
92.0472 False Alarm Rate
假警报率
92.0480 Fault Isolation
故障隔离
92.0482 Fault Masking
故障屏蔽
92.0483 Fault Modes
故障模式
92.0484 Fault Resolution
故障分辨率
92.0485 Fault Signature
故障表征
92.0519 Fixture, Test
测试夹具
92.0556 Functional Tester
功能测试仪
92.0570 Go/No-Go Test
通过/不通过测试
92.0571 Golden Assembly
黄金组件
92.0572 Golden Board
黄金板
92.0573 Gouge
凿槽
92.0576 Grey-Scale Processing
灰度处理
92.0582 Guarding
保护

92.0607 Hipot Test
高压测试
92.0636 In-Circuit Testing
在线测试
92.0648 Input Vector
输入矢量
92.0650 Inspection Personnel
检验人员
92.0651 Inspection Rate
检验速率
92.0652 Inter-Test Time (ITT)
测试间隔时间（ITT）
92.0670 Known Good Assembly (KGA)
已知好组件（KGA）
92.0671 Known Good Board (KGB)
已知好板（KGB）
92.0693 Scanner, Test
测试扫描仪
92.0700 Learn Time
学习时间
92.0714 Load Time
装载时间
92.0733 Magnification Power
放大率
92.0750 Meniscus
弯液面
92.0755 Scan Rate
扫描速率
92.0760 Microprobe
微探针
92.0792 Nail
钉
92.0799 Neighborhood Processing
相邻处理
92.0812 Open, Electrical
电气开路
92.0841 Peel Strength
剥离强度
92.0843 Percent of the Field of View
视场百分比
92.0863 Pinhole (Material)
针孔（材料）
92.0866 Pit
麻点
92.0901 Pregelation Particle
预胶凝粒子
92.0909 Primary Stage of Manufacture
制造主要阶段
92.0918 Probe, Test
测试探针
92.0919 Probe Point
探针测试点
92.0924 Proportional Dimensions
比例尺寸
92.0925 Pull Strength
拉拔强度
92.0938 Silver Migration
银迁移
92.0939 Simulated Aging
模拟老化
92.0940 Simulated Datum
模拟基准
92.1056 Testing Personnel
测试人员
92.1057 Test Language
测试语言
92.1058 Test Master
测试原版
92.1059 Test Pattern
测试图形
92.1060 Test Point
测试点
92.1061 Test Program
测试程序
92.1062 Test Set
测试装置
92.1063 Test Step
测试步骤
92.1090 Titrometry
滴定分析
92.1097 Touch-Up
修版
92.1123 Unconditional Test
无条件测试
92.1124 Undercut, After Fabrication
加工后侧蚀
92.1125 Undercut, In Process
制程中侧蚀
92.1128 Unload Time
卸载时间
92.1130 Upload (Test)
加负载（测试）
92.1137 Vesical
疱
92.1139 Visual Examination
目检
92.1144 Volumetric Analysis
体积分析
92.1160 Wetting Balance
润湿称量仪
92.1161 Whisker
晶须
92.1214 Qualitative Analysis
定性分析

92.1215 Quantitative Analysis
定量分析
92.1220 Coupon (Breakaway)
附连板（可分离）
92.1244 Repeat Set-Up Time
重复设置时间
92.1250 Resistor Drift
电阻漂移
92.1271 Run Time
运行时间
92.1278 Scan-Dead Time
扫描空载时间
92.1287 Self Test
自检测试
92.1298 Shear Strength
剪切强度
92.1301 Short, Electrical
电气短路
91.1302 Short-Term Capability
短期能力
92.1396 Fault Simulation
故障模拟
92.1421 Inspection Facility
检验设施
92.1422 Inspection Lot
检验批
92.1447 Microsectioning
显微剖切
92.1476 Plated-Through Hole Structure Test
镀覆孔结构测试
92.1492 Profile Factor
外形因数
92.1495 Quality Conformance Test Circuitry
质量符合性测试电路
92.1522 Set-Up Time
设置时间
92.1524 Sheet Capacitance
片电容
92.1525 Sheet Resistance
片电阻
92.1538 Surface Insulation Resistance (SIR)
表面绝缘电阻（SIR）
92.1548 Treatment Transfer
处理物转移
92.1560 Vesication
起疱
92.1561 Vesicativity Ratio
起泡率
92.1565 Bending Resistance
耐弯曲性
92.1566 White Spot
白斑
92.1603 Burr
毛刺
92.1641 Conformance Test Coupon Set
符合性测试用的附连板组
92.1649 Continuity Test
连通性测试
92.1664 Customer Test Data
客户测试数据
92.1670 Delivery Inspection
交付检验
92.1671 Final Inspection
最终检验
92.1680 Destructive Physical Analysis (DPA)
破坏性物理分析（DPA）
92.1683 Test Board
测试板
92.1765 Shear Test
剪切测试
92.1769 Specimens
试样
92.1771 Substrate Bending Test
基板弯曲测试
92.1790 Individual Test Specimen (ITS)
单独试样（ITS）
92.1819 Solder Spread Test
焊料铺展测试
92.1820 Test Coupon
附连测试板
92.1874 Humidity Aging
潮湿老化
92.1875 Humidity Indicator Card (HIC)
湿度指示卡（HIC）
92.2023 Scanning Electron Microscope (SEM)
电子扫描显微镜
92.2063 Steam Aging
蒸汽老化
92.2072 Extraneous Copper (Base Materials)
残余铜（基材）
92.2078 Scanning Acoustical Microscopy (SAM)
声学扫描显微镜（SAM）
92.2081 Test Coupon Set
附连测试板组
92.2086 Standard Laboratory Conditions
标准实验室条件
92.2088 Thermal Shock Test
热冲击测试
92.2098 Tracking Resistance
耐电痕性
92.2150 Known Tested Die (KTD)
已测试合格芯片（KTD）

93 Reliability Factors and Methodology
可靠性因素和方法

93.0001 Accelerated Aging
加速老化
93.0096 Bathtub Curve
浴盆曲线
93.0119 Accelerated Life Test
加速寿命测试
93.0216 Accelerated Test
加速测试
93.0260 Acceleration Factor (AF)
加速因子（AF）
93.0461 Experimental Error
实验误差
93.0552 F Ratio
F比率
93.0923 Producer's Risk
生产方风险
93.1324 Alternative Hypothesis
备择假设
93.1403 Forced-Field Analysis
强力场分析

94 Quality Management and Assurance
质量管理和保证

94.0062 Attributes Data
属性数据
94.0077 Background Variable
背景变量
94.0108 Binomial Distribution
二项分布
94.0116 Blocking Variables
分组变量
94.0147 Brainstorming
头脑风暴法
94.0188 Cause-and-Effect Diagram
因果图
94.0195 Check Plot
校查图
94.0196 Check Sheet
校查单
94.0262 Confirmation Run
确认试验
94.0264 Confounding
混淆
94.0274 Consumer's Risk
使用方风险
94.0301 Cost of Quality
质量成本
94.0320 Critical Defect
致命缺陷
94.0352 Degrees of Freedom (df)
自由度（df）
94.0448 Escape Rate
漏失率
94.0449 Escapes
漏失
94.0468 F (Fisher) Test
F（费歇尔）测试
94.0470 Factorial Experiment
析因实验
94.0734 Major Defect
主要缺陷
94.0830 Pareto Analysis
帕拉多分析
94.0931 Sigma (σ)
西格玛
94.0991 Scatter Diagram
散布图
94.1118 Type II Error
II类错误
94.1126 Underwriters Symbol
安全检测标记
94.1163 Window
窗口
94.1165 Window (Process)
窗口（工艺）
94.1191 Normal Distribution
正态分布
94.1212 Qualification Agency
鉴定机构
94.1213 Qualification Testing
鉴定测试
94.1219 Check List
检查清单
94.1365 Confidence Interval
置信区间
94.1496 Quality Conformance Testing
质量一致性测试
94.1665 Damage
损坏
94.1777 Risk Management Factor (RMF)
风险管理因子
94.1784 Capability Test Board (CTB)
能力测试板（CTB）
94.1785 Capability Test Segment (CTS)
能力测试块（CTS）
94.1807 Gaussian Distribution
高斯分布
94.1988 Production Data
生产数据
94.2027 Self Declaration
自我声明

95 Component Quality and Reliability
元器件质量和可靠性

95.0164 Burn-In
老化

95.0165 Burn-In, Dynamic
动态老化
95.0166 Burn-In, Static
静态老化
95.0504 Fine Leak
细泄露
95.0580 Gross Leak
重泄露
95.1024 Stress Corrosion Cracking
应力腐蚀裂纹
95.1663 Cratering (Chip-Out)
陷坑
95.1750 Immersion Conditions
浸入条件
95.1755 Mechanical Stress
机械应力
95.1945 Package Cracking
封装裂纹
95.2131 Wire Bond Degradation
金属线键合退化

96 Interconnection Structure Quality and Reliability
互连结构质量和可靠性

96.0020 Adhesion Failure
粘接失效
96.0023 Adsorbed Contaminant
吸附污染物
96.0222 Cohesion Failure
附着失效
96.0277 Contact Corrosion
接触腐蚀
96.0278 Contact Length
接触长度
96.0280 Contact Retention Force
接触保持力
96.0474 Fatigue Life
疲劳寿命
96.0475 Fatigue Limit
疲劳极限
96.0662 Metal Through Migration
金属贯穿迁移
96.0754 Metal Migrativity
金属迁移率
96.0763 Migration Rate
迁移速率
96.0764 Migration Velocity
迁移速度
96.0950 Sliver
镀屑
96.1000 Spotting Out
疵点显现
96.1208 Subsurface Corrosion
表面下腐蚀
96.1226 Metal Surface Migration
金属表面迁移
96.1340 Blister
起泡
96.1349 Circumferential Separation
环状断裂
96.1394 Fatigue Strength
疲劳强度
96.1395 Fatigue-Strength Reduction Factor (Kf)
疲劳强度降低系数（Kf）
96.1444 Barrel Crack
孔壁裂纹
96.1445 Metal Migration
金属迁移
96.1510 Reversion
裂解
96.1640 Conductor Protrusion
导体突出
96.1659 Corner Crack (Knee Crack)
拐角裂纹
96.1715 Electromigration
电迁移
96.1892 Land Tearing
连接盘撕裂
96.1920 Migration Resistance
耐迁移
96.1932 Conductor Nick
导体缺口
96.1990 Protrusion of Conductor
导体突出
96.2032 Tunnel Void, (Base Materials)
管状空洞（基材）
96.2033 Silver Streak (Base Materials)
银条纹（基材）
96.2078 Tear (Base Materials)
撕裂（基材）
96.2120 Voids (Base Materials)
空洞（基材）
96.2176 Pad Cratering
盘坑裂

97 Electronic Assembly/Subassembly Quality and Reliability
电子组件/分组件质量和可靠性

97.0226 Cold Solder Connection
冷焊接连接
97.0317 Crevice Corrosion
裂隙腐蚀
97.0370 Dewetting
退润湿
97.0563 Gas-Tight Area
气密区

97.0599 Heel Break
跟部断裂
97.0600 Heel Crack
跟部裂缝
97.0657 Intermittent Fault
间歇故障
97.0928 Push-Off Strength
推离强度
97.0993 Spalling
散裂
97.1384 Disturbed Solder Connection
受扰焊接连接
97.1424 Insufficient Solder Connection
焊接连接不充分
97.1816 Pull-Out Strength
拉出强度
97.1833 Solder Fillet Lifting
焊料填充起翘
97.1834 Solder Fillet Tearing
焊料填充撕裂
97.1862 Globule Method
焊球测试法
97.1905 Lift-Off
升离
97.1991 Pull-Off Strength (SMD)
拉离强度（SMD）
97.2031 Shrinkage Cavity
缩孔

Association Connecting Electronics Industries

ANSI/IPC-T-50 互联电子线路封装产品

条款及定义申报表

此表格将同步于企业和行业中例行的规定. 欢迎个体或单位参与发表意见。请填写此份表格并反馈给:

IPC
3000 Lakeside Drive, Suite 309S
Bannockburn, IL 60015-1249
传真: 847 615.7105

申请人信息:

姓名: _____

公司名称: _____

所在城市: _____

所属国家: _____

电话号码: _____

日期: _____

❑ 新的条款及定义的申报.

❑ 对原有条款及定义的补充.

❑ 对原有条款及定义的修改.

条款	定义

如空间不足,请写在背面或附页上.

文件: ❑ 不适用 ❑ 要求的 ❑ 待定

❑ 包括: 电子稿名称: _____

适用此条款及定义的文件: _____

_____

_____

与此条款及定义相关的委员会: _____

_____

_____

由IPC 内部填写

IPC Office

Date Received: _____
Comments Collated: _____
Returned for Action: _____
Revision Inclusion: _____

Committee 2-30

Date of Initial Review: _____
Comment Resolution: _____
Committee Action:
❑ Accepted ❑ Rejected ❑ Accept Modify

IEC Classification

Classification Code • Serial Number

Terms and Definition Committee Final Approval Authorization:
Committee 2-30 has approved the above term for release in the next revision.
Name: _____ Committee: IPC 2-30 Date: _____

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Association Connecting Electronics Industries

IPC Inc.
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IPC 会员的裨益

技术标准　　技术培训　　市场研究　　同行协作

印制电路和电子组装行业国际性的行业协会

IPC 简介

IPC（美国电子工业联接协会）是为电路板及电子组装行业服务的国际性协会，拥有约 2400 家会员公司，他们代表着当今电路板及电子互连行业所有的领域。IPC 的会员公司分布在全球近 53 国家和地区，这些会员公司既有员工人数仅 25 名，或者是全球知名的公司。人们几乎每天都在使用他们的产品。

IPC 成立于 1957 年，当时称为印制电路学会。1977 年，IPC 的名称修改为电子电路互连和封装学会，以进一步反映与电子互连行业相应的种类繁多的产品。1998 年，我们的名称再次作了更改，暨 IPC – Association Connecting Electronics Industries® （IPC - 美国电子工业联接协会“为电路板及电子组装行业服务”）,来表明 IPC 成立后 40 多年来赢得的国际知名度和凸显 IPC 服务于电子互连行业的各个技术领域。

IPC 会员公司的行业领域是：

- **印制电路行业** -- 生产印制电路裸板的公司或单位，产品供他们自己使用或销售给 OEM 客户。IPC 会员公司中有全球知名的印制电路板制造商。另外，会员单位名录中，注明了印制电路板供应商，设备制造商，原材料制造商和服务公司。由于印制电路板是所有电子产品的基础，因此，设计和使用印制电路板的诸 OEM，在会员单位名录有重点介绍。
- **电子组装行业** – 各类电子组装产品的公司，电子组装是电子产品的核心。会员单位名录中，有自己完成组装的 OEM，或者将产品和系统外发包给电子制造服务（EMS）公司的 OEM。IPC 有着服务于 EMS 行业的悠久历史，如 1984 年出版第一份市场研究报告，80 年代末期在行业中发展和推广 EMS 名称的应用。所有的著名 EMS 公司都是 IPC 的会员。名录中，按组装设备制造商，原材料制造商，分别介绍。正如印制电路板行业一样，电子组装行业的会员也包括诸 OEM 公司。
- **设计** -- 设计印制电路板布线的设计师或公司。一名设计师可以是在一家电路板制造公司，组装公司，或 OEM 工作；或者可以是独立的设计承包者。

为何要加入 IPC 协会呢？

新技术与您同步

IPC 从 1959 年起编制各类标准至今，已出版了近 200 种技术标准，技术规格和技术指南手册。IPC-A610C（电子组装验收）和 IPC-A-600F（印制板验收）这两个技术标准已有中文版。目前，IPC 正在翻译其它的标准。这些翻译好的标准，由 IPC 正式同意出版，确保译文的质量与可信性。

IPC 的技术标准在国际上被普遍推广和使用着。IPC 是国际电工技术委员会（IEC）的成员之一，电子组装的技术顾问和印制电路板秘书处成员。IPC 也是世界电子电路委员会(WECC）的秘书长。

员工培训和发展

IPC 为印制电路板和电子组装行业提供技术培训和授证的优质服务。作为 IPC 的会员，您们的公司能从授证中获得裨益。比如，IPC-A-610 授证和培训计划，已培训了仅 4,000 名讲解员和 40,000 名生产操作员。目前，IPC 与中国的相关行业协会合作，开展关于电子组装验收，以及电子组装的返修和返工的可接受性的培训和授证。

IPC 每年还为印制电路板和电子组装行业提供 90 个专题培训，现场辅导培训和技术报告会，全套的培训录像和基于计算机培训的技术资料。IPC 的手工焊接工艺培训 DVD，配有中文解说。IPC 正在翻译其它的录像带和 DVD 技术培训资料，以服务于企业的技术培训需求。

IPC 设计师委员会（IPC Designers Council）有 1,200 名会员，它提供培训和授证，协助您们与设计师间国际交流和合作，解决一些主要的设计难题。

您的事业迈向新高峰

IPC 提供在线服务，介绍会员公司并协助继续发展：

- 会员公司网站与 IPC 网站免费连接
- IPC 会员公司的产品和服务内容数据库
- 免费下载技术文件
- 免费刊登在线元器件存货清单，使电子组装公司可以在线销售多余元器件，或在线采购元器件

IPC 还提供当今的市场与管理方面的讯息：

- 〈〈IPC Review〉〉月刊，免费分发给会员公司，分享行业与协会的最新发展
- IPC 的管理讯息，分析报告和亚洲专刊，向会员公司提供市场发展情况和促进市场发展的技术发展趋势
- 完整的市场研究报告，包括世界印制电路板市场和北美 EMS 市场报告给 IPC 行业市场和技术论坛（IPC EMTF，会员费不包括论坛费）

节省您的开支

IPC 会员购买技术标准手册，半价优惠。对于参加培训课和购买各种培训资料，包括会员公司参加 IPC 的国际性展览会，都有实质性的优待。

Association Connecting Electronics Industries

会员申请表

衷心感谢您们成为 IPC 协会会员和对 IPC 的支持！
为了使 IPC 能更快更好地为会员服务，请在以下项目中选择最能反映您们单位情况的一栏，
并按提示填写。

□ **独立的印制板制造商**
制造印制板，并将产品售给其它公司，如线路板或者其它电子互连产品。您们生产和销售哪些产品？
□ 单面和双面印制板　□ 多层印制板　□ 柔性印制板　□其它互连产品

董事长/总经理：_____

□ **独立的电子组装 EMSI 公司**
根据合同，组装各类印制线路板，并可提供其它电子互连产品进行销售。

董事长/总经理：_____

□ **OEM-制造商，终端产品中使用电路板，或者自产自用电路板**
制造和销售最终产品，其产品中有外购的或自制的电路板及其它电子互连产品。

系列产品：_____

□ **行业供货商**
提供应用于电子互连产品制造或组装的原材料，机器，设备或技术服务。

供应产品品种：_____

□ **政府机构/高等院校，科研机构**
设计，研究，使用电子互连产品，非盈利为目的的事业单位。

单位情况：
单位名称：_____
地址：_____
电话：_____，传真：_____
联系人：_____，职称：_____
电子邮件：_____，网址：_____

请选择一项：
□ 单位会员，年费 US$1,000，自加入日起 12 个月。
□ 同一集团，不同单位，如已有原始会员，年费 US$800，自加入日起 12 个月。
□ 独立的电路板制造商，或 EMSI 供应商，年销售额不超过 100 万美元，年费 US$600，
自加入日起 12 个月。
□ 行业协会，非盈利的高等院校和科研机构，年费 US$250，自加入日起 12 个月。

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Association Connecting Electronics Industries

标准改善填写表

IPC-T-50H CN

此表的目的在于让这标准的有关工业使用者向IPC技术委员会提供建议.

欢迎个人或集体对IPC提交建议.我们将会收集所有的建议并上交给相应的委员会.

如果您能提供改善建议, 请填好下表并递至:

IPC
3000 Lakeside Drive, Suite 309S
Bannockburn, IL 60015-1219
传真: 847 615.7105
电子邮件: answers@ipc.org

1. 我想对以下提出更改建议:

   ___要求, 章节数

   ___那种测试方法_____, 章节数 _____

   以上章节数被证明为:

   ___不清楚 ___不适用 ___有误的

   ___其他

2. 具体的更改建议:

3. 对于标准的其他改进建议:

提交人:

姓名	电话
公司	电子邮件
地址	
城市/国家/洲	日期

Association Connecting Electronics Industries

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上海办公室
电话：（8621）54973435/36
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